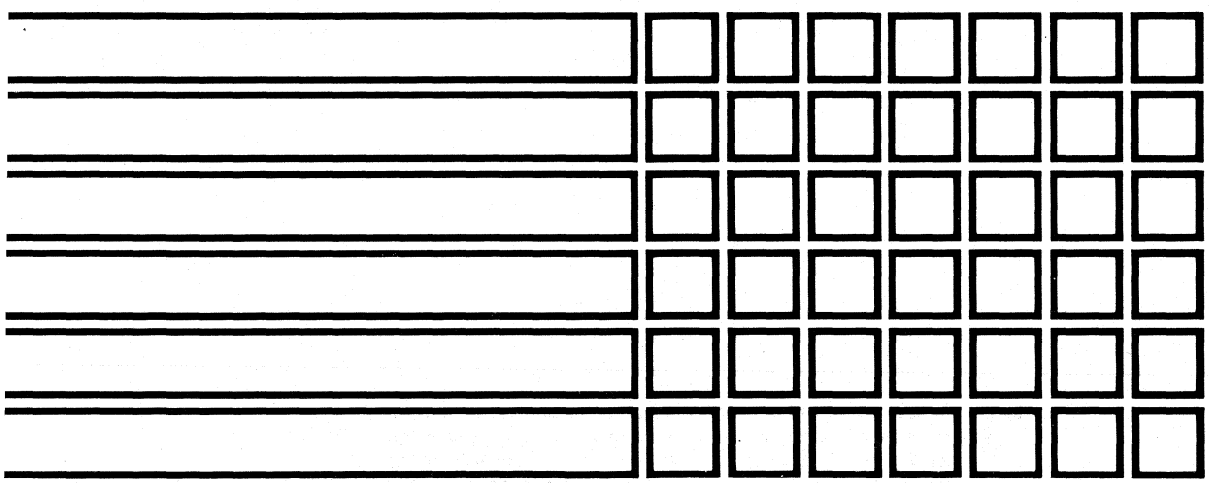
Signetics
integrated circuits
1979

Analogue circuits

signetics

SIGNETICS ANALOG
–SPECIFICATIONS
–MILITARY SUMMARY

DATA MANUAL
1979



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INTRODUCTION

As one of the world's largest manufacturers of integrated circuits, Signetics designs, develops, manufactures, and sells over 1600 different types of integrated circuits. Signetics produces linear circuits utilizing both bipolar and metal-oxide semiconductor (MOS) manufacturing processes.

The Analog division is a major broad line supplier of both Signetics' original designs and industry standard devices. The NE5534 High Performance Operational Amplifier, the NE5018 microprocessor compatible DAC, and the NE5554 Dual Tracking Regulator are among Signetics' original products. The breadth of the Analog product line offers the designer, the component engineer, and the purchasing agent a varied approach to linear circuits.

This broad analog circuit product line is backed by Signetics' industry image as a quality manufacturer to whom the servicing of the customers' needs is paramount.

The 1979 Analog Data Manual is intended to serve as a single reference for linear circuits by presenting information necessary to select Signetics' analog products properly. The data manual is updated and rewritten to reflect data on new products issued.

Additions and errata will be generated at periodic intervals.

Your inputs to improve our publications will be greatly appreciated.

Ira Zingmond
Manager, Linear Applications

ORDERING INFORMATION

Signetics' Analog integrated circuit products may be ordered by contacting either the local Signetics sales office, Signetics representatives and/or Signetics authorized distributors. A complete listing is located in the back of this manual.

Minimum Factory Order:

Commercial Product:
$1000 per order
$50 per line item per order

Military Product:
$250 per line item per order

Table 1 provides part number information concerning for both Signetics originated products and industry standard products.

Table 2 is a cross reference of both the old and new package suffixes for all presently existing types, while Table 3 and 4 provide appropriate explanations on the various prefixes employed in the part number descriptions.

As noted in Table 3, Signetics defines device operating temperature range by the appropriate prefix. It should be noted however, that devices with a SE prefix (-55°C to +125°C) indicates only its operating temperature range and *not* its military qualification status. The military qualification status of any analog product can be determined by either looking in the Military Section in this manual and/or contacting your local sales office.

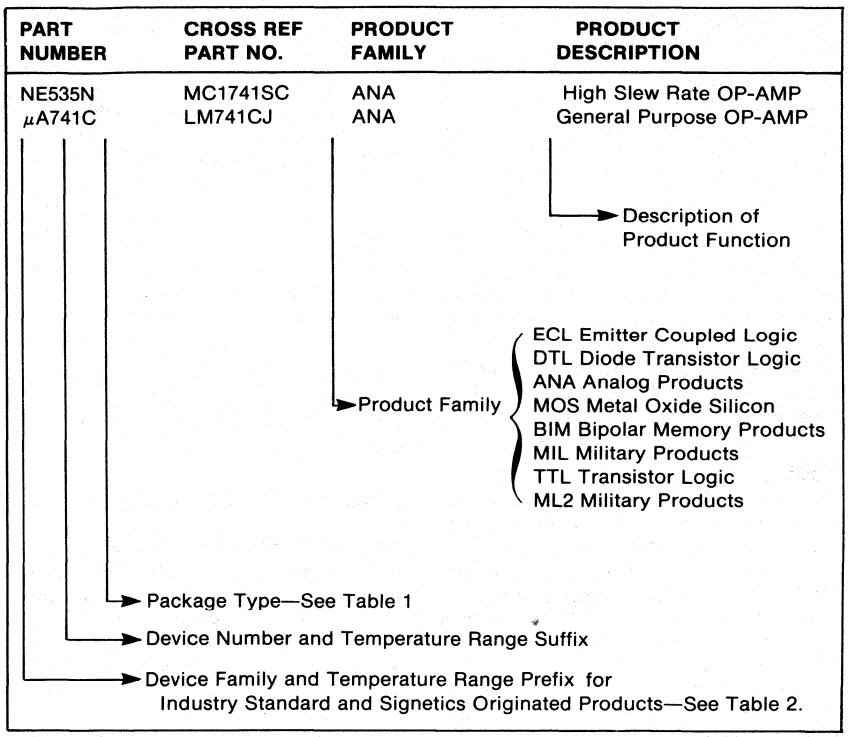


Table 1 PART NUMBER DESCRIPTION

SUFFIX		PACKAGE DESCRIPTION[2]
Old	New	
A,AA	N	14-lead plastic DIL
A	N-14	14-lead plastic DIL (Selected Analog products only)
B,BA	N	16-lead plastic DIL
DA	K	2-lead TO-3
DB	HB	3-lead TO-39
DC	DC	4-lead TO-46
DE	DE	4-lead TO-72
F	F	14, 16, 18, 22 and 24-lead ceramic (Cerdip) DIL
I,IK	I	14, 16, 18, 22, 28 and 4-lead ceramic DIL
K	K	10-lead TO-100
L	L	10-lead high-profile TO-100 can
NA,NX	N	24-lead plastic DIL
PN	PHA	12 + 1 GND pin DIL
Q,R	Q	10, 14, 16 and 24-lead ceramic flat
S	S	3-lead TO-92 plastic
SK	SK	Microprocessor kit
T,TA	T	8-lead TO-99
U	U	Plastic power TO-220
V	N	8-lead plastic DIL
W,WJ	W	10, 14, 16 and 24-lead ceramic (Cerpac) flat
XA	N	18-lead plastic DIL
XC	N	20-lead plastic DIL
XC	N	22-lead plastic DIL
XL,XF	N	28-lead plastic DIL

Table 2 PACKAGE DESCRIPTIONS

PREFIX	DEVICE TEMPERATURE RANGE
N-	0° to +70°C
S-	-55° to +125°C
NE-	0° to +70°C
SE-	-55° to +125°C
SA	-40° to +85°C
SU	-25° to +85°C

Table 3 DEVICE TEMPERATURE

PREFIX	DEVICE FAMILY
CA	Linear Industry Standard
DM	Linear Industry Standard
JB	Mil Rel—Jan Qualified—Old Designator
JM	Mil Rel—Jan Qualified—New Designator
LH	Linear Industry Standard
LM	Linear Industry Standard
M	Mil Rel—Jan Processed
MC	Linear Industry Standard
PA	Linear Industry Standard
SD	Linear DMOS
SP	DTL Series
UA	Linear Industry Standard
ULN	Linear Industry Standard

Table 4 FAMILY PREFIX

QUALITY AND RELIABILITY

Quality and reliability are two important measures of a product's merit. Quality is a measure of an integrated circuit's conformance to agreed-upon criteria at a given time, while Reliability is a measure of the circuit's ability to continue to conform over a period of time. The Signetics SUPR II Program has been designed to upgrade the basic product quality through the use of more rigorous screening criteria at the critical process steps. These additional screens constitute the Level A portion of the Program. A burn-in option is available for those users requiring enhanced reliability performance, and this option is designated as Level B.

Quality

The quality of an integrated circuit is appraised by the user based on the ability of the circuit to meet the specified electrical criteria and external visual appearance. The SUPR II Program focuses on supplying to the user a product that has a high probability of meeting the user's needs through the sampling plans defined in MIL-STD-105D and the quality levels (AQL's) stated in Table II. Many of the inspection methods at critical process steps are now based on MIL-STD-883 criteria in order to build, rather than test, quality into the product.

Reliability

System performance over a period of time is the user's measure of an integrated circuit's reliability. The SUPR II Program improves system reliability by building quality into the product via additional manufacturing inspections and the offering of a burn-in screen. In addition to the SUPR II Program, Signetics performs periodic reliability testing via the SURE II/883A Program to assure continuing uniformity and long-term reliability of all product lines. This data base is available upon request as is the ten-year reliability summary, Signetics Product Reliability Report, R-363.

How Do Integrated Circuit Failures Occur?

Results from the Signetics Failure Analysis Lab over a three-year period on product returned from board checkout, system checkout, field usage and accelerated life testing are graphically presented in Figure 1. Under typical system operating conditions, random manufacturing defects, as outlined in Table 1, are the primary cause of true device failure. Also shown in Table 1 are the process controls that have been added via the SUPR II Program to minimize these defects prior to shipment to the customer. The device failure models are categorized as:

Half of the devices analyzed were found to be electrically good. They are attributed to being "false pulls" that occur during normal troubleshooting at the board and system levels.

Devices damaged by electrical over-stress account for 25% of the failures. Typical causes for electrical over-stress are incorrect board insertion, board shorts between device pins, power supply transients, and poor handling techniques.

The remaining 25% were verified to be true failures which occurred as a result of an in-process manufacturing defect or test escape.

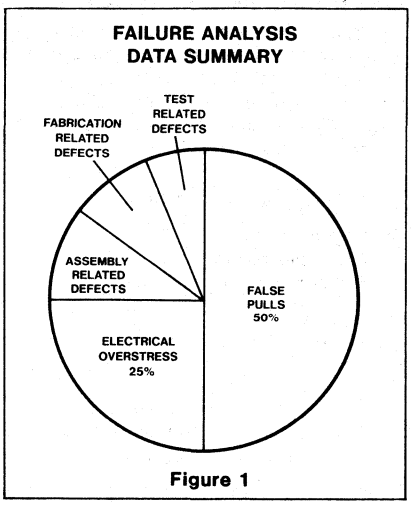


Figure 1

SIGNETICS SUPR II LEVEL A

Improved Quality Benefits

From the user's point of view, improved integrated circuit quality from the supplier means a lower cost of ownership. This cost saving can be effected through the reduction or elimination of involved incoming inspection testing, reduced PC board rework, simplified system checkout, reduced in-line inventories, and less complicated part tracking by Purchasing Management.

The SUPR II Program is Corporate in scope and covers Logic (Standard TTL, Schottky TTL, Low Power Schottky TTL, ECL, 8T Interface), Analog (Industrial, Consumer, Interface), Bipolar Memories (RAM's, ROM's, PROM's), and MOS Memories (RAM's, ROM's, Shift Registers), All package options are also available.

The SUPR II flow is detailed in Figure 5, including the test methods and Quality acceptance levels (Table 2 provides the electrical/mechanical finished product AQL's). Highlights of the flow are visual inspections, thermal shock preconditioning, hermeticity, and burn-in, all based on MIL-STD-883 criteria.

A good example of the savings which can be achieved by purchasing tighter inspection levels is given in Figure 2. Here we are comparing the various levels of inspection (AQL's) available for device functionality and its impact on the number of PC boards which must be reworked during system manufacturing. Using the standard commercial AQL in functionality of 1.0%, at 120 integrated circuit packages per board, typically more than 90% of boards will require rework. At 0.15% AQL, rework is reduced to 25%, and at 0.1%, typically only 12% rework is required.

SIGNETICS SUPR II LEVEL B

Infant Mortality Failures

Failure rates are most severe during the first few months of operating life. This is known as the "infant mortality" phase. A system

FAILURE MECHANISMS	CAUSES	SUPR II CONTROL
Die Fabrication Related	Metalization Oxide Defects Mechanical Scratches Contamination	SEM Monitor Visual Stabilization Bake Burn-In
Assembly Related	Bonding, Wire, Package and Seal Defects	Preseal Visual Thermal Shock Stabilization Bake Hermeticity Hot-Rail Testing
Test Related	Test Escapes	Tightened AQL Guarantees High Temperature Testing

Table 1

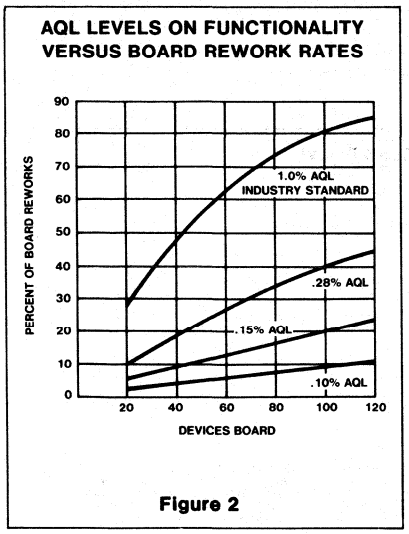


Figure 2

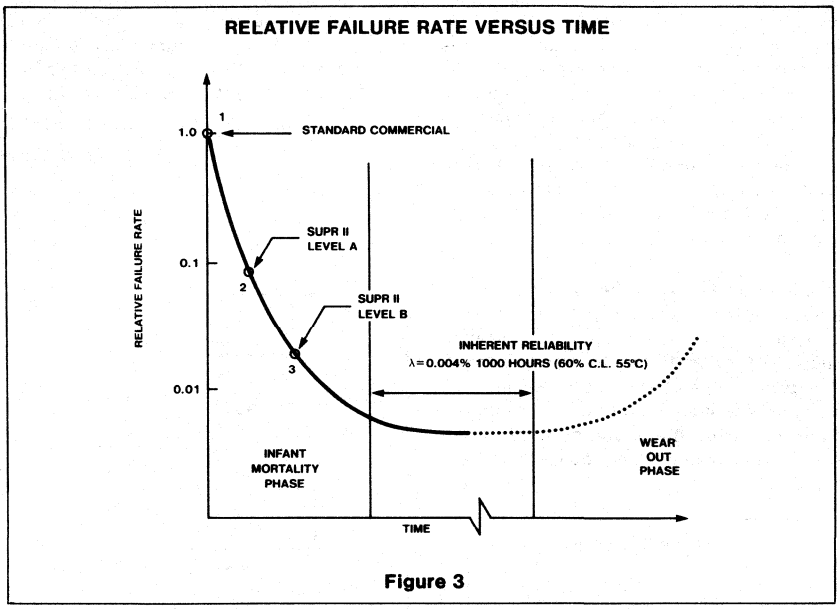


Figure 3

manufacturer has various options to solve problems arising from infant failures. He can ship his system to the end customer and repair field failures as they occur. He can operate the system in-house for this period and repair failures. Or he can purchase devices which have already been preconditioned to eliminate the early failures. Each customer must choose the most cost-effective method for his particular business. A considerable number of the reliabilty defects which cause early failures are eliminated by the manufacturing control and preconditioning steps of SUPR II Level A processing. More persistent defects can be removed by the use of "burn-in" techniques. The "burn-in" processing of SUPR II Level B effectively allows the system manufacturer to ship his equipment at Point 3 on the failure rate curve in Figure 3.

Burn-In Conditions

MIL-STD-883A, Method 1015 describes a number of different conditions for integrated

		ANALOG		BIPOLAR MEMORY		LOGIC		MOS/LSI	
		Plastic	Ceramic Metal Can	Plastic	Ceramic Metal Can	Plastic	Ceramic Metal Can	Plastic	Ceramic Metal Can
HOT OPENS	100°C	0.15%	-	0.15%	-	0.15%	-	0.15%	-
FUNCTIONALITY (NOTE 1)	25°C	0.15	0.15	0.25	0.25	0.10	0.10	0.25	0.25
	HIGH TEMPERATURE	0.25	0.25	-	-	0.10	0.10	0.25	0.25
D.C. PARAMETRIC	25°C	0.25	0.25	0.65	0.65	0.65	0.65	0.65	0.65
	OVER TEMPERATURE	0.65	0.65	0.65	0.65	0.65	0.65	0.65	0.65
A.C. PARAMETRIC	25°C	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0
MECHANICAL	MAJOR	0.25	0.25	0.25	0.25	0.25	0.25	0.25	0.25
	MINOR	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0
SEAL TEST (CERAMIC METAL CAN ONLY)	FINE LEAK 1×10^{-7} cc/s	N/A	1.0	N/A	1.0	N/A	1.0	N/A	1.0
	GROSS LEAK 1×10^{-5} cc/s	N/A	0.65	N/A	0.65	N/A	0.65	N/A	0.65

NOTE

1. To insure AQL levels tighter than 0.65% on D.C. parameters usually requires continual correlation of test equipment between customer and vendor to avoid test interpretation problems. If the objective is to reduce system rework costs, functional operation of a device (does it switch or toggle in the system) is often more critical than the absolute value of a parameter. For this reason SUPR II focuses attention on tightened AQL's on functionality.

For analog devices, D. C. parameters, such as input current and offset voltages, tend to be more critical to system operation than for logic devices. A 0.25% AQL is therefore offered on analog D.C. parameters, with the realization that careful attention must be paid to establishing correlation at the customer's incoming inspection.

Table 2 SUPRA II AQL GUARANTEE

circuit burn-in. For SUPR II Level B, Signetics has selected Condition F. This is the accelerated burn-in method derived from MIL-STD-883A, utilizing a high temperature reversed bias condition. This bias scheme is preferred for infant mortality screening, while operating conditions are generally utilized for internal reliability programs oriented toward generating MTBF data for the system designer.

Integrated Burn-In Flow

Signetics SUPR II Level B burn-in is performed to provide reliability assurance equivalent to a 168-hour/125°C screen. This process has been integrated into the standard manufacturing flow to provide the customer with the most cost effective screen and significantly reduced delivery times.

BURN-IN FLOW

ASSEMBLY

The flow from SEM control through package seal is common to Levels A and B.

⇩

TEST

The pre-burn-in electrical screen is designed to remove assembly rejects and increase equipment efficiency.

⇩

BURN-IN

The 24-hour/155°C accelerated burn-in is well controlled to provide maximum screening effectiveness without damaging good devices.

⇩

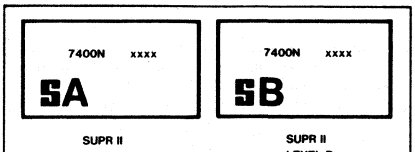
TEST

The post-burn-in electrical is a 100% production DC/function electrical test.

Figure 4

Marking Format

Product processed to the SUPR II manufacturing flow can be identified by an SA for Level A, and an SB for the Level B burn-in option.



SUPR II LEVEL A — SUPR II LEVEL B

NOTE
Marking for Level A in process of being implemented.

Figure 5 shows the generalized process flow for all Signetics integrated circuits purchased to the SUPR II program. Each product group (Analog, Bipolar Memory, Logic, and MOS) may follow slightly different procedures dictated by the specific device characteristics.

SUPR II PROCESS FLOW

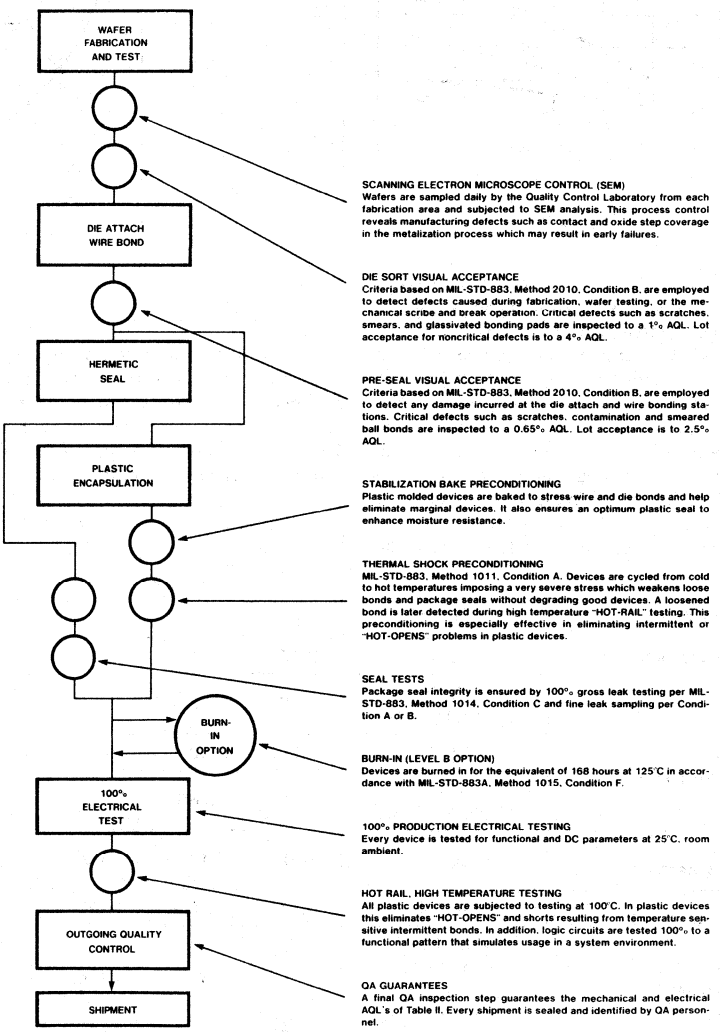


Figure 5

SURE II/883B RELIABILITY PROGRAM

Definition

Signetics is recognized as a manufacturer of reliable integrated circuts. Signetics realized long ago the need for a comprehensive reliability program to provide timely data representative of the entire Signetics product line. Thus the establishment of a Systematic and Uniform Reliability Evaluation program, known as SURE, which provides this data in a manner unique to the industry. Furthermore, this program is provided at no cost to customers.

The SURE Program is a Signetics in-house Qualification Test Program which has been in existence since 1963. The SURE Program is designed to monitor the continuing uniformity of all Signetics products and to demonstrate via periodic qualifications that Signetics products meet or exceed the stringent long-term reliability requirements of their intended applications.

The SURE Program is reviewed and modified annually to incorporate appropriate changes in military microelectronic test programs, products and demonstrated product capabilities, and market requirements. The 1978 SURE II/883B Reliability Program contains minor changes to the 1975 SURE II/883A Program, most significant of which is the inclusion of recent changes in military microelectronic test programs (i.e., inclusion of MIL-SD-883B, Method 5005.4 and MIL-M-38510D). The SURE II/883B Program continues to incorporate additional environmental tests to fulfill the need for special reliability assurance of plastic products.

For more detailed information regarding the SURE II program, refer to Section 11 of the 1979 Signetics Analog Applications Manual.

SECTION I
OPERATIONAL AMPLIFIERS

Section 1—OPERATIONAL AMPLIFIERS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

OPERATIONAL AMPLIFIERS DEFINITIONS

T_A
Ambient temperature range. Range of the surrounding environment of the operating device.

T_J
Junction Temperature. The maximum temperature of the device. 150°C is standard for silicon devices.

T_{STG}
Storage temperature range. Temperature range that the device can be stored in a non-operating condition.

T_{SOLD}
Soldering Temperature. The temperature which can be applied to the lead frame of the device for short periods of time (normally specified for a duration of 10 sec).

Absolute Maximum Rating
Operating safe zones exceeding these limits could cause permanent damage to the device and are not meant to imply that devices can operate at these limits.

Power Dissipation
The power that the device can safely handle at 25°C. The dissipation must be derated as indicated for the individual package type.

Package Type Designation
See full package designations in Appendix.

V_{CC} ($-V_{CC}$)
Supply Voltage. The range of power supply voltage over which the device will operate safely.

Acquisition Time
The time required to acquire a new analog input voltage with an output step of 10V. Note that acquisition time is not just the time required for the output to settle, but also includes the time required for all internal nodes to settle so that the output assumes the proper value when switched to the hold mode.

Aperture Delay Time
The time elapsed from the hold command to the opening of the switch.

Aperture Jitter
Also called "aperture uncertainty time", it's the time variation or uncertainty with which the switch opens, or the time variation in aperature delay.

Aperture Time
The delay required between "hold" command and an input analog transition, so that the transition does not affect the hold output.

Bandwidth
The frequency at which the gain is down 3dB from its dc value. It's measured in sample (track) mode with a small-signal sine wave that doesn't exceed the slew rate limit.

Effective Aperture Delay
The time difference between the hold command and the time at which the input signal is at the held voltage.

Figure Of Merit
The ratio of the available charging current during sample mode to the leakage current during hold mode.

Hold-Mode Droop
The output voltage change per unit of time while in hold. Commonly specified in V/s, μV/μs or other convenient units.

Hold-Mode Feed Through
The percentage of an input sinusoidal signal that is measured at the output of a sample-hold when it's in hold mode.

Hold Settling Time
The time required for the output to settle within 1mV of final value after the "hold" logic command.

Sample-To-Hold Offset Error
The difference in output voltage between the time the switch starts to open, and the time when the output has settled completely. It is caused by charge being transferred to the hold capacitor switch as it opens.

Slew Rate
The fastest rate at which the sample & hold output can change (specified in V/μs).

Hold Step
The voltage step at the output of the sample and hold when switching from sample mode to hold mode with a steady (dc) analog input voltage. Logic swing is 5V.

Dynamic Sampling Error
The error introduced into the held output due to a changing analog input at the time the hold command is given. Error is expressed in mV with a given hold capacitor value and input slew rate. Note that this error term occurs even for long sample times.

Gain Error
The ratio of output voltage swing to input voltage swing in the sample mode expressed as a percent difference.

Threshold
Level shall be defined as that level which causes the switch control to change state.

Average Input Offset Current T^O coeff.
The change in input offset current divided by the change to ambient temperature producing it.

Average Input Offset Voltage T^O coeff.
The change in input offset voltage divided by the change in ambient temperature producing it.

Common Mode Input Resistance
The resistance looking into both inputs, with inputs tied together.

Common Mode Rejection Ratio (CMRR)
The ratio of the change of input offset voltage to the input common mode voltage change producing it.

Full Power Bandwidth
The maximum frequency at which the full sinewave output might be obtained.

Input Bias Current
The average of the two input currents at zero output voltage. In some cases, the input current is measured for either input independently.

OPERATIONAL AMPLIFIERS DEFINITIONS (Cont'd)

Input Capacitance

The capacitance looking into either input terminal with the other grounded.

Input Current

The current into an input terminal.

Input Noise Voltage

The square root of the mean square narrow-band noise voltage referred to the input.

Input Offset Current

The difference in the currents into the two input terminals with the output at zero volts.

Input Offset Voltage

That voltage which must be applied between the input terminals to obtain zero output voltage. The input offset voltage may also be defined for the case where two equal resistances are inserted in series with the input leads.

Input Resistance

The resistance looking into either input terminal with the other grounded.

Input Voltage Range

The range of voltages on the input terminals for which the amplifier operates within specifications. In some cases, the input offset specifications apply over the input voltage range.

Large-Signal Voltage Gain

The ratio of the maximum output voltage swing to the change in input voltage required to drive the output to this voltage.

Output Resistance

The resistance seen looking into the output terminal with the output at null. This parameter is defined only under small signal conditions at frequencies above a few hundred cycles to eliminate the influence of drift and thermal feedback.

Output Short-Circuit Current

The maximum output current available from the amplifier with the output shorted to ground or to either supply.

Output Voltage Swing

The peak output swing, referred to zero, that can be obtained.

Power Consumption

The dc power required to operate the amplifier with the output at zero and with the output at zero and with no load current.

Power Supply Rejection Ratio

The ratio of the change in input offset voltage to the change in supply voltages producing it.

Rise Time

The time required for an output voltage step to change from 10% to 90% of its final value.

Slew Rate

The maximum rate of change of output voltage under large signal condition.

Supply Current

The current required from the power supply to operate the amplifier with no load and the output at zero.

Temperature Stability of Voltage Gain

The maximum variation of the voltage gain over the specified temperature range.

NOTE

Refer to Section 3 of the 1979 Analog Applications Manual for an in depth explanation of Operational Amplifiers and their applications

OPERATIONAL AMPLIFIERS CROSS REFERENCE

DEVICE	MANUFACTURED BY SIGNETICS		GENERAL DESCRIPTION	SIGNETICS REPLACEMENT PART	QRA	
	Yes	No			SUPR II	SURE II
LF Series	X		JFET Input Operational Amplifier			Yes
155/155A	X		JFET Input Operational Amplifier			Yes
156/156A	X		JFET Input Operational Amplifier			Yes
157/157A	X		JFET Input Operational Amplifier			Yes
255/255A	X		JFET Input Operational Amplifier			Yes
355/355A	X		JFET Input Operational Amplifier			Yes
356/356A	X		JFET Input Operational Amplifier			Yes
357/357A	X		JFET Input Operational Amplifier			Yes
LM107	X		General Purpose Operational Amplifier	SE530		Yes
LM207	X		General Purpose Operational Amplifier	SE530		Yes
LM307	X		General Purpose Operational Amplifier	NE530		Yes
MC1456	X		High Performance Operational Amplifier	NE530		Yes
MC1556	X		High Performance Operational Amplifier	SE530		Yes
MC1458	X		General Purpose Dual Operational Amplifier	NE5530		Yes
MC1558	X		General Purpose Dual Operational Amplifier	NE5530		Yes
SA1458	X		General Purpose Dual Operational Amplifier	NE5530		Yes
μA740C	X		FET Input Operational Amplifier	SU536		Yes
μA741/741A	X		General Purpose Operational Amplifier	NE530		Yes
SA741	X		General Purpose Operational Amplifier	SE530		Yes
μA747/747C	X		General Purpose Dual Operational Amplifier	NE5535		Yes
SA747C	X		General Purpose Dual Operational Amplifier	NE5535		Yes
μA748/748C	X		General Purpose Operational Amplifier	SE531		Yes
SA748C	X		General Purpose Operational Amplifier	SE531		Yes

MC1458 DUAL OPERATIONAL AMPLIFIER

COMPETITION	INDUSTRY VALUE	KEY PARAMETER	SIGNETICS AVAILABLE VALUE	SIGNETICS ORIGINATED DEVICES	QR&A		COMMENTS
					SURE II	SUPR II	
MOTOROLA FAIRCHILD RAYTHEON N.S.C. T.I.	0.5	Slew Rate	10 to 60 V/μ sec	NE/SE 5530 NE/SE 5538 NE 5532 NE 5532A NE 5533 NE 5533A	Yes Yes Yes Yes Yes Yes		
	20	Full power out	30 to 300 kHz	NE/SE 5530 NE/SE 5538 NE 5532 NE 5532A NE 5533 NE 5533A	Yes Yes Yes Yes		
	24	Noise	4 nv/√Hz	NE 5532 NE 5532A NE 5533 NE 5533A	Yes Yes		
	5	Offset voltage	2 mv	NE 5532 NE 5532A NE 5533 NE 5533A	Yes Yes		
	200	Bias current	1 to 60 na	NE/SE 5530 NE/SE 5538	Yes Yes		
	1	Gain bandwidth	1.5 ↓ 15 MHz	NE/SE 5530 NE/SE 5538 NE 5533 NE 5533A NE 5532 NE 5532A	Yes Yes Yes Yes		
	10,000	Maximum loading	600 OHM	NE 5533 NE 5533A NE 5532 NE 5532A	Yes Yes		

SIGNETICS REPLACEMENT STANDARDS

μa741 SINGLE OPERATIONAL AMPLIFIER

COMPETITION	INDUSTRY VALUE	KEY PARAMETER	SIGNETICS AVAILABLE VALUE	SIGNETICS ORIGINATED DEVICES	QR&A SURE II	QR&A SUPR II	COMMENTS
MOTOROLA FAIRCHILD RAYTHEON N.S.C. T.I.	0.5	Slew rate	10 to 800 V/μ sec	NE/SE 530 NE/SE 538 NE/SE 5534 NE/SE 5534A NE 5539*	Yes Yes Yes Yes	 Yes Yes	*Not pin for pin replacement. See new products
	20	Full power out	300 to 350,000 kHz	NE/SE 530 NE/SE 538 NE/SE 5534 NE/SE 5534A 5539*	Yes Yes Yes Yes	 Yes Yes	*Not pin for pin replacement. See new products
	24	Noise	4 nv/√Hz	NE/SE 5534 NE/SE 5534A	Yes Yes	Yes Yes	
	5	Offset voltage	2 mv	NE/SE 5534 NE/SE 5534A	Yes Yes	Yes Yes	
	200	Bias current	1 to 60 na	NE/SE 530 NE/SE 538	Yes Yes		
	1	Gain bandwidth	1.5 ↓ 2000 MHz	NE/SE 530 NE/SE 538 NE/SE 5534 NE/SE 5534A 5539*	Yes Yes Yes Yes	 Yes Yes	*Not pin for pin replacement. See new products
	10,000	Maximum loading	600 OHM	NE/SE 5534 NE/SE 5534A	Yes Yes	Yes Yes	

DESCRIPTION

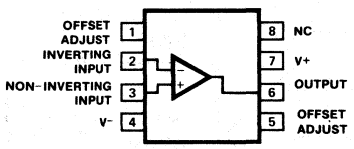
The 530/5530 are new generation operational amplifiers featuring high slew rates combined with improved input characteristics. Internally compensated, the SE530/5530 guarantee slew rates of 25V/μs with 2mV maximum offset voltage. Industry standard pinout and internal compensation allow the user to upgrade system performance by directly replacing general purpose amplifiers such as the 741, 747, 1458, 4558 and LF356 types.

FEATURES

- **Gain bandwidth product—3MHz**
- **35V/μs slew rate (Gain = -1)**
- **Internal frequency compensation**
- **Low input offset voltage 2mV max**
- **Low input bias current-60nA max**
- **Short circuit protection**
- **Offset null capability**
- **Large common mode and differential voltage ranges**

PIN CONFIGURATIONS

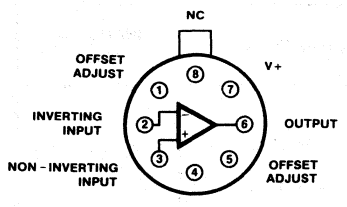
FE,N PACKAGE



ORDER PART NO.

SE530FE, SE530N
NE530FE, NE530N

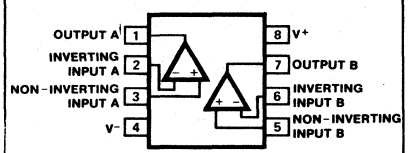
H PACKAGE



ORDER PART NO.

SE530H NE530H

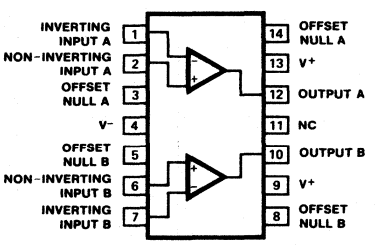
N PACKAGE



ORDER PART NO.

SE5530N
NE5530N

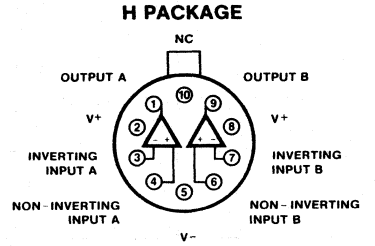
F , N-14 PACKAGE



ORDER PART NO.

SE5530F, SE5530N-14
NE5530F, NE5530N-14

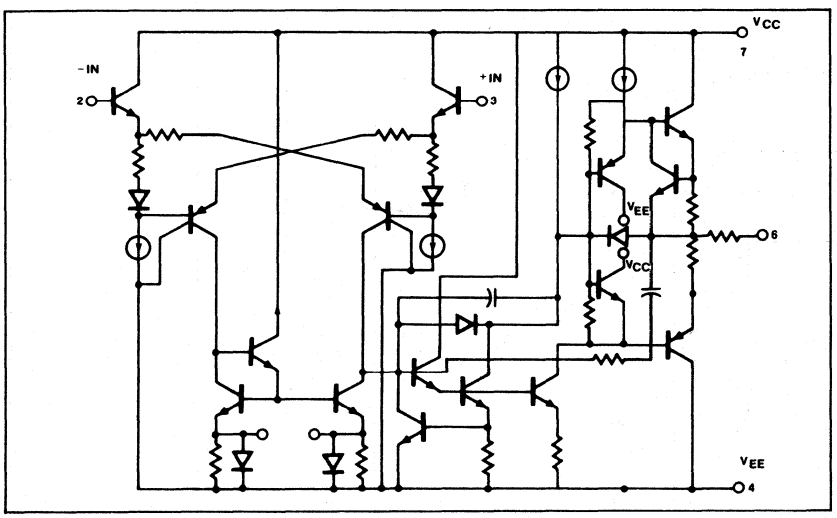
H PACKAGE



ORDER PART NO.

SE5530H
NE5530H

EQUIVALENT SCHEMATIC EACH AMPLIFIER



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE530/5530	±22	V
NE530/5530	±18	V
Internal power dissipation[1]		
N Package	500	mW
K/T Package	800	mW
FE, F Package	1000	mW
Differential input voltage	±30	V
Input voltage[2]	±15	V
Operating temperature range		
SE530/5530	-55 to +125	°C
NE530/5530	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead temperature range (Solder, 60sec)	300	°C
Output short circuit[3]	Indefinite	

DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_{CC} = \pm 15V$ unless otherwise specified.[1]

PARAMETER	TEST CONDITIONS	SE530/5530			NE530/5530			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input offset voltage	$R_S \leq 10k\Omega$ Over temperature		0.7	2.0 3.0		2.0	5.0 6.0	mV mV
Temperature coefficient of input offset voltage			3	15		6		$\mu V/°C$
Input offset current	 Over temperature		5	10 20		15	40 80	nA nA
Input bias current	 Over temperature		45	60 100		65	150 200	nA nA
Input resistance		3	10		1	6		MΩ
Input voltage range		±12	±13		±12	±13		V
Large signal voltage gain	$R_L \geq 2k\Omega$, $V_0 = \pm 10V$ Over temperature	50 25	200		50 25	200		V/mV V/mV
Output voltage swing	$R_L \geq 10k\Omega$ $R_L \geq 2k\Omega$	±12 ±10	±14 ±13		±12 ±10	±14 ±13		V V V
Output short circuit current			25			25		mA
Output resistance			100			100		Ω
Supply current	Each amplifier Over temperature		2.0 2.2	3.0 3.6		2.0 2.2	3.0	mA mA
Common mode rejection ratio	$R_S \leq 10k\Omega$ Over temperature	70	90		70	90		dB
Power supply rejection ratio	$R_S \leq 10k\Omega$ Over temperature		30	150		30	150	$\mu V/V$

AC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_{CC} = \pm 15V$ unless otherwise specified.

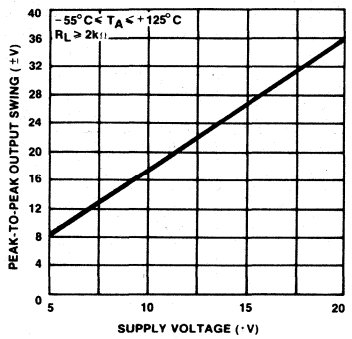
PARAMETER	TEST CONDITIONS	SE530/5530			NE530/5530			UNIT
		Min	Typ	Max	Min	Typ	Max	
Transient response								
Small signal rise time			.06			.06		μs
Small signal overshoot			13			13		%
Settling time	TO 0.1% (10V step)		0.9			0.9		μs
Slew rate	±15V supply, $V_0 = \pm 10V$, $R_L \geq 2k\Omega$							
Unity gain inverting		25	35		20	35		V/μs
Unity gain non-inverting		18	25		12	25		V/μs
Power bandwidth	5% THD, $V_0 = \pm 10V$, $R_L \geq 2k\Omega$	360	500		280	500		kHz
Small signal bandwidth	Open loop		3			3		MHz
Channel separation			120			120		dB

NOTE

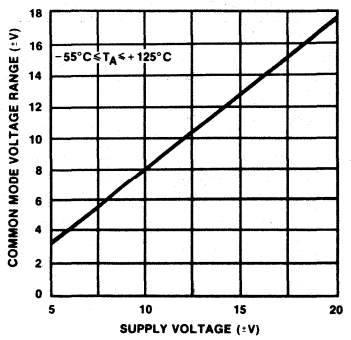
1. Operating temperature range for the SE530/5530 is -55°C to +125°C.
   Operating temperature range for the NE530/5530 is 0°C to +70°C.

TYPICAL PERFORMANCE CHARACTERISTICS

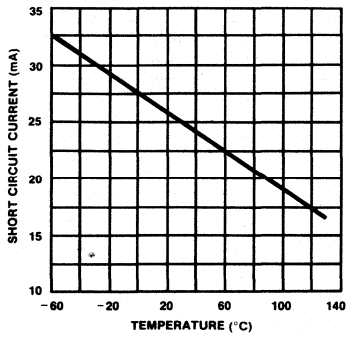
OUTPUT VOLTAGE SWING AS A FUNCTION OF SUPPLY VOLTAGE



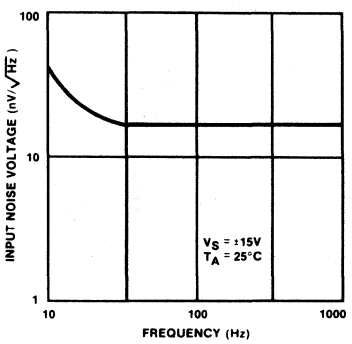
INPUT COMMON MODE VOLTAGE RANGE AS A FUNCTION OF SUPPLY VOLTAGE



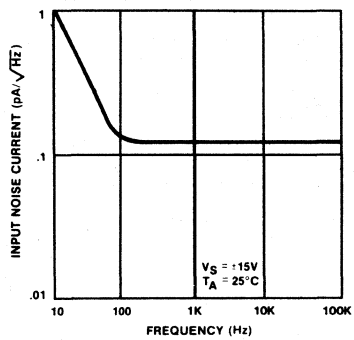
OUTPUT SHORT-CIRCUIT CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



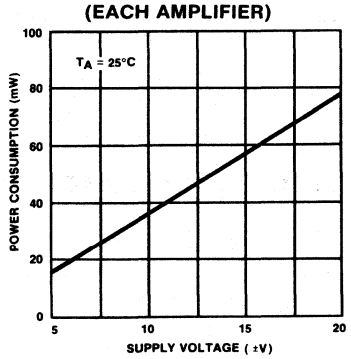
INPUT NOISE VOLTAGE AS A FUNCTION OF FREQUENCY



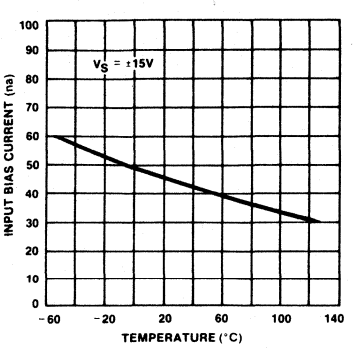
INPUT NOISE CURRENT AS A FUNCTION OF FREQUENCY



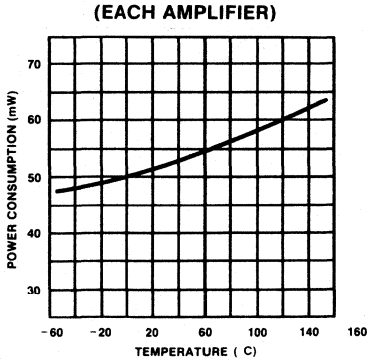
POWER CONSUMPTION AS A FUNCTION OF SUPPLY VOLTAGE (EACH AMPLIFIER)



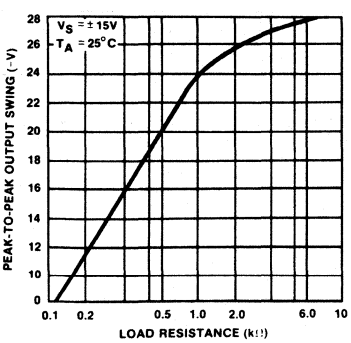
INPUT BIAS CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



POWER CONSUMPTION AS A FUNCTION OF AMBIENT TEMPERATURE (EACH AMPLIFIER)

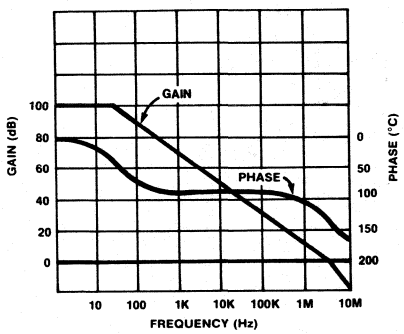


OUTPUT VOLTAGE SWING AS A FUNCTION OF LOAD RESISTANCE

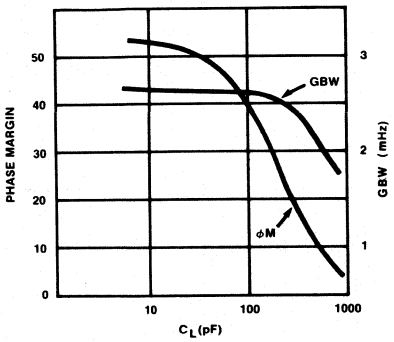


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

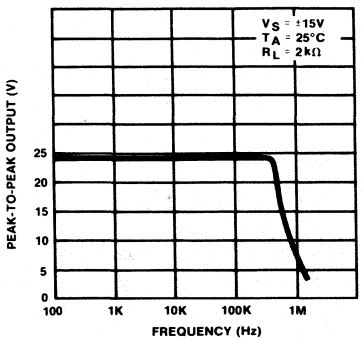
NE530 OPEN-LOOP GAIN AND PHASE vs FREQUENCY



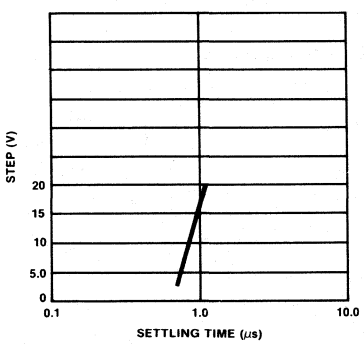
GAIN-BANDWIDTH PRODUCT AND PHASE MARGIN vs LOAD CAPACITANCE



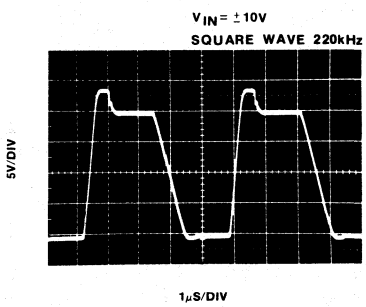
POWER BANDWIDTH



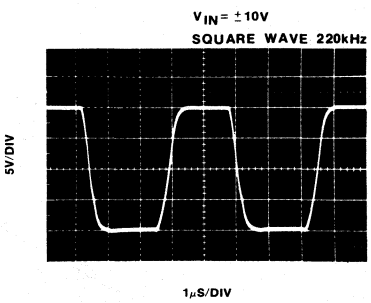
INPUT VOLTAGE STEP vs SETTLING TIME TO 10mV



SLEW RATE—VOLTAGE FOLLOWER

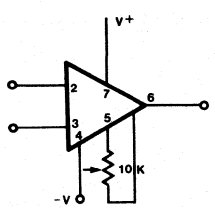


SLEW RATE (-1 AMPLIFIER)



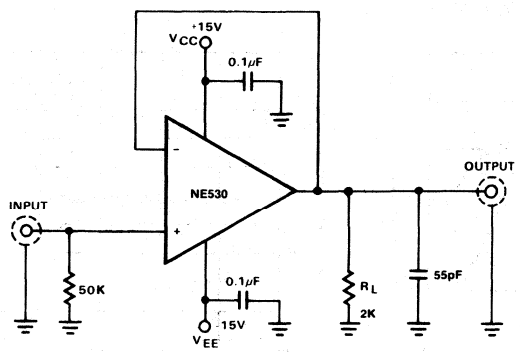
TYPICAL CIRCUIT CONNECTION

OFFSET ADJUST CIRCUIT



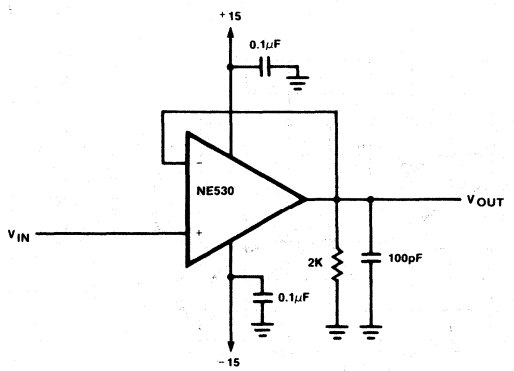
TEST LOAD CIRCUITS

SMALL SIGNAL TRANSIENT RESPONSE

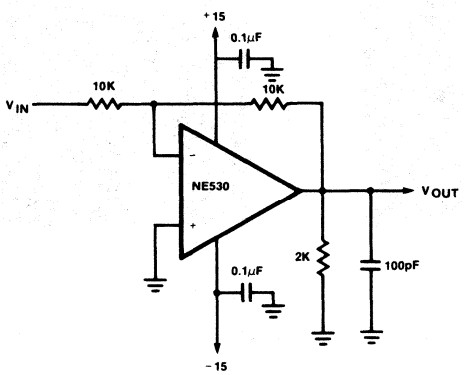


Pins not shown are not connected.
All resistor values are typical and in ohms.

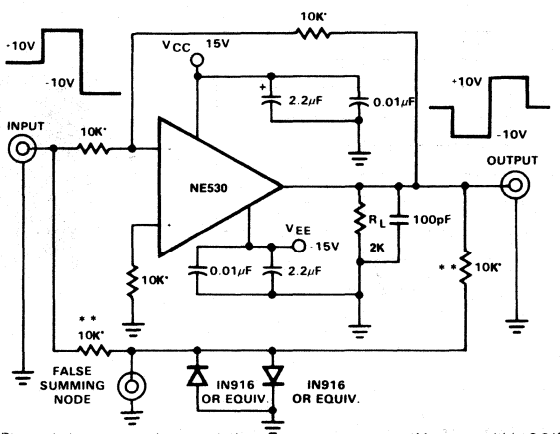
SLEW RATE—VOLTAGE FOLLOWER



SLEW RATE—INVERTING AMPLIFIER



SLEW RATE AND SETTLING TIME

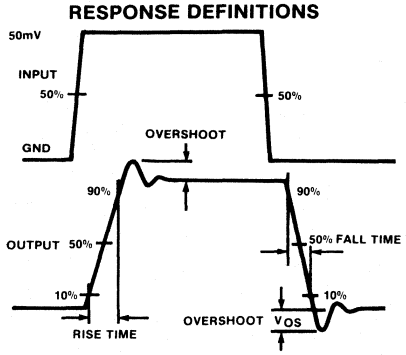


Pins not shown are not connected.
All resistor values are typical and in ohms.

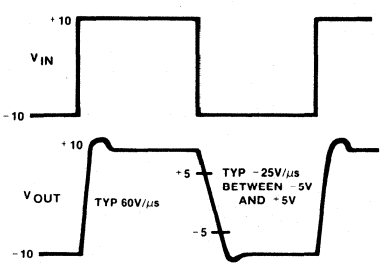
*Match to within 0.01%.
**Open for slew rate.

VOLTAGE WAVEFORMS

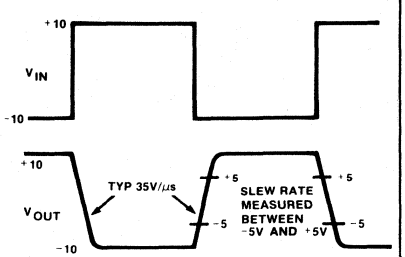
SMALL SIGNAL TRANSIENT RESPONSE DEFINITIONS



SLEW RATE—VOLTAGE FOLLOWER



SLEW RATE—INVERTING AMPLIFIER



HIGH SLEW RATE OPERATIONAL AMPLIFIER — NE/SE531

NE/SE531-N,H

DESCRIPTION

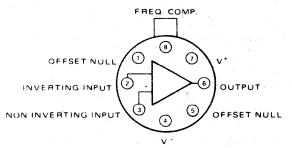
The 531 is a fast slewing high performance operational amplifier which retains dc performance equal to the best general purpose types while providing far superior large signal ac performance. A unique input stage design allows the amplifier to have a large signal response nearly identical to its small signal response. The amplifier is compensated for truly negligible overshoot with a single capacitor. In applications where fast settling and superior large signal bandwidths are required, the amplifier out performs conventional designs which have much better small signal response. Also, because the small signal response is not extended, no special precautions need be taken with circuit board layout to achieve stability. The high gain, simple compensation and excellent stability of this amplifier allow its use in a wide variety of instrumentation applications.

FEATURES

- **35V/μsec slew rate at unity gain**
- **Pin for pin replacement for μA709, μA748 or LM101**
- **Compensated with a single capacitor**
- **Same low drift offset null circuitry as μA741**
- **Small signal bandwidth 1MHz**
- **Large signal bandwidth 500KHz**
- **True op amp dc characteristics make the 531 the ideal answer to all slew rate limited operational amplifier applications.**

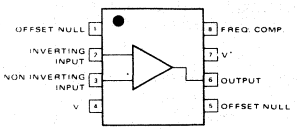
PIN CONFIGURATIONS

H PACKAGE
(Top View)



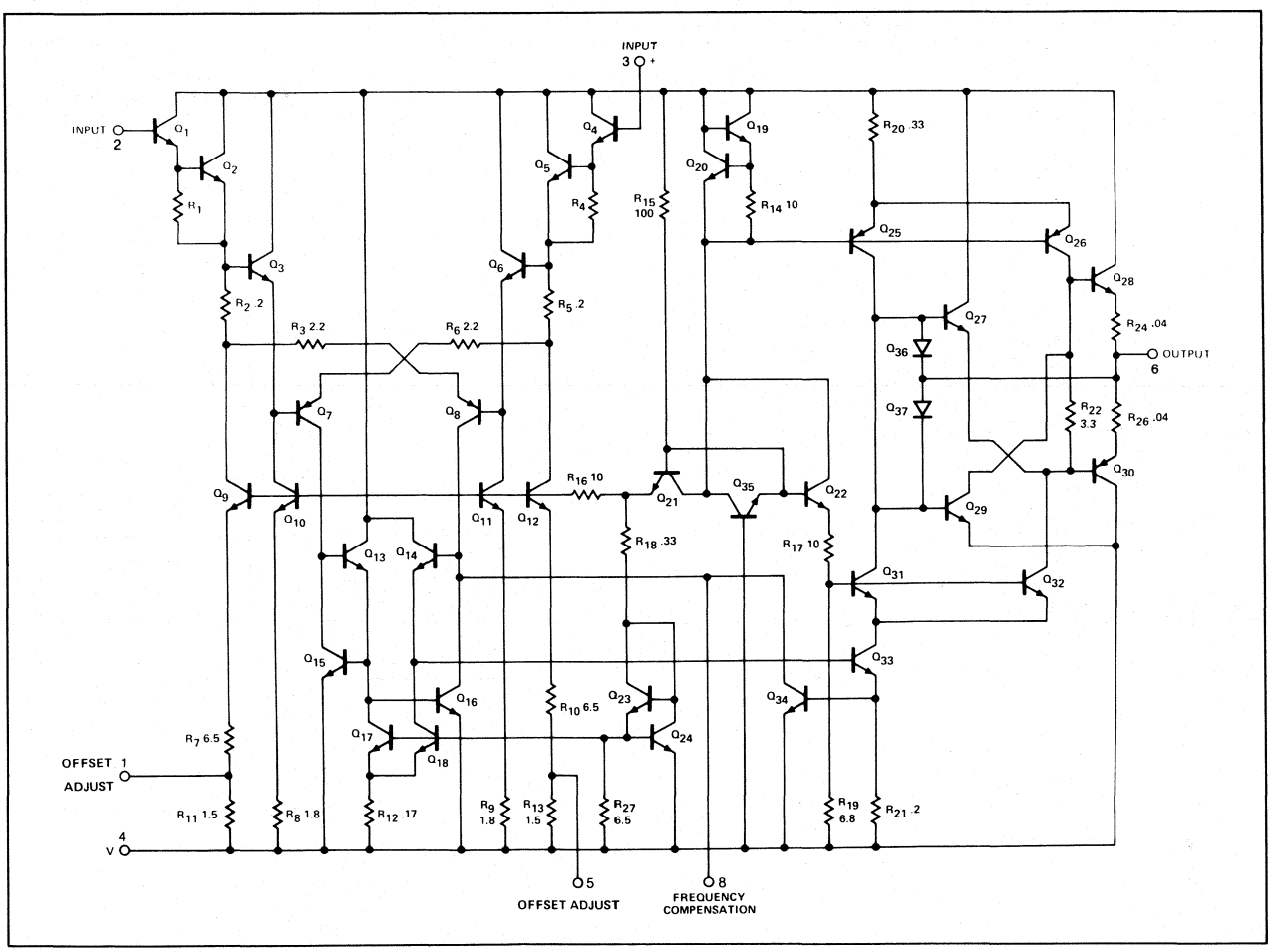
ORDER PART NO.
SE531T/NE531T

N PACKAGE



ORDER PART NO.
NE531N

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	±22	V
Internal power dissipation[1]	300	mW
Differential input voltage	±15	V
Common mode input voltage[2]	±15	V
Voltage between offset null and V-	±0.5	V
Operating temperature range		
NE531	0 to +70	°C
SE531	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60 sec)	300	°C
Output short circuit duration[3]	indefinite	

NOTES

1. Rating applies for case temperature to 125°C, derate linearly at 6.5mW/°C for ambient temperatures above +75°C.
2. For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.
3. Short circuit may be to ground or either supply. Rating applies to +125°C case temperature or to +75°C ambient temperature.

DC ELECTRICAL CHARACTERISTICS $V_S = \pm 15V$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SE531[1]			NE531			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OS}	Offset voltage	$R_S \leq 10k\Omega$, $T_A = 25°C$		2.0	5.0		2.0	6.0	mV
		$R_S \leq 10k\Omega$, over temp			6.0			7.5	mV
I_{OS}	Offset current	$T_A = 25°C$		30	200		50	200	nA
		T_A = HIGH			200			200	nA
		T_A = LOW			500			300	nA
I_{BIAS}	Input current	$T_A = 25°C$		300	500		400	1500	nA
		T_A = HIGH			500			1500	nA
		T_A = LOW			1500			2000	nA
V_{CM}	Common mode voltage range	$T_A = 25°C$	±10			±10			V
CMRR	Common mode rejection ratio	$T_A = 25°C$, $R_S \leq 10k\Omega$				70	100		dB
		Over temp $R_S \leq 10k\Omega$	70	90					dB
R_{IN}	Input resistance	$T_A = 25°C$		20			20		MΩ
V_{OUT}	Output voltage swing	$R_L \geq 10k\Omega$, over temp	±10	±13		±10	±13		V
I_{CC}	Supply current	$T_A = 25°C$			7.0			10	mA
		T_{MAX}			7.0			10	mA
P_D	Power consumption	$T_A = 25°C$			210			300	mW
P_{SRR}	Power supply rejection ratio	$R_S \leq 10k\Omega$, $T_A = 25°C$					10	150	μV/V
		$R_S \leq 10k\Omega$, over temp		10	150				μV/V
R_{OUT}	Output resistance	$T_A = 25°C$		75			75		Ω
A_{VOL}	Large signal voltage gain	$T_A = 25°C$, $R_L \geq 10k\Omega$, $V_{OUT} = \pm 10V$	50	100		20	60		V/mV
		$R_L \geq 10k\Omega$, $V_{OUT} = \pm 10V$, over temp	25			15			V/mV

NOTE

1. Temperature range:
   SE531 $-55°C \leq T_A \leq 125°C$
   NE531 $0°C \leq T_A \leq 70°C$

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $V_S = \pm 15V$ unless otherwise specified.

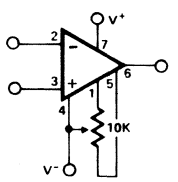
PARAMETER	TEST CONDITIONS	NE531			SE531			UNIT
		Min	Typ	Max	Min	Typ	Max	
Full power bandwidth			500			500		kHz
Settling time (1%) (.01%)	Av = +1, V_{IN} = ±10V		1.5 2.5			1.5 2.5		μs μs
Large signal overshoot Small signal overshoot	Av = +1, V_{IN} = ±10V Av = +1, V_{IN} = 400mV		2 5			2 5		% %
Small signal risetime	Av = +1, V_{IN} = 400mV		300			300		ns
Slew rate	A_V = 100 A_V = 10 Av = 1 (noninverting) Av = 1 (inverting)		35 35 30 35		 20 25	35 35 30 35		V/μs V/μs V/μs V/μs

NOTE

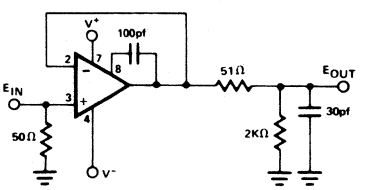
1. All AC testing is performed in the transient response test circuit.

TEST LOAD CIRCUITS

OFFSET NULL CIRCUIT

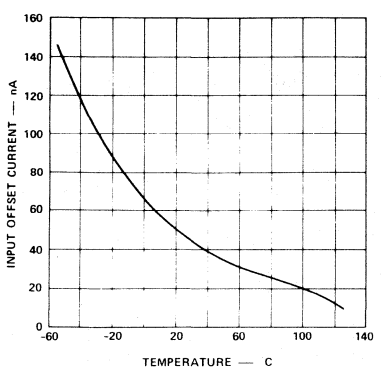


TRANSIENT RESPONSE CIRCUIT

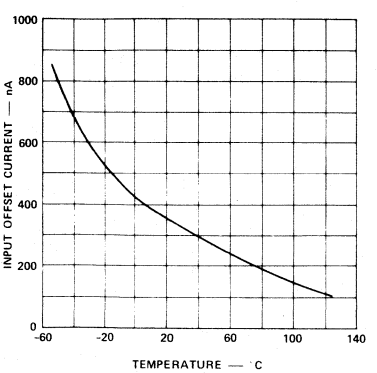


TYPICAL PERFORMANCE CHARACTERISTICS ($V_S = \pm 15V$, $T_A = +25°C$, unless otherwise specified.)

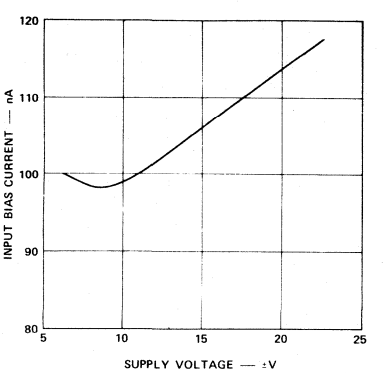
INPUT OFFSET CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



INPUT BIAS CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE

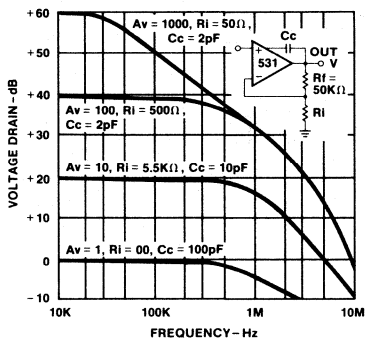


INPUT BIAS CURRENT AS A FUNCTION OF SUPPLY VOLTAGE

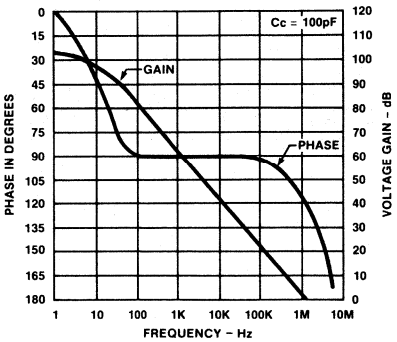


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

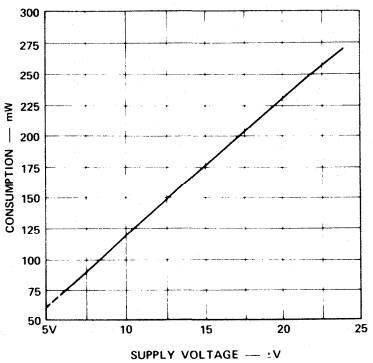
CLOSED LOOP NON-INVERTING VOLTAGE GAIN AS A FUNCTION OF FREQUENCY



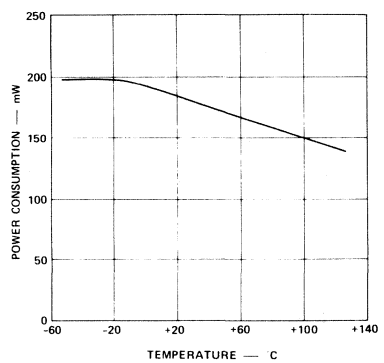
OPEN LOOP PHASE RESPONSE AND VOLTAGE GAIN AS A FUNCTION OF FREQUENCY



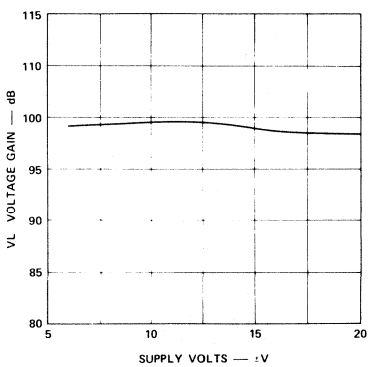
POWER CONSUMPTION AS A FUNCTION OF SUPPLY VOLTAGE



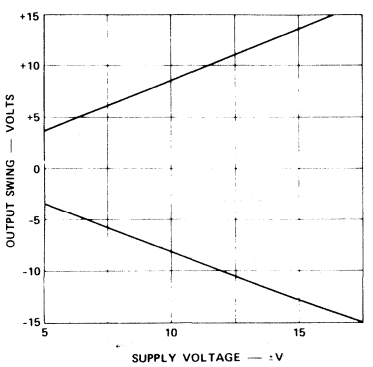
POWER CONSUMPTION AS A FUNCTION OF AMBIENT TEMPERATURE



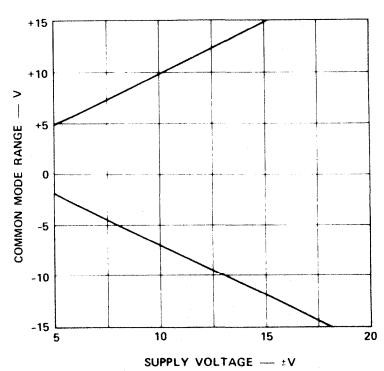
OPEN LOOP VOLTAGE GAIN AS A FUNCTION OF SUPPLY VOLTAGE



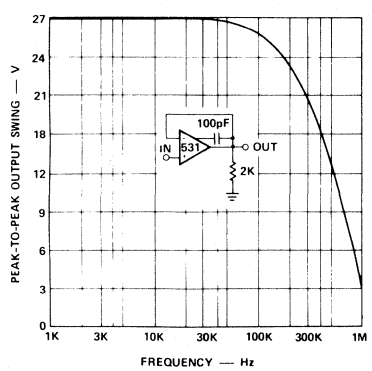
OUTPUT VOLTAGE SWING AS A FUNCTION OF SUPPLY VOLTAGE



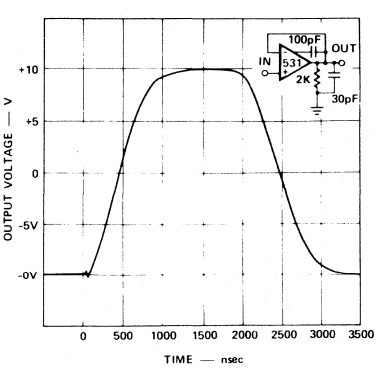
INPUT VOLTAGE RANGE AS A FUNCTION OF SUPPLY VOLTAGE



OUTPUT VOLTAGE SWING AS A FUNCTION OF FREQUENCY

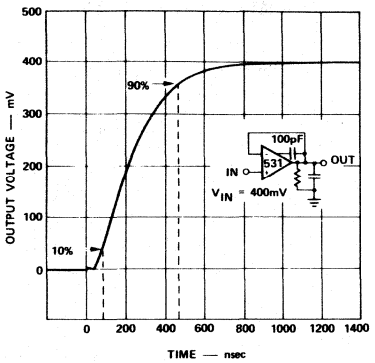


VOLTAGE FOLLOWER LARGE SIGNAL RESPONSE

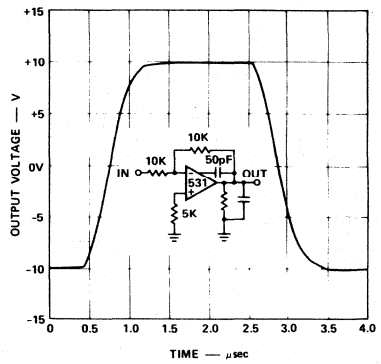


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

VOLTAGE FOLLOWER TRANSIENT RESPONSE

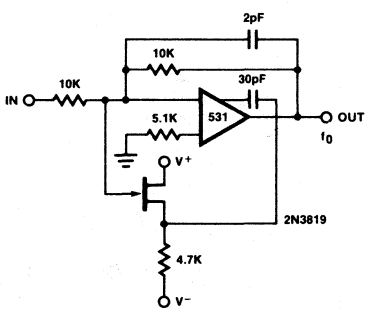


UNITY GAIN INVERTING AMPLIFIER LARGE SIGNAL RESPONSE

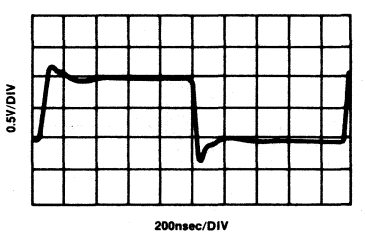


TYPICAL APPLICATIONS

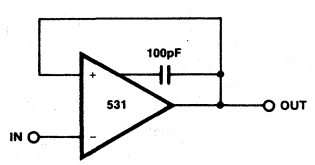
HIGH SPEED INVERTER (10MHz BANDWIDTH)



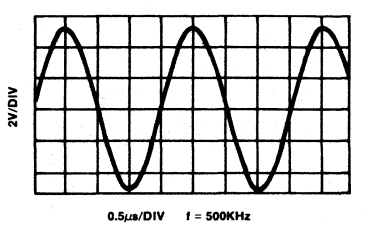
PULSE RESPONSE HIGH SPEED INVERTER



FAST SETTLING VOLTAGE FOLLOWER

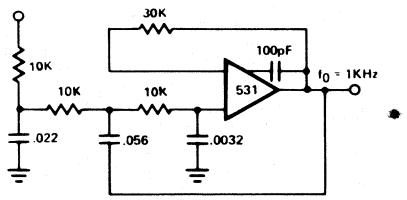


LARGE SIGNAL RESPONSE VOLTAGE FOLLOWER

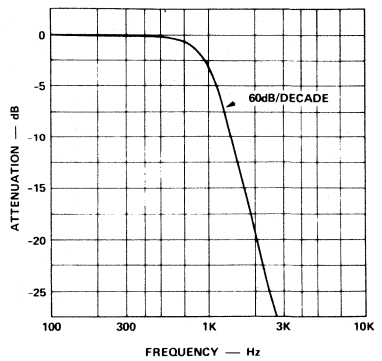


TYPICAL APPLICATIONS (Cont'd)

POLE ACTIVE LOW PASS FILTER BUTTERWORTH MAXIMALLY FLAT RESPONSE*



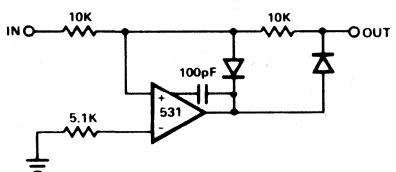
RESPONSE OF 3-POLE ACTIVE BUTTERWORTH MAXIMALLY FLAT FILTER



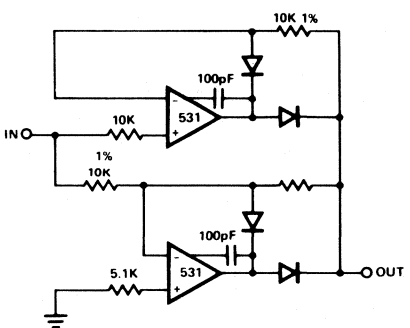
*Reference—EDN Dec. 15, 1970
Simplify 3-Pole Active Filter Design
A. Paul Brokow

PRECISION RECTIFIERS

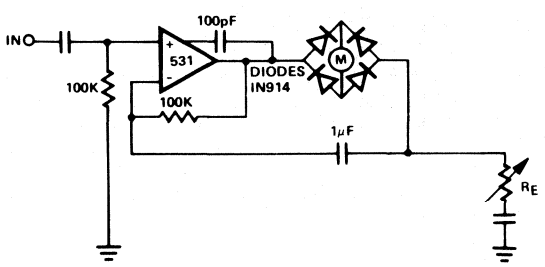
(a) HALF WAVE



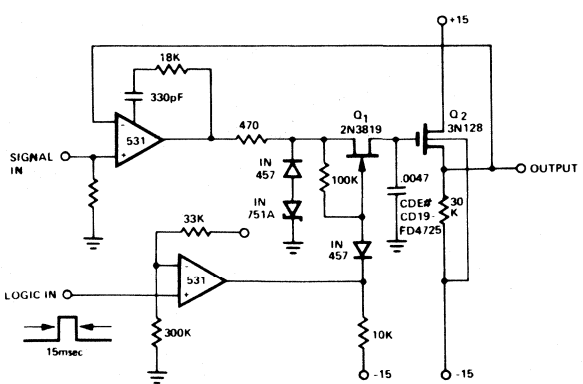
(b) FULL WAVE



AC MILLIVOLTMETER



SAMPLE AND HOLD



NE/SE532
LM158/258/358/N, H

DESCRIPTION

The 532/358 consists of two independent, high gain, internally frequency compensated operational amplifiers designed specifically to operate from a single power supply over a wide range of voltages. Operation from dual power supplies is also possible and the low power supply current drain is independent of the magnitude of the power supply voltage.

FEATURES

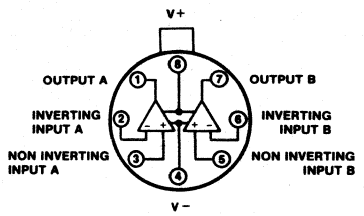
- **Internally frequency compensated for unity gain**
- **Large dc voltage gain—(100dB)**
- **Wide bandwidth (unity gain)—1MHz (temperature compensated)**
- **Wide power supply range**
  single supply—(3Vdc to 30Vdc)
  or dual supplies—(±1.5Vdc to ±15Vdc)
- **Very low supply current drain (400μA)—essentially independent of supply voltage (1mW/op amp at +5Vdc)**
- **Low input biasing current—(45nA dc temperature compensated)**
- **Low input offset voltage—(2mVdc) and offset current—(5nA dc)**
- **Differential input voltage range equal to the power supply voltage**
- **Large output voltage—(0Vdc to V+—-1.5Vdc swing)**
- **SE532 Mil std 883A,B,C available**

UNIQUE FEATURES

In the linear mode the input common-mode voltage range includes ground and the output voltage can also swing to ground, even though operated from only a single power supply voltage. The unity gain cross frequency is temperature compensated. The input bias current is also temperature compensated.

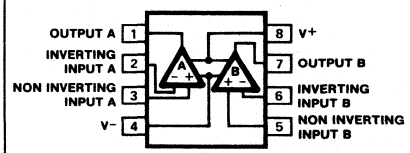
PIN CONFIGURATIONS

H PACKAGE
(Top View)



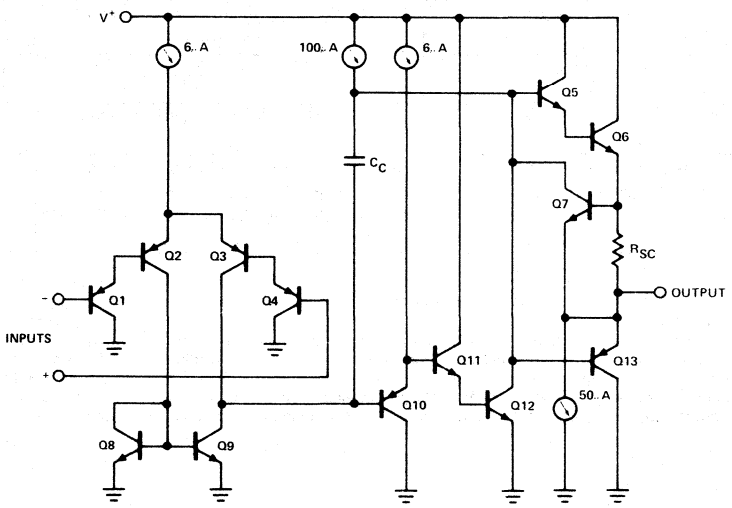
ORDER PART NO.
LM158/SE532H LM358/NE532H

N PACKAGE
(Top View)



ORDER PART NO.
LM158/SE532N LM358/NE532N

EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage, V+	32 or ±16	Vdc
Differential input voltage	32	Vdc
Input voltage	-0.3 to +32	Vdc
Power dissipation		
T package	680	mW
N package	625	mW
Output short-circuit to GND		
V+ < 15 Vdc and T_A = 25°C	Continuous	
Operating temperature range		
NE532/LM358	0 to +70	°C
LM258	-25 to +85	°C
SE532/LM158	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 10sec)	300	°C

NE/SE532
LM158/258/358/N,H

DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V+ = +5V unless otherwise specified.

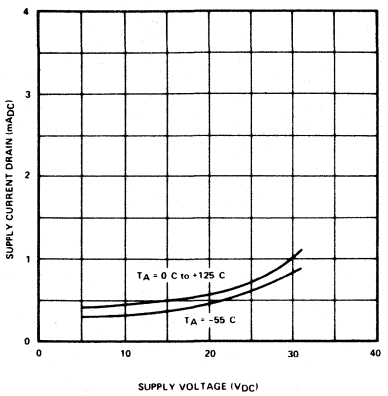
PARAMETER	TEST CONDITIONS	SE532, LM158/258			NE532/LM358			UNIT
		Min	Typ	Max	Min	Typ	Max	
V_{OS} Offset voltage[1]	$R_S \leq 0\Omega$		±2	±5		±2	±7	mV
	$R_S \leq 10k\Omega$, over temp.			±7			±9	mV
V_{OS} Drift	$R_S = 0\Omega$, over temp.		7			7		μV/°C
I_{OS} Offset current	$I_{IN}(+)$ or $I_{IN}(-)$		±3	±30		+5	±50	nA
I_{OS} Offset current	Over temp.			±100			±150	nA
I_{OS} Drift	Over temp.		10			10		pA/°C
I_{BIAS} Input current[2]	$I_{IN}(+)$ or $I_{IN}(-)$		45	150		45	250	nA
	Over temp., $I_{IN}(+)$ or $I_{IN}(-)$		40	300		40	500	nA
V_{CM} Common mode voltage range[3]	V+ = 30V	0		V+–1.5	0		V+–1.5	V
	Over temp., V+ = 30V			V+–2.0			V+–2.0	V
C_{MRR} Common mode rejection ratio	$R_S \leq 10k\Omega$	70	85		65	70		dB
V_{OUT} Output voltage swing (V_{OH})	$R_L \geq 2k\Omega$, V+ = 30V	26			26			V
	$R_L \geq 10k\Omega$, V+ = 30V	27	28		27	28		V
V_{OUT} Output voltage swing (V_{OL})	$R_L \leq 10k\Omega$, over temp.		5	20		5	20	mV
I_{CC} Supply current	$R_L = \infty$ on all amplifiers, over temp		0.5	1.2		0.5	1.2	mA
A_{VOL} Large signal voltage Gain	$R_L \geq 2k\Omega$, $V_{OUT} \pm 10V$, $V_S = \pm 15V$	50	100		25	100		V/mV
	Over temp.	25			15			V/mV
P_{SRR} Supply voltage rejection ratio	$R_S \leq 0\Omega$	65	100		65	100		dB
Amplifier-to-amplifier coupling[4]	f = 1kHz to 20kHz (input referred)		–120			–120		dB
Output current source	$V_{IN}+ = 1Vdc$, $V_{IN}- = 0Vdc$, V+ = 15Vdc	20	40		20	40		mA
Output current sink	$V_{IN}- = 1Vdc$, $V_{IN} = 0Vdc$, V+ = 15Vdc	10	20		10	20		mA
	$V_{IN}- = 1Vdc$, $V_{IN} = 0Vdc$, $V_{OUT} = 200mVdc$	12	50		12	50		μA
I_{SC}[5]			40	60		40	60	mA

NOTES

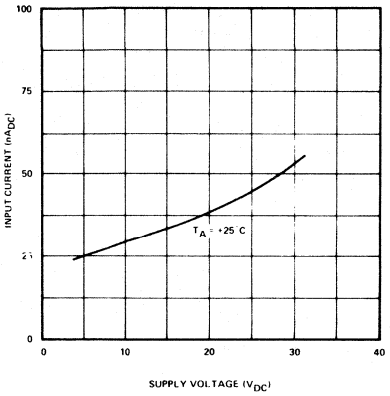
1. $V_O \cong 1.4V$, $R_S = 0\Omega$ with V+ from 5V to 30V; and over the full input common-mode range (9V to V+ –1.5V).
2. The direction of the input current is out of the IC due to the pnp input stage. This current is essentially contant, independent of the state of the output so no loading change exists on the input lines.
3. The input common-mode voltage or either input signal voltage should not be allowed to go negative by more than 0.3V. The upper end of the common-mode voltage range is V+ –1.5V, but either or both inputs can go to +32V without damage.
4. Due to proximity of external components, insure that coupling is not originating via stray capacitance between these external parts. This typically can be detected as this type of capacitive coupling increases at higher frequencies.
5. Short circuits from the output to V+ can cause excessive heating and eventual destruction. The maximum output current is approximately 40mA independent of the magnitude of V+. At values of supply voltage in excess of +15Vdc, continuous short-circuits can exceed the power dissipation ratings and cause eventual destruction.

TYPICAL PERFORMANCE CHARACTERISTICS

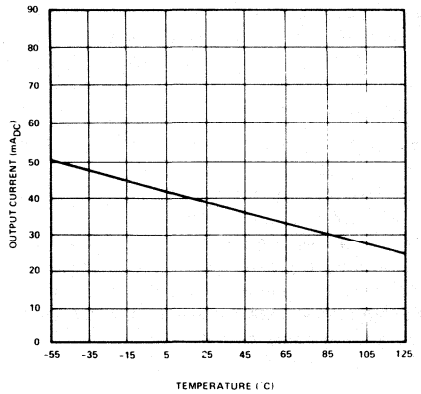
SUPPLY CURRENT



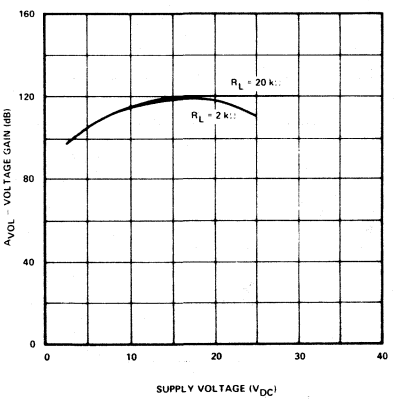
INPUT CURRENT



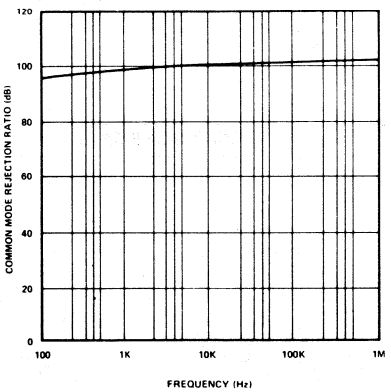
CURRENT LIMITING



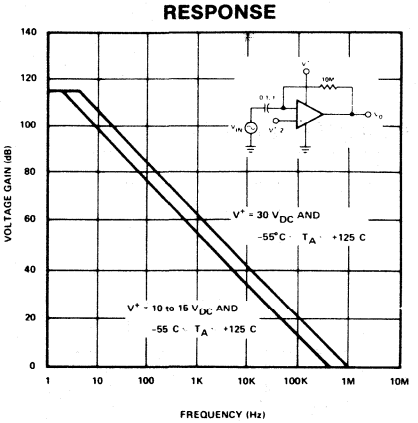
VOLTAGE GAIN



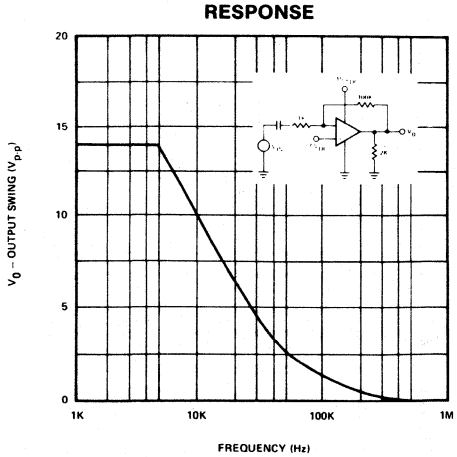
COMMON-MODE REJECTION RATIO



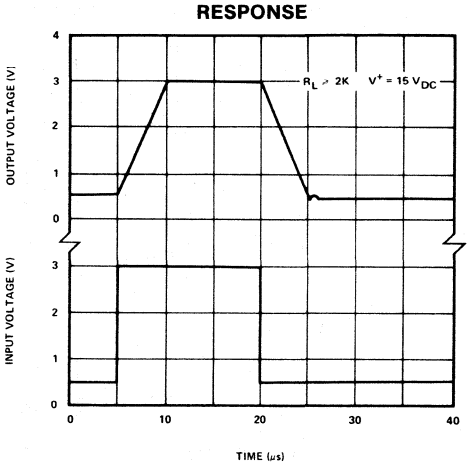
OPEN LOOP FREQUENCY RESPONSE



LARGE SIGNAL FREQUENCY RESPONSE



VOLTAGE FOLLOWER PULSE RESPONSE



NE5532/5532A-FE,H,N

DESCRIPTION

The NE5532 is a dual high-performance low noise operational amplifier. Compared to most of the standard operational amplifiers, such as the 1458, it shows better noise performance, improved output drive capability and considerably higher small-signal and power bandwidths.

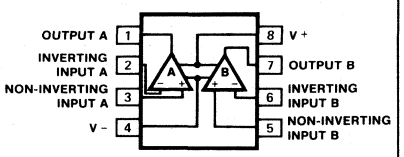
This makes the device especially suitable for application in high quality and professional audio equipment, instrumentation and control circuits, and telephone channel amplifiers. The op amp is internally compensated for gains equal to one. If very low noise is of prime importance, it is recommended that the NE5532A version be used which has guaranteed noise specifications.

FEATURES

- **Small-signal bandwidth: 10MHz**
- **Output drive capability: 600Ω, 10V (rms)**
- **Input noise voltage: 5nV/√Hz**
- **DC voltage gain: 50000**
- **AC voltage gain: 2200 at 10kHz**
- **Power bandwidth: 140kHz**
- **Slew-rate: 9V/μs**
- **Large supply voltage range: ±3 to ±20V**

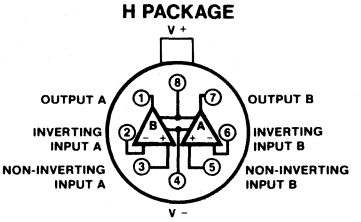
PIN CONFIGURATION

N, FE PACKAGE



ORDER PART NO.
NE5532FE,N
NE5532AFE,N

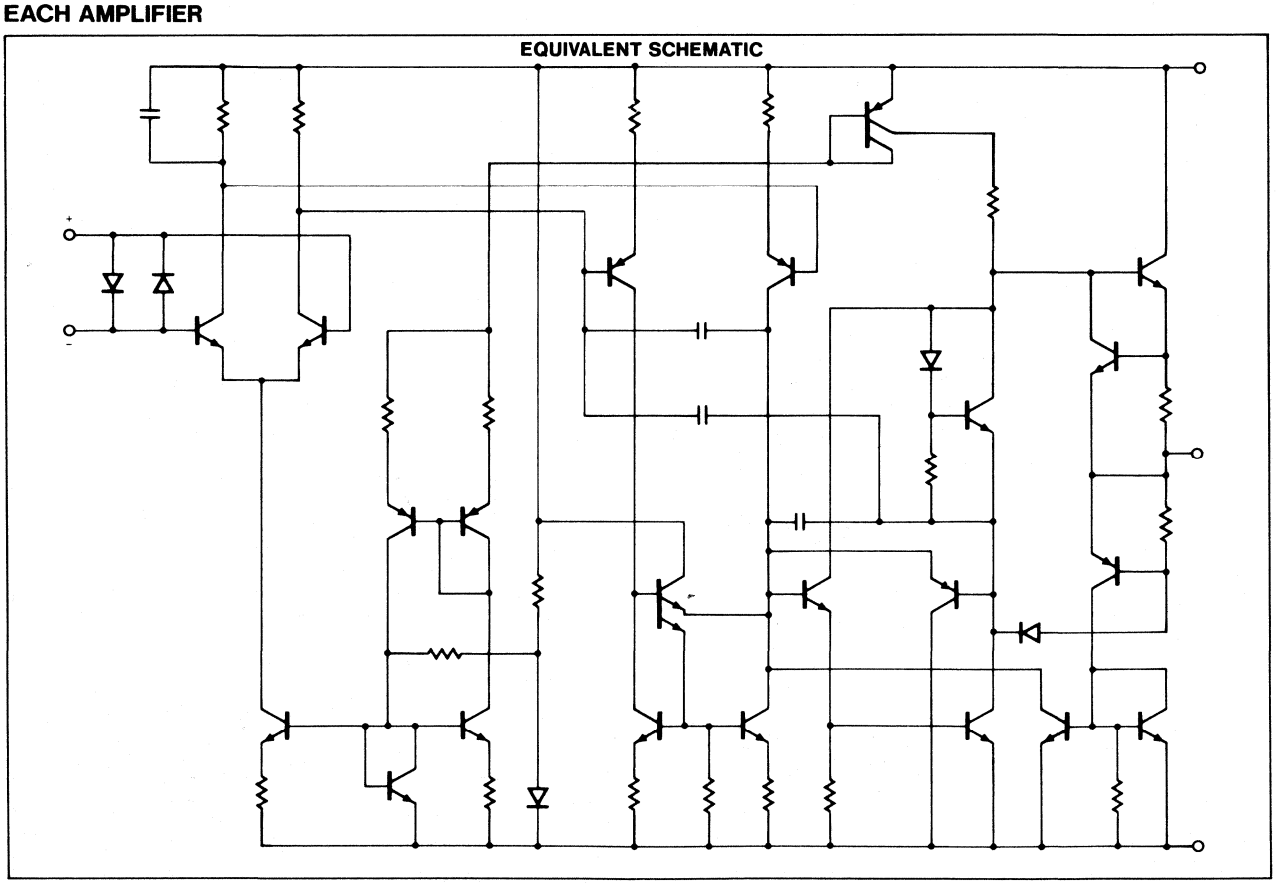
H PACKAGE



ORDER PART NO.
NE5532H
NE5532AH

EACH AMPLIFIER

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER		RATING	UNIT
V_S	Supply voltage	±22	V
V_{IN}	Input voltage	±V supply	V
V_{DIFF}	Differential input voltage[1]	±.5	V
T_A	Operating temperature range	0 to 70	°C
T_{STG}	Storage temperature	−65 to +150	°C
T_J	Junction temperature	150	°C
P_D	Power dissipation		
	5532T	800	mW
	5532FE	1000	mW
	Lead temperature (soldering, 10 sec)	300	°C

NOTES

1. Diodes protect the inputs against over-voltage. Therefore, unless current-limiting resistors are used, large currents will flow if the differential input voltage exceeds 0.6V. Maximum current should be limited to ± 10mA.
2. For operation at elevated temperature T package must be derated based on a thermal resistance of 150°C/W junction to ambient, 45°C/W junction to case. Thermal resistance of the FE package is 125°C/W.

DC ELECTRICAL CHARACTERISTICS T_A = 25°C, V_S = ±15V unless otherwise specified.[1]

PARAMETER		TEST CONDITIONS	NE5532/5532A			UNIT
			Min	Typ	Max	
V_{OS}	Offset voltage			.5	4	mV
		Over temperature			5	mV
I_{OS}	Offset current			10	150	nA
		Over temperature			200	nA
I_B	Input current			200	800	nA
		Over temperature			1000	nA
I_{CC}	Supply current			8	16	mA
V_{CM}	Common mode input range		±12	±13		V
CMRR	Common mode rejection ratio		70	100		dB
PSRR	Power supply rejection ratio			10	100	μV/V
A_{VOL}	Large signal voltage gain	$R_L \geq 2k\Omega$ V_O = ±10V	25	100		V/mV
		Over temperature	15			V/mV
		$R_L \geq 600$, V_O = ±10V	15	50		V/mV
		Over temperature	10			V/mV
V_{OUT}	Output swing	$R_L \geq 600\Omega$	±12	±13		V
		$R_L \geq 600\Omega$, V_S = ±18V	±15	±16		V
R_{IN}	Input resistance		30	300		kΩ
I_{SC}	Output short circuit current			38		mA

NOTE

1. For NE5532, NE5532A, T_{Min} = 0°C, T_{Max} = 70°C.

AC ELECTRICAL CHARACTERISTICS T_A = 25°C, V_S = ±15V unless otherwise specified.

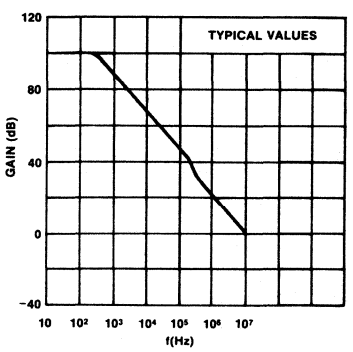
PARAMETER		TEST CONDITIONS	NE5532/5532A			UNIT
			Min	Typ	Max	
R_{OUT}	Output resistance	A_V = 30dB Closed loop f = 10kHz, R_L = 600Ω		0.3		Ω
	Overshoot	Voltage follower V_{IN} = 100mV p-p C_L = 100pF R_L = 600Ω		10		%
	Gain	f = 10kHz		2.2		v/mV
	Gain bandwidth product	C_L = 100pF R_L = 600Ω		10		mHz
	Slew rate			9		V/μs
	Power bandwidth	V_{OUT} = ±10V V_{OUT} = ±14V, R_L = 600Ω, V_{CC} = ±18V		140 100		kHz kHz

ELECTRICAL CHARACTERISTICS T_A = 25°C, V_S = ±15V unless otherwise specified.

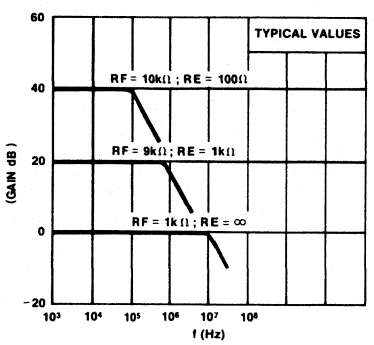
PARAMETER	TEST CONDITIONS	NE5532			NE5532A			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input noise voltage	f_o = 30Hz f_o = 1kHz		8 5			8 5	10 6	nV/√Hz nV/√Hz
Input noise current	f_o = 30Hz f_o = 1kHz		2.7 0.7			2.7 0.7		pA/√Hz pA/√Hz
Channel separation	f = 1kHz, RS = 5kΩ		110			110		dB

TYPICAL PERFORMANCE CHARACTERISTICS

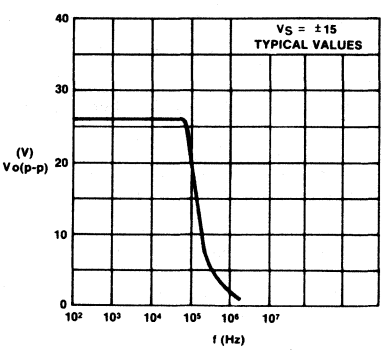
OPEN LOOP FREQUENCY RESPONSE



CLOSED LOOP FREQUENCY RESPONSE

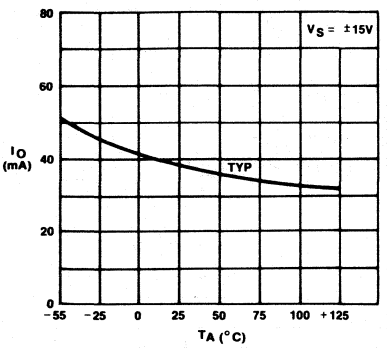


LARGE-SIGNAL FREQUENCY RESPONSE

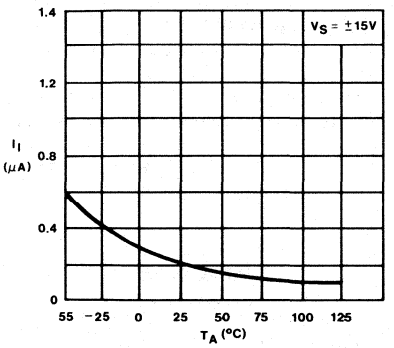


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

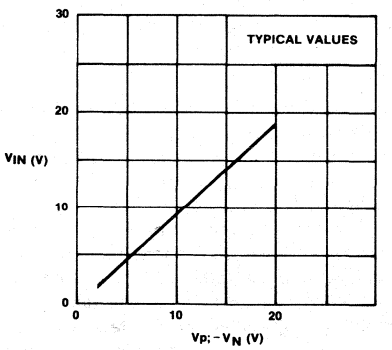
OUTPUT SHORT-CIRCUIT CURRENT



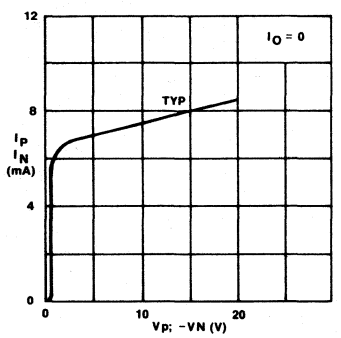
INPUT BIAS CURRENT



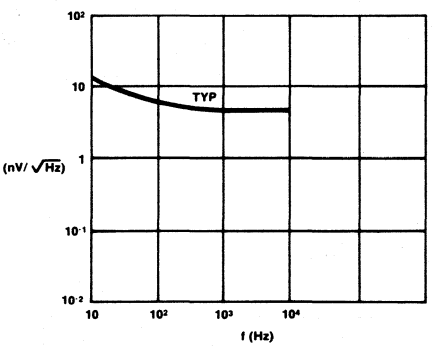
INPUT COMMON MODE VOLTAGE RANGE



SUPPLY CURRENT

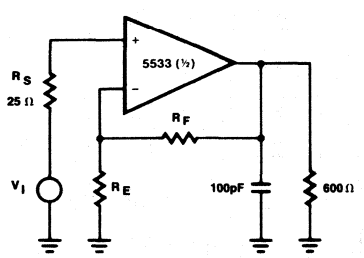


INPUT NOISE VOLTAGE DENSITY

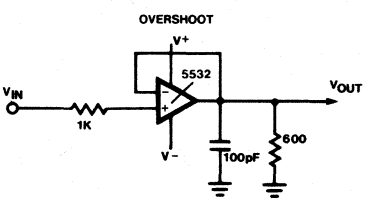


TEST CIRCUITS

CLOSED LOOP FREQUENCY RESPONSE



VOLTAGE FOLLOWER



NE/5533/5533A-N,F•NE/SE5534/5534A-N,H

DESCRIPTION

The 5533/5534 are single and dual high-performance low noise operational amplifiers. Compared to other operational amplifiers, such as TL083, they show better noise performance, improved output drive capability and considerably higher small-signal and power bandwidths.

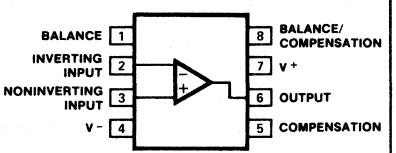
This makes the devices especially suitable for application in high quality and professional audio equipment, in instrumentation and control circuits and telephone channel amplifiers. The op amps are internally compensated for gain equal to, or higher than, three. The frequency response can be optimized with an external compensation capacitor for various applications (unity gain amplifier, capacitive load, slew-rate, low overshoot, etc.) If very low noise is of prime importance, it is recommended that the 5533A/5534A version be used which has guaranteed noise specifications.

FEATURES

- **Small-signal bandwidth: 10MHz**
- **Output drive capability: 600Ω, 10V (rms) at $V_S = \pm 18V$**
- **Input noise voltage: 4nV/$\sqrt{Hz}$**
- **DC voltage gain: 100000**
- **AC voltage gain: 6000 at 10kHz**
- **Power bandwidth: 200kHz**
- **Slew-rate: 13V/μs**
- **Large supply voltage range: ±3 to ±20V**

	5534
• Pin out	741
• Configuration	Single

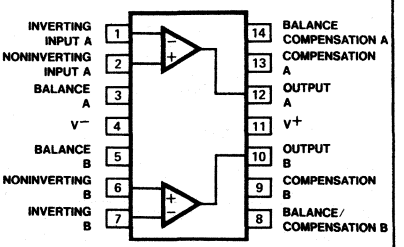
N PACKAGE



ORDER PART NO.
NE/SE5534N
NE/SE5534AN

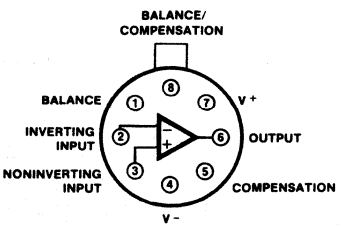
PIN CONFIGURATION

N PACKAGE



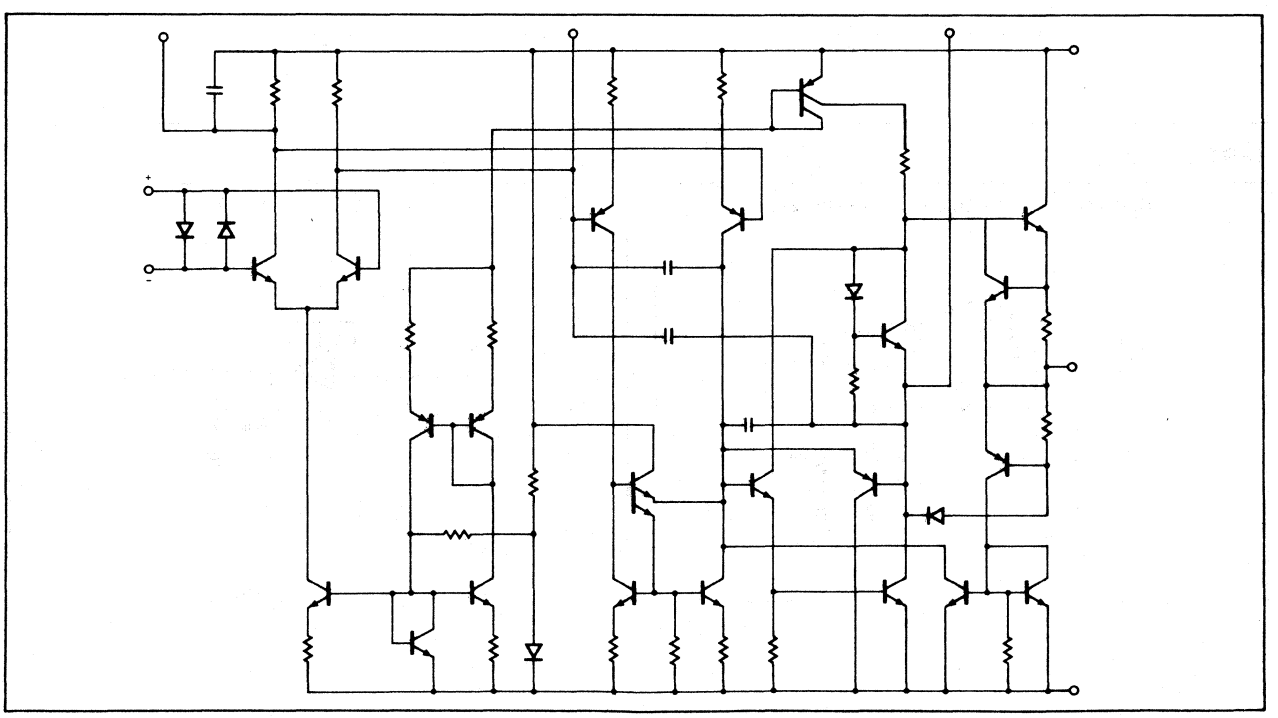
ORDER PART NO.
NE5533N/F
NE5533AN/AF

H PACKAGE



ORDER PART NO.
SE5534H
SE5534AH
NE5534H
NE5534AH

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER		RATING	UNIT
V_S	Supply voltage	±22	V
V_{IN}	Input voltage	±V supply	V
V_{DIFF}	Differential input voltage[1]	±.5	V
T_A	Operating temperature range		
	SE5534/5534A	-55 to +125	°C
	NE5533/5533A/5534/5534A	0 to 70	°C
T_{STG}	Storage temperature	-65 to +150	°C
T_J	Junction temperature	150	°C
P_D	Power dissipation at 25°C[2]		
	5533N 5534N	500	mW
	5534T	800	mW
	Output short circuit duration[3]	indefinite	
	Lead temperature (soldering 10 sec)	300	°C

NOTES

1. Diodes protect the inputs against over-voltage. Therefore, unless current-limiting resistors are used, large currents will flow if the differential input voltage exceeds 0.6V. Maximum current should be limited to ±10mA.
2. For operation at elevated temperature T package must be derated based on a thermal resistance of 150°C/W junction to ambient, 45°C/W junction to case. Thermal resistance of the N package is 240°C/W junction to ambient.
3. Output may be shorted to ground at $V_S = \pm 15V$, $T_A = 25°C$. Temperature and/or supply voltages must be limited to ensure dissipation rating is not exceeded.

DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $V_S = \pm 15V$ unless otherwise specified.[1,2]

PARAMETER		TEST CONDITIONS	SE5534/5534A			NE5533/5533A 5534/5534A			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OS}	Offset voltage			.5	2		.5	4	mV
		Over temperature			3			5	mV
I_{OS}	Offset current			10	200		20	300	nA
		Over temperature			500			400	nA
I_B	Input current			400	800		500	1500	nA
		Over temperature			1500			2000	nA
I_{CC}	Supply current			4	6.5		4	8	mA
	Per op amp	Over temperature			9				mA
V_{CM}	Common mode input range		±12	±13		±12	±13		V
CMRR	Common mode rejection ratio		80	100		70	100		dB
PSRR	Power supply rejection ratio			10	50		10	100	μV/V
A_{VOL}	Large signal voltage gain	$R_L \geq 600\Omega$, $V_O = \pm 10V$	50	100		25	100		V/mV
		Over temperature	25			15			V/mV
V_{OUT}	Output swing	$R_L \geq 600\Omega$	±12	±13		±12	±13		V
		$R_L \geq 600\Omega$ $V_S = \pm 18V$	±15	±16		±15	±16		V
R_{IN}	Input resistance		50	100		30	100		kΩ
I_{SC}	Output short circuit current			38			38		mA

NOTES

1. For NE5533/5533A/5534/5534A, $T_{MIN} = 0°C$, $T_{MAX} = 70°C$
2. For SE 5534/5534A, $T_{MIN} = -55°C$, $T_{MAX} = +125°C$

AC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_S = \pm 15V$ unless otherwise specified.

PARAMETER	TEST CONDITIONS	SE5534/5534A			NE5533/5533A 5534/5534A			UNIT
		Min	Typ	Max	Min	Typ	Max	
R_{OUT} Output resistance	A_V = 30dB closed loop f = 10kHz, R_L = 600Ω, C_C = 22pF		0.3			0.3		Ω
Transient response T_R Rise time Overshoot	Voltage follower, V_{IN} = 50mV R_L = 600Ω, C_C = 22pF, C_L = 100pF		 20 20			 20 20		 ns %
Transient response T_R Rise time Overshoot	V_{IN} = 50mv, R_L = 600Ω C_C = 47pF, C_L = 500pF		 50 35			 50 35		 ns %
AC Gain	f = 10kHz, C_C = 0 f = 10kHz, C_C = 22pF		6 2.2			6 2.2		V/mV V/mV
Gain bandwidth product	C_C = 22pF, C_L = 100pF		10			10		mHz
Slew rate	C_C = 0 C_C = 22pF		13 6			13 6		V/μS V/μS
Power bandwidth	V_{OUT} = ±10V, C_C = 0 V_{OUT} = ±10V, C_C = 22pF V_{OUT} = ±14V, R_L = 600Ω C_C = 22pF, V_{CC} = ±18V		200 95 70			200 95 70		kHz kHz kHz

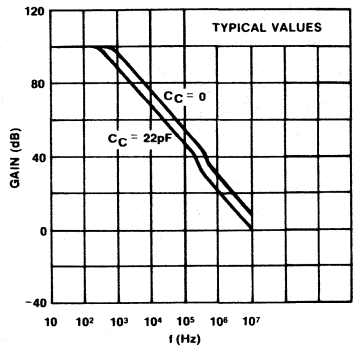
ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_S = \pm 15V$ unless otherwise specified.

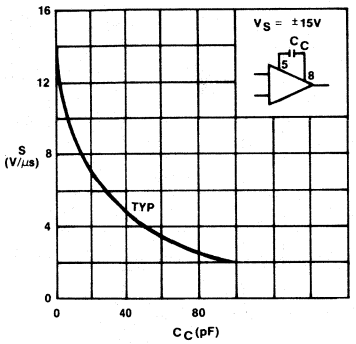
PARAMETER	TEST CONDITIONS	5533/5534			5533A/5534A			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input noise voltage	f_o = 30Hz f_o = 1kHz		7 4			5.5 3.5	7 4.5	$nV/\sqrt{Hz}$ $nV/\sqrt{Hz}$
Input noise current	f_o = 30Hz f_o = 1kHz		2.5 0.6			1.5 0.4		$pA/\sqrt{Hz}$ $pA/\sqrt{Hz}$
Broadband noise figure	f = 10Hz – 20kHz, R_S = 5kΩ					0.9		dB
Channel separation	f = 1kHz, R_S = 5kΩ		110			110		dB

TYPICAL PERFORMANCE CHARACTERISTICS

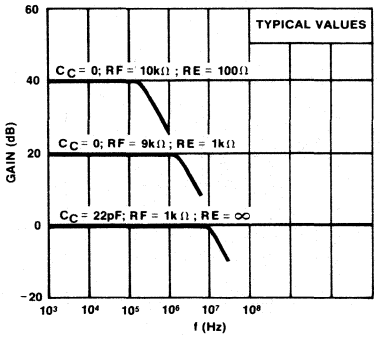
OPEN LOOP FREQUENCY RESPONSE



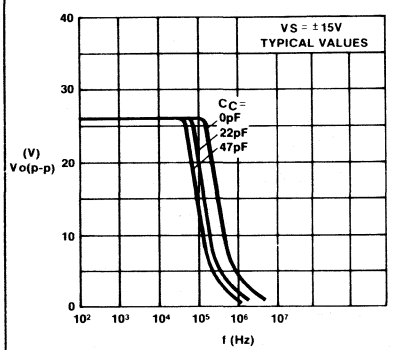
SLEW-RATE AS A FUNCTION OF COMPENSATION CAPACITANCE



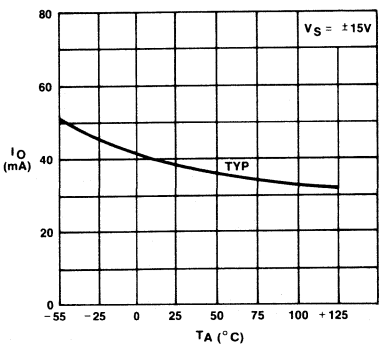
CLOSED LOOP FREQUENCY RESPONSE



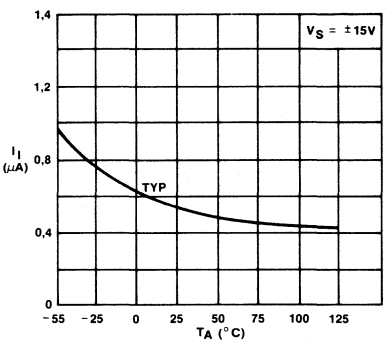
LARGE-SIGNAL FREQUENCY RESPONSE



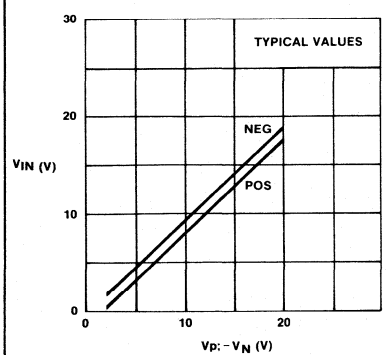
OUTPUT SHORT-CIRCUIT CURRENT



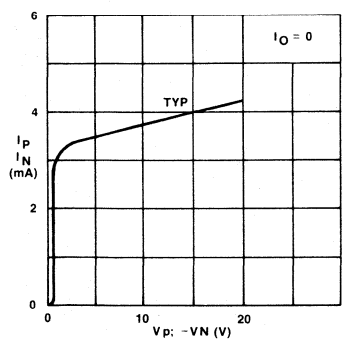
INPUT BIAS CURRENT



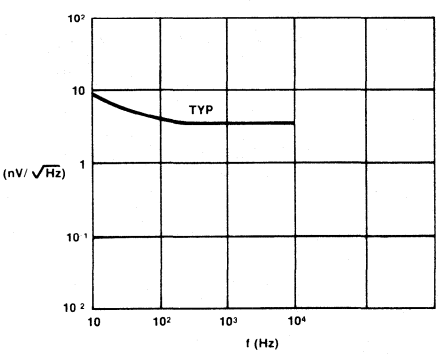
INPUT COMMON MODE VOLTAGE RANGE



SUPPLY CURRENT PER OP AMP

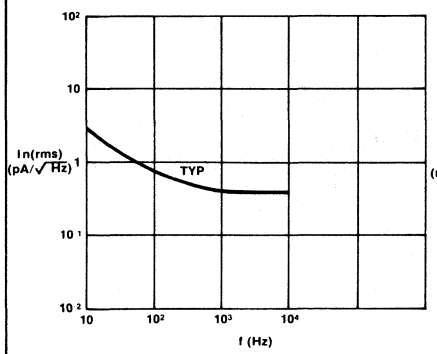


INPUT NOISE VOLTAGE DENSITY

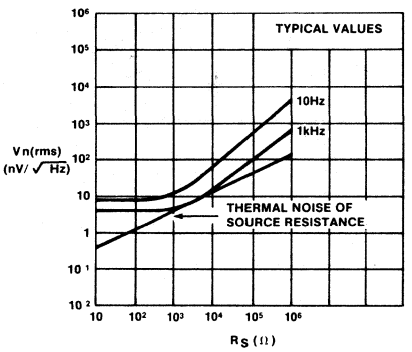


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

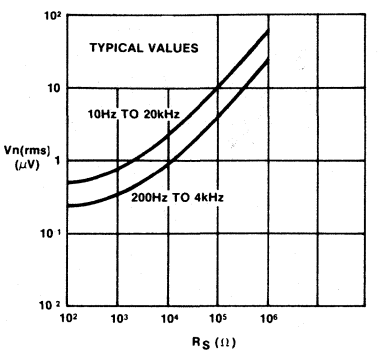
INPUT NOISE CURRENT DENSITY



TOTAL INPUT NOISE DENSITY

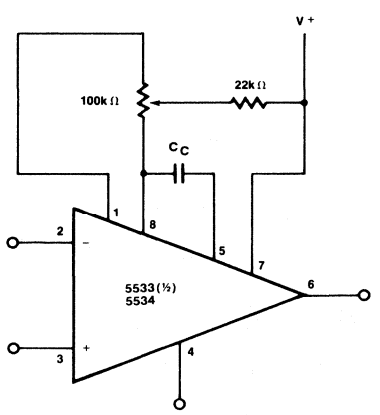


BROADBAND INPUT NOISE VOLTAGE

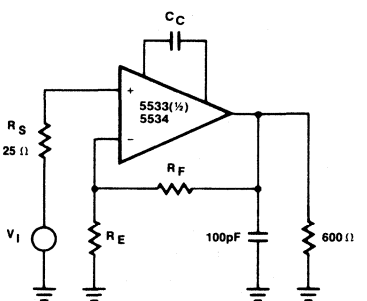


TEST LOAD CIRCUITS

FREQUENCY COMPENSATION AND OFFSET VOLTAGE ADJUSTMENT CIRCUIT



CLOSED LOOP FREQUENCY RESPONSE



FET INPUT OPERATIONAL AMPLIFIER — NE/SU 536

NE/SU536-H

DESCRIPTION

The 536 is a special purpose high performance operational amplifier utilizing an FET input stage for extremely high input impedance and low input current.

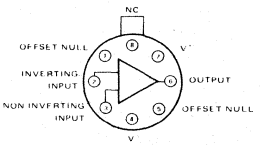
The device features internal compensation, standard pinout, wide differential and common mode input voltage range, high slew rate and high output drive capability.

FEATURES

- **5pA input bias current**
- **Input and output protection**
- **Offset null capability**
- **Internally compensated**
- **6V/μsec slew rate**
- **Standard pinout**
- **1MHz unity gain bandwidth**

PIN CONFIGURATION

H PACKAGE



ORDER PART NO.
SU536H
NE536H

ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	±22	V
Differential input voltage range	±30	V
Common mode input voltage range	$\pm V_S$	
Power dissipation[1]	500	mW
Operating temperature range		
SU536T	-55 to +85	°C
NE536T	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead temperature (solder, 60sec)	300	°C
Output short circuit duration[2]	indefinite	

NOTES

1. Rating applies for case temperature to +25°C; derate linearly at 6.5mW/°C for ambient temperatures above 75°C.
2. Short circuit may be to ground or either supply. Rating applies to +125°C case temperature or +75°C ambient temperature.

DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_S = ±15V unless otherwise specified.[1]

PARAMETER		TEST CONDITIONS	NE536			UNIT
			Min	Typ	Max	
V_{OS}	Offset voltage	$R_S \leq 10k\Omega$		30	90	mV
		Over temp., $R_S \leq 10k\Omega$		30		mV
V_{OS}	Drift	$R_S = 0\Omega$, over temp.		30		μV/°C
I_{OS}	Offset current			5		pA
I_{BIAS}	Input current[2]			30	100	pA
V_{CM}	Common mode voltage range		±10	±11		V
CMRR	Common mode rejection ratio	$R_S \leq 10k\Omega$, $V_{IN} = \pm 10V$	64	80		dB
R_{IN}	Input resistance			10^{14}		Ω
V_{OUT}	Output voltage swing	$R_L \geq 2k\Omega$, over temp.	±10	±11		V
		R_L 10kΩ, over temp.	±12	±13		V
I_{CC}	Supply current	V_{OUT} = OV		6.0	8.0	mA
P_{SRR}	Supply voltage rejection ratio	$R_S \leq 10k\Omega$, $\pm 6 \leq V_S \pm 15$		100	300	μV/V
A_{VOL}	Large signal voltage gain	$V_O = \pm 10V$, R_L 2kΩ	50			V/mV
		$V_O = \pm 10V$, $R_L \geq 2k\Omega$, over temp.	25			V/mV
P_S	Power supply range		±6	±18		V

NOTES

1. Operating temperature range: NE536 is 0°C to 70°C.
2. Input current typically doubles every 10°C.

DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $\pm 6V \leq V_S \leq \pm 20V$ unless otherwise specified.[2]

PARAMETER	TEST CONDITIONS	SU536			UNIT
		Min	Typ	Max	
V_{OS} Offset voltage	$R_S \leq 10k\Omega$		7.5	20	mV
	$R_S \leq 10k\Omega$, over temp.		7.5	30	mV
V_{OS} Drift	$R_S \leq 10k\Omega$		20		$\mu V/°C$
I_{OS} Offset current			5		pA
I_{BIAS} Input current[1]			5	30	pA
	Over temp.		250	3000	pA
V_{CM} Common mode voltage range	$V_S = \pm 15V$	±10	±11		V
CMRR Common mode rejection ratio	$R_S \leq 10k\Omega$, $V_{IN} = \pm 10V$	70	80		dB
R_{IN} Input resistance			10^{14}		Ω
V_{OUT} Output voltage swing	$R_L \geq 2k\Omega$, $V_S = \pm 15V$, over temp.	±10	±12		V
	$R_L \geq 10k\Omega$, $V_S = \pm 15V$, over temp.	±12	±13		V
I_{CC} Supply current	$V_{OUT} = OV$, $V_S = \pm 20V$		6.0	8.0	mA
P_{SRR} Supply voltage rejection ratio	$R_S \leq 10k\Omega$		50	150	$\mu V/V$
A_{VOL} Large signal voltage gain	Over temp., $V_S = \pm 15V$, $V_O = \pm 10V$, $R_L \geq 2k\Omega$	50			V/mV
P_S Power supply range		±6		±20	V

NOTES

1. Input current typically doubles every 10°C.
2. Operating temperature range for SU536 is -55°C to +85°C.

AC ELECTRICAL CHARACTERISTICS

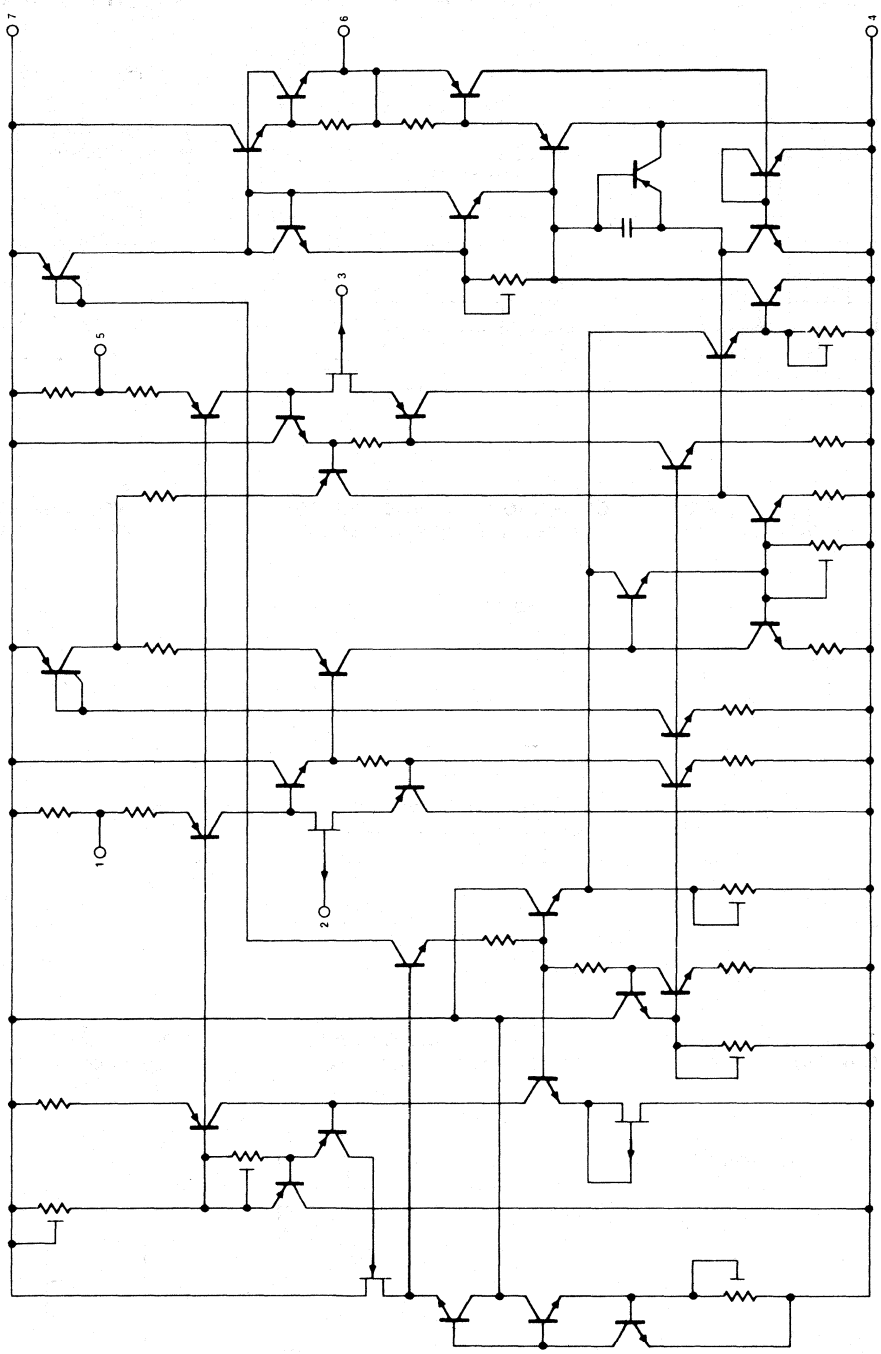
$T_A = 25°C$ unless otherwise specified.[1,2]

PARAMETER	TEST CONDITIONS	NE536			SU536			UNIT
		Min	Typ	Max	Min	Typ	Max	
Differential capacitance			6			6		pF
Input noise voltage	0.1Hz — 100kHz		20			20		μVrms
Output impedance			100			100		
Unity gain frequency	$V_S = \pm 15V$		1			1		MHz
Full power bandwidth	$V_S = \pm 15V$		100			100		KHz
Slew rate, inverter	$V_S = \pm 15V$, A = -1V		6			6		V/μs
Slew rate, follower	$V_S = \pm 15V$, A = +1V		6			6		V/μs

NOTES

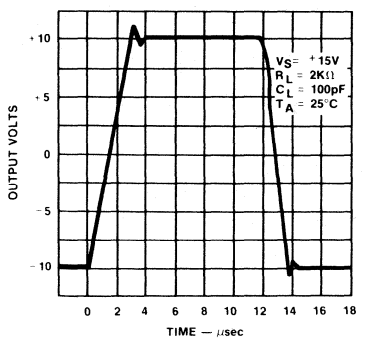
1. Temperature range for SU536 is $-55 \leq T_A \leq 85°C$
   Temperature range for NE536 is $0°C \leq T_A \leq 70°C$
2. SU536 — $\pm 6V \leq T_A \pm 20V$
   NE536 — $\pm 15V$

CIRCUIT SCHEMATIC

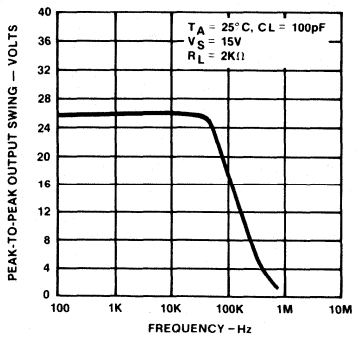


TYPICAL PERFORMANCE CHARACTERISTICS

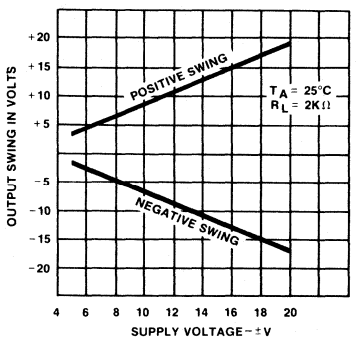
LARGE SIGNAL VOLTAGE FOLLOWER PULSE RESPONSE



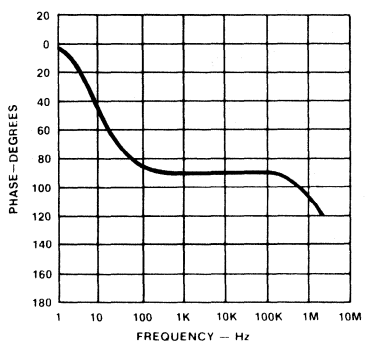
OUTPUT VOLTAGE SWING AS A FUNCTION OF FREQUENCY



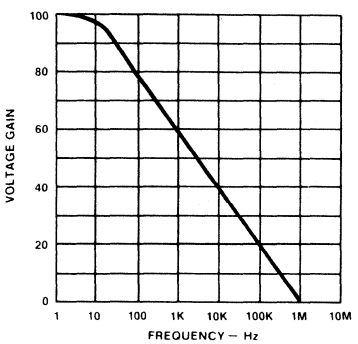
OUTPUT VOLTAGE SWING AS A FUNCTION OF SUPPLY VOLTAGE



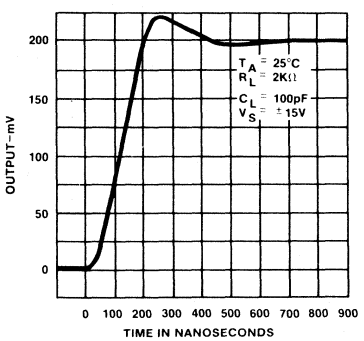
OPEN LOOP PHASE RESPONSE AS A FUNCTION OF FREQUENCY



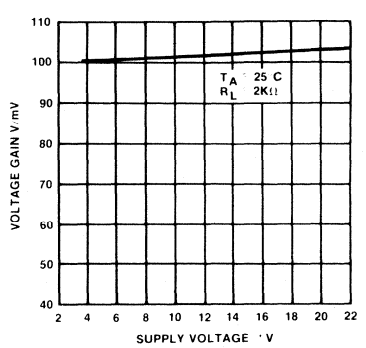
OPEN LOOP VOLTAGE GAIN AS A FUNCTION OF FREQUENCY



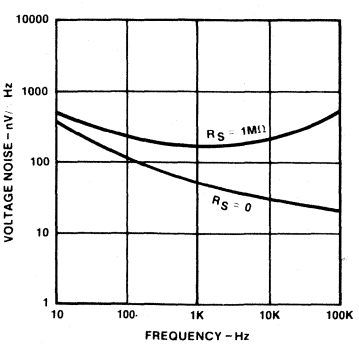
VOLTAGE FOLLOWER TRANSIENT RESPONSE



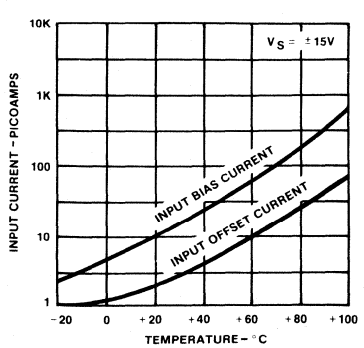
OPEN LOOP VOLTAGE GAIN AS A FUNCTION OF SUPPLY VOLTAGE



INPUT VOLTAGE NOISE AS A FUNCTION OF FREQUENCY

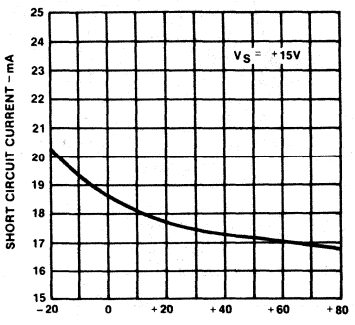


INPUT CURRENTS AS A FUNCTION OF AMBIENT TEMPERATURE



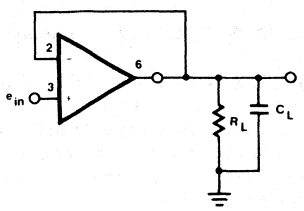
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

OUTPUT SHORT-CIRCUIT CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE

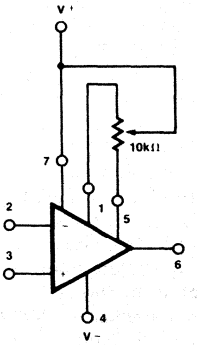


TEST CIRCUITS

VOLTAGE FOLLOWER CIRCUIT



OFFSET NULL CIRCUIT



DESCRIPTION

The NE5537 monolithic Sample and Hold amplifier combines the best features of ion implanted JFET's with bipolar devices to obtain high accuracy, fast acquisition time, and low droop rate. This device is pin compatible with the LF198, and features a superior performance in droop rate and output drive capability. The circuit shown in Figure 1 contains two operational amplifiers which function as a unity gain amplifier in the sample mode. The first amplifier has bipolar input transistors which gives the system a low offset voltage. The second amplifier has JFET input transistors to achieve low leakage current from the hold capacitor. A unique circuit design for leakage current cancellation using current mirrors gives the NE5537 a low droop rate at higher temperature. The output stage has the capability to drive a 2K load. The logic input is compatible with TTL, PMOS or CMOS logic. The differential logic threshold is 1.4V with the sample mode occurring where the logic input is high.

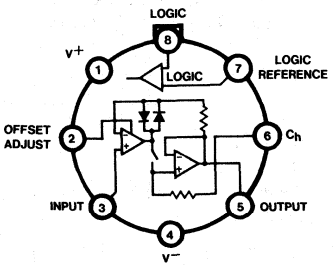
FEATURES

- **Operates from ±5V to ±18V supplies**
- **Hold leakage current 6pA @ T_j25°C**
- **Less than 10μs acquisition time**
- **TTL, PMOS, CMOS compatible logic input**
- **0.5mV typical hold step at C_h = 0.01μF**
- **Low input offset: 1MV (typical)**
- **0.002% gain accuracy with R_L = 2kΩ**
- **Low output noise in hold mode**
- **Input characteristics do not change during hold mode**
- **High supply rejection ratio in sample or hold**
- **Wide bandwidth**

Logic inputs on the 5537 are fully differential with low input current, allowing direct connection to TTL, PMOS, and CMOS. Differential threshold is 1.4V. The 5537 will operate from ±5V to ±18V supplies. It is available in an 8-lead TO-5 package.

PIN CONFIGURATION

H PACKAGE
Metal Can Package



TOP VIEW

ORDER PART NO.
NE/SE 5537-H

BLOCK DIAGRAM

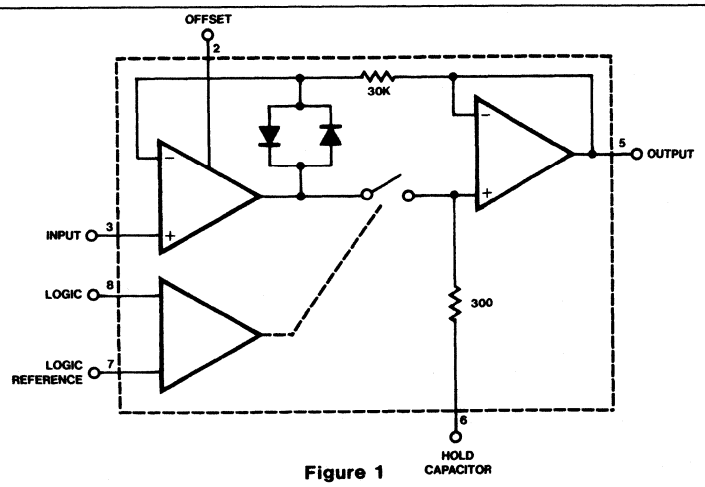


Figure 1

TYPICAL APPLICATIONS

TYPICAL CONNECTION

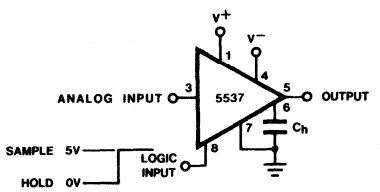


Figure 2

ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	±18	V
Power dissipation (package limitation)[1]	500	mW
Operating ambient temperature range		
SE5537	−55 to +125	°C
NE5537	0 to +70	°C
Storage temperature range	−65 to +150	°C
Input voltage	Equal to supply voltage	
Logic to logic reference differential voltage[2]	+7, −30	V
Output short circuit duration	Indefinite	
Hold capacitor short circuit duration	10	sec
Lead temperature (soldering, 10sec)	300	°C

NOTES

1. The maximum junction temperature of the SE5537 is 150°C and for the NE5537 100°C. When operating at elevated ambient temperature, the TO-5 package must be derated based on a thermal resistance (θ_{ja}) of 150°C/W.
2. Although the differential voltage may not exceed the limits given, the common mode voltage on the logic pins may be equal to the supply voltages without causing damage to the circuit. For proper logic operation, however, one of the logic pins must always be at least 2V below the positive supply and 3V above the negative supply.

DC ELECTRICAL CHARACTERISTICS[3]

PARAMETER	TEST CONDITIONS	SE5537			NE5537			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input offset voltage[6]	T_j = 25°C Full temperature range		1	3 5		2	7 10	mV mV
Input bias current[6]	T_j = 25°C Full temperature range		5	25 75		10	50 100	nA nA
Input impedance	T_j = 25°C		10^{10}			10^{10}		Ω
Gain error	T_j = 25°C, $-10V \leq V_{IN} \leq +10V$, RL = 2K $-11.5V \leq V_{IN} \leq +11.5V$, RL = 10K Full temperature range		0.002	0.007 0.02		0.004	0.01 0.02	% %
Feedthrough attenuation ratio at 1kHz	T_j = 25°C, C_h = 0.01μF	86	96		80	90		dB
Output impedance	T_j = 25°C, "HOLD" mode full temperature range		0.5	2 4		0.5	4 6	Ω
"HOLD" Step[4]	T_j = 25°C, C_h = 0.01μF, V_{OUT} = 0		0.5	2.0		1.0	2.5	mV
Supply current[6]	T_j=25°C		4.5	6.5		4.5	7.5	mA
Logic and logic reference input current	T_j = 25°C		2	10		2	10	μA

NOTES

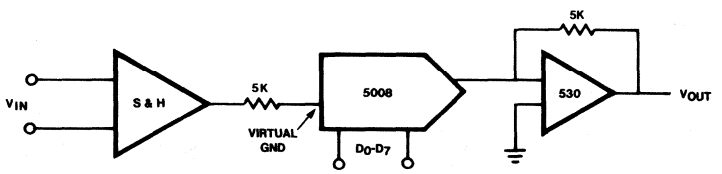
3. Unless otherwise specified, the following conditions apply. Unit is in "sample" mode, V_S = ±15V, T_j = 25°C, −11.5V, $\pm V_{IN}$, ±11.5V, C_h = 0.01μF, and R_L = 2kΩ. Logic reference voltage = 0V and logic voltage = 2.5V.
4. Hold step is sensitive to stray capacitive coupling between input logic signals and the hold capacitor. 1pF, for instance, will create an additional 0.5mV step with a 5V logic swing and a 0.01F hold capacitor. Magnitude of the hold step is inversely proportional to hold capacitor value.
5. Leakage current is measured at a junction temperature of 25°C. The effects of junction temperature rise due to power dissipation or elevated ambient can be calculated by doubling the 25°C value for each 1Φ°C increase in chip temperature. Leakage is guaranteed over full input signal range.
6. These parameters guaranteed over a supply voltage range of ±5 to ±18V.

DC ELECTRICAL CHARACTERISTICS[3] (Cont'd)

PARAMETER	TEST CONDITIONS	SE5537			NE5537			UNIT
		Min	Typ	Max	Min	Typ	Max	
Leakage current into hold capacitor[6]	T_j = 25°C hold mode[5]		6	50		6	100	pA
Acquisition time to 0.1%	V_{OUT} = 10V, C_h = 1000pF C_h = 0.01μf		 4 20			 4 20		 μs μs
Hold capacitor charging current	$V_{IN} - V_{OUT}$ = 2V		5			5		mA
Supply voltage rejection ratio	V_{OUT} = 0	80	110		80	110		dB
Differential logic threshold	T_j = 25°C	0.8	1.4	2.4	0.8	1.4	2.4	V

TYPICAL APPLICATIONS

MULTIPLYING DAC APPLICATION



$$V_{OUT} = V_{IN} \times \frac{1}{256} \left\{ 2^0 D_0 + 2^1 D_1 + \ldots 2^7 D_7 \right\} \quad \text{EQUATION 1}$$

Figure 3

ANALOG DATA MULTIPLEXING

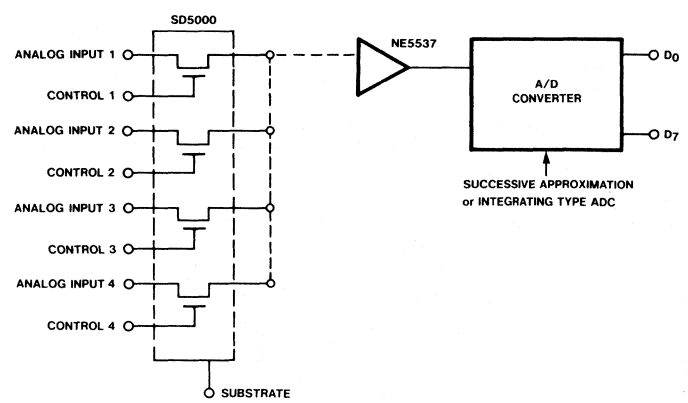
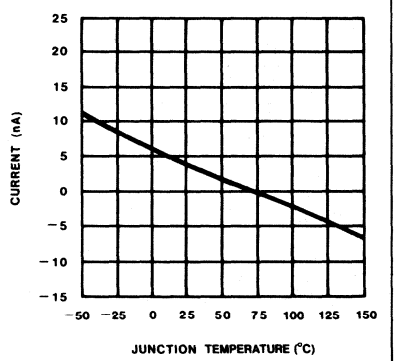


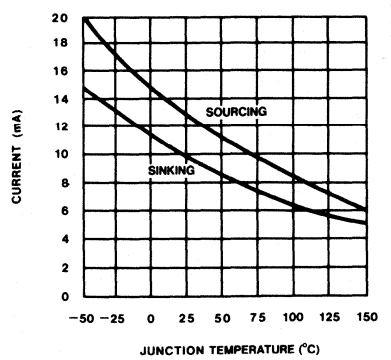
Figure 4

TYPICAL AC PERFORMANCE CHARACTERISTICS

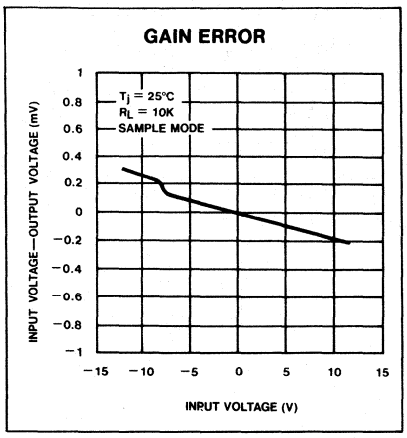
INPUT BIAS CURRENT

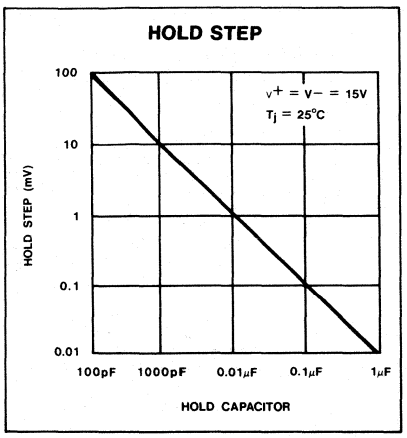


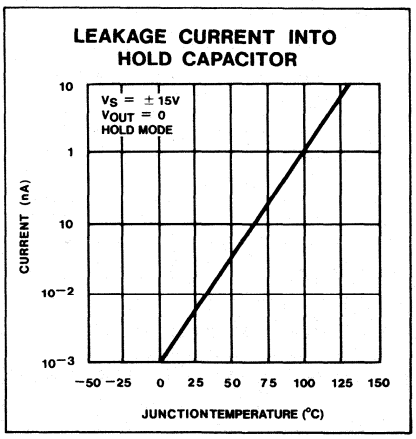
OUTPUT SHORT CIRCUIT CURRENT

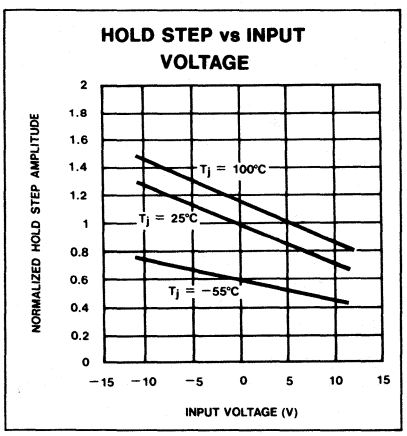


TYPICAL DC PERFORMANCE CHARACTERISTICS (Cont'd)

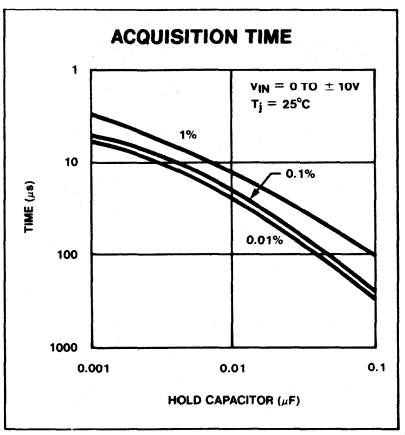


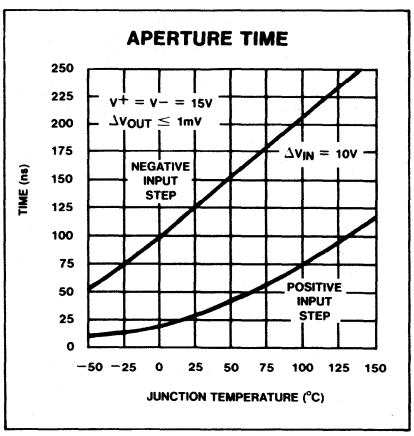


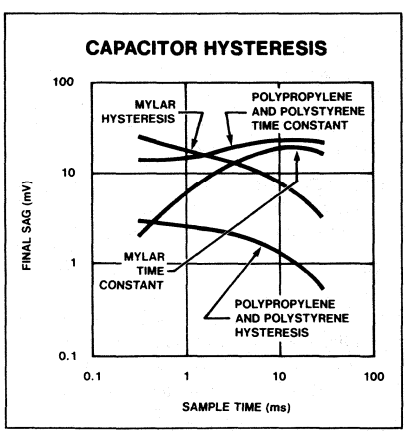


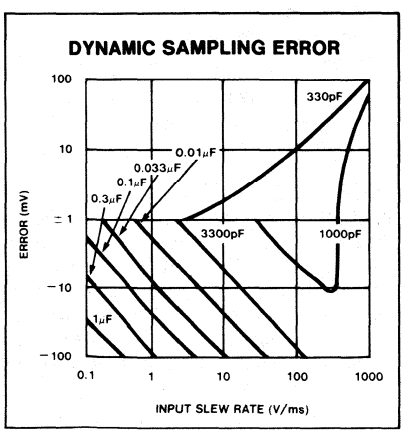


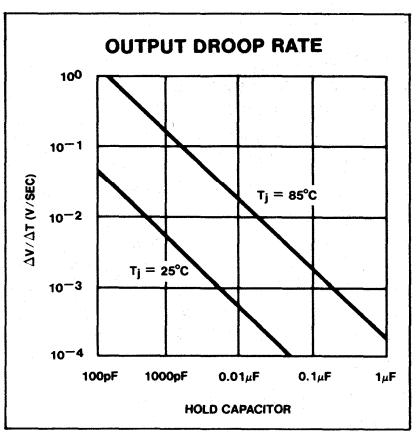
TYPICAL AC PERFORMANCE CHARACTERISTICS











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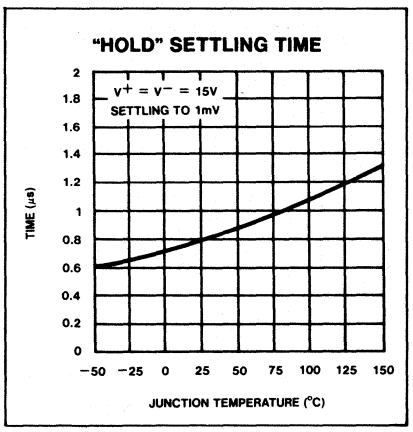
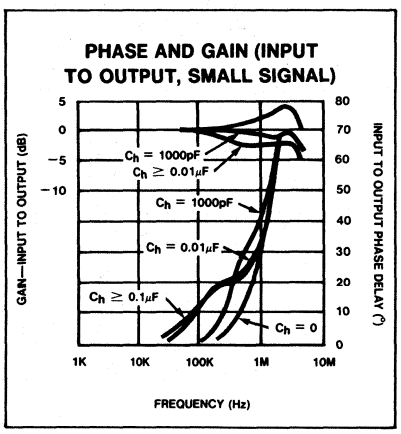
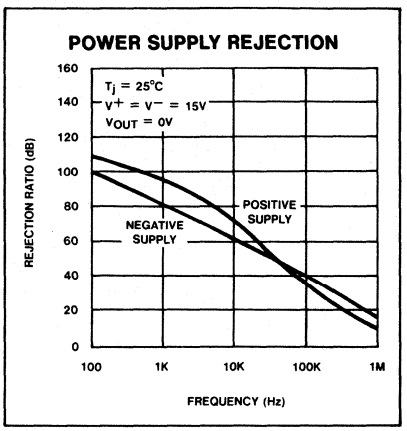
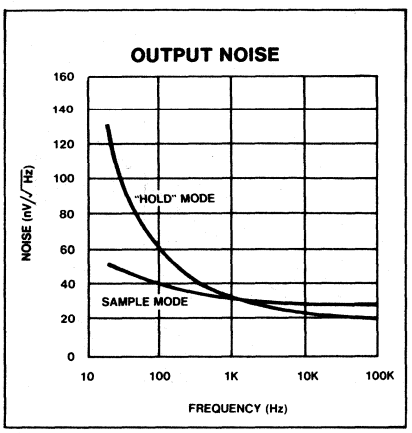
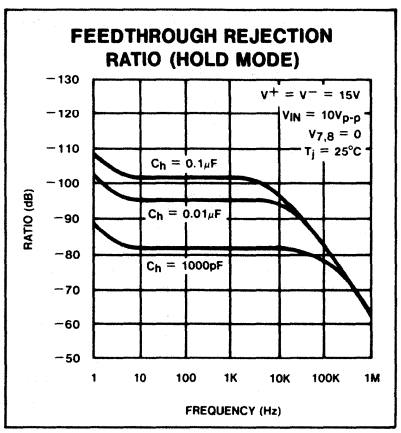










SAMPLE AND HOLD

INTRODUCTION

For many years designers have used the sample and hold (or track and hold) to operate on analog information in a time frame which is expedient.

By sampling a segment of the information and holding it until the proper timing for converting to some form of control signal or readout allows the designer certain freedom in performing predetermined manipulative functions. Therefore, the sample and hold can be defined as a "selective analog memory cell".

The memory is volatile and will also decay with time.

When using the sample and hold method for evaluating signal information, the designer is given the added feature of eliminating outside noise elements. With the analog to digital converter products available today the "dc memory" of the sample and hold can be easily converted to digital format and further incorporated into microprocessor based systems.

Parametric evaluation of the sample and hold will be discussed in the following paragraphs.

DEFINITION OF TERMS

ACQUISITION TIME: The time required to acquire a new analog input voltage with an output step of 10V. Note that acquisition time is not just the time required for the output to settle, but also includes the time required for all internal nodes to settle so that the output assumes the proper value when switched to the hold mode.

APERTURE DELAY TIME: The time elapsed from the hold command to the opening of the switch.

APERTURE JITTER: Also called "aperture uncertainty time", it's the time variation or uncertainty with which the switch opens, or the time variation in aperture delay.

APERTURE TIME: The delay required between "hold" command and an input analog transition, so that the transition does not affect the held output.

BANDWIDTH: The frequency at which the gain is down 3dB from its dc value. It's measured in sample (track) mode with a small-signal sine wave that doesn't exceed the slew rate limit.

EFFECTIVE APERTURE DELAY: The time difference between the hold command and the time at which the input signal is at the held voltage.

FIGURE OF MERIT: The ratio of the available charging current during sample mode to the leakage current during hold mode.

HOLD-MODE DROOP: The output voltage change per unit of time while in hold. Commonly specified in V/s, μV/μs or other convenient units.

HOLD-MODE FEEDTHROUGH: The percentage of an input sinusoidal signal that is measured at the output of a sample-hold when it's in hold mode.

HOLD SETTLING TIME: The time required for the output to settle within 1mV of final value after the "hold" logic command.

SAMPLE-TO-HOLD OFFSET ERROR: The difference in output voltage between the time the switch starts to open, and the time when the output has settled completely. It is caused by charge being transferred to the hold capacitor switch as it opens.

SLEW RATE: The fastest rate at which the sample & hold output can change (specified in V/μs).

HOLD STEP: The voltage step at the output of the sample and hold when switching from sample mode to hold mode with a steady (dc) analog input voltage. Logic swing is 5V.

DYNAMIC SAMPLING ERROR: The error introduced into the held output due to a changing analog input at the time the hold command is given. Error is expressed in mV with a given hold capacitor value and input slew rate. Note that this error term occurs even for long sample times.

GAIN ERROR: The ratio of output voltage swing to input voltage swing in the sample mode expressed as a percent difference.

THRESHOLD: Level shall be defined as that level which causes the switch control to change state.

BASIC BLOCK DIAGRAM

The basic circuit concept of the sample and hold circuit incorporates the use of two (2) operational amplifiers and a switch control mechanism (which determines sample, hold or track conditions). Reference figure 1.

The block diagram of the NE5537 is a closed loop non-inverting unity gain sample and hold system. The input buffer amplifier supplies the current necessary to charge the hold capacitor, while the output buffer amplifier closes the loop such that the output voltage is identical to the input voltage (with consideration for input offset voltage, offset current, and temperature variations which are common to *all* sample and hold circuits, be they monolithic, hybrid or modular).

When the sampling switch is open (in the hold mode) the clamping diodes close the loop around the input amplifier to keep it from being overdriven into saturation.

The switch control is driven by external logic levels via a timing sequence remote from the sample and hold device. Reference figure 2. The switch control has a floating reference (pin 7), referred to as the logic reference which makes the sample and hold device compatible to several types of external logic signals (TTL, PMOS, & CMOS). The switching device operates at a threshold level of 1.4V.

The switch mechanism is on (sampling an information stream) when the logic level is high (pin 8 is 1.4 volts higher than pin 7) and presents a load of 5 microamperes to the input logic signal. The analog sampled signal is amplified, stored (in the external holding capacitor), and buffered. At the end of the sampling period the internal switch mechanism turns off (switch opens) and the "stored analog memory" information on the external capacitor (pin 6) is loaded down by an operational amplifier connected in the unity gain non-inverting configuration. This amplifier, whose input impedance is effective by:

$$R = R_{IN}(A_{OL})/(1 + 1/A)$$

where
- R = Effective input impedance
- R_{IN} = Open loop input impedance
- A_{OL} = Open loop gain
- A = AC loop gain

Therefore, the higher the open loop gain of the second operational amplifier, the larger the effective loading on the capacitor. The larger the load, the lower the "leakage" current and the better the droop characteristics.

In actuality the amplifiers are designed with special leakage current cancellation circuits along with FET input devices. The leakage current cancellation circuits give better high temperature operation (remember that the FET amplifiers double in required bias current for every 10 degree increase in junction temperature).

Sampling time for the NE5537 is less than 10μsec, (measured to 0.1% of input signal). Leakage current is 6pa at a rate output load of 2kΩ.

BASIC APPLICATIONS

Multiplying DAC

As depicted in the block diagram of figure 3, the sample and hold circuit is used to supply a "variable" reference to the digital to analog converter. As the input reference varies, the output will change in accordance with equation 1.

Varying the input signal reference level can aid the system in performing both compression and expansion operations. The multiplying DAC's used are the Signetics SE/NE 5008; however, if the rate of change of the reference variation is kept slow enough a microprocessor compatible DAC can be incorporated.

DATA ACQUISITION SYSTEMS

As mentioned earlier, the designer may wish to operate on several different segments of an "analog" signal; however he is limited by the fact that only one analog to digital converter channel is available to him. Figure 4 shows the means by which a multiplexing system may be accomplished.

APPLICATION HINTS

Hold Capacitor

A significant source of error in an accurate sample and hold circuit is dielectric absorption in the hold capacitor. A mylar cap, for instance, may "sag back" up to 0.2% after a quick change in voltage. A long "soak" time is required before the circuit can be put back into the hold mode with this type of capacitor. Dielectrics with very low hysteresis are polystyrene, polypropylene, and Teflon. Other types such as mica and polycarbonate are not nearly as good. Ceramic is unusable with $>1\%$ hysteresis. The advantage of polypropylene over polystyrene is that it extends the maximum ambient temperature from 85°C to 100°C. The hysteresis relaxation time constant in polystyrene, for instance, is 10-50ms. If A-to-D conversion can be made within 1ms, hysteresis error will be reduced by a factor of ten.

DC Zeroing

dc Zeroing is accomplished by connecting the offset adjust pin to the wiper of a 1Ωk potentiometer which has one end tied to V^+ and the other end tied through a resistor to ground. The resistor should be selected to give $\simeq$0.6mA through the 1K potentiometer.

Sampling Dynamic Signals

Sampling errors due to moving (changing) input signals are of significant concern to designers employing sample and hold circuits. There exist finite phase delays through the sample and hold circuit causing an input-output phase differential for/as moving signals. In addition, the series protection resistor (300Ω to pin 6 of the NE5537) will add an RC time constant, over and above the slew rate limitation of the input buffer/current drive amplifier. This means that at the moment the "hold" command arrives, the hold capacitor voltage may be somewhat different than the actual analog input. The effect of these delays is opposite to the effect created by delays in the logic which switches the circuit from sample to hold. For example, consider an analog input of 20 Vp-p at 10kHz. Maximum dV/dt is 0.6V/μs. With no analog phase delay and 100ns logic delay, one could expect up to (0.1μs) (0.6V/μs) = 60mV error if the "hold" signal arrived near maximum dV/dt of the input. A positive going input would give a $\pm$60mV error. Now assume a 1MHz (3dB) bandwidth for the overall analog loop. This generates a phase delay of 160ns. If the hold capacitor sees this exact delay, then error due to analog delay will be (0.16μs) (0.6V/μs) = $-$96mV (analog) for a total of $-$36mV. To add to the confusion, analog delay is proportional to hold capacitor value while digital delay remains constant. A family of curves (dynamic sampling error) is included to help estimate errors.

A curve labeled *Aperture Time* has been included for sampling conditions where the input is steady during the sampling period, but may experience a sudden change nearly coincident with the "hold" command. This curve is based on a 1mV error fed into the output.

A second curve, *Hold Settling Time* indicates the time required for the output to settle to 1mV after the "hold" command.

Digital Feedthrough

Fast rise time logic signals can cause hold errors by feeding externally into the analog input at the same time the amplifier is put into the hold mode. To minimize this problem, board layout should keep logic lines as far as possible from the analog input. Grounded guarding traces may also be used around the input line, especially if it is driven from a high impedance source. Reducing high amplitude logic signals to 2.5V will also help.

NOTE

Logic signals also couple to hold cap. Hold cap is guarded by trace connected to sample & hold output. This also minimizes board leakage.

SPECIAL NOTES

1. Not all definitions herein defined are measured parametrically for the NE5537, but are legitimate terms used in sample and hold systems.
2. Reference should be made to Design Engineering, volumes 23 (Nov. 8, 1978), 25 (Dec. 6, 1978) and 26 (Dec. 20, 1978) for articles written by Eugene Zuch of Datel Systems, Inc. for a further discussion of sample and hold circuits.
3. Reference also made to National Semiconductor Corporation's Special Functions Data Book (1976).

DESCRIPTION

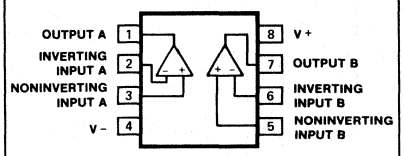
The NE/SE538/5538 are new generation operational amplifiers featuring high slew rates combined with improved input characteristics. Internally compensated for gains of 5 or larger, the SE538/5538 offers guaranteed minimum slew rates of 40V/μs or larger. Featuring 2mV max input offset voltage, the 538 is a single amplifier while the 5538 is a dual amplifier. Industry standard pin out and internal compensation allow the user to upgrade system performance by directly replacing general purpose amplifiers, such as 748, 101A, 741, 747 and 1458.

FEATURES

- **2mV max input offset voltage**
- **60nA max input offset current**
- **Short circuit protected**
- **Offset null capability**
- **Large common mode and differential voltage ranges**
- **60V/μs slew rate (gain of +5, -4 min)**
- **6MHz gain bandwidth product (gain +5, -4 minimum)**
- **Internal frequency compensation (gain of +5, -4 minimum)**
- **Pin out: 538 same as 741 (single)**
  5538 same as 747, 1458 (dual)

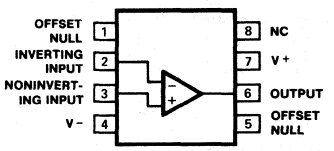
PIN CONFIGURATIONS

N PACKAGE



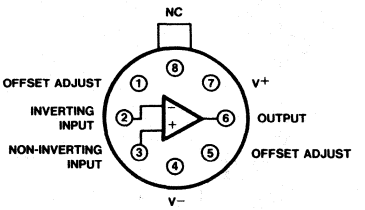
ORDER PART NO.
SE5538N, NE5538N

FE, N PACKAGE



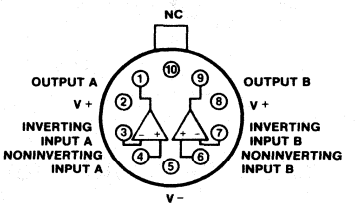
ORDER PART NO.
SE538N, FE NE538N, FE

H PACKAGE



ORDER PART NO.
SE538H NE538H

H PACKAGE



ORDER PART NO.
SE5538H NE5538H

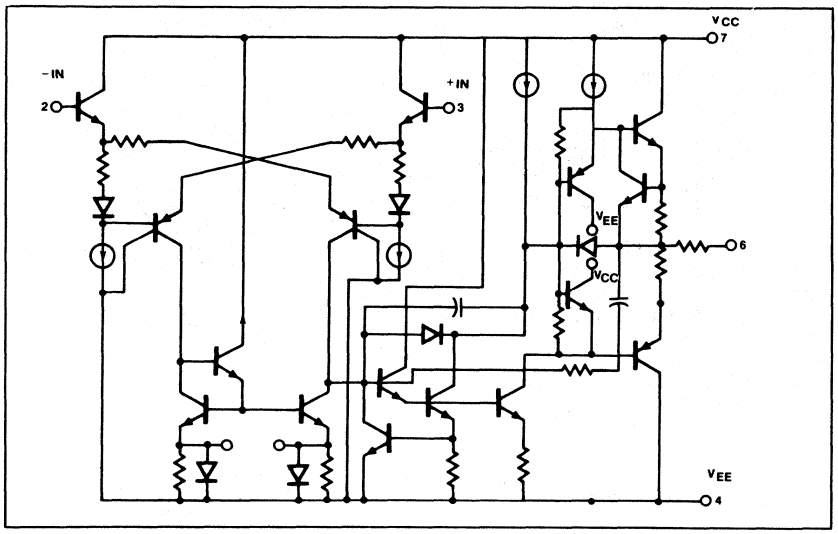
ABSOLUTE MAXIMUM RATINGS[1,2,3]

	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage		
	SE military grade	±22	V
	NE commercial grade	±18	V
P_D	Internal power dissipation FE package	1000	mW
P_D	Internal power dissipation[1] N package	500	mW
P_D	Internal power dissipation[1] H package	800	mW
	Differential input voltage	±30	V
	Input voltage[2]	±15	V
	Operating temperature range		
	SE military grade	-55 to +125	°C
	NE commercial grade	0 to 70	°C
	Output short circuit[3]	indefinite	
	Storage temperature range	-65 to +150	°C
	Lead temperature (solder, 60sec.)	300	°C

NOTES

1. Rating applies for thermal resistances of 240°C/W and 150°C/W junction to ambient for N and H packages. Maximum chip temperature is 150°C.
2. For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.
3. Short circuit may be to ground or either supply. Rating applies to 125°C case temperature or 75°C ambient temperature.

EQUIVALENT SCHEMATIC (EACH AMPLIFIER)



DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_S = \pm 15V$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SE538/SE5538			NE538/NE5538			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OS}	Input offset voltage	$R_S \leq 10k\Omega$		0.7	4.0		2.0	6.0	mV
V_{OS}	Input offset voltage	$R_S \leq 10k\Omega$, over temp.			5.0			7.0	mV
ΔV_{OS}	Input offset voltage drift	$R_S = 0\Omega$, over temp.		6.0			6.0		$\mu V/°C$
I_{OS}	Input offset current			5	20		15	40	nA
I_{OS}	Input offset current	Over temp.			40			80	nA
I_B	Input current			45	80		65	150	nA
I_B	Input current	Over temp.			200			200	nA
V_{CM}	Input common mode voltage range		±12	±13		±12	±13		V
C_{MRR}	Common mode rejection ratio	$R_S \leq 10k\Omega$, over temp.	70	90		70	90		dB
P_{SRR}	Power supply rejection	$R_S \leq 10k\Omega$, over temp.		30	150		30	150	$\mu V/V$
R_{IN}	Input resistance		3	10		1	6		MΩ
A_{VOL}	Large signal voltage gain	$R_L \geq 2k\Omega$, $V_{OUT} = \pm 10V$	50	200		50	200		V/mV
A_{VOL}	Large signal voltage gain	Over temp., $R_L \geq 2k\Omega$, $V_{OUT} = \pm 10V$	25			25			V/mV
V_{OUT}	Output voltage	Over temp., $R_L \geq 2k\Omega$	±10	±13		±10	±13		V
V_{OUT}	Output voltage	Over temp., $R_L \geq 10k\Omega$	±12	±14		±12	±14		V
I_{CC}	Supply current	Per amplifier		2	3		2	3	mA
I_{CC}	Supply current	Over temp., per amplifier		2.2	3.6		2.2		mA
P_D	Power dissipation	Per amplifier		60	90		60	90	mW
P_D	Power dissipation	Over temp., per amplifier		66	108		66		mW
I_{SC}	Output short circuit current			25			25		mA
R_{OUT}	Output resistance			100			100		Ω

NOTE

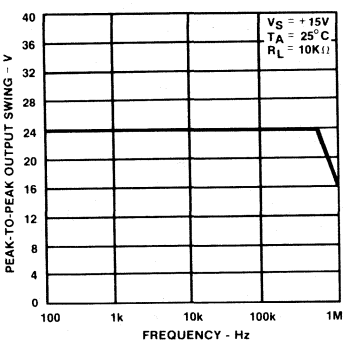
Temperature Range
SE Types $-55°C \leq T_A \leq 125°C$
NE Types $0°C \leq T_A \leq 70°C$

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

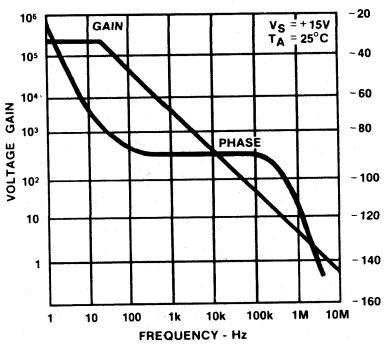
PARAMETER	TEST CONDITIONS	SE538/SE5538			SE538/NE5538			UNIT
		Min	Typ	Max	Min	Typ	Max	
Gain bandwidth product (Gain +5, -4 minimum)			6			6		MHz
Transient response Small signal rise time Small signal overshoot			0.25 6			0.25 6		μs %
Settling time	To 0.1%		1.2			1.2		μs
Slew rate	Minimum gain = 5 Noninverting $R_L \geq 2k\Omega$	40	60			60		V/μs

TYPICAL PERFORMANCE CHARACTERISTICS

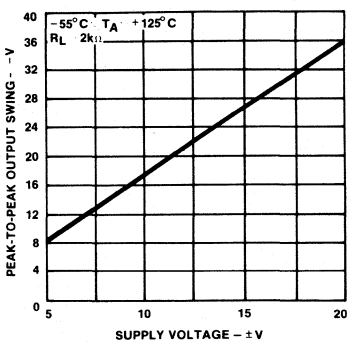
OUTPUT VOLTAGE SWING AS A FUNCTION OF FREQUENCY



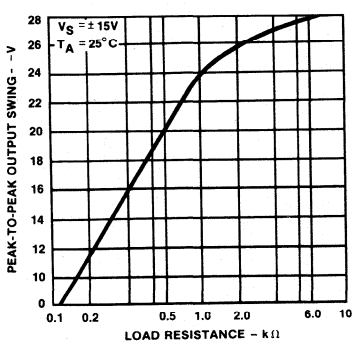
OPEN LOOP VOLTAGE GAIN AS A FUNCTION OF FREQUENCY



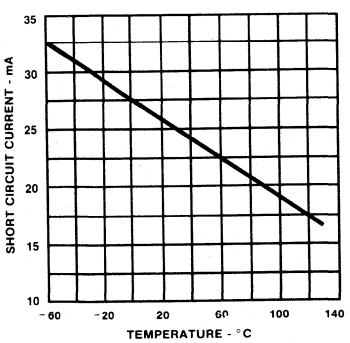
OUTPUT VOLTAGE SWING AS A FUNCTION OF SUPPLY VOLTAGE



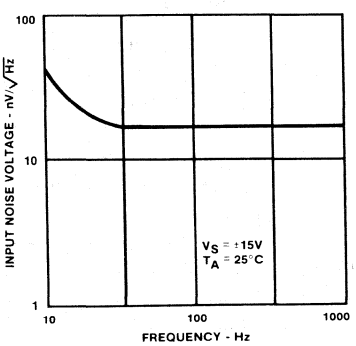
OUTPUT VOLTAGE SWING AS A FUNCTION OF LOAD RESISTANCE



OUTPUT SHORT-CIRCUIT CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE

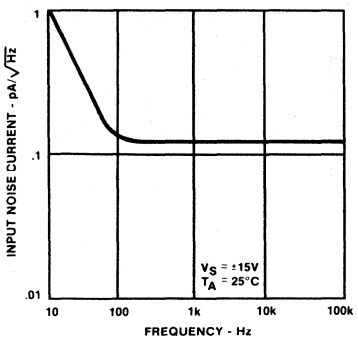


INPUT NOISE VOLTAGE AS A FUNCTION OF FREQUENCY

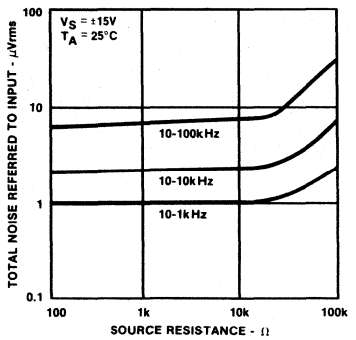


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

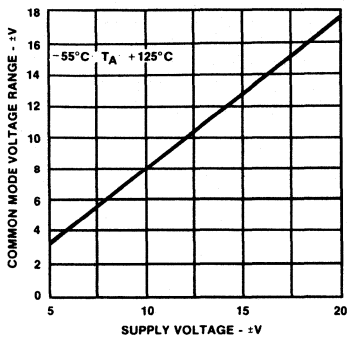
INPUT NOISE CURRENT AS A FUNCTION OF FREQUENCY



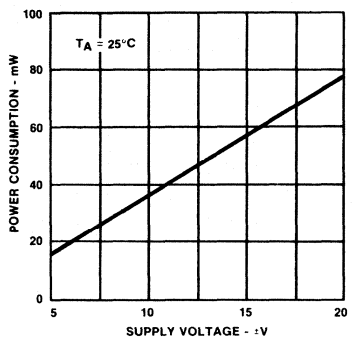
BROADBAND NOISE FOR VARIOUS BANDWIDTHS



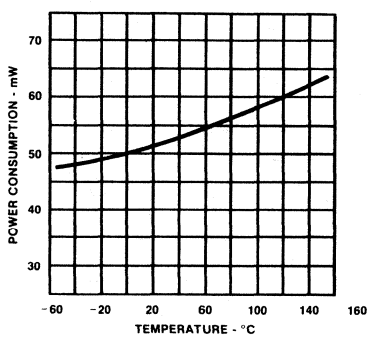
INPUT COMMON MODE VOLTAGE RANGE AS A FUNCTION OF SUPPLY VOLTAGE



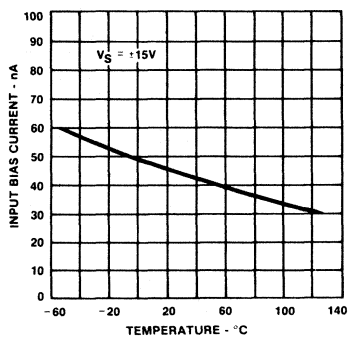
POWER CONSUMPTION AS A FUNCTION OF SUPPLY VOLTAGE



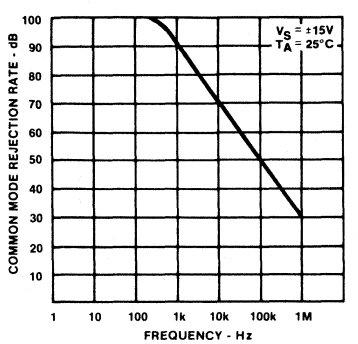
POWER CONSUMPTION AS A FUNCTION OF AMBIENT TEMPERATURE



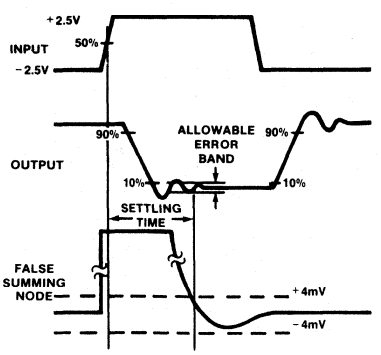
INPUT BIAS CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



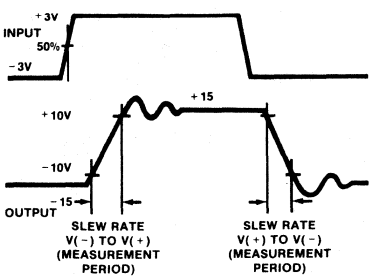
COMMON MODE REJECTION RATIO AS A FUNCTION OF FREQUENCY



SETTLING TIME MEASUREMENT WAVEFORMS

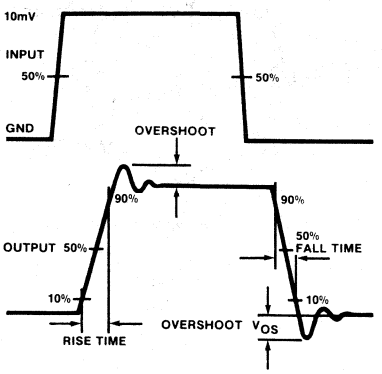


SLEW RATE MEASUREMENT VCC = ±20V



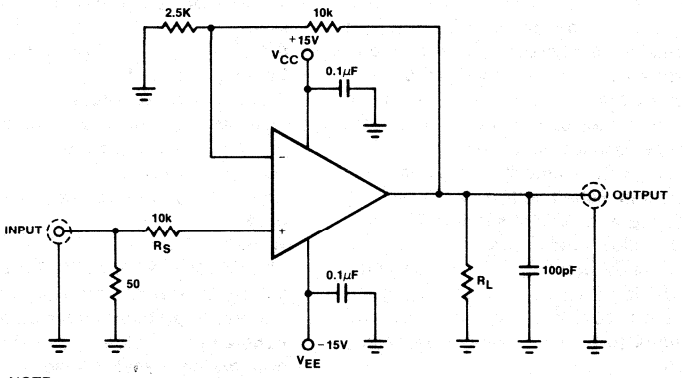
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

SMALL-SIGNAL TRANSIENT RESPONSE DEFINITIONS



TEST LOAD CIRCUITS

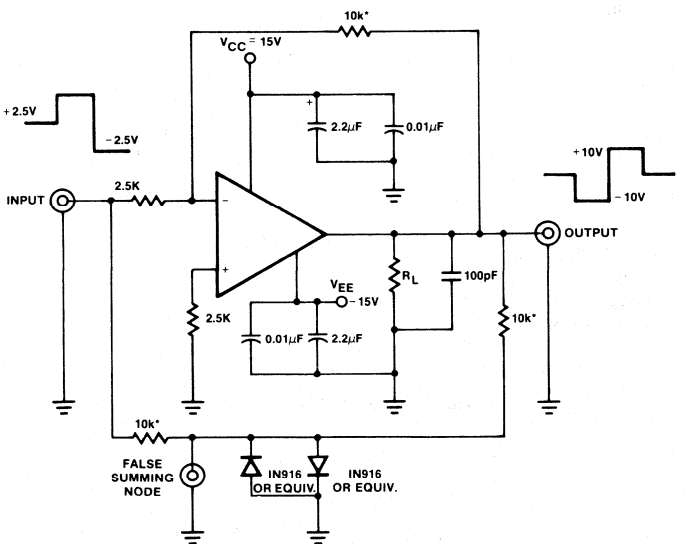
SLEW RATE AND SMALL SIGNAL TRANSIENT RESPONSE TEST CIRCUIT



NOTE
Pins not shown are not connected.
All resistors values are typical and in ohms.

TEST LOAD CIRCUITS (Cont'd)

SETTLING TIME TEST CIRCUIT



*Match to within 0.01%.
NOTE
Pins not shown are not connected.
All resistors values are typical and in ohms.

LF198/LF298/LF398-H

DESCRIPTION

The Signetics LF198/LF298/LF398 are monolithic sample and hold circuits which utilize high-voltage Ion-Inplant JFET technology to obtain ultra-high dc accuracy with fast acquisition of signal and low droop rate. Operating as a unity gain follower, dc gain accuracy is 0.002% typical and acquisition time is as low as 6μs to 0.01%. A bipolar input stage is used to achieve low offset voltage and wide bandwidth. Input offset adjust is accomplished with a single pin and does not degrade input offset drift. The wide bandwidth allows the LF198 to be included inside the feedback loop of 1MHz op amps without having stability problems. Input impedance of $10^{10}\Omega$ allows high source impedances to be used without degrading accuracy.

P-channel junction FET's are combined with bipolar devices in the output amplifier to give droop rates as low as 5mV/min with a 1μF hold capacitor. The JFET's have much lower noise than MOS devices used in previous designs and do not exhibit high temperature instabilities. The overall design guarantees no feed-through from input to output in the hold mode even for input signals equal to the supply voltages.

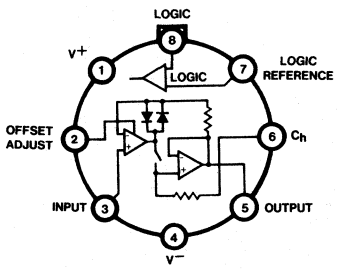
Logic inputs on the LF198 are fully differential with low input current, allowing direct connection to TTL, PMOS, and CMOS. Differential threshold is 1.4V. The LF198 will operate from ±5V to ±18V supplies. It is available in an 8-lead TO-5 package.

FEATURES

- **Operates from ±5V to ±18V supplies**
- **Less than 10μs acquisition time**
- **TTL, PMOS, CMOS compatible logic input**
- **0.5mV typical hold step at C_h = 0.01μF**
- **Low input offset**
- **0.002% gain accuracy**
- **Low output noise in hold mode**
- **Input characteristics do not change during hold mode**
- **High supply rejection ratio in sample or hold**
- **Wide bandwidth**
- **The LF198/LF298/LF398 are ideally suited for a wide variety of sample and hold applications including data acquisition, analog to digital conversion, synchronous demodulation, and automatic test setup.**

PIN CONFIGURATION

H PACKAGE



TOP VIEW

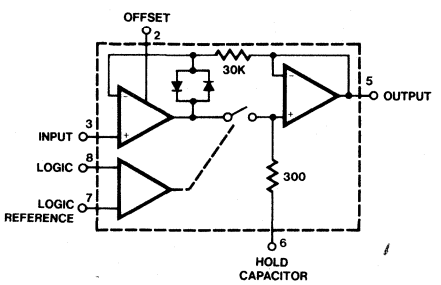
ORDER PART

NO. LF198H
LF298H
LF398H

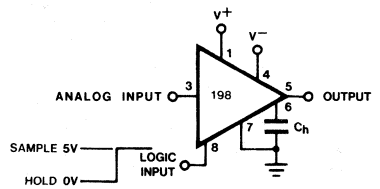
ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	±18	V
Power dissipation (package limitation)[1]	500	mW
Operating ambient temperature range		
LF198	−55 to +125	°C
LF298	−25 to +85	°C
LF398	0 to +70	°C
Storage temperature range	−65 to +150	°C
Input voltage	Equal to supply voltage	
Logic to logic reference differential voltage[2]	+7, −30	V
Output short circuit duration	Indefinite	
Hold capacitor short circuit duration	10	sec
Lead temperature (soldering, 10sec)	300	°C

FUNCTIONAL DIAGRAM



TYPICAL APPLICATIONS



DC ELECTRICAL CHARACTERISTICS Unless otherwise specified, the following conditions apply. Unit is in "sample" mode, $V_S = \pm 15V$, $T_j = 25°C$, $-11.5V \leq V_{IN} \leq +11.5V$, $C_h = 0.01\mu F$, and $R_L = 10k\Omega$. Logic reference voltage = OV and logic voltage = 2.5V.

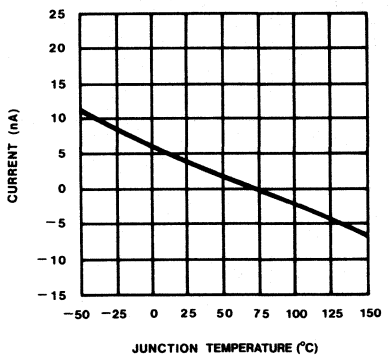
PARAMETER	TEST CONDITIONS	LF198/LF298			LF398			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input offset voltage [6]	$T_j = 25°C$ Full temperature range		1	3 5		2	7 10	mV mV
Input bias current [6]	$T_j = 25°C$ Full temperature range		5	25 75		10	50 100	nA nA
Input impedance	$T_j = 25°C$		10^{10}			10^{10}		Ω
Gain error	$T_j = 25°C$, $R_L = 10K$ Full temperature range		0.002	0.005 0.02		0.004	0.01 0.02	% %
Feedthrough attenuation ratio at 1kHz	$T_j = 25°C$, $C_h = 0.01\mu F$	86	96		80	90		dB
Output impedance	$T_j = 25°C$, "HOLD" mode Full temperature range		0.5	2 4		0.5	4 6	Ω Ω
"HOLD" step [4]	$T_j = 25°C$, $C_h = 0.01\mu F$, $V_{OUT} = 0$		0.5	2.0		1.0	2.5	mV
Supply current [6]	$T_j \geq 25°C$		4.5	5.5		4.5	6.5	mA
Logic and logic reference input current	$T_j = 25°C$		2	10		2	10	μA
Leakage current into hold capacitor [6]	$T_j = 25°C$ [5] Hold mode		30	100		30	200	pA
Acquisition time to 0.1%	$\Delta V_{OUT} = 10V$, $C_h = 1000pF$ $C_h = 0.01\mu F$		4 20			4 20		μs μs
Hold capacitor charging current	V_{IN}-$V_{OUT} = 2V$		5			5		mA
Supply voltage rejection ratio	$V_{OUT} = 0$	80	110		80	110		dB
Differential logic threshold	$T_j = 25°C$	0.8	1.4	2.4	0.8	1.4	2.4	V

NOTES

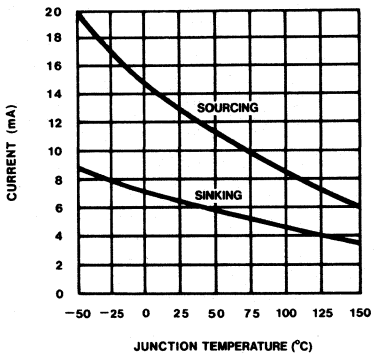
1. The maximum junction temperature of the LF198 is 150°C, for the LF298, 115°C, and for the LF398, 100°C. When operating at elevated ambient temperature, the TO-5 package must be derated based on a thermal resistance (ΘjA) of 150°C/W.
2. Although the differential voltage may not exceed the limits given, the common-mode voltage on the logic pins may be equal to the supply voltages without causing damage to the circuit. For proper logic operation, however, one of the logic pins must always be at least 2V below the positive supply and 3V above the negative supply.
3. Unless otherwise specified, the following conditions apply. Unit is in "sample" mode, $V_S = \pm 15V$, $T_j = 25°C$, $-11.5V \leq V_{IN} \leq +11.5V$, $C_h = 0.01\mu F$, and $R_L = 10k\Omega$. Logic reference voltage = OV and logic voltage = 2.5V.
4. Hold step is sensitive to stray capacitive coupling between input logic signals and the hold capacitor. 1pF, for instance, will create an additional 0.5mV step with a 5V logic swing and a 0.01μF hold capacitor. Magnitude of the hold step is inversely proportional to hold capacitor value.
5. Leakage current is measured at a junction temperature of 25°C. The effects of junction temperature rise due to power dissipation or elevated ambient can be calculated by doubling the 25°C value for each 11°C increase in chip temperature. Leakage is guaranteed over full input signal range.
6. The parameters guaranteed over a supply voltage of ±5 to ±18V.

TYPICAL DC PERFORMANCE CHARACTERISTICS

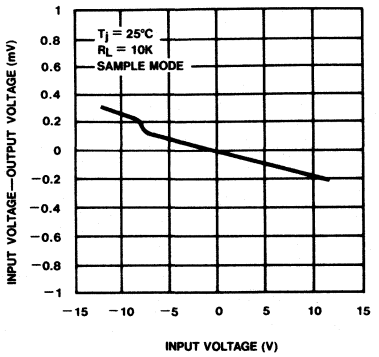
INPUT BIAS CURRENT



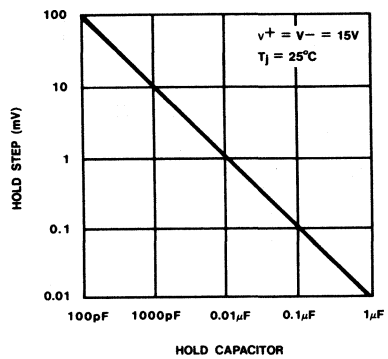
OUTPUT SHORT CIRCUIT CURRENT



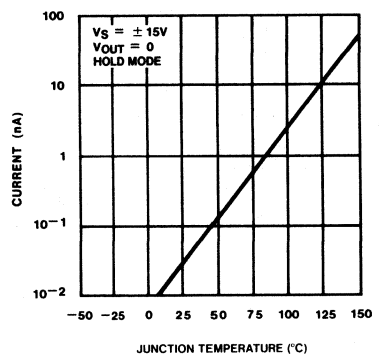
GAIN ERROR



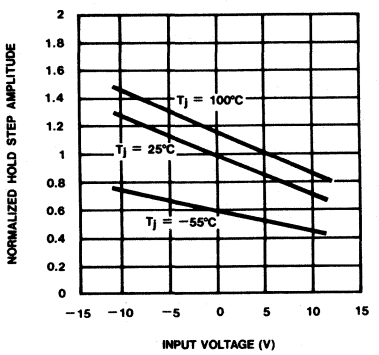
HOLD STEP



LEAKAGE CURRENT INTO HOLD CAPACITOR

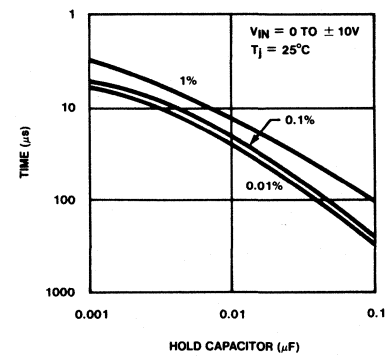


HOLD STEP INPUT VOLTAGE

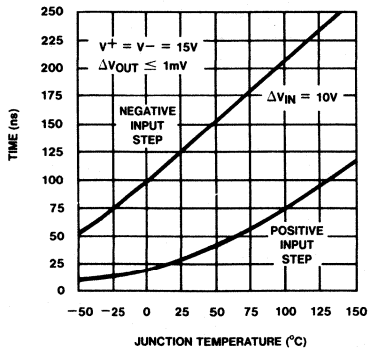


TYPICAL AC PERFORMANCE CHARACTERISTICS

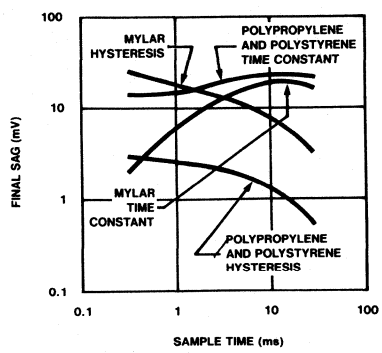
ACQUISITION TIME



APERTURE TIME

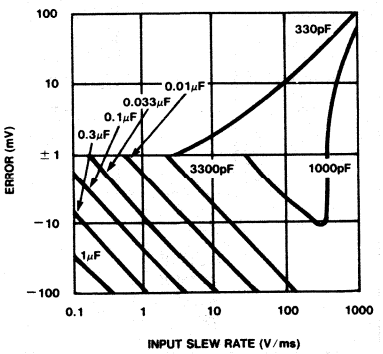


CAPACITOR HYSTERESIS

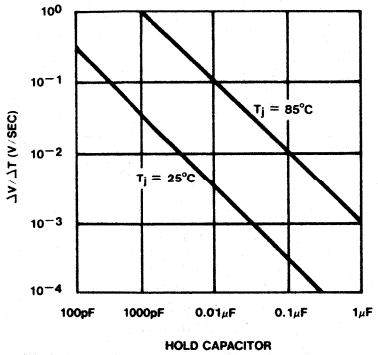


TYPICAL AC PERFORMANCE CHARACTERISTICS (cont'd)

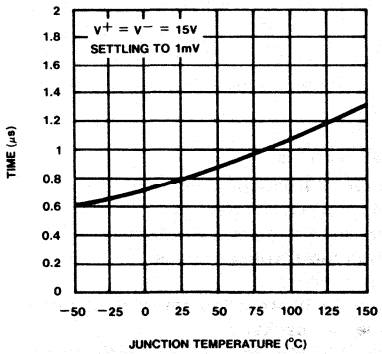
DYNAMIC SAMPLING ERROR



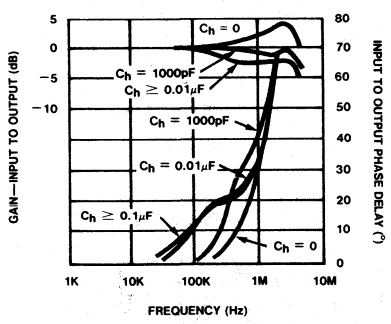
OUTPUT DROOP RATE



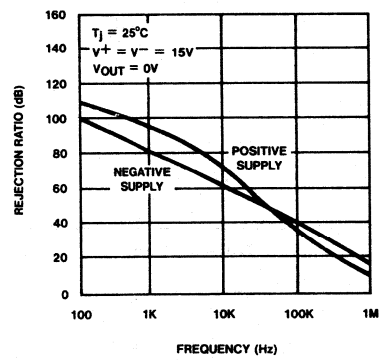
"HOLD" SETTLING TIME



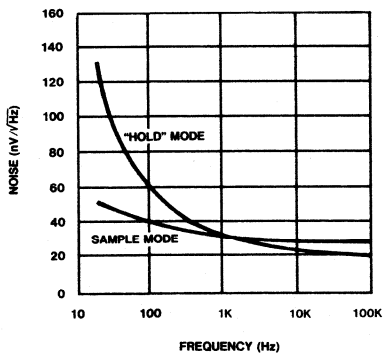
PHASE AND GAIN (INPUT TO OUTPUT, SMALL SIGNAL)



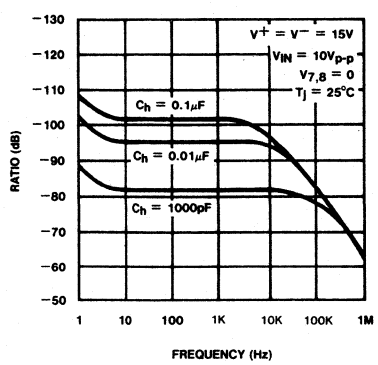
POWER SUPPLY REJECTION



OUTPUT NOISE



FEEDTHROUGH REJECTION RATIO (HOLD MODE)



μA741/741C,
MC1458/1558-F,N,H

DESCRIPTION

The μA741 is a high performance operational amplifier with high open loop gain, internal compensation, high common mode range and exceptional temperature stability. The μA741 is short-circuit protected and allows for nulling of offset voltage.

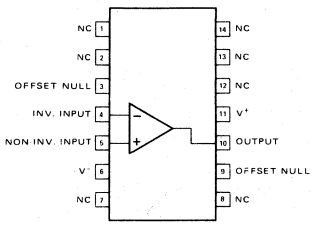
The MC1558/MC1458/SA1458 consist of a pair of 741 operational amplifiers on a single chip.

FEATURES

- **Internal frequency compensation**
- **Short circuit protection**
- **Excellent temperature stability**
- **High input voltage range**
- **No latch-up**
- **1558/1458 are 2 "op amps" in space of one 741 package**
- **MC1558 Mil std 883A,B,C available**
- **μA741 Mil std 883A,B,C available**

PIN CONFIGURATIONS

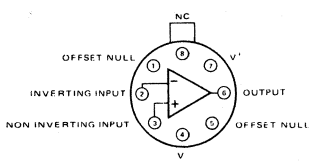
F,N-14 PACKAGE



ORDER PART NO.

μA741F
μA741N-14
μA741CF
μA741CN-14

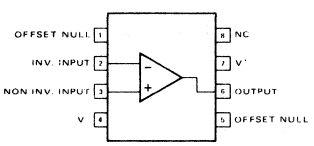
H PACKAGE



ORDER PART NO.

μA741H
μA741CH

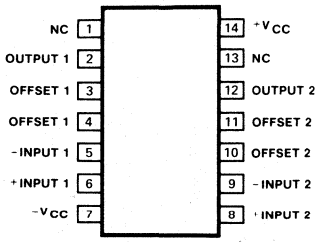
N PACKAGE



ORDER PART NO.

μA741N
μA741CN

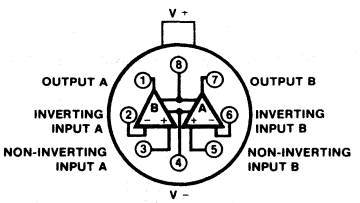
F,N-14 PACKAGE



ORDER PART NO.

MC1458F
MC1558F
MC1458N-14
MC1558N-14

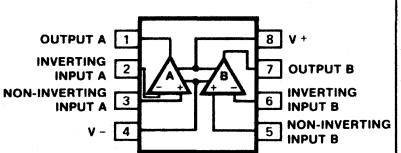
H PACKAGE



ORDER PART NO.

MC1458H
MC1558H

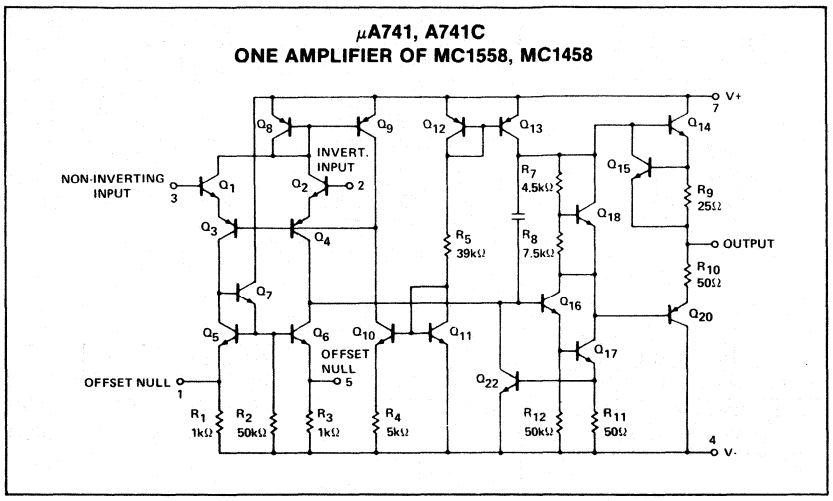
N PACKAGE



ORDER PART NO.

MC1458N
MC1558N

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
μA741C	±18	V
MC1458		
μA741, MC1558	±22	V
Internal power dissipation, N-14	600	mW
N package	500	mW
H package[1]	800	mW
F package	1000	mW
Differential input voltage	±30	V
Input voltage[2]	±15	V
Output short-circuit duration	Continuous	
Operating temperature range		
μA741C, MC1458	0 to +70	°C
	-40 to +85	°C
μA741, MC1558	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering 60sec)	300	°C

NOTES

1. Ratings based on thermal resistances, junction to ambient, of 208°C/W, 240°C/W, 150°C/W, 110°C/W for N-14, N, H and F packages respectively, and a maximum junction temperature of 150°C.
2. For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.

DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_S = \pm 15V$, unless otherwise specified.

PARAMETER		TEST CONDITIONS	μA741			μA741C			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OS}	Offset voltage	$R_S = 10k\Omega$ $R_S = 10k\Omega$, over temp.		1.0 1.0	5.0 6.0		2.0	6.0 7.5	mV mV
I_{OS}	Offset current	 Over temp. $T_A = +125°C$ $T_A = -55°C$		20 7.0 20	200 200 500		20	200 300 	nA nA nA nA
I_{BIAS}	Input bias current	 Over temp. $T_A = +125°C$ $T_A = -55°C$		80 30 300	500 500 1500		80	500 800 	nA nA nA nA
V_{OUT}	Output voltage swing	$R_L = 10k\Omega$ $R_L = 2k\Omega$, over temp.	±12 ±10	±14 ±13		±12 ±10	±14 ±13		V V
A_{VOL}	Large signal voltage gain	$R_L = 2k\Omega$, $V_O = \pm 10V$ $R_L = 2k\Omega$, $V_O = \pm 10V$, over temp.	50 25	200		20 15	200		V/mV V/mV
	Offset voltage adjustment range			±30			±30		mV
P_{SRR}	Supply voltage rejection ratio	$R_S \leq 10k\Omega$ $R_S \leq 10k\Omega$, over temp.		 10	 150		10	150	μV/V μV/V
CMRR	Common mode rejection ratio	 Over temp.	 70	 90					dB dB
I_{CC}	Supply current	 $T_A = +125°C$ $T_A = -55°C$		1.4 1.5 2.0	2.8 2.5 3.3		1.4	2.8	mA mA mA
V_{IN} R_{IN}	Input voltage range Input resistance	(μA741, over temp.)	±12 0.3	±13 2.0		±12 0.3	±13 2.0		V MΩ
P_d	Power consumption	 $T_A = +125°C$ $T_A = -55°C$		50 45 45	85 75 100		50	85	mW mW mW
R_{OUT} I_{SC}	Output resistance Output short-circuit current			75 25			75 25		Ω mA

μA741/741C,
MC1458/1558-F,N,H

DC ELECTRICAL CHARACTERISTICS (Cont'd) $T_A = 25°C$, $V_S = \pm 15V$, unless otherwise specified.

PARAMETER		TEST CONDITIONS	MC1558			UNIT
			Min	Typ	Max	
V_{OS}	Offset voltage	$R_S = 10k\Omega$ $R_S = 10k\Omega$, over temp.		1.0	5.0 6.0	mV mV
I_{OS}	Offset current	 Over temp.		20	200 500	nA nA
I_{BIAS}	Input bias current	 Over temp.		80	500 1500	nA nA
V_{OUT}	Output voltage swing	$R_L = 10k\Omega$ $R_L = 2k\Omega$, over temp.	±12 ±10	±14 ±13		V V
A_{VOL}	Large signal voltage gain	$R_L = 2k\Omega$, $V_O = \pm 10V$ $R_L = 2k\Omega$, $V_O = \pm 10V$, over temp.	50 25	100		V/mV V/mV
	Offset voltage adjustment range			±30		mV
P_{SRR}	Supply voltage rejection ratio	$R_S \leq 10k\Omega$		30	150	μV/V
CMRR	Common mode rejection ratio			70	90	dB
I_{CC}	Supply current			2.3	5.6	mA
V_{IN} R_{IN}	Input voltage range Input resistance	(μA741, over temp.)	±12	±13		V MΩ
P_d	Power consumption			70	150	mW
 R_{OUT} I_{SC}	Channel separation Output resistance Output short-circuit current			120 25		dB Ω mA

DC ELECTRICAL CHARACTERISTICS (Cont'd) $T_A = 25°C$, $V_S = \pm 15V$, unless otherwise specified.

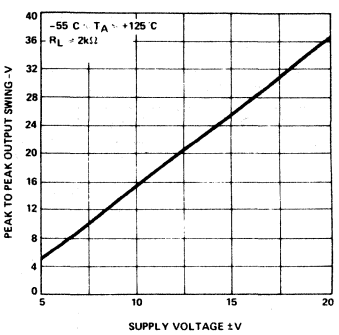
PARAMETER		TEST CONDITIONS	MC1458			UNIT
			Min	Typ	Max	
V_{OS}	Offset voltage	$R_S = 10k\Omega$ $R_S = 10k\Omega$, over temp.		2.0	6.0 7.5	mV mV
I_{OS}	Offset current	 Over temp.		20	200 300	nA nA
I_{BIAS}	Input bias current	 Over temp.		80	500 800	nA nA
V_{OUT}	Output voltage swing	$R_L = 10k\Omega$ $R_L = 2k\Omega$, over temp.	±12 ±10	±14 ±13		V V
A_{VOL}	Large signal voltage gain	$R_L = 2k\Omega$, $V_O = \pm 10V$ $R_L = 2k\Omega$, $V_O = \pm 10V$, over temp.	25 15	200		V/mV V/mV
	Offset voltage adjustment range			±30		mV
P_{SRR}	Supply voltage rejection ratio	$R_S \leq 10k\Omega$		30	170	μV/V
CMRR	Common mode rejection ratio			70	90	dB
I_{CC}	Supply current			2.3	5.0	mA
V_{IN} R_{IN}	Input voltage range Input resistance	(μA741, over temp.)	±12	±13		V MΩ
P_d	Power consumption			70	170	mW
 I_{SC}	Channel separation Output short-circuit current			120 25		dB mA

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $V_S = \pm 15V$, unless otherwise specified.

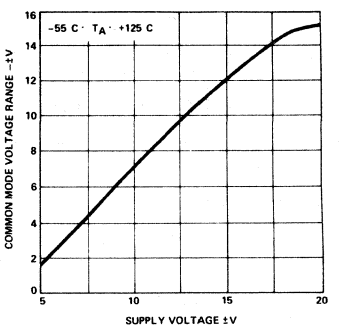
PARAMETER	TEST CONDITIONS	μA741, μA741C			MC1558, MC1458			UNIT
		Min	Typ	Max	Min	Typ	Max	
Parallel input resistance	Open loop, f = 20Hz				0.3			MΩ
Parallel input capacitance	Open loop, f = 20Hz		1.4					pF
Common mode input impedance	f = 20Hz					200		MΩ
Equivalent input noise voltage	A_V = 100, R_S = 10kΩ, B_W = 1.0kHz f = 1.0kHz					45		$nV\sqrt{Hz}$
Power bandwidth	A_V = 1, R_L = 2.0kΩ, THD ≤ 5% V_{OUT} = 20Vp-p					14		kHz
Phase margin						65		degrees
Gain margin						11		dB
Unity gain crossover frequency	Open loop		1.0			1.0		MHz
Transient response unity gain	V_{IN} = 20mV, R_L = 2kΩ, C_L ≤ 100pf							
Rise time			0.3			0.3		μs
Overshoot			5.0			5.0		%
Slew rate	C ≤ 100pf, R_L ≥ 2k, V_{IN} = ±10V		0.5			0.8		V/μs

TYPICAL PERFORMANCE CHARACTERISTICS

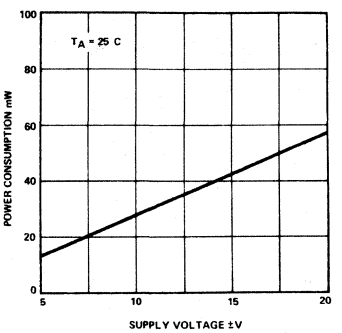
OUTPUT VOLTAGE SWING AS A FUNCTION OF SUPPLY VOLTAGE



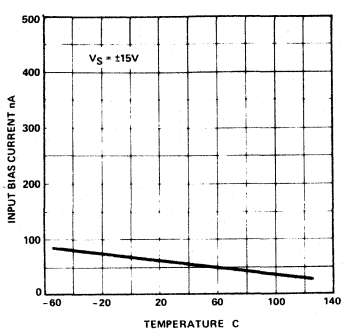
INPUT COMMON MODE VOLTAGE RANGE AS A FUNCTION OF SUPPLY VOLTAGE



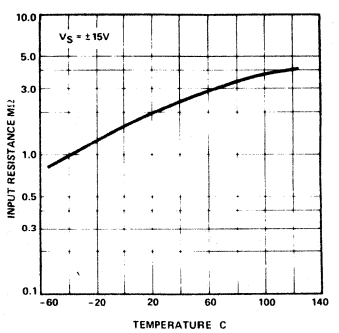
POWER CONSUMPTION AS A FUNCTION OF SUPPLY VOLTAGE



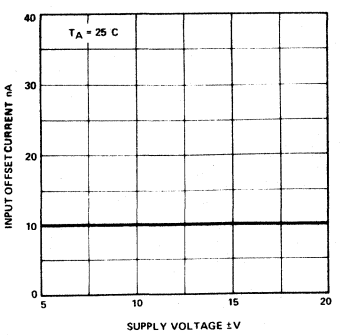
INPUT BIAS CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



INPUT RESISTANCE AS A FUNCTION OF AMBIENT TEMPERATURE

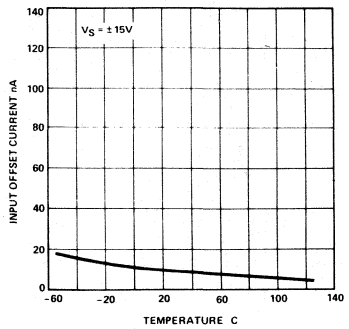


INPUT OFFSET CURRENT AS A FUNCTION OF SUPPLY VOLTAGE

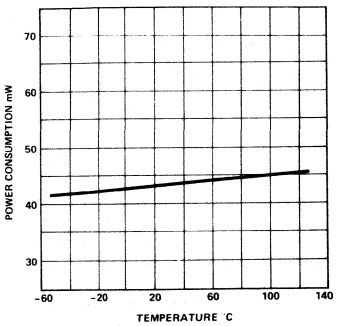


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

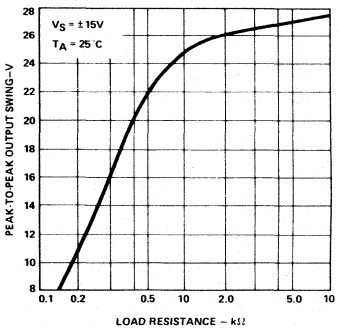
INPUT OFFSET CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



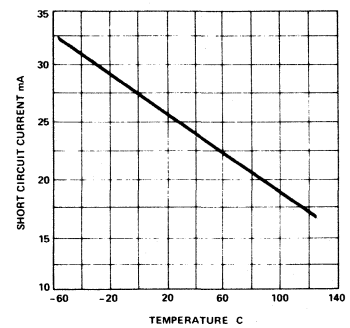
POWER CONSUMPTION AS A FUNCTION OF AMBIENT TEMPERATURE



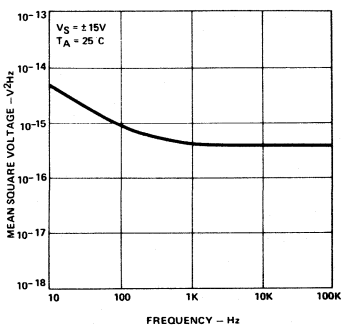
OUTPUT VOLTAGE SWING AS A FUNCTION OF LOAD RESISTANCE



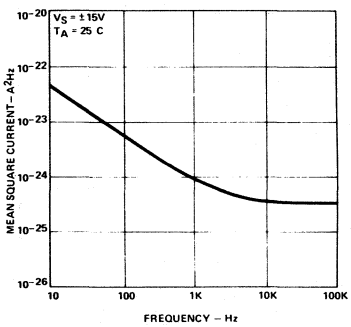
OUTPUT SHORT-CIRCUIT CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE



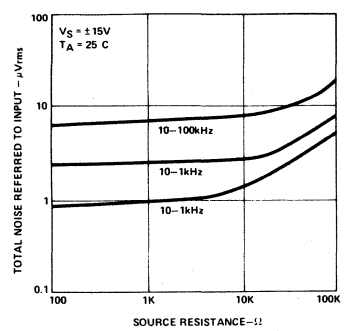
INPUT NOISE VOLTAGE AS A FUNCTION OF FREQUENCY



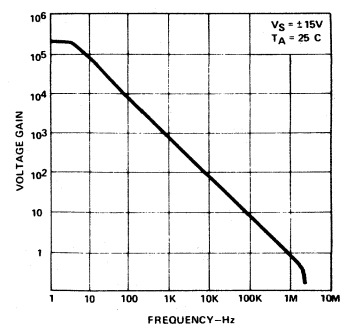
INPUT NOISE CURRENT AS A FUNCTION OF FREQUENCY



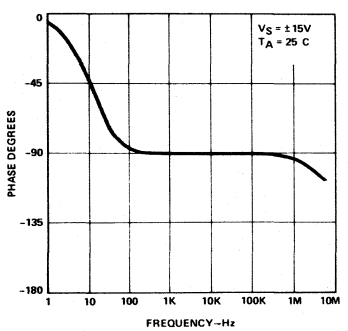
BROADBAND NOISE FOR VARIOUS BANDWIDTHS



OPEN LOOP VOLTAGE GAIN AS A FUNCTION OF FREQUENCY

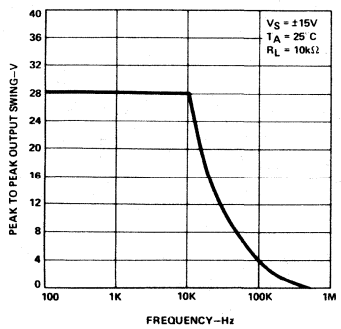


OPEN LOOP PHASE RESPONSE AS A FUNCTION OF FREQUENCY

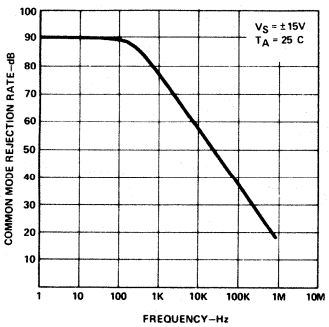


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

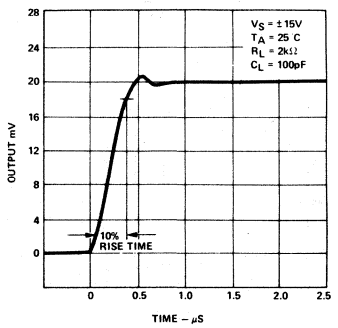
OUTPUT VOLTAGE SWING AS A FUNCTION OF FREQUENCY



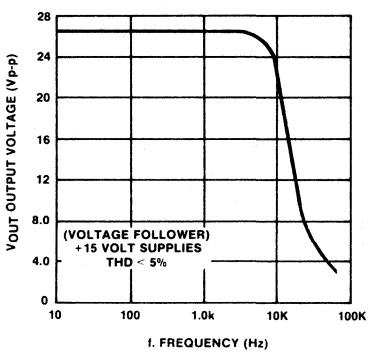
COMMON MODE REJECTION RATIO AS A FUNCTION OF FREQUENCY



TRANSIENT RESPONSE



POWER BANDWIDTH (Large Signal Swing vs Frequency)



SECTION 2
VIDEO AMPLIFIERS

Section 2—VIDEO AMPLIFIERS

**See NE/SE592 for pin to pin replacement.

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

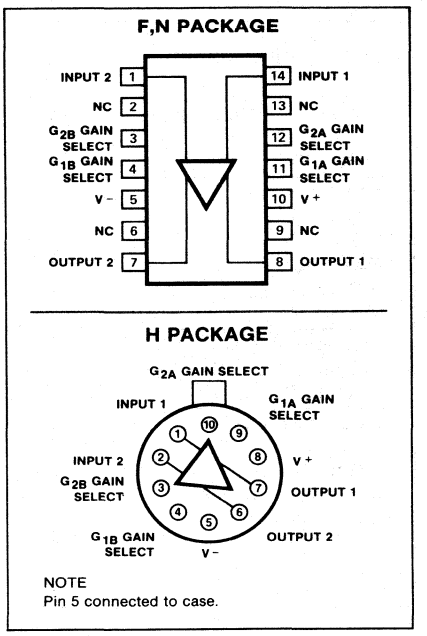
DESCRIPTION

The SE/NE592 is a monolithic, two stage, differential output, wideband video amplifier. It offers fixed gains of 100 and 400 without external components and adjustable gains from 400 to 0 with one external resistor. The input stage has been designed so that with the addition of a few external reactive elements between the gain select terminals, the circuit can function as a high pass, low pass, or band pass filter. This feature makes the circuit ideal for use as a video or pulse amplifier in communications, magnetic memories, display and video recorder systems. The 592 is a pin-for-pin replacement for the μA733.

FEATURES

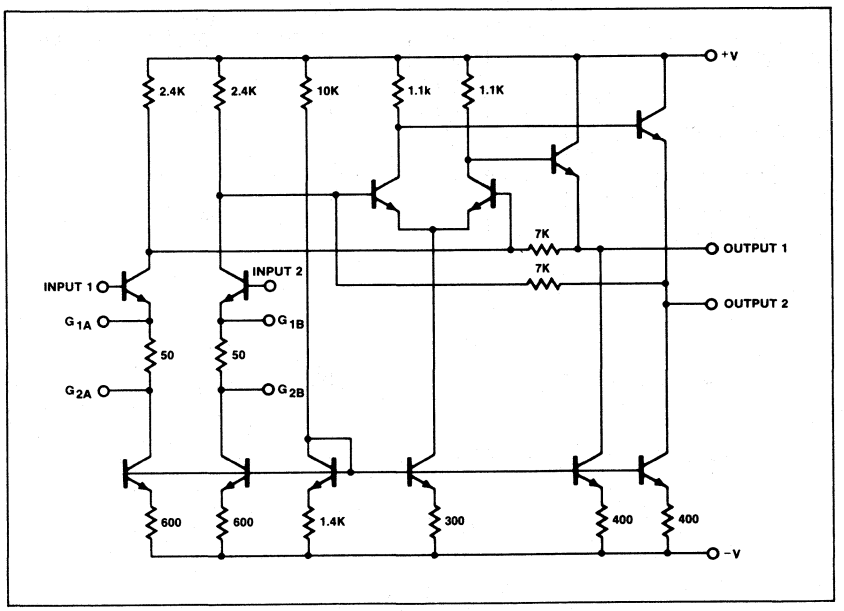
- **120MHz bandwidth**
- **Adjustable gains from 0 to 400**
- **Adjustable pass band**
- **No frequency compensation required**
- **Wave shaping with minimal external components**

PIN CONFIGURATION



NOTE
Pin 5 connected to case.

EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise specified.

PARAMETER	RATING	UNIT
Supply voltage	±8	V
Differential input voltage	±5	V
Common mode Input voltage	±6	V
Output current	10	mA
Operating temperature range		
SE592K	-55 to +125	°C
NE592K	0 to +70	°C
Storage temperature range	-65 to +150	°C
Power dissipation	500	mW

DC ELECTRICAL CHARACTERISTICS

T_A = +25°C, V_S = ±6V, V_{CM} = 0 unless otherwise specified
Recommend operating supply voltages V_S = ±6.0V

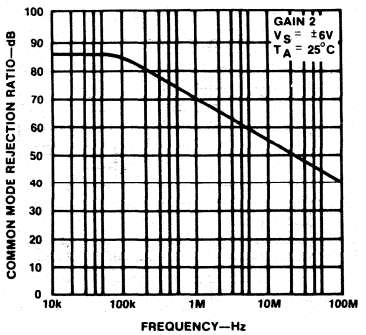
PARAMETER	TEST CONDITIONS	NE592			SE592			UNITS
		Min	Typ	Max	Min	Typ	Max	
Differential voltage gain								
Gain 1[1]	R_L = 2kΩ, V_{OUT} = 3V p-p	250	400	600	300	400	500	V/V
Gain 2[2]		80	100	120	90	100	110	V/V
Bandwidth								
Gain 1[1]			40			40		MHz
Gain 2[2]			90			90		MHz
Rise time								
Gain 1[1]	V_{OUT} = 1V p-p		10.5			10.5		ns
Gain 2[2]			4.5	12		4.5	10	ns
Propagation delay								
Gain 1[1]	V_{OUT} = 1V p-p		7.5			7.5		ns
Gain 2[2]			6.0	10		6.0	10	ns
Input resistance								
Gain 1[1]			4.0			4.0		kΩ
Gain 2[2]		10	30		20	30		kΩ
Input capacitance[2]	Gain 2		2.0			2.0		pF
Input offset current			0.4	5.0		0.4	3.0	μA
Input bias current			9.0	30		9.0	20	μA
Input noise voltage	BW 1kHz to 10kHz		12			12		μVrms
Input voltage range				±1.0			±1.0	V
Common mode rejection ratio								
Gain 2	VCM ±1V,F < 100kHz	60	86		60	86		dB
Gain 2	VCM ±1V,F = 5MHz		60			60		dB
Supply voltage rejection ratio								
Gain 2	ΔVS = ±0.5V	50	70		50	70		dB
Output offset voltage								
Gain 3[3]	R_L = ∞		0.35	0.75		0.35	0.75	V
Output common mode voltage	R_L = ∞	2.4	2.9	3.4	2.4	2.9	3.4	V
Ouptut voltage swing	R_L = 2K	3.0	4.0		3.0	4.0		
Ouput resistance			20			20		Ω
Power supply current	R_L = ∞		18	24		18	24	mA

NOTES

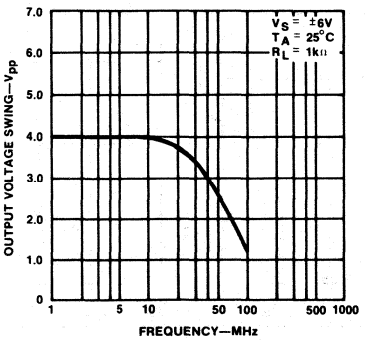
1. Gain select pins G_{1A} and G_{1B} connected together.
2. Gain select pins G_{2A} and G_{2B} connected together.
3. All gain select pins open.

TYPICAL PERFORMANCE CHARACTERISTICS

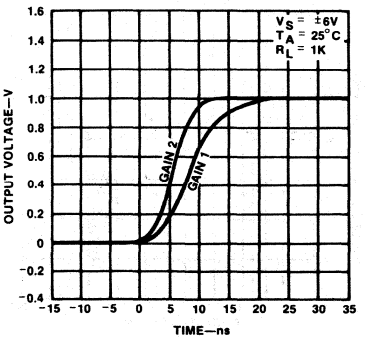
COMMON MODE REJECTION RATIO AS A FUNCTION OF FREQUENCY



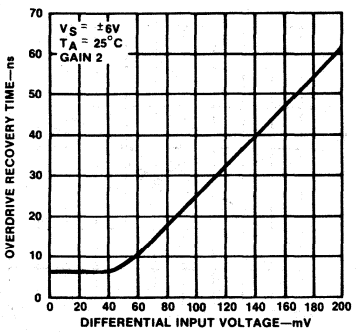
OUTPUT VOLTAGE SWING AS A FUNCTION OF FREQUENCY



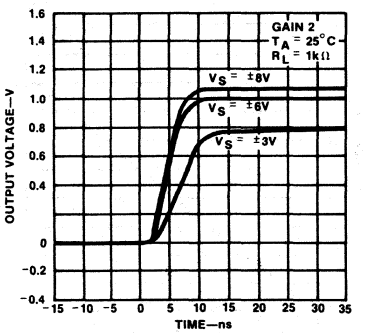
PULSE RESPONSE



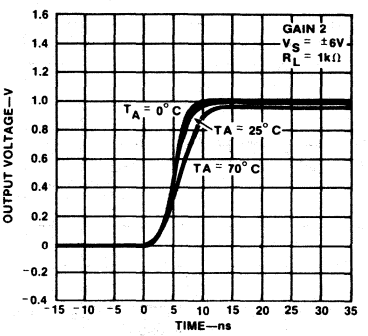
DIFFERENTIAL OVERDRIVE RECOVERY TIME



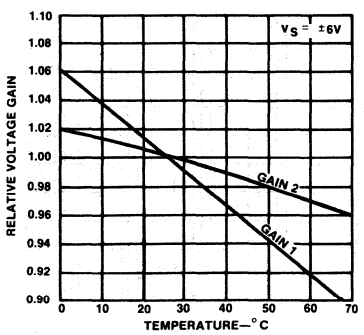
PULSE RESPONSE AS A FUNCTION OF SUPPLY VOLTAGE



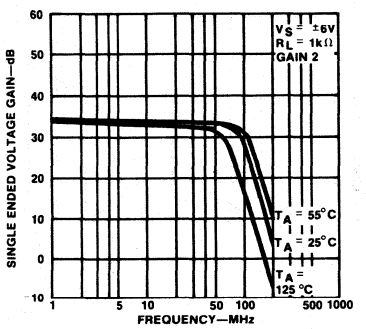
PULSE RESPONSE AS A FUNCTION OF TEMPERATURE



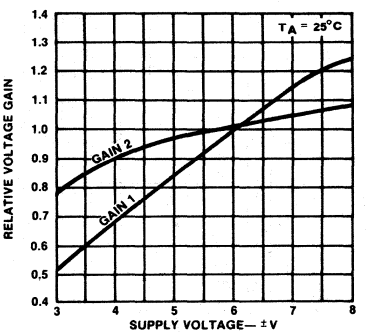
VOLTAGE GAIN AS A FUNCTION OF TEMPERATURE



GAIN vs FREQUENCY AS A FUNCTION OF TEMPERATURE

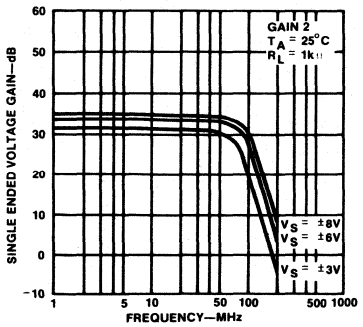


VOLTAGE GAIN AS A FUNCTION OF SUPPLY VOLTAGE

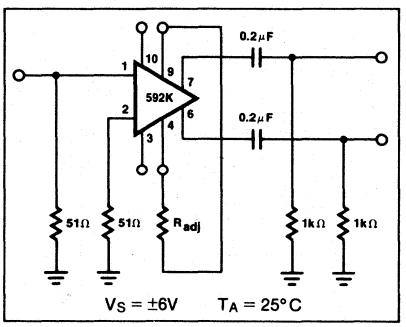


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

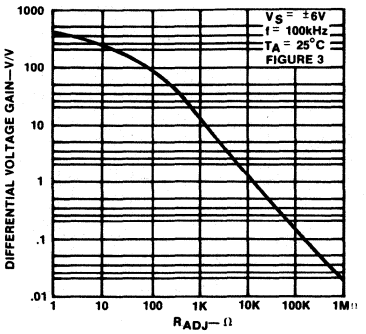
GAIN vs FREQUENCY AS A FUNCTION OF SUPPLY VOLTAGE



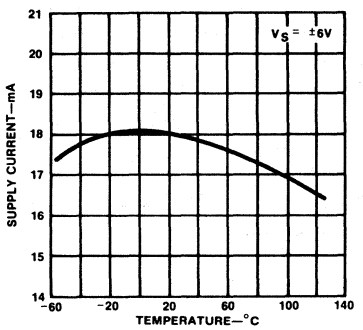
VOLTAGE GAIN ADJUST CIRCUIT



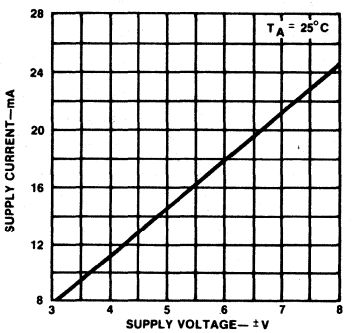
VOLTAGE GAIN AS A FUNCTION OF RADJ (FIGURE 3)



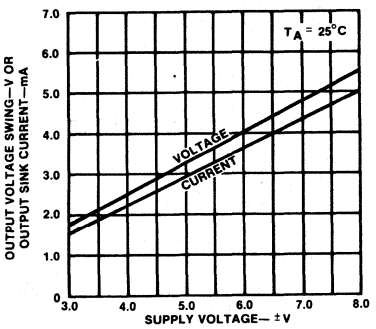
SUPPLY CURRENT AS A FUNCTION OF TEMPERATURE



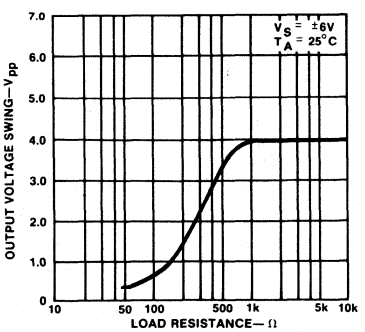
SUPPLY CURRENT AS A FUNCTION OF SUPPLY VOLTAGE



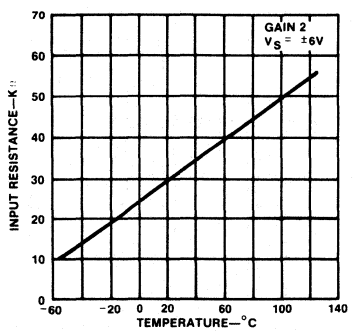
OUTPUT VOLTAGE AND CURRENT SWING AS A FUNCTION OF SUPPLY VOLTAGE



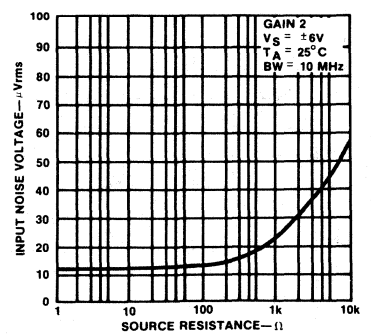
OUTPUT VOLTAGE SWING AS A FUNCTION OF LOAD RESISTANCE



INPUT RESISTANCE AS A FUNCTION OF TEMPERATURE

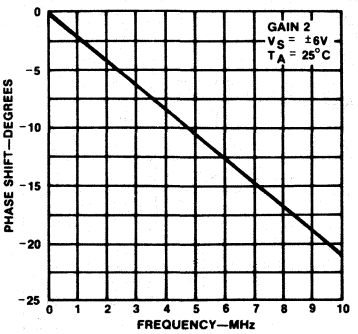


INPUT NOISE VOLTAGE AS A FUNCTION OF SOURCE RESISTANCE

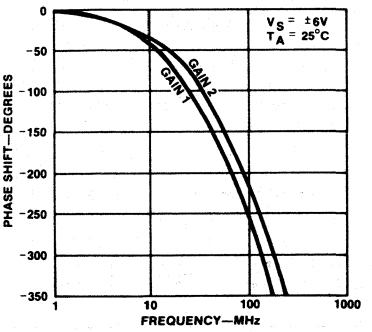


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

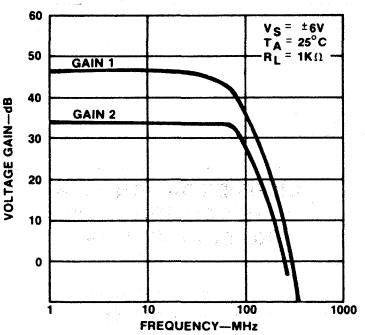
PHASE SHIFT AS A FUNCTION OF FREQUENCY



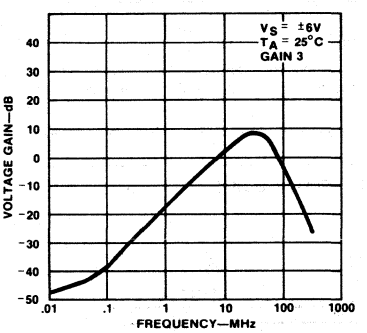
PHASE SHIFT AS A FUNCTION OF FREQUENCY



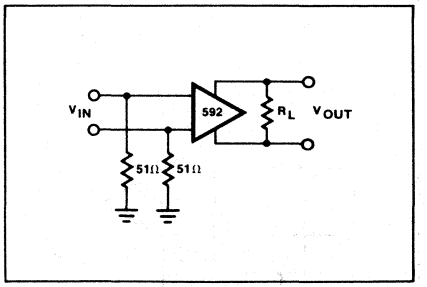
VOLTAGE GAIN AS A FUNCTION OF FREQUENCY

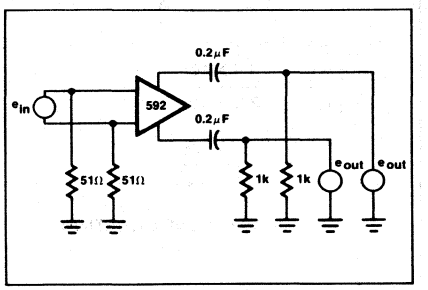


VOLTAGE GAIN AS A FUNCTION OF FREQUENCY (ALL GAIN SELECT PINS OPEN)



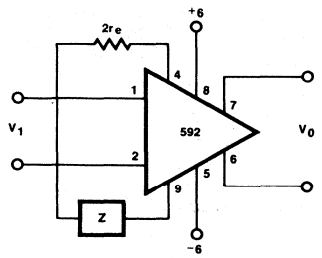
TEST CIRCUITS T_A = 25° C unless otherwise specified





TYPICAL APPLICATIONS

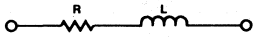
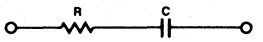
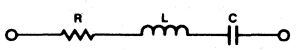
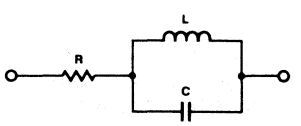
FILTER NETWORKS



$$\frac{V_0(s)}{V_1(s)} \cong \frac{1.4 \times 10^4}{Z(s) + 2r_e}$$

$$\cong \frac{1.4 \times 10^4}{Z(s) + 32}$$

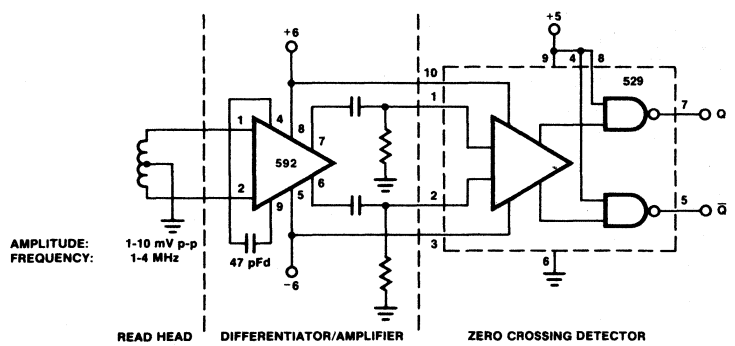
BASIC CONFIGURATION

Z NETWORK	FILTER TYPE	V_0 (s) TRANSFER V_1 (s) FUNCTION
	LOW PASS	$\frac{1.4 \times 10^4}{L}\left[\frac{1}{s + R/L}\right]$
	HIGH PASS	$\frac{1.4 \times 10^4}{R}\left[\frac{s}{s + 1/RC}\right]$
	BAND PASS	$\frac{1.4 \times 10^4}{L}\left[\frac{s}{s^2 + R/L\, s + 1/LC}\right]$
	BAND REJECT	$\frac{1.4 \times 10^4}{R}\left[\frac{s^2 + 1/LC}{s^2 + 1/LC + s/RC}\right]$

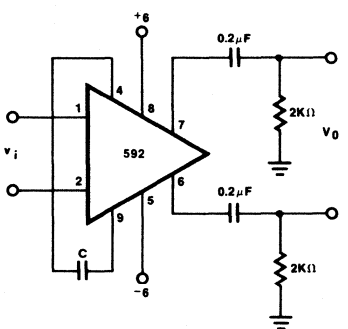
NOTE

In the networks above, the R value used is assumed to include $2r_e$, or approximately 32Ω.

DISC/TAPE PHASE MODULATED READBACK SYSTEMS



DIFFERENTIATION WITH HIGH COMMON MODE NOISE REJECTION



FOR FREQUENCY $F_1 << 1/2\,\pi\,(32)\,C$

$V_0 \cong 1.4 \times 10^4 C \frac{dVi}{dT}$

SECTION 3
VOLTAGE REGULATORS

Section 3—VOLTAGE REGULATORS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

VOLTAGE REGULATOR DEFINITIONS

T_A
Ambient temperature range. Range of the surrounding environment of the operating device.

T_J
Junction Temperature. The maximum temperature of the device. 150°C is standard for silicon devices.

T_{STG}
Storage temperature range. Temperature range that the device can be stored in a non-operating condition.

T_{SOLD}
Soldering Temperature. The temperature which can be applied to the lead frame of the device for short periods of time (normally specified for a duration of 10 sec).

Truth Tables
0 is logic level low
1 is logic level high
X - don't care condition - has no effect under circuit conditions listed.

Absolute Maximum Rating
Operating safe zones exceeding these limits could cause permanent damage to the device and are not meant to imply that devices can operate at these limits.

Power Dissipation
The power that the device can safely handle at 25°C. The dissipation must be derated as indicated for the individual package type.

Package Type Designation
See full package designations in Appendix.

V_{CC} ($-V_{CC}$)
Supply Voltage. The range of power supply voltage over which the device will operate safely.

Line Regulation
Sometimes referred to as "static regulation". This term refers to the changes in the output as the input is varied slowly from its rated minimum value to its rated maximum value (from 105 VAC_{RMS} to 125 VAC_{RMS}). Measured in mv/V.

Load Regulation
Sometimes referred to as "dynamic regulation". This term refers to the changes in the output when load conditions are suddenly changed (from no load to full load). Measured in mv/V.

Thermal Regulation
Referred to as changes due to ambient variations or thermal drift. Also referred to as temperature coefficient, measured in ppm/°C or mv/°C.

Transient Response
The ability of a regulator to respond to rapid changes in line variations, load variations, or intermittent transient input conditions. (Transient Response is often referred to as "recovery time"). Measured in milliseconds (ms).

Voltage Limiting
The ability of the regulator to "shut down" in the event that the internal reference sources fail to function properly. Measured in Volts.

Current Limiting
The ability of the amplified segment to limit the output current of the device when safe operating limits are exceeded. Measured in amperes (pre-determined).

Thermal Shutdown
The ability of the regulator to shut itself down when the maximum die temperature is exceeded. Measured in degrees Celsius (C).

Power Dissipation
The ability of the regulator to tolerate excessively high levels of input power while maintaining its operation within the safe operating area of its active devices. Measured in watts.

Efficiency
Regarding a regulator, the ratio of the total power input to the usable power output. Expressed as a percentage. (For example, if a regulator has a 50 watt input and a 40 watt output, its efficiency is 80 percent).

EMI/RFI
("Electromagnetic Interference/Radio Frequency Interference") regarding regulators, magnetic field disturbance and radio frequency interference signals generated especially by SMPS devices. Measurement is generally unspecified.

Safe Operating Area Restriction (SOAR)
Limits the output current of the amplifier to maintain safe (no thermal runaway) operating conditions. (Accomplished through internal sensor amplifiers).

NOTE
Refer to Section 4 of Analog Applications Manual for an in-depth explanation of Voltage Regulators

DUAL TRACKING VOLTAGE REGULATOR

COMPETITION	INDUSTRY VALUE	KEY PARAMETER	SIGNETICS AVAILABLE VALUE	SIGNETICS ORIGINATED DEVICES	QR&A		COMMENTS
					SURE II	SUPR II	
NATIONAL MOTOROLA RAYTHEON		Line Regulator	1 %	SE/NE 555X	Yes		I_{OUT} 400mA
LM125, −6, −7	0.1 %	Line Regulator	0.25 %				
Raytheon 4194	±.05 to ±40	V_{OUT}	± 5 to ±20 Volts	SE/NE 5553/4	Yes		
Motorola 1568	100 mA	I_{OUT}	±400 mA	SE/NE 5553/4			
		Package Power Dissipation	8 Watts	SE, NE { 5553/4 Series in SIL-9 package			

3

DESCRIPTION

The NE/SE5553,4 are dual polarity tracking regulators designed to produce balanced or unbalanced output voltages from 5 to 20 volts with up to 300 mA output current. Similar in specifications to the 78MXX and 79MXX fixed regulators, the 5551 series can be continuously adjusted, balanced or unbalanced. Standard fixed voltages available are ±5, ±6, ±12, ±15, and +5, -12 volts. Employing current limiting and thermal shutdown protection, these dual polarity regulators are ideal for local on-card regulation.

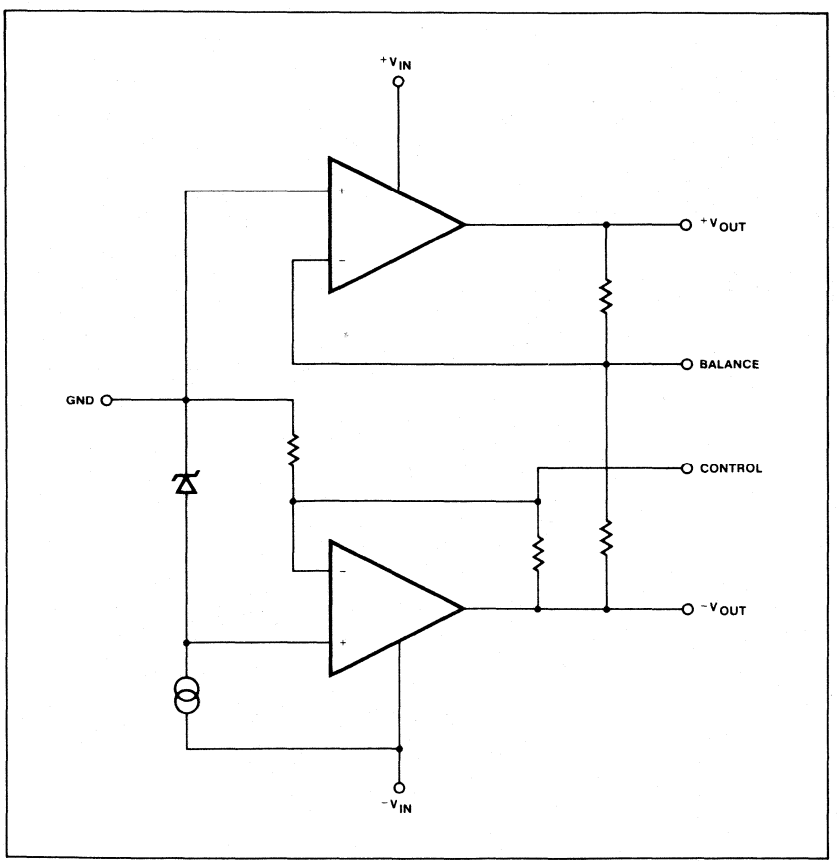
FEATURES

- **Output current to 300mA**
- **Internally current limited**
- **Thermal overload protected**
- **Input voltage to ±32V**
- **Output balance 1% typ.**
- **External balance control**
- **Continuously adjustable from 5 to 20 volts, balanced or unbalanced**
- **No external components required**
- **Short circuit current 400mA**
- **Heat sink available for increased power dissipation**

ABSOLUTE MAXIMUM RATINGS

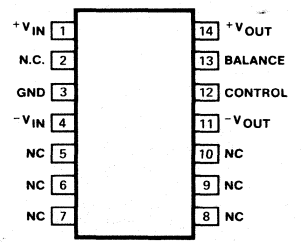
PARAMETER	RATING	UNIT
V_{IN} input voltage	±32	V
T_{SG} storage temperature	-65 to +150	°C
T_J operating junction temperature		
NE5553,4	0 to +125	°C
SE5553,4	-55 to +150	°C
Lead temperature 10 sec.	300	°C

BLOCK DIAGRAM



PIN CONFIGURATIONS

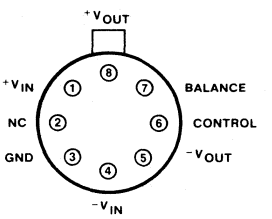
N PACKAGE



ORDER PART NUMBERS

VOLTAGE	PART NO.
±12V	SE/NE5553N
±15V	SE/NE5554N

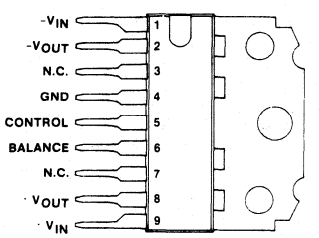
H PACKAGE



ORDER PART NUMBERS

VOLTAGE	PART NO.
±12V	SE/NE5553H
±15V	SE/NE5554H

U PACKAGE



ORDER PART NUMBERS

VOLTAGE	PART NO.
±12V	SE/NE 5553 U
±15V	SE/NE 5554 U

Power dissipation (without heat sink)

H Package: Θ_{JC} = 20°C/W Θ_{JA} = 150°

N Package: Θ_{JC} = 33°C/W Θ_{JA} = 95°

U Package: Θ_{JC} = 30°C/W Θ_{JA} = 62°

DC ELECTRICAL CHARACTERISTICS

PARAMETER		TEST CONDITIONS	SE5553			NE5553			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OUT}	Output voltage		+11.5 -12.5	+12 -12	+12.5 -11.5	+11.5 -12.5	+12 -12	+12.5 -11.5	V
	Line regulation Load regulation	$\pm 20 \le V_{IN} \le \pm 30V$ $1mA \le I_{Load} \le 50mA$ $1mA \le I_{Load} \le 200mA$		100 10 30	150 25 100		100 10 30	300 50 200	mV mV mV
V_{OUT}	Output voltage	$1mA \le I_L \le 100mA$ $\pm 20V \le V_{IN} \le \pm 30V$ over temp.[1]	+11.4 -12.6	+12 -12	+12.6 -11.4	+11.4 -12.6	+12 -12	+12.6 -11.4	V V
I_{Q+} I_{Q-}	Positive quiescent current Negative quiescent current	$I_{Load} = 0$ $I_{Load} = 0$		1.70 5.60	3.5 8.5		1.70 5.60	3.5 8.5	mA mA
V_{BAL}	Input/output differential voltage Output voltage balance Output noise voltage	100Hz to 10kHz		2.5 .2 55			2.5 .2 55		V V μVrms
I_{Peak}	Peak output current Temperature stability of output voltage			400 1			400 1		mA mV/°C

DC ELECTRICAL CHARACTERISTICS (Cont'd) $V_{IN} = \pm 20V$, $I_L = 100mA$, $T_J = 25°C$, $C_{IN} = C_{OUT} = 0.1\mu F$ unless otherwise specified.

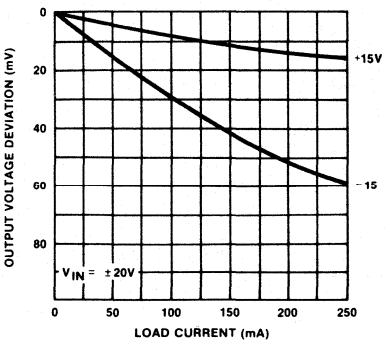
PARAMETER		TEST CONDITIONS	SE5554			NE5554			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{OUT}	Output voltage		+14.4 -15.6	+15 -15	+15.6 -14.4	+14.4 -15.6	+15 -15	+15.6 -14.4	V
	Line regulation Load regulation	$\pm 20 \le V_{IN} \le \pm 30V$ $1mA \le I_{Load} \le 50mA$ $1mA \le I_{Load} \le 200mA$		100 10 30	150 25 100		100 10 30	300 50 200	mV mV mV
V_{OUT}	Output voltage	$1mA \le I_L \le 100mA$ $\pm 20V \le V_{IN} \le \pm 30V$ over temp.[1]	+14.25 -15.75	+15 -15	+15.75 -14.25	+14.25 -15.75	+15 -15	+15.75 -14.25	V V
I_{Q+} I_{Q-}	Positive quiescent current Negative quiescent current	$I_{Load} = 0$ $I_{Load} = 0$		1.70 5.60	3.5 8.5		1.70 5.60	3.5 8.5	mA mA
V_{BAL}	Input/output differential voltage Output voltage balance Output noise voltage	100Hz to 10kHz		2.5 .2 55			2.5 .2 55		V V μVrms
I_{Peak}	Peak output current Temperature stability of output voltage			400 1			400 1		mA mV/°C

NOTES

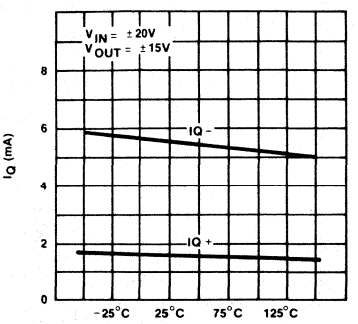
1. Junction temperature range
   SE prefix -55°C < T_J < 150°C
   NE prefix 0°C < T_J < 125°C
2. C_{IN} needed only when isolated from filter capacitors
   C_{OUT} needed only if dynamic regulation is to be improved.
3. Thermal resistance, DIP
   θ_{JA} = 95°C/W θ_{JC} = 35°C/W, TO-5
   θ_{JA} = 150°C/W θ_{JC} = 25°C/W
   $_{SIL}\Theta_{JA}$ = 62.4°C/w Θ_{JC} = 30°C/w

TYPICAL PERFORMANCE CHARACTERISTICS

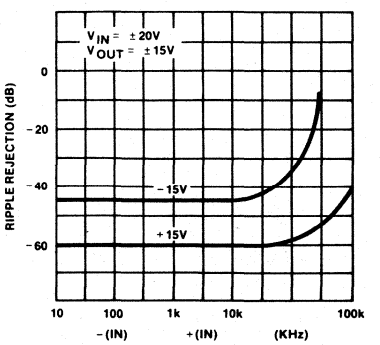
LOAD REGULATION



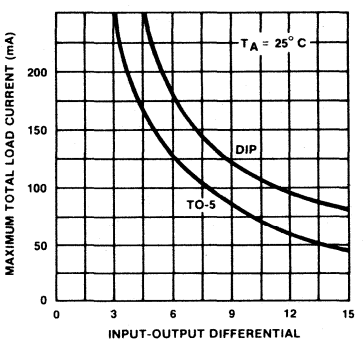
IQ +, IQ -



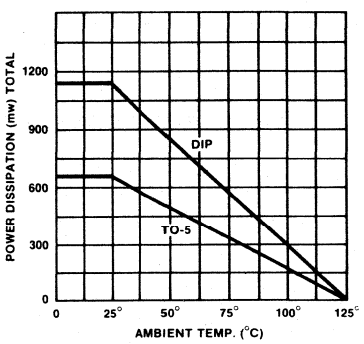
RIPPLE REJECTION



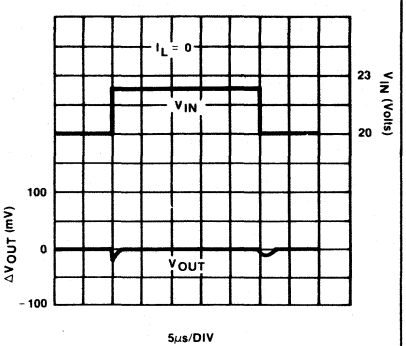
MAXIMUM CURRENT CAPABILITY



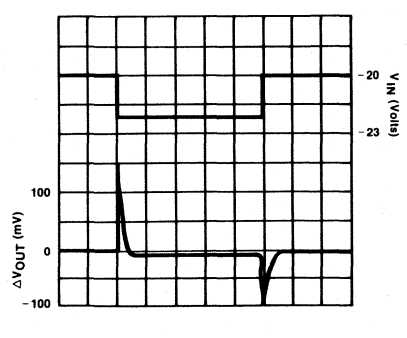
MAXIMUM POWER DISSIPATION[4]



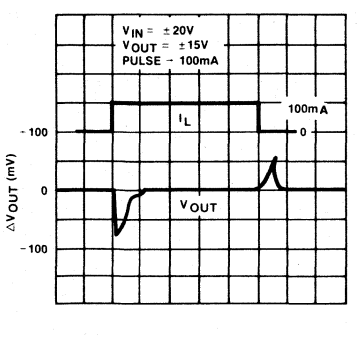
LINE TRANSIENT RESPONSE, POSITIVE



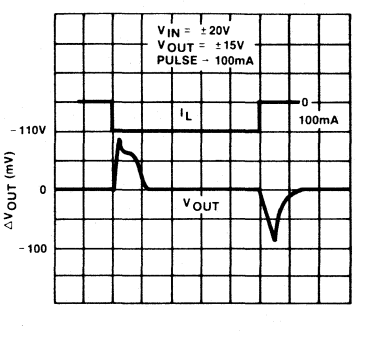
LINE TRANSIENT RESPONSE, NEGATIVE



LOAD TRANSIENT RESPONSE, POSITIVE



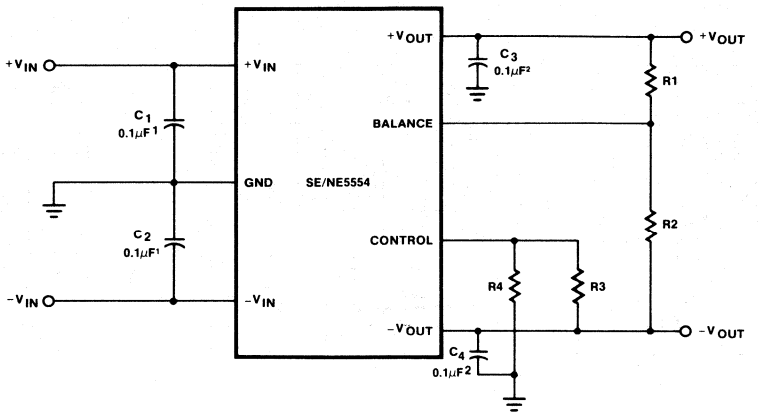
LOAD TRANSIENT RESPONSE, NEGATIVE



4. Device capability in free air.

BLOCK DIAGRAM

TYPICAL CONNECTION



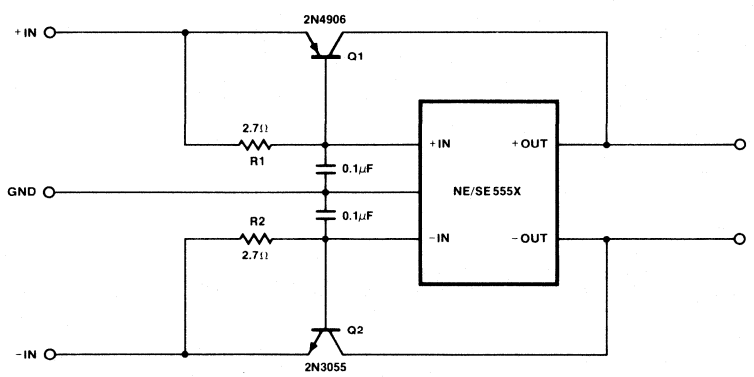
R1 and R2 adjust $+V_{OUT}$ with respect to $-V_{OUT}$
R3 and R4 adjust $-V_{OUT}$ From -5V to -20V

NOTES

1. Required if regulator is operated any distance from filter capacitor.
2. Not required for stability, but improves dynamic regulation.

TYPICAL APPLICATIONS

HIGH CURRENT TRACKING REGULATOR



$$R1 = R2 = \frac{V_{BE}}{I_{REG(max)}(\beta + 1) - I_{out(max)}}$$

For

$$\beta(Q) \geq \frac{I_{out\ (max)}}{I_{reg\ (max)}}$$

SE/NE550-F,H,N

DESCRIPTION

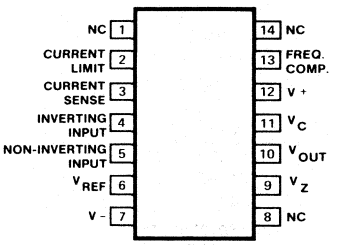
The 550 is a precision monolithic voltage regulator capable of positive or negative supply operation as series, shunt, switching or floating regulator. Guaranteed line regulation is provided for input voltages ranging from 8.5 volts to as high as 50 volts. The output voltage can be continuously adjusted from 2 volts to 40 volts. Foldback current limiting can be accomplished through the use of one external resistor. Internal circuitry permits on and off strobing with DTL and TTL logic inputs and latched shut-down with a pulsed input.

FEATURES

- **Line regulation guaranteed over input voltage range of 8.5 volts to as high as 50 volts.**
- **Output voltage continuously adjustable from 2 volts to 40 volts**
- **.01% line and load regulation**
- **Adjustable limiting of short circuit current**
- **Foldback current limiting with one external resistor**
- **Remote and latching shutdown**
- **Output current up to 150mA without external power transistors**

PIN CONFIGURATIONS

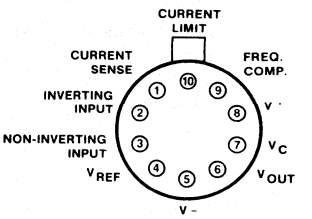
F,N PACKAGE



ORDER PART NO.

SE550F	NE550N
SE550F	NE550F

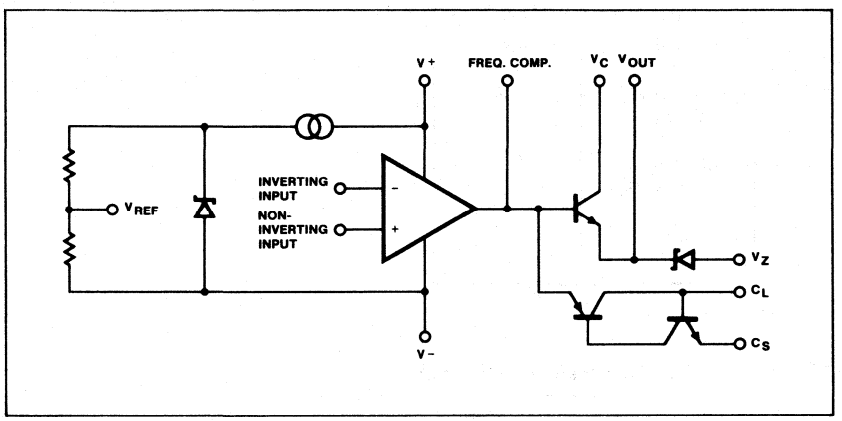
H PACKAGE



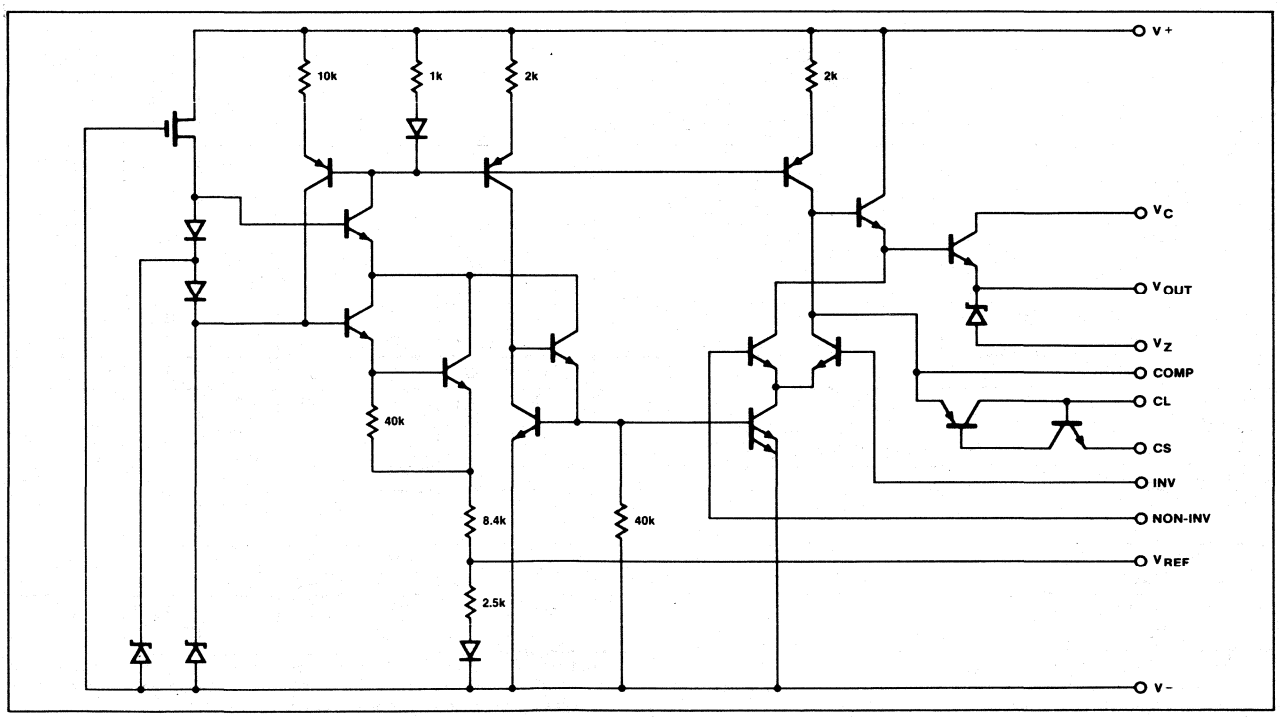
ORDER PART NO.

SE550H	NE550H

CIRCUIT SCHEMATIC



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Voltage from V+ to V-		
SE550	50	V
NE550	40	V
Input-output voltage differential		
SE550	45	V
NE550	37	V
Maximum output current		
SE550	150	mA
NE550	150	mA
Current from V_Z		
SE550	15	mA
NE550	15	mA
Internal power dissipation[1]		
SE550	800	mW
NE550	800	mW
Operating temperature range		
SE550	-55 to +125	°C
NE550	0 to 70	°C
Storage temperature range		
SE550	-65 to +150	°C
NE550	-65 to +150	°C
Lead temperature		
SE550	300	°C
NE550	300	°C

NOTE

1. Rating applies for case temperatures to 125°C; derate linearly at 6.5mW/°C for ambient termperature above +75°C.

DC ELECTRICAL CHARACTERISTICS T_A = 25°C unless otherwise specified.[1,2]

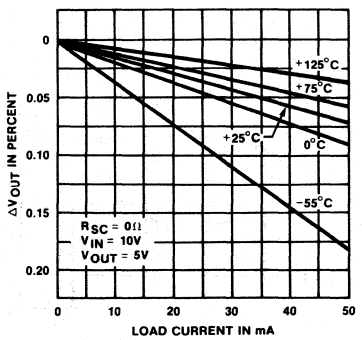
PARAMETER	TEST CONDITIONS	NE550			SE550			UNIT
		Min	Typ	Max	Min	Typ	Max	
Line regulation	V_{IN} = 8.5 to 40V		.08	0.3				%V_{OUT}
	0°C ≤ T_A ≤ 70°C, V_{IN} = 12 to 40V			0.35				%V_{OUT}
	V_{IN} = 12 to 40V					0.05	0.1	%V_{OUT}
	V_{IN} = 8.5 to 50V					0.2	0.6	%V_{OUT}
	-55°C ≤ T_A ≤ +125°C, V_{IN} = 12 to 40V						0.25	%V_{OUT}
Load regulation	I_L = 1mA to 50mA		.03	0.2		0.03	.10	%V_{OUT}
	0°C ≤ T_A ≤ 70°C			0.4				%V_{OUT}
	-55°C ≤ T_A ≤ +125°C						.6	%V_{OUT}
Ripple rejection	f = 50Hz to 10kHz							dB
	C_{REF} = 0		75			75		dB
	C_{REF} = 5μF		90			90		dB
Average temperature coefficient of output voltage	-55° ≤ T_A ≤ +125°C					.002	.012	%/°C
	0°C ≤ T_A ≤ 70°		.002	.015				%/°C
Short circuit limit	RSC = 10Ω, V_{OUT} = 0	50	60	70	50	60	70	mA
Reference voltage		1.58	1.63	1.73	1.58	1.63	1.68	V
Output noise voltage	BW = 100Hz to 10kHz, C_{REF} = 0		20			20		μVrms
	BW = 100Hz to 10kHz, C_{REF} = 5μF		2.5			2.5		μVrms
Long term stability						0.1		%/1000hrs.
Standby current drain	I_L = 0, V_{IN} = 50V					1.3	2.0	mA
	I_L = 0, V_{IN} = 40V		1.6	3.0				mA
Input voltage range		8.5		40	8.5		50	V
Output voltage range		2.0		40	2.0		37	V
Input-output voltage differential		3.0		38	3.0		45	V

NOTES

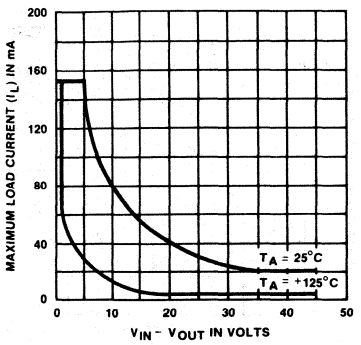
1. V_{IN} = V+ = V_C = 12V, V- = 0V, V_{OUT} = 5V, I_L = 1mA, R_{SC} = 0_1Cl = 100pF, and divider impedance as seen by error amplifier ≈ 2kΩ.
2. The load and line regulation specifications are for constant temperature junction. Temperature drift effects must be taken into account separately when the unit is operating under conditions of high or varying dissipation.

TYPICAL PERFORMANCE CHARACTERISTICS

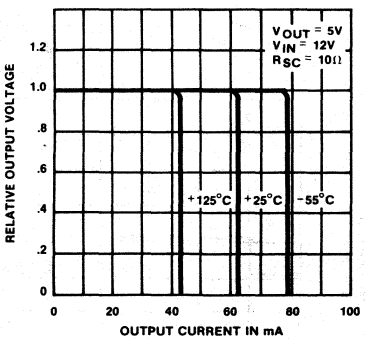
LOAD REGULATION AS A FUNCTION OF LOAD CURRENT



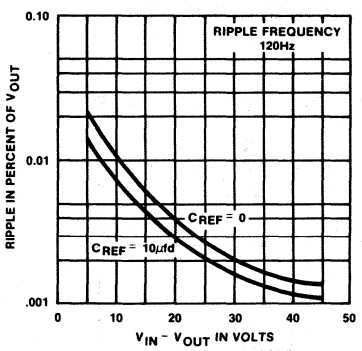
MAXIMUM LOAD CURRENT AS A FUNCTION OF INPUT-OUTPUT VOLTAGE DIFFERENTIAL



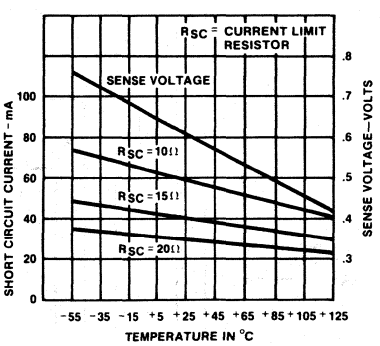
RELATIVE OUTPUT VOLTAGE AS A FUNCTION OF LIMITED OUTPUT CURRENT



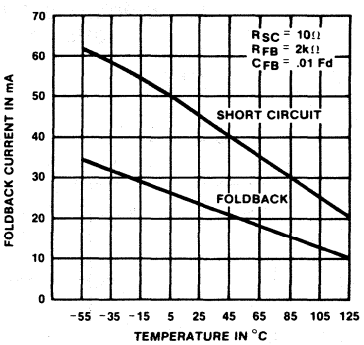
RIPPLE REJECTION AS A FUNCTION OF INPUT-OUTPUT VOLTAGE DIFFERENTIAL



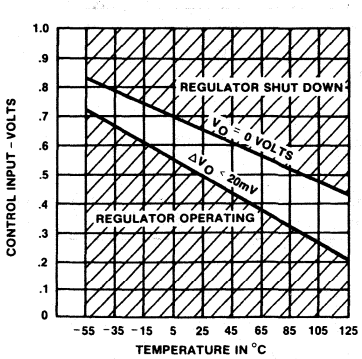
SENSE VOLTAGE AND SHORT CIRCUIT CURRENT LIMIT AS A FUNCTION OF TEMPERATURE



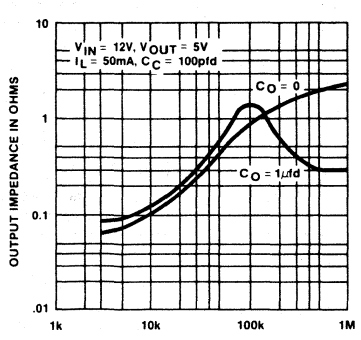
SHORT CIRCUIT AND FOLDBACK CURRENTS AS A FUNCTION OF TEMPERATURE



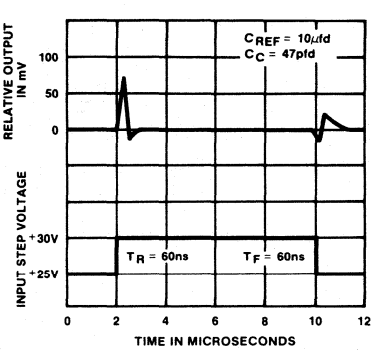
REMOTE CONTROL CHARACTERISTICS AS A FUNCTION OF TEMPERATURE



OUTPUT IMPEDANCE AS A FUNCTION OF FREQUENCY

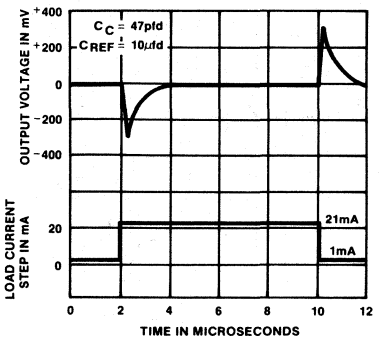


LINE TRANSIENT RESPONSE

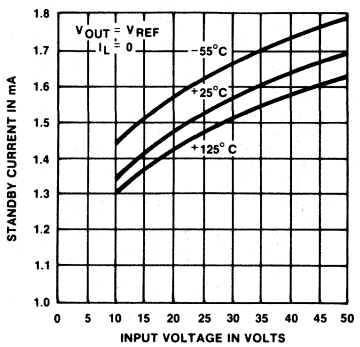


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

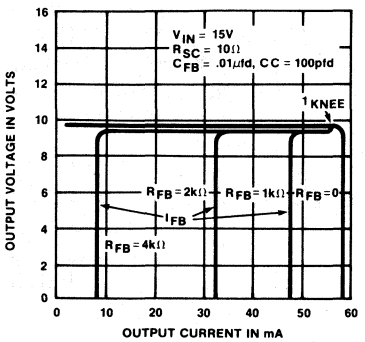
LOAD TRANSIENT RESPONSE



STANDBY CURRENT AS A FUNCTION OF INPUT VOLTAGE

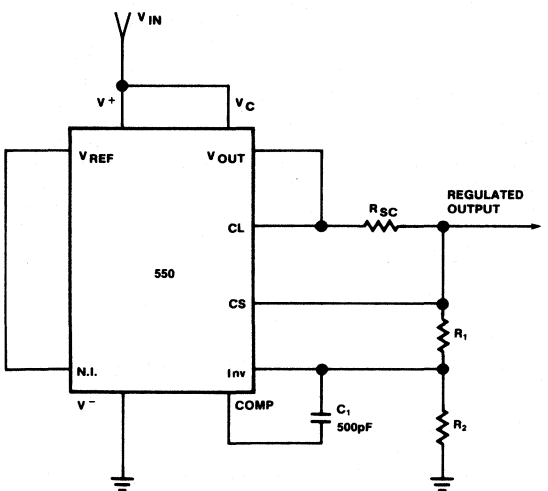


FOLDBACK CURRENT LIMITED OUTPUT VOLTAGE AS A FUNCTION OF OUTPUT CURRENT



TYPICAL APPLICATIONS

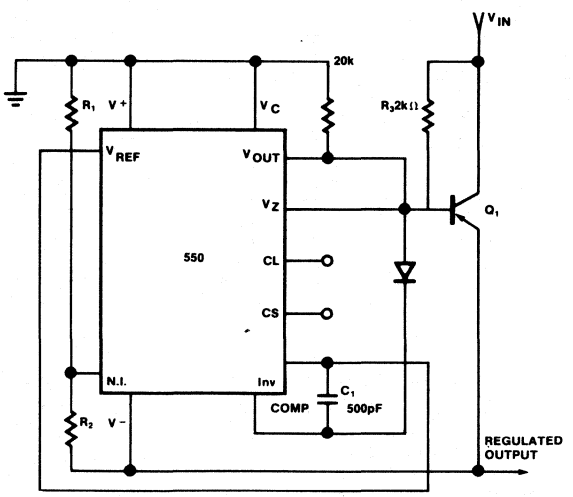
BASIC POSITIVE VOLTAGE REGULATOR



$$V_{OUT} = V_{REF}\frac{R_1 + R_2}{R_2} \quad ISC = \frac{V_{SENSE}}{RSC}$$

$$\frac{R_1R_2}{R_1 + R_2} = 2k\Omega \text{ for minimum temperature drift}$$

NEGATIVE VOLTAGE REGULATOR



$$V_{OUT} = -V_{REFX}\frac{R_1 + R_2}{R_2}$$

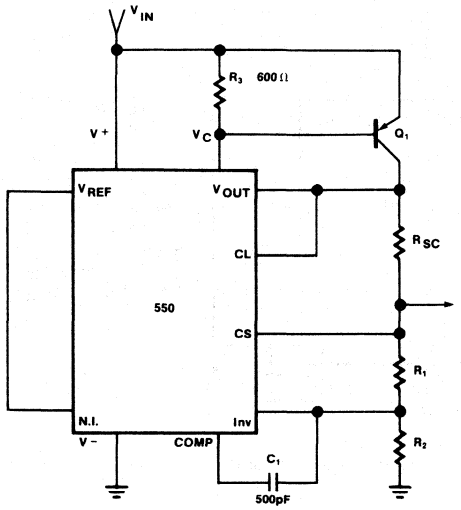
$$\frac{R_1R_2}{R_1 + R_2} = 2k\Omega \text{ for minimum temperature drift}$$

NOTE

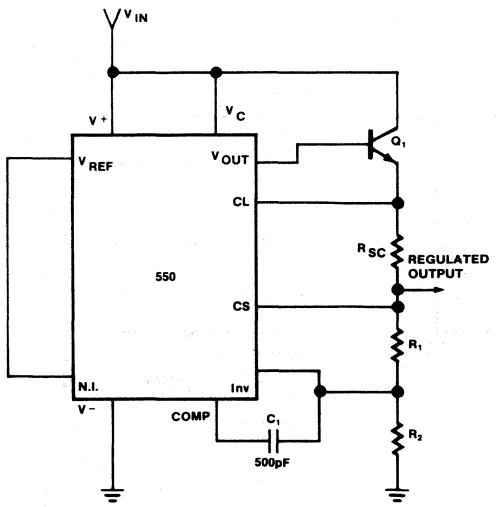
To utilize the SE550L in applications which require Vz, an external 6.2 volt zener diode should be connected in series with V_{OUT}.

TYPICAL APPLICATIONS (Cont'd)

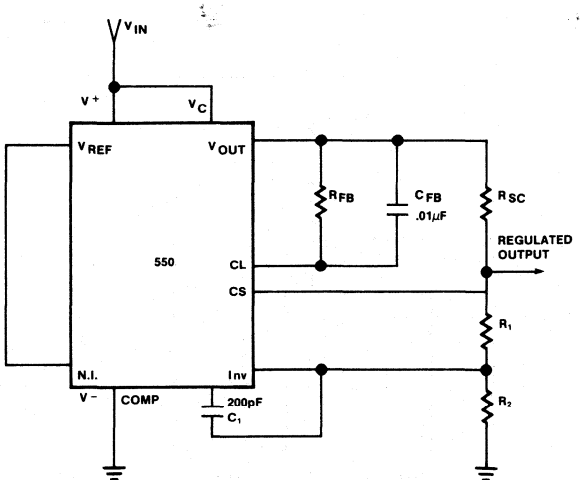
POSITIVE VOLTAGE REGULATOR (External PNP Pass Transistor)



POSITIVE VOLTAGE REGULATOR (External NPN Pass Transistor)



FOLDBACK CURRENT LIMITED REGULATOR

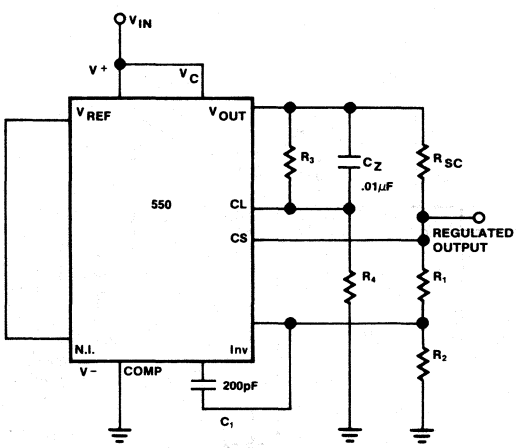


$$I_{KNEE} = \frac{V_{SENSE}}{R_{SC}}$$

$$I_{FB} = \frac{V_{SENSE} - (R_{FB} - I_{CL})}{R_{SC}}$$

$I_{CL} = 125\mu A$

SECOND ORDER FOLDBACK CURRENT LIMITED REGULATOR



$$R_3 = \frac{V_{SENSE}\,(I_{KNEE} - I_{FB})\,V_{OUT}}{I_{CL}\,(I_{KNEE} - I_{FB} + I_{SC})\,V_{OUT} - (I_{FB} - I_{SC})\,V_{SENSE}}$$

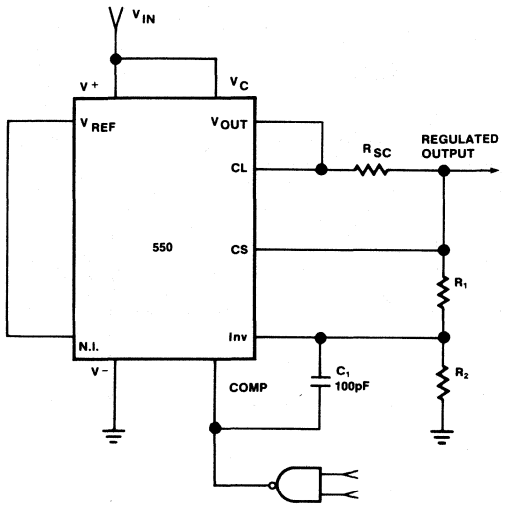
$$\frac{R_3}{R_4} = \frac{(V_{SENSE} - I_{CL}\,R_3)\,(I_{FB} - I_{SC})}{V_{OUT}\,I_{SC} - V_{SENSE}\,(I_{FB} - I_{SC})}$$

$$R_{SC} = \frac{(V_{OUT} + V_{SENSE})\,R_3/R_4 + V_{SENSE}}{I_{KNEE}}$$

$I_{CL} = 125\mu A$

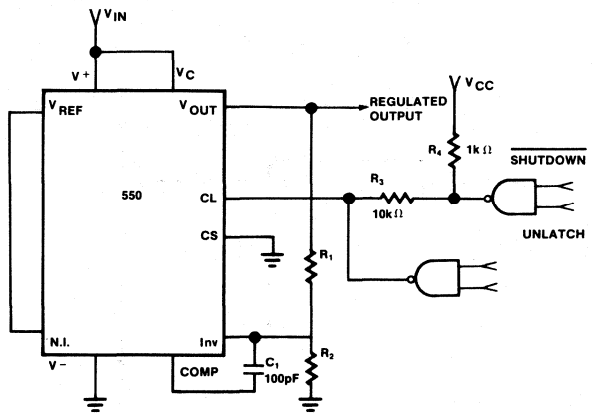
TYPICAL APPLICATIONS (Cont'd)

REMOTE SHUTDOWN REGULATOR WITH CURRENT LIMITING



1/4 8T80, 1/6 8T90, 1/10 8TO1B, etc.

REMOTE LATCHING SHUTDOWN REGULATOR

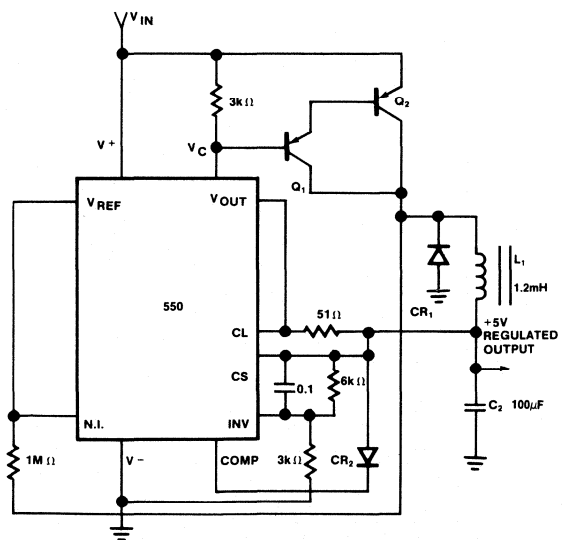


8415, 8417, 2/3 8471, 1/3 8891, 8T90, 1/2 8481, 8881, 8T90

NOTE

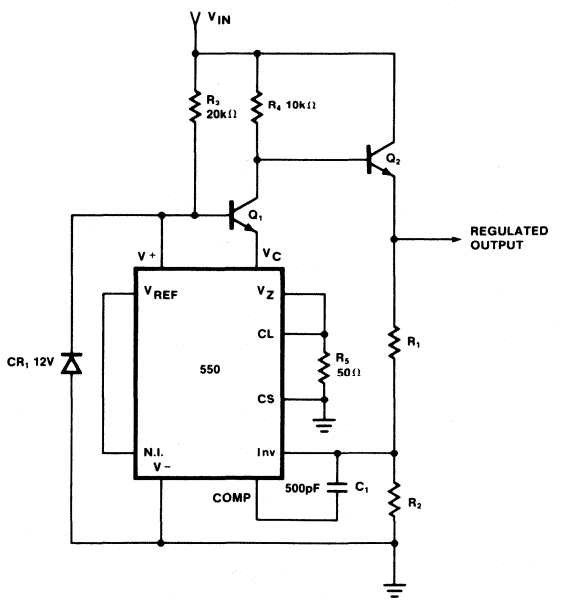
The "Shut-down" gate need only be pulsed to latch the regulator output to zero. R4 may omitted for active pull-up devices. The "Unlatch" gate must have an open collector.

POSITIVE SWITCHING REGULATOR



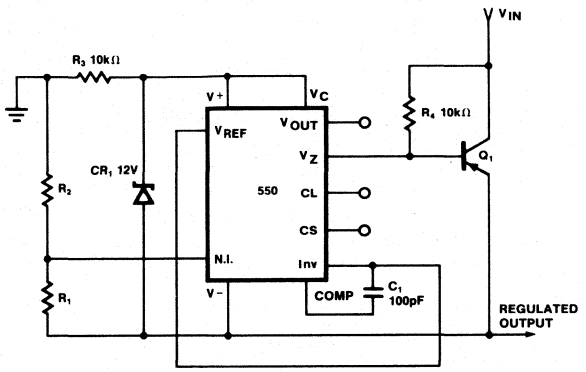
L_1 is 50 turns of #22 wire wound on Ferroxcube. 42/29-377 A400

POSITIVE FLOATING REGULATOR



TYPICAL APPLICATIONS (Cont'd)

NEGATIVE FLOATING REGULATOR



NE/SE5560-F,N

DESCRIPTION

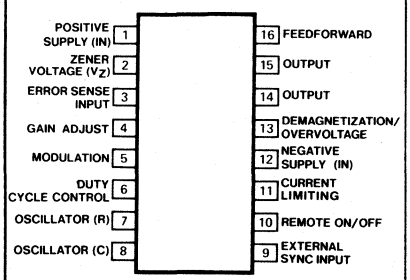
The NE/SE5560 is a control circuit for use in switched mode power supplies. This single monolithic chip incorporates all the control and housekeeping (protection) functions required in switched mode power supplies, including an internal temperature compensated reference source, internal Zener reference, sawtooth generator, pulse width modulator, output stage and various protection circuits.

FEATURES

- **Stabilized power supply**
- **Temperature compensated reference source**
- **Sawtooth generator**
- **Pulse width modulator**
- **Remote on/off switching**
- **Current limiting**
- **Low supply voltage protection**
- **Loop fault protection**
- **Demagnetization/overvoltage protection**
- **Maximum duty cycle adjustment**
- **Feed forward control**
- **External synchronization**

PIN CONFIGURATION

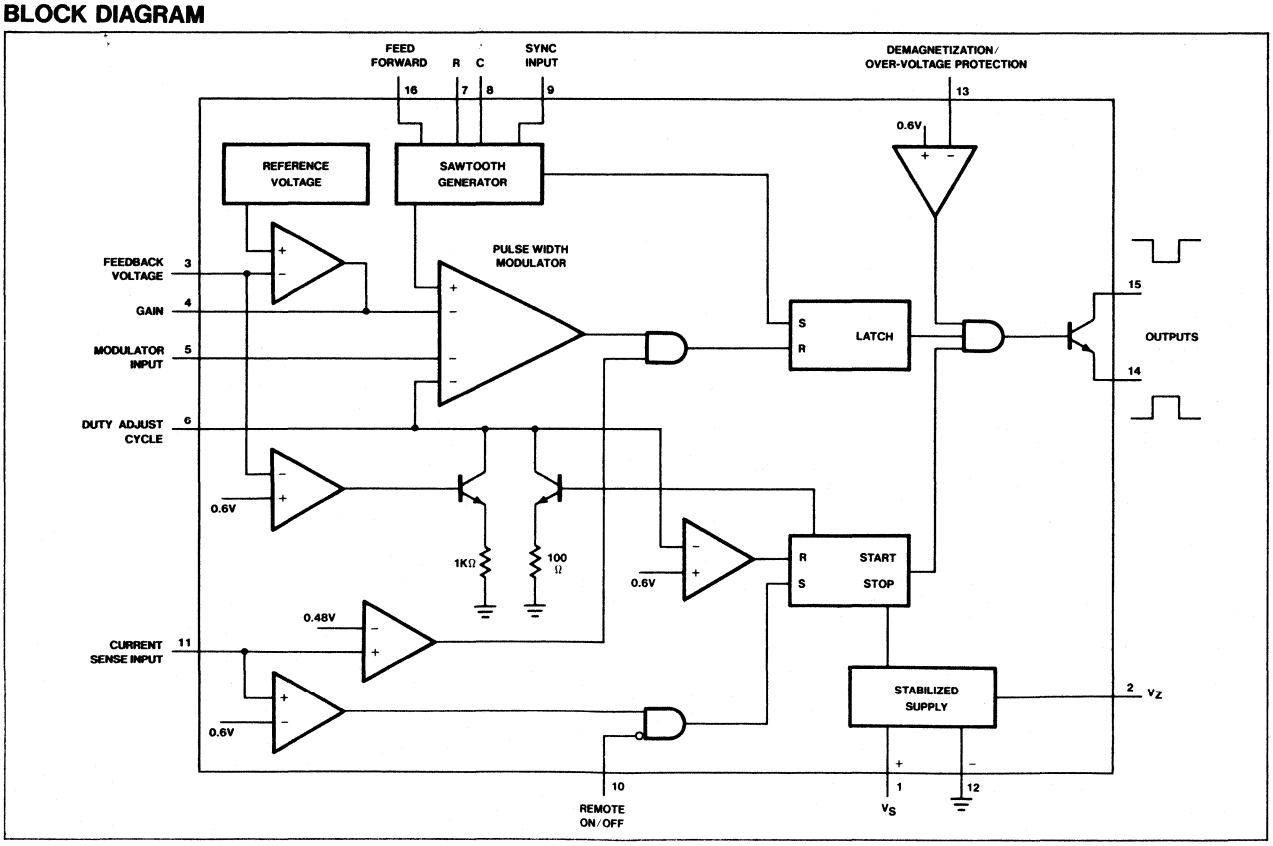
F,N PACKAGE



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage (Voltage sourced)	+18	V
Supply current (Current sourced)	30	mA
Output current	40	mA
Operating temperature range (ambient)		
SE5560	−55 to +125	°C
NE5560	0 to +70	°C
Storage temperature range	−65 to +150	°C

BLOCK DIAGRAM



DC ELECTRICAL CHARACTERISTICS T_A = 25°C, V_{CC} = 12V unless otherwise specified

PARAMETER	TEST CONDITIONS	SE5560			NE5560			UNIT
		Min	Typ	Max	Min	Typ	Max	
REFERENCE SECTIONS	Over temp.	3.42		4.04	3.38		4.07	V
Internal reference voltage (V_{ref})	25°C	3.45	3.72	4.0	3.4	3.72	4.05	V
Internal Zener reference (V_Z)	I_L = 7mA	7.8	8.4	9.0	7.8	8.4	9.0	V
Temperature coefficient of V_{ref}				± 100		± 100		ppm/°C
Temperature coefficient of V_Z			± 150			± 150		ppm/°C
OSCILLATOR SECTION								
Frequency range	Over temp.	50		100K	50		100K	Hz
Initial accuracy	R = 5K		5			5		%
Duty cycle range[1]	fo = 20kHz	0		98	0		98	%
MODULATOR								
Modulator input current	Voltage at Pin 5 = 1V over temp.		0.2	20		0.2	20	μA
HOUSEKEEPING FUNCTION								
Pin 6 Duty cycle limit control	(For 50% Maximum duty cycle) 15kHz to 50kHz	38	40	42	37	40	43	% of V_Z
Pin 6 Input current	Over temp.		.2	20		0.2	20	μA
Pin 1 Low supply voltage protection thresholds		V_Z+.2	V_Z+7V	V_Z +1.7V	V_Z+.2	V_Z+.7	V_Z+1.7	V
Pin 3 Feedback loop protection trip on threshold		470	600	720	470	600	720	mV
Pin 3 Pull up current	Over temp.		−15	−35		−15	−35	μA
Pin 13 Demagnetization/over voltage protection trip on threshold		470	600	720	470	600	720	mV
Pin 13 Input current	Over temp.		0.6	10		0.6	10	μA
	25°C			20			20	μA
Pin 16 Feed forward duty cycle[2] control	Voltage at Pin 16 = 2V_Z		0.4			0.4		original duty cycle
Feed forward input current			0.2	5		0.2	5	μA
	Over temp. 25°C			10			10	μA
EXTERNAL SYNCHRONIZATION								
Pin 9 off		0		0.8	0		0.8	V
on		2		V_Z	2		V_Z	V
Sink current	Voltage at Pin 9 = 0V 25°C		−65	−100		−65	−125	μA
	Over temp.			−125			−125	μA
REMOTE								
Pin 10 off		0		0.8	0		0.8	V
on		2		V_Z	2		V_Z	V
Sink current	25°C		−85	−100		−75	−125	μA
	Over temp.			−125			−125	μA
CURRENT LIMITING								
Pin 11; I_{IN}	Voltage at Pin 11 = 250mV, 25°C		−2	−10		−2	−10	μA
	Over temp.			−20			−20	
Single pulse inhibit delay	Inhibit delay time for 20% overdrive at 40mA I_{OUT}		0.7	0.8		0.7	0.8	μs
Trip Levels:								
Shut down/slow start		.500	.600	.700	.500	.600	.700	V
Current limit		.400	.48	.56	.400	.480	.560	V

NOTES
1. See graph
2. See graph

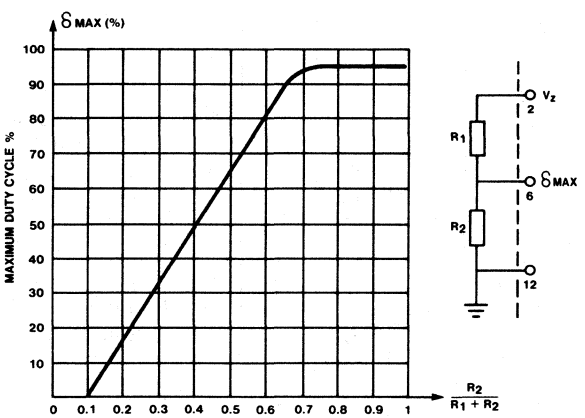
DC ELECTRICAL CHARACTERISTICS (Con't) T_A = 25°C, V_{CC} = 12V unless otherwise specified

PARAMETER	TEST CONDITIONS	SE5560			NE5560			UNIT
		Min	Typ	Max	Min	Typ	Max	
ERROR AMPLIFIER								
Open loop gain			60			60		dB
Feedback resistor		10K			10K			Ω
Small signal bandwith			3			3		MHz
Output voltage swing (positive)		6.2			6.2			V
Output voltage swing (negative)				0.7			0.6	V
OUTPUT STAGE								
Output Current (Pin 15)		40			40			mA
Max emitter voltage (Pin 14)		5	6		5	6		V
V_{CE}(SAT) I_C = 40mA				0.5			0.5	V
SUPPLY VOLTAGE/CURRENT								
I_{CC}	I_Z = 0, Voltage fed, V_{CC} = 12V, 25°C			10			10	mA
	Over temp.			15			15	mA
V_{CC}	I_{CC} = 10mA, Current fed	20		23	19		24	V
V_{CC}	I_{CC} = 30mA, Current fed	20		30	20		30	V

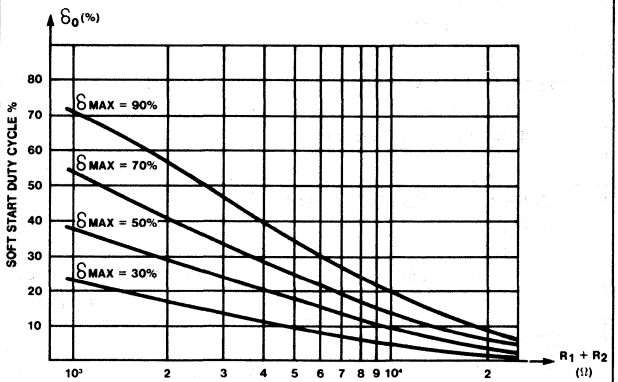
NOTES
1. See graph
2. See graph

TYPICAL PERFORMANCE CHARACTERISTICS

GRAPH FOR DETERMINING δ MAX

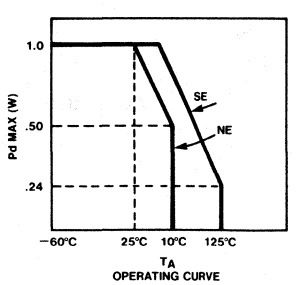


SOFT-START MIN. DUTY CYCLE VS $R_1 + R_2$



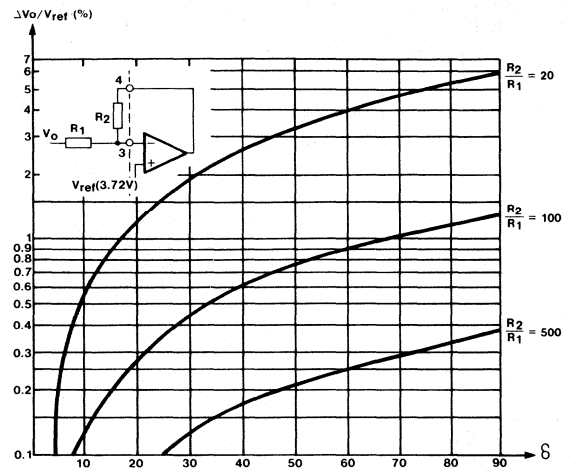
POWER DERATING CURVE

$Pd = V_{CC} I_{CC} + (V_{CC} - V_Z)I_Z + [(V_{15}-V_{14})I_{15} \times \text{DUTY CYCLE}]$



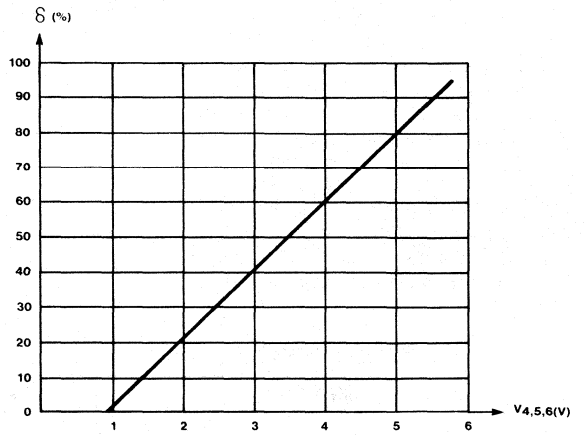
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

REGULATION VS ERROR AMP CLOSED LOOP GAIN

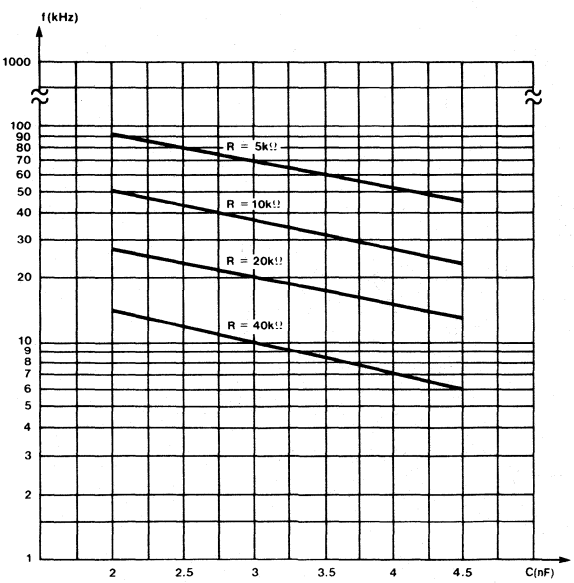


TRANSFER CURVE OF PULSE WIDTH MODULATOR

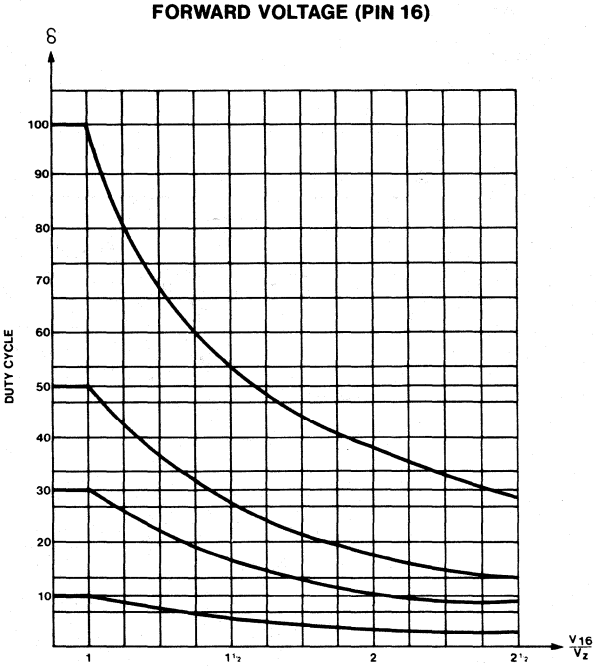
DUTY CYCLE VS INPUT VOLTAGE



TYPICAL FREQUENCY PLOT VS R_T AND C_T



DUTY CYCLE SENSITIVITY TO FEED FORWARD VOLTAGE (PIN 16)



SG1524/SG2524/SG3524-F,N

DESCRIPTION

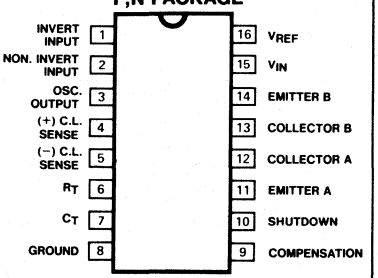
This monolithic integrated circuit contains all the control circuitry for a regulating power supply inverter or switching regulator. Included in a 16-pin dual-in-line package is the voltage reference, error-amplifier, oscillator, pulse width modulator, pulse steering flip-flop, dual alternating output switches and current limiting and shut-down circuitry. This device can be used for switching regulators of either polarity, transformer coupled DC to DC converters, transformerless voltage doublers and polarity converters, as well as other power control applications. The SG1524 is specified for operation over the full military temperature range of −55°C to +125°C, while the SG2524 and SG3524 are designed for commercial applications of 0°C to +70°C.

FEATURES

- **Complete PWM power control circuitry**
- **Single ended or push-pull outputs**
- **Line and load regulation of 0.2%**
- **1% maximum temperature variation**
- **Total supply current is less than 10mA**
- **Operation beyond 100kHz**

PIN CONFIGURATION

CONNECTION DIAGRAM
F,N PACKAGE

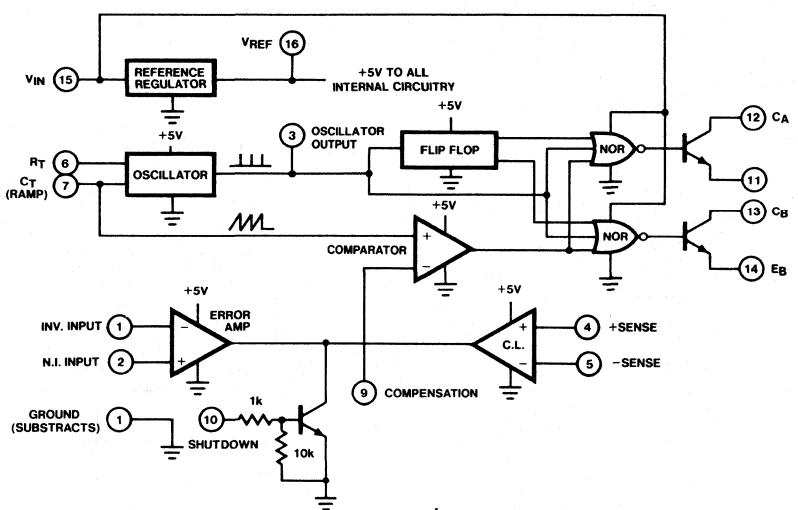


TOP VIEW
ORDER PART NO.
SG1524F, SG2524F
SG2524N, SG3524F
SG3524N

ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Input voltage	40	V
Output current (each output)	100	mA
Reference output current	50	mA
Oscillator charging current	5	mA
Power dissipation		
Package limitation	1000	mW
Derate above 25°C	8	mW/°C
Operating temperature range		
SG1524	−55 to +125	°C
SG2524/SG3524	0 to +70	°C
Storage temperature range	−65 to +150	°C

BLOCK DIAGRAM



DC ELECTRICAL CHARACTERISTICS

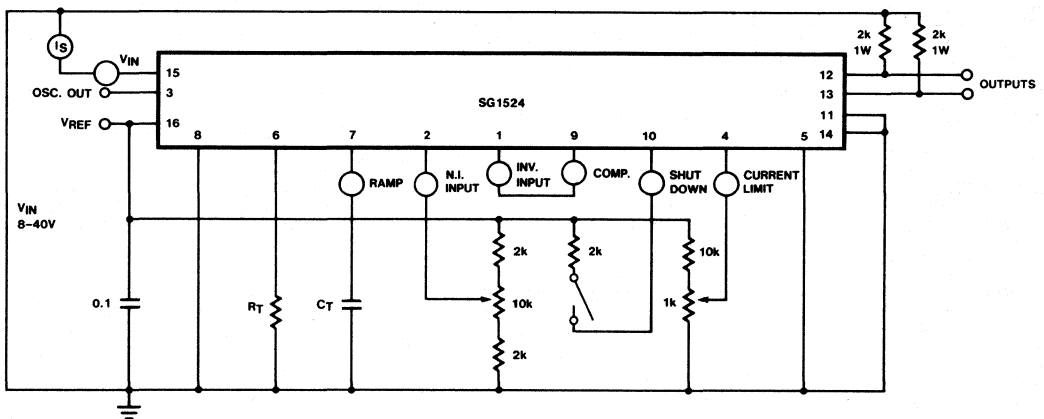
(Unless otherwise stated, these specifications apply for T_A = −55°C to +125°C for the SG1524 and 0°C to +70°C for the SG2524 and SG3524, V_{IN} = 20V, and f = 20kHz)

PARAMETER	TEST CONDITIONS	SG1524 SG2524			SG3524			UNIT
		Min	Typ	Max	Min	Typ	Max	
REFERENCE SECTION								
Output voltage		4.8	5.0	5.2	4.6	5.0	5.4	V
Line regulation	V_{IN} = 8 to 40V		10	20		10	30	mV
Load regulation	I_L = 0 to 20mA		20	50		20	50	mV
Ripple rejection	f = 120Hz, T_A = 25°C		66			66		dB
Short circuit current limit	V_{REF} = 0, T_A = 25°C		100			100		mA
Temperature stability	Over operating temperature range		0.3	1		0.3	1	%
Long term stability	T_A = 25°C		20			20		mV/kHr
OSCILLATOR SECTION								
Maximum frequency	C_T = .001 mfd, R_T = 2kΩ		300			300		kHz
Initial accuracy	R_T and C_T constant		5			5		%
Voltage stability	V_{IN} = 8 to 40V, T_A = 25°C			1			1	%
Temperature stability	Over operating temperature range						2	%
Output amplitude	Pin 3, T_A = 25°C		3.5			3.5		V
Output pulse width	C_T = .01 mfd, T_A = 25°C		0.5			0.5		μs
ERROR AMPLIFIER SECTION								
Input offset voltage	V_{CM} = 2.5V		0.5	5		2	10	mV
Input bias current	V_{CM} = 2.5V		2	10		2	10	μA
Open loop voltage gain		72	80		60	80		dB
Common mode voltage	T_A = 25°C	1.8		3.4	1.8		3.4	V
Common mode rejection ratio	T_A = 25°C		70			70		dB
Small signal bandwidth	A_V = 0dB, T_A = 25°C		3			3		MHz
Output voltage	T_A = 25°C	0.5		3.8	0.5		3.8	V
COMPARATOR SECTION								
Duty cycle	% each output "ON"	0		45	0		45	%
Input threshold	Zero duty cycle		1			1		V
Input threshold	Maximum duty cycle		3.5			3.5		V
Input bias current			1			1		μA
CURRENT LIMITING SECTION								
Sense voltage	Pin 9 = 2V with error amplifier set for maximum out, T_A = 25°C	190	200	210	180	200	220	mV
Sense voltage T.C.			0.2			0.2		mV/°C
Common mode voltage		−1		+1	−1		+1	V
OUTPUT SECTION (each output)								
Collector-emitter voltage		40			40			V
Collector-leakage current	V_{CE} = 40V		0.1	50		0.1	50	μA
Saturation voltage	I_C = 50mA		1	2		1	2	V
Emitter output voltage	V_{IN} = 20V	17	18		17	18		V

DC ELECTRICAL CHARACTERISTICS (Cont'd) (Unless otherwise stated, these specifications apply for $T_A = -55°C$ to $+125°C$ for the SG1524 and 0°C to +70°C for the SG2524 and SG3524, V_{IN} = 20V, and f = 20kHz)

PARAMETER	TEST CONDITIONS	SG1524 SG2524			SG3524			UNIT
		Min	Typ	Max	Min	Typ	Max	
Rise time	R_C = 2K ohm, T_A = 25°C		0.2			0.2		μs
Fall time	R_C = 2K ohm, T_A = 25°C		0.1			0.1		μs
TOTAL STANDBY CURRENT (excluding oscillator charging current, error and current limit dividers, and with outputs open)	V_{IN} = 40V		8	10		8	10	mA

OPEN LOOP TEST CIRCUIT



APPLICATIONS

Voltage Reference

An internal series regulator provides a nominal 5 volt output which is used both to generate a reference voltage and is the regulated source for all the internal timing and controlling circuitry. This regulator may be bypassed for operation from a fixed 5 volt supply by connecting pins 15 and 16 together to the input voltage. In this configuration, the maximum input voltage is 6.0 volts.

This reference regulator may be used as a 5 volt source for other circuitry. It will provide up to 50mA of current itself and can easily be expanded to higher currents with an external PNP as shown in Figure 1.

Oscillator

The oscillator in the SG1524 uses an external resistor (R_T) to establish a constant charging current into an external capacitor (C_T). While this uses more current than a series connected RC, it provides a linear ramp voltage on the capacitor which is also used as a reference for the comparator. The charging current is equal to 3.6V ÷ R_T and should be kept within the range of approximately 30μA to 2mA, i.e., 1.8K<R_T<100K.

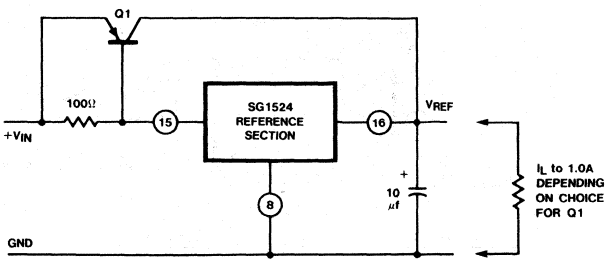
The range of values for C_T also has limits as the discharge time of C_T determines the pulse width of the oscillator output pulse. This pulse is used (among other things) as a blanking pulse to both outputs to insure that there is no possibility of having both outputs on simultaneously during transitions. This output dead time relationship is shown in Figure 2. A pulse width below approximately 0.5 microseconds may allow false triggering of one output by removing the blanking pulse prior to the flip-flops reaching a stable state. If small values of C_T must be used, the pulse width may still be expanded by adding a shunt capacitance (≈100pF) to ground at the oscillator output. (Note: Although the oscillator output is a convenient oscilloscope sync input, the cable and input capacitance may increase the blanking pulse width slightly.) Obviously, the upper limit to the pulse width is determined by the maximum duty cycle acceptable. Practical values of C_T fall between .001 and 0.1 microfarad.

The oscillator period is approximately t = R_TC_T where t is in microseconds when R_T = ohms and C_T = microfarads. The use of Figure 3 will allow selection of R_T and C_T for a wide range of operating frequencies. Note that for series regulator applications, the two outputs can be connected in parallel for an effective 0-90% duty cycle and the frequency of the oscillator is the frequency of the output. For push-pull applications, the outputs are separated and the flip-flop divides the frequency such that each outputs duty cycle is 0-45% and the overall frequency is one-half that of the oscillator.

If it is desired to synchronize the SG1524 to an external clock, a pulse of ≈+3 volts may be applied to the oscillator output terminal with R_TC_T set slightly greater than the clock period. The same considerations of pulse width apply. The impedance to ground at this point is approximately 2K ohms.

If two or more SG1524's must be synchronized together, one must be designated as master with its R_TC_T set for the correct period. The slaves should each have an R_TC_T

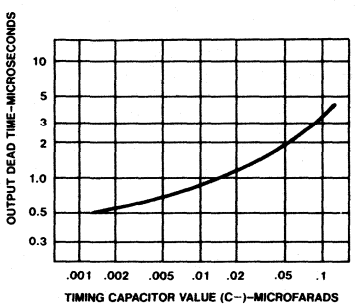
TYPICAL APPLICATION



Expanded Reference Current Capability.

Figure 1

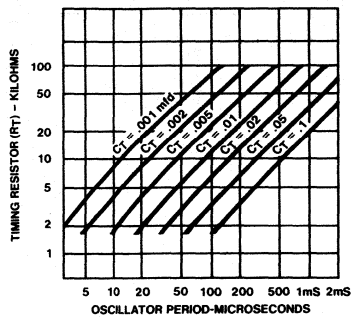
TYPICAL APPLICATION



Output stage dead time as a function of the timing capacitor value.

Figure 2

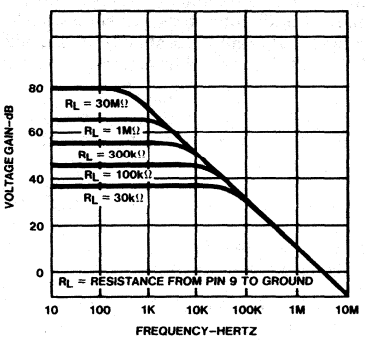
TYPICAL APPLICATION



Oscillator period as a function of R_T and C_T.

Figure 3

TYPICAL APPLICATION



Amplifies open-loop gain as a function of frequency and loading on Pin 9.

Figure 4

set for approximately 10% longer period than the master with the added requirement that C_T (slave) = one-half C_T (master). Then connecting Pin 3 on all units together will insure that the master output pulse—which occurs first and has a wider pulse width—will reset the slave units.

Error Amplifier

This circuit is a simple differential-input, transconductance amplifier. The output is the compensation terminal, pin 9, which is a high impedance node ($R_L \approx 5M\Omega$). The gain is

$$A_V = gmR_L = \frac{8\, I_C\, R_L}{2kT} \approx .002\, R_L$$

and can easily be reduced from a nominal of 10,000 by an external shunt resistance from pin 9 to ground, as shown in Figure 4.

In addition to DC gain control, the compensation terminal is also the place for AC phase compensation. The frequency response curves of Figure 4 show the uncompensated amplifier with a single pole at approximately 200Hz and a unity gain cross-over at 5MHz.

Typically, most output filter designs will introduce one or more additional poles at a significantly lower frequency. Therefore, the best stabilizing network is a series R-C combination between pin 9 and ground which introduces a zero to cancel one of the output filter poles. A good starting point is 50kΩ plus .001 microfarad.

One final point on the compensation terminal is that this is also a convenient place to insert any programming signal which is to override the error amplifier. Internal shutdown and current limit circuits are connected here, but any other circuit which can sink 200μA can pull this point to ground thus shutting off both outputs.

While feedback is normally applied around the entire regulator, the error amplifier can be used with conventional operational amplifier feedback and is stable in either the inverting or non-inverting mode. Regardless of the connections, however, input common-mode limits must be observed or output signal inversions may result. For conventional regulator applications, the 5 volt reference voltage must be divided down as shown in Figure 5. The error amplifier may also be used in fixed duty cycle applications by using the unity gain configuration shown in the open loop test circuit.

Current Limiting

The current limiting circuitry of the SG1524 is shown in Figure 6.

By matching the base-emitter voltages of Q1 and Q2, and assuming negligible voltage drop across R_1,

$$\text{Threshold} = V_{BE}(Q1) + I_1R_2 - V_{BE}(Q2)$$
$$= I_1R_2 \approx 200mV$$

Although this circuit provides a relatively small threshold with a negligible temperature coefficient, there are some limitations to its use, the most important of which is the ± 1 volt common mode range which requires sensing in the ground line. Another factor to consider is that the frequency compensation provided by R_1C_1 and Q1 provides a roll-off pole at approximately 300Hz.

Since the gain of this circuit is relatively low, there is a transition region as the current limit amplifier takes over pulse width control from the error amplifier. For testing purposes, threshold is defined as the input voltage to get 25% duty cycle with the error amplifier signaling maximum duty cycle.

In addition to constant current limiting, pins 4 and 5 may also be used in transformer-coupled circuits to sense primary current and shorten an output pulse, should transformer

saturation occur. (Refer to Figure 14). Another application is to ground pin 5 and use pin 4 as an additional shutdown terminal: i.e., the output will be off with pin 4 open and on when it is grounded. Finally, foldback current limiting can be provided with the network of Figure 7. This circuit can reduce the short-circuit current (I_{SC}) to approximately one-third the maximum available output current (I_{MAX}).

Output Circuits

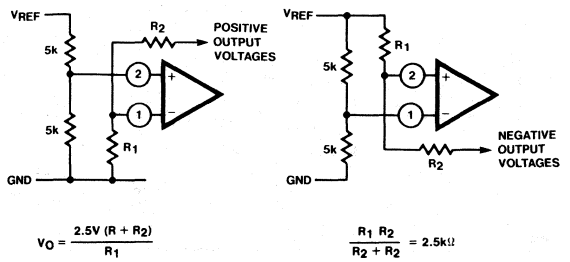
The outputs of the SG1524 are two identical NPN transistors with both collectors and emitters uncommitted. This circuitry is very similar to that used in the SG111 comparator in that each output transistor has antisaturation circuitry for fast response, and current limiting set for a maximum output current of approximately 100mA. The availability of both collectors and emitters allows maximum versatility to enable driving either NPN or PNP external transistors.

In considering the application of the SG1524 to voltage regulator circuitry, there are a multitude of output configurations possible. In general, however, they fall into three basic classifications:

1. Capacitor-diode coupled voltage multipliers
2. Inductor-capacitor single-ended circuits
3. Transformer-coupled circuits

Examples of each category are shown in Figures 8, 9 and 10. In each case, the switches indicated can be either the output transistors in the SG1524 or added external transistors according to the load current requirements.

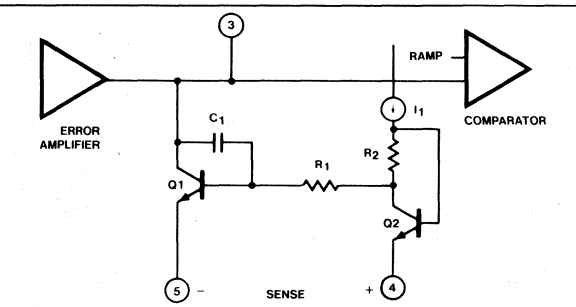
TYPICAL APPLICATION



Error amplifier biasing circuits. Note change in input connections for opposite polarity outputs.

Figure 5

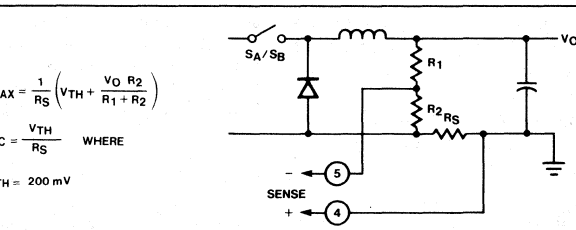
TYPICAL APPLICATION



Current Limiting Circuitry of the SG1524.

Figure 6

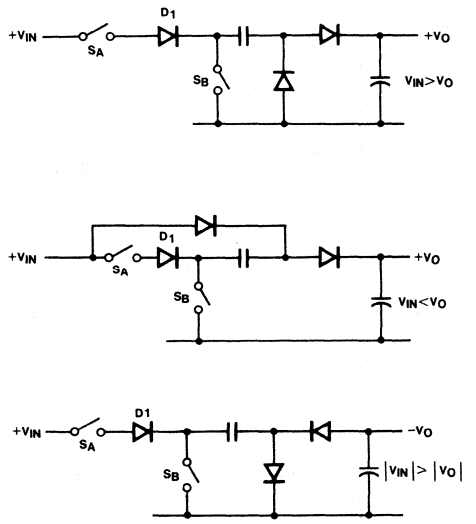
TYPICAL APPLICATION



Foldback current limiting can be used to reduce power dissipation under shorted output conditions.

Figure 7

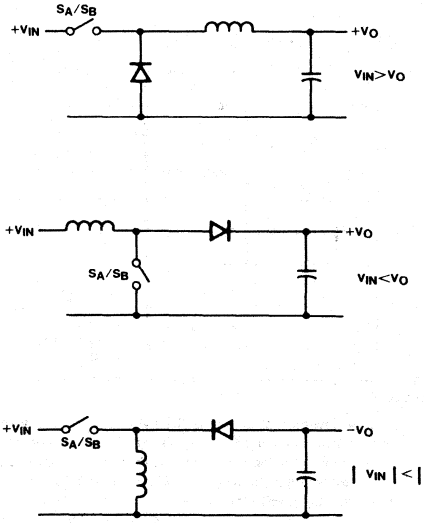
TYPICAL APPLICATION (Cont'd)



Capacitor-diode coupled voltage multiplier output stages. (Note: Diode D1 is necessary to prevent reverse emitter-base breakdown to transistor switch S_A).

Figure 8

TYPICAL APPLICATION



Single-ended inductor circuits where the two outputs of the SG1524 are connected in parallel.

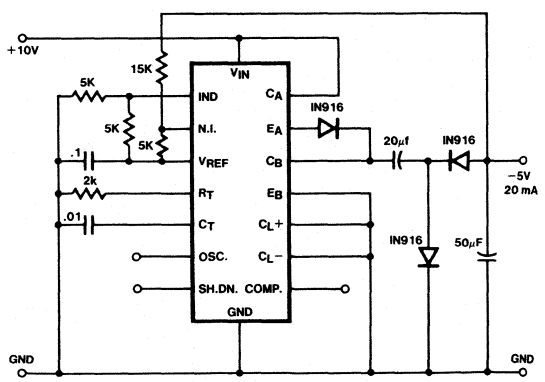
Figure 9

TYPICAL APPLICATION

Transformer-coupled outputs need not relate to the input in either amplitude or polarity.

Figure 10

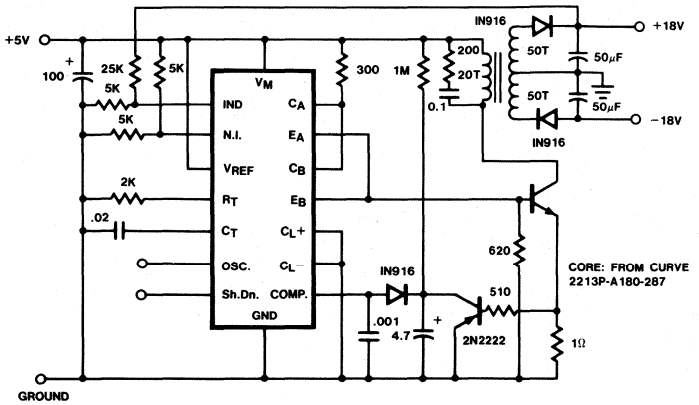
TYPICAL APPLICATION



The capacitor-diode output circuit is used here as a polarity converter to generate a −5 volt supply from +15 volts. This circuit is useful for an output current of up to 20mA with no additional boost transistors required. Since the output transistors are current limited, no additional protection is necessary. Also, the lack of an inductor allows the circuit to be stabilized with only the output capacitor.

Figure 11

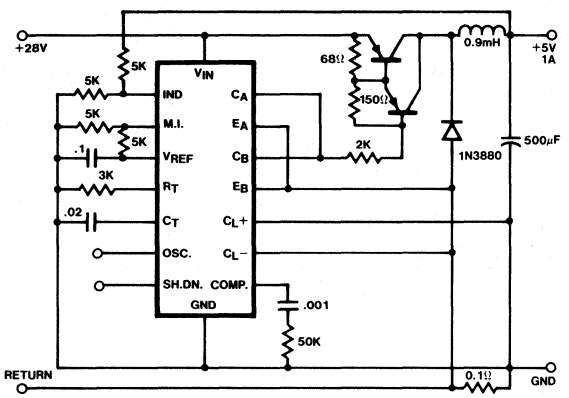
TYPICAL APPLICATION



Another low-current supply is the flyback converter used here to generate ±15 volts at 20mA from a +5 volt regulated line. The reference generator in the SG1524 is unused with the input voltage providing the reference. Current limiting in a flyback converter is difficult and is accomplished here by sensing current in the primary line and resetting a soft-start circuit.

Figure 12

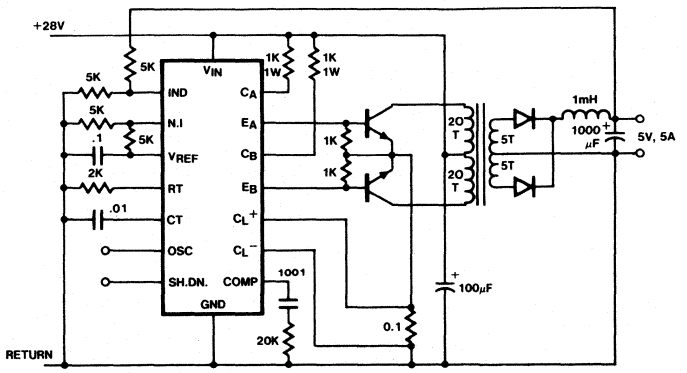
TYPICAL APPLICATION



In this conventional single-ended regulator circuit, the two outputs of the SG1524 are connected in parallel for effective .0-90% duty-cycle modulation. The use of an output inductor requires an R-C phase compensation network for loop stability.

Figure 13

TYPICAL APPLICATION



Push-pull outputs are used in this transformer-coupled DC-DC regulating converter. Note that the oscillator must be set at twice the desired output frequency as the SG1524's internal flip-flop divides the frequency by 2 as it switches the P.W.M. signal from one output to the other. Current limiting is done here in the primary so that the pulse width will be reduced should transformer saturation occur.

Figure 14

SECTION 4
TIMERS

Section 4—TIMERS

4

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

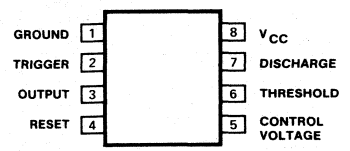
SE555F,H,N,N-14 • SE555C,F,H,N,N-14 • NE555F,H,N,N-14

FEATURES

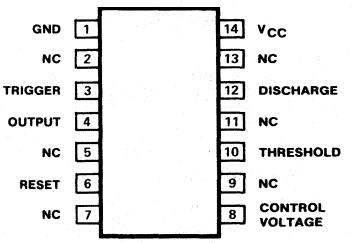
- Turn off time less than 2μs
- Maximum operating frequency greater than 500kHz
- Timing from microseconds to hours
- Operates in both astable and monostable modes
- High output current
- Adjustable duty cycle
- TTL compatible
- Temperature stability of 0.005% per °C
- SE555 Mil std 883A,B,C available M38510 (JAN) approved, M38510 processing available.

PIN CONFIGURATIONS

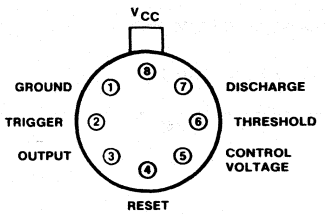
N PACKAGE



F,N-14 PACKAGE



H PACKAGE



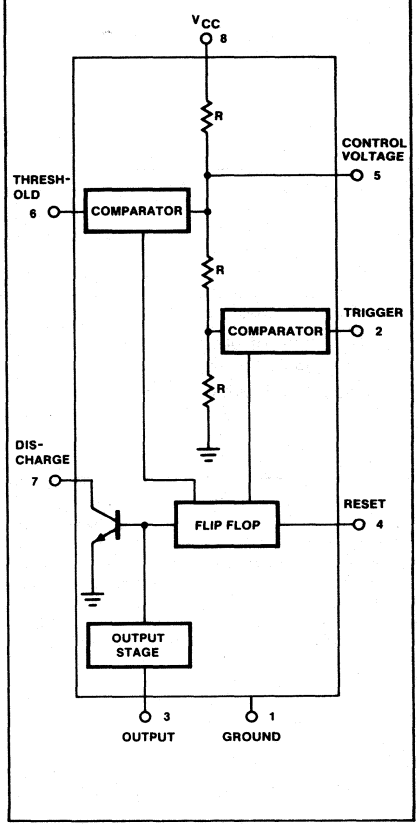
APPLICATIONS

- Precision timing
- Pulse generation
- Sequential timing
- Time delay generation
- Pulse width modulation
- Pulse position modulation
- Missing pulse detector

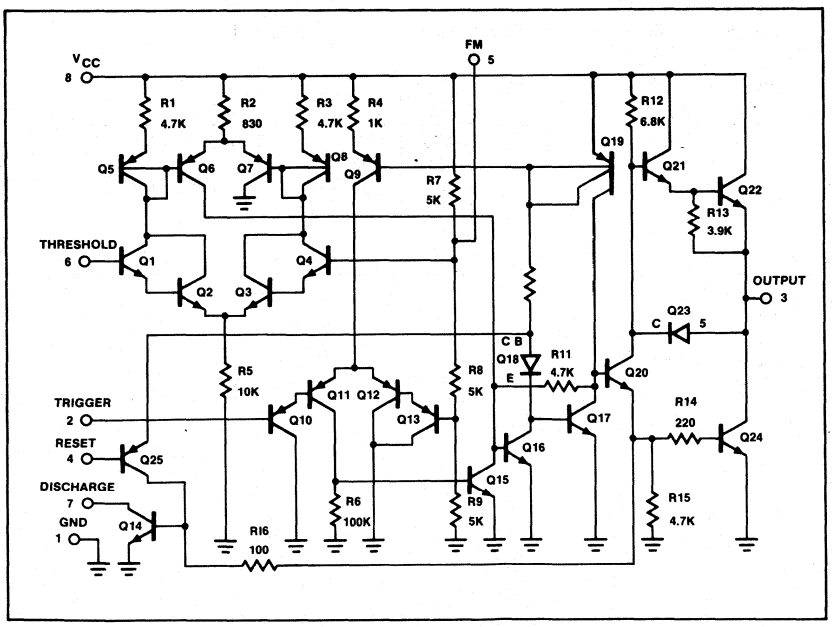
ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE555	+18	V
NE555, SE555C,	+16	V
Power dissipation	600	mW
Operating temperature range		
NE555	0 to +70	°C
SE555, SE555C	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Load temperature (soldering, 60sec)	300	°C

BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_{CC} = +5V to +15 unless otherwise specified.

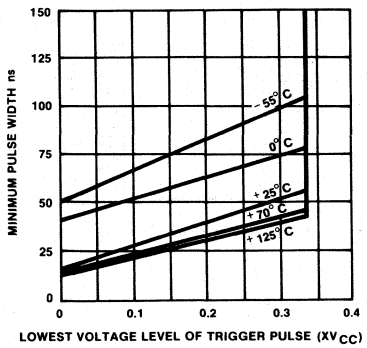
PARAMETER	TEST CONDITIONS	SE555			NE555/SE555C			UNIT
		Min	Typ	Max	Min	Typ	Max	
Supply voltage		4.5		18	4.5		16	V
Supply current (low state)[1]	V_{CC} = 5V R_L = ∞		3	5		3	6	mA
	V_{CC} = 15V R_L = ∞		10	12		10	15	mA
Timing error (monostable)	R_A = 2KΩ to 100KΩ							
Initial accuracy[2]	C = 0.1μF		0.5	2.0		1.0	3.0	%
Drift with temperature			30	100		50		ppm/°C
Drift with supply voltage			0.05	0.2		0.1	0.5	%/V
Timing error (astable)	R_A, R_B = 1kΩ to 100kΩ							
Initial accuracy[2]	C = 0.1μF		1.5			2.25		%
Drift with temperature	V_{CC} = 15V		90			150		ppm/°C
Drift with supply voltage			0.15			0.3		%/V
Control voltage level	V_{CC} = 15V	9.6	10.0	10.4	9.0	10.0	11.0	V
	V_{CC} = 5V	2.9	3.33	3.8	2.6	3.33	4.0	V
Threshold voltage	V_{CC} = 15V	9.4	10.0	10.6	8.8	10.0	11.2	V
	V_{CC} = 5V	2.7	3.33	4.0	2.4	3.33	4.2	V
Threshold current[3]			0.1	0.25		0.1	0.25	μA
Trigger voltage	V_{CC} = 15V	4.8	5.0	5.2	4.5	5.0	5.6	V
	V_{CC} = 5V	1.45	1.67	1.9	1.1	1.67	2.2	V
Trigger current	V_{TRIG} = 0V		0.5	0.9		0.5	2.0	μA
Reset voltage[4]		0.4	0.7	1.0	0.4	0.7	1.0	V
Reset current			0.1	0.4		0.1	0.4	mA
Reset current	V_{RESET} = 0V		0.4	1.0		0.4	1.5	mA
Output voltage (low)	V_{CC} = 15V							
	I_{SINK} = 10mA		0.1	0.15		0.1	0.25	V
	I_{SINK} = 50mA		0.4	0.5		0.4	0.75	V
	I_{SINK} = 100mA		2.0	2.2		2.0	2.5	V
	I_{SINK} = 200mA		2.5			2.5		V
	V_{CC} = 5V							
	I_{SINK} = 8mA		0.1	0.25		0.3	0.4	V
	I_{SINK} = 5mA		0.05	0.2		0.25	0.35	V
Output voltage (high)	V_{CC} = 15V							
	I_{SOURCE} = 200mA		12.5			12.5		V
	I_{SOURCE} = 100mA	13.0	13.3		12.75	13.3		V
	V_{CC} = 5V							
	I_{SOURCE} = 100mA	3.0	3.3		2.75	3.3		V
Turn off time[5]	V_{RESET} = V_{CC}		0.5	2.0		0.5		μs
Rise time of output			100	200		100	300	ns
Fall time of output			100	200		100	300	ns
Discharge leakage current			20	100		20	100	na

NOTES

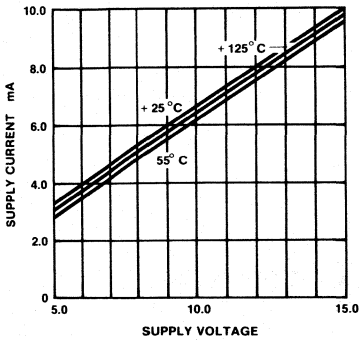
1. Supply current when output high typically 1mA less.
2. Tested at V_{CC} = 5V and V_{CC} = 15V.
3. This will determine the maximum value of $R_A + R_B$, for 15V operation, the max total R = 10 megohm, and for 5V operation, the max total R = 3.4 megohm.
4. Specified with trigger input high.
5. Time measured from a positive going input pulse from 0 to 0.8xV_{CC} into the threshold to the drop from high to low of the output. Trigger is tied to threshold.

TYPICAL PERFORMANCE CHARACTERISTICS

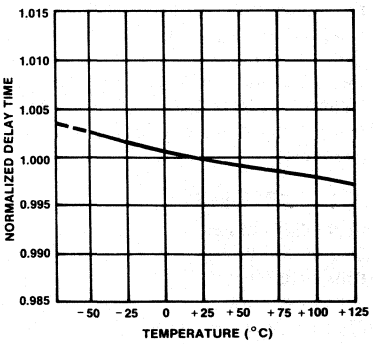
MINIMUM PULSE WIDTH REQUIRED FOR TRIGGERING



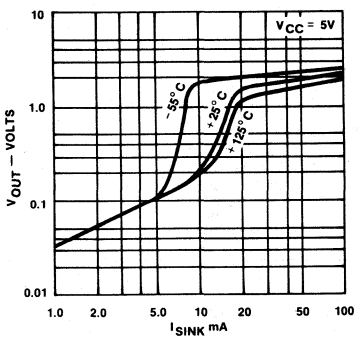
SUPPLY CURRENT vs SUPPLY VOLTAGE



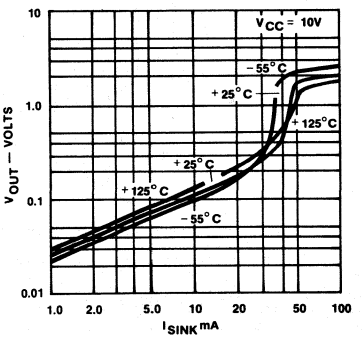
DELAY TIME vs TEMPERATURE



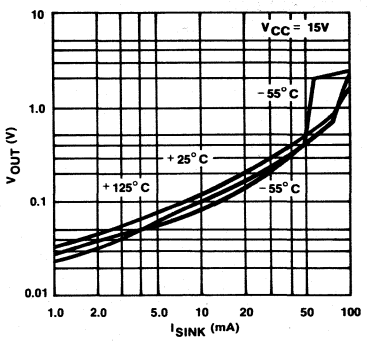
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



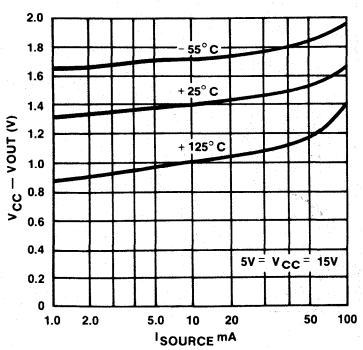
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



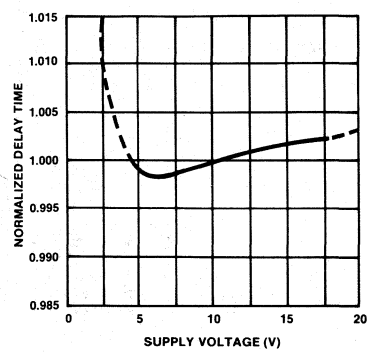
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



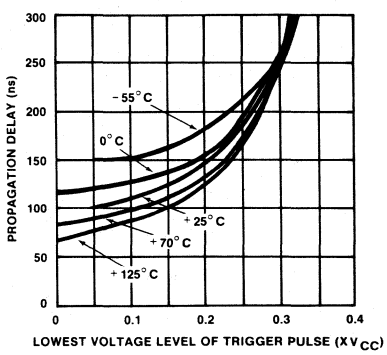
HIGH OUTPUT VOLTAGE DROP vs OUTPUT SOURCE CURRENT



DELAY TIME vs SUPPLY VOLTAGE



PROPAGATION DELAY vs VOLTAGE LEVEL OF TRIGGER PULSE



SE556N,F • NE556F,N • SE556C,F,N

FEATURES

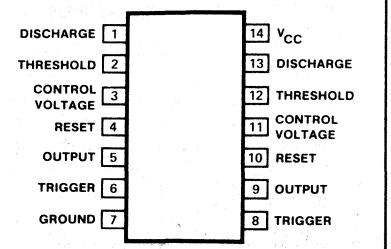
- Timing from microseconds to hours
- Replaces two 555 timers
- Operates in both astable and monostable modes
- High output current
- Adjustable duty cycle
- TTL compatible
- Temperature stability of 0.005% per °C
- SE566 MIL STD 883A, B, C available, N38510 (JAN planned, 38510 processing available).

APPLICATIONS

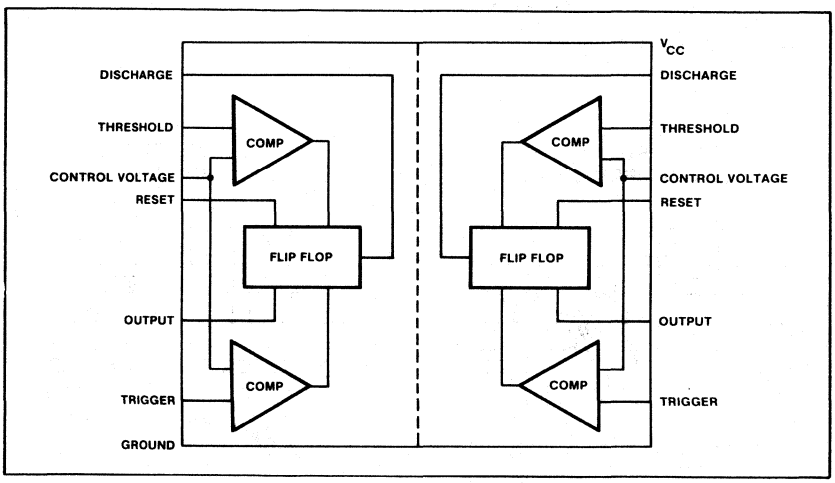
- Precision timing
- Sequential timing
- Pulse shaping
- Pulse generator
- Missing pulse detector
- Tone burst generator
- Pulse width modulation
- Time delay generator
- Frequency division
- Industrial controls
- Pulse position modulation
- Appliance timing
- Traffic light control
- Touch tone encoder

PIN CONFIGURATION

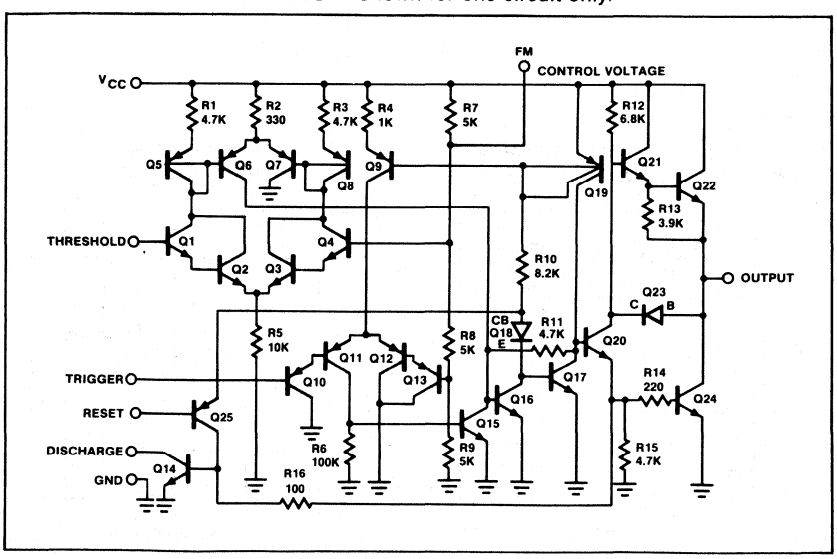
F,N PACKAGE



BLOCK DIAGRAM



EQUIVALENT SCHEMATIC (Shown for one circuit only)



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE556	+18	V
NE556, SE556C,	+16	V
Power dissipation	600	mW
Operating temperature range		
NE556	0 to +70	°C
SE556, SE556C	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (Soldering, 60 sec)	+300	°C

ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_{CC} = +5V$ to $+15V$ unless otherwise specified.

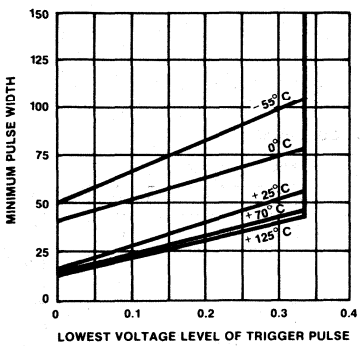
PARAMETER	TEST CONDITIONS	SE556			NE556/SE556C			UNITS
		Min	Typ	Max	Min	Typ	Max	
Supply voltage		4.5		18	4.5		16	V
Supply current (low state)[1]	$V_{CC} = 5V$ $R_L = \infty$		6	10		6	12	mA
	$V_{CC} = 15V$ $R_L = \infty$		20	24		20	30	mA
Timing error (monostable)	$R_A = 2k\Omega$ to $100k\Omega$							
Initial accuracy[2]	$C = 0.1\mu F$		0.5	1.5		0.75	3.0	%
Drift with temperature			30	100		50		ppm/°C
Drift with supply voltage			0.05	0.2		0.1	0.5	%/V
Timing error (astable)	R_A, $R_B = 1k\Omega$ to $100k\Omega$							
Initial accuracy[2]	$C = 0.1\mu F$		1.5			2.25		%
Drift with temperature	$V_{CC} = 15V$		90			150		ppm/°C
Drift with supply voltage			0.15			0.3		%/V
Control voltage level	$V_{CC} = 15V$	9.6	10.0	10.4	9.0	10.0	11.0	V
	$V_{CC} = 5V$	2.9	3.33	3.8	2.6	3.33	4.0	V
Threshold voltage	$V_{CC} = 15V$	9.4	10.0	10.6	8.8	10.0	11.2	V
	$V_{CC} = 5V$	2.7	3.33	4.0	2.4	3.33	4.2	V
Threshold current[3]			30	250		30	250	nA
Trigger voltage	$V_{CC} = 15V$	4.8	5.0	5.2	4.5	5.0	5.6	V
	$V_{CC} = 5V$	1.45	1.67	1.9	1.1	1.67	2.2	V
Trigger current	$V_{TRIG} = 0V$		0.5	0.9		0.5	2.0	μA
Reset voltage[5]		0.4	0.7	1.0	0.4	0.7	1.0	V
Reset current			0.1	0.4		0.1	0.6	mA
Reset current	$V_{RESET} = 0V$		0.4	1.0		0.4	1.5	mA
Output voltage (low)	$V_{CC} = 15V$							
	$I_{SINK} = 10mA$		0.1	0.15		0.1	0.25	V
	$I_{SINK} = 50mA$		0.4	0.5		0.4	0.75	V
	$I_{SINK} = 100mA$		2.0	2.25		2.0	3.2	V
	$I_{SINK} = 200mA$		2.5			2.5		V
	$V_{CC} = 5V$							
	$I_{SINK} = 8mA$		0.1	0.2		0.25	0.3	V
	$I_{SINK} = 5mA$		0.05	0.15		0.15	0.25	V
Output voltage (high)	$V_{CC} = 15V$							
	$I_{SOURCE} = 200mA$		12.5			12.5		V
	$I_{SOURCE} = 100mA$	13.0	13.3		12.75	13.3		V
	$V_{CC} = 5V$							
	$I_{SOURCE} = 100mA$	3.0	3.3		2.75	3.3		V
Rise time of output			100	200		100	300	ns
Fall time of output			100	200		100	300	ns
Discharge leakage current			20	100		20	100	nA
Matching characteristics[4]								
Initial accuracy[2]			0.5	1.0		1.0	2.0	%
Drift with temperature			10			10		ppm/°C
Drift with supply voltage			0.1	0.2		0.2	0.5	%/V

NOTES

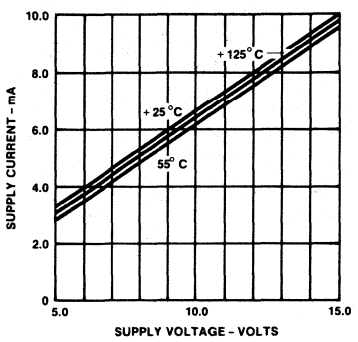
1. Supply current when output is high is typically 1.0mA less.
2. Tested at V_{CC} = 5V and V_{CC} = 15V.
3. This will determine the maximum value of $R_A + R_B$. For 15V operation, the maximum total R = 10 meg-ohms, and for 5V operation, the max. total R = 3.4 meg-ohms.
4. Matching charactristics refer to the difference between performance characteristics for each timer section in the monostable mode.
5. Specified with trigger input high.

TYPICAL PERFORMANCE CHARACTERISTICS

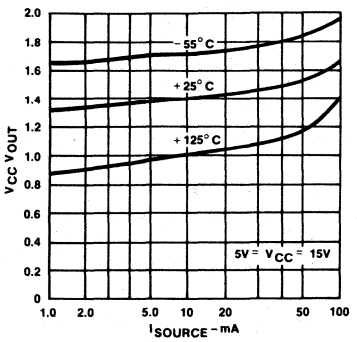
MINIMUM PULSE WIDTH REQUIRED FOR TRIGGERING



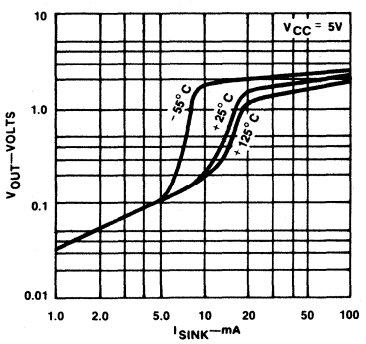
SUPPLY CURRENT vs SUPPLY VOLTAGE



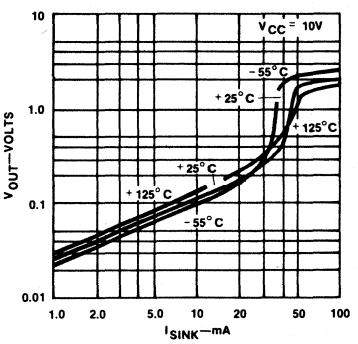
HIGH OUTPUT VOLTAGE DROP vs OUTPUT SOURCE CURRENT



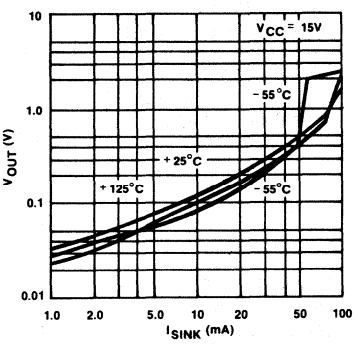
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



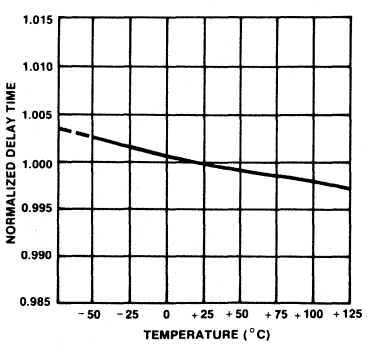
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



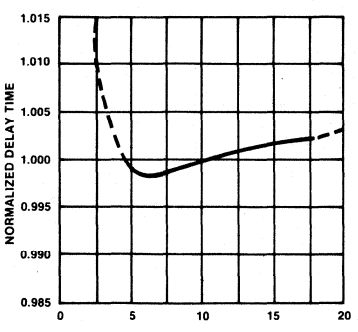
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



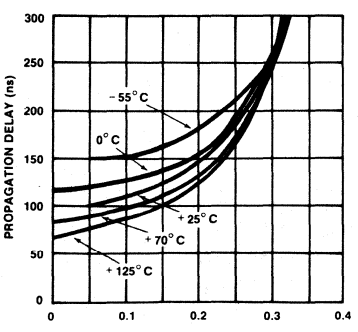
DELAY TIME vs TEMPERATURE



DELAY TIME vs SUPPLY VOLTAGE



PROPAGATION DELAY vs VOLTAGE LEVEL OF TRIGGER PULSE



SE556-1N,F • NE556-1N,F • SE556-1CN,F

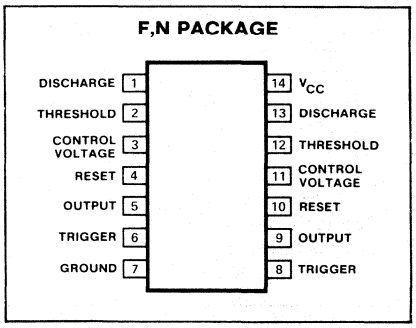
FEATURES

- Turn off time less than 2μS
- Maximum operating frequency greater than 500kHz
- Timing from microseconds to hours
- Replaces two 555 timers
- Operates in both astable and monostable modes
- High output current
- Adjustable duty cycle
- TTL compatible
- Temperature stability of 0.005% per °C

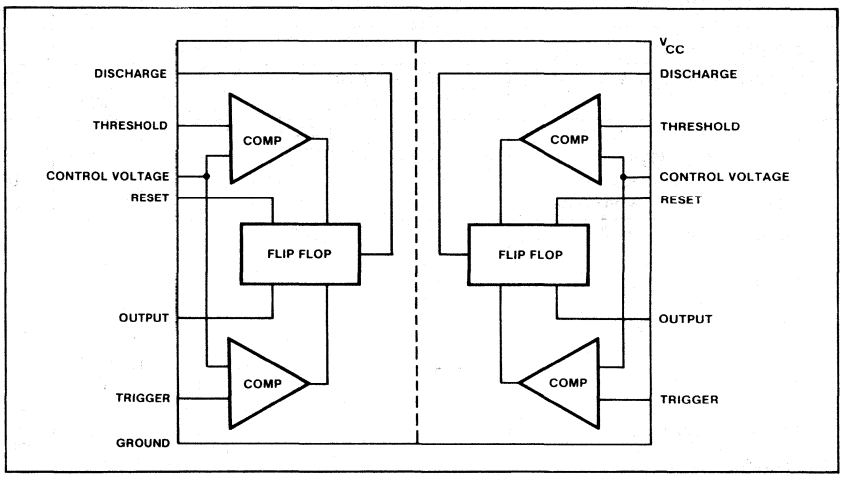
APPLICATIONS

- Precision timing
- Sequential timing
- Pulse shaping
- Pulse generator
- Missing pulse detector
- Tone burst generator
- Pulse width modulation
- Time delay generator
- Frequency division
- Industrial controls
- Pulse position modulation
- Appliance timing
- Traffic light control
- Touch tone encoder

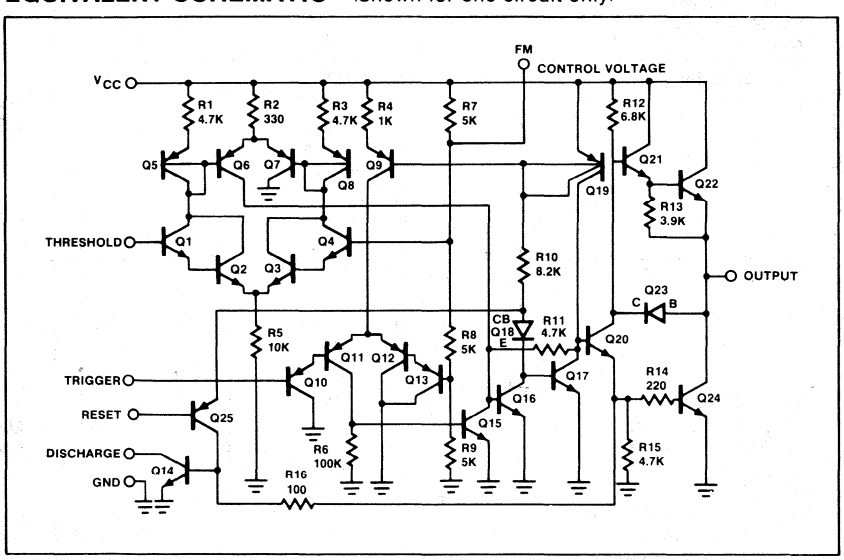
PIN CONFIGURATION



BLOCK DIAGRAM



EQUIVALENT SCHEMATIC (Shown for one circuit only)



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE556-1	+18	V
NE556-1, SE556-1C	+16	V
Power dissipation	1.20	W
Operating temperature range		
NE556-1	0 to +70	°C
SE556-1, SE556-1C	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature		
(soldering, 60 sec)	+300	°C

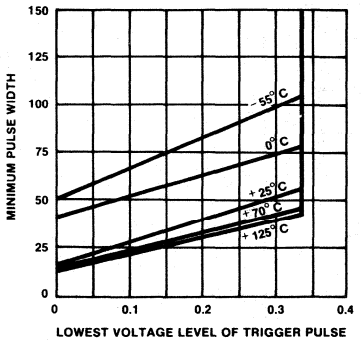
ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_{CC} = +5V$ to $+15V$ unless otherwise specified.

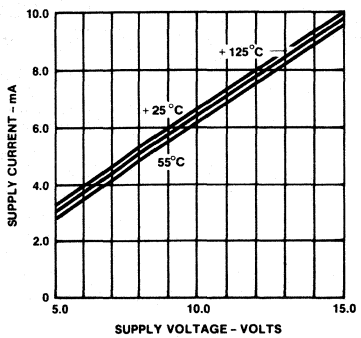
PARAMETER	TEST CONDITIONS	SE556-1			NE556-1/SE556-1C			UNITS
		Min	Typ	Max	Min	Typ	Max	
Supply voltage		4.5		18	4.5		16	V
Supply current (low state)[1]	V_{CC} = 5V $R_L = \infty$		6	10		6	12	mA
	V_{CC} = 15V $R_L = \infty$		20	24		20	30	mA
Timing error (monostable)	R_A = 2kΩ to 100kΩ							
Initial accuracy[2]	C = 0.1μF		0.5	1.5		0.75	3.0	%
Drift with temperature			30	100		50		ppm/°C
Drift with supply voltage			0.05	0.2		0.1	0.5	%/V
Timing error (astable)	R_A, R_B = 1kΩ to 100kΩ							
Initial accuracy[2]	C = 0.1μF		1.5			2.25		%
Drift with temperature	V_{CC} = 15V		90			150		ppm/°C
Drift with supply voltage			0.15			0.3		%/V
Control voltage level	V_{CC} = 15V	9.6	10.0	10.4	9.0	10.0	11.0	V
	V_{CC} = 5V	2.9	3.33	3.8	2.6	3.33	4.0	V
Threshold voltage	V_{CC} = 15V	9.4	10.0	10.6	8.8	10.0	11.2	V
	V_{CC} = 5V	2.7	3.33	4.0	2.4	3.33	4.2	V
Threshold current[3]			30	250		30	250	nA
Trigger voltage	V_{CC} = 15V	4.8	5.0	5.2	4.5	5.0	5.6	V
	V_{CC} = 5V	1.45	1.67	1.9	1.1	1.67	2.2	V
Trigger current	V_{TRIG} = 0V		0.5	0.9		0.5	2.0	μA
Reset voltage[5]		0.4	0.7	1.0	0.4	0.7	1.0	V
Reset current			0.1	0.4		0.1	0.6	mA
Reset current	V_{RESET} = 0V		0.4	1.0		0.4	1.5	mA
Output voltage (low)	V_{CC} = 15V							
	I_{SINK} = 10mA		0.1	0.15		0.1	0.25	V
	I_{SINK} = 50mA		0.4	0.5		0.4	0.75	V
	I_{SINK} = 100mA		0.8	1.2		2.0	2.5	V
	I_{SINK} = 200mA		2.5			2.5		V
	V_{CC} = 5V							
	I_{SINK} = 8mA		0.1	0.2		0.25	0.3	V
	I_{SINK} = 5mA		0.05	0.15		0.15	0.25	V
Output voltage (high)	V_{CC} = 15V							
	I_{SOURCE} = 200mA		12.5			12.5		V
	I_{SOURCE} = 100mA	13.0	13.3		12.75	13.3		V
	V_{CC} = 5V							
	I_{SOURCE} = 100mA	3.0	3.3		2.75	3.3		V
Turn off time[6]	V_{RESET} = V_{CC}		0.5	2.0		0.5		μs
Rise time of output			100	200		100	300	ns
Fall time of output			100	200		100	300	ns
Discharge leakage current			20	100		20	100	nA
Matching characteristics[4]								
Initial accuracy[2]			0.5	1.0		1.0	2.0	%
Drift with temperature			±10			±10		ppm/°C
Drift with supply voltage			0.1	0.2		0.2	0.5	%/V

TYPICAL CHARACTERISTICS

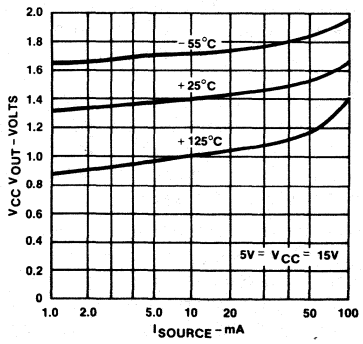
MINIMUM PULSE WIDTH REQUIRED FOR TRIGGERING



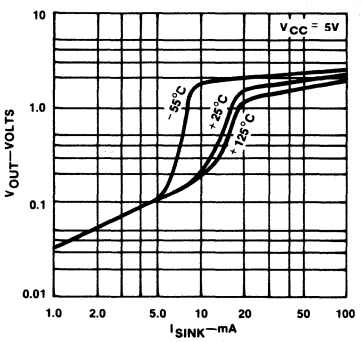
SUPPLY CURRENT vs SUPPLY VOLTAGE



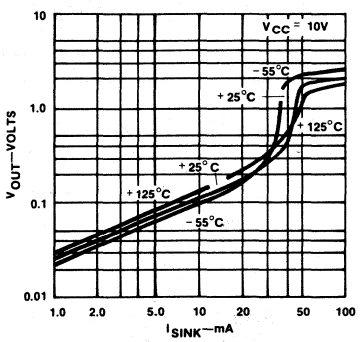
HIGH OUTPUT VOLTAGE DROP vs OUTPUT SOURCE CURRENT



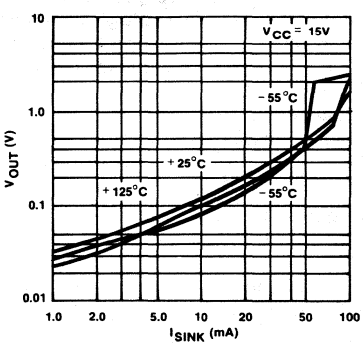
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



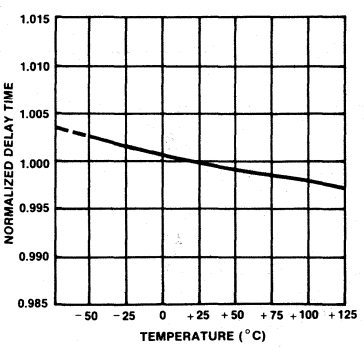
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



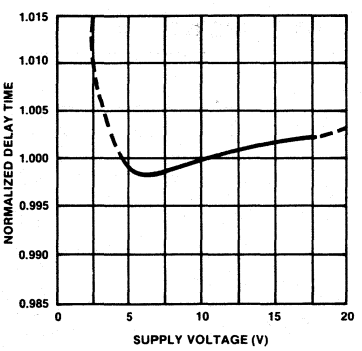
LOW OUTPUT VOLTAGE vs OUTPUT SINK CURRENT



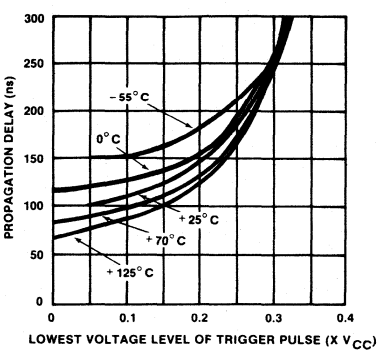
DELAY TIME vs TEMPERATURE



DELAY TIME vs SUPPLY VOLTAGE



PROPAGATION DELAY vs VOLTAGE LEVEL OF TRIGGER PULSE



NOTES

1. Supply current when output is high is typically 1.0mA less.
2. Tested at V_{CC} = 5V and V_{CC} = 15V.
3. This will determine the maximum value of $R_A + R_B$. For 15V operation, the maximum total R = 10 megohms, and for 5V operation, the max. total R = 3.4 megohms.
4. Matching characteristics refer to the difference between performance characteristics for each timer section in the monostable mode.
5. Specified with trigger input high.
6. Time measured from a positive going input pulse from 0 to 0.8 V_{CC} into the threshold to the drop from high to low of the output. Trigger is tied to threshold.

NE/SE558-F, N

DESCRIPTION

The SA/SE/NE558 Quad Timers are monolithic timing devices which can be used to produce four entirely independent timing functions. The 558 output sinks current. These highly stable, general purpose controllers can be used in a monostable mode to produce accurate time delays, from microseconds to hours. In the time delay mode of operation, the time is precisely controlled by one external resistor and one capacitor. A stable operation can be achieved by using two of the four timer sections.

The four timing sections in the 558 are edge triggered; therefore, when connected in tandem for sequential timing applications, no coupling capacitors are required. Output current capability of 100mA is provided in both devices.

FEATURES

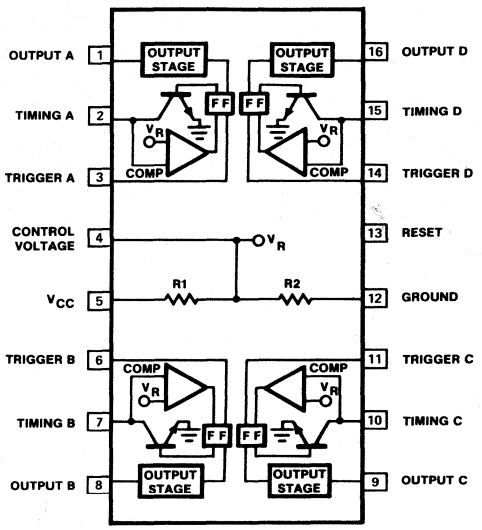
- **100mA output current per section**
- **Edge triggered (no coupling capacitor)**
- **Output independent of trigger conditions**
- **Wide supply voltage range 4.5V to 18V**
- **Timer intervals from microseconds to hours**
- **Time period equals RC**
- **Military qualifications pending**

APPLICATIONS

- **Sequential timing**
- **Time delay generation**
- **Precision timing**
- **Industrial controls**
- **Quad one-shot**

PIN CONFIGURATION

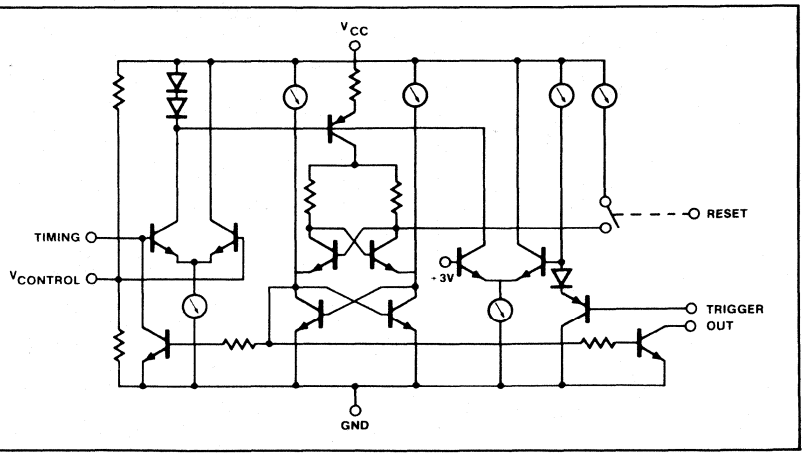
F,N PACKAGE



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE558, SE559	+18	V
NE558, NE559	+16	V
Power dissipation	1.25	W
Operating temperature range		
NE558, NE559	0 to +70	°C
SE558	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60sec)	+300	°C

558 EQUIVALENT CIRCUIT



ELECTRICAL CHARACTERISTICS T_A = 25°C, V_{CC} = +5V to +15V unless otherwise specified.

PARAMETER	TEST CONDITIONS	SE558			NE558			UNIT
		Min	Typ	Max	Min	Typ	Max	
Supply voltage		4.5		18	4.5		16	V
Supply current (558) (559) Timing accuracy (T = RC)	V_{CC} = Reset = 15V V_{CC} = Reset = 15V R = 2kΩ to 100kΩ C = 1μF		21 9	32 16		27 12	36 18	mA mA
Initial accuracy Drift with temperature Drift with supply voltage			1.0 150 0.1	3		2 150 0.1		% ppm/°C %/V
Trigger voltage[1] Trigger current	V_{CC} = 15V Trigger = 0V	0.8	1.5 5	2.4 30	0.8	1.5 5	2.4 100	V μA
Reset voltage[2] Reset current	Reset	0.8	1.5 50	2.4 300	0.8	1.5 50	2.4	V μA
Threshold voltage Threshold leakage			0.63 15			0.63 15		xVCC nA
Output voltage (558)[3]	I_L = 10mA I_L = 100mA		0.1 0.7	0.2 1.5		0.1 1.0	0.4 2.0	V V
Output voltage (559)[4]	I_L = 10mA I_L = 100mA	13 12.5	13.6 13.3		12.5 12.0	13.3 13.0		V V
Output leakage Propagation delay (558) (559)			10 1.0 0.4			10 1.0 0.4		nA μs μs
Risetime of output Falltime of output	I_L = 100mA I_L = 100mA		100 100			100 100		ns ns

NOTES

1. The trigger functions only on the falling edge of the trigger pulse only after previously being high. After reset the trigger must be brought high and then low to implement triggering.
2. For reset below 0.8 volts, outputs set low and trigger inhibited. For reset above 2.4 volts, trigger enabled.
3. The 558 output structure is open collector which requires a pull up resistor to V_{CC} to sink current. The output is normally low sinking current.
4. The 559 output structure is a darlington emitter follower which requires a pull down resistor to ground to source current. The output is normally low and sources current only when switched high.

SECTION 5
COMPARATORS

Section 5—COMPARATORS

5

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

FEATURES

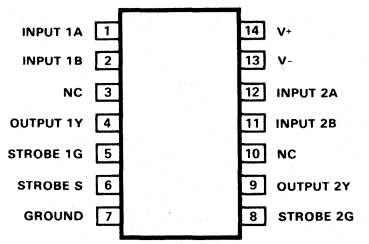
- 12ns maximum guaranteed propagation delay
- 20μA maximum input bias current
- TTL compatible strobes and outputs
- Large common mode input voltage range
- Operates from standard supply voltages
- Military qualifications pending

APPLICATIONS

- MOS memory sense amp
- A-to-D conversion
- High speed line receiver

PIN CONFIGURATION

F,N PACKAGE

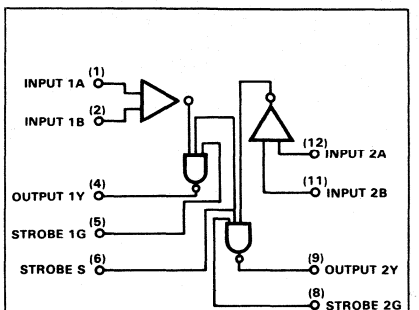


Order Part No.
NE521 F,N
SE521 F,N

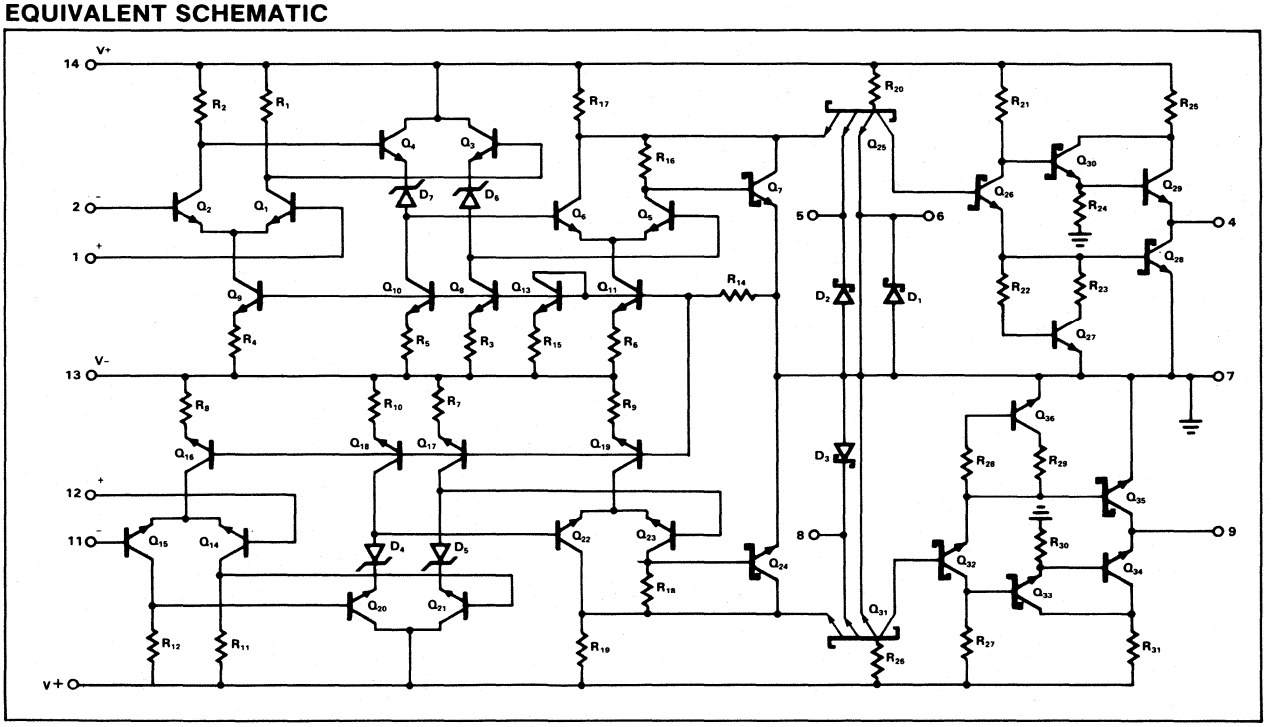
ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
	Supply voltage		V
V+	Positive	+7	
V-	Negative	-7	
V_{IDR}	Differential input voltage	±6	V
V_{IN}	Input voltage		V
	Common mode	±5	
	Strobe/gate	+5.25	
P_D	Power dissipation	600	mW
T_A	Operating temperature range	0 to 70	°C
T_{stg}	Storage temperature range	-65 to +150	°C
	Lead temperature (solder, 60 sec)	+300	°C

BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS $V+ = +5V$, $V- = -5V$, $T_A = 0$ to 70°C unless otherwise specified

	PARAMETER	TEST CONDITIONS	SE LIMITS Min	SE LIMITS Typ	SE LIMITS Max	UNITS
V_{OS}	Input offset voltage At 25°C Over temperature range	V+ = +4.5V, V- = -4.75V		 6	 7.5 15	mV
I_{BIAS}	Input bias current At 25°C Over temperature range	V+ = +5.5V, V- = -5.5V		 7.5	 20 40	µA
I_{OS}	Input offset current At 25°C Over temperature range	V+ = +5.5V, V- = -5.5V		 1.0	 5 12	µA
V_{CM}	Common mode voltage range	V+ = +4.5V, V- = -4.5V	±3			V
V_{IL}	Low level input voltage At 25°C Over temperature				 0.8 0.7	
I_{IH}	Input current High	V+ = +5.5V, V- = -5.5V V_{IH} = 2.7V 1G or 2G strobe Common strobe S			 50 100	 µA µA
I_{IL}	Low	V_{IL} = 0.5V 1G or 2G strobe Common strobe S			 -2.0 -4.0	 mA mA
V_{OH} V_{OL}	Output voltage High Low	$V_{I(S)}$ = 2.0V V+ = +4.5V, V- = -4.5V, I_{LOAD} = -1mA V+ = +4.5V, V- = -4.5V, I_{LOAD} = -10mA T_A=25°C	 2.5	 3.4	 0.5	V
V+ V-	Supply voltage Positive Negative		 4.5 -4.5	 5.0 -5.0	 5.5 -5.5	V
I_{CC+} I_{CC-}	Supply current Positive Negative	V+ = 5.5V, V- = -5.5V, T_A = 25°C		 27 -15	 50 -28	mA
I_{SC}	Short circuit output current		-35		-125	µA

DC ELECTRICAL CHARACTERISTICS (Cont'd) $V+ = +5V$, $V- = -5V$, $T_A = 0$ to $70°C$ unless otherwise specified

	PARAMETER	TEST CONDITIONS	NE LIMITS Min	NE LIMITS Typ	NE LIMITS Max	UNITS
V_{OS}	Input offset voltage At 25°C Over temperature range	V+ = +4.75V, V- = -4.75V		6	7.5 10	mV
I_{BIAS}	Input bias current At 25°C Over temperature range	V+ = +5.25V, V- = -5.25V		7.5	20 40	µA
I_{OS}	Input offset current At 25°C Over temperature range	V+ = +5.25V, V- = -5.25V		1.0	5 12	µA
V_{CM}	Common mode voltage range	V+ = +4.75V, V- = -4.75V	±3			V
	Input current	V+ = +5.25V, V- = -5.25V				
I_{IH}	High	V_{IH} = 2.7V				
		1G or 2G strobe			50	µA
		Common strobe S			100	µA
I_{IL}	Low	V_{IL} = 0.5V				
		1G or 2G strobe			-2.0	mA
		Common strobe S			-4.0	mA
	Output voltage	$V_{I(S)}$ = 2.0V				V
V_{OH}	High	V+ = +4.75V, V- = -4.75V, I_{LOAD} = -1mA	2.7	3.4		
V_{OL}	Low	V+ = +5.25V, V- = -5.25V, I_{LOAD} = 20mA			0.5	
	Supply voltage					V
V+	Positive		4.75	5.0	5.25	
V-	Negative		-4.75	-5.0	-5.25	
	Supply current	V+ = 5.25V, V- = -5.25V, T_A = 25°C				mA
I_{CC+}	Positive			27	50	
I_{CC-}	Negative			-15	-28	
I_{SC}	Short circuit output current		-40		-100	µA

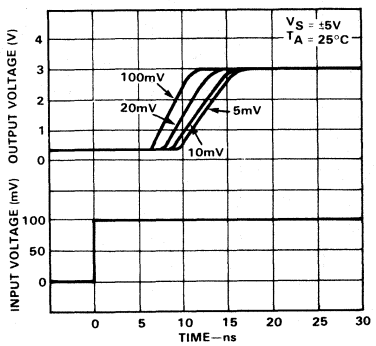
AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $R_L = 280\,\Omega$ $C_L = 15pF$ $V+ = +5V$ $V- = -5V$

PARAMETER		FROM INPUT	TO OUTPUT	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
Large Signal Switching Speed							
	Propagation delay						ns
$t_{PLH(D)}$	Low to high[1]	Amp	Output		8	12	
$t_{PHL(D)}$	High to low[1]	Amp	Output		6	9	
$t_{PLH(S)}$	Low to high[2]	Strobe	Output		4.5	6	
$t_{PHL(S)}$	High to low[2]	Strobe	Output		3.0	4.5	
	Maximum operating frequency			40	55		MHz

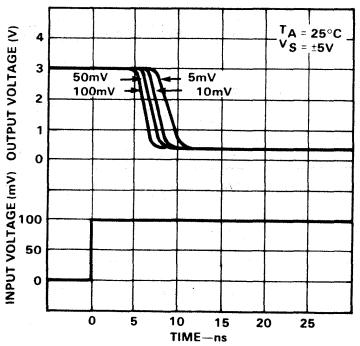
NOTES
1. Response time measured from 0V point of ±100mV p-p 10MHz square wave to the 1.5V point of the output
2. Response time measured from 1.5V point of input to 1.5V point of the output

TYPICAL PERFORMANCE CHARACTERISTICS

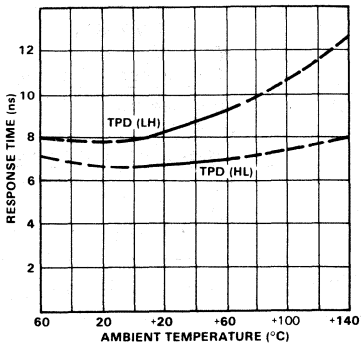
RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



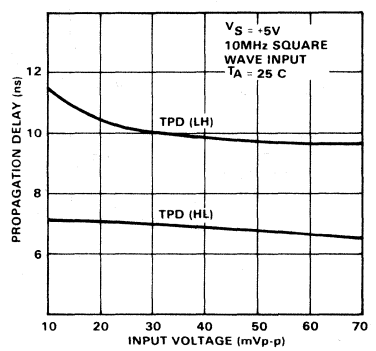
RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



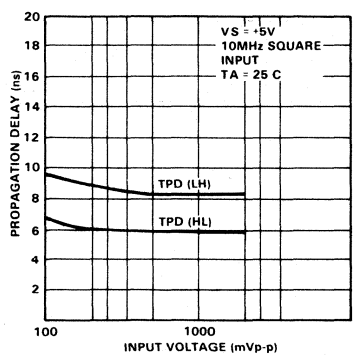
RESPONSE TIME vs TEMPERATURE



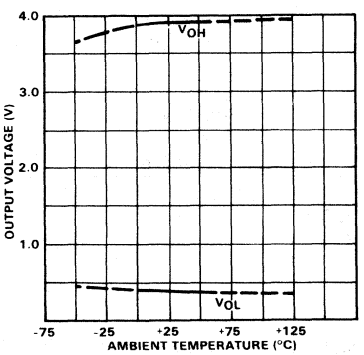
PROPAGATION DELAY FOR VARIOUS INPUT VOLTAGE



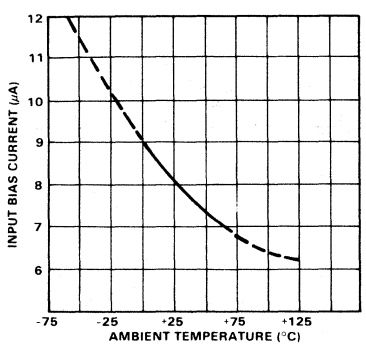
PROPAGATION DELAY FOR VARIOUS INPUT VOLTAGES



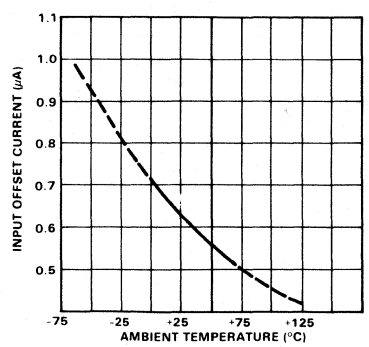
OUTPUT VOLTAGE vs AMBIENT TEMPERATURE



INPUT BIAS CURRENT vs AMBIENT TEMPERATURE



INPUT OFFSET CURRENT vs AMBIENT TEMPERATURE



NE522-F,N • SE522-F

FEATURES

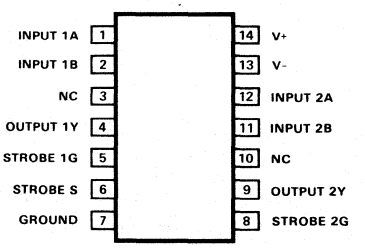
- 15ns maximum guaranteed propagation delay
- 20μA maximum input bias current
- TTL compatible strobes and outputs
- Open collector output for wire-OR'd applications
- Large common mode input voltage range
- Operates from standard supply voltages

APPLICATIONS

- MOS memory sense amp
- A-to-D conversion
- High speed line receiver

PIN CONFIGURATION

F,N PACKAGE



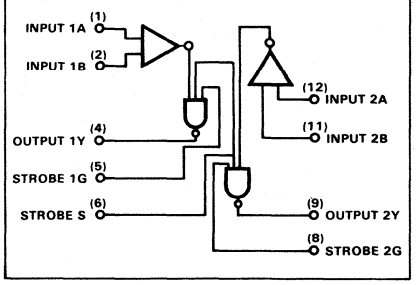
Order Part No.

NE522 F,N
SE522 F

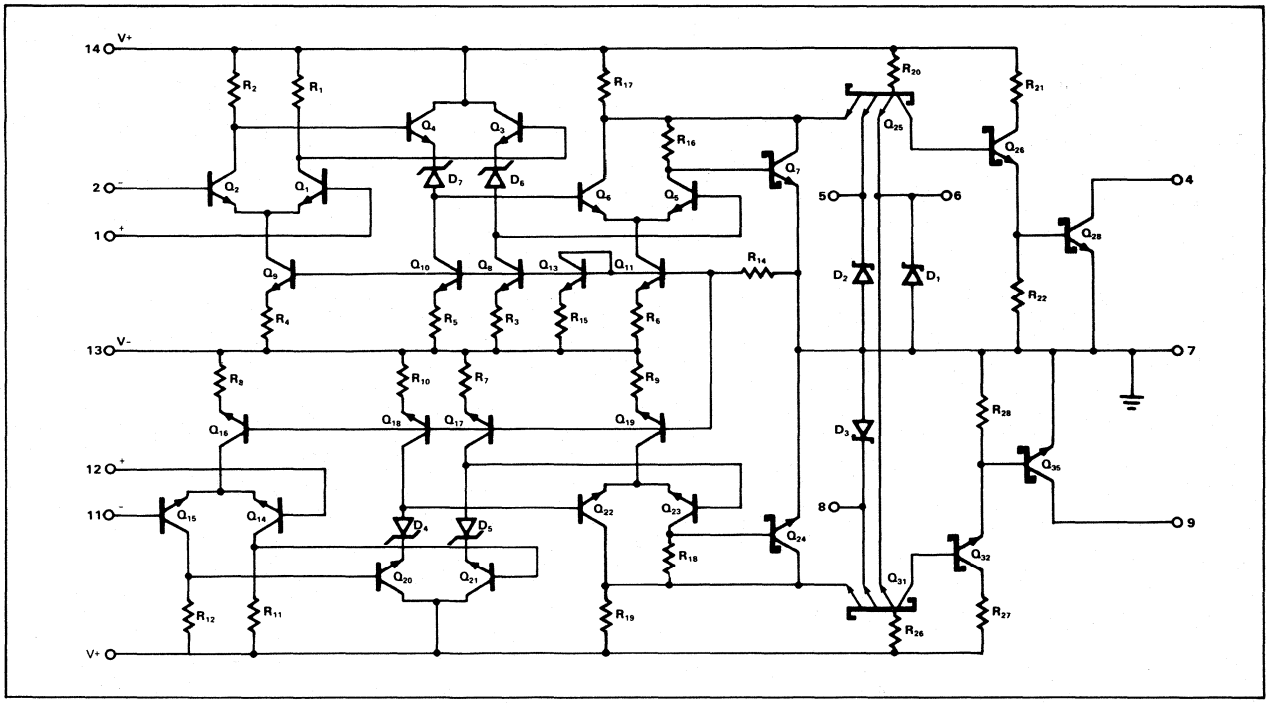
ABSOLUTE MAXIMUM RATINGS

PARAMETER		RATING	UNIT
	Supply voltage		V
V+	Positive	+7	
V-	Negative	-7	
V_{IDR}	Differential input voltage	±6	V
V_{IN}	Input voltage		V
	Common mode	±5	
	Strobe/gate	±5.25	
P_D	Power dissipation	600	mW
T_A	Operating temperature range NE	0 to 70	°C
	SE	-55 to +125	
T_{stg}	Storage temperature range	-65 to +150	°C
	Lead temperature (solder, 60 sec)	+300	°C

BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS

±5V ±10%, T_A = -55 to 125°C unless otherwise specified

PARAMETER		TEST CONDITIONS	SE LIMITS			UNIT
			Min	Typ	Max	
V_{OS}	Input offset voltage At 25°C Over temperature range	V+ = +4.5V, V- = -4.5V		 6	 7.5 15.	mV
I_{BIAS}	Input bias current At 25°C Over temperature range	V+ = +5.5V, V- = -5.5V		 7.5	 20. 40.	μA
I_{OS}	Input offset current At 25°C Over temperature range	V+ = +5.5V, V- = -5.5V		 1.0	 5. 12.	μA
V_{CM}	Common mode voltage range	V+ = +4.5V, V- = -4.5V	±3			V
I_{IH}	Input current High	V+ = +5.5V, V- = -5.5V V_{IH} = 2.7V 1G or 2G strobe Common strobe S			 50 100	 μA μA
I_{IL}	Low	V_{IL} = 0.5V 1G 2G strobe Common strobe S			 -2 -4	 mA mA
V_{OL}	Output voltage Low	V+ = +4.5V, V- = -4.5V I_{OL} = 20mA, T_A = 25°C I_{OL} = 10mA			 .5 .5	V
I_{OH}	Output current High	V_{CC+} = +4.5, V_{CC-} = -4.5V, V_{OH} = 5.5V			 250	μA
V+ V-	Supply voltage Positive Negative		 4.5 -4.5	 5.0 -5.0	 5.5 -5.5	V
I_{CC+} I_{CC-}	Supply current Positive Negative	V+ = 5.5V, V- = -5.5V		 27 -15	 50 -28	mA

DC ELECTRICAL CHARACTERISTICS (Cont'd) ±5V ±5%, T_A = 0 to 70°C unless otherwise specified

PARAMETER		TEST CONDITIONS	NE LIMITS			UNIT
			Min	Typ	Max	
V_{OS}	Input offset voltage At 25°C Over temperature range	V+ = +4.75V, V- = -4.75V		 6	 7.5 10	mV
I_{BIAS}	Input bias current At 25°C Over temperature range	V+ = +5.25V, V- = -5.25V		 7.5	 20 40	μA
I_{OS}	Input offset current At 25°C Over temperature range	V+ = +5.25V, V- = -5.25V		 1.0	 5 12	μA
V_{CM}	Common mode voltage range	V+ = +4.75V, V- = -4.75V	±3			V
I_{IH}	Input current High	V+ = +5.25V, V- = -5.25V V_{IH} = 2.7V 1G or 2G strobe Common strobe S			 50 100	 μA μA
I_{IL}	Low	V_{IL} = 0.5V 1G 2G strobe Common strobe S			 -2.0 -4.0	 mA mA
V_{OL}	Output voltage Low	V+ = +5.25V, V- = -5.25V, $V_{I\,(S)}$ = 2.0V			0.5	V
I_{OH}	Output current High	I_{LOAD} = 20mA, V_{CC+} = +4.75, V_{CC-} = -4.75V, V_{OH} = 5.25V			250	μA
V+ V-	Supply voltage Positive Negative		 4.75 -4.75	 5.0 -5.0	 5.25 -5.25	V
I_{CC+} I_{CC-}	Supply current Positive Negative	V+ = 5.25V, V- = -5.25V, T_A = 25°C		 27 -15	 50 -28	mA

AC ELECTRICAL CHARACTERISTICS T_A = 25°C, R_L = 280Ω, C_L = 15pF

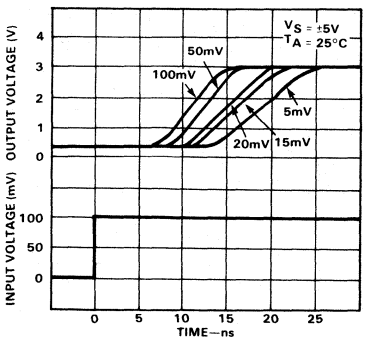
PARAMETER		FROM INPUT	TO OUTPUT	LIMITS			UNIT
				Min	Typ	Max	
	Input resistance				4		kΩ
	Input capacitance				3		pF
Large Signal Switching Speed							
	Propagation delay						ns
$t_{PLH(D)}$	Low to high[1]	Amp	Output		10	15	
$t_{PHL(D)}$	High to low[1]	Amp	Output		8	12	
$t_{PLH(S)}$	Low to high[2]	Strobe	Output		6	10	
$t_{PHL(S)}$	High to low[2]	Strobe	Output		5	8	
	Maximum operating frequency			25	35		MHz
Small Signal Switching Speed							
	Propagation delay						ns
$t_{PLH(D)}$	Low to high[3]	Amp	Output		17	25	
$t_{PHL(D)}$	High to low[3]	Amp	Output		11	17	

NOTES

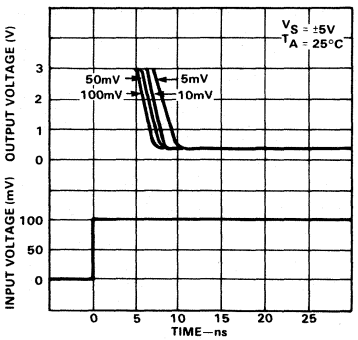
1. Response time measured from 0V point of ±100mV p-p 10MHz square wave to the 1.5V point of the output
2. Response time measured from 1.5V point of input to 1.5V point of the output
3. Response time measured from the start of a 100mV input step with 5mV overdrive to the 1.5V point of the output

TYPICAL PERFORMANCE CHARACTERISTICS

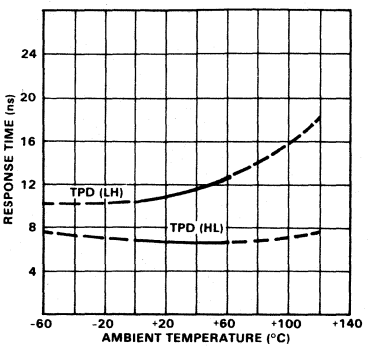
RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



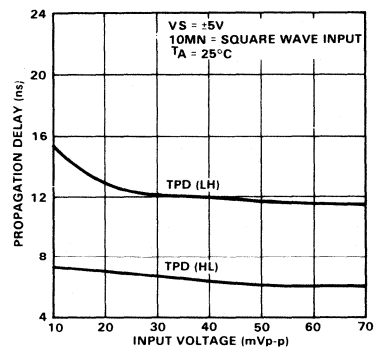
RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



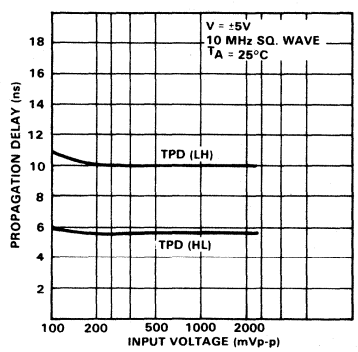
RESPONSE TIME vs TEMPERATURE



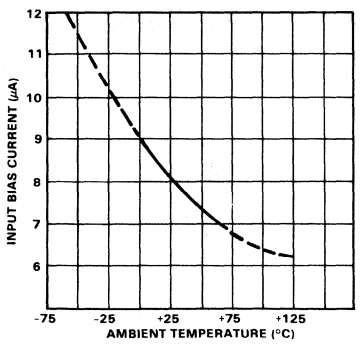
PROPAGATION DELAY FOR VARIOUS INPUT VOLTAGES



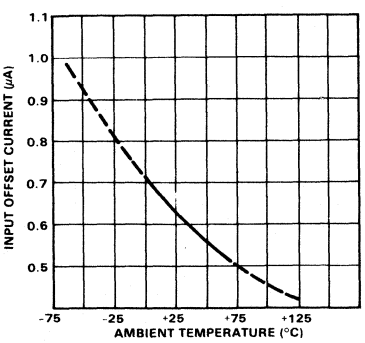
PROPAGATION DELAY FOR VARIOUS INPUT VOLTAGES



INPUT BIAS CURRENT vs AMBIENT TEMPERATURE



INPUT OFFSET CURRENT vs AMBIENT TEMPERATURE



NE527-F,H,N/SE527-F,H,N

DESCRIPTION

The SE/NE527 is a high speed analog voltage comparator which, in the first time mates state-of-the-art Schottky diode technology with the conventional linear process. This allows simultaneous fabrication of high speed T²L gates with a precision linear amplifier on a single monolithic chip. The SE/NE527 is similar in design to the Signetics SE/NE529 voltage comparator except that it incorporates a "Emitter Follower" input stage for extremely low input currents. This opens the door to a whole new range of applications for analog voltage comparators.

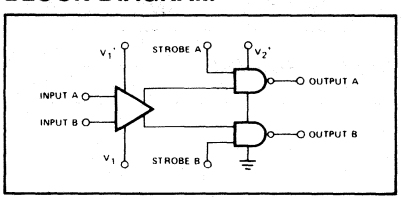
FEATURES

- **15ns propagation delay**
- **Complementary output gates**
- **TTL or ECL compatible outputs**
- **Wide common mode and differential voltage range**
- **Mil std 883A,B,C available**

APPLICATIONS

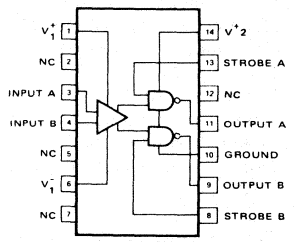
- **A/D conversion**
- **ECL to TTL interface**
- **TTL to ECL interface**
- **Memory sensing**
- **Optical data coupling**

BLOCK DIAGRAM

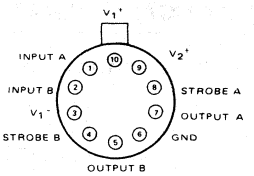


PIN CONFIGURATIONS

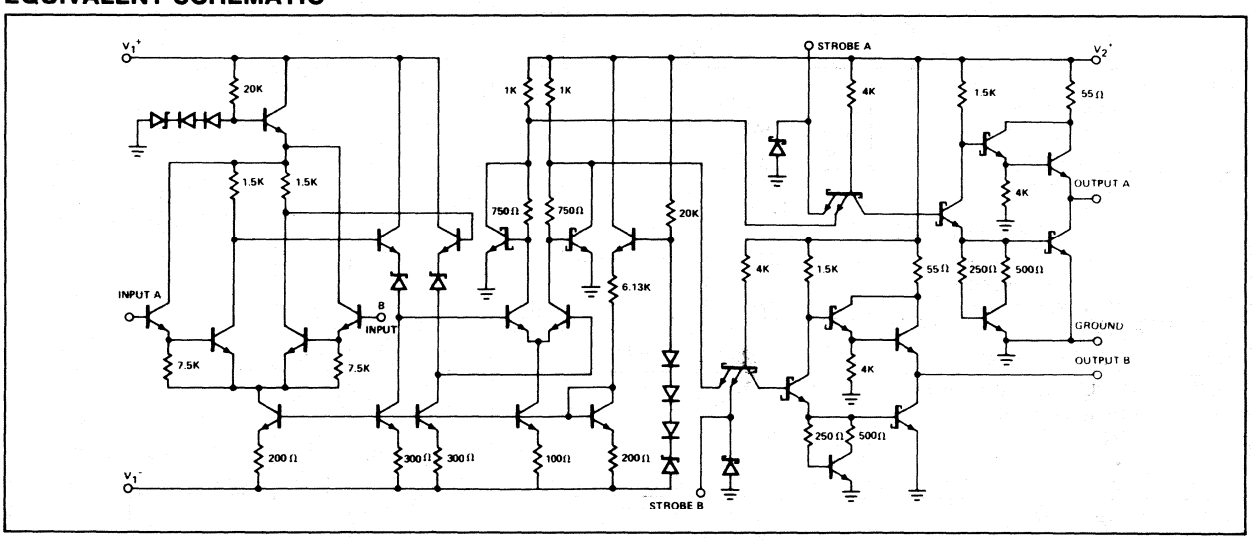
F,N PACKAGE



H PACKAGE



EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Positive supply voltage (V1+)	+15	V
Negative supply voltage (V1-)	-15	V
Gate supply voltage (V2+)	+7	V
Output voltage	+15	V
Differential input voltage	±5	V
Input common mode voltage	±6	V
Power dissipation	600	mW
Operating temperature range		
NE527	0 to +70	°C
SE527	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60sec)	+300	°C

DC ELECTRICAL CHARACTERISTICS $V_1^+ = 10V, V_1^- = -10V, V_2^+ = +5.0V$

PARAMETER	TEST CONDITIONS	SE527			NE527			UNIT
		Min	Typ	Max	Min	Typ	Max	
INPUT CHARACTERISTICS								
Input offset voltage @ 25°C				4			6	mV
Over temperature range				6			10	mV
Input bias current @ 25°C				2			2	μA
Over temperature range				4			4	μA
Input offset current @ 25°C				0.5			0.75	μA
Over temperature range	$V_{IN} = 0V$			1			1	μA
GATE CHARACTERISTICS								
Output voltage								
"1" State	$V_2^+ = 4.75V, I_{SOURCE} = -1mA$	2.5	3.3		2.7	3.3		V
"0" State	$V_2^+ = 4.75V, I_{SINK} = 10mA$			0.5			0.5	V
Strobe inputs								
"0" Input current	$V_2^+ = 5.25V, V_{STROBE} = 0.5V$			-2			-2	mA
"1" Input current @ 25°C	$V_2^+ = 5.25V, V_{STROBE} = 2.7V$			50			100	μA
Over temperature range	$V_2^+ = 5.25V, V_{STROBE} = 2.7V$			200			200	μA
"0" Input voltage	$V_2^+ = 4.75V$			0.8			0.8	V
"1" Input voltage	$V_2^+ = 4.75V$	2.0			2.0			V
Short circuit								
Output current	$V_2^+ = 5.25V, V_{OUT} = 0V$	-18		-70	-18		-70	mA
POWER SUPPLY REQUIREMENTS								
Supply voltage								
V_1^+		5		10	5		10	V
V_1^-		-6		-10	-6		-10	V
V_2^+		4.5	5	5.5	4.75	5	5.25	V
Supply current	$V_1^+ = 10V, V_1^- = -10V$ $V_2^+ = 5.25V$							
I_1^+	Over temp.			5			5	mA
I_1^-	Over temp.			10			10	mA
I_2^+	Over temp.			20			20	mA

*NOTE

Parameters are guaranteed over the temperature range unless otherwise specified.

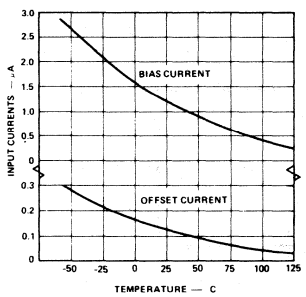
AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ	Max	
Transient response propagation delay time t_{PLH} t_{PHL}	$V_{IN} = \pm 100mV$ step $T_A = 25°C$		 16 14	 26 24	 ns ns
Delay between output A and B			2	5	ns
Strobe delay time t_{on} Turn-on time t_{off} Turn-off time			 6 6		 ns ns

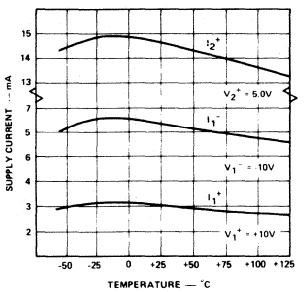
5

TYPICAL PERFORMANCE CHARACTERISTICS

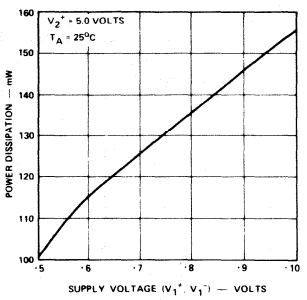
INPUT CURRENTS vs TEMPERATURE



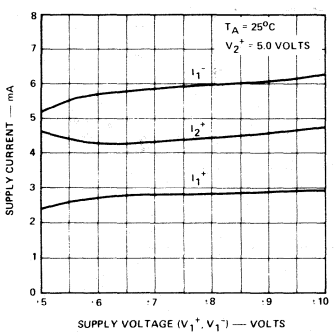
SUPPLY CURRENT vs TEMPERATURE



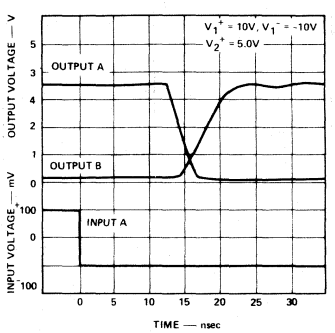
POWER DISSIPATION vs SUPPLY VOLTAGE



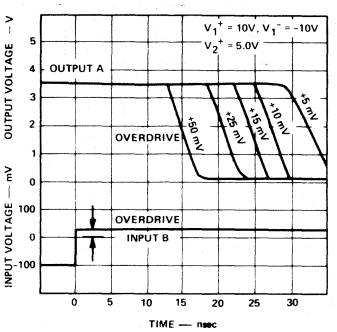
SUPPLY CURRENT vs SUPPLY VOLTAGE



OUTPUT PROPAGATION DELAYS



RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



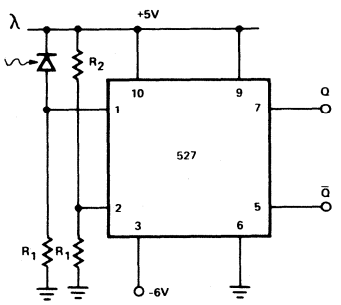
APPLICATIONS

One of the main features of the device is that supply voltages (V1+, V1−) need not be balanced, as indicated in the following diagrams. For proper operation, however, negative supply (V1−) should always be at least six volts more negative than the ground terminal (pin 6). Input Common Mode range should be limited to values of two volts less than the supply voltages (V1+ and V1−) up to a maximum of ±6 volts as supply voltages are increased.

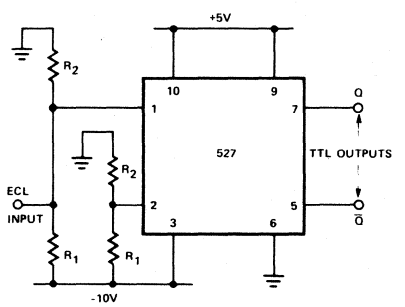
It is also important to note that Output A is in phase with Input A and Output B is in phase with Input B.

TYPICAL APPLICATIONS

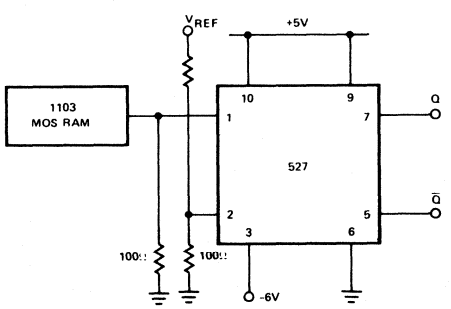
PHOTODIODE DETECTOR



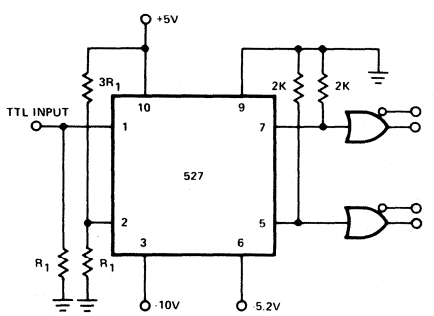
ECL TO TTL INTERFACE



MOS MEMORY SENSE AMP



TTL TO ECL INTERFACE



NE529-F,H,N/SE529-F,H

DESCRIPTION

The SE/NE529 is a high speed analog voltage comparator which, for the first time mates state-of-the-art Schottky diode technology with the conventional linear process. This allows simultaneous fabrication of high speed T²L gates with a precision linear amplifier on a single monolithic chip.

FEATURES

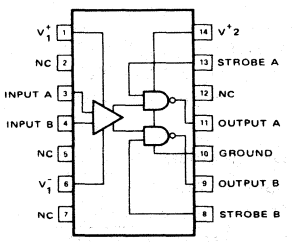
- **10ns propagation delay**
- **Complementary output gates**
- **TTL or ECL compatible outputs**
- **Wide common mode and differential voltage range**

APPLICATIONS

- **A/D conversion**
- **ECL to TTL interface**
- **TTL to ECL interface**
- **Memory sensing**
- **Optical data coupling**
- **Mil std 883A,B,C available**

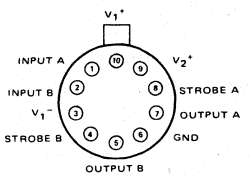
PIN CONFIGURATION

F,N PACKAGE



ORDER PART NO.
NE/SE529F,NE529N

H PACKAGE

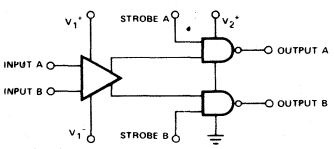


ORDER PART NO.
NE/SE529H

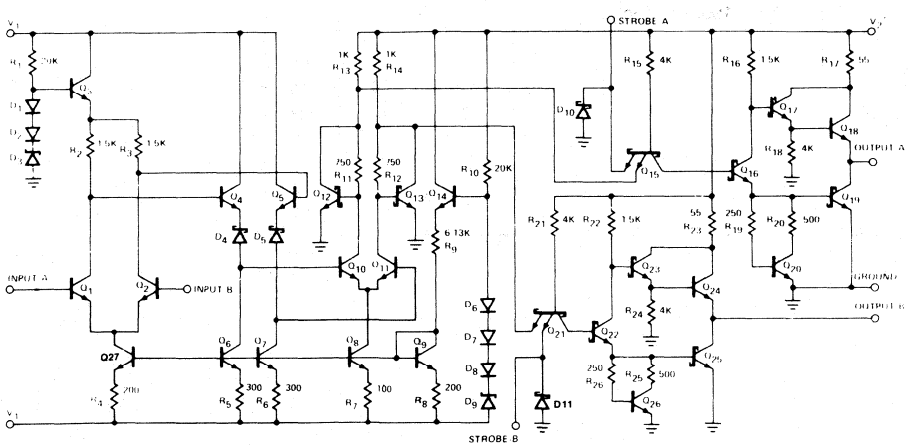
ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Positive supply voltage (V1+)	+15	V
Negative supply voltage (V1-)	-15	V
Gate supply voltage (V2+)	+7	V
Output voltage	+15	V
Differential input voltage	±5	V
Input common mode voltage	±6	V
Power dissipation	600	mW
Operating temperature range		
NE529	0 to +70	°C
SE529	-55 to +125	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60 sec)	+300	°C

BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS $V_1+ = +10V, V_2+ = +5.0V, V_1- = -10V$

PARAMETER	TEST CONDITIONS	SE529			NE529			UNIT
		Min	Typ	Max	Min	Typ	Max	
INPUT CHARACTERISTICS								
Input offset voltage @25°C				4			6	mV
Over temperature range				6			10	mV
Input bias current @25°C			5	12		5	20	μA
Over temperature range	$V_{IN} = 0V$			36			50	μA
Input offset current @25°C			2	3		2	5	μA
Over temperature range	$V_{IN} = 0V$			9			15	μA
GATE CHARACTERISTICS								
Output voltage								
"1" state	$V_2+ = 4.75V, I_{source} = -1mA$	2.5	3.3		2.7	3.3		V
"0" state	$V_2+ = 4.75V, I_{sink} = 10mA$			0.5			0.5	V
Strobe inputs								
"0" input current	$V_2+ = 5.25V, V_{strobe} = 0.5V$			-2			-2	mA
"1" input current @25°C	$V_2+ = 5.25V, V_{strobe} = 2.7V$			50			100	μA
Over temperature range	$V_2+ = 5.25V, V_{strobe} = 2.7V$			200			200	μA
"0" input voltage	$V_2+ = 4.75V$			0.8			0.8	V
"1" input voltage	$V_2+ = 4.75V$	2.0			2.0			V
Short circuit								
Output current	$V_2+ = 5.25V, V_{OUT} = 0V$	-18		-70	-18		-70	mA
POWER SUPPLY REQUIREMENTS								
Supply voltage								
V_1+		5		10	5		10	V
V_1-		-6		-10	-6		-10	V
V_2+		4.5	5	5.5	4.75	5	5.25	V
Supply current	$V_1+ = 10V, V_1- = -10V$ $V_2+ = 5.25V$							
I_1+	Over temp.			5			5	mA
I_1-	Over temp.			10			10	mA
I_2+	Over temp.			20			20	mA

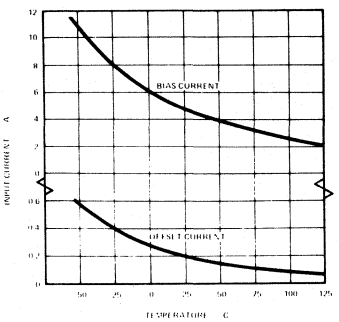
Parameters are guaranteed over the temperature range unless otherwise specified.

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$

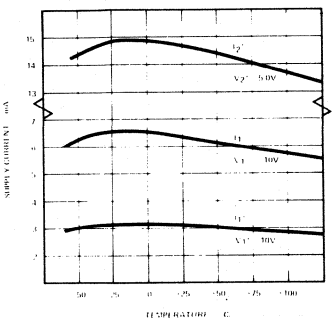
PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ	Max	
Transient response	$V_{IN} = \pm 100mV$ step				
Propagation delay time					
t_{PLH}			12	22	ns
t_{PHL}			10	20	ns
Delay between output A and B			2	5	ns
Strobe delay time					
t_{ON} turn-on time			6		ns
t_{OFF} turn-off time			6		ns

TYPICAL PERFORMANCE CHARACTERISTICS

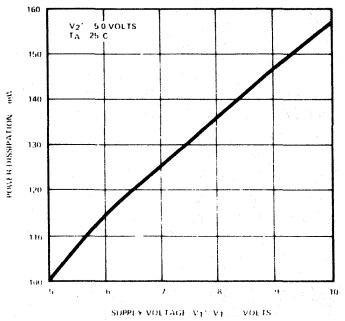
INPUT CURRENTS vs TEMPERATURE



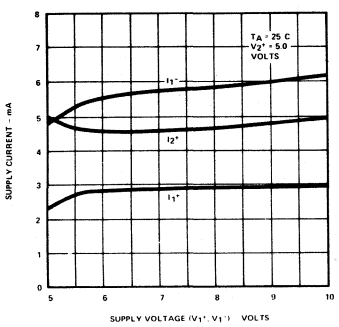
SUPPLY CURRENT vs TEMPERATURE



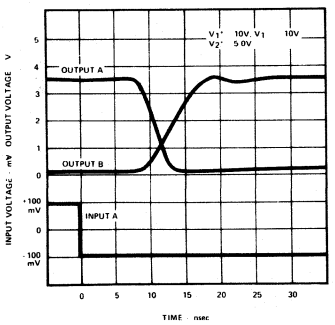
POWER DISSIPATION vs SUPPLY VOLTAGE



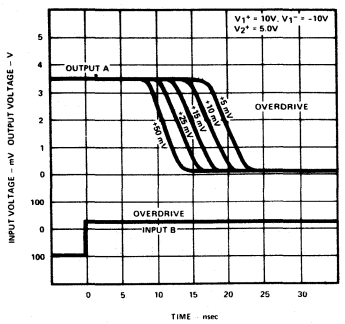
SUPPLY CURRENT vs SUPPLY VOLTAGE



OUTPUT PROPAGATION DELAYS



RESPONSE TIME FOR VARIOUS INPUT OVERDRIVES



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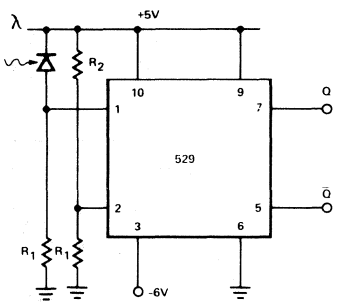
APPLICATIONS

One of the main features of the device is that supply voltages (V1+, V1-) need not be balanced, as indicated in the following diagrams. For proper operation, however, negative supply (V1-) should always be at least five volts more negative than the ground terminal (pin 6). Input Common Mode range should be limited to values of two volts less than the supply voltages (V1+ and V1-) up to a maximum of ±6 volts as supply voltages are increased.

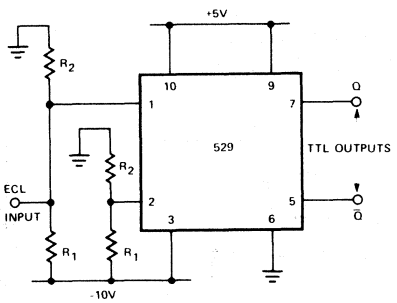
It is also important to note that Output A is in phase with Input A and Output B is in phase with Input B.

TYPICAL APPLICATIONS

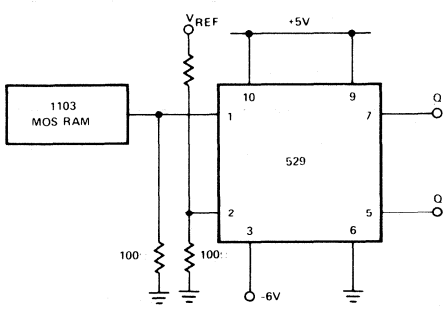
PHOTODIODE DETECTOR



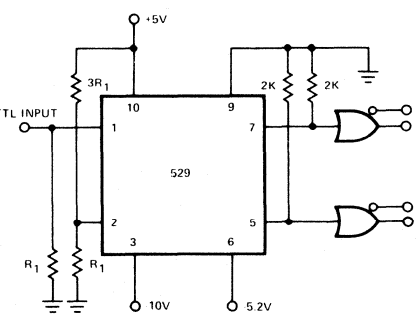
ECL TO TTL INTERFACE



MOS MEMORY SENSE AMP



TTL TO ECL INTERFACE



SECTION 6
INTERFACE

Section 6—INTERFACE

6

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

ADDRESSABLE PERIPHERAL DRIVERS — NE590/NE591

PRELIMINARY SPECIFICATION

DESCRIPTION

The NE590/NE591 addressable peripheral drivers are high current latched drivers, similar in function to the 9334 address decoder. The device has 8 darlington power outputs, each capable of 250mA load current. The outputs are turned on or off by respectively loading a logic "1" or logic "0" into the device data input. The required output is defined by a 3 bit address. The device must be enabled by a $\overline{CE}$ input line which also serves the function of further address decoding. A common clear input, $\overline{CLR}$, turns all outputs off when a logic "0" is applied.

The NE590 has 8 open collector darlington outputs which sink current to ground. The device is packaged in a 16 pin molded or cerdip package.

The NE591 has 8 open emitter darlington outputs which source current to an external load from a common collector line, V_S. The V_S line need not necessarily be the same as the 5 volt V_{CC} supply. The device is packaged in an 18 pin molded or cerdip package.

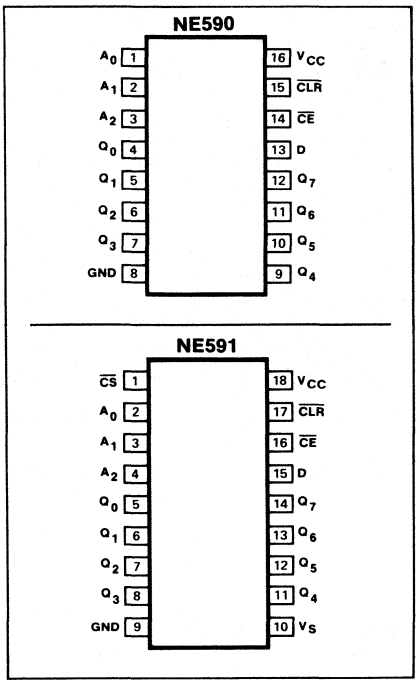
FEATURES

- **8 high current outputs**
- **Low-loading bus compatible inputs**
- **Power-on clear ensures safe operation**
- **NE590 will operate in addressable or demultiplex mode**
- **Allows random (addressed) data entry**
- **Easily expandable**
- **NE590 is pin compatible with 9334.**

APPLICATIONS

- **Relay driver**
- **Indicator lamp driver**
- **Triac trigger**
- **LED display digit driver**
- **Stepper motor driver**

PIN CONFIGURATIONS



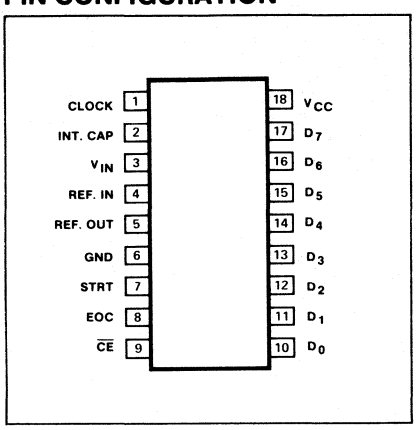
6

8-BIT ANALOG-TO-DIGITAL CONVERTER — NE5030

DESCRIPTION

The NE5030 is an 8-bit A-to-D converter employing the triple-slope technique of conversion. The device includes a voltage reference and clock generator and so constitutes the total conversion system with a minimum of components. Conversion time is approximately 10mS; voltage requirement is a single 5V supply and the data outputs are tri-state bus compatible.

PIN CONFIGURATION



TRUTH TABLE (NE590)

INPUTS						OUTPUTS								MODE
$\overline{CLR}$	$\overline{CE}$	D	A_0	A_1	A_2	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	
L	H	X	X	X	X	H	H	H	H	H	H	H	H	Clear
L	L	L	L	L	L	H	H	H	H	H	H	H	H	Demultiplex
L	L	H	L	L	L	L	H	H	H	H	H	H	H	
L	L	L	H	L	L	H	H	H	H	H	H	H	H	
L	L	H	H	L	L	H	L	H	H	H	H	H	H	
L	L	L	H	H	H	H	H	H	H	H	H	H	H	
L	L	H	H	H	H	H	H	H	H	H	H	H	L	
H	H	X	X	X	X	Q_{N-1} →								Memory
H	L	L	L	L	L	H Q_{N-1} →								Addressable Latch
H	L	H	L	L	L	L Q_{N-1} →								
H	L	L	H	L	L	Q_{N-1} H Q_{N-1} →								
H	L	H	H	L	L	Q_{N-1} L Q_{N-1}								
H	L	L	H	H	H	Q_{N-1} → H								
H	L	H	H	H	H	Q_{N-1} → L								

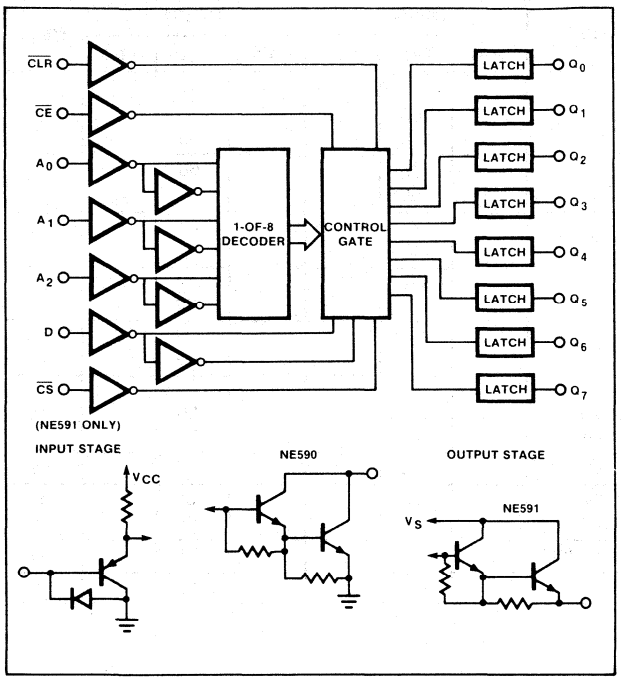
X = Don't care condition
Q_{N-1} = Previous output state
L = Low voltage level/"ON" output state
H = High voltage level/"OFF" output state

TRUTH TABLE (NE591)

INPUTS							OUTPUTS								MODE
$\overline{CLR}$	$\overline{CE}$	$\overline{CS}$	D	A_0	A_1	A_2	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	
L	X	X	X	X	X	X	L	L	L	L	L	L	L	L	Clear
H	H	H	X	X	X	X	Q_{N-1} →								Memory
H	H	L	X	X	X	X	Q_{N-1} →								
H	L	H	X	X	X	X	Q_{N-1} →								
H	L	L	L	L	L	L	L Q_{N-1} →								Addressable Latch
H	L	L	H	L	L	L	H Q_{N-1} →								
H	L	L	L	H	L	L	Q_{N-1} L Q_{N-1} →								
H	L	L	H	H	L	L	Q_{N-1} H Q_{N-1} →								
H	L	L	L	H	H	H	Q_{N-1} → L								
H	L	L	H	H	H	H	Q_{N-1} → H								

X = Don't care
Q_{N-1} = Previous output state
L = Low voltage level/"OFF" output state
H = High voltage level/"ON" output state

BLOCK DIAGRAMS



ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

PARAMETER		RATING	UNIT
V_{CC}	Supply voltage	-0.5 to +7	V
V_{IN}	Input voltage	-0.5 to +15	V
V_{OUT}	Output voltage		V
	NE590	0 to +7	
	NE591	0 to V_{CC}	
V_S	Source bus voltage		V
	NE591 only	-0.5 to +7	
V_S-V_{CC}	Source/supply differential voltage		V
	NE591 only	-5 to +2	
I_{OUT}	Output current		mA
	Each output	300	
	All outputs	1000	
P_D	Power dissipation[1]	1	W
	Temperature range		°C
T_A	Ambient	0 to +70	
T_J	Junction	150	
T_{STG}	Storage	-65 to +150	
T_{sold}	Lead soldering temperature (10sec max)	300	°C

DC ELECTRICAL CHARACTERISTICS

V_{CC} = 4.75 to 5.25V, 0°C ≤ T_A ≤ 70°C unless otherwise specified.[2,3]

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
	Input voltage					V
V_{IH}	High		2.0			
V_{IL}	Low				0.8	
	Output voltage					V
V_{OL}	Low (NE590 only)	I_{OL} = 250mA, T_A = 25°C		1.0	1.3	
		Over temperature			1.5	
V_{OH}	High (NE591 only)	I_{OH} = -250mA, V_{CC} = V_S = 5V	2.9			
	Input current					μA
I_{IH}	High	V_{in} = V_{CC}		0.1	10	
I_{IL}	Low	V_{in} = 0V				
	$\overline{CE}$ input			-25	-60	
	All other inputs			-15	-50	
	Supply current[4]	V_S = V_{CC} = 5V				mA
I_{CCL}	All outputs low					
	NE590			33	50	
	NE591			15	50	
I_{CCH}	All outputs high					
	NE590			15	50	
	NE591			30	50	

NOTES

1. Derate power dissipation as indicated above threshold ambient temperature:
   NE590N at 95°C/W above 55°C
   NE590F at 100°C/W above 50°C
   NE591N at 90°C/W above 60°C
   NE591F at 93°C/W above 57°C
2. All typical values are at V_{CC} = 5V and T_A = 25°C.
3. For the NE591, V_S = V_{CC} in all tests.
4. Supply current for the NE591 is measured with no output load.

SWITCHING CHARACTERISTICS V_{CC} = 5V, T_A = 25°C

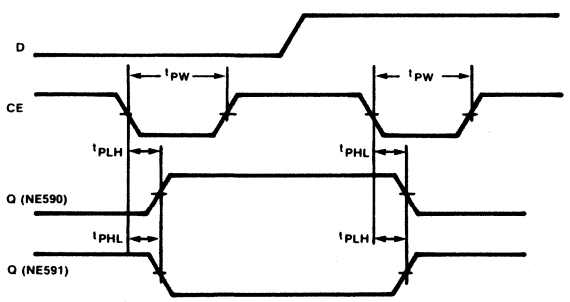
PARAMETER	TO	FROM	NE590			NE591			UNIT
			Min	Typ	Max	Min	Typ	Max	
Propagation delay time									ns
t_{PLH} Low to high[5]	Output	$\overline{CE}$		100			70		
t_{PHL} High to low[5]				130			80		
t_{PLH} Low to high[6]	Output	Data		80			60		
t_{PHL} High to low[6]				100			70		
t_{PLH} Low to high[7]	Output	Address		125			70		
t_{PHL} High to low[7]				115			70		
t_{PLH} Low to high[8]	Output	$\overline{CLR}$		80					
t_{PHL} High to low[8]							60		
t_{PLH} Low to high[5]	Output	$\overline{CS}$					70		
t_{PHL} High to low[5]							80		
SWITCHING SET-UP REQUIREMENTS									
$t_{s(H)}$[9]	Chip enable	High data		120			50		ns
$t_{s(L)}$[9]	Chip enable	Low data		120			70		ns
$t_{s(A)}$[10]	Chip enable	Address		-60			-10		ns
$t_{h(H)}$[9]	Chip enable	High data		-60			-60		ns
$t_{h(L)}$[9]	Chip enable	Low data		-60			-20		ns
$t_{s(CS)}$[9]	Chip enable	Low chip select					70		ns
$t_{pw(E)}$ Chip enable pulse width[5]				150			80		ns

NOTES

5. See Turn-On and Turn-Off Delays, Enable to Output and Enable Pulse Width timing diagram.
6. See Turn-On and Turn-Off Delays, Data to Output timing diagram.
7. See Turn-On and Turn-Off Delays, Address to Output timing diagram.
8. See Turn-Off Delay, Clear to Output timing diagram.
9. See Setup and Hold Time, Data to Enable timing diagram.
10. See Setup Time, Address to Enable timing diagram.

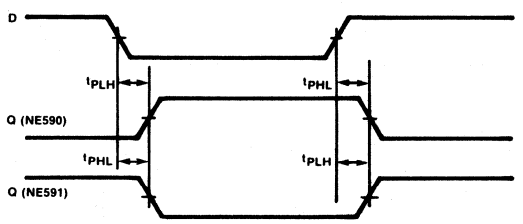
TIMING DIAGRAMS

TURN-ON AND TURN-OFF DELAYS, ENABLE TO OUTPUT AND ENABLE PULSE WIDTH



Other Inputs: $\overline{CLR}$ = H, A = Stable, $\overline{CS}$ = L

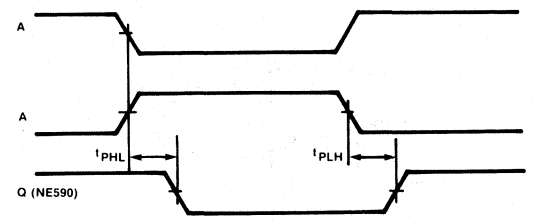
TURN-ON AND TURN-OFF DELAYS, DATA TO OUTPUT



Other Inputs: $\overline{CE}$ = $\overline{CS}$ = L, $\overline{CLR}$ = H, A = Stable

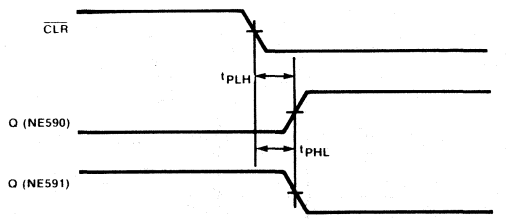
TIMING DIAGRAMS (Cont'd)

TURN-ON AND TURN-OFF DELAYS, ADDRESS TO OUTPUT



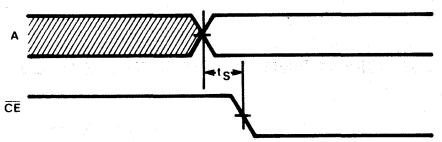
Other Inputs: $\overline{CE}$ = L, $\overline{CLR}$ = L, D = H

TURN-OFF DELAY, CLEAR TO OUTPUT



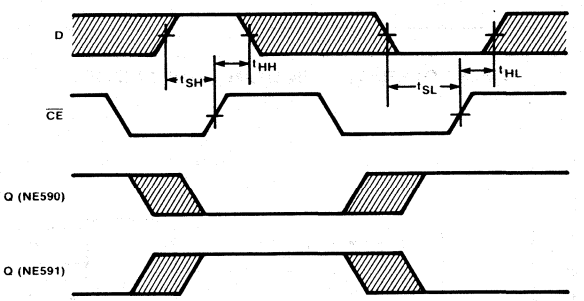
Other Inputs: $\overline{CE}$ = H, $\overline{CS}$ = H

SETUP TIME, ADDRESS TO ENABLE



Other Inputs: $\overline{CLR}$ = H, $\overline{CS}$ = L

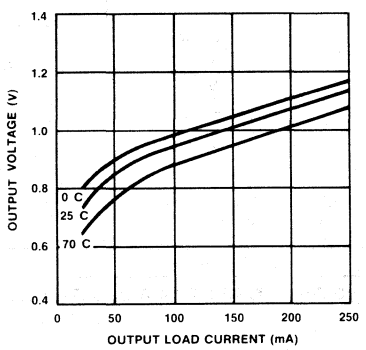
SETUP AND HOLD TIME, DATA TO ENABLE



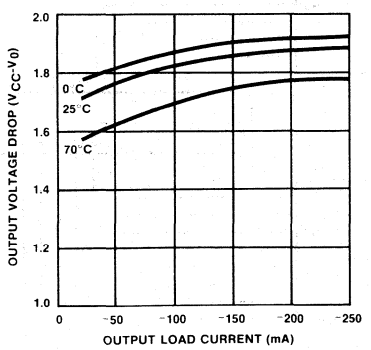
Other Inputs: $\overline{CLR}$ = H, A = Stable, $\overline{CS}$ = L

TYPICAL PERFORMANCE CHARACTERISTICS

OUTPUT VOLTAGE VS LOAD CURRENT(NE590)

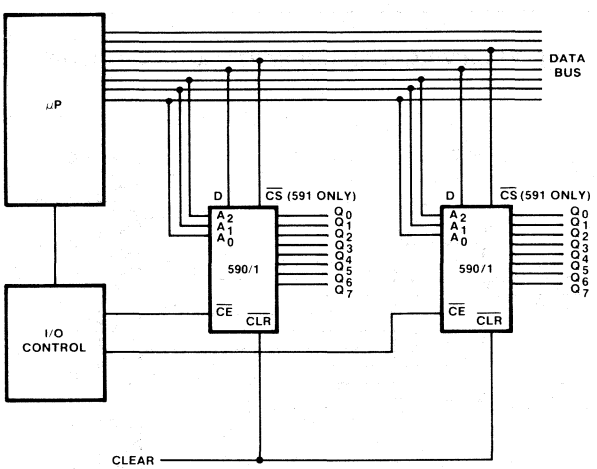


OUTPUT VOLTAGE DROP VS LOAD CURRENT(NE591)



TYPICAL APPLICATIONS

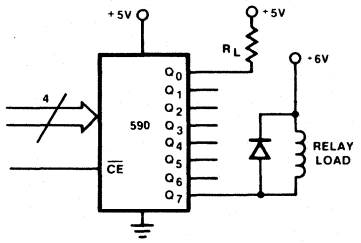
INTERFACING THE 590/591 WITH A MICROPROCESSOR SYSTEM



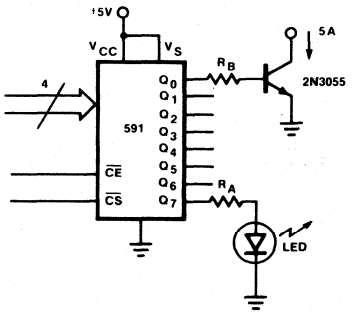
A_0, A_1, A_2, and $\overline{CS}$ may be connected to the address bus if permitted by system design.

TYPICAL APPLICATIONS (Cont'd)

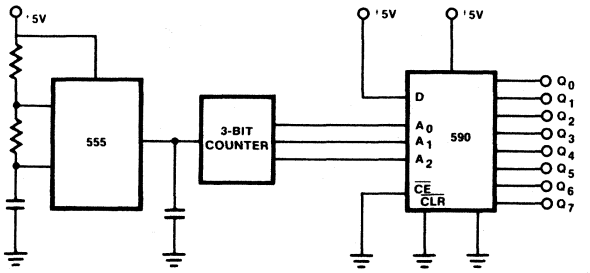
NE590 DRIVING SIMPLE LOADS



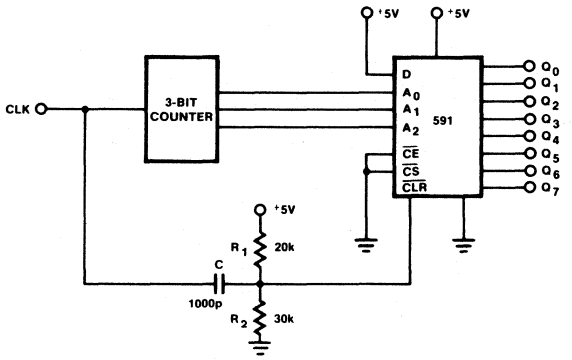
NE591 DRIVING SIMPLE LOADS



NE590 OPERATING IN DEMULTIPLEX MODE

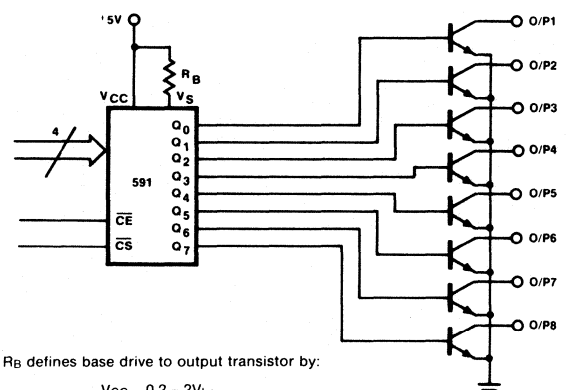


NE591 OPERATING IN DEMULTIPLEX MODE



For display applications, interdigit blanking is provided by time constant $\tau = C(R_1/R_2) \approx 10\mu s$ with values shown.

NE591 DRIVING HIGH CURRENT (5A) TRANSISTORS

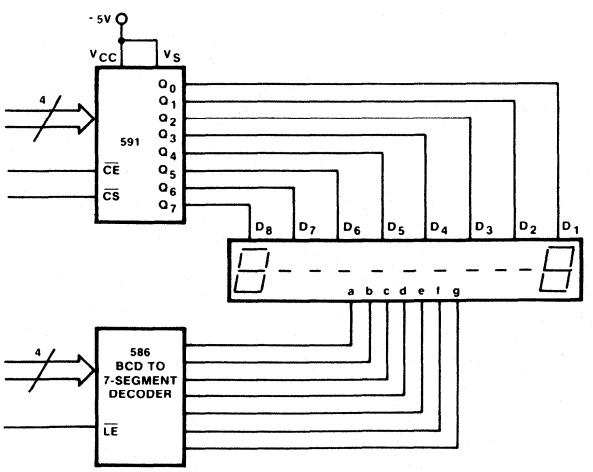


R_B defines base drive to output transistor by:

$$I_b = \frac{V_{CC} - 0.2 - 2V_{be}}{R_b}$$

provided that only one output is ON at any time.

NE591 AS THE DIGIT DRIVER IN A LED DISPLAY SYSTEM



MC1488-F,N

DESCRIPTION

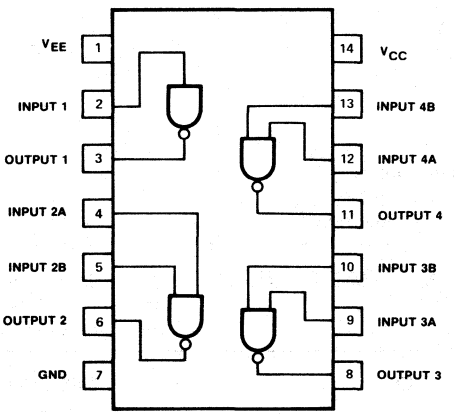
The MC1488 is a quad line driver which converts standard DTL/TTL input logic levels through one stage of inversion to output levels which meet EIA Standard No. RS-232C and CCITT Recommendation V.24.

FEATURES

- **Current limited output: ±10mA Typ**
- **Power-off source impedance: 300Ω Min**
- **Simple slew rate control with external capacitor**
- **Flexible operating supply range**
- **Inputs are DTL/TTL compatible**

PIN CONFIGURATION

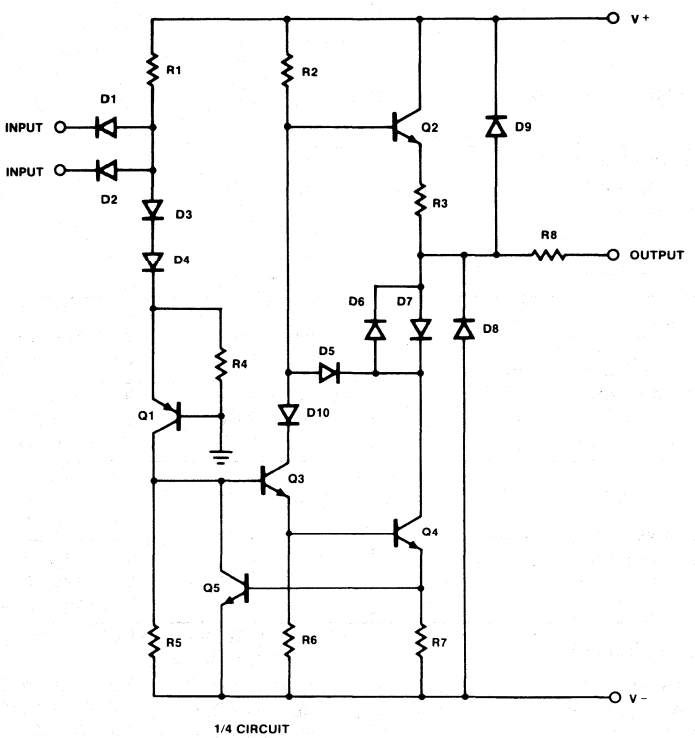
F,N PACKAGE



ORDER PART NO.

MC1488N/F

CIRCUIT SCHEMATIC



1/4 CIRCUIT

ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage V+	+15	V
V-	-15	V
Input voltage (V_{IN})	$-15 \leq V_{IN} \leq 7.0$	V
Output voltage	±15	V
Power dissipation:		
F package	1000	mW
N package	800	mW
Operating temperature range	0 to +75	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 10sec)	300	°C

DC ELECTRICAL CHARACTERISTICS

V+ = +9.0V ± 1%, V- = -9.0V ± 1%, T_A = 0°C to +75°C unless otherwise specified.
All typicals are for V+ = 9.0V, V- = -9.0V, and T_A = 25°C.*

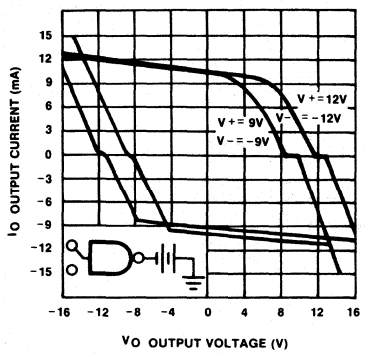
PARAMETER	TEST CONDITIONS		LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
Logic "0" input current	V_{IN} = 0V			-1.0	-1.6	mA
Logic "1" input current	V_{IN} = +5.0V			.005	10.0	μA
High level output voltage	R_L = 3.0kΩ, V_{IN} = 0.8V	V+ = 9.0V, V- = -9.0V	6.0	7.0		V
		V+ = 13.2V, V- = -13.2V	9.0	10.5		V
Low level output voltage	R_L = 3.0kΩ, V_{IN} = 1.9V	V+ = 9.0V, V- = -9.0V	-6.0	-6.8		V
		V+ = 13.2V, V- = -13.2V	-9.0	-10.5		V
High level output Short-circuit current	V_{OUT} = 0V, V_{IN} = 0.8V		-6.0	-10.0	-12.0	mA
Low level output Short-circuit current	V_{OUT} = 0V, V_{IN} = 1.9V		6.0	10.0	12.0	mA
Output resistance	V+ = V- = 0V, V_{OUT} = ±2V		300			Ω
Positive supply current (output open)	V_{IN} = 1.9V	V+ = 9.0V, V- = -9.0V		15.0	20.0	mA
		V+ = 12V, V- = -12V		19.0	25.0	mA
		V+ = 15V, V- = -15V		25.0	34.0	mA
	V_{IN} = 0.8V	V+ = 9.0V, V- = -9.0V		4.5	6.0	mA
		V+ = 12V, V- = -12V		5.5	7.0	mA
		V+ = 15V, V- = -15V		8.0	12.0	mA
Negative supply current (output open)	V_{IN} = 1.9V	V+ = 9.0V, V- = -9.0V		-13.0	-17.0	mA
		V+ = 12V, V- = -12V		-18.0	-23.0	mA
		V+ = 15V, V- = -15V		-25.0	-34.0	mA
	V_{IN} = 0.8V	V+ = 9.0V, V- = -9.0V		-1	-15	μA
		V+ = 12V, V- = -12V		-1	-15	μA
		V+ = 15V, V- = -15V		-.01	-2.5	mA
Power dissipation	V+ = 9.0V, V- = -9.0V			252	333	mW
	V+ = 12V, V- = -12V			444	576	mW
Propagation delay to "1" (t_{pd1})	R_L = 3.0kΩ, C_L = 15pF, T_A = 25°C			275	350	ns
Propagation delay to "0" (t_{pd0})	R_L = 3.0kΩ, C_L = 15pF, T_A = 25°C			70	175	ns
Rise time (t_r)	R_L = 3.0kΩ, C_L = 15pF, T_A = 25°C			75	100	ns
Fall time (t_f)	R_L = 3.0kΩ, C_L = 15pF, T_A = 25°C			40	75	ns

NOTE

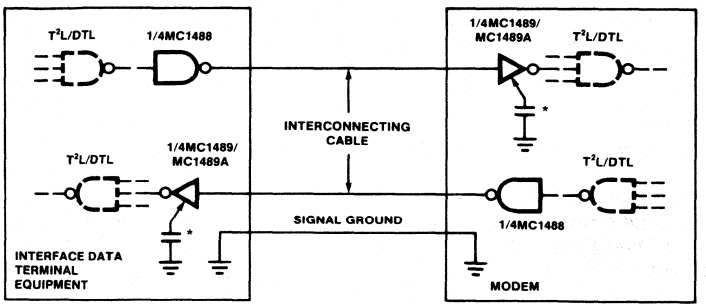
*Voltage values shown are with respect to network ground terminal. Positive current is defined as current into the referenced pin.

TYPICAL PERFORMANCE CHARACTERISTICS

OUTPUT VOLTAGE AND CURRENT-LIMITING CHARACTERISTICS



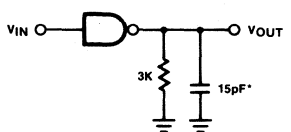
RS232C DATA TRANSMISSION



NOTE

*Optional for noise filtering

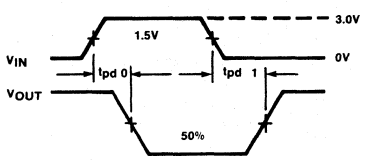
AC LOAD CIRCUIT



NOTE

*C_L includes probe and jig capacitance.

SWITCHING WAVEFORMS



NOTE

t_r and t_f are measured between 10% and 90% of the output waveform

APPLICATIONS

By connecting a capacitor to each driver output the slew rate can be controlled utilizing the output current limiting characteristics of the MC1488. For a set slew rate the appropriate capacitor value may be calculated using the following relationship

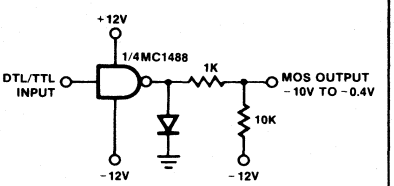
$$C = I_{SC}\,(\Delta T/\Delta V)$$

where C is the required capacitor, I_{SC} is the short circuit current value, and $\Delta V/\Delta T$ is the slew rate.

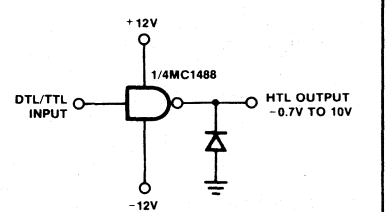
RS232C specifies that the output slew rate must not exceed 30V per microsecond. Using the worst case output short circuit current of 12mA in the above equation, calculations result in a required capacitor of 400pF connected to each output.

TYPICAL APPLICATIONS

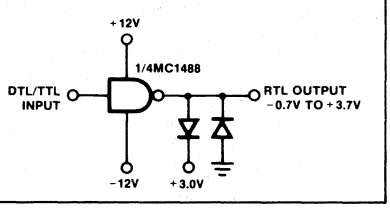
DTL/TTL-TO-MOS TRANSLATOR



DTL/TTL-TO-HTL TRANSLATOR



DTL/TTL-TO-RTL TRANSLATOR



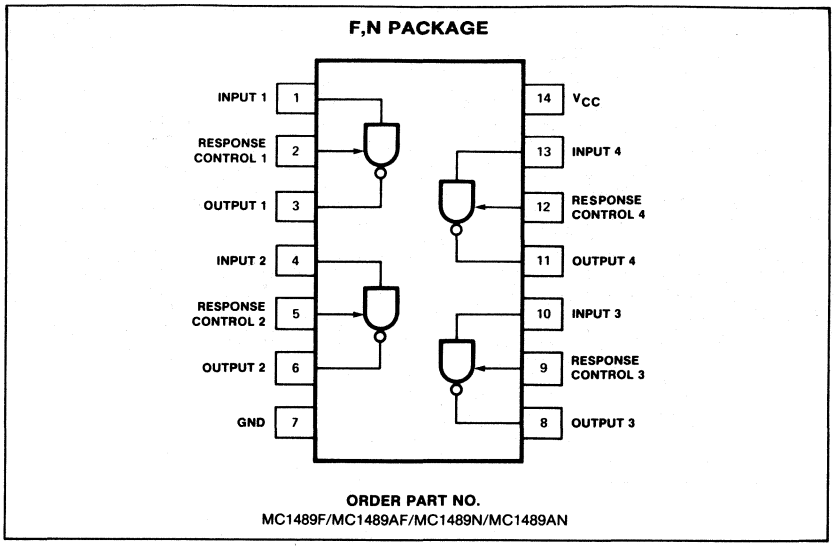
DESCRIPTION

The MC1489/MC1489A are quad line receivers designed to interface data terminal equipment with data communications equipment. They are constructed on a single monolithic silicon chip. These devices satisfy the specifications of EIA standard No. RS232C.

FEATURES

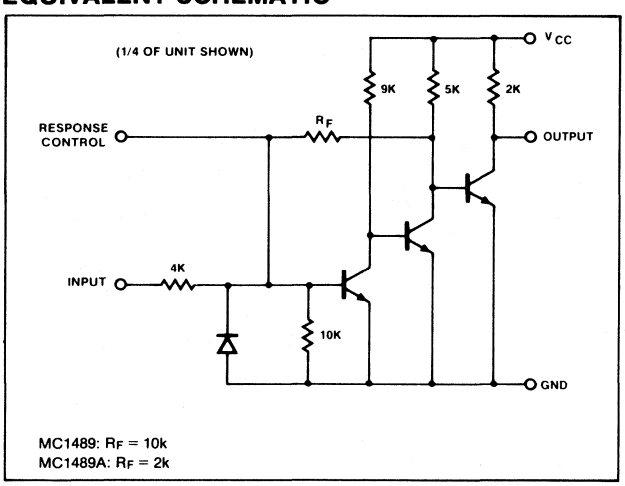
- **Four totally separate receivers per package**
- **Programmable threshold**
- **Built-in input threshold hysteresis**
- **"Fail safe" operating mode**
- **Inputs withstand ±30V**

PIN CONFIGURATION



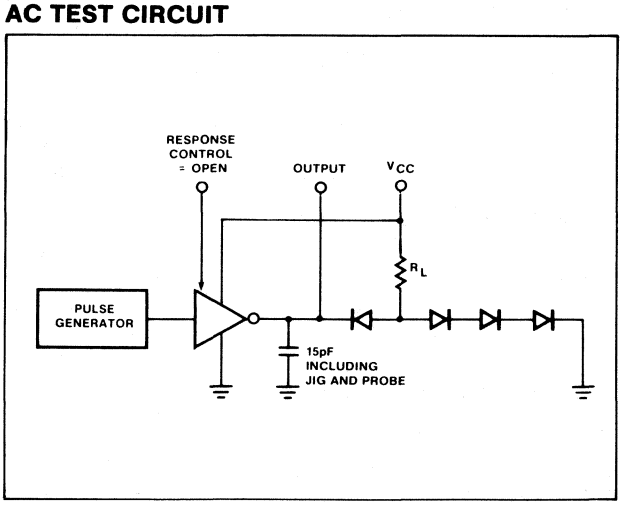
ORDER PART NO.
MC1489F/MC1489AF/MC1489N/MC1489AN

EQUIVALENT SCHEMATIC



MC1489: R_F = 10k
MC1489A: R_F = 2k

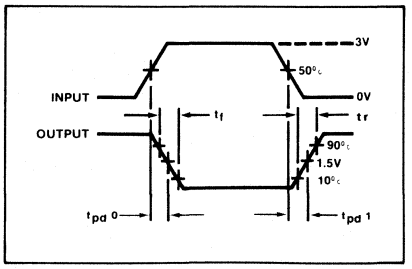
AC TEST CIRCUIT



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Power supply voltage	10	V
Input voltage range	±30	V
Output load current	20	mA
Power dissipation:		
F package	1	W
N package	800	mW
Operating temperature range	0 to +75	°C
Storage temperature range	-65 to +150	°C

VOLTAGE WAVEFORMS



DC ELECTRICAL CHARACTERISTICS V_{CC} = 5.0V ± 1%, 0°C ≤ T_A ≤ +75°C unless otherwise specified.[1,2]

PARAMETER	TEST CONDITIONS	MC1489			MC1489A			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input high threshold voltage	T_A = 25°C, V_{OUT} ≤ 0.45V, I_{OUT} = 10mA	1.0		1.5	1.75		2.25	V
Input low threshold voltage	T_A = 25°C, V_{OUT} ≤ 2.5V, I_{OUT} = -0.5mA	0.75		1.25	0.75		1.25	V
	V_{IN} = +25V	+3.6	+5.6	+8.3	+3.6	+5.6	+8.3	mA
	V_{IN} = -25V	-3.6	-5.6	-8.3	-3.6	-5.6	-8.3	
Input current	V_{IN} = +3V	+0.43	+0.53		+0.43	+0.53		mA
	V_{IN} = -3V	-0.43	-0.53		-0.43	-0.53		
Output high voltage	V_{IN} = 0.75V, I_{OUT} = -0.5mA	2.6	3.8	5.0	2.6	3.8	5.0	V
	Input = Open, I_{OUT} = -0.5mA	2.6	3.8	5.0	2.6	3.8	5.0	V
Output low voltage	V_{IN} = 3.0V, I_{OUT} = 10mA		0.33	0.45		0.33	0.45	V
Output short circuit current	V_{IN} = 0.75V		3.0			3.0		mA
Supply current	V_{IN} = 5.0V		20	26		20	26	mA
Power dissipation	V_{IN} = 5.0V		100	130		100	130	mW

NOTES

1. Voltage values shown are with respect to network ground terminal. Positive current is defined as current into the referenced pin.
2. These specifications apply for response control pin = open.

AC ELECTRICAL CHARACTERISTICS V_{CC} = 5.0V ± 1%, T_A = 25°C unless otherwise specified.[1,2]

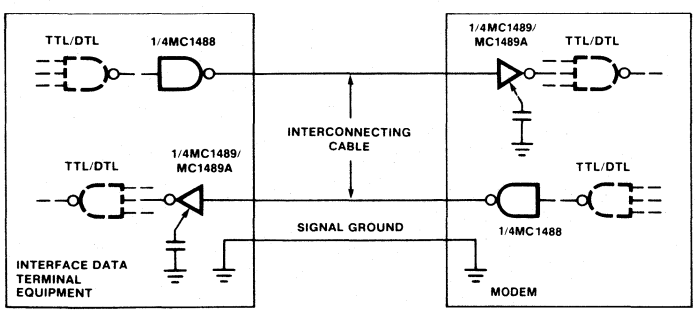
PARAMETER	TEST CONDITIONS	MC1489			MC1489A			UNIT
		Min	Typ	Max	Min	Typ	Max	
Input to output "high" Propagation delay (t_{pd1})	R_L = 3.9kΩ (AC test circuit)		25	85		25	85	ns
Input to output "low" Propagation delay (t_{pd0})	R_L = 390Ω (AC test circuit)		20	50		20	50	ns
Output rise time	R_L = 3.9kΩ (AC test circuit)		110	175		110	175	ns
Output fall time	R_L = 390Ω (AC test circuit)		9	20		9	20	ns

NOTES

1. Voltage values shown are with respect to network ground terminal. Positive current is defined as current into the referenced pin.
2. These specifications apply for response control pin = open.

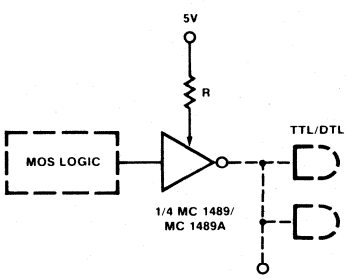
TYPICAL APPLICATIONS

RS232C DATA TRANSMISSION



*Optional for noise filtering

MOS TO TTL/DTL TRANSLATOR



SECTION 7
TRANSISTOR ARRAYS

Section 7—TRANSISTOR ARRAYS

7

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

DESCRIPTION

These high-voltage, high-current Darlington transistor arrays are comprised of seven silicon NPN Darlington pairs on a common monolithic substrate. All units feature open collector outputs and integral suppression diodes for inductive loads. Peak inrush currents to 600mA are allowable, making them ideal for driving tungsten filament lamps also.

The Type ULN-2003 has a series base resistor to each Darlington pair, and thus allows operation directly with TTL or CMOS operating at a supply voltage of 5V.

The Type ULN-2004 has an appropriate series input resistor to allow its operation directly from CMOS or PMOS outputs utilizing supply voltages of 6 to 15V. The required input current is below that of the Type ULN-2003 while the required input voltage is less than that required by the Type ULN-2002.

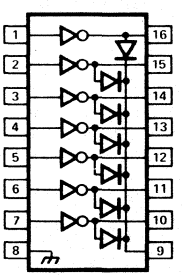
In all cases, the individual Darlington pair collector current rating is 500mA. However, outputs may be paralleled for higher load current capability. All devices are supplied in a 16-pin dual in-line plastic package.

FEATURES

- **Peak inrush current 600mA**
- **Protected internally against inductive loads**
- **Open collector topology**
- **Compatible with most logic technologies**

PIN CONFIGURATION

N PACKAGE

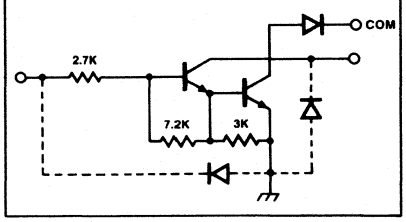


ORDER PART NO.

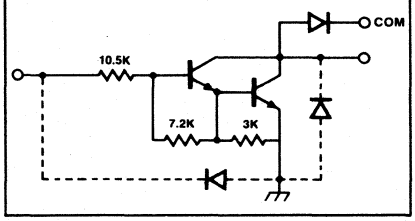
ULN2003N
ULN2004N

EQUIVALENT SCHEMATICS

TYPE ULN2003 (each driver)



TYPE ULN2004 (each driver)



ABSOLUTE MAXIMUM RATINGS

at 25°C Free-Air temperature for any one Darlington pair unless otherwise specified.

PARAMETER		RATING	UNIT
V_{CE}	Output voltage	50	V
V_{IN}	Input voltage	30	V
V_{EBO}	Emitter base voltage	6	V
I_C	Continuous collector current	500	mA
I_B	Continuous base current	25	mA
P_D	Power dissipation	1.3	W
	Derating factor above 25°C	95	°C/W
T_A	Ambient temperature range (operating)	0 to +85	°C
T_S	Storage temperature range	-65 to +150	°C

*NOTE
Under normal operating conditions, these units will sustain 350mA per output with $V_{CE(SAT)}$ = 1.6V at 70°C with a pulse width of 20 ms and a duty cycle of 30%.

DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.[1,2,3]

PARAMETER		TEST CONDITIONS	Test Fig.	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
I_{CEX}	Output leakage current	$V_{CE} = 50V$, $T_A = 70°C$	1A	—	—	100	μA
	Type ULN-2004	$V_{CE} = 50V$, $T_A = 70°C$, $V_{IN} = 1V$	1B	—	—	500	μA
$V_{CE(SAT)}$	Collector-emitter Saturation voltage	$I_C = 350mA$, $I_B = 500\mu A$	2	—	1.25	1.6	V
		$I_C = 200mA$, $I_B = 350\mu A$	2	—	1.1	1.3	V
		$I_C = 100mA$, $I_B = 250\mu A$	2	—	0.9	1.1	V
$I_{IN(ON)}$	Input current						
	Type ULN-2003	$V_{IN} = 3.85V$	3	—	0.93	1.35	mA
	Type ULN-2004	$V_{IN} = 5V$	3	—	0.35	0.5	mA
		$V_{IN} = 12V$	3	—	1.0	1.45	mA
$I_{IN(OFF)}$	Input current	$I_C = 500\mu A$, $T_A = 70°C$	4	50	65	—	μA
$V_{IN(ON)}$	Input voltage						
	Type ULN-2003	$V_{CE} = 2V$, $I_C = 200mA$	5	—	—	2.4	V
		$V_{CE} = 2V$, $I_C = 250mA$	5	—	—	2.7	V
		$V_{CE} = 2V$, $I_C = 300mA$	5	—	—	3.0	V
	Type ULN-2004	$V_{CE} = 2V$, $I_C = 125mA$	5	—	—	5.0	V
		$V_{CE} = 2V$, $I_C = 200mA$	5	—	—	6.0	V
		$V_{CE} = 2V$, $I_C = 275mA$	5	—	—	7.0	V
		$V_{CE} = 2V$, $I_C = 350mA$	5	—	—	8.0	V
C_{IN}	Input capacitance		—	—	15	30	pF
I_R	Clamp diode leakage current	$V_R = 50V$	6	—	—	50	μA
V_F	Clamp diode forward voltage	$I_F = 350mA$	7	—	1.7	2	V

NOTES

1. All limits stated apply to the complete Darlington series except as specified for a single device type.
2. The $I_{IN(OFF)}$ current limit guarantees against partial turn-on of the output.
3. The $V_{IN(ON)}$ voltage limit guarantees a minimum output sink current per the specified test conditions.

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.[1,2,3]

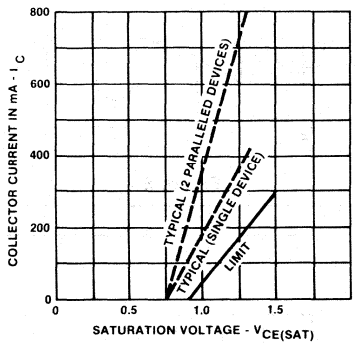
PARAMETER		TEST CONDITIONS	Test Fig.	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
t_{PLH}	Turn-on delay	0.5 E_{IN} to 0.5 E_{OUT}	—	—	1.0	5	μs
t_{PHL}	Turn-off delay	0.5 E_{IN} to 0.5 E_{OUT}	—	—	1.0	5	μs

NOTES

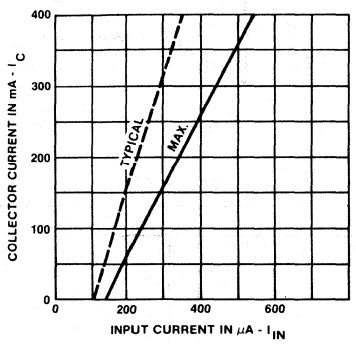
1. All limits stated apply to the complete Darlington series except as specified for a single device type.
2. The $I_{IN(OFF)}$ current limit guarantees against partial turn-on of the output.
3. The $V_{IN(ON)}$ voltage limit guarantees a minimum output sink current per the specified test conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

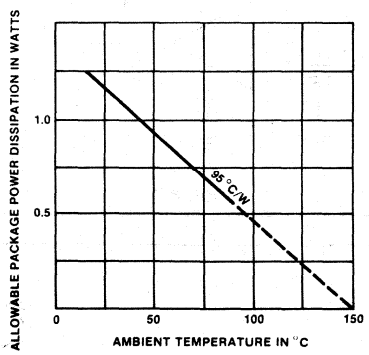
COLLECTOR CURRENT AS A FUNCTION OF SATURATION VOLTAGE



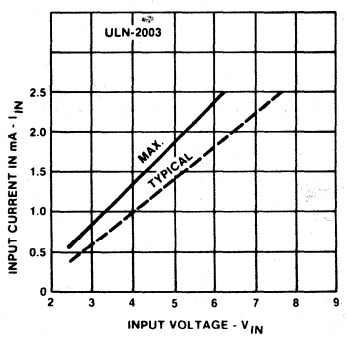
COLLECTOR CURRENT AS A FUNCTION OF INPUT CURRENT



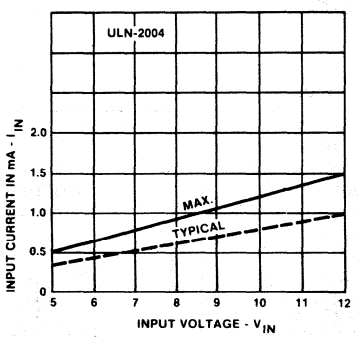
ALLOWABLE AVERAGE PACKAGE POWER DISSIPATION AS A FUNCTION OF AMBIENT TEMPERATURE



INPUT CURRENT AS A FUNCTION OF INPUT VOLTAGE FOR TYPE ULN-2003



INPUT CURRENT AS A FUNCTION OF INPUT VOLTAGE FOR TYPE ULN-2004



TEST FIGURES

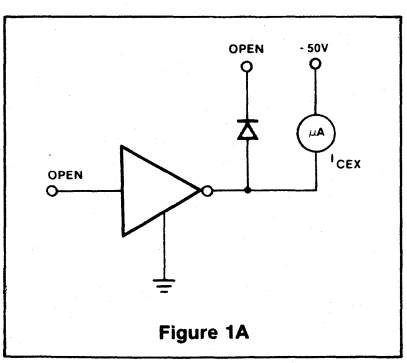


Figure 1A

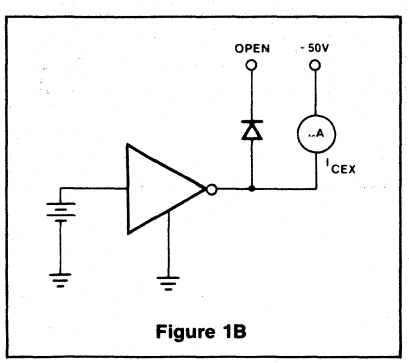


Figure 1B

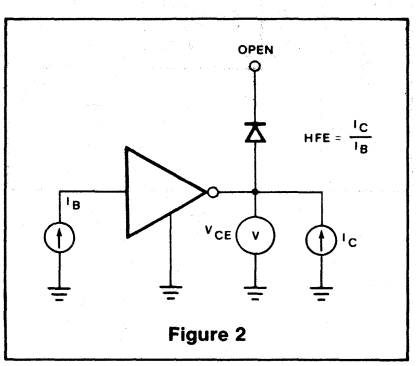


Figure 2

TEST FIGURES (Cont'd)

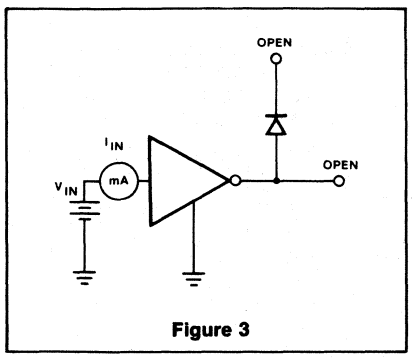


Figure 3

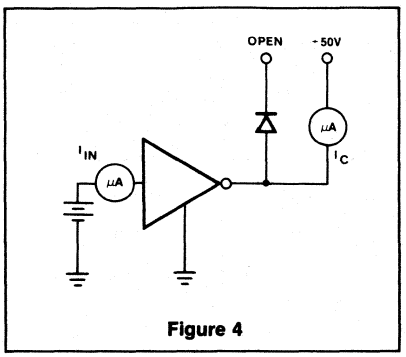


Figure 4

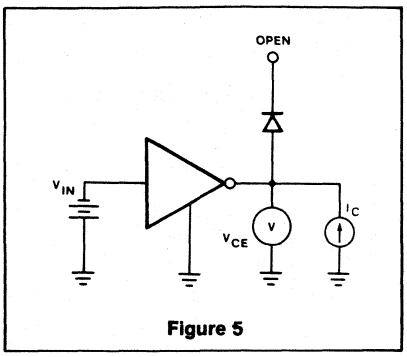


Figure 5

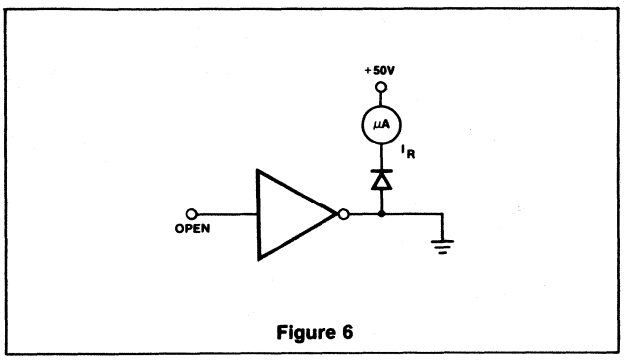


Figure 6

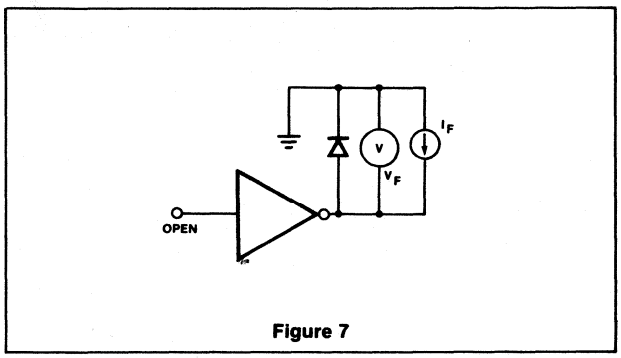
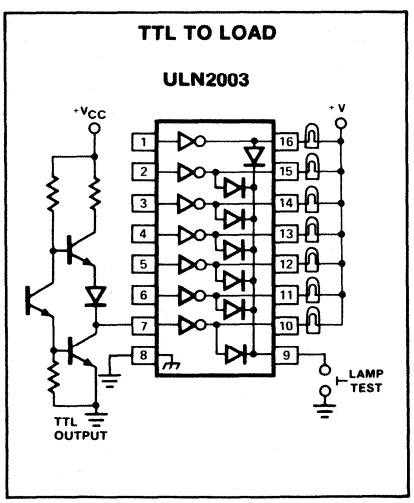
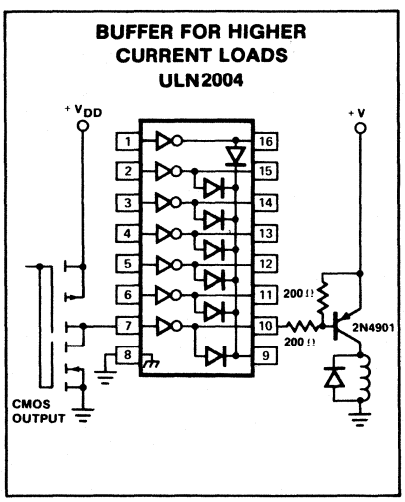


Figure 7

TYPICAL APPLICATIONS





CA3081/3082-N,F

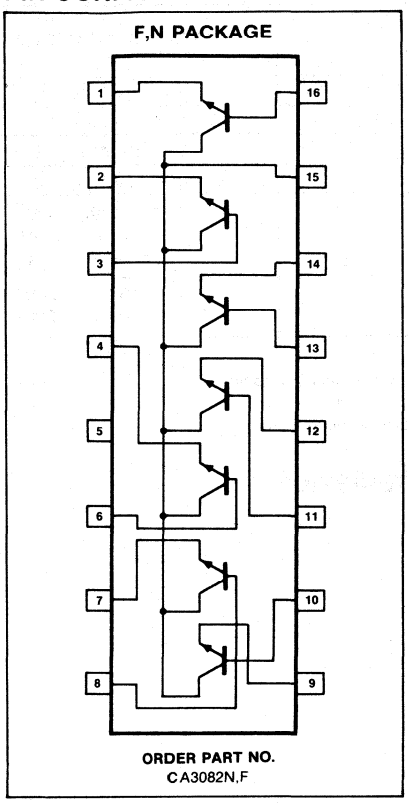
DESCRIPTION

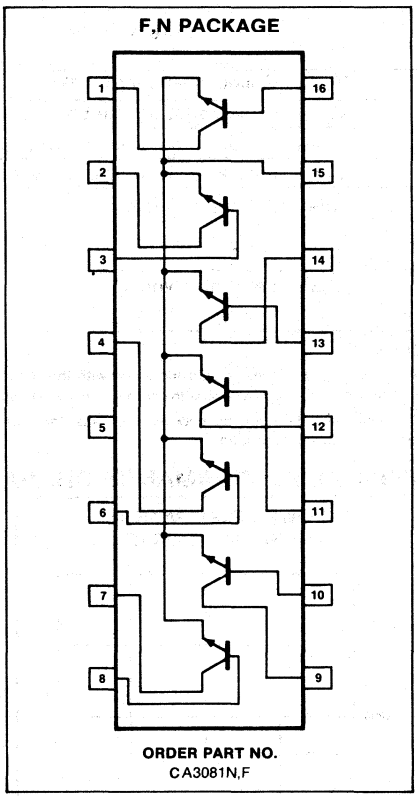
The CA3081 and CA3082 are monolithic integrated circuits each consisting of seven separate npn transistors on a common substrate. The transistors are capable of driving loads up to 100mA. At the same time the transistor geometry used gives maximum current gain at quite low currents, making the devices also suitable for small signal applications. In the CA3081 the transistors are connected in common emitter configuration while in the CA3082 the collectors are common. The transistor arrays are particularly suitable for driving light-emitting diodes and seven-segment displays as well as for general purpose applications.

FEATURES

- **V_{CBO}=50V**
- **V_{CEO}=35V**
- **Collector current 100mA**
- **Common emitter or common collector configuration**

PIN CONFIGURATIONS





ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
V_{CEO}	Collector-emitter voltage (open base)		V
V_{CBO}	Collector-base voltage (open emitter)	50	V
V_{CSO}	Collector-substrate voltage (open base and emitter)	50	V
V_{EBO}	Emitter-base voltage (open collector)	6	V
I_C	Collector current (dc)	100	mA
I_B	Base current (dc)	20	mA
P	Power dissipation: any one transistor	500	mW
P_{TOT}	total package (see derating curve)	750	mW
T_A	Operating ambient temperature	-40 to +125	°C
T_{stg}	Storage temperature	-50 to +125	°C
T_j	Junction temperature	125	°C
	Lead temperature (10 sec)	300	°C

7

DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	CA3081/3082			UNIT
			Min	Typ	Max	
V_{CEO}	Collector-emitter breakdown voltage	$I_C = 1mA$, $I_B = 0$	35			V
V_{CSO}	Collector-substrate breakdown voltage	$I_C = 1mA$, $I_B = 0$, $I_E = 0$	50			V
V_{CBO}	Collector-base breakdown voltage	$I_C = 10\mu A$, $I_E = 0$	50			V
V_{EBO}	Emitter-base breakdown voltage	$I_E = 10\mu A$, $I_C = 0$	5.5	7.0		V
hfe	DC current gain	$I_E = 10\mu A$, $V_{CE} = 5V$ $I_E = 1mA$, $V_{CE} = 5V$ $I_E = 20mA$, $V_{CE} = 5V$	50 50 30			
V_{SAT}	Saturation voltage	$I_C = 5mA$, $I_B = .5mA$ $I_C = 50mA$, $I_B = 5mA$		0.2 0.4	0.4 0.8	V V

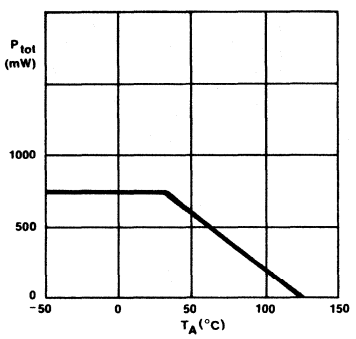
NOTE

As each collector forms a parasitic diode with the substrate, the substrate has to be connected to a voltage which is lower than the lowest collector voltage.

To avoid parasitic coupling between the transistors, the substrate (pin 5) should be connected to signal ground.

TYPICAL PERFORMANCE CHARACTERISTICS

POWER DISSIPATION DERATING CURVE



SECTION 8
PHILIPS INDUSTRIAL

Section 8—PHILIPS INDUSTRIAL

8

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

SAA1027-N

DESCRIPTION

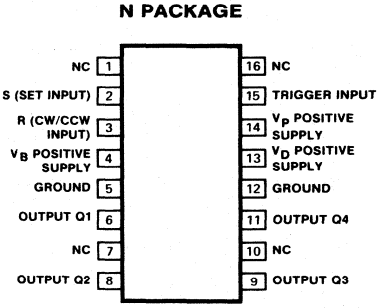
The SAA1027 is intended for driving a four phase two stator stepper motor. The circuit consists of four output stages, a logic part and three input stages. The logic part is driven by three input stages; a trigger input stage, an input stage which can change the switching sequence of the logic part so that the motor can rotate clock wise (CW) or counter clock wise (CCW) and a set input stage to set the four output stages. The three inputs are compatible with high noise immunity logic to ensure proper operation, even in noisy environments. The output can deliver 350mA in each phase. The right switching sequence of the four phases is obtained from the logic part of the circuit. Integrated diodes protect the outputs against transient spikes.

FEATURES

- **CW or CCW rotation**
- **4-phase drive**
- **Few external components**

PIN CONFIGURATION

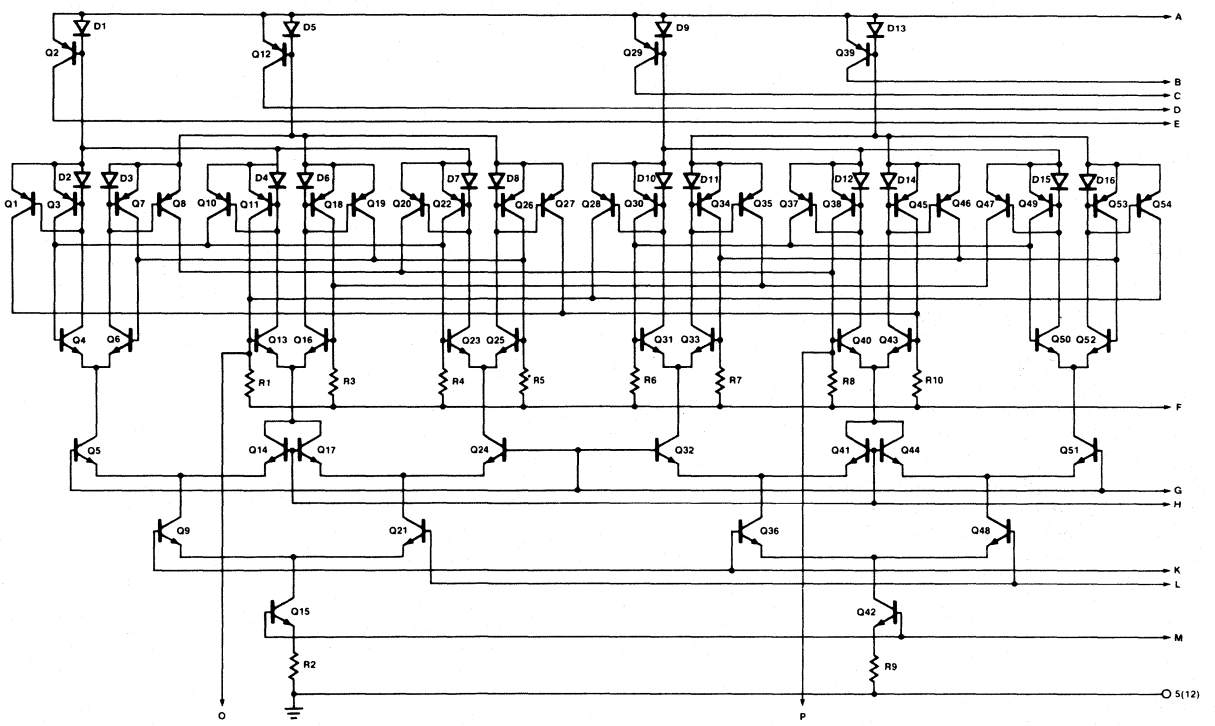
N PACKAGE



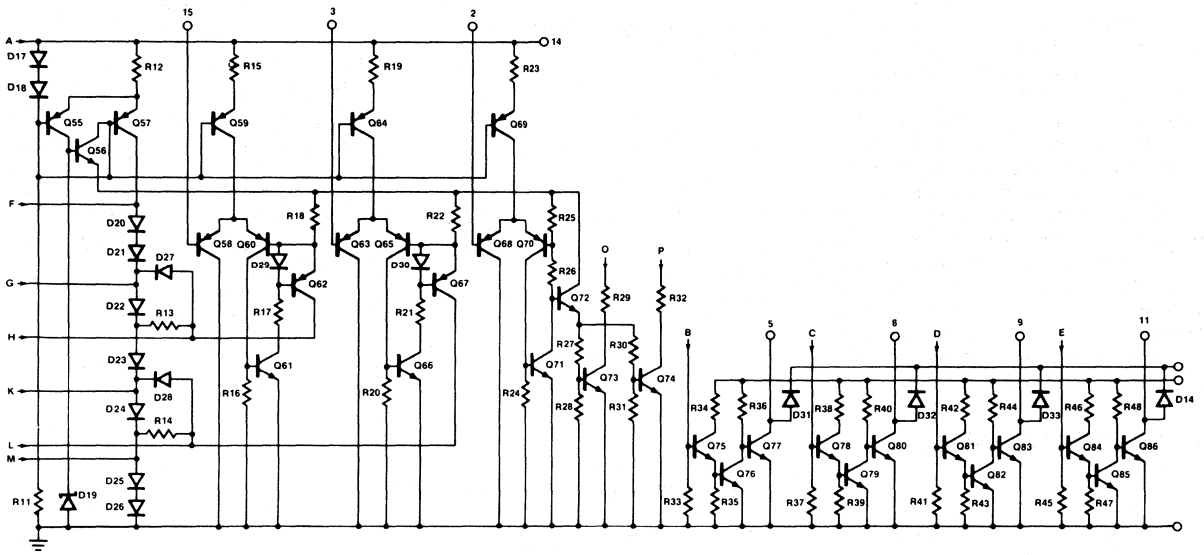
ORDER PART NO.
SAA1027N

EQUIVALENT SCHEMATIC

BI-DIRECTIONAL, 4 POSITION, SYNCHRONOUS COUNTER



EQUIVALENT SCHEMATIC (Cont'd)



ABSOLUTE MAXIMUM RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

	PARAMETER	RATING	UNIT
	VOLTAGES		
V_P	Supply voltage (pin 4, 13, 14)	20	V
V_I	Input voltage; R (pin 3), S (pin 2), T (pin 15)	20	V
	CURRENT		
I_Q	Output current; Q_1 (pin 6), Q_2 (pin 8), Q_3	500	mA
	POWER DISSIPATION	See figure 1	
	TEMPERATURES		
T_{STG}	Storage temperature	-40 to +125	°C
T_A	Operating ambient temperature	-20 to +70	°C
	THERMAL RESISTANCE		
θ_{ja}	From junction to ambient	70	°C/W

*NOTE

Additional power caused by the self-inductance of the motor-coils will be dissipated in the diodes (D31 to D34).

TRUTH TABLE[1,2]

S = H									
R = H					R = L				
T	Q1	Q2	Q3	Q4	T	Q1	Q2	Q3	Q4
0	L	H	L	H	0	L	H	L	H
1	H	L	L	H	1	L	H	H	L
2	H	L	H	L	2	H	L	H	L
3	L	H	H	L	3	H	L	L	H
4	L	H	L	H	4	L	H	L	H

Trigger Conditions(T)

NOTES

1. Direction conditions (R)
   The direction of rotation can be changed at any moment independent of the state of the T and S inputs.
2. Set conditions (S)
   When T is HIGH and S LOW then the outputs are set: $Q_1 = L$, $Q_2 = H$, $Q_3 = L$, $Q_4 = H$.

DC ELECTRICAL CHARACTERISTICS $-20°C \leq T_A \leq 65°$, $V_P = 12V$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SAA1027			UNIT
			Min	Typ	Max	
V_P	Supply voltage (pin 14)		9.5	12	18	V
I_P	Supply current	Pin 4 open, without loads, all inputs high	2.0	4.5	6.5	mA
V_{IH}		R, S, T inputs	7.5			V
I_{IH}		R, S, T inputs		1		μA
V_{IL}		R, S, T inputs			4.5	V
I_{IL}		R, S, T inputs		30		μA
V_Q	Supply voltage	Each output stage	1.5	12	18	V
I_Q	Supply current	Each output stage			350	mA
V_{SAT}	Saturation voltage				1	V
	Bias voltage and current	Reference Figure 2.				
	Bias resistor	Reference Figure 3.				
	Bias resistor power dissipation	Reference Figure 4.				
	Device power dissipation	Reference Figure 5.				

TYPICAL PERFORMANCE CHARACTERISTICS

POWER DISSIPATION DERATING CURVE

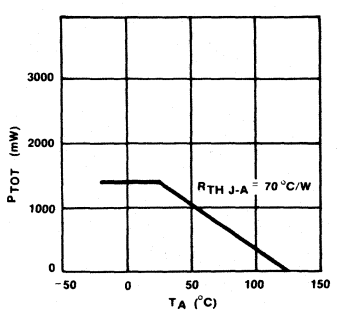


Figure 1

BIAS VOLTAGE AND CURRENT

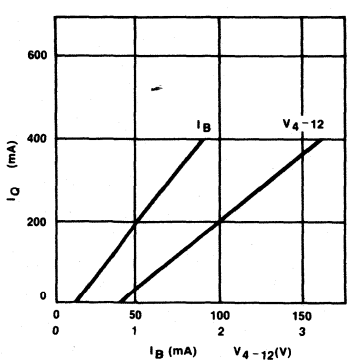


Figure 2

BIAS RESISTOR

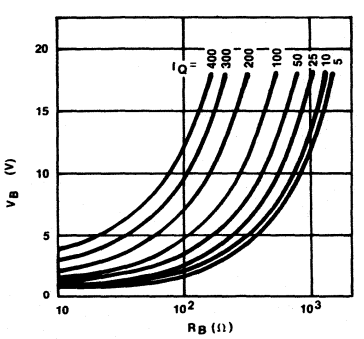


Figure 3

TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

BIAS RESISTOR POWER DISSIPATION

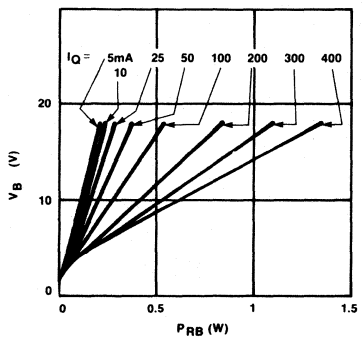


Figure 4

TOTAL DEVICE POWER DISSIPATION

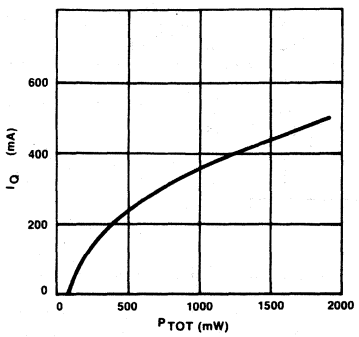


Figure 5

TYPICAL APPLICATIONS

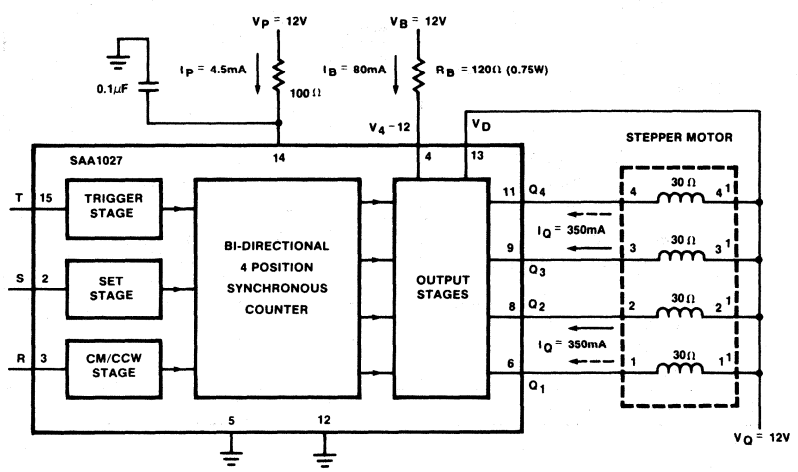


Figure 6

SECTION 9
DISPLAY DRIVERS

Section 9—DISPLAY DRIVERS

9

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

DISPLAY DRIVER DEFINITIONS

T_A

Ambient temperature range. Range of the surrounding environment of the operating device.

T_J

Junction Temperature. The maximum temperature of the device. 150°C is standard for silicon devices.

T_{STG}

Storage temperature range. Temperature range that the device can be stored in a non-operating condition.

T_{SOLD}

Soldering Temperature. The temperature which can be applied to the lead frame of the device for short periods of time (normally specified for a duration of 10 sec).

Truth Tables

0 is logic level low
1 is logic level high
X - don't care condition - has no effect under circuit conditions listed.

Absolute Maximum Rating

Operating safe zones exceeding these limits could cause permanent damage to the device and are not meant to imply that devices can operate at these limits.

Power Dissipation

The power that the device can safely handle at 25°C. The dissipation must be derated as indicated for the individual package type.

Package Type Designation

See full package designations in Appendix.

V_{CC} ($-V_{CC}$)

Supply Voltage. The range of power supply voltage over which the device will operate safely.

LED

Light Emitting Diode

$\overline{XX}$

Negate Bar-when it appears over a function indicates that the "true" or valid condition of that function is a logic low level.

i.e. LE - would require a logic high level to cause a latch enable.
$\overline{LE}$ - would require a logic low level to cause a latch enable.

I_{SEG}

Segment Current. The amount of current supplied to each segment in a display. Current ratios are generally compared to segment 'b'.

BCD

Binary Coded Decimal

$\overline{BI}$/RBO

Blanking Input or Ripple Blanking Output.

$\overline{RBI}$

Ripple Blanking Input. The maximum clock frequency: the maximum input frequency at a clock input for the predictable performance. Above this frequency the device may cease to function.

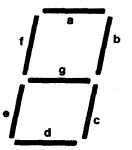
t_{PLH}

Propagation Delay Time. The time between the specified reference points on the input and output waveforms with the output changing from the defined LOW level to the defined HIGH level.

t_{PHL}

Propagation Delay Times. The time between the specified reference points on the input and output waveforms with the output changing from the defined HIGH level to the defined LOW level.

Segment Identification



t_h

Hold Time. The interval immediately following the active transition of the timing pulse (usually the clock pulse) or following the transition of the control input to its latching level, during which interval the data to be recognized must be maintained at the input to ensure its continued recognition. A negative hold time indicates that the current logic level may be released prior to the active transition of the timing pulse and still be recognized.

t_s

Setup Time. The interval immediately preceeding the active transition of the timing pulse (usually the clock pulse) or preceeding the transition of the control input to its latching level, during which interval the data to be recognized must be maintained at the input to ensure its recognition. A negative setup time indicates that the correct logic level may be initiated sometime after the active transition of the timing pulse and still be recognized.

t_W

Pulse Width. The time between the specified reference points on the leading and trailing edges of a pulse.

t_{rec}

Recovery Time. The time between the reference point on the trailing edge of an asynchronous input control pulse and the reference point on the activating edge of a synchronous (clock) pulse input such that the device will respond to the synchronous input.

V_S

Source Voltage. A separate V_{CC} line depending on part type.

I_{OH}

Output Current Source the device can supply while maintaining a specified voltage output level.

Typical Value

The typical value of a particular parameter determined by characterization of the device or sampling. Usually indicates that the particular device is not 100% tested for the parameter because it does not vary or can be determined by design and other tested variables. Occasionally typical values are given rather than min-

DISPLAY DRIVER DEFINITIONS (Cont'd)

max values because 100% testing would raise the cost of the product to a prohibitive level. If a typical value must be guaranteed to ensure specific operation, custom testing can often be provided at an additional cost to the user.

I_S

Source Current. Current flowing into the V_S supply terminal of the device with specified operating conditions.

Duty Cycle

Ratio of time on to time off. Generally expressed in percentage.

V_F

Forward voltage drop of a device at a specified current level.

I_B

Input Bias Current Current into an analog circuit input, specified at a particular voltage level.

CLR

Clear. Clear command will preset all internal circuits to a predetermined state.

CE

Chip Enable.

V_{IH}

Input High Voltage. The range of input voltages recognized by the device as a logic high.

V_{IL}

Input Low Voltage. The range of input voltages recognized by the device as a logic low.

V_{OH}

Output High Voltage. The minimum guaranteed High voltage at an output terminal for the specified output current I_{OH} and at the minimum V_{CC} value.

V_{OL}

Output Low Voltage. The maximum guranteed low voltage at an output terminal sinking the specified load current I_{OL}.

V_{BR}

Output Breakdown Voltage. Maximum voltage applied to a disabled (off) output to ensure a leakage current less than the specified value.

V_{IN}

The range of voltage on any input which the device can safely handle or a specified input voltage to the device.

V_{OUT}

The range of voltage on any output which the device can safely handle or a specified output voltage to the device.

$I_{CC}(-I_{CC})$

Supply Current. The current flowing into the $+V_{CC}$ ($-V_{CC}$) supply terminal of the circuit with specified input conditions and open outputs. Input conditions are chosen to guarantee worst case operation unless specified.

I_{IH}

Input High Current. The Current flowing into or out of an input when a specified High level voltage is applied to that input.

I_{IL}

Input Low Current. The current flowing out of an input when a specified Low level voltage is applied to that input.

I_{OL}

Output Low Current. The current flowing into an output when a which is in the Low State.

I_{OS}

Output Short-Circuit Current. The current flowing out of an output which is in the High state when that output is short circuit to the ground.

I_{CEX}

Output Leakage Current. The current flowing out of or into a disabled (off) output with a specified High output voltage applied.

DESCRIPTION

The NE586/587 is a latch/decoder/driver for 7-segment common anode LED displays. The NE586 outputs draw a constant 25mA, which is essentially independent of output voltage, power supply voltage, and temperature. The NE587 has a programmable current output up to 50mA. The data (BCD) inputs and $\overline{LE}$ (latch enable) input are low-loading so that they are compatible with any data bus system. The 7-segment decoding is implemented with a ROM so that alternative fonts can be made available.

FEATURES

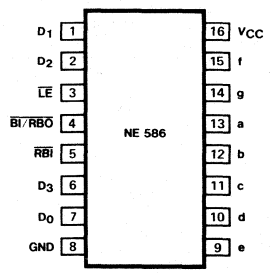
- **Latched BCD inputs**
- **Low loading bus-compatible inputs**
- **Ripple-blanking on leading and/or trailing edge zeros**
- **The NE586 is pin-compatible with 7447, 9374, and 8674**
- **Constant current outputs**

APPLICATIONS

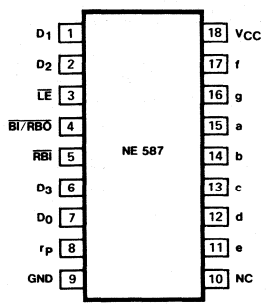
- **Digital panel meters**
- **Measuring instruments**
- **Test equipment**
- **Digital clocks**
- **Digital bus monitoring**

PIN CONFIGURATIONS

F,N PACKAGE



F,N PACKAGE



ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise specified

PARAMETER		RATING	UNIT
V_{CC}	Supply voltage	−0.5 to +7	V
V_{IN}	Input voltage (D_0 - D_3, $\overline{LE}$, $\overline{RBI}$)	−0.5 to +15	V
V_{OUT}	Output voltage (a-g, RBO)	−0.5 to +7	V
P_D	Power dissipation (25°C)[1]	1000	mW
T_A	Ambient temperature range	0 to 70	°C
T_J	Junction temperature	150	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_{SOLD}	Soldering temperature (10 sec. max)	300	°C

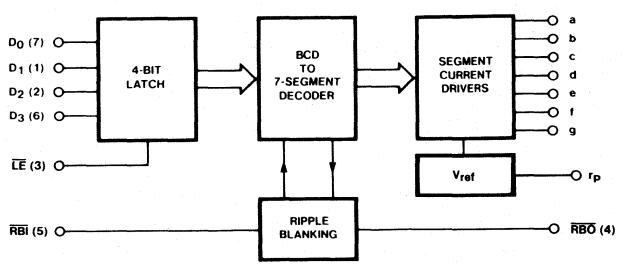
NOTE

Derate power dissipation as indicated

N package - 95°C/watt above 55°C

F package - 100°C/watt above 50°C

BLOCK DIAGRAM



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DC ELECTRICAL CHARACTERISTICS

V_{CC} = 4.75 to 5.25V, 0°C < T_A < 70°C.
Typical values are at V_{CC} = 5V, T_A = 25°C, R_P = 1kΩ (± 1%) unless otherwise stated.

PARAMETER		TEST CONDITIONS	NE586/587			UNIT
			Min	Typ	Max	
V_{CC}	Operating supply voltage		4.75	5.00	5.25	V
V_{IH}	Input high voltage	All Inputs except $\overline{BI}$ + $\overline{RBI}$ $\overline{BI}$ $\overline{RBI}$	2.0 2.0 3.0		15 5.5 15.0	V
V_{IL}	Input low voltage		0		0.8	V
V_{IC}	Input clamp voltage	I_{IN} = −12mA, T_A = 25°C			−1.5	V
I_{IH}	Input high current	Inputs D_0 −D_3, $\overline{LE}$, $\overline{RBI}$ V_{IN} = 2.4V V_{IN} = 15V		0.1	20 250	μA μA
I_{IH}	Input high current	Input $\overline{BI}$ (pin 4) $\overline{RBI}$ = H V_{IN} = V_{CC} = 5.25V			100	μA
I_{IL}	Input low current	V_{IN} = 0.4V, Inputs D_0 − D_3 $\overline{LE}$ $\overline{RBI}$		−5 −200 −140	−50 −400 −300	μA
I_{IL}	Input low current	Input $\overline{BI}$ (pin 4) V_{CC} = 5.25.V $\overline{RBI}$ = H, V_{IN} = 0.4V		−0.45	−1.0	mA
V_{OL}	Output low voltage	Output $\overline{RBO}$ (pin 4) I_{out} = 3.0mA			0.5	V
V_{OH}	Output high voltage	Output $\overline{RBO}$ (pin 4) I_{OUT} = −50μA $\overline{RBI}$ = H	3.5	4.25		V
I_{OUT}	Output segment "ON" current (586 only)	Outputs "a" thru "g", T_A = 25°C V_{OUT} = 1.5V over temp	20 17	25 25	30 33	mA
I_{OUT}	Output segment "ON" current (587 only)	Outputs "a" thru "g" V_{OUT} = 1.5V	20	25	30	mA
ΔI_{OUT}	Output current ratio (for 587 all outputs ON)	With reference to "b" segment V_{OUT} = 1.5V	0.90	1.00	1.10	
I_{OFF}	Output segment "OFF" current	Outputs "a" thru "g" V_{OUT} = 5.0V		20	250	μA
I_{CCO}	Supply current	V_{CC} = 5.25V All outputs "ON" V_{OUT} > 1V		28	50	mA
I_{CCI}	Supply current	V_{CC} = 5.25V All outputs blanked		45	60	mA

AC ELECTRICAL CHARACTERISTICS

V_{CC} = 5V T_A = 25°C. R_L = 130Ω, C_L = 30pF including probe capacity.

PARAMETER		TEST CONDITIONS	NE586/587			UNIT
			Min	Typ	Max	
t_{HL}	Propagation delay Figure 2	From data to output		85		ns
t_{LH}	Propagation delay Figure 3	From $\overline{LE}$ to output		85		ns
t_W	Latch enable pulse width Figure 4		85			ns
t_S	Latch enable setup time Figure 4	From data to $\overline{LE}$	75			ns
t_H	Latch enable hold time Figure 4	From $\overline{LE}$ to data	0			ns

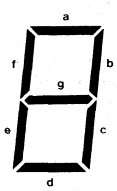
TRUTH TABLE

BINARY INPUT	INPUTS						OUTPUTS								DISPLAY
	$\overline{LE}$	$\overline{RBI}$	D_3	D_2	D_1	D_0	a	b	c	d	e	f	g	$\overline{RBO}$	
–	H	*	X	X	X	X	STABLE								STABLE BLANK
0	L	L	L	L	L	L	H	H	H	H	H	H	H	L	
0	L	H	L	L	L	L	L	L	L	L	L	L	H	H	0
1	L	X	L	L	L	H	H	L	L	H	H	H,	H	H	1
2	L	X	L	L	H	L	L	L	H	L	L	H	L	H	2
3	L	X	L	L	H	H	L	L	L	L	H	H	L	H	3
4	L	X	L	H	L	L	H	L	L	H	H	L	L	H	4
5	L	X	L	H	L	H	L	H	L	L	H	L	L	H	5
6	L	X	L	H	H	L	L	H	L	L	L	L	L	H	6
7	L	X	L	H	H	H	L	L	L	H	H	H	H	H	7
8	L	X	H	L	L	L	L	L	L	L	L	L	L	H	7
9	L	X	H	L	L	H	L	L	L	L	H	L	L	H	9
10	L	X	H	L	H	L	H	H	H	H	H	H	L	H	-
11	L	X	H	L	H	H	L	H	H	L	L	L	L	H	E
12	L	X	H	H	L	L	H	L	L	H	L	L	L	H	H
13	L	X	H	H	L	H	H	H	H	L	L	L	H	H	L
14	L	X	H	H	H	L	L	L	H	H	L	L	L	H	P
15	L	X	H	H	H	H	H	H	H	H	H	H	H	H	blank
**BI	X	X	X	X	X	X	H	H	H	H	H	H	H	L**	blank

H = HIGH voltage level, output is "OFF"
L = LOW voltage level, output is "ON"
X = Don't care

* The $\overline{RBI}$ will blank the display only if a binary zero is stored in the latches.
** $\overline{RBO}/\overline{BI}$ used as an input overrides all other input conditions.

SEGMENT IDENTIFICATION



NE587 PROGRAMMING

NE587 output current can be programmed by using a programming resistor, R_P, connected between r_P (pin 8) and Gnd (pin 9). The voltage at r_P (pin 8) is constant ($\approx$1.25V). A partial schematic of the voltage reference used in the NE586 and NE587 is shown in figure 1. R_P is internal for the NE586. I_P can be calculated as shown.

Output current to program current ratio, I_O/I_P, is 20 in the 15mA to 50mA range. Note that I_P must be derived from a resistor (R_P), and not from a high impedance source such as an I_{OUT} DAC used to control display brightness.

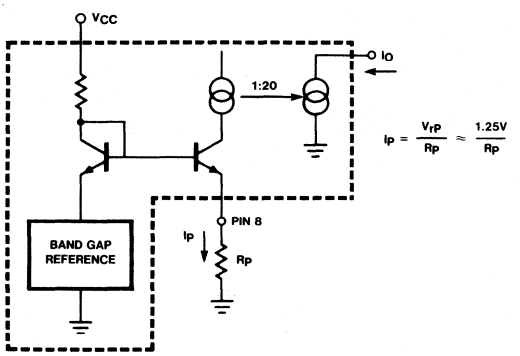


Figure 1

TIMING DIAGRAMS

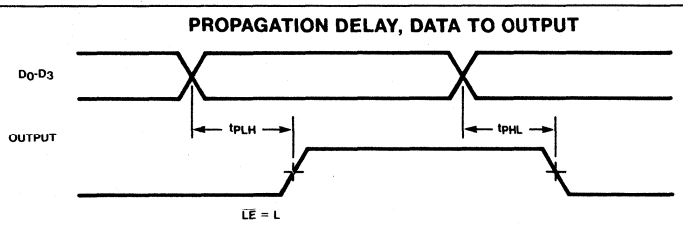


Figure 2

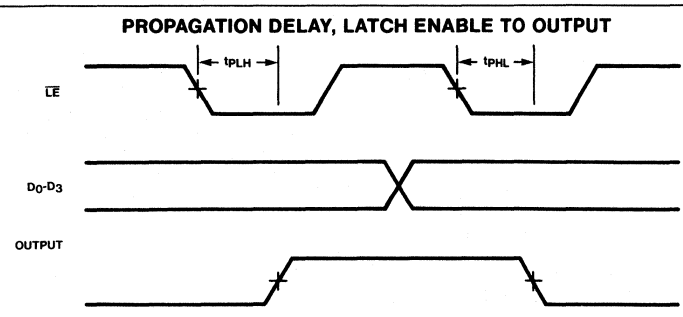


Figure 3

POWER DISSIPATION CONSIDERATIONS

LED displays are power hungry devices, and inevitably somewhat inefficient in their use of the power supply necessary to drive them. Duty cycle control does afford one way of improving display efficiency, provided that the LEDS are not driven too far into saturation, but the improvement is marginal. Operation at higher peak currents has the added advantage of giving much better matching of light output, both from segment-to-segment and digit-to-digit.

An output current of 25mA was chosen for the NE586 so that it would be suitable for multiplexed operation of large size LED digits. When designing a display system, particular care must be taken to minimize power dissipation within the IC display driver. Since the NE586 output is a constant current source, all the remaining supply voltage, which is not dropped across the LED (and the digit driver, if used), will appear across the output of the NE586. Thus, the power dissipation in the NE586 will go up sharply if the display power supply voltage rises. Clearly, then, it is good design practice to keep the display supply voltage as low as possible consistent with proper operation of the supply output current sources. Inserting a resistor or diode in series with the display supply is a good way of reducing the power dissipation within the integrated circuit segment driver, although, of course, total system power remains the same.

Power dissipation within the NE586 may be calculated as follows. Referring to figure 13, the two system power supplies are V_{CC} and V_S. In many cases, these will be the same voltage. Necessary parameters are:

V_{CC},	Supply voltage to driver
V_S,	Supply voltage to display
I_{CC},	Quiescent supply current of driver
I_{SEG},	LED segment current
V_F,	LED segment forward voltage at I_{seg}
K_{DC},	% Duty cycle

V_F, the forward LED drop, depends upon the type of LED material (hence the color) and the forward current. The actual forward voltage drops should be obtained from the LED display manufacturer's literature for the peak segment current selected; however, approximate voltages at nominal rated currents are:

Red	1.6 to 2.0V
Orange	2.0 to 2.5V
Yellow	2.2 to 3.5V
Green	2.5 to 3.5V

TIMING DIAGRAMS (Cont'd)

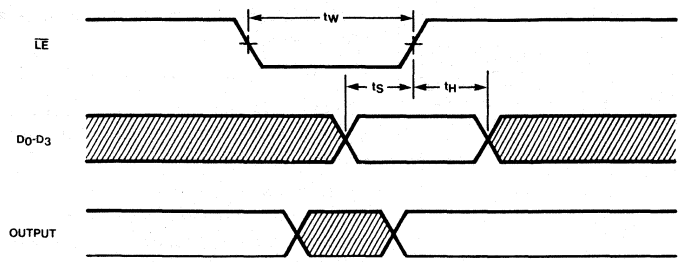


Figure 4

These voltages are all for single diode displays. Some early red displays had 2 series LEDS per segment; hence the forward voltage drop was around 3.5V.

Thus a maximum power dissipation calculation when all segments are on, is:

$P_d = V_{CC} \times I_{CC} + (V_S - V_F) \times 7 \times I_{seg} \times K_{DC}$ mW

Assuming $V_S = V_{CC} = 5.25V$
$V_F = 2.0V$
$K_{DC} = 100\%$
$P_{d\ max} = 5.25 \times 50 + 3.25 \times 7 \times 30$ mW
$= 945$ mW

TYPICAL PERFORMANCE CURVES

OUTPUT CURRENT VS OUTPUT VOLTAGE
NE586

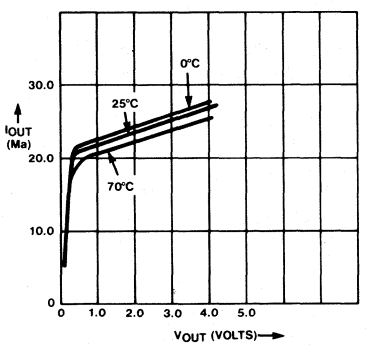


Figure 5

OUTPUT CURRENT VS OUTPUT VOLTAGE
NE587
R_P = 1Kohms

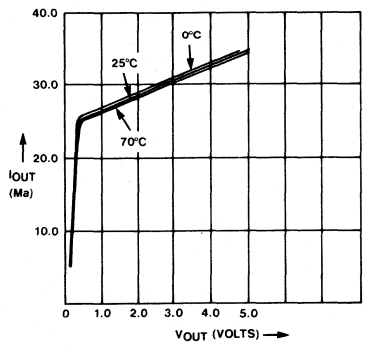


Figure 6

NORMALIZED OUTPUT CURRENT
VS TEMPERATURE
NE586/587
V_{CC} = 5.0 VOLTS

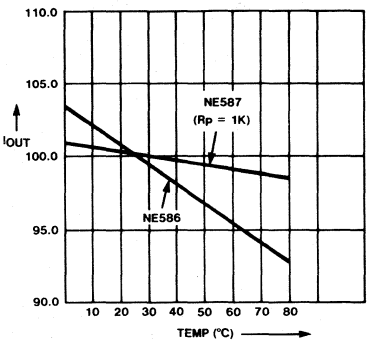


Figure 7

NORMALIZED OUTPUT CURRENT
VS SUPPLY VOLTAGE
NE586/587
V_O = 1.5V
T_A = 25°C

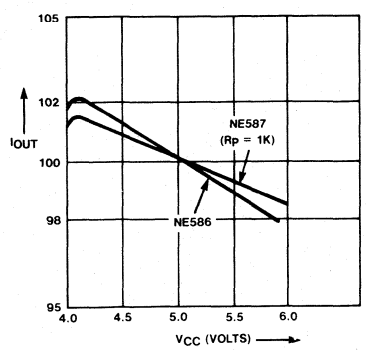


Figure 8

MAXIMUM POWER DISSIPATION
VS TEMPERATURE

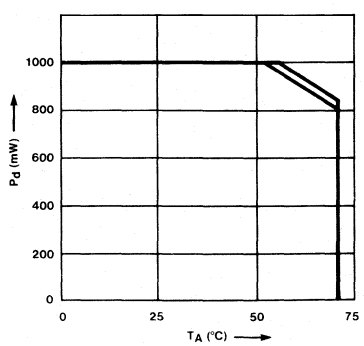


Figure 9

TYPICAL PERFORMANCE CURVES (Cont'd)

SUPPLY CURRENT VS SUPPLY VOLTAGE NE586

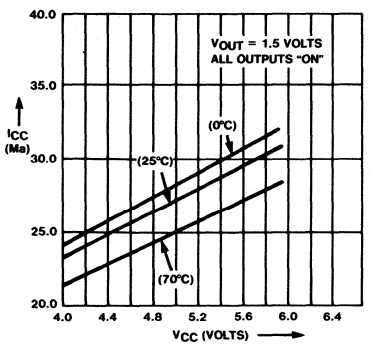


Figure 11

SUPPLY CURRENT VS SUPPLY VOLTAGE NE587

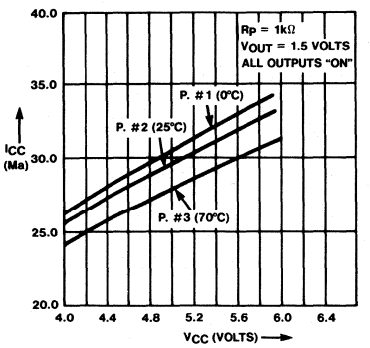
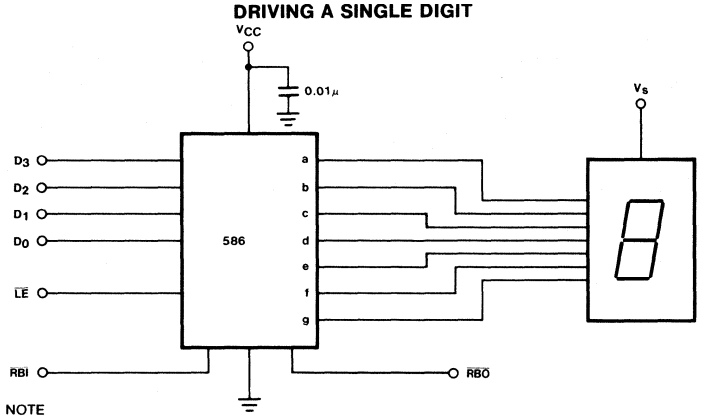


Figure 12

TYPICAL APPLICATIONS

DRIVING A SINGLE DIGIT



NOTE
Decoupling capacitor on V_{CC} should be 0.01 μF ceramic

Figure 13

However, the average power dissipation will be considerably less than this. Assuming 5 segments are on (the average for all output code combinations), then

$P_{d\,av} = 5.0 \times 30 + 3.00 \times 5 \times 25$ mW
$= 525$ mW

Operating temperature range limitations can be deduced from the power dissipation graph in figure 9.

However, a major portion of this power dissipation ($P_{d\,max}$) is because the current source output is operating with 3.25 V across it. In practice, the outputs operate satisfactorily down to 0.5V, and so the extra voltage may be dropped external to the integrated circuit.

Suppose the worst case V_{CC}/V_S supply is 4.75 to 5.25V, and that the maximum V_E for the LED display is 2.25V. Only 2.75V is required to keep the display active, and hence 2.0V may be dropped externally with a resistor from V_{CC} to V_S. The value of this resistor is calculated by:

$$R_S = \frac{2.0}{7 \times I_{seg}} \simeq 10\Omega\ (\tfrac{1}{2}\text{ W rating})$$

assuming worst case I_{seg} of 30 mA

Hence now $P_{d\,max} = V_{CC} \times I_{CC} + (V_S - V_V - R_X \times 7 \times I_{seg}) \times 7 \times X \times I_{seg} \times K_{DC}$
$= 5.25 \times 50 + 1.25 \times 7 \times 30$ mW
$= 525$ mW

and $P_{d\,av} = 5.0 \times 30 + 1.25 \times 5 \times 25$
$= 306$ mW

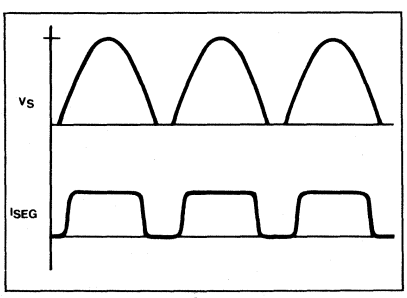
If a diode (or 2) is used to reduce voltage to the display, then the voltage appearing across the display driver will be independent of the number of "ON" segments and will be equal to

$V_S - V_F - nV_d$, $V_D \simeq 0.8V$

Where n is the number of diodes used, power dissipation can be calculated in a similiar manner.

In a multiplexed display system, the voltage drop across the digit driver must also be considered in computing device power dissipation. It may even be an advantage to use a digit driver which drops an appreciable voltage, rather than the saturating PNP transistors shown in figure 16. For example a darlington PNP or NPN emitter follower may be preferable. Figure 15 shows the NE591 as the digit driver in a multiplexed display system. The NE591 output drops about 1.8V which means that the power dissipation is evenly distributed between the two integrated circuits.

Where V_S and V_{CC} are two different supplies, the V_S supply may be optimized for minimum system power dissipation and/or cost. Clearly, good regulation in the V_S supply is totally unnecessary, and so this supply can be made much cheaper than the regulated 5V supply used in the rest of the system. In fact a simple unsmoothed full-wave rectified sine wave works extremely well if a slight loss in brightness can be tolerated. A transformer voltage of about 3-4.5V rms works well in most LED display systems. Waveforms are shown below:



The duty cycle for this system depends upon V_S, V_F and the output characteristics of the display driver.

With
$V_S = 4.9V$ pk.
$V_F = 2.0V$

The duty cycle is approximately 60%.

TYPICAL PERFORMANCE CURVES (Cont'd)

OUTPUT CURRENT VS PROGRAM RESISTOR

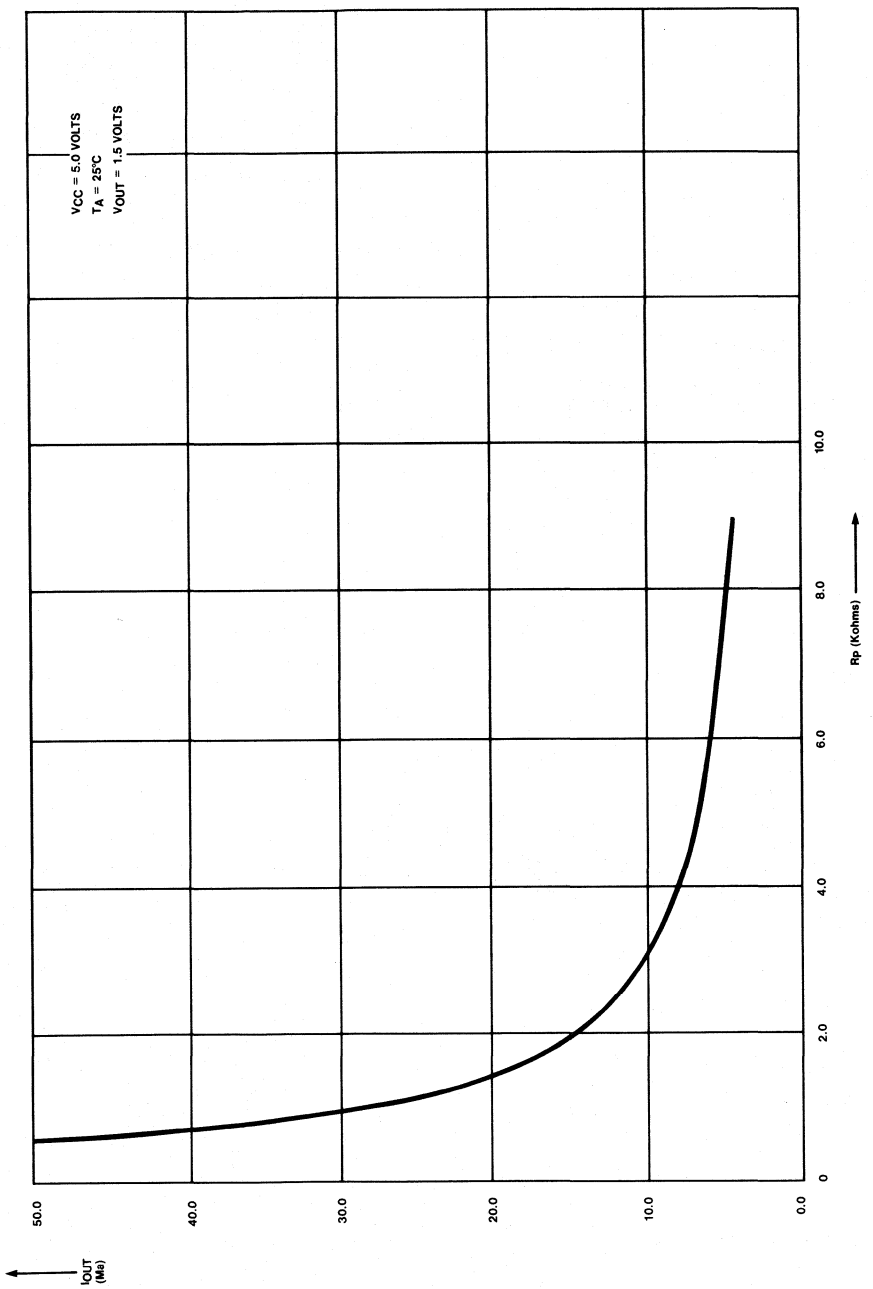


Figure 10

9

TYPICAL APPLICATIONS (Cont'd)

4-DIGIT DISPLAY WITH BRIGHTNESS CONTROL AND LEADING EDGE RIPPLE BLANKING

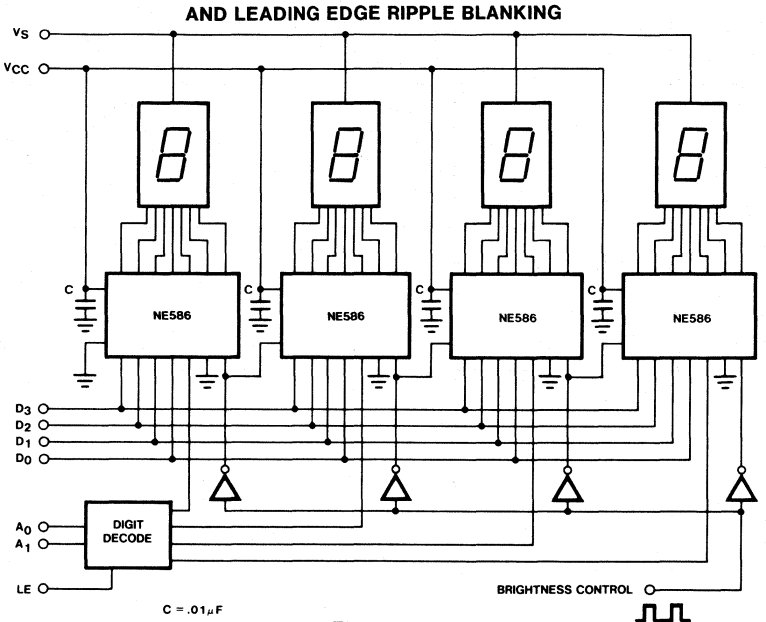


Figure 14

INTERFACING 8-DIGIT LED DISPLAY WITH μP BUS

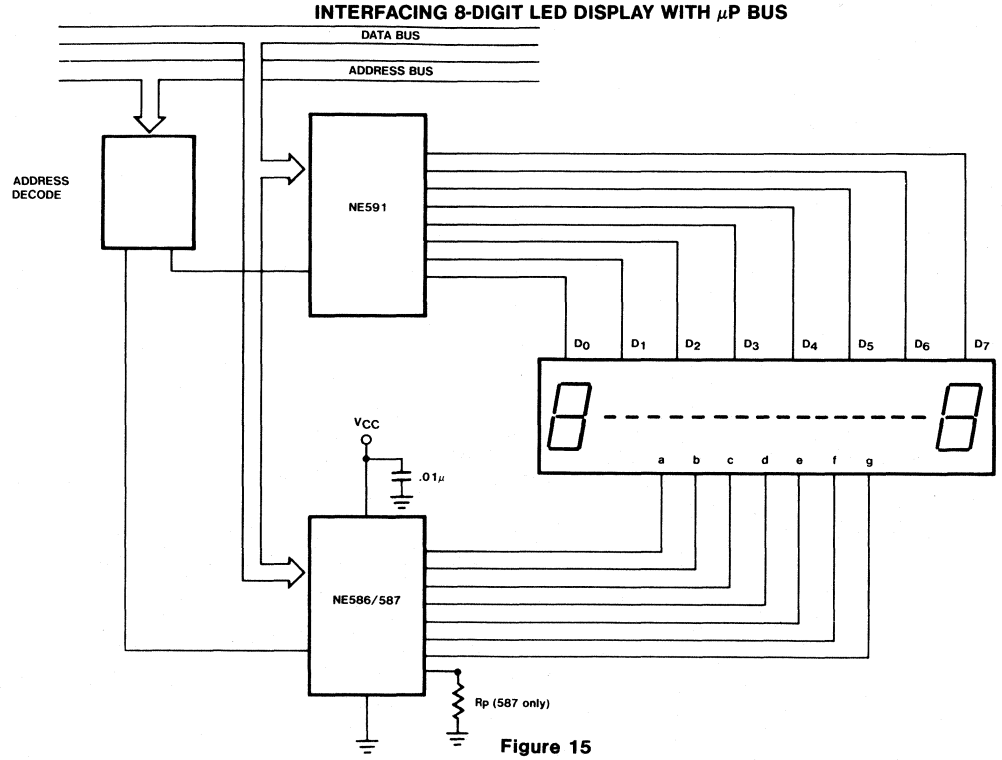


Figure 15

TYPICAL APPLICATIONS (Cont'd)

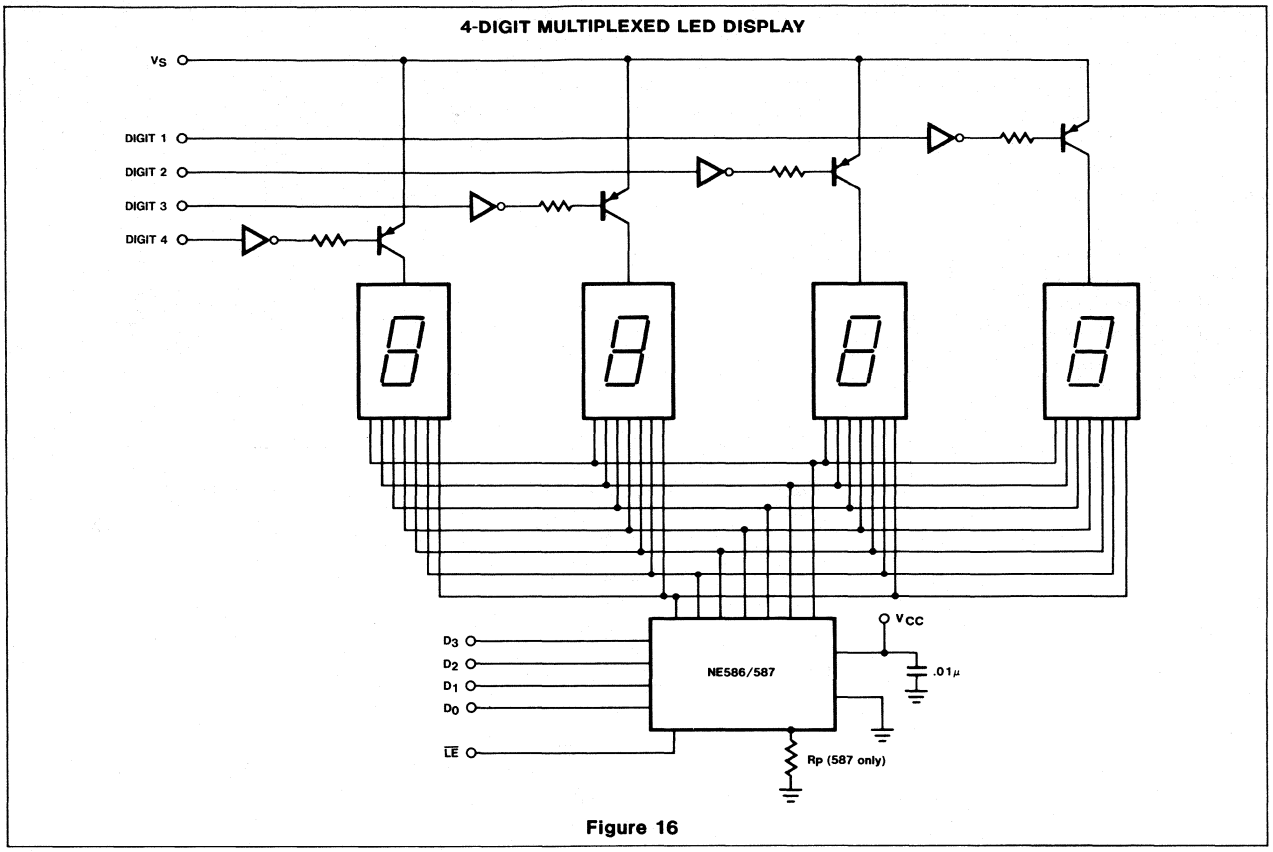


Figure 16

PRELIMINARY SPECIFICATION

DESCRIPTION

The SA594 is a display driver interface for vacuum fluorescent displays. The device is comprised of 8 drivers and a bias network and is capable of driving the digits and/or segments of most vacuum fluorescent displays.

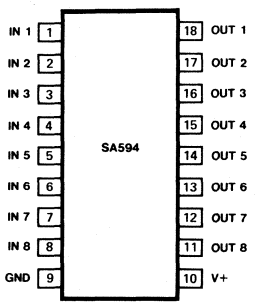
The inputs are designed to be compatible with TTL, DTL, NMOS, PMOS or CMOS output circuitry.

There is an active pull-down circuit on each output so that display ghosting is minimized and no external components are required for most fluorescent display applications.

FEATURES

- **Digit and/or segment drivers**
- **Active output pull-down circuitry**
- **High output breakdown voltage**
- **Low supply voltage**
- **Input compatible with all logic outputs**

PIN CONFIGURATION



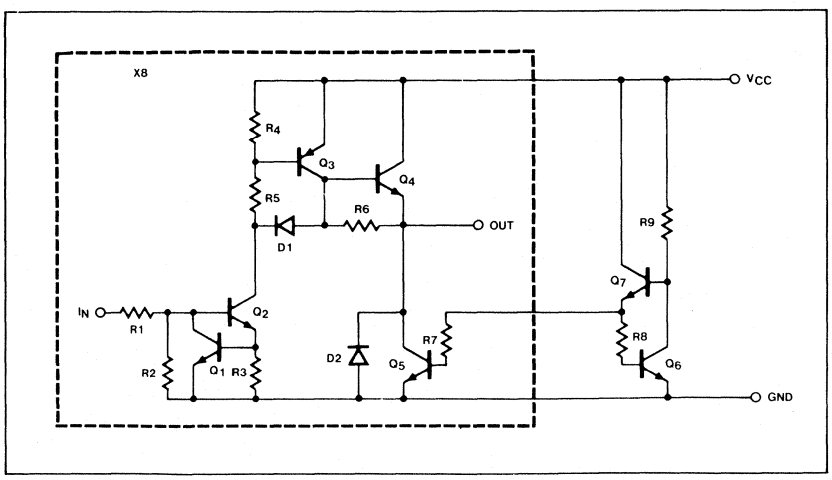
SA594N Plastic DIP
SA594F Ceramic DIP

ABSOLUTE MAXIMUM RATINGS (at 25°C unless otherwise noted)

	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	45	V
V_{OUT}	Output voltage	V_{CC}	
V_{IN}	Input voltage	−0.3, +20	V
I_{OUT}	Output current		
	Each output	50	mA
	All outputs	200	mA
Pd	Power dissipation* (at 25°C)	800	mW
T_A	Operating temperature range	−40 to +85	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_J	Maximum junction temperature	150	°C
T_{SOLD}	Lead soldering temperature (10 seconds)	300	°C

NOTE
*Derate N (Plastic) Package above 38°C at 7.14 mW/°C.
Derate F (Ceramic) Package above 75°C at 10.8 mW/°C.

EQUIVALENT SCHEMATIC



PRELIMINARY SPECIFICATION

DC ELECTRICAL CHARACTERISTICS V_{CC} = +4.75 to +40V, T_A = −40 to +85°C unless otherwise stated.

PARAMETER		TEST CONDITIONS		SA594 Min	SA594 Typ	SA594 Max	UNIT
V_{CC}	Supply voltage range			4.75	35	40	V
I_{CCH}	Supply current (all outputs high)	V_{CC} = 40V	V_{IN} = 3.5V		3	6	mA
I_{CCL}	Supply current (all outputs low)	V_{CC} = 40V	V_{IN} = 0.4V		0.4	1	mA
V_{IN}	Input voltage range			0		15	V
V_{IH}	Input voltage to ensure logic '1'			2.6			V
V_{IL}	Input voltage to ensure logic '0'					0.8	V
I_{IH}	Input current to ensure logic '1'			100			μA
I_{IL}	Input current to ensure logic '0'					10	μA
I_{IN}	Input current	V_{IN} = 2.6V			60	100	μA
		V_{IN} = 5.0V			180	250	μA
		V_{IN} = 15.0V			.68	1.0	mA
V_{OH}	Output high voltage	V_{IN} = 3.5V	T_A = 25°C	V_{CC}−1.5	V_{CC}−1.1		V
		I_{OUT} = −25mA	Over Temp.	V_{CC} −2	V_{CC}−1.3		V
		V_{OUT} with respect to V_{CC}					
V_{OH}	Output high, *no load* voltage	V_{IN} = 3.5V I_{OUT} = 0, T_A=25°C V_{OUT} with respect to V_{CC}		V_{CC}−1	V_{CC}−0.8		V
V_{OFF}	Output 'OFF' voltage level	V_{IN} = 0.8V I_{OUT} = 0			10	200	mV
I_{OH}	Available output current	V_{CC} = 35V V_{OUT} = 30V T_A = 25°C	V_{IN} = 3.5V	−35			mA
I_{OUT}	Output pulldown current	V_{CC} = V_{OUT} = 35V Inputs open		100	200	400	μA
I_{CEX}	Output leakage current	T_A = 25°C V_{CC} = 40V,	V_{IN} = 0.4V V_{OUT} = 0V		−1		μA

AC ELECTRICAL CHARACTERISTICS[1] V_{CC} = 35V, T_A = 25°C

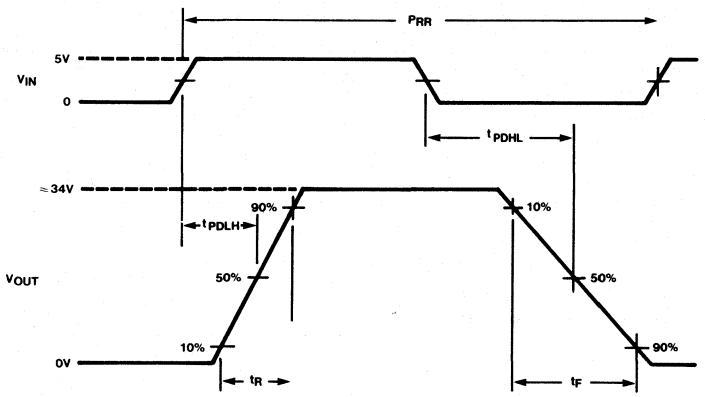
PARAMETER		TEST CONDITIONS	SA594 Min	SA594 Typ	SA594 Max	UNIT
t_{PdLH}	Propagation delay - low to high output transition.	50% V_{IN} to 50% V_{OUT}		1	5	μS
t_{PdHL}	Propagation delay - high to low output transition.	50% V_{IN} to 50% V_{OUT}		3	10	μS
t_R	Output rise time	10% V_{OUT} to 90% V_{OUT}		0.5	3	μS
t_F	Output fall time	90% V_{OUT} to 10% V_{OUT}		1.5	5	μS

NOTE

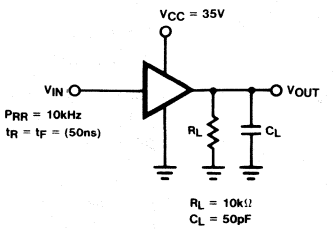
1. See figure 1

SWITCHING TIMES OF DRIVERS

VOLTAGE WAVEFORMS



TEST CIRCUIT

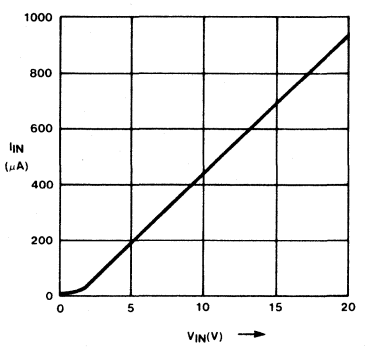


INCLUDES PROBE AND FIXTURE CAPACITANCE

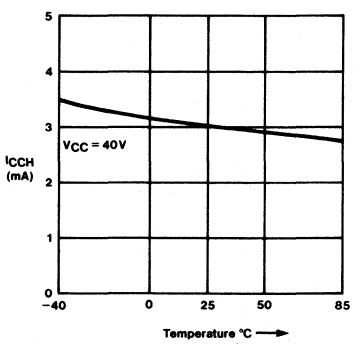
Figure 1

TYPICAL PERFORMANCE CHARACTERISTICS

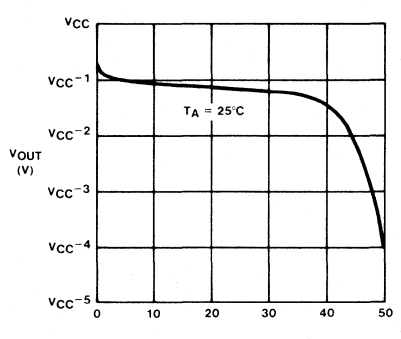
I_{IN} VS V_{IN}



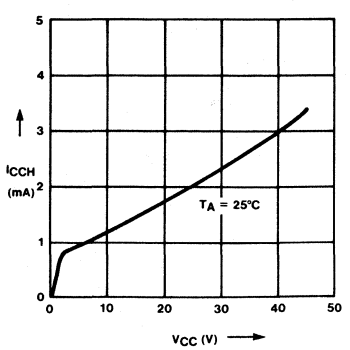
I_{CCH} VS TEMPERATURE



OUTPUT VOLTAGE VS OUTPUT CURRENT



I_{CC} VS V_{CC} (ALL INPUTS HIGH)



TYPICAL APPLICATION
DIGITAL CLOCK WITH ALARM

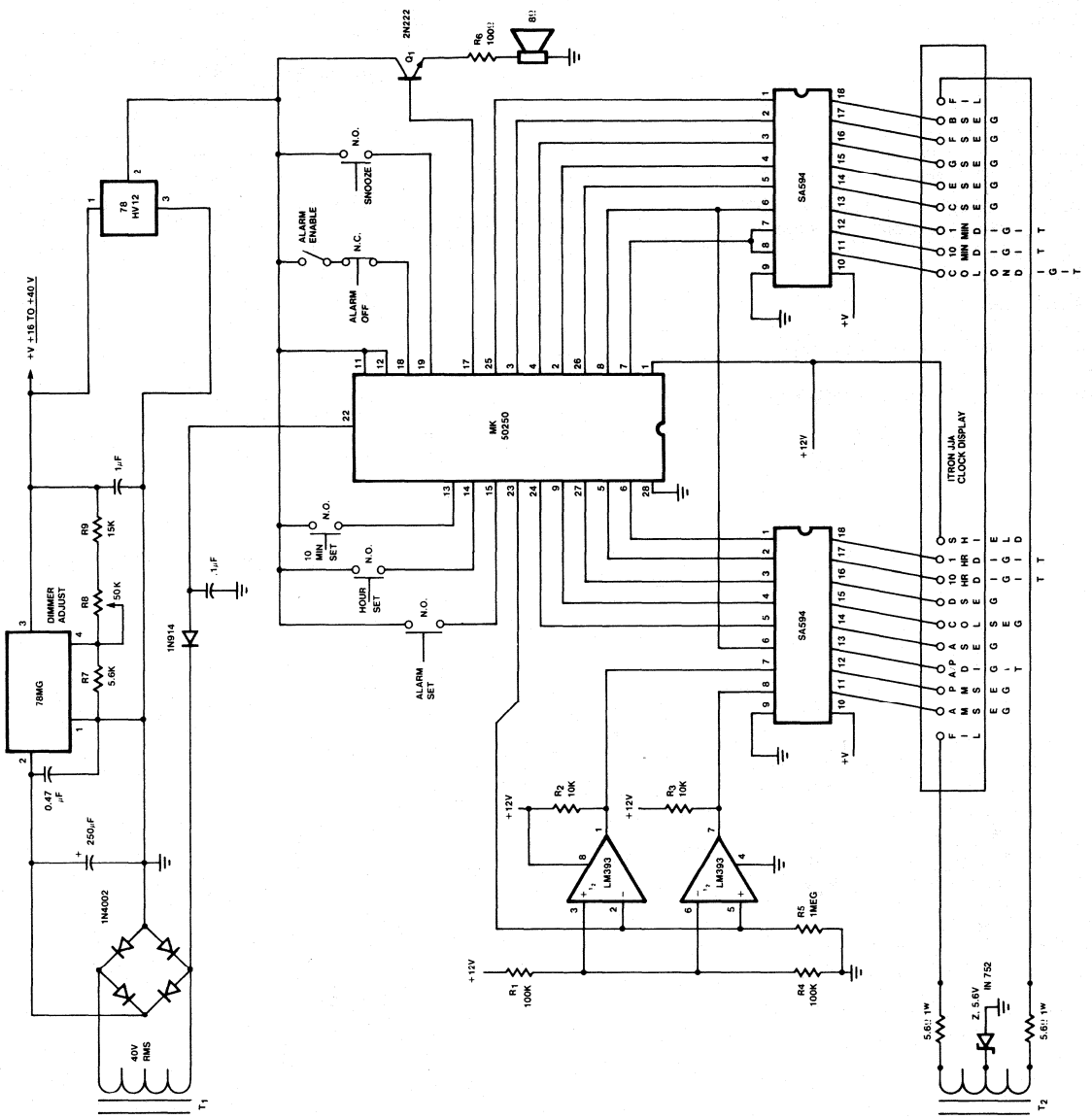


Figure 2

NE582-N

DESCRIPTION

The NE582 is a general interface device comprising a high current output transistor and drive circuitry in each of 6 elements. Each output transistor is individually capable of sinking 400mA with a typical saturation voltage of 0.5V. Input loading is such that direct interfacing with P-MOS, N-MOS, C-MOS or TTL is possible.

The NE582 has applications as a LED display driver, low voltage relay/lamp drivers and many others where high current capability without speed constraints is required.

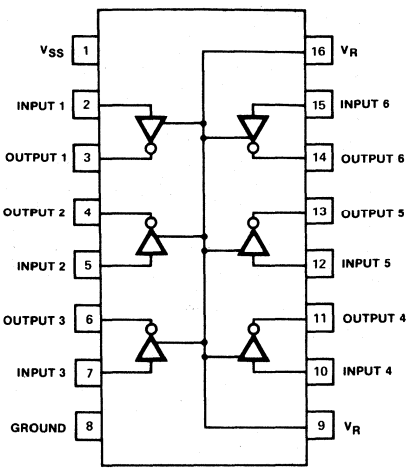
The NE582 is supplied in a 16-pin high dissipation dual-in-line plastic package.

FEATURES

- **Low saturation voltage (typically 0.5V) for minimum power dissipation**
- **High output sink current capability—400mA**
- **Low input current loading for MOS compatibility**
- **Low standby power consumption**
- **Suitable for 3 volt battery operation**
- **Inputs/outputs are compatible with 75494**

PIN CONFIGURATION

N PACKAGE

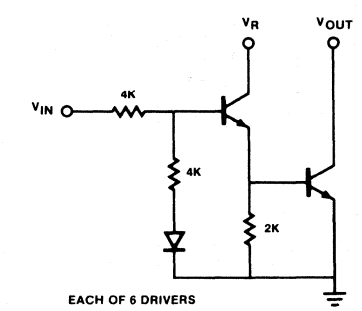


ORDER PART NO.
NE582N

ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Input voltage range[1]	-12 to V_{SS}	V
Output voltage[2]	10	V
Output to input voltage differential	10	V
Voltage at V_{SS} (pin 1)	10	V
Output current—each output	400	mA
Output current—all outputs	800	mA
Continuous total power dissipation at or below 25°C[3]	800	mW
Current in V_R (pin 9 or 16)	25	mA
Operating free-air temperature range	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead temperature 1/16 inch from case for 10sec	260	°C

EQUIVALENT SCHEMATIC



NOTES

1. The inputs are the only pins which may be negative with respect to ground.
2. Voltage values are with respect to ground.
3. Above 25°C, derate power dissipation at 6.25mW/°C.

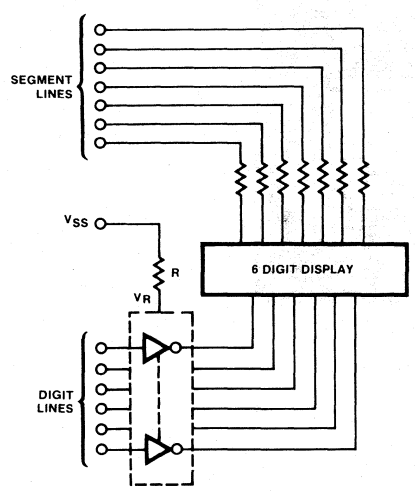
ELECTRICAL CHARACTERISTICS $T_A = 0°C$ to $70°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
V_{OL}	Low level output voltage	V_{IN} I_R I_{OL} V mA mA 6.5 12 250 6.5 20 400 R_{IN} = 1K (Series input resistance)		 .320 .500	 .450 .750	 V V
I_{OH}	High level output current	V_{OH} = 10V, I_{IN} = 40μA V_{OH} = 10V, V_{IN} = 0.5V			400 400	μA μA
I_{IN}	Input current at maximum Input voltage	V_{IN} = 10V, I_{OL} = 20mA, I_R = 2mA		2.2	3.3	mA
V_R I_{SS}	Current into pin 1	V_{IN} = 6.5V, I_R = 6mA, I_{OL} = 80mA V_{SS} = 10V		.9	1.5 100	V μA

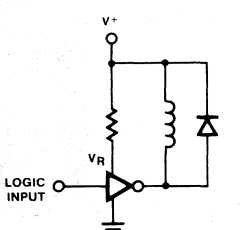
AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
T_{PLH}	Switching characteristics Propagation delay, low to high level input	R_R = 680Ω R_L = 39Ω C_L = 15pF		300		ns
T_{PHL}	Propagation delay, high to low level input	V_{IH} = 7.5V V_{IL} = 0V $t_r = t_f \leq 10ns$ $t_w = 1\mu s$ PRR = 100kHz		30		ns

TYPICAL APPLICATION FOR DIGIT DRIVING OF AN LED DISPLAY



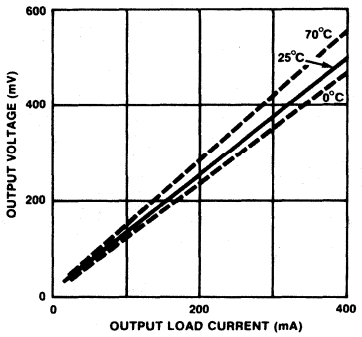
1/6 NE582 AS A RELAY DRIVER



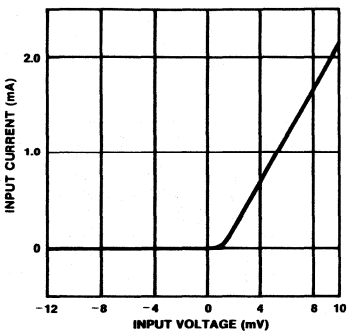
1/6 NE582 AS A RELAY DRIVER

PRELIMINARY SPECIFICATION

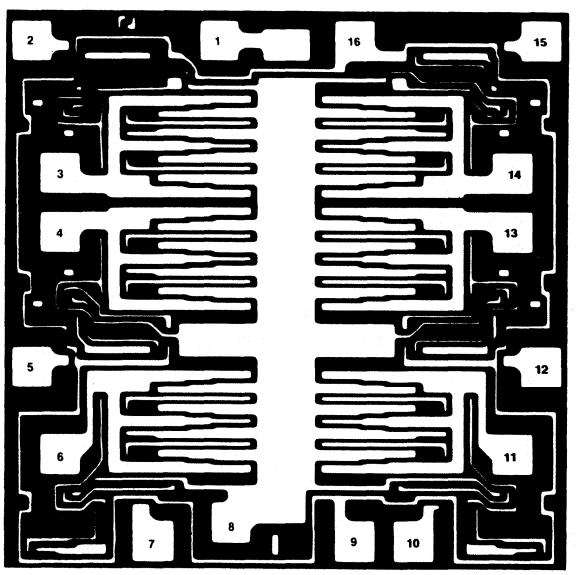
OUTPUT SATURATION VOLTAGE AS A FUNCTION OF OUTPUT LOAD CURRENT, I_R = 25mA V_{IN} = 6.5 VOLTS



INPUT CURRENT AS A FUNCTION OF INPUT VOLTAGE, I_R = 25mA, V_{SS} = 10V, T_A = 25°C



CHIP LAYOUT



SECTION 10
D/A-A/D CONVERTERS

Section 10—D/A—A/D CONVERTERS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

T_A
Ambient temperature range. Range of the surrounding environment of the operating device.

T_J
Junction Temperature. The maximum temperature of the device. 150°C is standard for silicon devices.

T_{STG}
Storage temperature range. Temperature range that the device can be stored in a non-operating condition.

T_{SOLD}
Soldering Temperature. The temperature which can be applied to the lead frame of the device for short periods of time (normally specified for a duration of 10 sec).

Truth Tables
0 is logic level low
1 is logic level high
X - don't care condition - has no effect under circuit conditions listed.

Absolute Maximum Rating
Operating safe zones exceeding these limits could cause permanent damage to the device and are not meant to imply that devices can operate at these limits.

Power Dissipation
The power that the device can safely handle at 25°C. The dissipation must be derated as indicated for the individual package type.

Package Type Designation
See full package designations in Appendix.

V_{CC} ($-V_{CC}$)
Supply Voltage. The range of power supply voltage over which the device will operate safely.

Accuracy
The maximum deviation of the DAC output relative to an ideal straight line drawn from zero to full scale; 1 LSB for any bit combination.

Monotonicity
For a 1 LSB increase of input code, the output either increases or remains the same.

Differential Linearity
The incremental error from an ideal 1 LSB analog output change when the digital input is changed 1 LSB; guaranteed monotonicity requires the differential linearity error be less than 1 LSB and with a tempco of essentially zero.

Absolute Accuracy
Error of a D/A converter output is the difference between the analog output expected and the actual output with a given code applied. Error of an A/D converter is the difference between the theoretical analog output required to produce a given output code and the actual input required to produce a given output code and the actual input required to produce that same code. The actual input is a range and the measured value is the midpoint of the measured band and the theoretical midpoint.

Resolution
The number of bits on the input or output of an A/D or D/A converter. The number of discrete steps or states is equal to 2^n when n is the resolution of the converter. However, n bits of resolution does not guarantee n bits of accuracy.

Quantizing Error
In an A/D converter, there is an infinite number of possible input voltages, but only 2^n output codes (n = number of bits). Therefore, there will be an error as great as 1/2LSB because of this quantizing effect and the greatest error will occur at the transition voltage where the output changes state.

No Missing Codes
This is a property of an A/D converter that is related to, but is more stringent than monotonicity. If a converter is guaranteed to have no missing codes, there will be no output digital state that will be skipped when the input voltage is varied over the entire range.

Most Significant Bit (MSB)
The highest-order bit or the bit with the greatest weight.

Least Significant Bit (LSB)
The lowest-order bit or the bit with the least weight.

Gain Error
The error in the input-to-output ratio, usually expressed in percent.

Offset Error
This is an error in the reference point of the transfer function. It appears as a constant amplitude error signal at a D/A output or an A/D input. It also appears as a constant frequency shift in the output of a V/F converter. It is nulled prior to adjusting gain error by setting the input to the most-negative input and adjusting the output to the proper value.

Settling Time
The time delay between a change of input signal value and the effected change in the output signal. It is usually expressed in terms of how long it takes the output to arrive at, and remain within, a certain error band around the final value and is often given for several different magnitudes of input step change.

Conversation Time
Time required for a complete measurement by an A/D converter. Conversion times are a function of the number of bits (resolution) and the clock frequency.

Switching Time
The time it takes for a multiplexer to change from one channel to the next with the new output signal being within a certain percentage of its final value. It is expressed for a maximum voltage transition.

Throughput Rate
An A/D converter or a data acquisition system has a finite number of points that it can convert in any given time. Throughput rate is an expression of that quantity. It is dependent on the time it takes to make a conversion and the time required to set up to make the next conversion. In a data acquisition system this time includes the composite delay due to switching and settling times of the mux, settling time of the amplifier and acquisition time of the sample-and-hold.

Full Scale Tempco
The change in DAC full scale current with change in temperature expressed in ppm/°C.

Differential Non-Linearity Tempco
The non-linearity specification over a specified range of temperatures. This specification generally appears as the range of tem-

peratures that the device is monotonic (DAC) or has no missing codes (ADC).

Leakage Current

Multiplexer input current that does not flow through to the output but is shunted internally. It is also current that flows from OFF channels into the ON channel. In a current output D/A converter, there is a digital input code that ideally yields zero output current. If current flows with that input code, it is called leakage current. It is analogous to output voltage offset in a voltage-output D/A converter.

Power Supply Sensitivity

The change in DAC output current with changes in power supply voltage.

Output Voltage Compliance

The range of allowable voltage levels the output pins can assume without a major effect on circuit performance.

Compliance Voltage Range

For a current source the maximum range of terminal voltage for which the current source will maintain its specified values.

NOTE

Refer to Section 5 (Interface Circuits) of the 1979 Analog Applications Manual for an in-depth explanation of Converters and their applications

SE/NE 5018 DAC

COMPETITION	INDUSTRY VALUE	KEY PARAMETER	SIGNETICS AVAILABLE VALUE	SIGNETICS ORIGINATED DEVICES	QR&A		COMMENTS
					SURE II	SUPR II	
AMD Analog Devices Datel Fairchild Harris Precision National	8	Resolution (Bits)	8 Bits	NE5018 SE5018 NE5019 SE5019	Yes Yes Yes Yes	Yes Yes Yes Yes	*Not pin for pin replacement. Do not have total capability of the NE5018 μP compatible series.
	.19	Linearity	0.1 %				
	2- 300 μ sec	Settling Time ½ LSB	2 μsec				
	10-50	Gain TC	20 PPM/°C				
	0-4	Current (Output)	 mA	NE/SE 5118 NE/SE 5119	Yes Yes	Yes Yes	
	−10 to +18	Voltage (Output)	0-10 ±5 Volts	NE5018 SE5019	Yes Yes	Yes Yes	

DAC-08/08A

COMPETITION	INDUSTRY VALUE	KEY PARAMETER	SIGNETICS AVAILABLE VALUE	SIGNETICS ORIGINATED DEVICES	QR&A		COMMENTS
					SURE II	SUPR II	
AMD Analog Devices Datel Motorola National	8	Resolution	8 Bits	NE/SE5008 NE/SE5009	Yes Yes	Yes Yes	
	.19	Linearity	19 %FS	NE/SE5008 NE/SE5009	Yes Yes	Yes Yes	
	85-300	Settling time	135 nsec	NE/SE5008 NE/SE5009	Yes Yes	Yes Yes	
	48-500	Power supply regulator	48 mW	NE/SE5008 NE/SE5009	Yes Yes	Yes Yes	

DESCRIPTION

The 5007/5008 series of 8-bit monolithic multiplying Digital-to-Analog Converters provide very high speed performance coupled with low cost and outstanding applications flexibility.

Advanced circuit design achieves 85ns settling times with very low glitch and at low power consumption. Monotonic multiplying performance is attained over a wide 40 to 1 reference current range. Matching to within 1 LSB between reference and full scale currents eliminates the need for full scale trimming in most applications. Direct interface to all popular logic families with full noise immunity is provided by the high swing, adjustable threshold logic inputs.

Dual complementary outputs are provided, increasing versatility and enabling differential operation to effectively double the peak-to-peak output swing. True high voltage compliance outputs allow direct output voltage conversion and eliminate output op amps in many applications.

All 5007/5008 series models guarantee full 8-bit monotonicity and linearities as tight as 0.1% over the entire operating temperature range are available. Device performance is essentially unchanged over the ±4.5V to ±18V power supply range, with 33mW power consumption attainable at ±5V supplies.

The compact size and low power consumption make the 5007/5008 attractive for portable and military/aerospace applications.

FEATURES

- **Fast settling output current—85ns**
- **Full scale current prematched to ±1 LSB**
- **Direct interface to TTL, CMOS, ECL, HTL, PMOS**
- **Relative accuracy to 0.1% maximum over temperature range**
- **High output compliance—-10V to +18V**
- **True and complemented outputs**
- **Wide range multiplying capability**
- **Low FS current drift—±10ppm/°C**
- **Wide power supply range—±4.5V to ±18V**
- **Low power consumption—33mW at ±5V**
- **SE5008 military qualifications pending**

APPLICATIONS

- **8-bit, 1μs A-to-D converters**
- **Servo-motor and pen drivers**
- **Waveform generators**
- **Audio encoders and attenuators**
- **Analog meter drivers**
- **Programmable power supplies**
- **CRT display drivers**
- **High speed modems**
- **Other applications where low cost, high speed and complete input/output versatility are required**

ORDERING INFORMATION

RELATIVE ACCURACY	0 to 70°C	-55 to 125°C
0.39% FS	NE5007N NE5007F	-
0.19% FS	NE5008N NE5008F	SE5008F

DEFINITION OF TERMS

Accuracy—The maximum deviation of the Dac output relative to an ideal straight line drawn from zero to full scale; 1 LSB for any bit combination

Differential linearity—The incremental error from an ideal 1 LSB analog output change when the digital input is changed 1 LSB; guaranteed monotonicity requires the differential linearity error be less than 1 LSB and with a tempco of essentially zero

Full scale tempco—The change in Dac full scale current with change in temperature expressed in ppm/°C

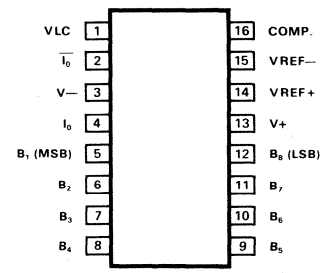
Monotonicity—For a 1 LSB increase of input code, the output either increases or remains the same

Output voltage compliance—The range of allowable voltage levels the output pins can assume without a major effect on circuit performance

Power supply sensitivity—The change in Dac output current with changes in power supply voltage

PIN CONFIGURATION

F,N PACKAGE*



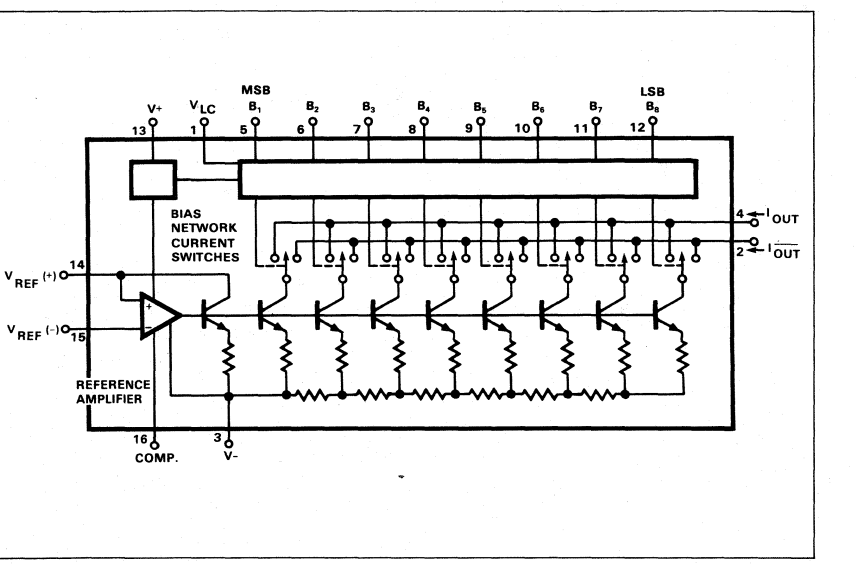
*N = Plastic DIP
F = Cerdip

CROSS REFERENCE

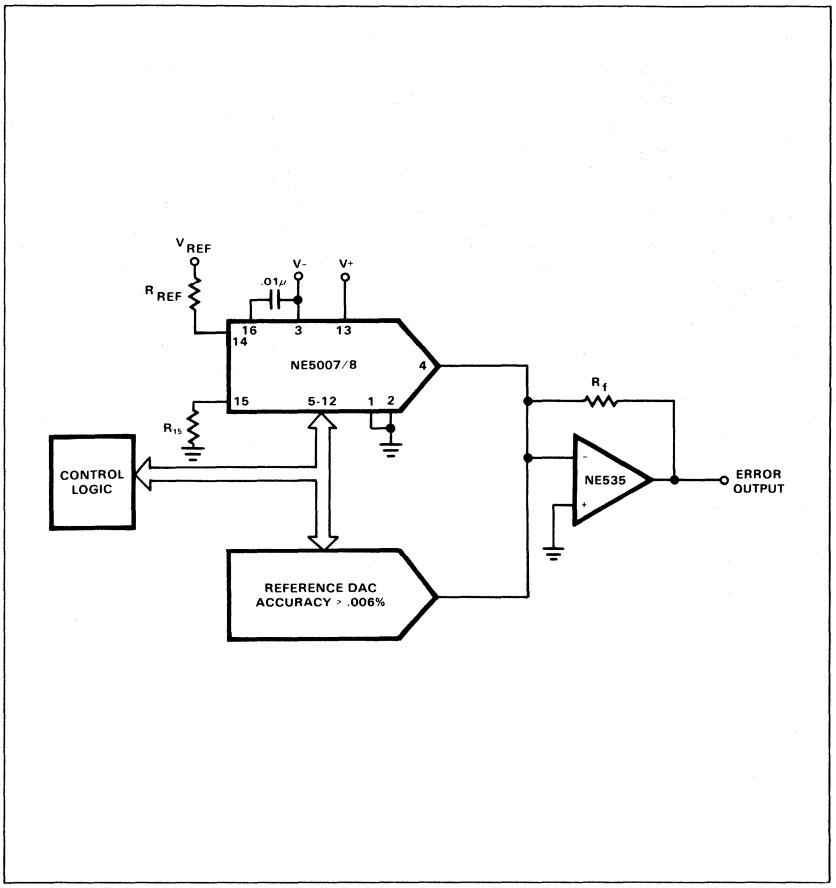
The 5007/5008 series are pin and functionally compatible with the DAC-08 series of devices.

PMI	SIGNETICS
DAC-08A	SE5009
DAC-08	SE5008
DAC-08H	NE5009
DAC-08E	NE5008
DAC-08C	NE5007

BLOCK DIAGRAM



TEST CIRCUIT



ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise noted

PARAMETER		RATING	UNIT
T_A	Operating temperature range		°C
	SE5008	-55 to +125	
	NE5007/8	0 to +70	
t_{stg}	Storage temperature	-65 to +150	°C
P_D	Power dissipation	500	mW
	Lead soldering temperature (60sec)	300	°C
	V+ to V- supply	36	V
	Logic inputs	V- to V- plus 36V	
V_{LC}	Logic threshold control	V- to V+	
	Analog current outputs	See output current or output voltage performance curve	
V_{14}, V_{15}	Reference inputs	V- to V+	
V_{14} to V_{15}	Reference input differential voltage	±18	V
I_{14}	Reference input current	5.0	mA

AC ELECTRICAL CHARACTERISTICS V_S = ±15V, I_{REF} = 2.0mA, Output characteristics refer to both IOUT and $\overline{IOUT}$ unless otherwise noted. NE5008: T_A = 0°C to 70°C. SE5008: T_A = -55°C to 125°C.

PARAMETER		TEST CONDITIONS	NE5007			NE5008			SE5008			UNIT
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	8	8	8	Bits
	Relative accuracy	Over temperature range			±0.39			±0.19			±0.19	%FS
t_s	Settling time	To ±½ LSB, all bits switched on or off, T_A=25°C		85	135		85	135		85	135	ns
t_{PLH} t_{PHL}	Propagation delay Low-to-high High-to-low	T_A=25°C, each bit. All bits switched		35	60		35	60		35	60	ns
TCI_{FS}	Full scale tempco			±10			±10			±10		ppm/°C
V_{OC}	Output voltage compliance	Full scale current change <½ LSB	-10		+18	-10		+18	-10		+18	V
I_{FS4}	Full scale current	V_{REF}=10.000V, R_{14}, R_{15}=5.000kΩ, T_A=25°C	1.94	1.99	2.04	1.94	1.99	2.04	1.94	1.99	2.04	mA
I_{FSS}	Full scale symmetry	I_{FS4}-I_{FS2}		±2.0	±16		±1.0	±8.0		±1.0	±8.0	μA
I_{ZS}	Zero scale current			0.2	4.0		0.2	2.0		0.2	2.0	μA
I_{FSR}	Output current	V-=-5.0V V-=-7.0V to -18V	0 0	2.0 2.0	2.1 4.2	0 0	2.0 2.0	2.1 4.2	0 0	2.0 2.0	2.1 4.2	mA
V_{IL} V_{IH}	Logic input levels Low High	V_{LC}=0V	 2.0		0.8	 2.0		0.8	 2.0		0.8	V
I_{IL} I_{IH}	Logic input current Low High	V_{LC}=0V V_{IN}=-10V to +0.8V V_{IN}=2.0V to 18V		-2.0 0.002	-10 10		-2.0 0.002	-10 10		-2.0 0.002	-10 10	μA
V_{IS}	Logic input swing	V-=-15V	-10		+18	-10		+18	-10		+18	V
V_{THR}	Logic threshold range	V_S=±15V	-10		+13.5	-10		+13.5	-10		+13.5	V
I_{15}	Reference bias current			-1.0	-3.0		-1.0	-3.0		-1.0	-3.0	μA
dI/dt	Reference input slew rate	Figures 1, 3	4.0	8.0		4.0	8.0		4.0	8.0		mA/μs
$PSSI_{FS+}$ $PSSI_{FS-}$	Power supply sensitivity Positive Negative	I_{REF}=1mA V+=4.5 to 5.5V, V-=-15V; V+=13.5 to 16.5V, V-=-15V V-=-4.5 to -5.5V, V+=+15V; V-=-13.5 to -16.5, V+=+15V		0.0003 0.002	0.01 0.01		0.0003 0.002	0.01 0.01		0.0003 0.002	0.01 0.01	%FS/%VS
I+ I-	Power supply current Positive Negative	V_S=±5V, IREF=1.0mA		2.3 -4.3	3.8 -5.8		2.3 -4.3	3.8 -5.8		2.3 -4.3	3.8 -5.8	mA
I+ I-	Positive Negative	V_S=+5V, -15V, I_{REF}=2.0mA		2.4 -6.4	3.8 -7.8		2.4 -6.4	3.8 -7.8		2.4 -6.4	3.8 -7.8	
I+ I-	Positive Negative	V_S=±15V, I_{REF}=2.0mA		2.5 -6.5	3.8 -7.8		2.5 -6.5	3.8 -7.8		2.5 -6.5	3.8 -7.8	
P_D	Power dissipation	±5V, I_{REF}=1.0mA +5V, -15V, I_{REF}=2.0mA ±15V, I_{REF}=2.0mA		33 108 135	48 136 174		33 108 135	48 136 174		33 108 135	48 136 174	mW

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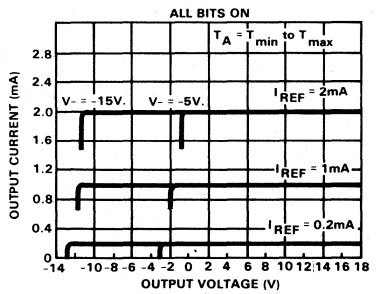
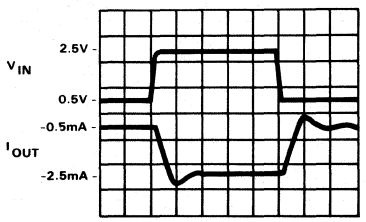
TYPICAL PERFORMANCE CHARACTERISTICS

OUTPUT CURRENT vs OUTPUT VOLTAGE (OUTPUT VOLTAGE COMPLIANCE)

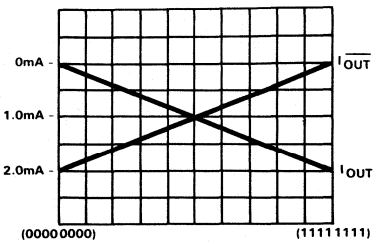


FAST PULSED REFERENCE OPERATION

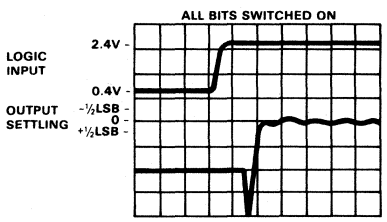


200ns/division
See Figure 1
R_{EQ} = 200Ω, R_L = 100Ω, CC = O

TRUE AND COMPLEMENTARY OUTPUT OPERATION



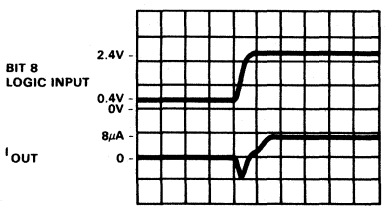
FULL SCALE SETTLING TIME



50ns/division

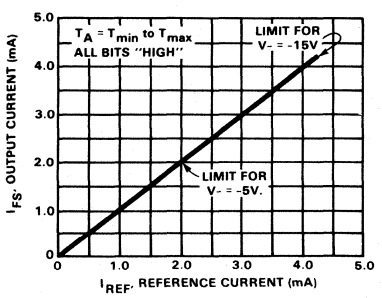
IFS = 2mA, R_L = 1kΩ ½ LSB = 4μA

LSB SWITCHING

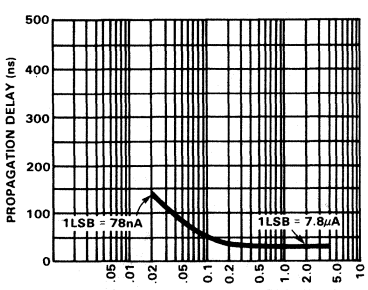


50ns/division

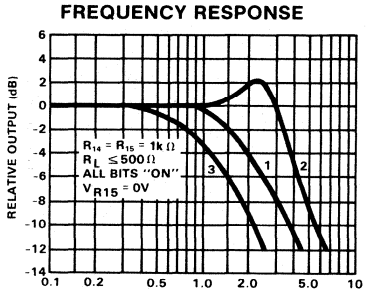
FULL SCALE CURRENT vs REFERENCE CURRENT



LSB PROPAGATION DELAY vs IFS



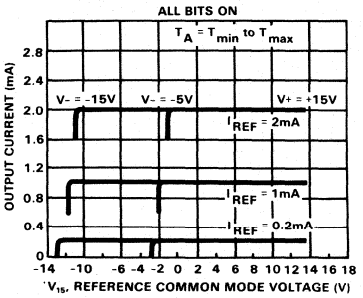
REFERENCE INPUT FREQUENCY RESPONSE



Curve 1: CC = 15pF, V_{IN} = 2.0V p-p centered at +1.0V.
Curve 2: CC = 15pF, V_{IN} = 50mV p-p centered at +200mV.
Curve 3: CC = 0pF, V_{IN} = 100mV p-p centered at 0V and applied thru 50Ω connected to pin 14. +2.0V applied to R_{14}.

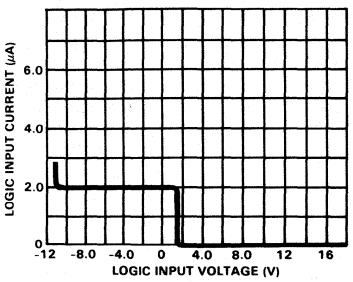
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

REFERENCE AMP COMMON MODE RANGE

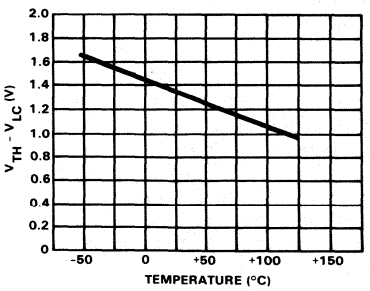


Positive common mode range is always (V+) - 1.5V

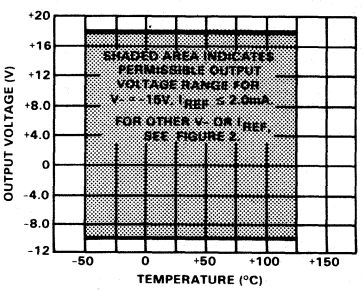
LOGIC INPUT CURRENT vs INPUT VOLTAGE



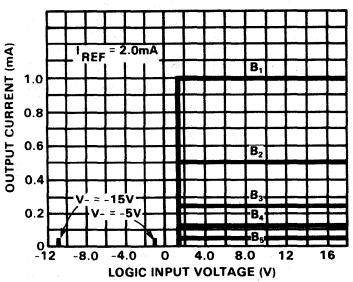
$V_{TH} - V_{LC}$ vs TEMPERATURE



OUTPUT VOLTAGE COMPLIANCE vs TEMPERATURE



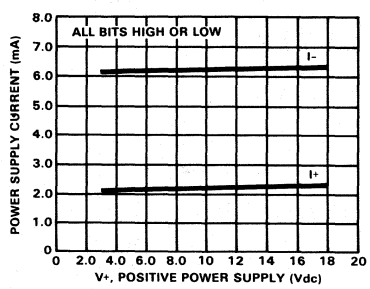
BIT TRANSFER CHARACTERISTICS



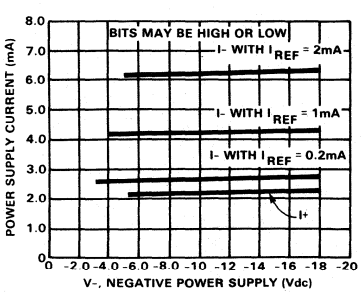
NOTE

B_1 through B_8 have identical transfer characteristics. Bits are fully switched, with less than ½ LSB error, at less than ±100mV from actual threshold. These switching points are guaranteed to lie between 0.8 and 2.0 volts over the operating temperature range (VLC = 0.0V).

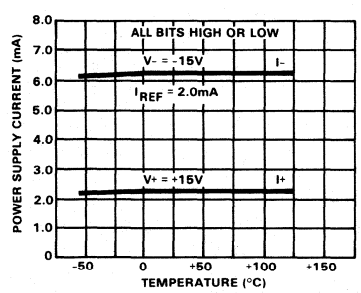
POWER SUPPLY CURRENT vs V+



POWER SUPPLY CURRENT vs V-

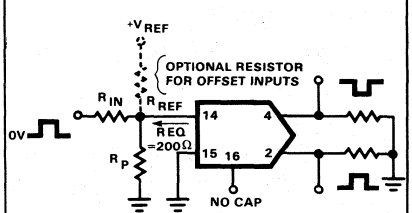


POWER SUPPLY CURRENT vs TEMPERATURE



TYPICAL APPLICATION

PULSED REFERENCE OPERATION



TYPICAL VALUES

R_{IN} = 5K

$+V_{IN}$ = 10V

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NE5009-F,N • SE5009-F

DESCRIPTION

The 5009 monolithic 8-bit digital-to-analog converter is an electrical selection of the 5007/8 series of 8-bit D/A converters. Relative accuracy is specified to ±1/4 LSB maximum over the operating temperature range. Differential nonlinearity and settling times are also specified to maximum limits.

The device is specifically designed for precision applications in process control and military systems. The SE5009 is specified as equal or superior to the PMI DAC-08A in all respects. Additional relevant testing and application material is shown in the data sheet and application notes for the NE5007/8.

FEATURES

- **Fast settling output current—60ns typical, 135ns maximum**
- **Relative accuracy— ±0.1% maximum**
- **Differential nonlinearity—±0.19% maximum**
- **Low full-scale current drift, ±10 ppm/°C typical**
- **SE5009 military qualifications pending**

APPLICATIONS

- **Fast 8-bit A/D converter**
- **Variable gain amplifiers**
- **Waveform generators**
- **3 digit BCD D/A converter (0.1%)**
- **Programmable power supplies**

DEFINITION OF TERMS

Relative Accuracy—The maximum deviation of the DAC output relative to an ideal straight line drawn from zero to full scale; 1 LSB for any bit combination.

Differential Nonlinearity—The incremental error from an ideal 1 LSB analog output change when the digital input is changed 1 LSB; guaranteed monotonicity requires the differential linearity error be less than 1 LSB and with a tempco of essentially zero.

Full Scale Tempco—The change in DAC full scale current with change in temperature expressed in ppm/°C.

Monotonicity—For a 1 LSB increase of input code, the output either increases or remains the same.

Output Voltage Compliance—The range of allowable voltage levels the output pins can assume without a major effect on circuit performance.

Power Supply Sensitivity—The change in DAC output current with changes in power supply voltage.

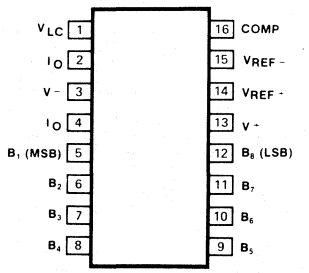
CROSS REFERENCE

The 5009 series are pin and functionally compatible with the DAC-08 series of devices.

PMI	SIGNETICS
DAC-08A	SE-5009
DAC-08	SE-5008
DAC-08H	NE-5009
DAC-08E	NE-5008
DAC-08C	NE-5007

PIN CONFIGURATION

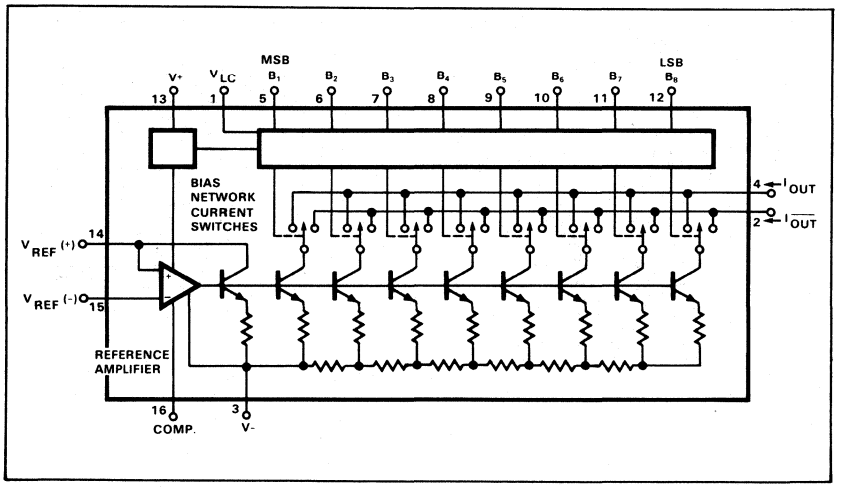
F,N PACKAGE*



NOTE

*SE5009 is in F package only.

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

PARAMETER	RATING	UNIT
Total supply voltage (V+ - V-)	36	V
Logic input voltage	V- + 36	V
V_{LC} Voltage at pin 1	V- to V+	V
Reference input voltage	V- to V+	V
Reference input differential voltage	±18	V
Reference input current	5.0	mA
Operating temperature range		
SE5009	-55 to +125	°C
NE5009	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead soldering temperature (10sec)	300	°C
Power dissipation*	500	mW

NOTE

*Derate F package at 10mW/°C above 100°C.

DC ELECTRICAL CHARACTERISTICS

These specs apply for $V_S = \pm 15V$, $I_{REF} = 2mA$, T_A for NE5009 0° to 70°C, T_A for SE5009 -55° to +125°C. Output characteristic for both I_{OUT} and $\overline{I_{OUT}}$.

PARAMETER		TEST CONDITIONS	NE5009			SE5009			UNIT
			Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	bits
	Monotonicity		8	8	8	8	8	8	bits
	Relative accuracy	Over temperature range			±0.1			±0.1	% FS
	Differential nonlinearity			±0.1	±0.19		±0.1	±0.19	% FS
TCI_{FS}	Full scale tempco			±10	±50		±10	±50	ppm/°C
V_{OC}	Output voltage compliance	Full scale current change < 1/2 LSB	-10		+18	-10		+18	V
I_{FS4}	Full scale current	$V_{REF} = 10.000V$, $R_{14} \cdot R_{15} = 5.00CK$ $T_A = 25°C$	1.984	1.992	2.000	1.984	1.992	2.000	mA
I_{FSS}	Full scale symmetry	$I_{FS4} - I_{FS2}$		±0.5	±4.0		±0.5	±4.0	μA
I_{ZS}	Zero scale current			0.1	1.0		0.1	1.0	μA
I_{FSR}	Output current range	V- = -5.0V	0	2.0	2.1	0	2.0	2.1	mA
		V- = -7.0V to -18V	0	2.0	4.2	0	2.0	4.2	mA
	Logic input levels								
V_{IL}	Logic "0"	$V_{LC} = 0V$			0.8			0.8	V
V_{IH}	Logic "1"	$V_{LC} = 0V$	2.0			2.0			V
	Logic input current	$V_{LC} = 0V$							
I_{IL}	Logic "0"	$V_{IN} = -10V$ to +0.8V		-2.0	-10		-2.0	-10	μA
I_{IH}	Logic "1"	$V_{IN} = 2.0V$ to 18V		0.002	10		0.002	10	μA
V_{IS}	Logic input swing	V- = -15V	-10		+18	-10		+18	V
V_{THR}	Logic threshold range	$V_S = \pm 15V$	-10		+13.5	-10		+13.5	V
I_{15}	Reference bias current			-1.0	-3.0		-1.0	-3.0	μA
di/dt	Reference input slew rate		4.0	8.0		4.0	8.0		mA/μs
	Power supply sensitivity								
PSSIFS+		$I_{REF} = 1mA$, V- = -15V:							
		V+ = 4.5 to 5.5V		0.0003	0.01		0.0003	0.01	%FS/%VS
		V+ = 13.5 to 16.5V		0.0003	0.01		0.0003	0.01	%FS/%VS
PSSIFS-		$I_{REF} = 1mA$, V+ = +15V:							
		V- = -4.5 to -5.5V		0.0003	0.01		0.0003	0.01	%FS/%VS
		V- = -13.5 to -16.5V		0.0003	0.01		0.0003	0.01	%FS/%VS
	Power supply current	$V_S = \pm 15V$, $I_{REF} = 1.0mA$							
I+				2.3	3.8		2.3	3.8	mA
I-				-4.3	-5.8		-4.3	-5.8	mA
	Power supply current	$V_S = +5V, -15V$; $I_{REF} = 2.0mA$							
I+				2.4	3.8		2.4	3.8	mA
I-				-6.4	-7.8		-6.4	-7.8	mA
	Power supply current	$V_S = \pm 15V$, $I_{REF} = 2.0mA$							
I+				2.5	3.8		2.5	3.8	mA
I-				-6.5	-7.8		-6.5	-7.8	mA
P_D	Power dissipation	±5V, $I_{REF} = 1.0mA$		33	48		33	48	mW
		+5V, -15V, $I_{REF} = 2.0mA$		108	136		108	136	mW
		±15V, $I_{REF} = 2.0mA$		135	174		135	174	mW

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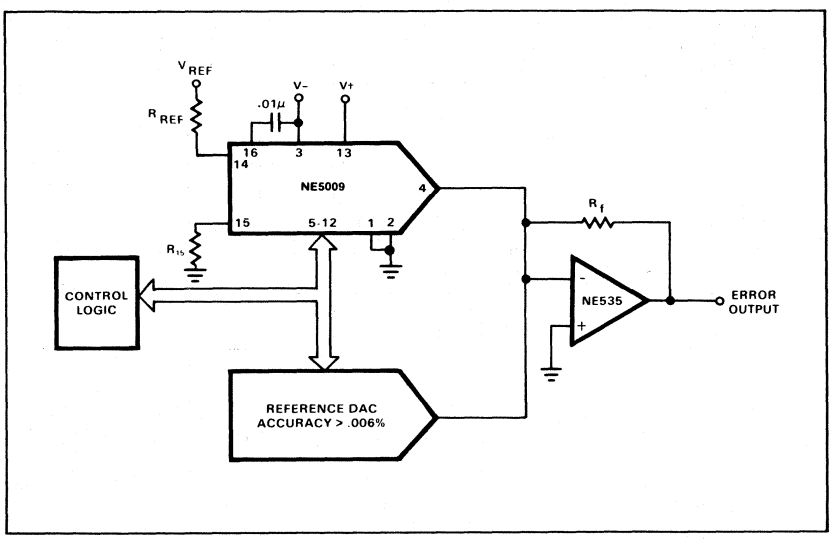
AC ELECTRICAL CHARACTERISTICS

These specs apply for $V_S = \pm 15V$, $I_{REF} = 2mA$, Output characteristic for both I_{OUT} and $\overline{I_{OUT}}$.

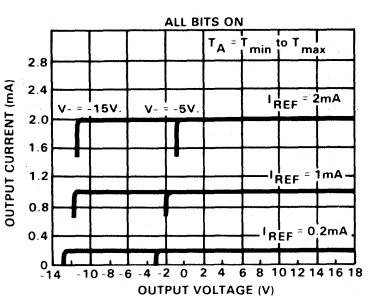
PARAMETER		TEST CONDITIONS	SE/NE5009			UNIT
			Min	Typ	Max	
t_s	Settling time	To $\pm 1/2$ LSB all bits switched ON or OFF, $T_A = 25°C$		60	135	ns
	Major carry transition	To 90% complete, $T_A = 25°C$		20		ns
t_{PLH}, t_{PHL}	Propagation delay	$T_A = 25°C$				
	Each bit			35	60	ns
	All bits switched			35	60	ns

TEST CIRCUIT

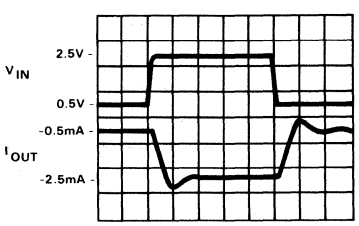


TYPICAL PERFORMANCE CHARACTERISTICS

OUTPUT CURRENT vs OUTPUT VOLTAGE (OUTPUT VOLTAGE COMPLIANCE)

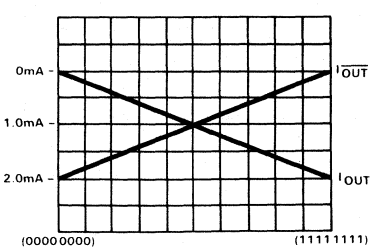


FAST PULSED REFERENCE OPERATION



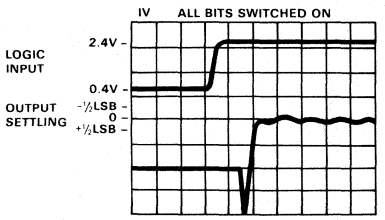
200ns/division
See Figure 1
$R_{EQ} = 200\Omega$, $R_L = 100\Omega$, CC = O

TRUE AND COMPLEMENTARY OUTPUT OPERATION



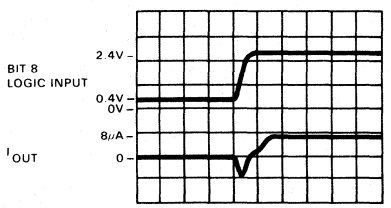
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

FULL SCALE SETTLING TIME

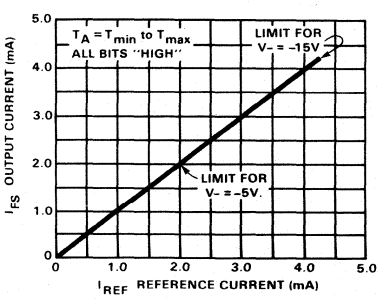


See Figure 13 for settling time fixture

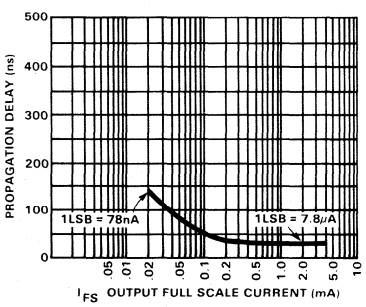
LSB SWITCHING



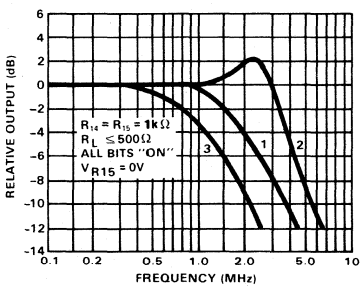
FULL SCALE CURRENT vs REFERENCE CURRENT



LSB PROPAGATION DELAY vs IFS

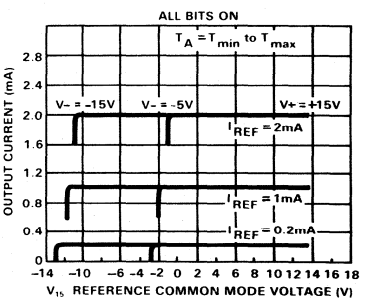


REFERENCE INPUT FREQUENCY RESPONSE



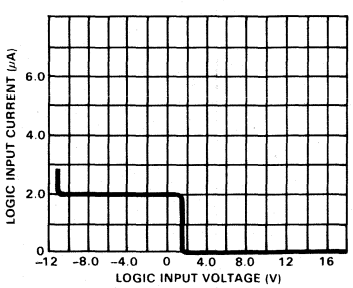
Curve 1:CC = 15pF, V_{IN} = 2.0V p-p centered at +1.0V.
Curve 2:CC = 15pF, V_{IN} = 50mV p-p centered at +200mV.
Curve 3:CC = 0pF, V_{IN} = 100mV p-p centered at 0V and applied thru 50Ω connected to pin 14. +2.0V applied to R_{14}.

REFERENCE AMP COMMON MODE RANGE

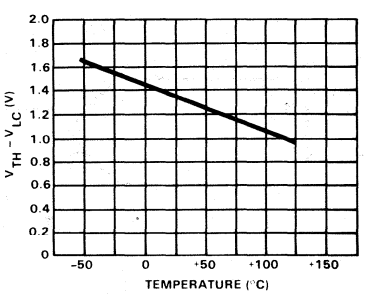


Positive common mode range is always (V+) - 1.5V

LOGIC INPUT CURRENT vs INPUT VOLTAGE

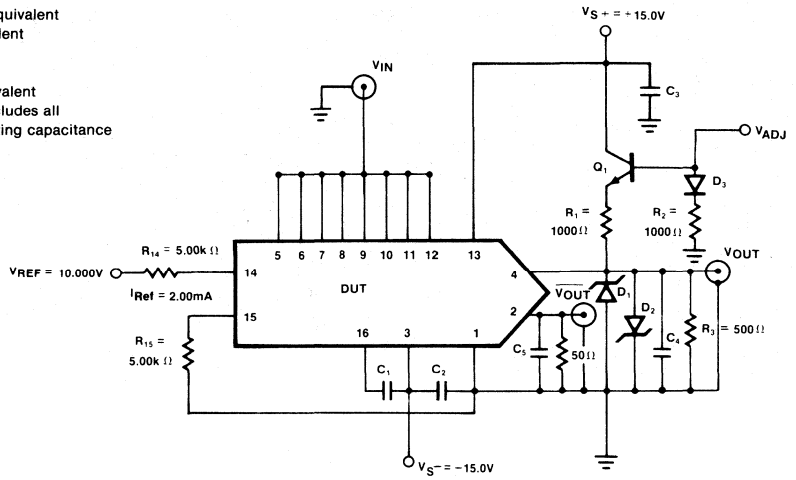


V_{TH}-V_{LC} vs TEMPERATURE

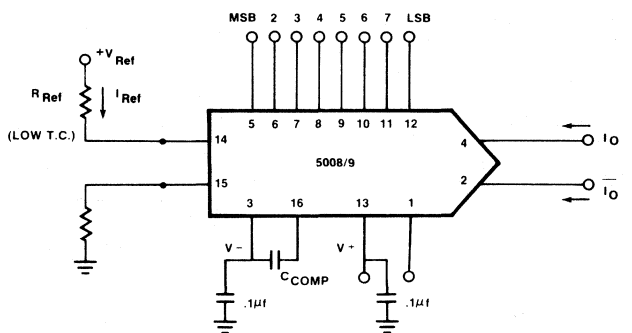


SETTLING TIME AND PROPAGATION DELAY

D_1, D_2 = IN6263 or equivalent
D_3 = IN914 or equivalent
C_1 = 0.01μf
C_2, C_3 = 0.1μf
Q_1 = 2N3904 or equivalent
C_4, C_5 = 15pf and includes all probe and fixturing capacitance

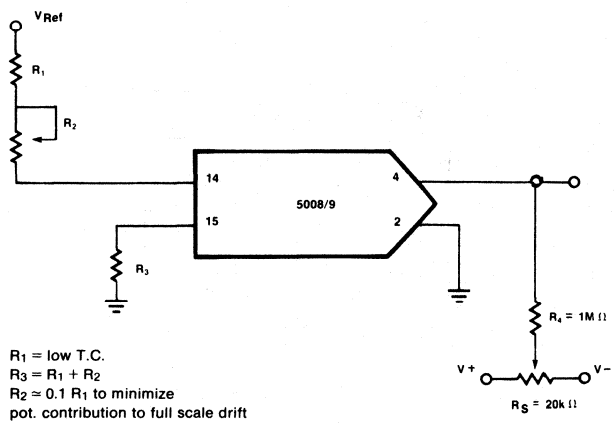


BASIC 5008/5009 CONFIGURATION



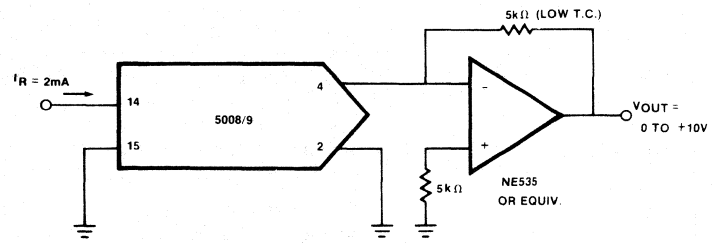
$$I_{FS} \approx \frac{+V_{Ref}}{R_{Ref}} \times \frac{255}{256}\ ;\ I_O + \overline{I_O} = I_{FS} \text{ for all logic states}$$

RECOMMENDED FULL SCALE AND ZERO SCALE ADJ.



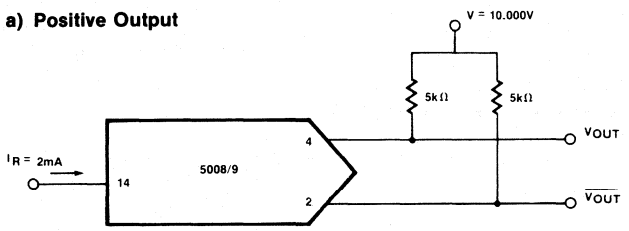
R_1 = low T.C.
$R_3 = R_1 + R_2$
$R_2 \approx 0.1\ R_1$ to minimize pot. contribution to full scale drift

UNIPOLAR VOLTAGE OUTPUT FOR LOW IMPEDANCE OUTPUT

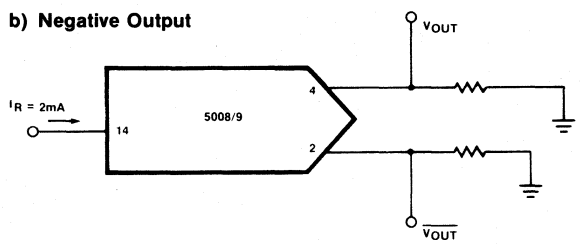


UNIPOLAR VOLT OUTPUT FOR HIGH IMPEDANCE OUTPUT

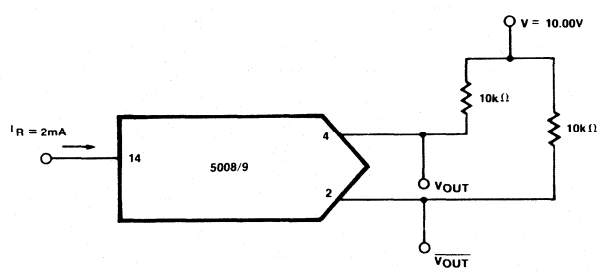
a) Positive Output



b) Negative Output



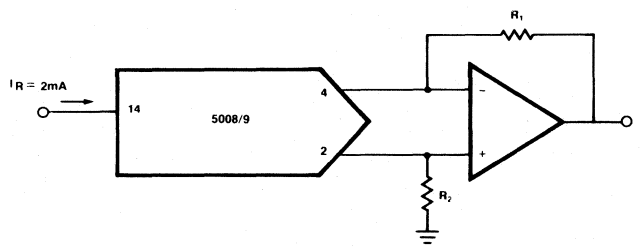
BASIC BIPOLAR OUTPUT OPERATION (OFFSET BINARY)



CODE CHART

	B_1	B_2	B_3	B_4	B_5	B_6	B_7	B_8	V_{OUT}	$\overline{V_{OUT}}$
POS full scale	1	1	1	1	1	1	1	1	-9.920V	+10.000
POS f.s. - 1LSB	1	1	1	1	1	1	1	0	-9.840V	+9.920
+ Zero scale + 1LSB	1	0	0	0	0	0	0	1	-0.080V	+0.160
Zero scale	1	0	0	0	0	0	0	0	0.000	+0.080
Zero scale - 1LSB	0	1	1	1	1	1	1	1	0.080	0.000
Neg full scale - 1LSB	0	0	0	0	0	0	0	1	+9.920	-9.840
Neg full scale	0	0	0	0	0	0	0	0	+10.000	-9.920

SYMMETRICAL OFFSET BINARY (BIPOLAR)



V_{OUT} = 0 to ±V*

±V *Range:
±5V for $R_1 = R_2 = 2.5K$
±10V for $R_1 = R_2 = 5.0K$

3 DIGIT BCD CONVERTER

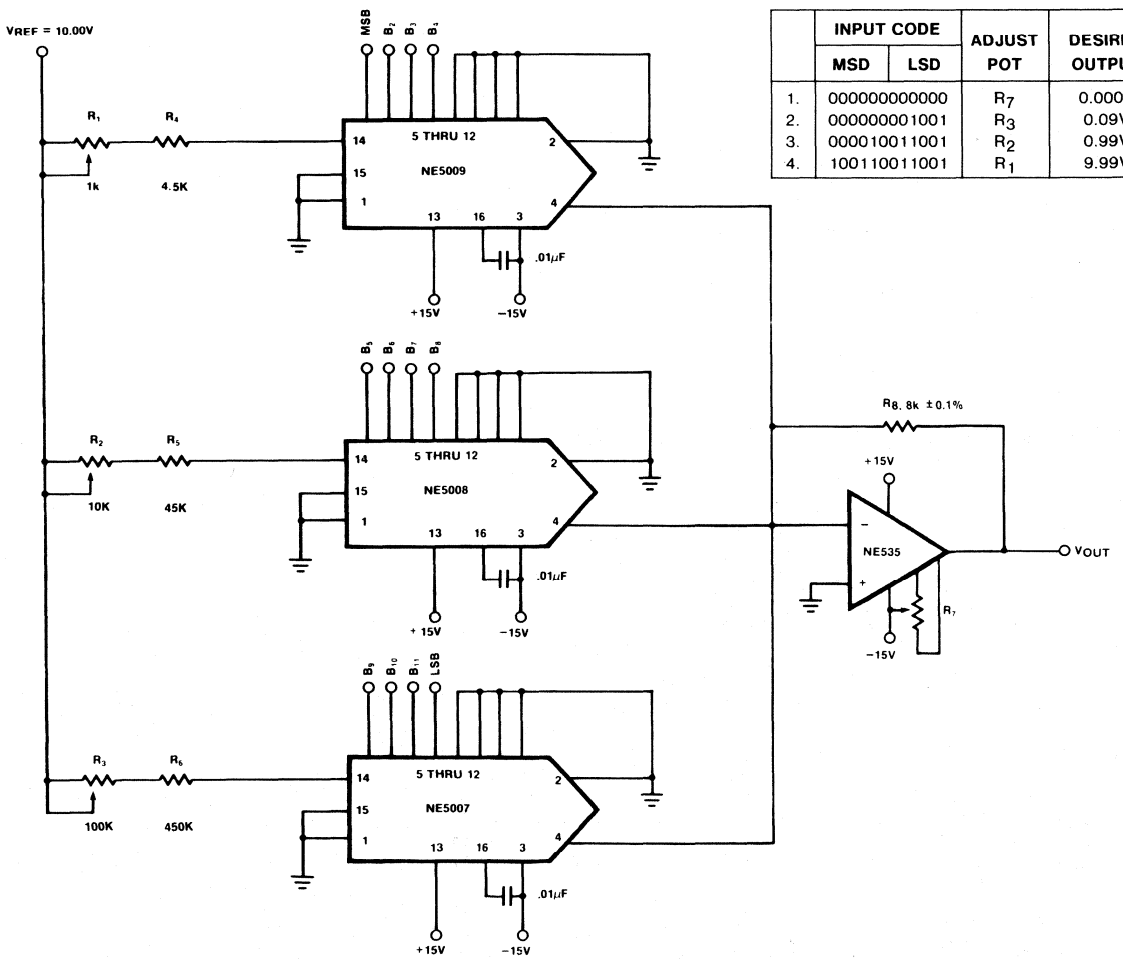
A 3 digit BCD converter, using inexpensive 8-bit binary DACs, can achieve ±0.1% accuracy. The circuit shown in Figure 20 utilizes three DACs, one for each decade, to provide 0 to 999 output steps. DAC 1 contains the first four significant digits controlling the hundreds digit; DAC 2 controls the tens digit and DAC 3 steps 0 to 9. The feedback resistor (R_7) sets the full scale at 9.99V.

The input coding is the popular 8-4-2-1 coding; i.e. the weighting ratios are 8, 4, 2 and 1. The full scale (999) BCD code is input code 100110011001.

Full scale adjustment procedure.

In the sequence below, switch on the following code combinations and adjust the indicated potentiometer for the proper output.

3 DIGIT BCD CONVERTER WITH ±0.1% ACCURACY



	INPUT CODE		ADJUST POT	DESIRED OUTPUT
	MSD	LSD		
1.	000000000000		R_7	0.000V
2.	000000001001		R_3	0.09V
3.	000010011001		R_2	0.99V
4.	100110011001		R_1	9.99V

DESCRIPTION

The NE5018 is a complete 8-bit digital to analog converter subsystem on one monolithic chip. The data inputs have input latches, controlled by a latch enable pin. The data and latch enable inputs are ultra-low loading for easy interfacing with all logic systems. The latches appear transparent when the $\overline{LE}$ input is in the low state. When $\overline{LE}$ goes high, the input data present at the moment of transition is latched and retained until $\overline{LE}$ again goes low. This feature allows easy compatibility with most micro-processors.

The chip also comprises a stable voltage reference (5V nominal) and a high slew rate buffer amplifier. The voltage reference may be externally trimmed with a potentiometer for easy adjustment of full scale, while maintaining a low temperature co-efficient.

The output of the buffer amplifier may be offset so as to provide bipolar as well as unipolar operation.

FEATURES

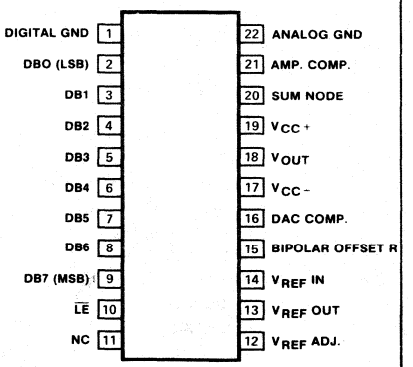
- **8-bit resolution**
- **Input latches**
- **Low-loading data inputs**
- **On-chip voltage reference**
- **Output buffer amplifier**
- **Accurate to ± 1/4 LSB (.1%)**
- **Monotonic to 8 bits**
- **Amplifier and reference both short-circuit protected**
- **Compatible with 2650,8080 and many other μP's**

APPLICATIONS

- **Precision 8-bit D/A converters**
- **A/D converters**
- **Programmable power supplies**
- **Test equipment**
- **Measuring instruments**
- **Analog-digital multiplication**

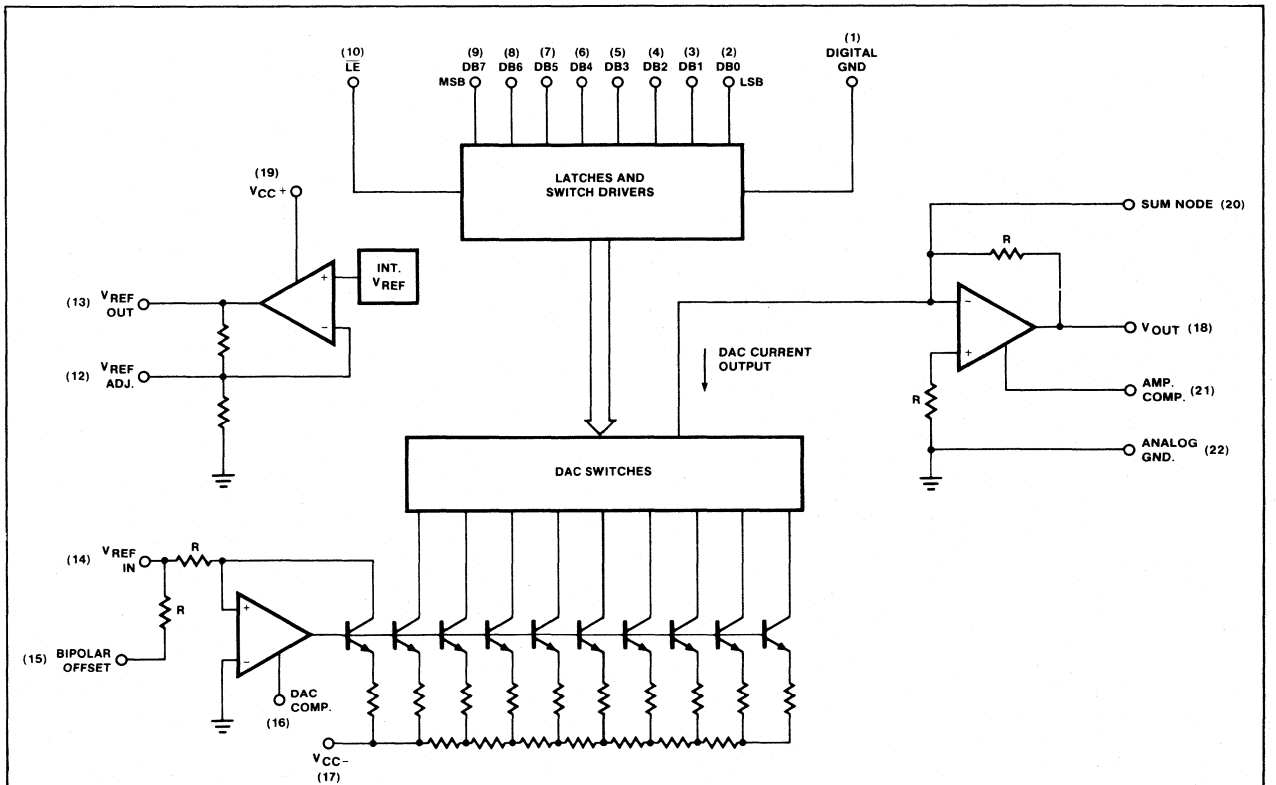
PIN CONFIGURATION

F,N PACKAGE



SE/NE5018 available in F package only.

BLOCK DIAGRAM



All R values equal 5KΩ and are thermally matched.

Figure 1

ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
$V_{CC}+$	Positive supply voltage	18	V
$V_{CC}-$	Negative supply voltage	−18	V
V_{IN}	Logic input voltage	0 to 18	V
$V_{REF}IN$	Voltage at V_{REF} input	12	V
$V_{REF}ADJ$	Voltage at V_{REF} adjust	0 to V_{REF}	V
V_{SUM}	Voltage at sum node	12	V
I_{REFSC}	Short-circuit current to ground at V_{REF} OUT	Continuous	
I_{OUTSC}	Short-circuit current to ground or either supply at V_{OUT}	Continuous	
I_{REF}	Reference input current	5	mA
P_D	Power dissipation*		
	-N package	800	mW
	-F package	1000	mW
T_A	Operating temperature range		
	SE5018	−55 to +125	°C
	NE5018	0 to +70	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_{SOLD}	Lead soldering temperature (10 seconds)	300	°C

*NOTES
For N package, derate at 120°C/W above 35°C
For F package, derate at 75°C/W above 75°C

DC ELECTRICAL CHARACTERISTICS

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5018. $-55°C \leq T_A \leq 125°C$, NE5018. $0°C \leq T_A \leq 70°C$ unless otherwise specified[1]
Typical values are specified at 25°C

	PARAMETER	TEST CONDITIONS	SE5018			NE5018			UNIT
			Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	Bits
	Relative accuracy				±0.1			±0.1	%FS
$V_{CC}+$	Positive supply voltage		11.4	15		11.4	15		V
$V_{CC}-$	Negative supply voltage		−11.4	−15		−11.4	−15		V
$V_{IN(1)}$	Logic "1" input voltage	Pin 1 = 0V	2.0			2.0			V
$V_{IN(0)}$	Logic "0" input voltage	Pin 1 = 0V			0.8			0.8	V
$I_{IN(1)}$	Logic "1" input current	Pin 1 = 0V, $2V < V_{IN} < 18V$		0.1	10		0.1	10	μA
$I_{IN(0)}$	Logic "0" input current	Pin 1 = 0V, $-5V < V_{IN} < 0.8V$		−2.0	−10		−2.0	−10	μA
V_{FS}	Full scale output voltage	Unipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C	9.50	9.961	10.50	9.50	9.961	10.50	V
V_{FS}	Full scale output voltage	Bipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C		+4.961			+4.961		V
				−5.000			−5.000		
V_{ZS}	Zero scale voltage			5			5		mV
I_{OS}	Output short circuit current	T_A = 25°C, V_{OUT} = 0V		15	40		15	40	mA
$PSR+_{(out)}$	Output power supply rejection (+)	V− = −15V, 13.5V≤V+≤16.5V, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
$PSR-_{(out)}$	Output power supply rejection (−)	V+ = 15V, −13.5V≤V−≤−16.5V, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
TC_{FS}	Full scale temperature coefficient	$V_{REF\ IN}$ = 5.000V		20			20		ppm/°C
TC_{ZS}	Zero scale temperature coefficient			5			5		ppm/°C

DC ELECTRICAL CHARACTERISTICS (Cont'd)

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5018. $-55°C \leq T_A \leq 125°C$, NE5018. $0°C \leq T_A \leq 70°C$ unless otherwise specified.[1]
Typical values are specified at 25°C

PARAMETER		TEST CONDITIONS	SE/5018			NE5018			UNIT
			Min	Typ	Max	Min	Typ	Max	
I_{REF}	Reference output current	$\Delta V_{REF} \leq 0.1\%$		5			5		mA
I_{REFSC}	Reference short circuit current	$T_A = 25°C$, $V_{REF\ OUT} = 0V$		15			15		mA
$PSR+_{(REF)}$	Reference power supply rejection (+)	$V- = -15V$, $13.5V \leq V+ \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/%VS
$PSR-_{(REF)}$	Reference power supply rejection (−)	$V+ = 15V$, $-13.5V \leq V- \leq 16.5V$,		.003	.01		.003	.01	%VR/%VS
V_{REF}	Reference voltage	$I_{REF} = 1.0mA$	4.5	5.0	5.5	4.5	5.0	5.5	V
TC_{REF}	Reference voltage temperature coefficient	$I_{REF} = 1.0mA$		60			60		ppm/°C
Z_{IN}	DAC V_{REF} IN input impedance	$I_{REF} = 1.0mA$	4.0	5.0	6.0	4.0	5.0	6.0	KΩ
$I_{CC}+$	Positive supply current	$V_{CC}+ = 15V$		7	14		7	14	mA
$I_{CC}-$	Negative supply current	$V_{CC}- = -15V$		−10	−15		−10	−15	mA
P_D	Power dissipation	$I_{REF} = 1.0mA$, $V_{CC} = \pm 15V$		255	435		255	435	mW

NOTE

1. Refer to Figure 2.

AC ELECTRICAL CHARACTERISTICS[2]

$V_{CC} = \pm 15V$, $T_A = 25°C$

PARAMETER		TO	FROM	TEST CONDITIONS	SE/NE5018			UNIT
					Min	Typ	Max	
T_{SLH}	Settling time	± ½ LSB	Input	All bits low to high[3]		1.8		μs
T_{SHL}	Settling time	± ½ LSB	Input	All bits high to low[4]		2.3		μs
t_{plh}	Propagation delay	Output	Input	All bits switched low to high[3]		300		ns
t_{phl}	Propagation delay	Output	Input	All bits switched high to low[4]		150		ns
t_{plsb}	Propagation delay	Output	Input	1 LSB change[3,4]		150		ns
t_{plh}	Propagation delay	Output	$\overline{LE}$	low to high transition[5]		300		ns
t_{phl}	Propagation delay	Output	$\overline{LE}$	high to low transition[6]		150		ns
t_s	Set-up time	$\overline{LE}$	Input	2, 7	100			ns
t_h	Hold time	Input	$\overline{LE}$	2, 7	50			ns
t_{pw}	Latch enable pulse width			2, 7	150			ns
	Reference input Slew rate			2		25		v/μs

NOTES

2. Refer to Figure 3.
3. See Figure 6.
4. See Figure 7.
5. See Figure 8.
6. See Figure 9.
7. See Figure 10.

DC PARAMETRIC TEST CONFIGURATION

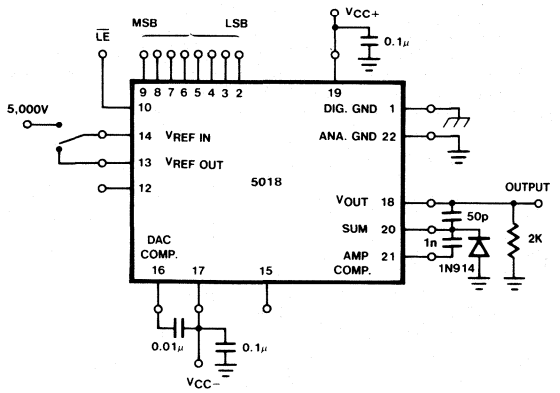


Figure 2

AC PARAMETRIC TEST CONFIGUTATION

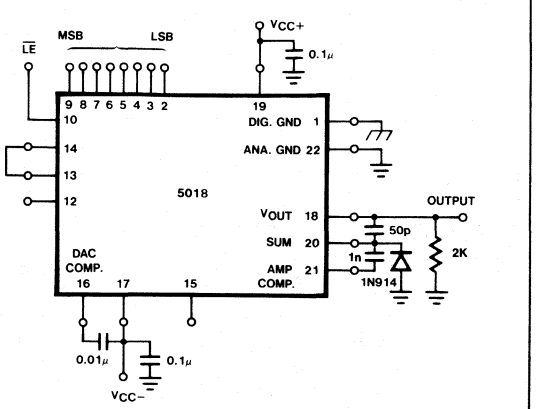


Figure 3

FULL/ZERO SCALE ADJUST—UNIPOLAR OUTPUT (0-10V)

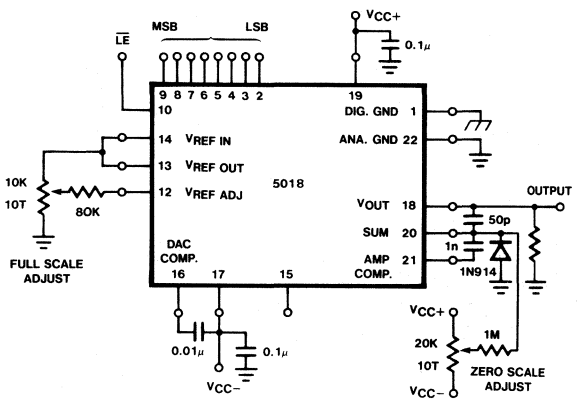


Figure 4

BIPOLAR OUTPUT OPERATION (−5 to +5V)

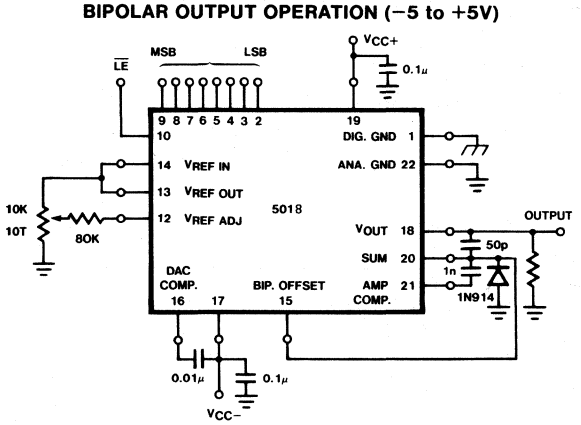


Figure 5

SETTLING TIME AND PROPAGATION DELAY, LOW TO HIGH DATA

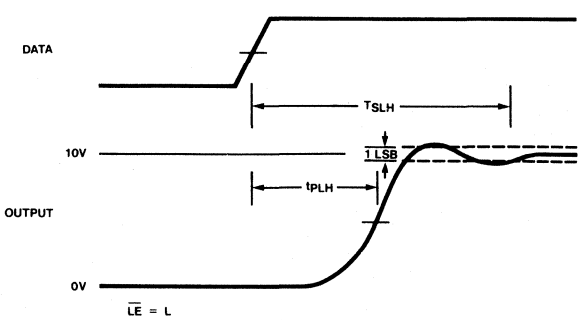


Figure 6

SETTLING TIME AND PROPAGATION DELAY, HIGH TO LOW DATA

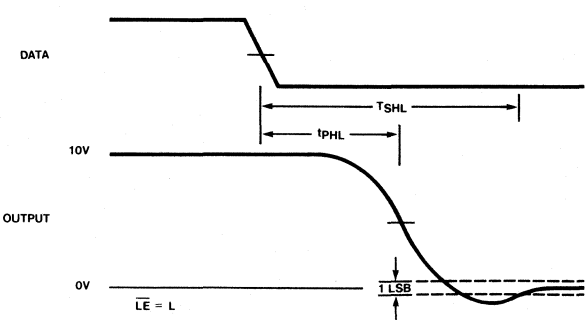


Figure 7

PROPAGATION DELAY, LATCH ENABLE TO OUTPUT

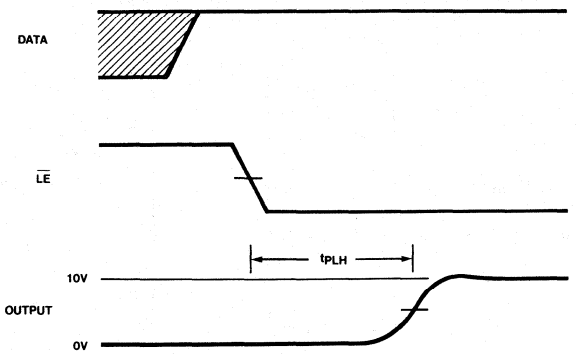


Figure 8

PROPAGATION DELAY, LATCH ENABLE TO OUTPUT

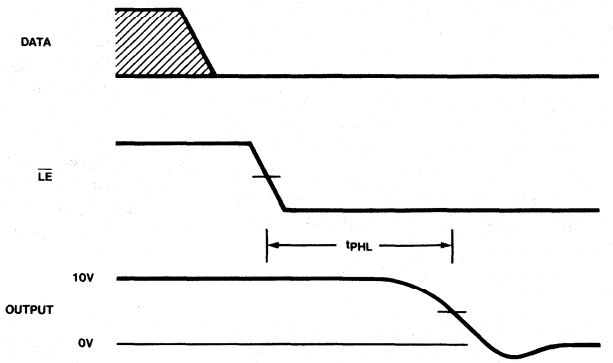


Figure 9

LATCH ENABLE PULSE WIDTH, SET-UP AND HOLD TIMES

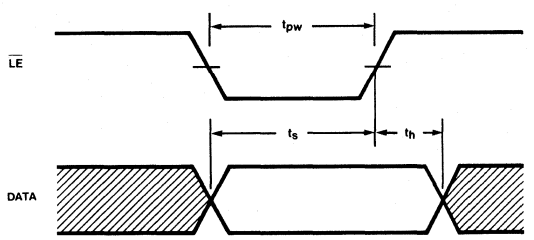


Figure 10

DESCRIPTION

The NE5019 is a complete 8-bit digital to analog converter subsystem on one monolithic chip. The data inputs have input latches, controlled by a latch enable pin. The data and latch enable inputs are ultra-low loading for easy interfacing with all logic systems. The latches appear transparent when the $\overline{LE}$ input is in the low state. When $\overline{LE}$ goes high, the input data present at the moment of transition is latched and retained until $\overline{LE}$ again goes low. This feature allows easy compatibility with most micro-processors.

The chip also comprises a stable voltage reference (5V nominal) and a high slew rate buffer amplifier. The voltage reference may be externally trimmed with a potentiometer for easy adjustment of full scale, while maintaining a low temperature co-efficient.

The output of the buffer amplifier may be offset so as to provide bipolar as well as unipolar operation.

FEATURES

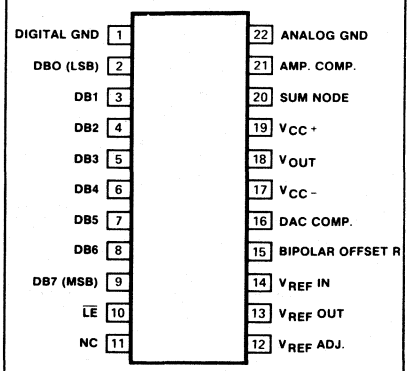
- **8-bit resolution**
- **Input latches**
- **Low-loading data inputs**
- **On-chip voltage reference**
- **Output buffer amplifier**
- **Accurate to ± 1/4 LSB (.1%)**
- **Monotonic to 8 bits**
- **Amplifier and reference both short-circuit protected**
- **Compatible with 2650,8080 and many other μP's**

APPLICATIONS

- **Precision 8-bit D/A converters**
- **A/D converters**
- **Programmable power supplies**
- **Test equipment**
- **Measuring instruments**
- **Analog-digital multiplication**

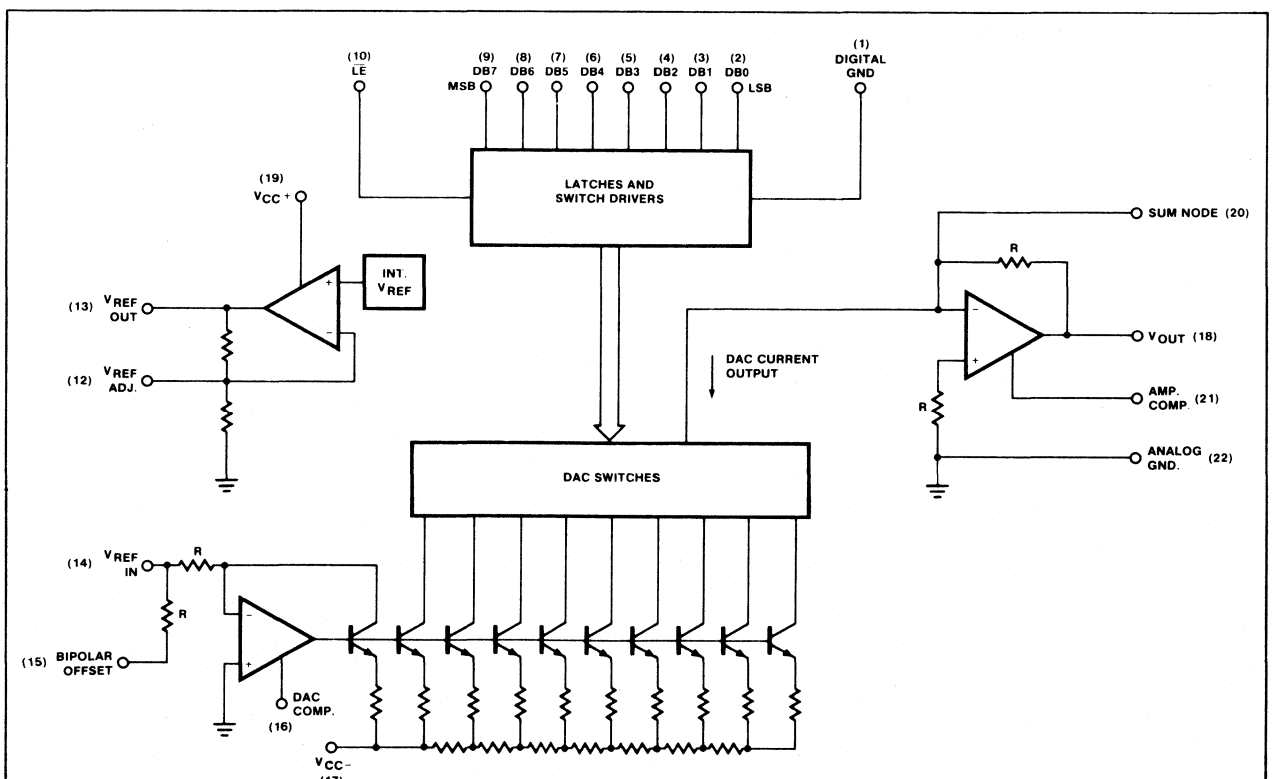
PIN CONFIGURATION

F,N PACKAGE



SE/NE5019 available in F package only.

BLOCK DIAGRAM



All R values equal 5KΩ and are thermally matched.

Figure 1

ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
$V_{CC}+$	Positive supply voltage	18	V
$V_{CC}-$	Negative supply voltage	−18	V
V_{IN}	Logic input voltage	0 to 18	V
$V_{REF}IN$	Voltage at V_{REF} input	12	V
$V_{REF}ADJ$	Voltage at V_{REF} adjust	0 to V_{REF}	V
V_{SUM}	Voltage at sum node	12	V
I_{REFSC}	Short-circuit current to ground at V_{REF} OUT	Continuous	
I_{OUTSC}	Short-circuit current to ground or either supply at V_{OUT}	Continuous	
I_{REF}	Reference input current	5	mA
P_D	Power dissipation*		
	-N package	800	mW
	-F package	1000	mW
T_A	Operating temperature range		
	SE5019	−55 to +125	°C
	NE5019	0 to +70	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_{SOLD}	Lead soldering temperature (10 seconds)	300	°C

*NOTES
For N package, derate at 120°C/W above 35°C
For F package, derate at 75°C/W above 75°C

DC ELECTRICAL CHARACTERISTICS

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5019. $-55°C \leq T_A \leq 125°C$, NE5019. $0°C \leq T_A \leq 70°C$ unless otherwise specified.[1]
Typical values are specified at 25°C

PARAMETER		TEST CONDITIONS	SE5019			NE5019			UNIT
			Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	Bits
	Relative accuracy				±0.1			±0.1	%FS
$V_{CC}+$	Positive supply voltage		11.4	15		11.4	15		V
$V_{CC}-$	Negative supply voltage		−11.4	−15		−11.4	−15		V
$V_{IN(1)}$	Logic "1" input voltage	Pin 1 = 0V	2.0			2.0			V
$V_{IN(0)}$	Logic "0" input voltage	Pin 1 = 0V			0.8			0.8	V
$I_{IN(1)}$	Logic "1" input current	Pin 1 = 0V, $2V < V_{IN} < 18V$		0.1	10		0.1	10	μA
$I_{IN(0)}$	Logic "0" input current	Pin 1 = 0V, $-5V < V_{IN} < 0.8V$		−2.0	−10		−2.0	−10	μA
V_{FS}	Full scale output voltage	Unipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C	9.50	9.961	10.50	9.50	9.961	10.50	V
V_{FS}	Full scale output voltage	Bipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C		+4.961			+4.961		V
V_{ZS}	Zero scale voltage			−5.000			−5.000		
				5			5		mV
I_{OS}	Output short circuit current	T_A = 25°C, V_{OUT} = 0V		15	40		15	40	mA
PSR+(out)	Output power supply rejection (+)	V− = −15V, 13.5V≤V+≤16.5V, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
PSR−(out)	Output power supply rejection (−)	V+ = 15V, −13.5V≤V−≤−16.5V, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
TC_{FS}	Full scale temperature coefficient	$V_{REF\ IN}$ = 5.000V		20			20		ppm/°C
TC_{ZS}	Zero scale temperature coefficient			5			5		ppm/°C

NOTE
1. Refer to Figure 2.

DC ELECTRICAL CHARACTERISTICS (Cont'd)

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5019. $-55°C \leq T_A \leq 125°C$, NE5019. $0°C \leq T_A \leq 70°C$ unless otherwise specified.[1]
Typical values are specified at 25°C

PARAMETER		TEST CONDITIONS	SE5019			NE5019			UNIT
			Min	Typ	Max	Min	Typ	Max	
I_{REF}	Reference output current	$\Delta V_{REF} \leq 0.1\%$		5			5		mA
I_{REFSC}	Reference short circuit current	$T_A = 25°C$ $V_{REF\ OUT} = 0V$		15			15		mA
$PSR+_{REF}$	Reference power supply rejection (+)	$V- = -15V$, $13.5V \leq V+ \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/ %VS
$PSR-_{REF}$	Reference power supply rejection (−)	$V+ = 15V$, $-13.5V \leq V- \leq 16.5V$,		.003	.01		.003	.01	%VR/ %VS
V_{REF}	Reference voltage	$I_{REF} = 1.0mA$	4.5	5.0	5.5	4.5	5.0	5.5	V
TC_{REF}	Reference voltage temperature coefficient	$I_{REF} = 1.0mA$		60			60		ppm/°C
Z_{IN}	DAC V_{REF}IN input impedance	$I_{REF} = 1.0mA$	4.0	5.0	6.0	4.0	5.0	6.0	KΩ
$I_{CC}+$	Positive supply current	$V_{CC}+ = 15V$		7	14		7	14	mA
$I_{CC}-$	Negative supply current	$V_{CC}- = -15V$		−10	−15		−10	−15	mA
P_D	Power dissipation	$I_{REF} = 1.0mA$, $V_{CC} = \pm 15V$		255	435		255	435	mW

NOTE
1. Refer to Figure 2.

AC ELECTRICAL CHARACTERISTICS[2] $V_{CC} = \pm 15V$, $T_A = 25°C$

PARAMETER		TO	FROM	TEST CONDITIONS	SE/NE5019			UNIT
					Min	Typ	Max	
T_{SLH}	Settling time	± ½ LSB	Input	All bits low to high[3]		1.8		μs
T_{SHL}	Settling time	± ½ LSB	Input	All bits high to low[4]		2.3		μs
t_{plh}	Propagation delay	Output	Input	All bits switched low to high[3]		300		ns
t_{phl}	Propagation delay	Output	Input	All bits switched high to low[4]		150		ns
t_{plsb}	Propagation delay	Output	Input	1 LSB change[3,4]		150		ns
t_{plh}	Propagation delay	Output	$\overline{LE}$	low to high transition[5]		300		ns
t_{phl}	Propagation delay	Output	$\overline{LE}$	high to low transition[6]		150		ns
t_s	Set-up time	$\overline{LE}$	Input	2, 7	100			ns
t_h	Hold time	Input	$\overline{LE}$	2, 7	50			ns
t_{pw}	Latch enable pulse width			2, 7	150			ns
	Reference input Slew rate			2		25		v/μs

NOTES
2. Refer to Figure 3.
3. See Figure 6.
4. See Figure 7.
5. See Figure 8.
6. See Figure 9.
7. See Figure 10.

DC PARAMETRIC TEST CONFIGURATION

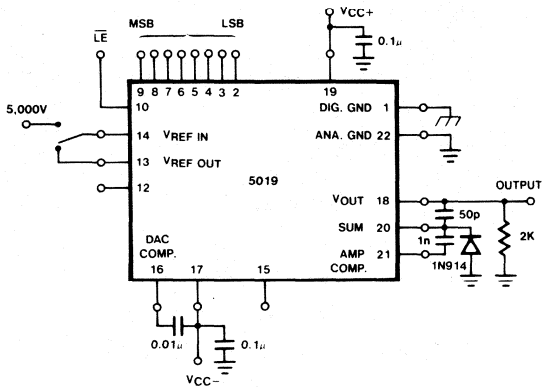


Figure 2

AC PARAMETRIC TEST CONFIGUTATION

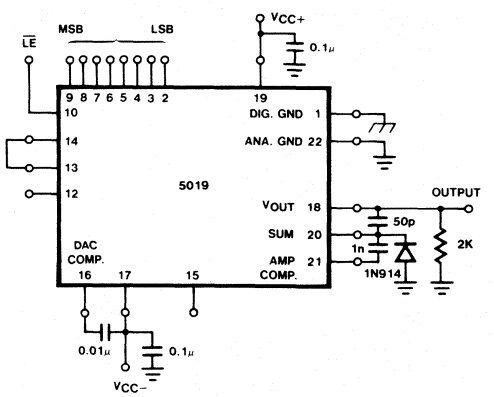


Figure 3

FULL/ZERO SCALE ADJUST—UNIPOLAR OUTPUT (0-10V)

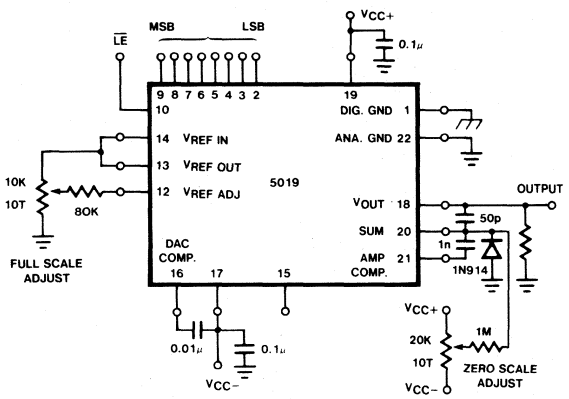


Figure 4

BIPOLAR OUTPUT OPERATION (−5 to +5V)

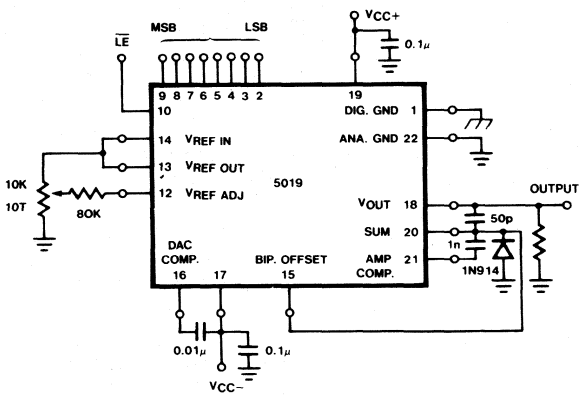


Figure 5

SETTLING TIME AND PROPAGATION DELAY, LOW TO HIGH DATA

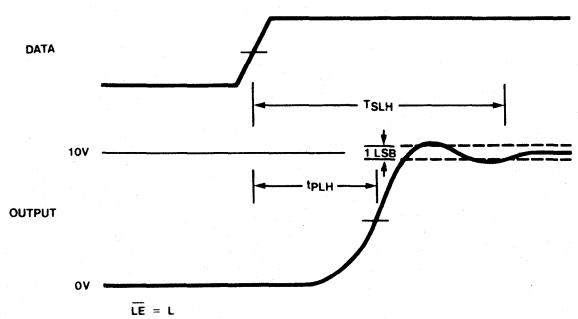


Figure 6

SETTLING TIME AND PROPAGATION DELAY, HIGH TO LOW DATA

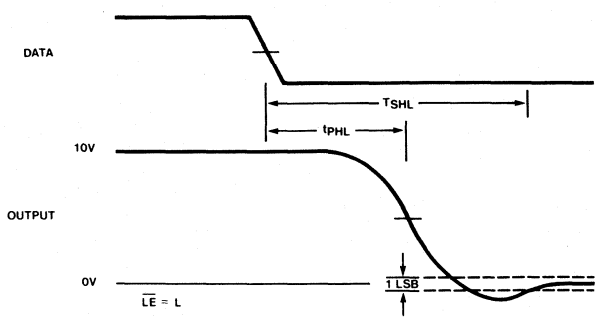


Figure 7

PROPAGATION DELAY, LATCH ENABLE TO OUTPUT

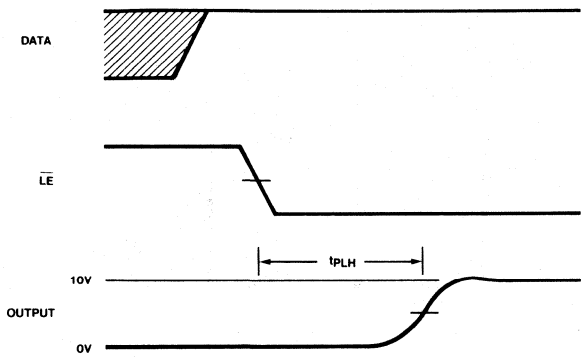


Figure 8

PROPAGATION DELAY, LATCH ENABLE TO OUTPUT

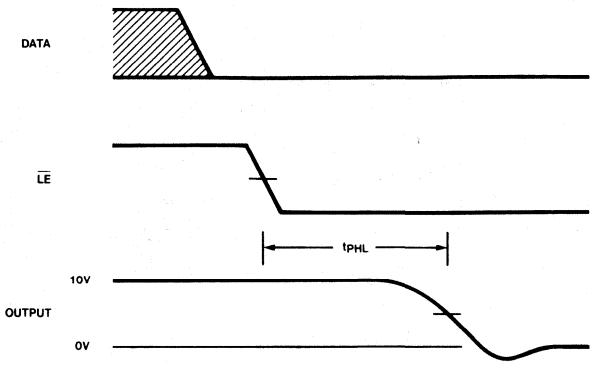


Figure 9

LATCH ENABLE PULSE WIDTH, SET-UP AND HOLD TIMES

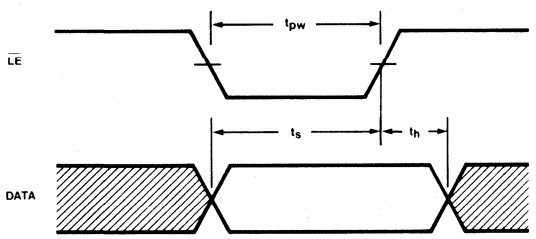


Figure 10

SE5118-F • NE5118-N

DESCRIPTION

The NE5118 is a high-speed 8-bit digital to analog converter subsystem on one monolithic chip. The data inputs have input latches, controlled by a latch enable pin. The data and latch enable inputs are ultra-low loading for easy interfacing with all logic systems. The latches appear transparent when the $\overline{LE}$ input is in the low state. When $\overline{LE}$ goes high, the input data present at the moment of transition is latched and retained until $\overline{LE}$ again goes low. This feature allows easy compatibility with most microprocessors.

The chip also comprises a stable voltage reference (5V nominal). The voltage reference may be externally trimmed with a potentiometer for easy adjustment of full scale, while maintaining a low temperature co-efficient.

The output has high voltage compliance increasing versatility.

FEATURES

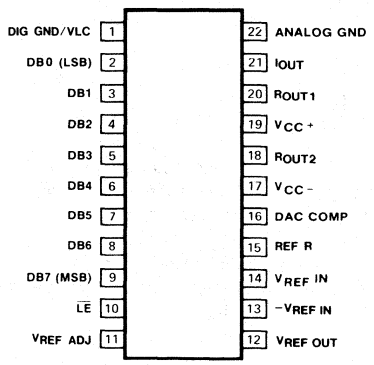
- 8-bit resolution
- Input latches
- Low-loading data inputs
- On-chip voltage reference
- Fast settling output current—200ns
- Accurate to ±1/2 LSB
- Monotonic to 8 bits
- Reference short-circuit protected
- Compatible with 2650, 8080 and many other μP's

APPLICATIONS

- Precision 8-bit D/A converters
- A/D converters
- Programmable power supplies
- Test equipment
- Measuring instruments
- Analog-digital multiplication
- CRT display drivers
- High-speed modems

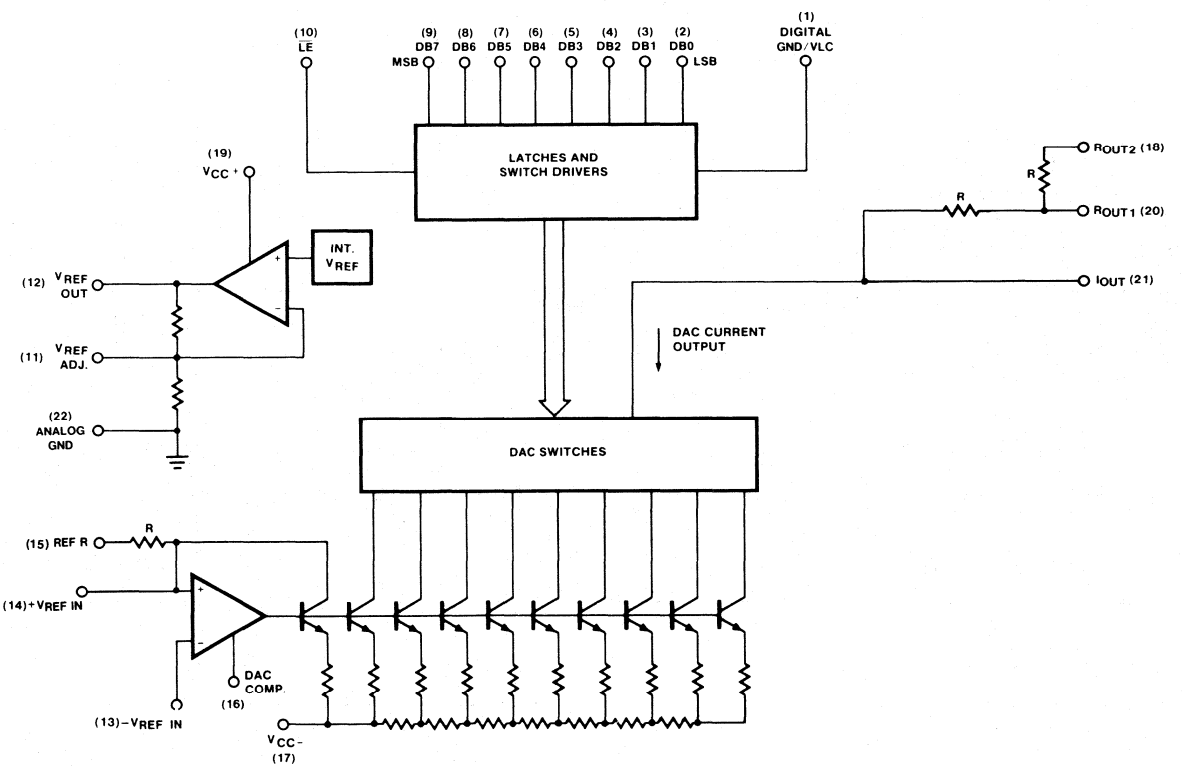
PIN CONFIGURATION

F,N PACKAGE



SE5118 available in F package only.

BLOCK DIAGRAM



All R values equal 5kΩ and are thermally matched.

Figure 1

ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
$V_{CC}+$	Positive supply voltage	18	V
$V_{CC}-$	Negative supply voltage	−18	V
V_{IN}	Logic input voltage	0 to 18	V
$V_{REF}IN$	Voltage at R_{REF} input	12	V
$V_{REF}ADJ$	Voltage at V_{REF} adjust	0 to V_{REF}	V
V_{SUM}	Voltage at sum node	12	V
I_{REFSC}	Short-circuit current to ground at V_{REF} OUT	Continuous	
I_{REF}	Reference input current	5	mA
P_D	Power dissipation*		
	-N package	800	mW
	-F package	1000	mW
T_A	Operating temperature range		
	SE5118	−55 to +125	°C
	NE5118	0 to +70	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_{SOLD}	Lead soldering temperature (10 seconds)	300	°C

*NOTES

For N package, derate at 120°C/W above 35°C

For F package, derate at 75° C/W above 75°C

DC ELECTRICAL CHARACTERISTICS

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5118. $-55°C \leq T_A \leq 125°C$, NE5118. $0°C \leq T_A \leq 70°C$ unless otherwise specified.
Typical values are specified at 25°C

	PARAMETER	TEST CONDITIONS	SE5118			NE5118			UNIT
			Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	Bits
	Relative accuracy				±0.19			±0.19	%FS
$V_{CC}+$	Positive supply voltage		11.4	15		11.4	15		V
$V_{CC}-$	Negative supply voltage		−11.4	−15		−11.4	−15		V
$V_{IN(1)}$	Logic "1" input voltage	Pin 1 = 0V	2.0			2.0			V
$V_{IN(0)}$	Logic "0" input voltage	Pin 1 = 0V			0.8			0.8	V
$I_{IN(1)}$	Logic "1" input current	Pin 1 = 0V, $2V < V_{IN} < 18V$		0.1	10		0.1	10	μA
$I_{IN(0)}$	Logic "0" input current	Pin 1 = 0V, $-5V < V_{IN} < 0.8V$		−2.0	−10		−2.0	−10	μA
I_{FS}	Full scale output current	Unipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C	1.90	1.992	2.10	1.90	1.992	2.10	mA
I_{ZS}	Zero scale current			1			1		μA
V_{REF}	Internal reference voltage	I_O = 1mA	4.5	5.0	5.5	4.5	5.0	5.5	V
$PSR+_{(out)}$	Output power supply rejection (+)	V− = −15V, $11.4V \leq V+ \leq 16.5V$, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
$PSR-_{(out)}$	Output power supply rejection (−)	V+ = 15V, $-11.4V \leq V- \leq -16.5V$, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
TC_{FS}	Full scale temperature coefficient	$V_{REF\ IN}$ = 5.000V		20			20		ppm/°C
TC_{ZS}	Zero scale temperature coefficient			5			5		ppm/°C

DC ELECTRICAL CHARACTERISTICS

(Cont'd) $V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5118. $-55°C \leq T_A \leq 125°C$, NE5118. $0°C \leq T_A \leq 70°C$ unless otherwise specified. Typical values are specified at 25°C

PARAMETER		TEST CONDITIONS	SE5118			NE5118			UNIT
			Min	Typ	Max	Min	Typ	Max	
I_{REF}	Reference output current	$\Delta V_{REF} \leq 0.1\%$		5			5		mA
I_{REFSC}	Reference short circuit current	$T_A = 25°C$		15	30		15	30	mA
		$V_{REF\ OUT} = 0V$							
$PSR+_{(REF)}$	Reference power supply rejection (+)	$V- = -15V$, $13.5V \leq V+ \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/ %VS
$PSR-_{(REF)}$	Reference power supply rejection (−)	$V+ = 15V$, $-13.5V \leq V- \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/ %VS
TC_{REF}	Reference voltage temperature coefficient	$I_{REF} = 1.0mA$		60			60		ppm/°C
Z_{IN}	DAC $R_{REF}IN$ input impedance		4.0	5.0	6.0	4.0	5.0	6.0	kΩ
$I_{CC}+$	Positive supply current	$V_{CC}+ = 15V$		7	14		7	14	mA
$I_{CC}-$	Negative supply current	$V_{CC}- = -15V$		−10	−15		−10	−15	mA
P_D	Power dissipation	$I_{REF} = 1.0mA$, $V_{CC} = \pm 15V$		255	435		255	435	mW

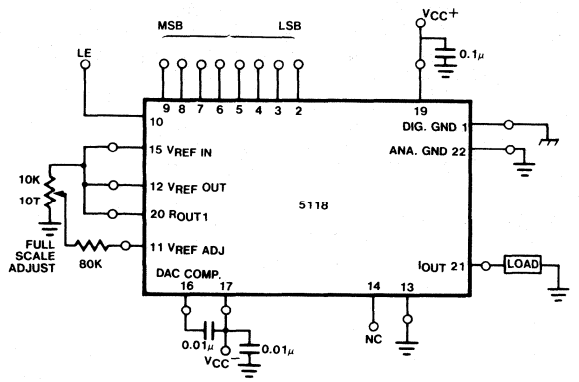
AC ELECTRICAL CHARACTERISTICS

$V_{CC} = \pm 15V$, $T_A = 25°C$

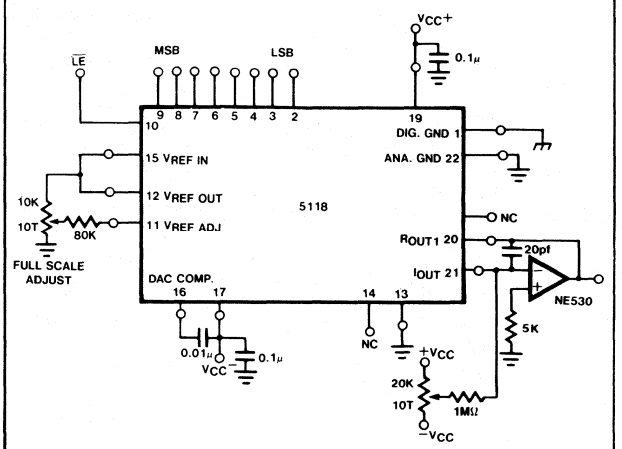
PARAMETER		TO	FROM	TEST CONDITIONS	SE/NE5118			UNIT
					Min	Typ	Max	
T_{SLH}	Settling time	± ½ LSB	Input	All bits Low-to-high		200		ns
T_{SHL}	Settling time	± ½ LSB	Input	All bits High-to-low		200		ns
t_{PLH}	Propagation delay	Output	Input	All bits switched Low-to-high		60		ns
t_{PHL}	Propagation delay	Output	Input	All bits switched High-to-low		60		ns
t_{PLSB}	Propagation delay	Output	Input	1 LSB change		60		ns
t_{PLH}	Propagation delay	Output	$\overline{LE}$	Low-to-high transition		60		ns
t_{PHL}	Propagation delay	Output	$\overline{LE}$	High-to-low transition		60		ns
t_s	Set-up time	$\overline{LE}$	Input		100			ns
t_h	Hold time	Input	$\overline{LE}$		50			ns
t_{pw}	Latch enable pulse width				150			ns
	Reference input Slew rate					5		mA/μs

SE5118-F • NE5118-N

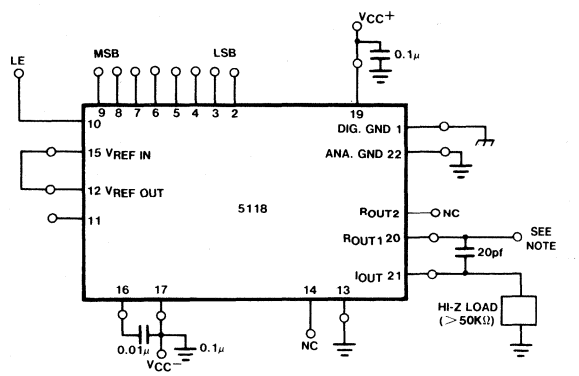
BIPOLAR OUTPUT OPERATION (−1mA TO +1mA)



UNIPOLAR VOLTAGE OUTPUT (0 →+10V)



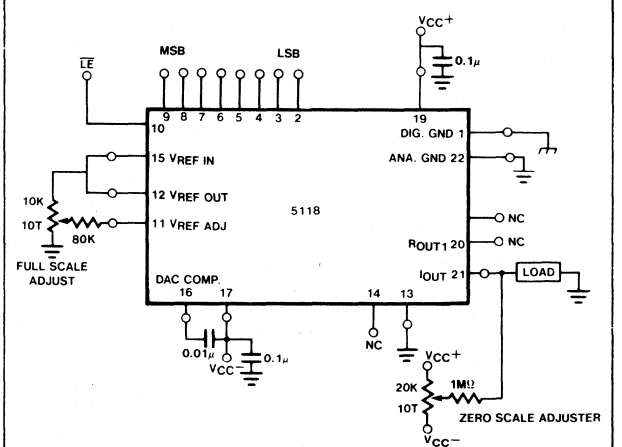
FAST VOLTAGE OUTPUT



NOTE

DATA INPUT CODE	VOLTAGE OUTPUT (PIN 21)	
0 0 0 0 0 0 0 0	+10V	0V
1 1 1 1 1 1 1 1	0V	−10V
	Pin 20 tied to +10V	Pin 20 tied to 0V

BASIC UNIPOLAR CURRENT OUTPUT (0 →−2mA)



SE5119-F • NE5119-N

DESCRIPTION

The NE5119 is a high-speed 8-bit digital to analog converter subsystem on one monolithic chip. The data inputs have input latches, controlled by a latch enable pin. The data and latch enable inputs are ultra-low loading for easy interfacing with all logic systems. The latches appear transparent when the $\overline{LE}$ input is in the low state. When $\overline{LE}$ goes high, the input data present at the moment of transition is latched and retained until $\overline{LE}$ again goes low. This feature allows easy compatibility with most microprocessors.

The chip also comprises a stable voltage reference (5V nominal). The voltage reference may be externally trimmed with a potentiometer for easy adjustment of full scale, while maintaining a low temperature co-efficient.

The output has high voltage compliance increasing versatility.

FEATURES

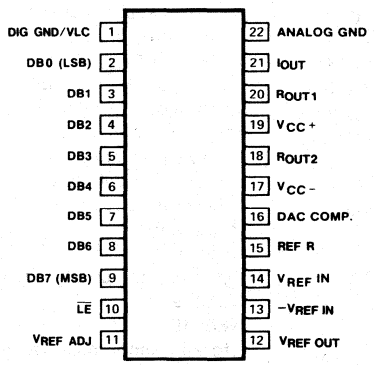
- 8-bit resolution
- Input latches
- Low-loading data inputs
- On-chip voltage reference
- Fast settling output current—200ns
- Accurate to ± 1/4 LSB
- Monotonic to 8 bits
- Reference short-circuit protected
- Compatible with 2650, 8080 and many other μP's

APPLICATIONS

- Precision 8-bit D/A converters
- A/D converters
- Programmable power supplies
- Test equipment
- Measuring instruments
- Analog-digital multiplication
- CRT display drivers
- High-speed modems

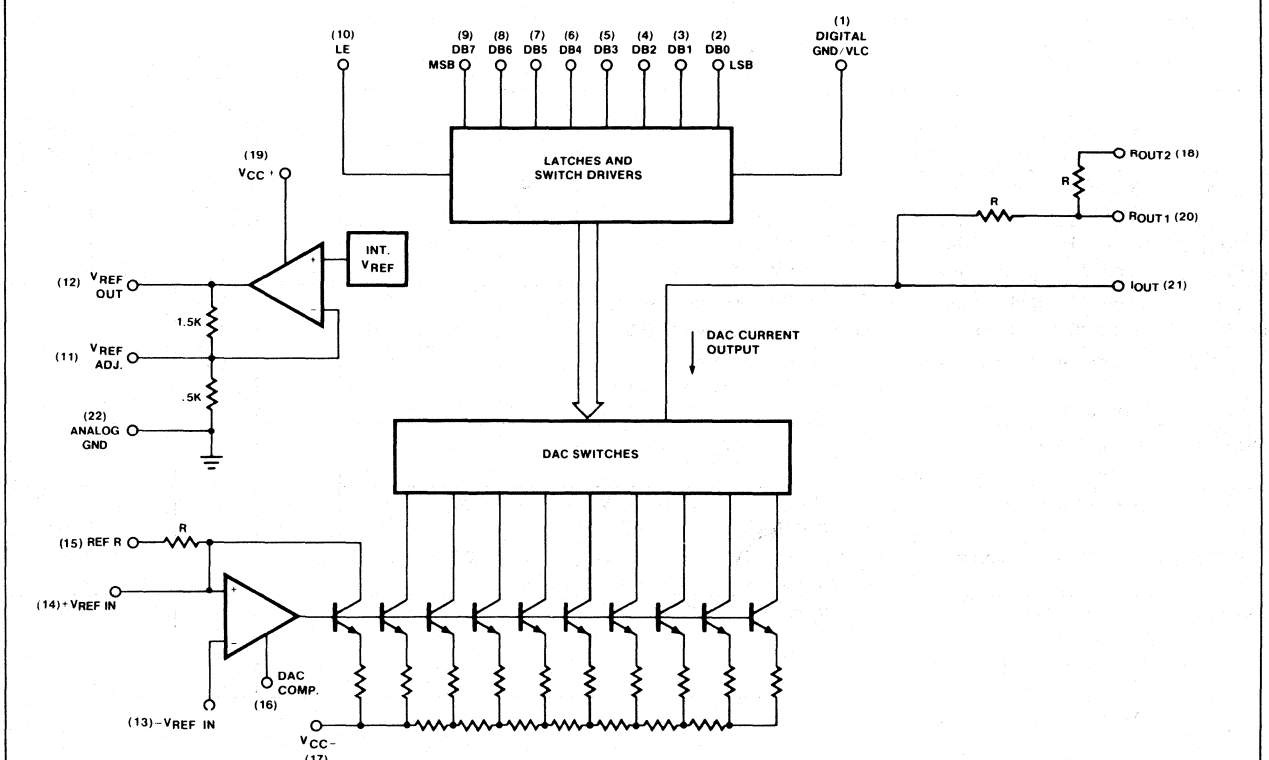
PIN CONFIGURATION

F,N PACKAGE



SE5119 available in F package only.

BLOCK DIAGRAM



All R values equal 5kΩ and are thermally matched.

Figure 1

ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
$V_{CC}+$	Positive supply voltage	18	V
$V_{CC}-$	Negative supply voltage	−18	V
V_{IN}	Logic input voltage	0 to 18	V
$V_{REF}IN$	Voltage at R_{REF} input	12	V
$V_{REF}ADJ$	Voltage at V_{REF} adjust	0 to V_{REF}	V
V_{SUM}	Voltage at sum node	12	V
I_{REFSC}	Short-circuit current to ground at V_{REF} OUT	Continuous	
I_{REF}	Reference input current	5	mA
P_D	Power dissipation*		
	-N package	800	mW
	-F package	1000	mW
T_A	Operating temperature range		
	SE5119	−55 to +125	°C
	NE5119	0 to +70	°C
T_{STG}	Storage temperature range	−65 to +150	°C
T_{SOLD}	Lead soldering temperature (10 seconds)	300	°C

*NOTES

For N package, derate at 120°C/W above 35°C

For F package, derate at 75° C/W above 75°C

DC ELECTRICAL CHARACTERISTICS

$V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5119. $-55°C \leq T_A \leq 125°C$, NE5119. $0°C \leq T_A \leq 70°C$ unless otherwise specified.
Typical values are specified at 25°C

	PARAMETER	TEST CONDITIONS	SE5119			NE5119			UNIT
			Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	Bits
	Relative accuracy				±0.1			±0.1	%FS
$V_{CC}+$	Positive supply voltage		11.4	15		11.4	15		V
$V_{CC}-$	Negative supply voltage		−11.4	−15		−11.4	−15		V
$V_{IN(1)}$	Logic "1" input voltage	Pin 1 = 0V	2.0			2.0			V
$V_{IN(0)}$	Logic "0" input voltage	Pin 1 = 0V			0.8			0.8	V
$I_{IN(1)}$	Logic "1" input current	Pin 1 = 0V, $2V < V_{IN} < 18V$		0.1	10		0.1	10	μA
$I_{IN(0)}$	Logic "0" input current	Pin 1 = 0V, $-5V < V_{IN} < 0.8V$		−2.0	−10		−2.0	−10	μA
I_{FS}	Full scale output current	Unipolar operation $V_{REF\ IN}$ = 5.000V, T_A = 25°C	1.90	1.992	2.10	1.90	1.992	2.10	mA
I_{ZS}	Zero scale current			1			1		μA
V_{REF}	Internal reference voltage	I_O = 1mA	4.5	5.0	5.5	4.5	5.0	5.5	V
$PSR+_{(out)}$	Output power supply rejection (+)	V− = −15V, $13.5V \leq V+ \leq 16.5V$, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
$PSR-_{(out)}$	Output power supply rejection (−)	V+ = 15V, $-13.5V \leq V- \leq -16.5V$, external $V_{REF\ IN}$ = 5.000V		.001	.01		.001	.01	%FS/%VS
TC_{FS}	Full scale temperature coefficient	$V_{REF\ IN}$ = 5.000V		20			20		ppm/°C
TC_{ZS}	Zero scale temperature coefficient			5			5		ppm/°C

DC ELECTRICAL CHARACTERISTICS

(Cont'd) $V_{CC}+ = +15V$, $V_{CC}- = -15V$, SE5119. $-55°C \leq T_A \leq 125°C$, NE5119. $0°C \leq T_A \leq 70°C$ unless otherwise specified. Typical values are specified at 25°C

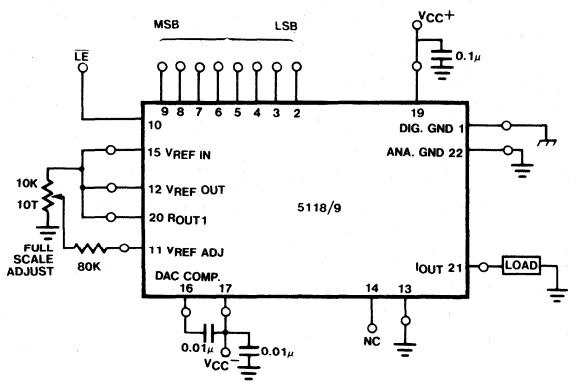
PARAMETER		TEST CONDITIONS	SE5119			NE5119			UNIT
			Min	Typ	Max	Min	Typ	Max	
I_{REF}	Reference output current	$\Delta V_{REF} \leq 0.1\%$		5			5		mA
I_{REFSC}	Reference short circuit current	$T_A = 25°C$, $V_{REF\ OUT} = 0V$		15	30		15	30	mA
$PSR+_{(REF)}$	Reference power supply rejection (+)	$V- = -15V$, $13.5V \leq V+ \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/ %VS
$PSR-_{(REF)}$	Reference power supply rejection (−)	$V+ = 15V$, $-13.5V \leq V- \leq 16.5V$, $I_{REF} = 1.0mA$		.003	.01		.003	.01	%VR/ %VS
TC_{REF}	Reference voltage temperature coefficient	$I_{REF} = 1.0mA$		60			60		ppm/°C
Z_{IN}	DAC $R_{REF}IN$ input impedance		4.0	5.0	6.0	4.0	5.0	6.0	kΩ
$I_{CC}+$	Positive supply current	$V_{CC}+ = 15V$		7	14		7	14	mA
$I_{CC}-$	Negative supply current	$V_{CC}- = -15V$		−10	−15		−10	−15	mA
P_D	Power dissipation	$I_{REF} = 1.0mA$, $V_{CC} = \pm 15V$		255	435		255	435	mW

AC ELECTRICAL CHARACTERISTICS

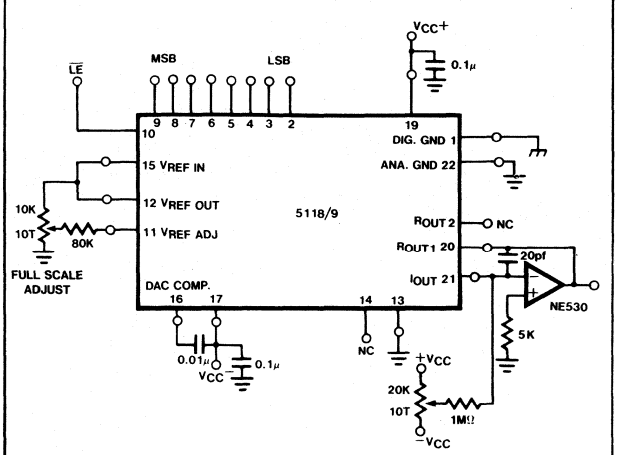
$V_{CC} = \pm 15V$, $T_A = 25°C$

PARAMETER		TO	FROM	TEST CONDITIONS	SE/NE5119			UNIT
					Min	Typ	Max	
T_{SLH}	Settling time	± ½ LSB	Input	All bits Low-to-high		200		ns
T_{SHL}	Settling time	± ½ LSB	Input	All bits High-to-low		200		ns
t_{PLH}	Propagation delay	Output	Input	All bits switched Low-to-high		60		ns
t_{PHL}	Propagation delay	Output	Input	All bits switched High-to-low		60		ns
t_{PLSB}	Propagation delay	Output	Input	1 LSB change		60		ns
t_{PLH}	Propagation delay	Output	$\overline{LE}$	Low-to-high transition		60		ns
t_{PHL}	Propagation delay	Output	$\overline{LE}$	High-to-low transition		60		ns
t_s	Set-up time	$\overline{LE}$	Input		100			ns
t_h	Hold time	Input	$\overline{LE}$		50			ns
t_{pw}	Latch enable pulse width				150			ns
	Reference input Slew rate					5		mA/μs

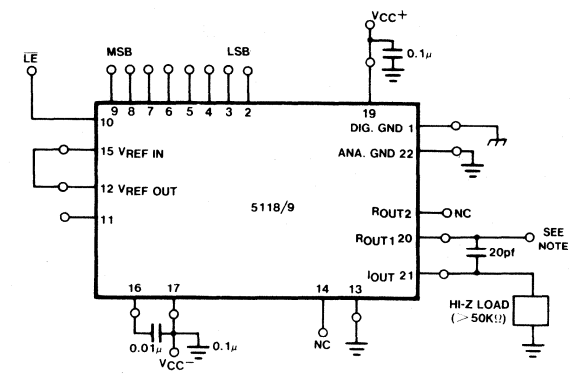
BIPOLAR OUTPUT OPERATION (−1mA TO +1mA)



UNIPOLAR VOLTAGE OUTPUT (0 → +10V)



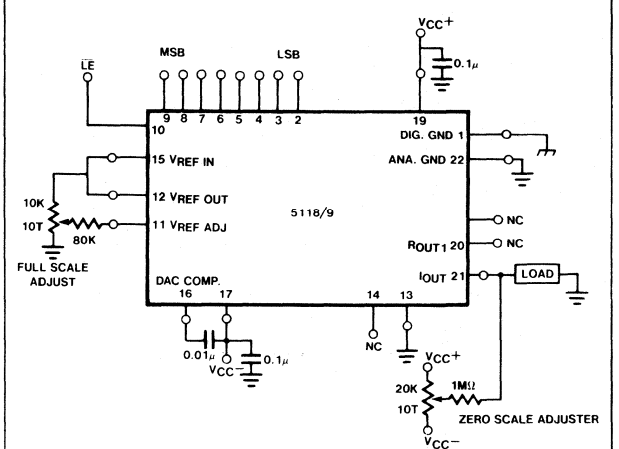
FAST VOLTAGE OUTPUT



NOTE

DATA INPUT CODE	VOLTAGE OUTPUT (PIN 21)	
0 0 0 0 0 0 0 0	+10V	0V
1 1 1 1 1 1 1 1	0V	−10V
	Pin 20 tied to +10V	Pin 20 tied to 0V

BASIC UNIPOLAR CURRENT OUTPUT (0 → −2mA)



SECTION II
AUDIO/RADIO CIRCUITS

Section 11—AUDIO/RADIO CIRCUITS

II

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

NE/SE540-H

DESCRIPTION

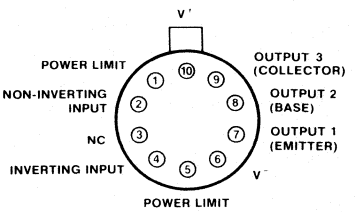
The NE/SE540 is a monolithic, class AB power amplifier designed specifically to drive a pair of complementary output transistors. The device features low standby current yet retains a high output current drive capability with internal current limiting. A wide power bandwidth and excellent linearity make this device ideal for use an audio power amplifier.

FEATURES

- **Internal current limiting**
- **Low standby current**
- **High output current capability**
- **Wide power bandwidth**
- **Low distortion**

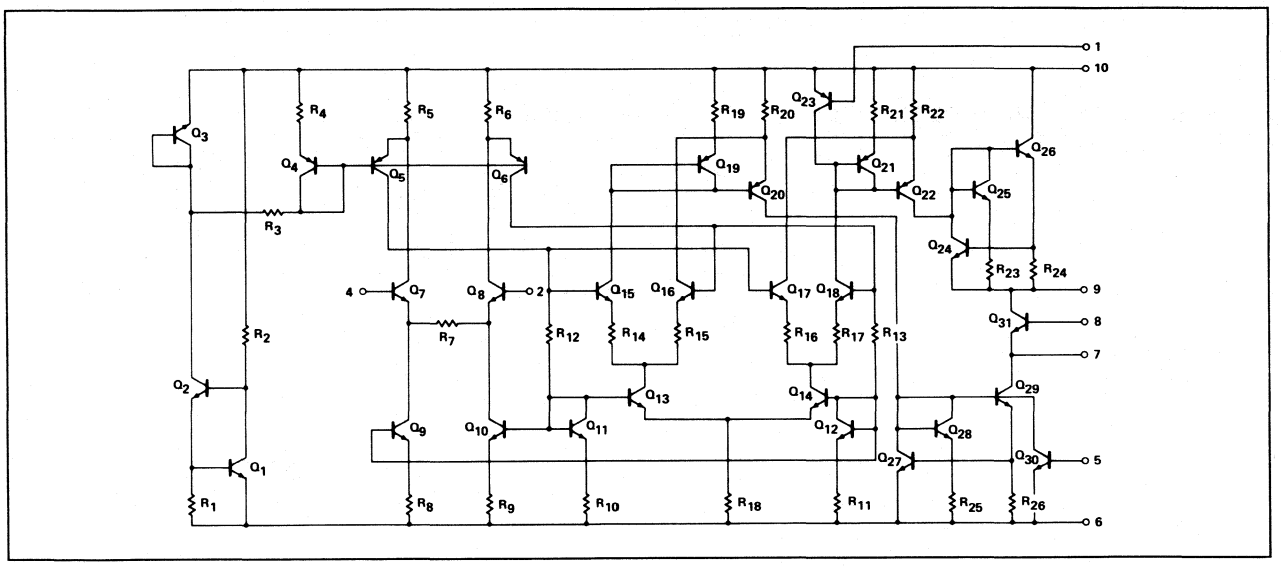
PIN CONFIGURATION

H PACKAGE



ORDER PART NO.
NE540H, SE540H

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage		
SE540	±27	V
NE540	±22	V
Operating temperature range		
SE540	-55 to +125	°C
NE540	0 to +70	°C
Storage temperature range	-65 to +150	°C
Output short circuit duration (Not exceeding maximum dissipation.)	Indefinite	

DC ELECTRICAL CHARACTERISTICS

T_A = 25°C and V_{CC} = ±20V unless otherwise specified.

PARAMETER	TEST CONDITIONS	SE540			NE540			UNIT
		Min	Typ	Max	Min	Typ	Max	
Operating supply voltage		±5		±25	±5		±20	V
Quiescent current			13	20		13	20	mA
Input offset voltage			5	7		7	10	mV
Input offset current			0.3	0.7		0.5	1	μA
Input bias current			1.5	3		2	5	μA
Input impedance			20			20		kΩ
Current gain		80	100		70	90		dB
Gain variation over temperature range	40dB gain		±0.1			±0.1		dB
Power supply rejection ratio	40dB gain	80	90		60	80		dB
Common mode rejection ratio			110			90		dB
Output drive current		±120	±150		±80	±100		mA

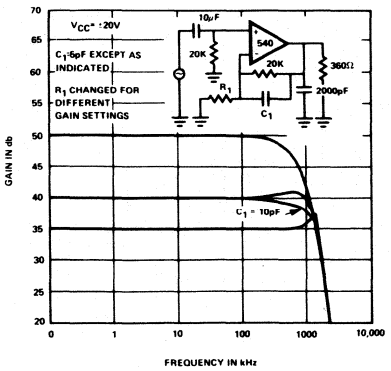
AC ELECTRICAL CHARACTERISTICS

T_A = 25°C and V_{CC} = ±20V unless otherwise specified.

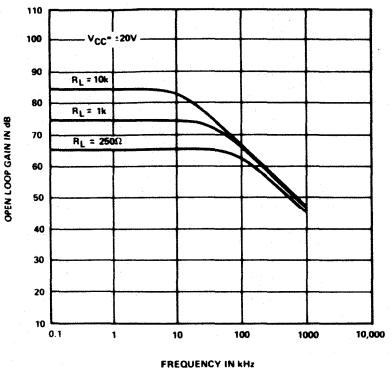
PARAMETER	TEST CONDITIONS	SE540			NE540			UNIT
		Min	Typ	Max	Min	Typ	Max	
Frequency response	40dB gain ±1dB		500			100		kHz
Distortion	40dB gain, Output 3dB below clipping		0.25	0.5		0.5	1.0	%
	R_L = 600Ω							
	R_L = 2kΩ		0.06			0.06		
Equivalent input noise voltage	R_S = 600Ω 50Hz to 500kHz		10			10		μV
Slew rate	V_{CC} = ±20V V_{OUT} = ±15V		200			200		V/μs

TYPICAL PERFORMANCE CHARACTERISTICS

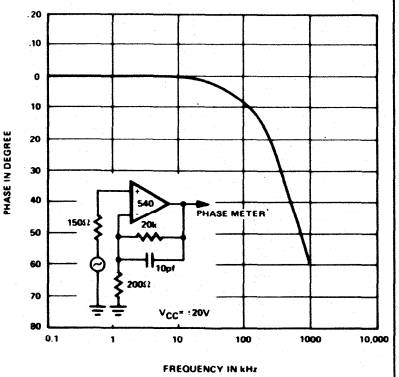
CLOSED LOOP FREQUENCY RESPONSE



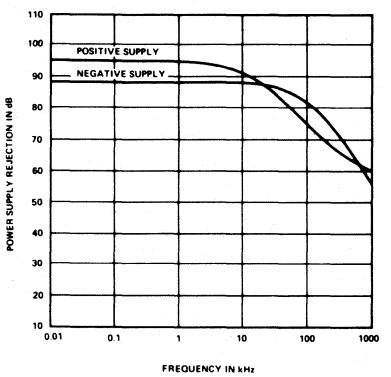
OPEN LOOP GAIN AND FREQUENCY RESPONSE



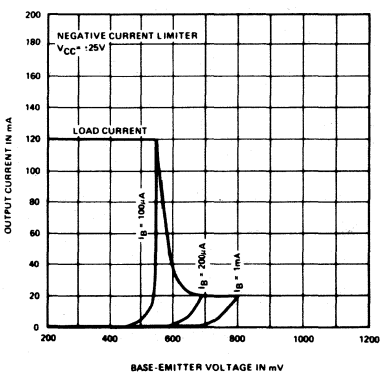
PHASE RESPONSE vs FREQUENCY



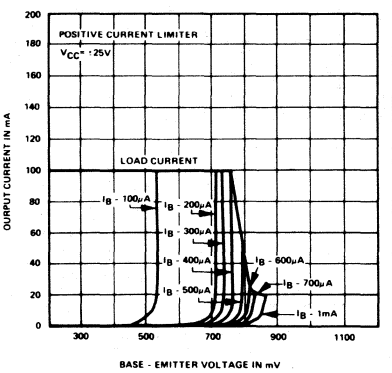
POWER SUPPLY REJECTION vs FREQUENCY



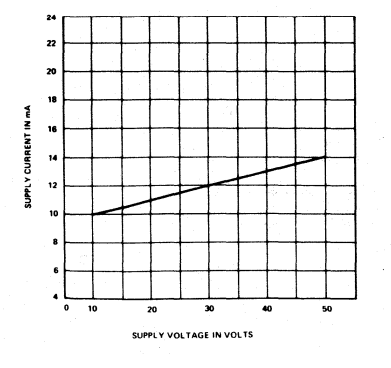
OUTPUT CURRENT vs I_B/V_{BE} OF CURRENT LIMITER



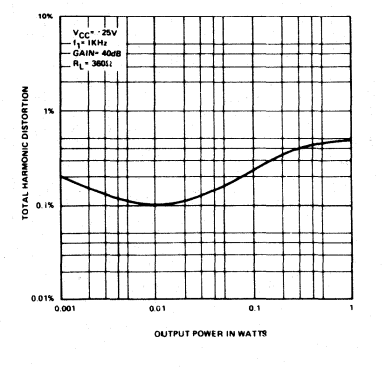
OUTPUT CURRENT vs I_B/V_{BE} OF CURRENT LIMITER



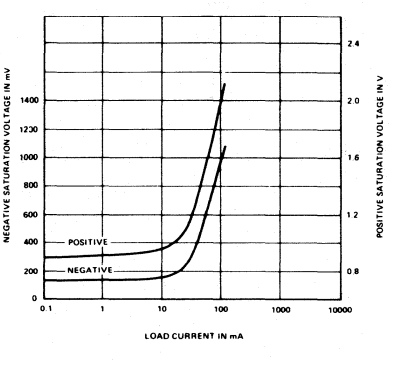
QUIESCENT CURRENT vs SUPPLY VOLTAGE



TOTAL HARMONIC DISTORTION vs OUTPUT

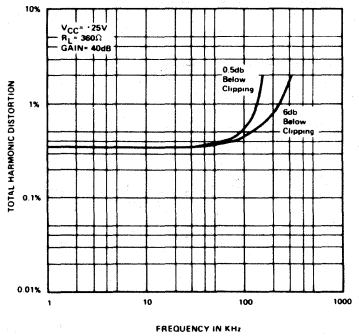


OUTPUT SATURATION VOLTAGE vs LOAD

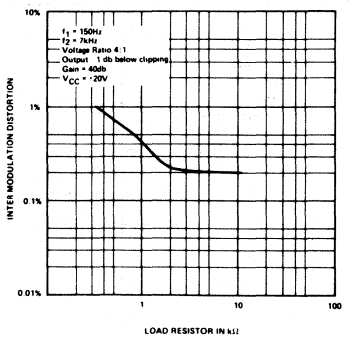


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

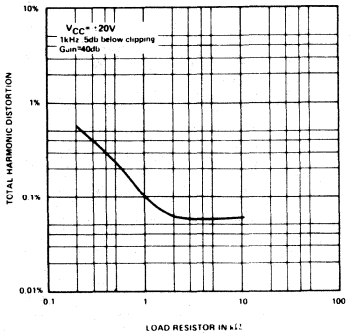
TOTAL HARMONIC DISTORTION vs FREQUENCY



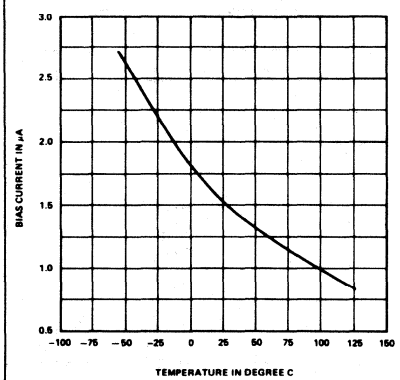
INTERMODULATION DISTORTION vs LOAD



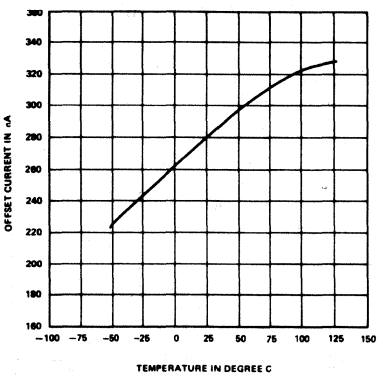
TOTAL HARMONIC DISTORTION vs LOAD



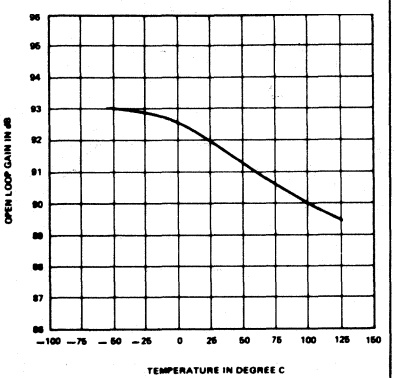
BIAS CURRENT vs TEMPERATURE



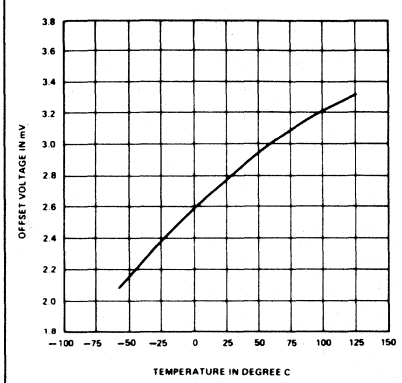
OFFSET CURRENT vs TEMPERATURE



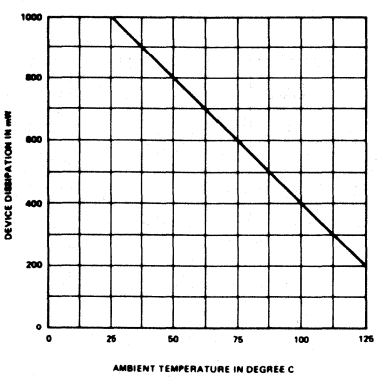
OPEN LOOP GAIN vs TEMPERATURE



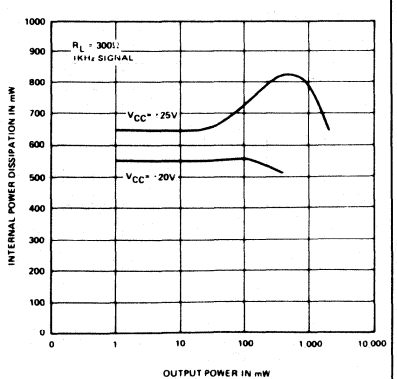
OFFSET VOLTAGE vs TEMPERATURE



MAXIMUM DISSIPATION vs AMBIENT TEMPERATURE

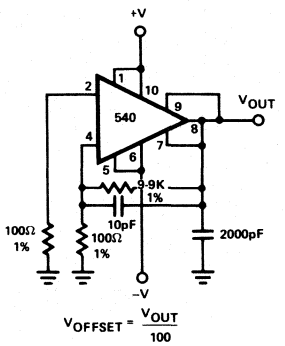


INTERNAL POWER DISSIPATION vs LOAD POWER

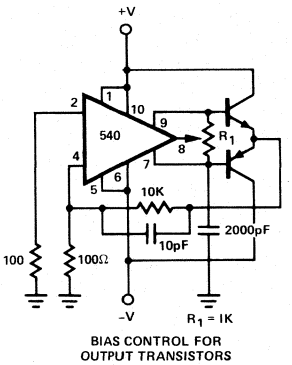


TEST CIRCUITS

OFFSET VOLTAGE MEASUREMENT



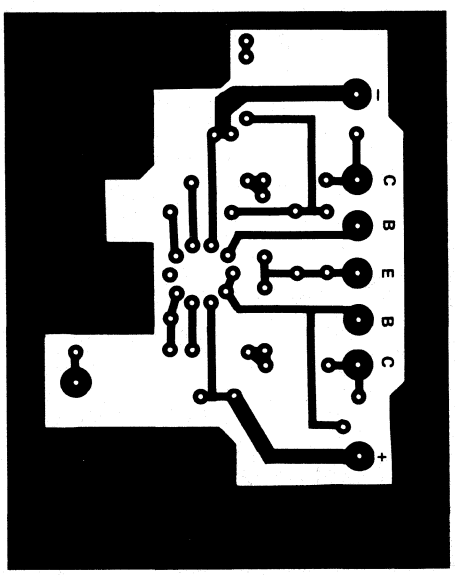
OUTPUT BIAS CONTROL



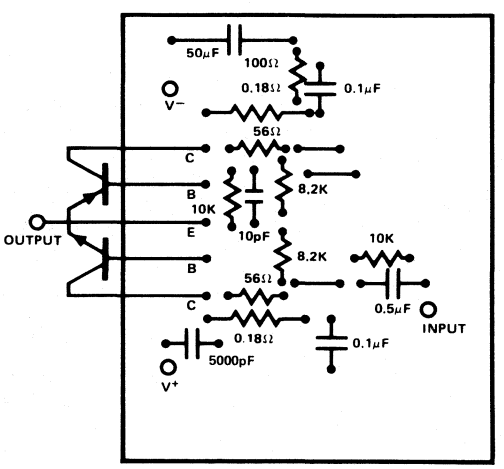
BIAS CONTROL FOR
OUTPUT TRANSISTORS

35 WATT AMPLIFIER

P.C. BOARD LAYOUT
(Bottom View)



PARTS LAYOUT
(Top View)



NE542-N

DESCRIPTION

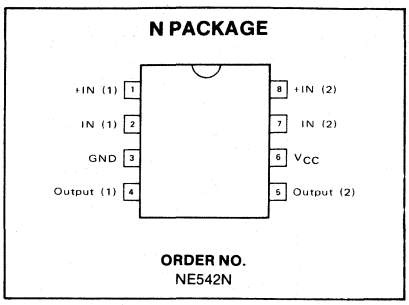
The NE542 is a dual preamplifier for the amplification of low level signals in applications requiring optimum noise performance. Each of the two amplifiers is completely independent, with individual internal power supply decoupler-regulator, providing 110dB supply rejection and 70dB channel separation. Other outstanding features include high gain (104dB), large output voltage swing (V_{CC} -2Vp-p), and internal compensation to 10dB. The NE542 operates from a single supply across the wide range of 9 to 24V.

The NE542 is ideal for use in stereo phono, tape, or microphone preamps and other applications requiring low noise amplication of small signals.

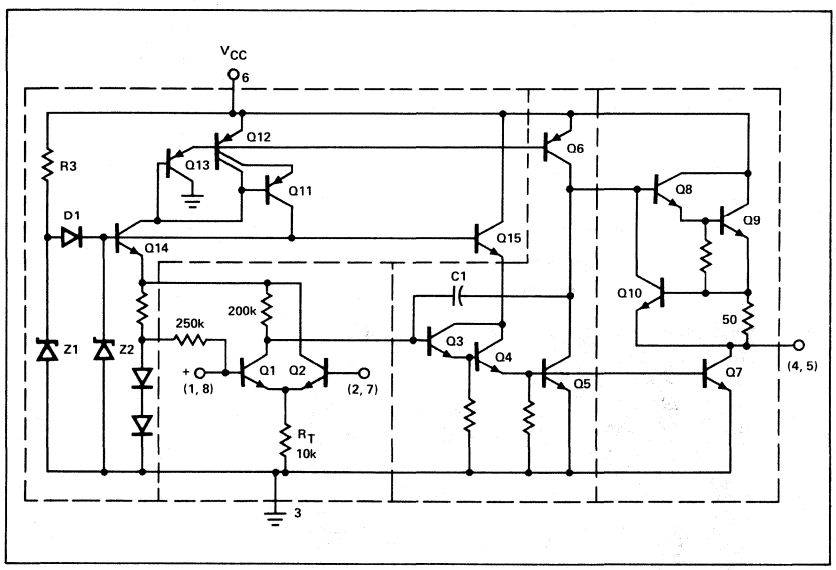
FEATURES

- **Low noise—.7μV total input noise**
- **High gain—104dB open loop**
- **Single supply operation**
- **Wide supply range 9 to 24V**
- **Power supply rejection 110dB**
- **Large output voltage swing (V_{CC} -2V p-p)**
- **Wide bandwidth 15MHz unity gain**
- **Power bandwidth 100kHz (15V p-p)**
- **Internally compensated (stable at 10dB)**
- **Short circuit protected**
- **High slew rate 5V/μs**

PIN CONFIGURATION



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	+24	V
Power dissipation	500	mW
Operating temperature range	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60sec)	+300	°C

DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_{CC} = 14V$ unless otherwise specified.

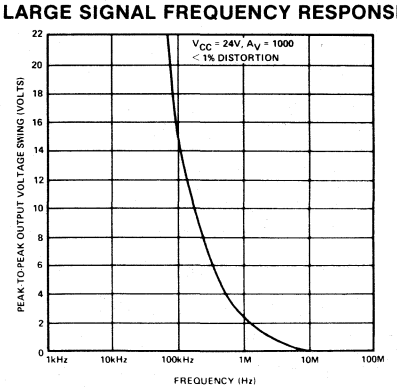
PARAMETER	TEST CONDITIONS	NE542			UNIT
		Min	Typ	Max	
Supply voltage		9		24	V
Supply current	V_{CC} = 9 to 18V, $R_L = \infty$		9	15	mA
Input resistance					
Positive input			100		kΩ
Negative input			200		kΩ
Output resistance	Open loop		150		Ω

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $V_{CC} = 14V$ unless otherwise specified.

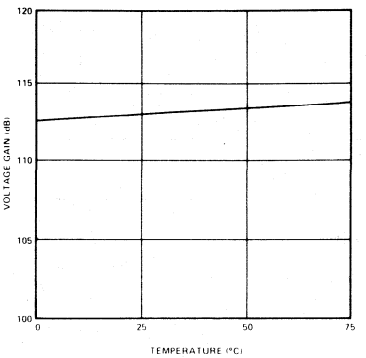
PARAMETER	TEST CONDITIONS	NE542			UNIT
		Min	Typ	Max	
Voltage gain	Open loop		160,000		V/V
Input current Negative input			 .5		 μA
Output current	Source Sink (linear operation)	8 2	14 3		mA mA
Output voltage swing Small signal bandwidth Slew rate Power bandwidth	 15V p-p	V_{CC} -2.5	V_{CC} -2 15 5 100		V MHz V/μs kHz
Maximum input voltage	Linear operation			300	mVrms
Supply rejection ratio Channel separation	f = 60, 120Hz f = 1kHz f = 1kHz		100 110 70		dB dB dB
Total harmonic distortion Total equivalent input Noise	75dB gain, f = 1kHz RS = 600Ω, 100 - 10,000Hz		.1 .7	 1.2	% μVrms
Noise figure	RS = 50kΩ, 10 - 10,000Hz RS = 20kΩ, 10 10,000Hz RS = 10kΩ, 10 - 10,000Hz RS = 5kΩ, 10 - 10,000Hz		1.2 1.2 1.5 2.4		dB dB dB dB

TYPICAL PERFORMANCE CHARACTERISTICS

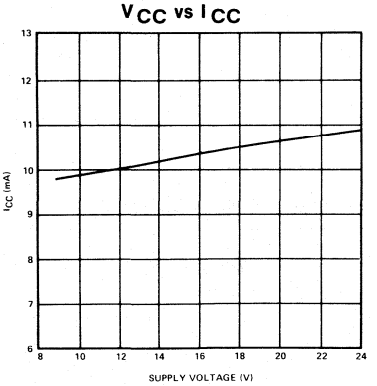
LARGE SIGNAL FREQUENCY RESPONSE



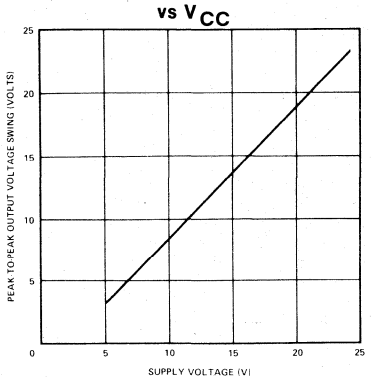
GAIN vs TEMPERATURE



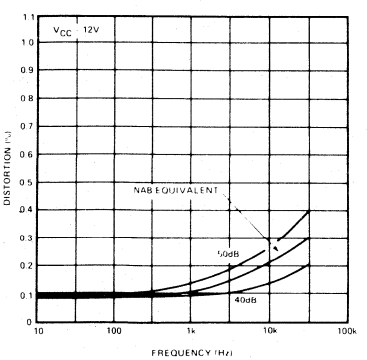
V_{CC} vs I_{CC}



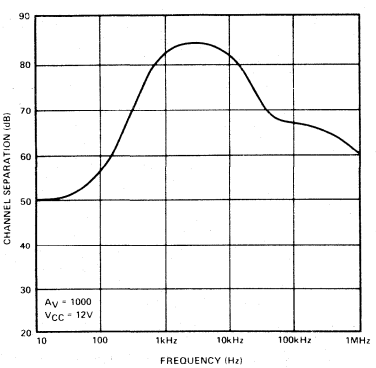
P-P OUTPUT VOLTAGE SWING vs V_{CC}



% DISTORTION

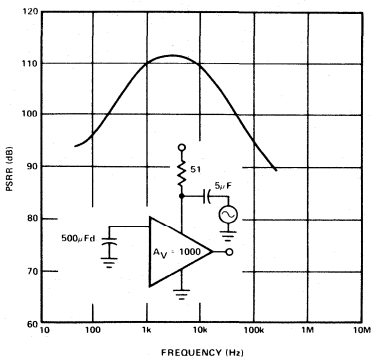


CHANNEL SEPARATION

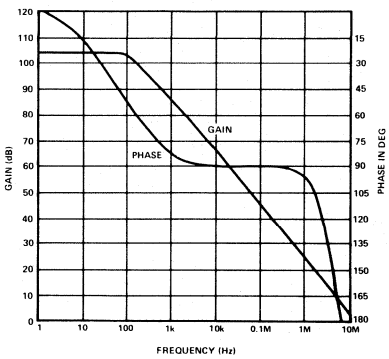


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

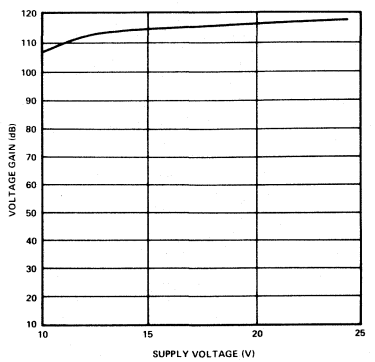
PSRR vs FREQUENCY



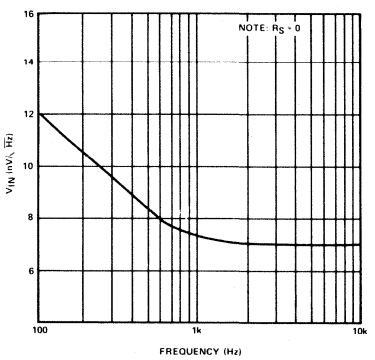
GAIN AND PHASE RESPONSE



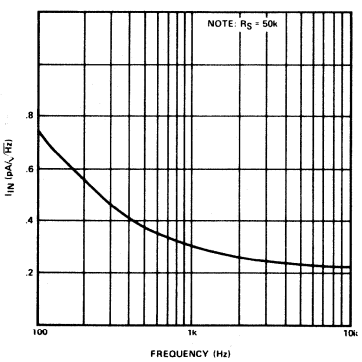
VOLTAGE GAIN vs SUPPLY VOLTAGE



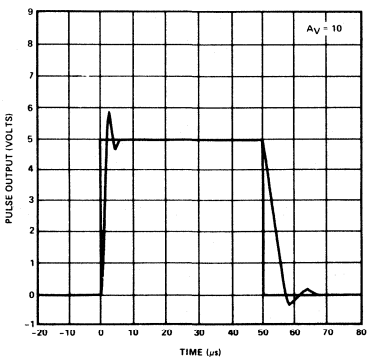
NOISE VOLTAGE vs FREQUENCY



NOISE CURRENT vs FREQUENCY

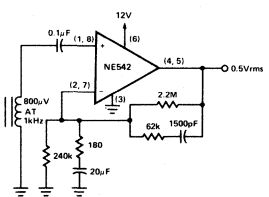


PULSE RESPONSE

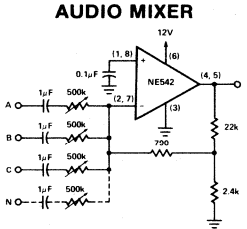


TYPICAL APPLICATIONS

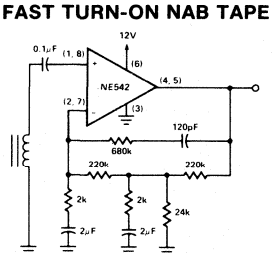
TYPICAL TAPE PLAYBACK AMPLIFIER



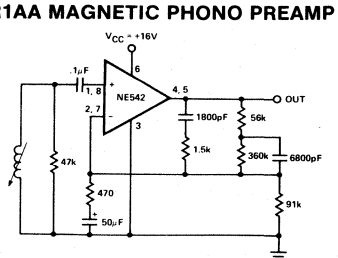
AUDIO MIXER



TWO-POLE FAST TURN-ON NAB TAPE PREAMP



R1AA MAGNETIC PHONO PREAMP



NOTE: All resistors values are typical and in ohms.

DESCRIPTION

The NE570/571 is a versatile low cost dual gain control circuit in which either channel may be used as a dynamic range compressor or expandor. Each channel has a full wave rectifier to detect the average value of the signal; a linerarized, temperature compensated variable gain cell; and an operational amplifier.

The NE570/571 is well suited for use in telephone subscriber and trunk carrier systems, communications systems and hi-fi audio systems.

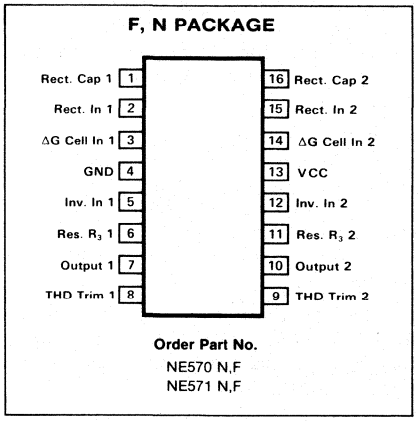
FEATURES

- **Complete compressor and expandor in 1 IC**
- **Temperature compensated**
- **Greater than 110dB dynamic range**
- **Operates down to 6Vdc**
- **System levels adjustable with external components**
- **Distortion may be trimmed out**

APPLICATIONS

- **Telephone trunk compandor—570**
- **Telephone subscriber compandor—571**
- **High level limiter**
- **Low level expandor—noise gate**
- **Dynamic noise reduction systems**
- **Voltage controlled amplifier**
- **Dynamic filters**

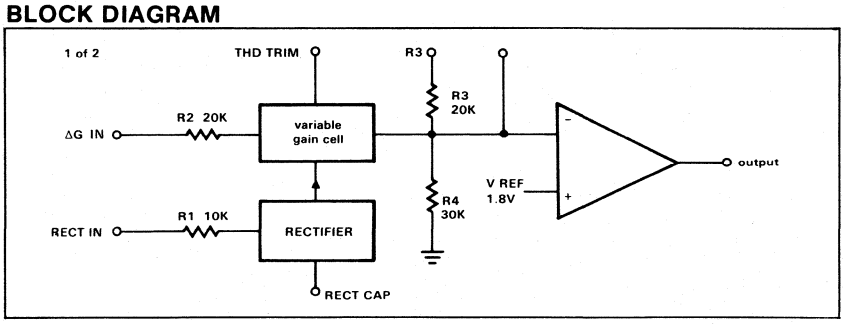
PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
	Positive supply		Vdc
	570	24	
	571	18	
T_A	Operating temperature range	-40 to +70	°C
P_D	Power dissipation	400	mW

BLOCK DIAGRAM



CIRCUIT DESCRIPTION

The NE570/571 compandor building blocks, as shown in the block diagram, are a full wave rectifier, a variable gain cell, an operational amplifier and a bias system. The arrangement of these blocks in the IC result in a circuit which can perform well with few external components, yet can be adapted to many diverse applications.

The full wave rectifier rectifies the input current which flows from the rectifier input, to an internal summing node which is biased at V_{REF}. The rectified current is averaged on an external filter capacitor tied to the C_{RECT} terminal, and the average value of the input current controls the gain of the variable gain cell. The gain will thus be proportional to the average value of the input signal for capacitively coupled voltage inputs as shown in the following equation. Note that for capacitively coupled inputs there is no offset voltage capable of producing a gain error. The only error will come from the bias current of the rectifier (supplied internally) which is less than .1μA.

$$G \propto \frac{|V_{IN} - V_{REF}|_{ave}}{R_1}$$

or

$$G \propto \frac{|V_{IN}|_{ave}}{R_1}$$

The speed with which gain changes to follow changes in input signal levels is determined by the rectifier filter capacitor. A small capacitor will yield rapid response but will not fully filter low frequency signals. Any ripple on the gain control signal will modulate the signal passing through the variable gain cell. In an expandor or compressor application, this would lead to third harmonic distortion, so there is a tradeoff to be made between fast attack and decay times, and distortion. For step changes in amplitude, the change in gain with time is shown by this equation.

$$G(t) = (G_{initial} - G_{final})\ e^{-t/\tau} + G_{final};\ \tau = 10K \times C_{RECT}$$

The variable gain cell is a current in, current out device with the ratio I_{OUT}/I_{IN} controlled by the rectifier. I_{IN} is the current which flows from the ΔG input to an internal summing node biased at V_{REF}. The following equation applies for capacitively coupled inputs. The output current, I_{OUT}, is fed to the summing node of the op amp.

$$I_{IN} = \frac{V_{IN} - V_{REF}}{R_2} = \frac{V_{IN}}{R_2}$$

A compensation scheme built into the ΔG cell compensates for temperature, and cancels out odd harmonic distortion. The only distortion which remains is even harmonics, and they exist only because of internal offset voltages. The THD trim terminal provides a means for nulling the internal offsets for low distortion operation.

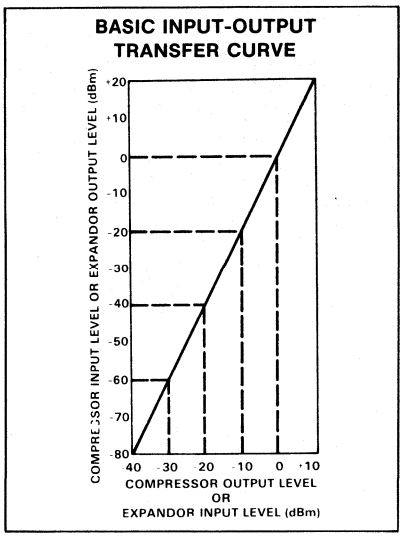
The operational amplifier (which is internally compensated) has the non-inverting input tied to V_{REF}, and the inverting input connected to the ΔG cell output as well as brought out externally. A resistor, R_3, is brought out from the summing node and allows compressor or expandor gain to be determined only by internal components.

The output stage is capable of ±20mA output current. This allows a +13dBm (3.5V rms) output into a 300Ω load which, with a series resistor and proper transformer, can result in +13dBm with a 600Ω output impedance.

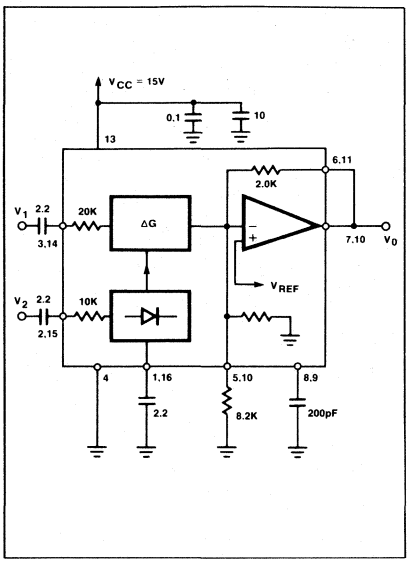
A band gap reference provides the reference voltage for all summing nodes, a regulated supply voltage for the rectifier and ΔG cell, and a bias current for the ΔG cell. The low tempco of this type of reference provides very stable biasing over a wide temperature range.

The typical performance characteristics illustration shows the basic input-output transfer curve for basic compressor or expandor circuits.

TYPICAL PERFORMANCE CHARACTERISTICS



TYPICAL TEST CIRCUIT



DC ELECTRICAL CHARACTERISTICS T_A = 25°C, V_{CC} = 15V[1]

PARAMETER	TEST CONDITIONS	NE570			NE571			UNIT
		Min	Typ	Max	Min	Typ	Max	
V_{CC} Supply voltage		6		24	6		18	V
I_{CC} Supply current	No signal		3.2	4.0		3.2	4.8	mA
Output current capability		±20						mA
Output slew rate			±.5					V/us
Gain cell distortion[2]	Untrimmed		.3	1.0		.5	2.0	%
	Trimmed		.05			.1		
Resistor tolerance			±5	±15				%
Internal reference voltage		1.7	1.8	1.9	1.65	1.8	1.95	V
Output dc shift[3]	Untrimmed		±20	±50		±30	±100	mV
Expandor output noise	No signal, 20Hz-20kHz		20					μV
			-15					dBRNC
Unity gain level		-1	0	+1	-1.5	0	+1.5	dBm
Gain change[2,4]	-40°C < T < 70°C		±.1			±.1		dB
	0°C < T < 70°C		±.1	±.2		±.1	±.4	
Reference drift[4]	-40°C < T < 70°C		+2, -25	-10, -40		+2, -25	+20, -50	mV
	0°C < T < 70°C		±5	±10		±5	±20	
Resistor drift[4]	-40°C < T < 70°C		+8,-0					%
	0°C < T < 70°C		+1,-0					
Tracking error [5], input	Rectifier input, V_2 =							dB
V_1 = OdBm	+6dBm		±.2					
	-10dBm		+.2	-.2,+.4		+.2	-.2,+.5	
	-20dBm		+.2	-.3,+.6		+.2	-.4,+.7	
	-30dBm		+.2	-.5,+1		+.2	-1,+1.5	
	-40dBm		+.2,-.4			+.2,-.4		

NOTES

1. Except where indicated, the 571 specifications are identical to the 570
2. Measured at OdBm,1kHz
3. Expandor ac input change from no signal to OdBm
4. Relative to value at T_A = 25°C
5. Relative to OdBm

LM387-N

DESCRIPTION

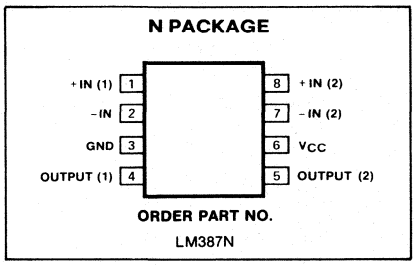
The LM387 is a dual preamplifier for the amplification of low level signals in applications requiring optimum noise performance. Each of the two amplifiers is completely independent, with an internal power supply decoupler-regulator, providing 110dB supply rejection and 60dB channel separation. Other outstanding features include high gain (104dB), large output voltage swing (V_{CC} - 2V p-p), and wide power bandwidth (75kHz, 20V p-p). The LM387 operates from a single supply across the wide range of 9 to 40V.

The amplifiers are internally compensated for all gains greater than 10. The LM387 is available in an 8 lead dual-in-line package.

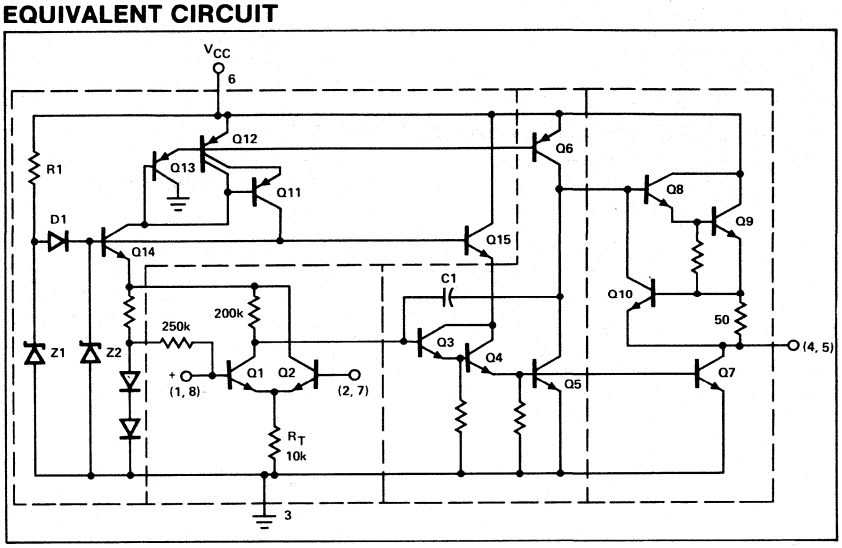
FEATURES

- **Low noise—0.8μV total input noise**
- **High gain—104dB open loop**
- **Single supply operation**
- **Wide supply range 9 to 40V**
- **Power supply rejection—110dB**
- **Large output voltage swing (VCC - 2V p-p)**
- **Wide bandwidth 15MHz unity gain**
- **Power bandwidth 75kHz, 20V p-p**
- **Internally compensated**
- **Short circuit protected**

PIN CONFIGURATION



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	+40	V
Power dissipation	500	mW
Operating temperature range	0 to +70	°C
Storage temperature range	-65 to +150	°C
Lead temperature (soldering, 60sec)	+300	°C

DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_{CC} = 14V unless otherwise specified.

PARAMETER	TEST CONDITIONS	LM387			UNIT
		Min	Typ	Max	
Voltage gain	Open loop		160,000		V/V
Supply current	V_{CC} 9 to 40V, $R_L = \infty$		10		mA
Input resistance	Positive input		100		kΩ
	Negative input		200		kΩ
Input current	Negative input		0.5		μA
Output resistance	Open loop		150		Ω
Output current	Source		8		mA
	Sink		2		mA
Output voltage swing	Peak-to-peak		V_{CC}-2		V

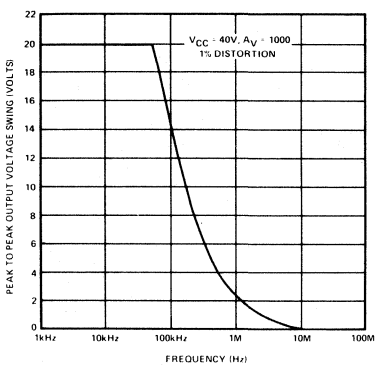
AC ELECTRICAL CHARACTERISTICS

$T_A = 25\,°C$, $V_{CC} = 14V$ unless otherwise specified.

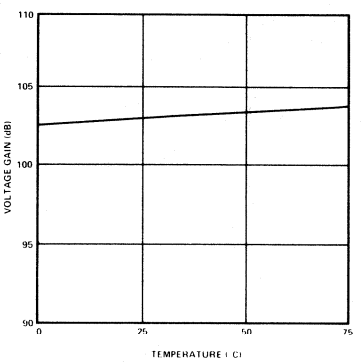
PARAMETER	TEST CONDITIONS	LM387			UNIT
		Min	Typ	Max	
Small signal bandwidth			15		MHz
Power bandwidth	20V p-p ($V_{CC} = 24V$)		75		kHz
Maximum input voltage	Linear operation			300	μVrms
Supply rejection ratio	f = 1kHz		110		dB
Channel separation	f = 1kHz		60		dB
Total harmonic distortion	75dB gain, f = 1kHz		0.1		%
Total equivalent input noise	$R_S = 600\Omega$, 100-10,000Hz		0.8	1.4	μVrms
Noise figure	50kΩ, 100-10,000Hz		1.0		dB
	10kΩ, 100-10,000Hz		1.6		dB
	5kΩ, 100-10,000Hz		2.8		dB

TYPICAL PERFORMANCE CHARACTERISTICS

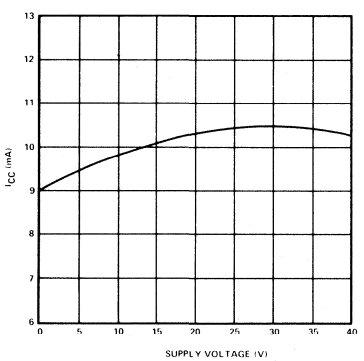
LARGE SIGNAL FREQUENCY RESPONSE



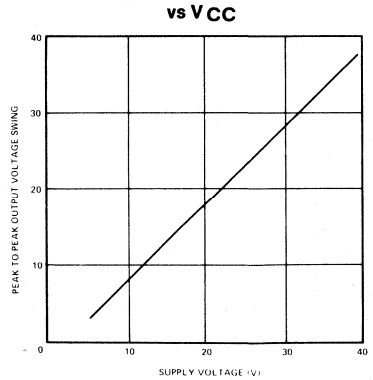
GAIN vs TEMPERATURE



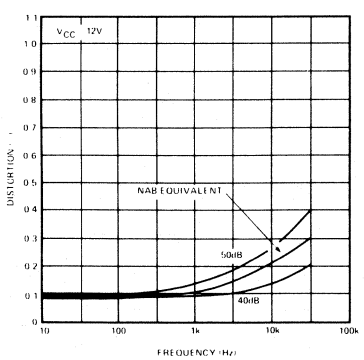
V_{CC} vs I_{CC}



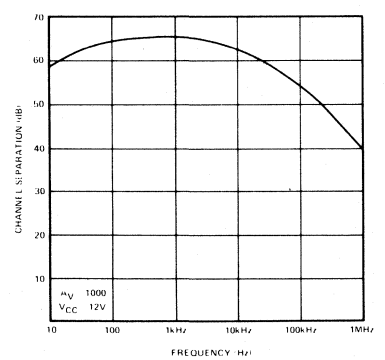
P-P OUTPUT VOLTAGE SWING vs V_{CC}



% DISTORTION

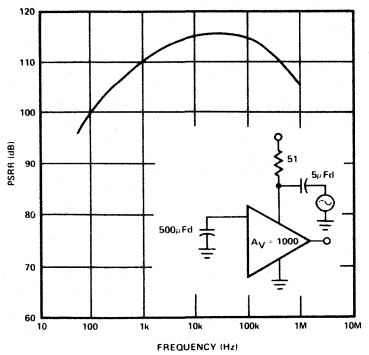


CHANNEL SEPARATION

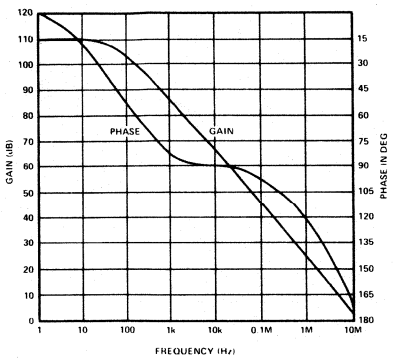


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

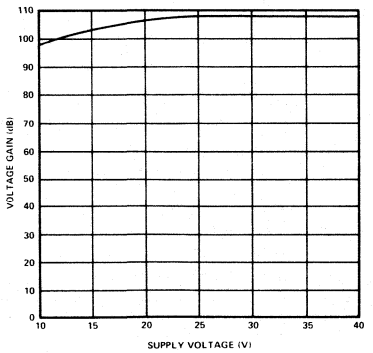
PSRR vs FREQUENCY



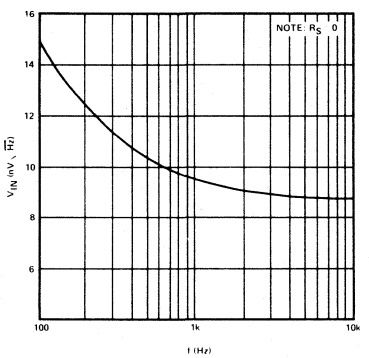
GAIN AND PHASE RESPONSE



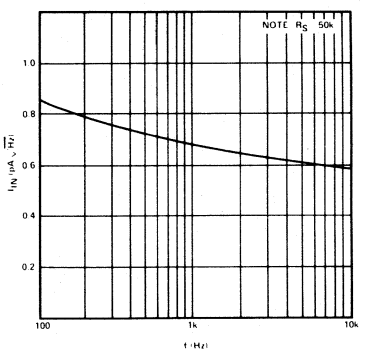
VOLTAGE GAIN vs SUPPLY VOLTAGE



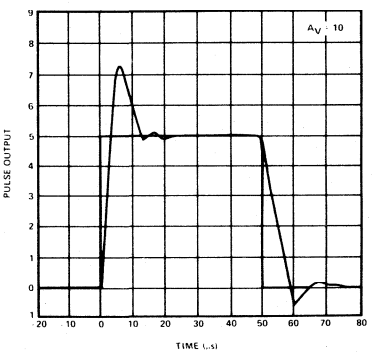
NOISE VOLTAGE vs FREQUENCY



NOISE CURRENT vs FREQUENCY

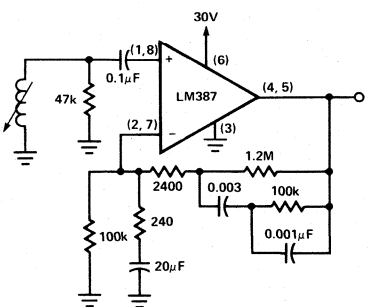


PULSE RESPONSE

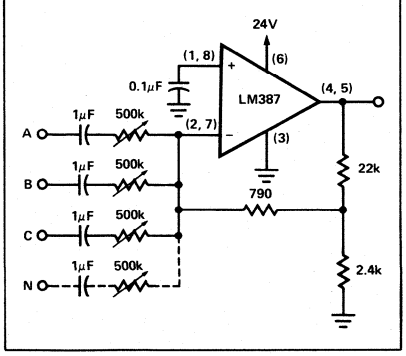


TYPICAL APPLICATIONS

TYPICAL MAGNETIC PHONO PREAMPLIFIER

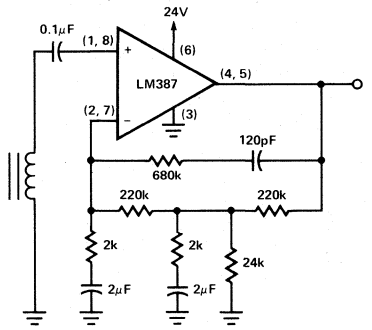


AUDIO MIXER

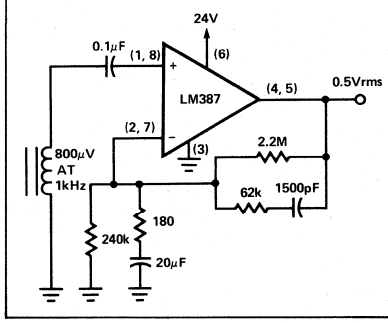


TYPICAL APPLICATIONS (Cont'd)

TWO-POLE FAST TURN-ON NAB TAPE PREAMPLIFIER



TYPICAL TAPE PLAYBACK AMPLIFIER



TCA 440-N

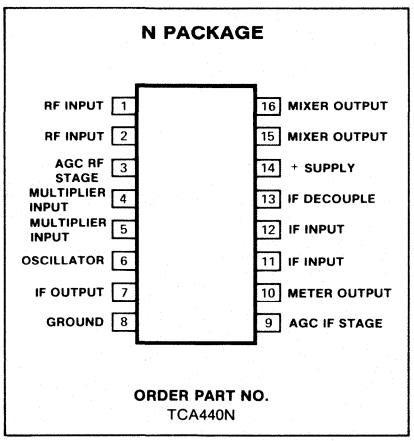
DESCRIPTION

TCA440 is a monolithic IC, especially developed for AM receivers up to 50MHz. It includes a RF stage with AGC, a balanced mixer, separate oscillator and an IF amplifier with AGC. Because of its low current consumption and of its internal stabilization the TCA440 is perfectly suited for battery operated portables, car and home radios.

FEATURES

- **Balanced circuit**
- **Separately controllable prestage**
- **Multiplicative push-pull mixer with separate oscillator**
- **High signal handling capability even with 4.5V supply voltage**
- **100dB feedback control range in 5 stages**
- **Direct connection for tuning meter**
- **Minimum external components**

PIN CONFIGURATION

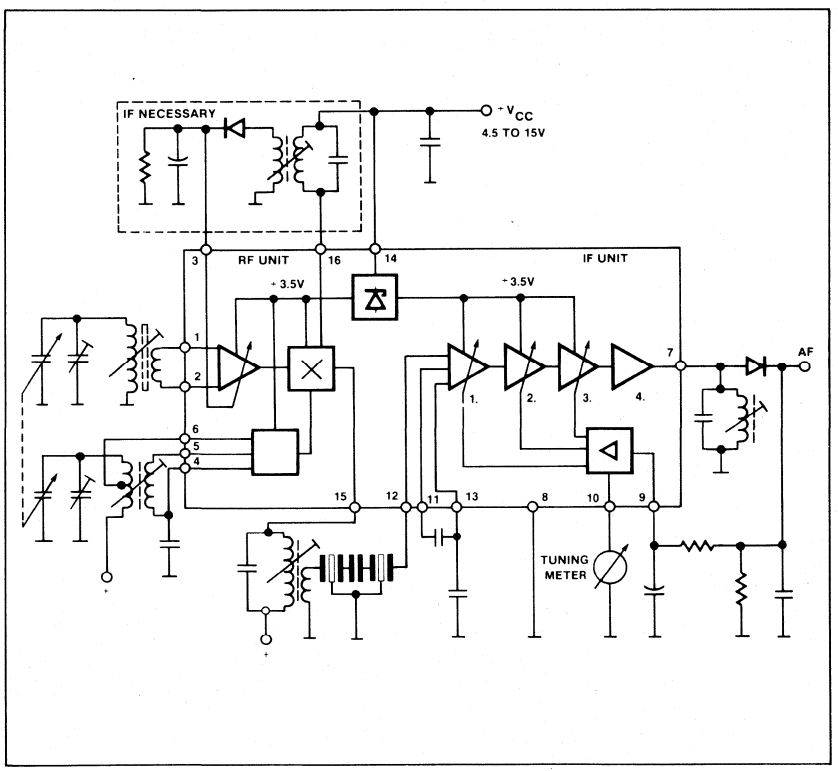


ORDER PART NO.
TCA440N

ABSOLUTE MAXIMUM RATINGS

PARAMETER		RATING	UNIT
V_{CC}	Supply voltage	15	V
T_{amb}	Ambient temperature in operation	-15 to +80	°C
T_s	Storage temperature	-30 to +125	°C
V_{CC}	Range of operation	4.5 to 15	V

BLOCK DIAGRAM



TUNING METER

Recommended instruments:

or $500\mu A$ ($R_1 = 800k\Omega$)
$300\mu A$ ($R_1 = 1.5k\Omega$)

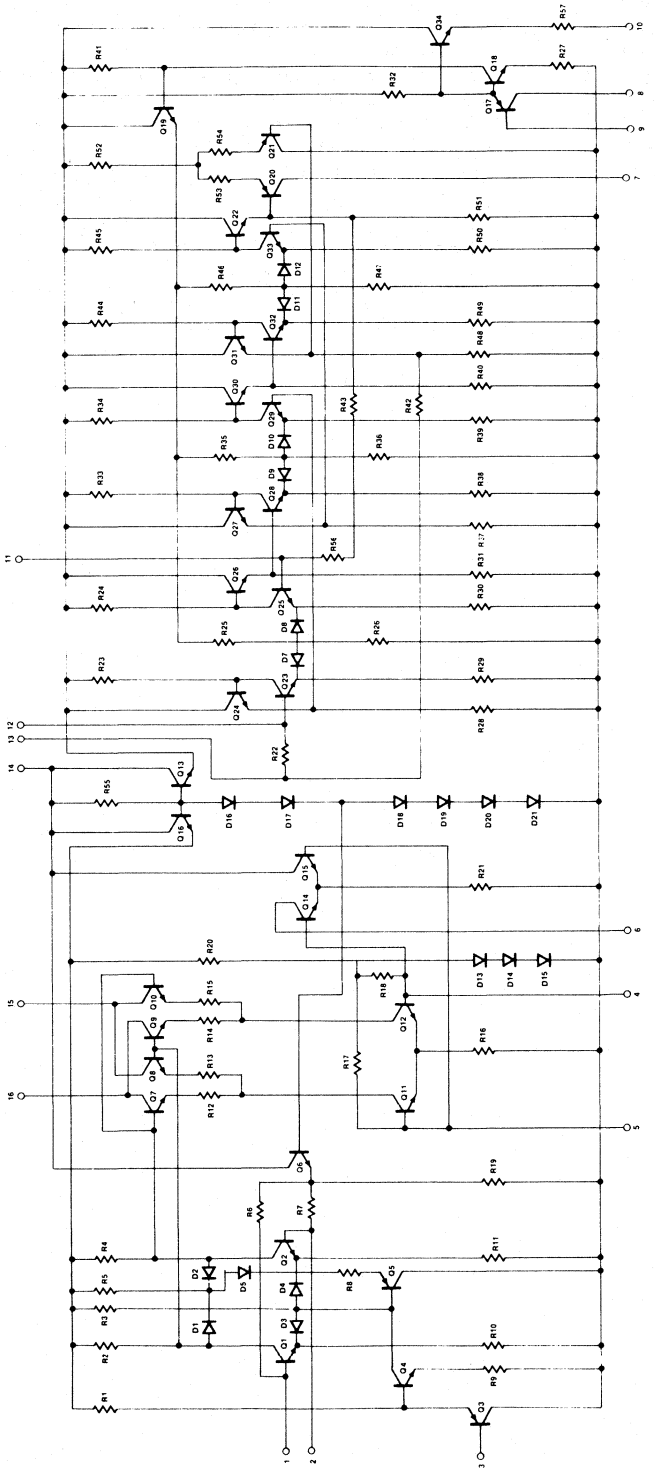
The IC offers at pin 10 a tuning meter voltage of 600 mV_{EMP} max. with a source impedance of approx. 400Ω.

FUNCTION

As pictured in the circuit diagram the TCA440 comprises two control loops independent of each other which control the RF stage and the IF stages. By AGCing the RF stage, excellent signal handling is obtained. A voltage of $2.6V_{pp}$ on the IC input can be handled with very low distortion. The push-pull mixer operates multiplicatively, thereby resulting in few harmonic mixing products and whistling points. The oscillator which is separated from the mixer is also apted excellently for short waves. From the AGC of the RF amplifier a voltage is derived for a tuning meter which can be connected directly to the meter. The symmetric composition of the circuit provides high stability against oscillation and, at the same time, an AGC range of more than 100dB. The bridge circuit of the mixer provides good isolation of the oscillator.

TCA 440-N

EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS V_{CC} = 9V, T_A = 25°C unless otherwise specified.

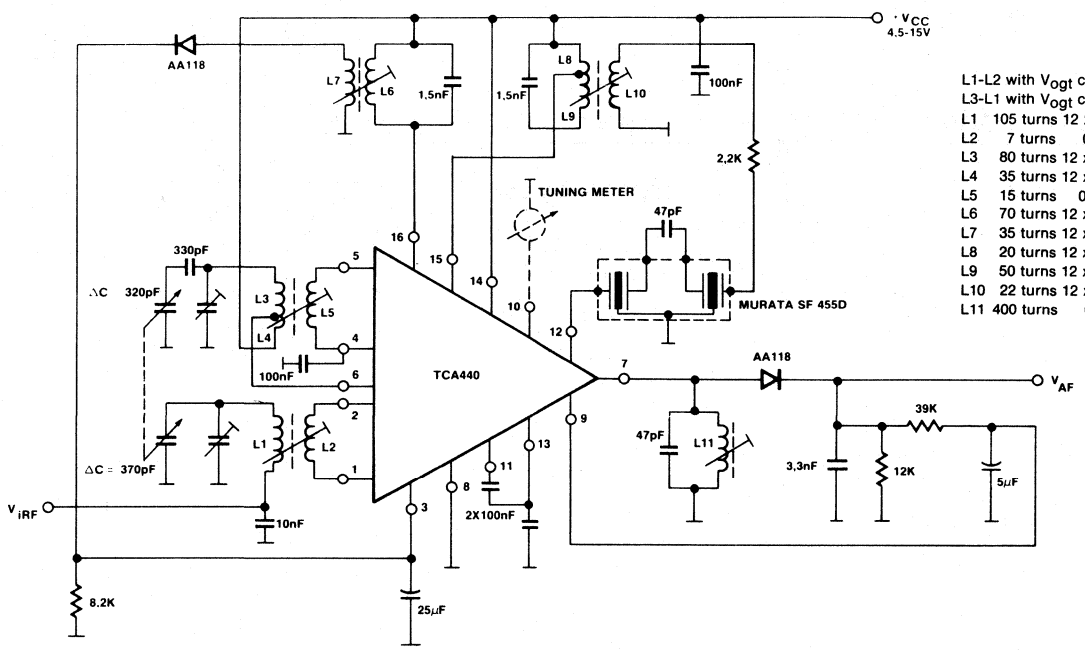
PARAMETER		TEST CONDITIONS	TCA 440 Min	TCA 440 Typ	TCA 440 Max	UNIT
I_{CC}	Total current consumption at:	V_{CC} = 4.5V		7		mA
		V_{CC} = 9V		10.5		mA
		V_{CC} = 15V		12		mA

AC ELECTRICAL CHARACTERISTICS V_{CC} = 9V, T_A = 25°C, f_{IRF} = 600kHz, fmod = 1kHx unless otherwise specified.

PARAMETER		TEST CONDITIONS	TCA 440 Min	TCA 440 Typ	TCA 440 Max	UNIT
ΔG_{RF}	RF level deviation for (m = 80%)	ΔV_{AF} = 6dB		65		dB
		ΔV_{AF} = 10dB		80		dB
V_{AFeff}	AF output voltage for V_{IRF} (symm. measured at 1-2)	m = 80% V_{IRF} = 20µV		140		mV
		V_{IRF} = 1mV		260		
		V_{IRF} = 500mV		350		
		m = 30% V_{IRF} = 20µV		50		mV
		V_{IRF} = 1mV		100		
		V_{IRF} = 500mV		130		
V_{IRF}	Input sensitivity (measured at 60Ω, f_{IRF} = 1MHz, m = 30%/0%, R_G = 540Ω)	At signal-to-noise distance				
		$\frac{S+N}{N}$ = 6dB		1		µV
		$\frac{S+N}{N}$ = 26dB		7		µV
		$\frac{S+N}{N}$ = 58dB		1		mV
RF unit						
f_{IRF}	Input frequency range			0 to 50		MHz
f_{IF}	Output frequency	$f_{IF} = f_{OSC} - f_{IRF}$		460		kHz
ΔG_V	Control range			38		dB
V_{IRFpp}	Input voltage	for 600kHz, m = 80%, for Overdrive, k_{AF} = 10%, Symmetrically measured at pins 1 & 2 (mean carrier value)		2.6		Vpp
V_{IRFeff}				.5		V
s_{IF}	IF suppression between 1-2 to 15			20		dB
Z_I	RF input impedance	Asymmetrical coupling at:				
		G_{RFmax}		2/5		kΩ/pF
		G_{RFmin}		2.2/1.5		kΩ/pF
		Symmetrical coupling at:				
		G_{RFmax}		4/5		kΩ/pF
		G_{RFmin}		4.5/1.5		kΩ/pF
Z_{gosc}	Mixer output impedance	Pins 15 or 16		250/4.5		kΩ/pF
IF unit						
f_{IIF}	Input frequency range			0 to 2		MHz
ΔG_V	Control range at 460kHz			62		dB
V_{IFeff}	Input voltage	Mean carrier value at G_{min} for Overdrive (k_{AF} = 10%), measured at Pin 12 (60Ω to ground, f_{IF} = 460kHz, m = 80%, f_{mod} = 1kHz)		200		mV
V_{AFeff}	AF output voltage	V_{IIF} at 60Ω (Pin 12) f_{mod} = 1kHz				
		V_{IF} = 30µV, m = 80%		50		mV
		V_{IF} = 3mV, m = 80%		200		mV
		V_{IF} = 3mV, m = 30%		70		mV
Z_I	IF input impedance	Asymmetrical coupling		3/3		kΩ/pF
Z_g	IF output impedance	Pin 7		200/8		kΩ/pF

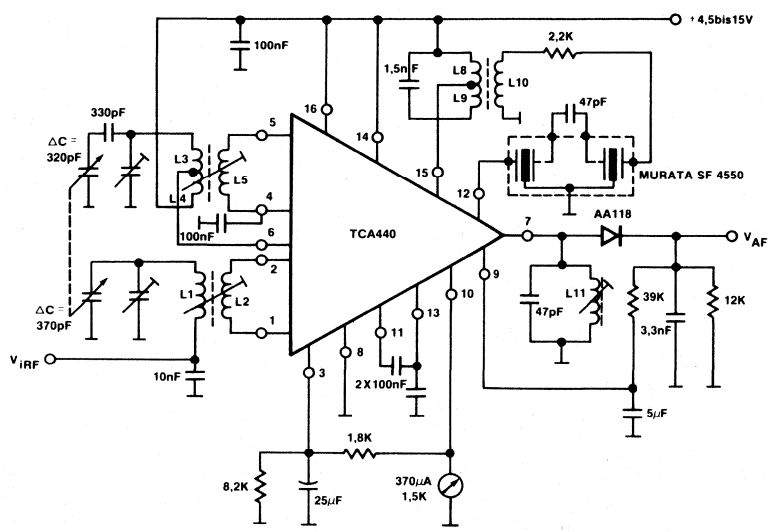
TYPICAL APPLICATIONS

APPLICATION EXAMPLE FOR MW



L1-L2 with V_{ogt} coil set D21-2375.1
L3-L1 with V_{ogt} coil set D41-2519
L1 105 turns 12 x 0.04 CuLS
L2 7 turns 0.10 CuL
L3 80 turns 12 x 0.04 CuLS
L4 35 turns 12 x 0.04 CuLS
L5 15 turns 0.10 CuL
L6 70 turns 12 x 0.04 CuLS
L7 35 turns 12 x 0.04 CuLS
L8 20 turns 12 x 0.04 CuLS
L9 50 turns 12 x 0.04 CuLS
L10 22 turns 12 x 0.04 CuLS
L11 400 turns 0.06 CuL

APPLICATION EXAMPLE FOR MW

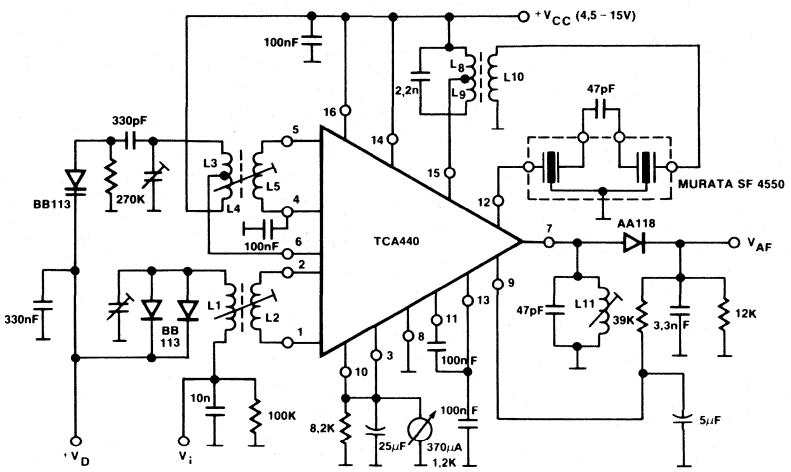


Prestage control is derived from IF control

L1 105 turns 12 x 0.04 CuLS
L2 7 turns 0.10 CuL
L3 80 turns 12 x 0.04 CuLS
L4 35 turns 12 x 0.04 CuLS
L5 15 turns 0.10 CuL
L8 20 turns 12 x 0.04 CuLS
L9 50 turns 12 x 0.04 CuLS
L10 22 turns 12 x 0.04 CuLS
L11 400 turns 0.04 CuL
L1-L2 with V_{ogt} coil set D21-23751
L3-L11 with V_{ogt} coil set D41-2519

TYPICAL APPLICATIONS (Cont'd)

APPLICATION EXAMPLE FOR AM USING VARICAP DIODES BB 113

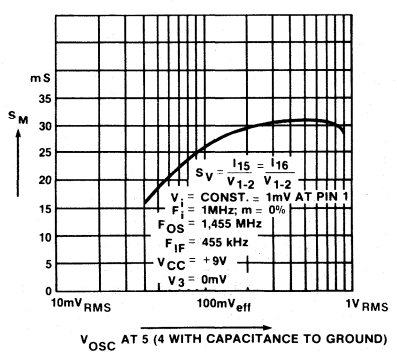


L1 105 turns 12 x 0.04 CuLS
L2 7 turns 0.10 CuL
L3 80 turns 12 x 0.04 CuLS
L4 35 turns 12 x 0.04 CuLS
L5 15 turns 0.10 CuL
L8 20 turns 12 x 0.04 CuLS
L9 50 turns 12 x 0.04 CuLS
L10 22 turns 12 x 0.04 CuLS
L11 400 turns 0.06 CuL

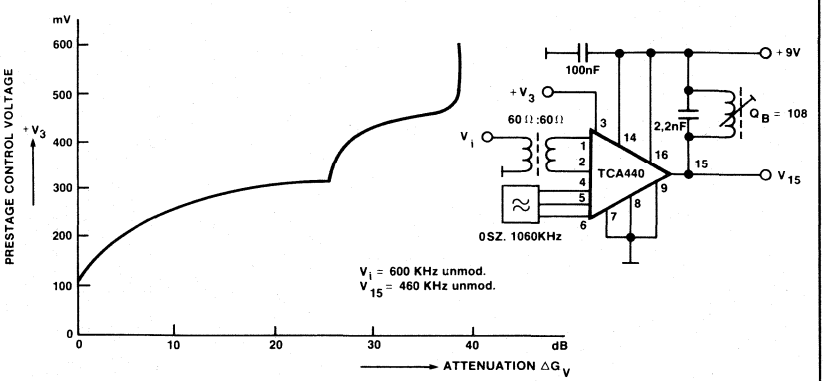
L1-L2 with Vogt coil set D21-23751
L3-L11 with Vogt coil set D41-2519

V_D = 8.5V→f_i = 800kHz
V_D = 30V→f_i = 1620kHz

CONVERSION CONDUCTANCE vs OSCILLATOR VOLTAGE



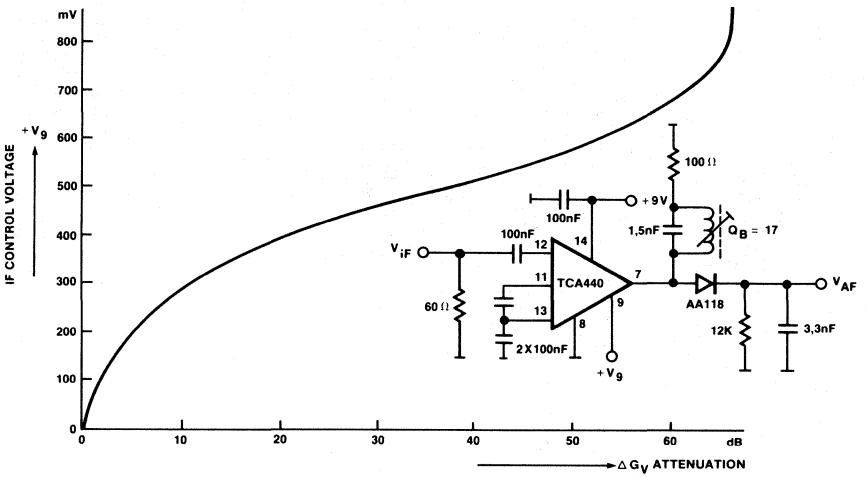
RF STAGE CONTROL



The input is not power matched and can be driven with a higher resistance, V_i is chosen so that a constant V_{15} is obtained ($50mV_{pp}$).

TYPICAL APPLICATIONS (Cont'd)

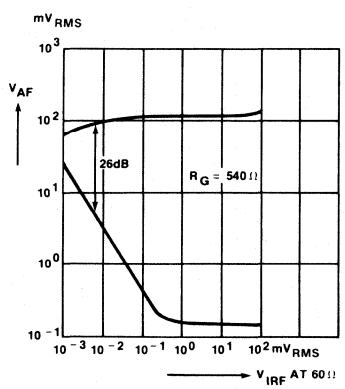
IF CONTROL



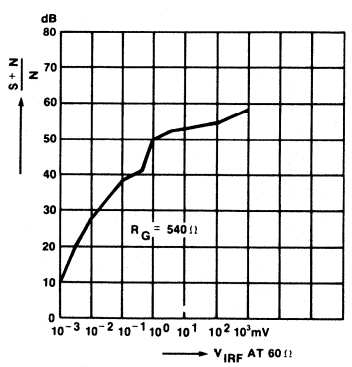
V_{IF} (469kHz; m = 80%; f_{mod} = 1kHz) is chosen so that always a constant V_{AF} is obtained ($200mV_{RMS}$)

TYPICAL PERFORMANCE CHARACTERISTICS

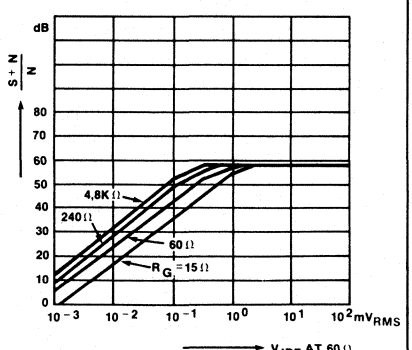
AF OUTPUT VOLTAGE AND NOISE FIGURE vs RF INPUT VOLTAGE (switching position 1)



SIGNAL TO NOISE DISTANCE vs RF INPUT VOLTAGE (switching position 2)

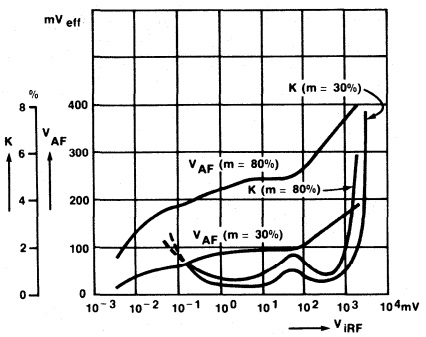


SIGNAL TO NOISE DISTANCE vs RF INPUT VOLTAGE (parameter is generator impedance) (switching position 1)

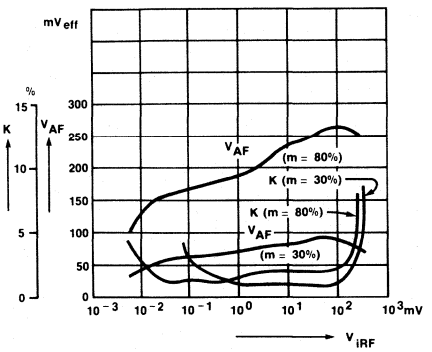


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

TEST FIGURES FOR APPLICATION EXAMPLE FOR MW HARMONIC DISTORTION AND AF OUTPUT VOLTAGE vs RF INPUT VOLTAGE MEASURED SYMMETRICALLY AT PINS 1 AND 2 f_i = 1MHz, f_{mod} = 1kHz, f_{IF} = 455kHz, V_{cc} = 9V



TEST FIGURES FOR APPLICATION EXAMPLE FOR AM USING BB 113 f_i = 1MHz, f_{mod} = 1kHz, f_{IF} = 455 kHz, V_{cc} = 9V, V_{IRF} measured symmetrically at pins 1 and 2

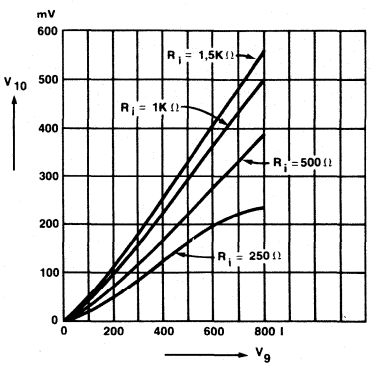


Example for moving coil instruments

R_i for full-scale deflection

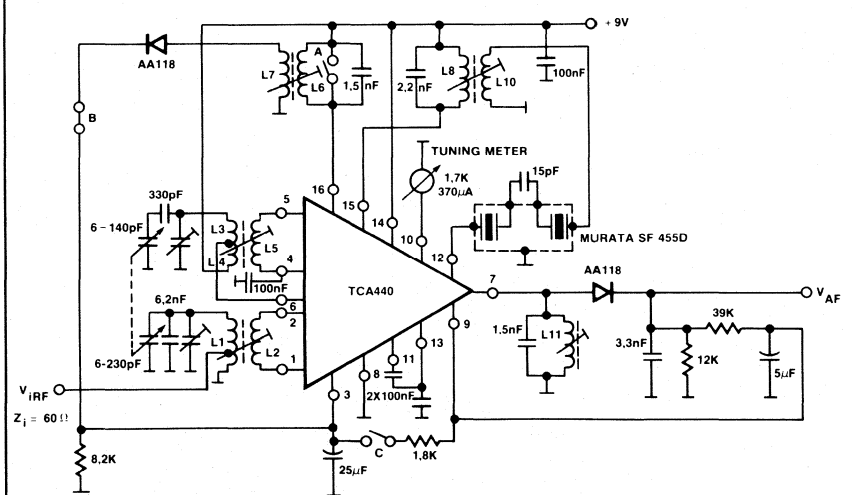
1.5kΩ	100μA
1.5kΩ	170μA
2kΩ	200μA
350Ω	500μA

TUNING METER VOLTAGE vs IF CONTROL VOLTAGE (parameter is impedance of tuning meter)



TEST CIRCUITS

TEST CIRCUIT FOR NOISE FIGURE



L1-L2 M25 pot core
L3-L11 with Vogt coil set D41-2519

L1	2 + 6	turns	6 x 12 x 0.04 CuLS
L2	n		0.15 CuL
L3	90	turns	12 x 0.04 CuLS
L4	35	turns	12 x 0.04 CuLS
L5	15	turns	0.10 CuL
L6	70	turns	12 x 0.04 CuLS
L7	35	turns	12 x 0.04 CuLS
L8	60	turns	12 x 0.04 CuLS
L10	22	turns	12 x 0.04 CuLS
L11	68	turns	0.06 CuL

switch A	switch B	switch C	
off	on	off	separate RF stage control
on	off	on	RF stage control voltage derived from IF control voltage

f_i = 1MHz; m = 30%

n(turns)	$R_{Generator}$(Ω)
1	15
2	60
4	240
6	540
9	1,2K
12	2,2K
18	4,8K

SECTION 12
TV CIRCUITS

Section 12—TV CIRCUITS

12

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

ULN2211-N

DESCRIPTION

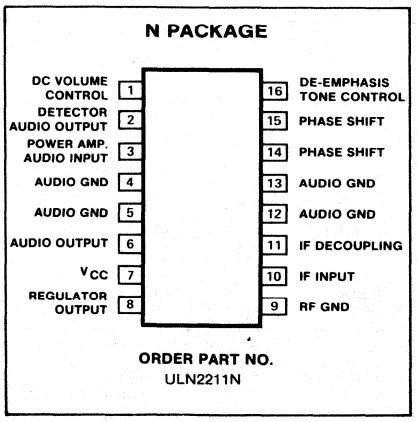
The ULN2211 contains a limiting amplifier, an FM quadrature detector, an electronic gain control stage and a 2-watt audio output stage. It can be used to detect and amplify any FM modulated signal having a 0.1–20MHz carrier frequency.

It is especially recommended as a complete TV sound channel requiring few external components and only one tuning adjustment for the 4.5MHz tank circuit. Provision is made for 6dB/octave de-emphasis and tone control.

FEATURES

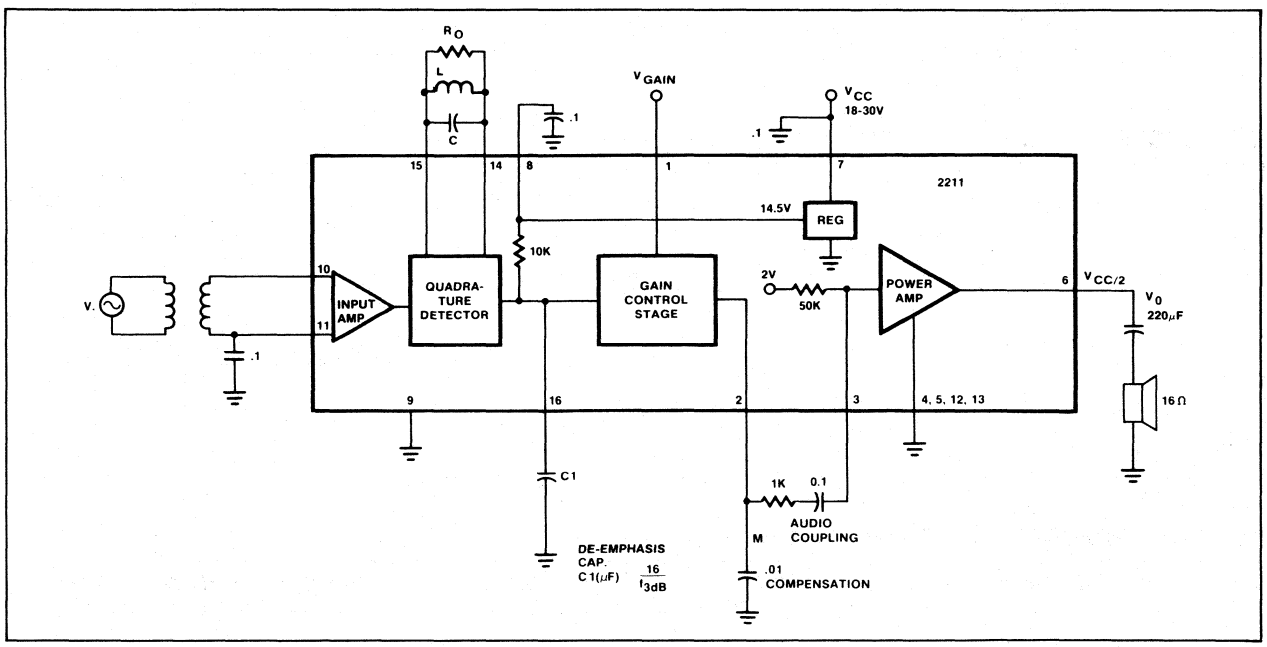
- **2-watt output**
- **DC volume control attenuation, 70dB typ**
- **Limiter gain of 70dB**
- **Limiting threshold typically less than 200μV**
- **Automatic thermal shutdown**
- **Over-current limiting**
- **20dB ripple rejection**
- **Single supply operation (18-30V)**
- **No crossover distortion**

PIN CONFIGURATION



NOTE: Internal power dissipation in watts.

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage, V_{CC}	+30	V
Input voltage (pin 10)	+4.0	Vrms
Power consumption (internal)	See Figure 1	
Operating temperature	-25 to +70	°C
Storage temperature	-65 to +150	°C

AC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_{CC} = +24V; f_o= 4.5MHz, Δf = 25kHz, f_m = 400Hz unless otherwise specified.

PARAMETER		TEST CONDITIONS	ULN2211			UNIT
			Min	Typ	Max	
V_{TH}	Recovered audio limiting threshold[1]	Adjust V_1 for V_0 = 5.6V (P_O = 2W)		150	350	μV
AMR	AM rejection[2]	Adjust V_1 for 2W, V_{IN} = 10mV	30	55		dB
V_O	Recovered AF voltage (pin 16)	V_{IN} = 10mV, f = 25kHz	500	800		mVrms
THD_D	Detector output distortion	V_{IN} = 10mV, f = 25kHz		1.0	2.0	%
THD_O	Output distortion	P_O = 2W, R_L = 16		2	10	%
	Playthrough	V_1 = 0		10	15	mVrms
I_{MAX}	Current limit	R_L = 0		800		mA
V_N	Noise	V_{IN} = 0, V_1 = +15V		15	20	mVrms
A_V	Power AMP voltage gain[3]		25	27	29	dB
V_O/V_{CC}	Output tracking (V_6/V_7)	V_{CC} = 18 to 27V		0.5		V/V
Z_{IN}	Audio amp input impedance	f = 1kHz	40	50	60	kΩ

NOTES

1. Measured with output at -3dB, reference V_{IN} = 10mV, Δf = 25kHz
2. $AMR = 20 \log \frac{V_0 \text{ (FM, } \Delta f = 7.5\text{kHz)}}{V_0 \text{ (AM, 30\%)}}$
3. Set V_0 = 1Vrms. $A_V = 20 \log \frac{1}{(V3\text{rms})}$

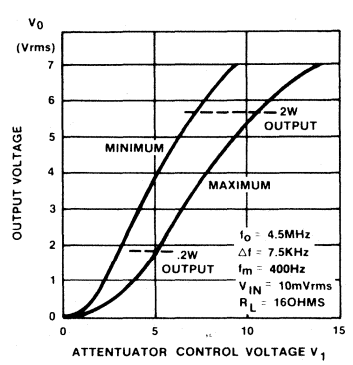
DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_{CC} = +24V unless otherwise specified.

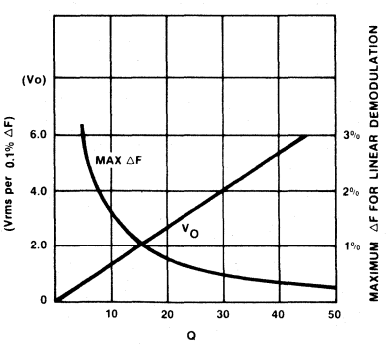
PARAMETER		TEST CONDITIONS	ULN2211			UNIT
			Min	Typ	Max	
I_{CC}	Standby current	V_{IN} = 0	25	45	60	mA
V_6	Terminal voltage		10.5	12.5	14.5	V
V_{10}				1.4		V
V_{11}				1.4		V
V_{14}, V_{15}				4.0		V
V_{16}				8.0		V
V_8			14	14.5	16	V
V_2				10		V
V_3				2.6		V

TYPICAL PERFORMANCE CHARACTERISTICS

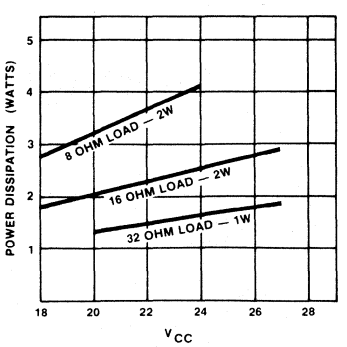
GAIN CONTROL CHARACTERISTIC



OUTPUT VOLTAGE AND LINEAR RANGE vs Q OF DETECTOR COIL



TYPICAL POWER DISSIPATION vs LOAD RESISTANCE AND V_{CC}



MAXIMUM ALLOWABLE POWER DISSIPATION

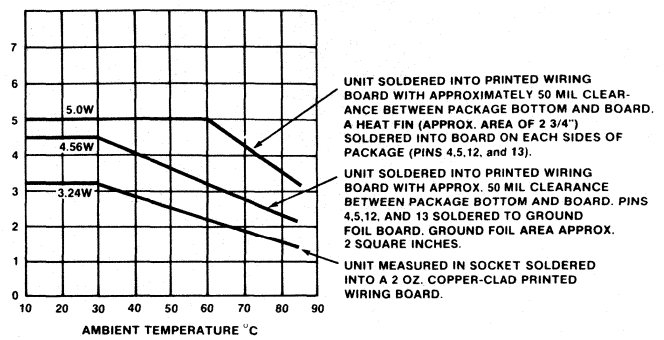


Figure 1

TYPICAL APPLICATION

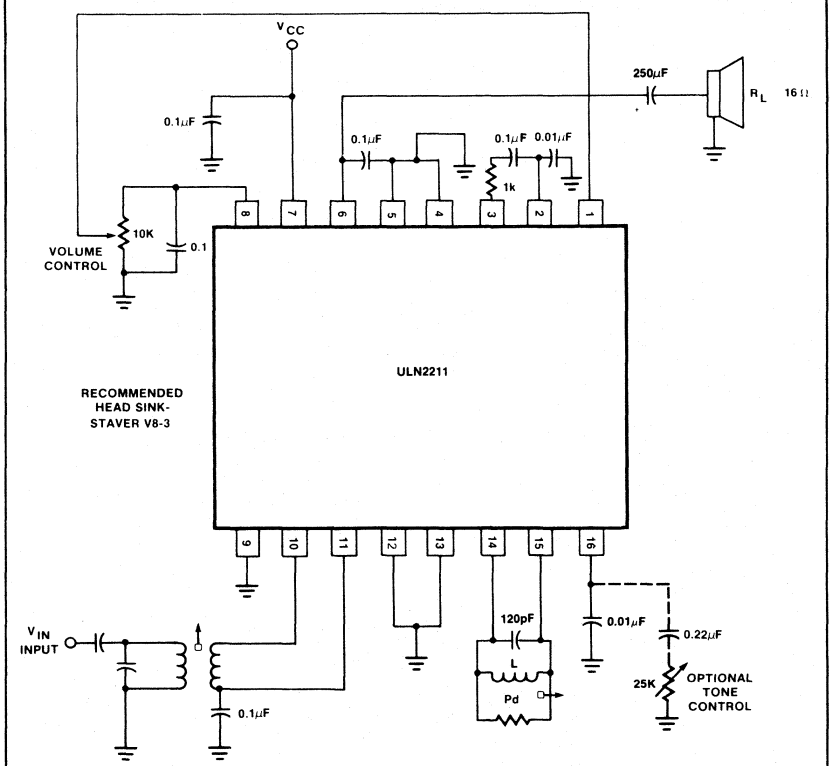


Table 1

f_o	L	R_D
4.5mHz	10-14μH	∞
10./mHz	1-3μH	5K

Figure 2

TBA/120S-N

DESCRIPTION

An eight stage amplifier with balanced demodulator for amplifying, limiting and the demodulation of FM signals, specially designed for the sound-IF in TV and RF-IF amplifier in radios. An electronic Volume Control for the audio outputsignal is also provided.

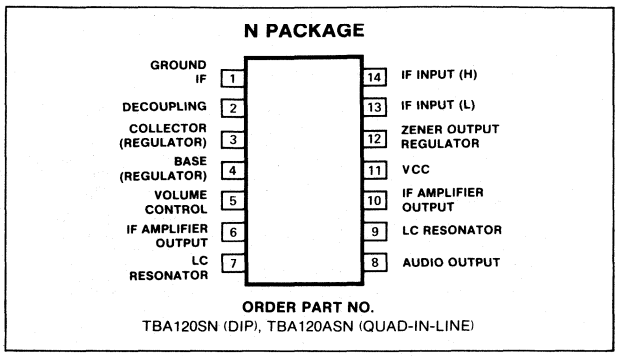
Groups:

TBA 120 S is delivered in groups:
An attenuation of -30dB of the audio outputsignal requires a resistor from pin 5 to ground as indicated in the table.

Group	2	3	4	5
Value (kΩ)	1.9 to 2.2	2.1 to 2.5	2.4 to 2.9	2.8 to 3.3

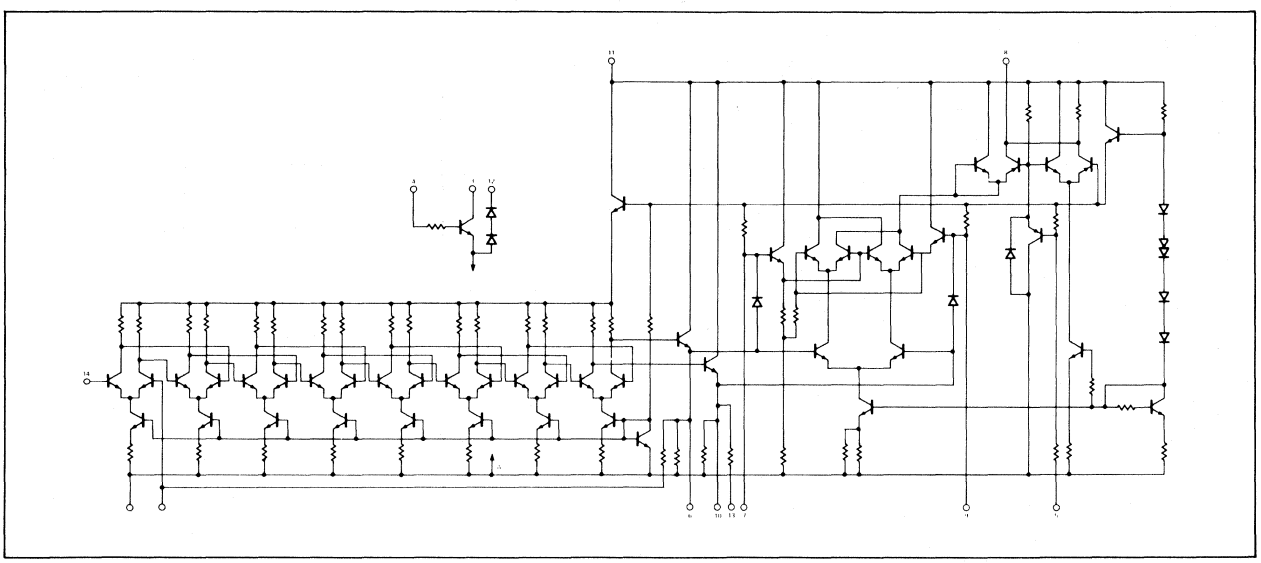
For example, devices marked TBA120S-3 indicate group 3.

PIN CONFIGURATION



ORDER PART NO.
TBA120SN (DIP), TBA120ASN (QUAD-IN-LINE)

EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage	18	V
Operating temperature range	-15 to +70	°C
Storage temperature	-40 to +125	°C
Power dissipation	400	mW
max 1 minute	500	mW
Supply current	15	mA
max 1 minute	20	mA
Current 13	1	mA
14	1	mA
Operating supply voltage	6 to 18	V
Frequency range	0 to 12	MHz

DC ELECTRICAL CHARACTERISTICS (V_{CC} = 12V; T_{amb} = 25°C)

PARAMETER		TEST CONDITIONS	TBA120S			UNIT
			Min	Typ	Max	
I_{CC}	Total current requirement	$R_5 = \infty$ $R_5 = 0$	10 12	14 16	18 20	mA mA
V_8 V_5	dc-portion of the output signal Voltage	$V_1 = 0$ -1dB down -70dB down		7.3 2.4 1.3	 2.6 	V V V

AC ELECTRICAL CHARACTERISTICS T_A = 25°C, V_{CC} = 12V unless otherwise specified.

PARAMETER		TEST CONDITIONS	TBA120S			UNIT
			Min	Typ	Max	
G_V	IF-voltage gain V_6/V_{14}	f = 5.5MHz		68		dB
V_{QPP}	IF-output voltage at limiting; each output			250		mV
V_{AFrms}	AF-output voltage	f = 5.5MHz; $\Delta f = \pm 50$kHz; V_I = 10mV; f_{mod} = 1kHz; Q = 45; k = 4% f = 5.5MHz; $\Delta f = \pm 50$kHz; V_I = 10mV; f_{mod} = 1kHz; Q = 20; k = 1%		1.1 0.55		V V
V_{lim}	Input voltage starting limiting	f = 5.5MHz; f = 50kHz; f_{mod} = 1kHz; Q = 45;		30	60	μV
Z_I R_Q	Input impedance Output resistance	f = 5.5MHz Pin 8	15/6	40/4.5 2.6		kΩ/pf kΩ
V_{AFmax} V_{AFmin} a_{AM}	Range of volume control AM-suppression	f = 5.5MHz; f = +50Hz; $V_I = 500\mu$V; f_{mod} = 1kHz; m = 30%	 45	70 55	 	dB dB
R_5	Potentiometer resistance	-1dB down -70dB down	 1.0	3.7 1.4	4.7 	kΩ kΩ
CHARACTERISTICS OF THE AUXILIARY CIRCUIT V_{12} R_Z	 Z-voltage Z-resistance	 I_{12} = 5mA	 11.2	 12 30	 13.2 	 V Ω
$V_{CEO\ T43}$ h_{FE}	Breakdown voltage Current gain	$I_4 = 0$; $I_3 = 500\mu$A I_3 = 1mA	13 30	 120	 	 V

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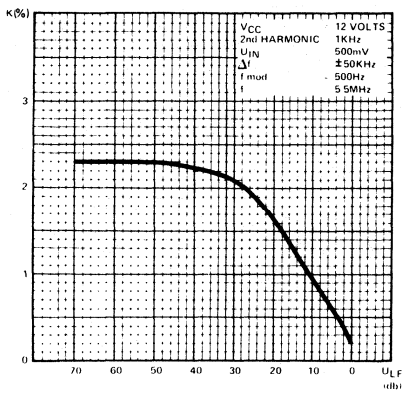
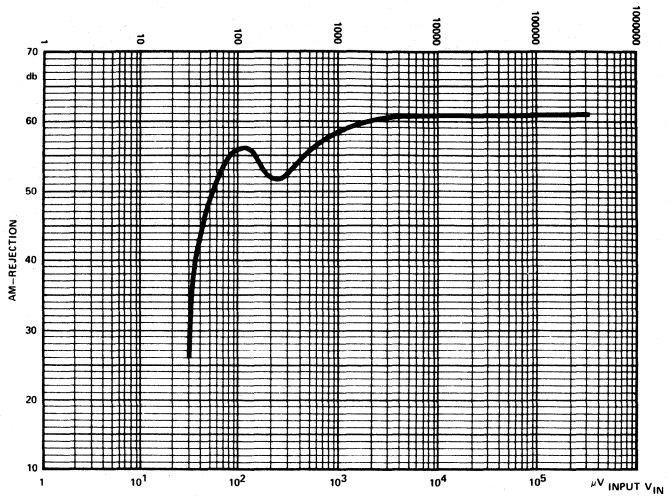
TYPICAL PERFORMANCE CHARACTERISTICS

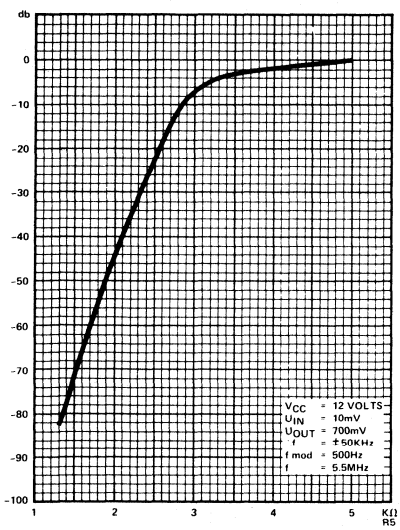
TYPICAL CURVE FROM PRODUCT SELECTION NR3.



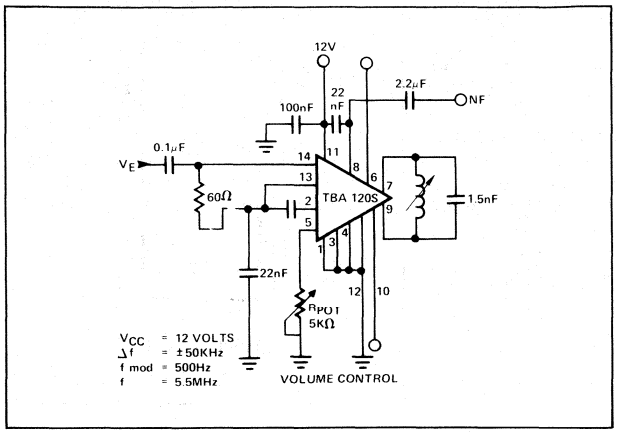
TYPICAL CURVE FROM PRODUCE-REFLECTION NR3.



VOLUME CONTROL SIGNETICS TBA120S



TEST CIRCUIT



12

TBA1441-N

DESCRIPTION

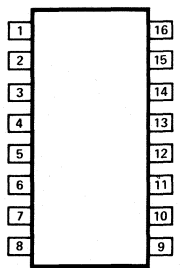
The TBA1441 (for npn tuner pre-stages) has been developed from the TBA440P/N. Improvements are as follows:

- Reduced residual IF at outputs 11 and 12
- Reduced residual IF at pin 13
- Considerably improved intermodulation distance
- Excellent tuning attitude even with low-ohmic tank circuit at demodulator

The IC's contain a high-amplifying controllable video IF amplifier, a controlled demodulator and two low-resistance video outputs with positive- and negative-going signals as well as the complete keyed control and delayed tuner control.

- Large control range with low noise and wide dynamic range
- High sensitivity
- Controlled demodulator, so minimum 1.07MHz disturbances
- Internal temperature stabilization
- The white levels of the video signals at the positive and negative video output are independent of the operating voltage
- The white and black levels can be adjusted separately

N PACKAGE



ORDER PART NO.
TBA1441N

ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
V_{13}	Supply voltage	15*	V
V_4	Voltages	5	V
V_5		20	V
V_{14}		5	V
R_{8-9}	Ohmic resistance between pins 8 and 9	≤ 20	Ω
R_{THSA}	Thermal resistance (system-air)	100	K/W
T_J	Junction temperature	150	°C
T_S	Storage temperature	-40 to +125	°C
V_{13}	Supply voltage range	10.5 to 15	V
T_A	Ambient temperature in operation	-25 to +60	°C

*NOTE
Briefly 16.5V

DC ELECTRICAL CHARACTERISTICS

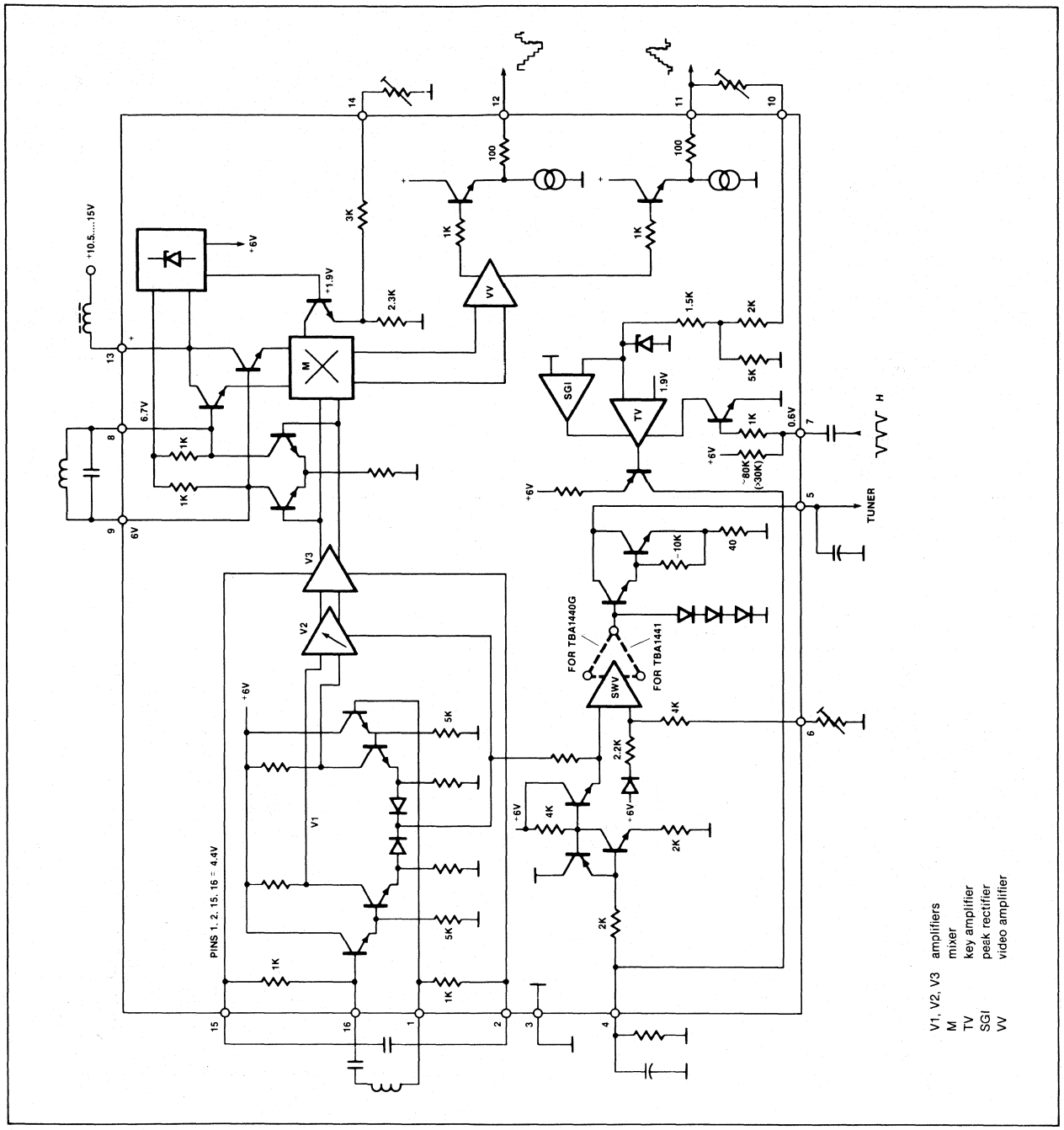
V_{13} = 13V, f_{IIF} = 38.9MHz; T_A = 25°C; all data with reference to ground, unless otherwise specified.

	PARAMETER	TEST CONDITIONS	TBA 1441 Min	TBA 1441 Typ	TBA 1441 Max	UNIT
I_{13}	Current consumption	V_{13} = 15V	34	47	60	mA
V_{11}	DC voltage at output 11	V_{13} = 15V; V_1 = 0				
		R_{14-3} = ∞		5.5		V
		R_{14-3} = 0		9.6		V
V_{12}	DC voltage at output 12	V_{13} = 15V; V_1 = 0				
		R_{14-3} = ∞		1.9		V
		R_{14-3} = 0		3.5		V
$V_{10} = V_{11}$	AGC threshold	V_{10} = sync pulse level for R_{10-11} = 0		1.9		V
V_{11sync}	Sync pulse level with async or without gating pulses	Peak level control		.5		V
V_4	IF control voltage	For max. gain	0		.5	V
		For min. gain	2.5		5	V
$-V_7$	Gating pulse voltage		2		5	V
I_{11}; I_{12}	Output current	To ground			5	mA
		TO $+V_{13}$			-1	mA

NOTES

1. According to test circuit; V_1 = effective sync pulse level at 60Ω.
2. Test level a_{cc} = -3dB
   a_{sc} = -20dB referring to picture carrier.

EQUIVALENT SCHEMATIC



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AC ELECTRICAL CHARACTERISTICS

(V_{13} = 13V; f_{IIF} = 38.9MHz; T_A = 25°C; all data with reference to ground, unless otherwise specified.

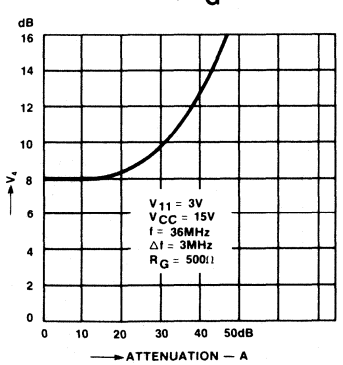
PARAMETER		TEST CONDITIONS	TBA1441			UNIT
			Min	Typ	Max	
$\Delta V_{11}/\Delta V_{13}$ $\Delta V_{12}/\Delta V_{13}$	White level deviation			100 20		mV/V mV/V
R_{14-3} R_{10-11}	Resistance for ΔV_{11} = 1V Resistance for sync pulse level deviation of 1V			8.5 2.4		kΩ kΩ
I_5	Control current for tuner prestage	V_5 > 2V TBA1440G: 10dB after AGC TBA1441: 10dB previous to AGC	10	15		mA
V_{11}; V_{12}	Residual IF (basic frequency)			10		mV
Z_{1-16}	Input impedance	At max. gain At min. gain		1.8/2 1.9/0		kΩ/pF kΩ/pF
V_1 B_{video}	Input voltage[1] Video band width	V_{11} = 3V_{PP} -3dB	70 6	100 7	300	μV MHz
ΔG_v a $Z_{q\ 8-9}$	AGC range Intermodulation with reference color carrier[2] Output impedance			55 45 2/2.5		dB dB kΩ/pF

NOTES

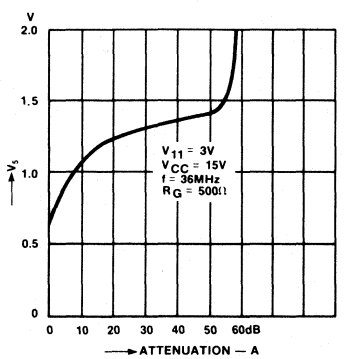
1. According to test circuit; V_1 = effective sync pulse level at 60Ω.
2. Test level a_{cc} = -3dB
   a_{sc} = -20dB referring to picture carrier.

TYPICAL PERFORMANCE CHARACTERISTICS

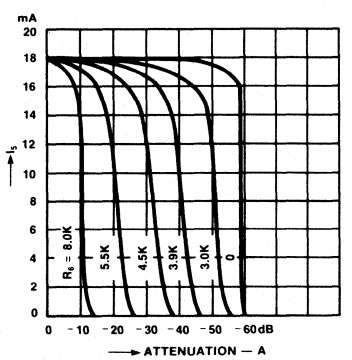
NOISE FIGURE vs ATTENUATION (MEASURED AD VIDEO FREQUENCY)
$-V_{fb}$ = 3V, V_{CC} = 15V, f = 36MHz, Δf = 3MHz, R_G = 500Ω



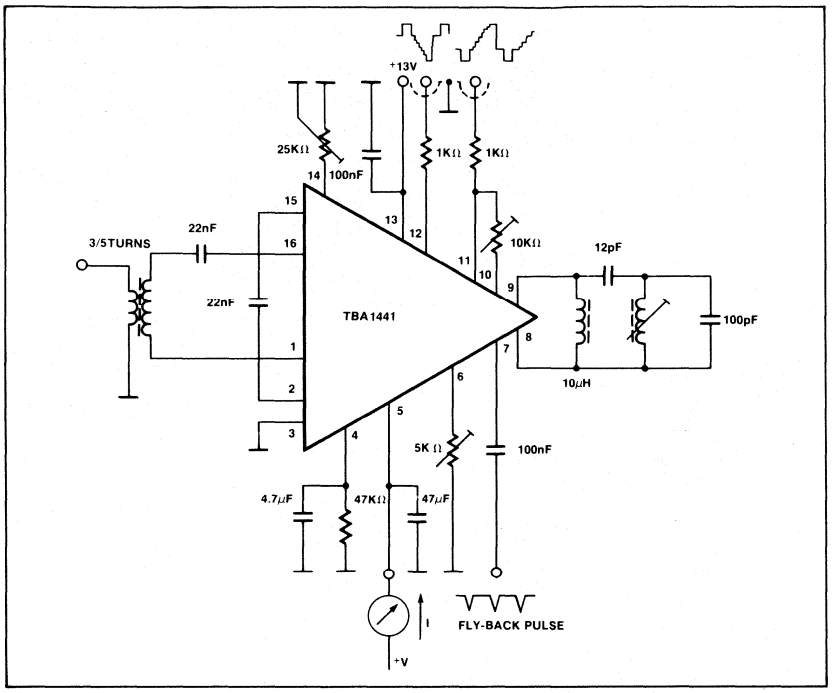
CONTROL VOLTAGE vs ATTENUATION
$-V_{fb}$ = 3V, V_{CC} = 15V, f = 36MHz, RG = 500Ω



TUNER CONTROL CURRENT vs ATTENUATION
R_G = PARAMETER
TBA1441



TEST CIRCUIT

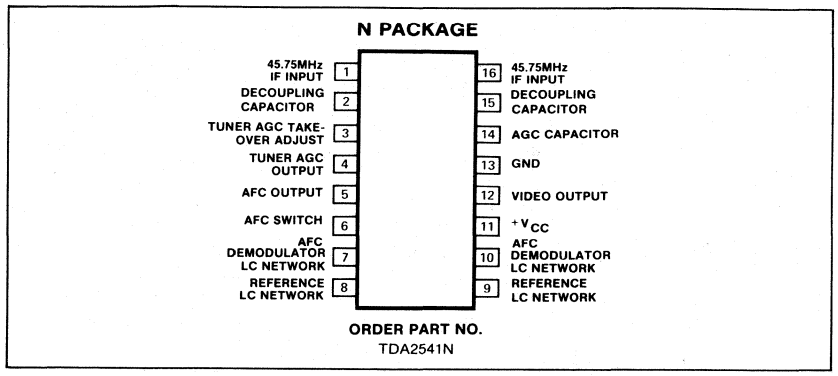


TDA2541-N

FEATURES

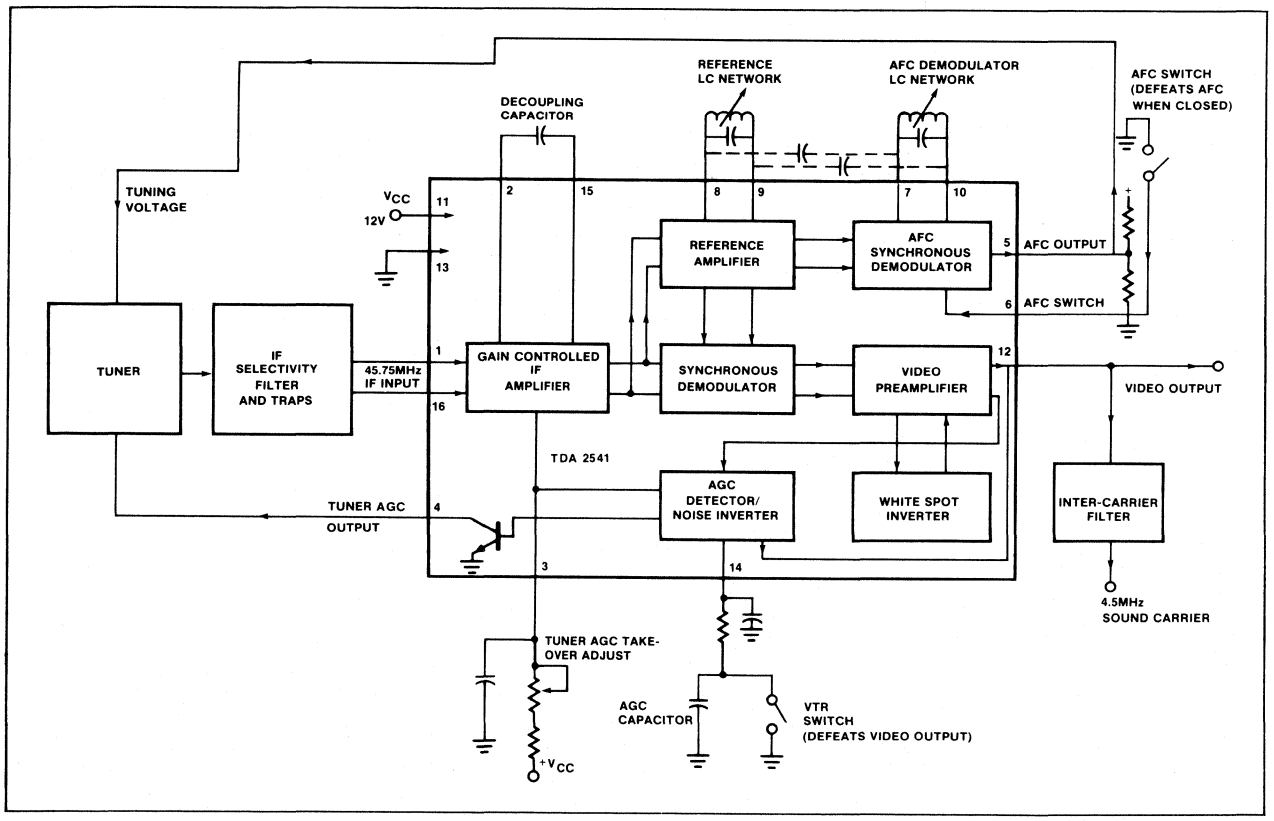
- Performs all video IF functions
- Provides 63dB IF AGC range
- Tuner AGC output
- Black and white noise inverting circuits
- AFC output
- High input sensitivity—100μV typical
- 53dB S/N ratio at 40dB gain control
- Minimal external components and adjustments required
- Switch disabling of video to allow direct video interface with VTR

PIN CONFIGURATION



ORDER PART NO.
TDA2541N

SIMPLIFIED BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage V_{CC}	14	V
Supply current (V_{CC} = 14V)	75	mA
Power dissipation (V_{CC} = 14V)	1.0	W
Operating temperature	0 to +70	°C
Storage temperature	-65 to +150	°C

DC ELECTRICAL CHARACTERISTICS

T_A = 25°C, V_{CC} = 12V unless otherwise specified.

PARAMETER		TEST CONDITIONS	TDA 2541			UNIT
			Min	Typ	Max	
I_{CC}	Supply current		37		67	mA
$V_{th(AFC)}$	AFC switched off below			2.5		V
I_5	AFC symmetry	V_i = 0, V_{14} = 0	-40		+40	μA
$V_{th(VTR)}$	VTR switch switches off below			1.1		V
V_{WS}	White spot inverter threshold level			6.6		V
$V_{D(WS)}$	White spot inversion clamping level			4.6		V
V_N	Noise inverter threshold level			1.8		V
$V_{0(N)}$	Noise inversion clamping level			3.8		V
I_4	Tuner AGC output ON current		10			mA
$V_{4(SAT)}$	Tuner AGC output voltage	I_4 = 10mA			300	mV
I_4	Tuner AGC output OFF current				10	μA

AC ELECTRICAL CHARACTERISTICS

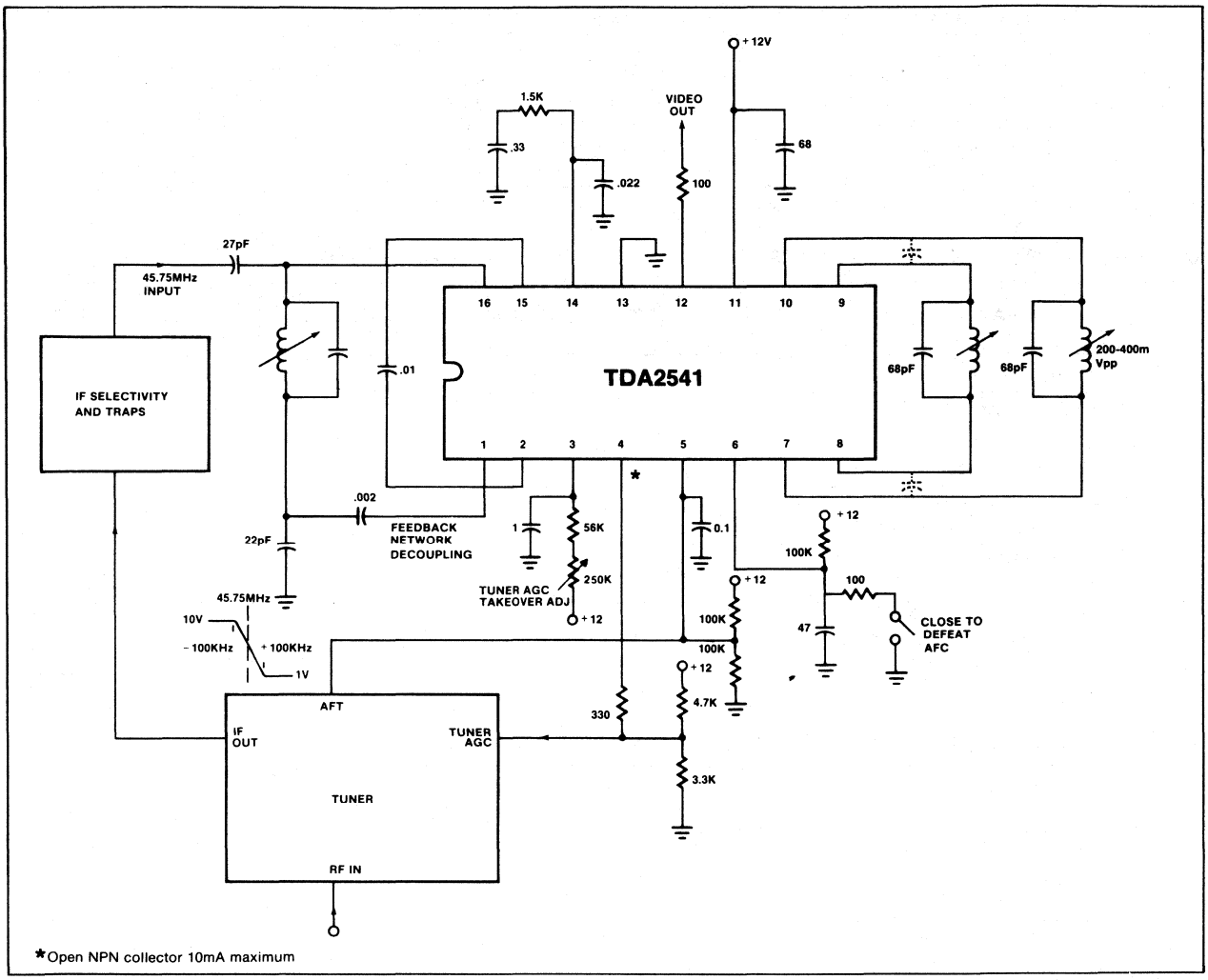
T_A = 25°C, V_{CC} = 12V unless otherwise specified.

PARAMETER		TEST CONDITIONS	TDA 2541			UNIT
			Min	Typ	Max	
V_i	IF input voltage for onset of AGC (f = 45.75MHz)		70	100	140	μV
$V_{o(Z)}$	Zero signal output level		5.7	6	6.3	V
$V_{o(TS)}$	Top sync level		2.9	3	3.2	V
V_5	AFC output voltage swing			10		V
ΔV_i	IF gain control range		50	63		dB
S/N	S/N at V_i = 10mV[1]			58		dB
B	3dB bandwidth of video amplifier			6		MHz
dG	Differential gain[2]			4	10	%
d0	Differential phase[2]			3°	10°	
	Intermodulation (1.1MHz)[3]	1.1MHz blue	46	60		dB
		1.1MHz yellow	46	50		dB
	Intermodulation (3.3MHz)[4]	3.3MHz	46	54		dB
	Carrier signal at video output			4	30	mV
	2nd harmonic of carrier at video output			20		mV
Δf	Change of frequency for 10V AFC swing			100	200	kHz

NOTES

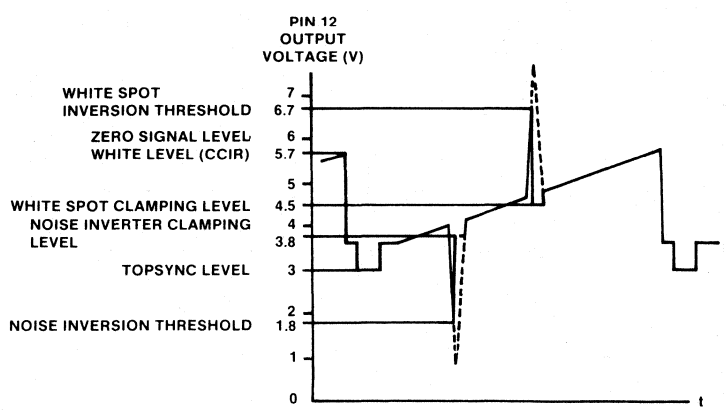
1. S/N = $\frac{V_o \text{ black to white}}{V \text{ noise r.m.s. } B = 5MHz}$
2. Measured with the VZM-2 test set-up of Wandel & Goltermann or equivalent. Measured between 10 and 75% of topsync level.
3. Intermodulation 1.1MHz = 20 log $(\frac{V_o \text{ B-W}}{V_o \text{ p-p } 1.1MHz})$ dB = 20 log $(\frac{V_o \text{ 4.4MHz}}{V_o \text{ 1.1MHz}})$ + 3.6dB
4. Intermodulation 3.3MHz = 20 log $(\frac{V_o \text{ 4.4MHz}}{V_o \text{ 3.3MHz}})$ dB

TYPICAL APPLICATION



*Open NPN collector 10mA maximum

TDA2541 VIDEO OUTPUT



SECTION 13
GENERAL CONSUMER

Section 13—GENERAL CONSUMER

13

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

NE544/644-N,W

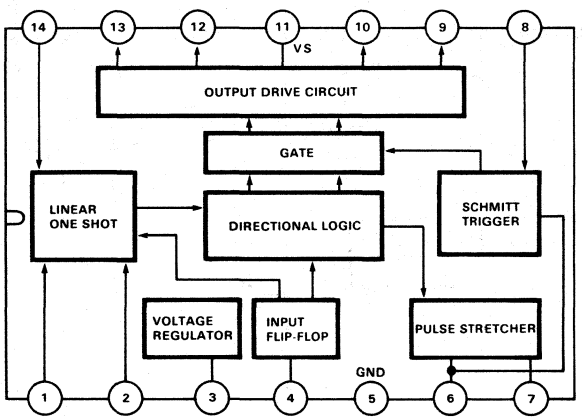
DESCRIPTION

The NE544 is a servo amplifier and pulse-width demodulator with internal motor drive transistors. It is designed for remote control applications in digital proportional systems but can be used in many other closed loop position control applications. It incorporates a linear one shot for improved positional accuracy and outputs for external pnp motor drive transistors.

FEATURES

- **500mA load current capability**
- **Bidirectional bridge output with single power supply**
- **Low standby power drain**
- **Adjustable deadband and trigger thresholds**
- **High linearity, 0.5% maximum error**
- **Output drive for external PNP transistors (optional)**
- **Wide supply voltage range**

BLOCK DIAGRAM



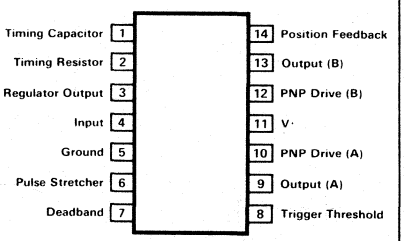
ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

	PARAMETER	RATING	UNIT
V+	Supply voltage	6.0	V
I_O	Output current	500	mA
T_A	Operating temperature	-20 to +75	°C
T_{stg}	Storage temperature	-65 to +150	°C

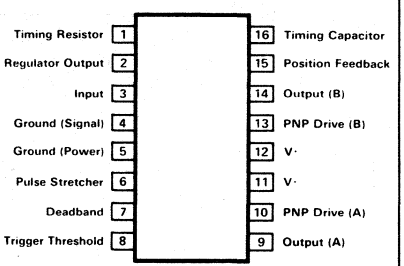
PIN CONFIGURATIONS

N PACKAGE



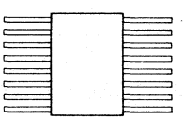
Order part no. NE544N

N PACKAGE



Order part no. NE644N

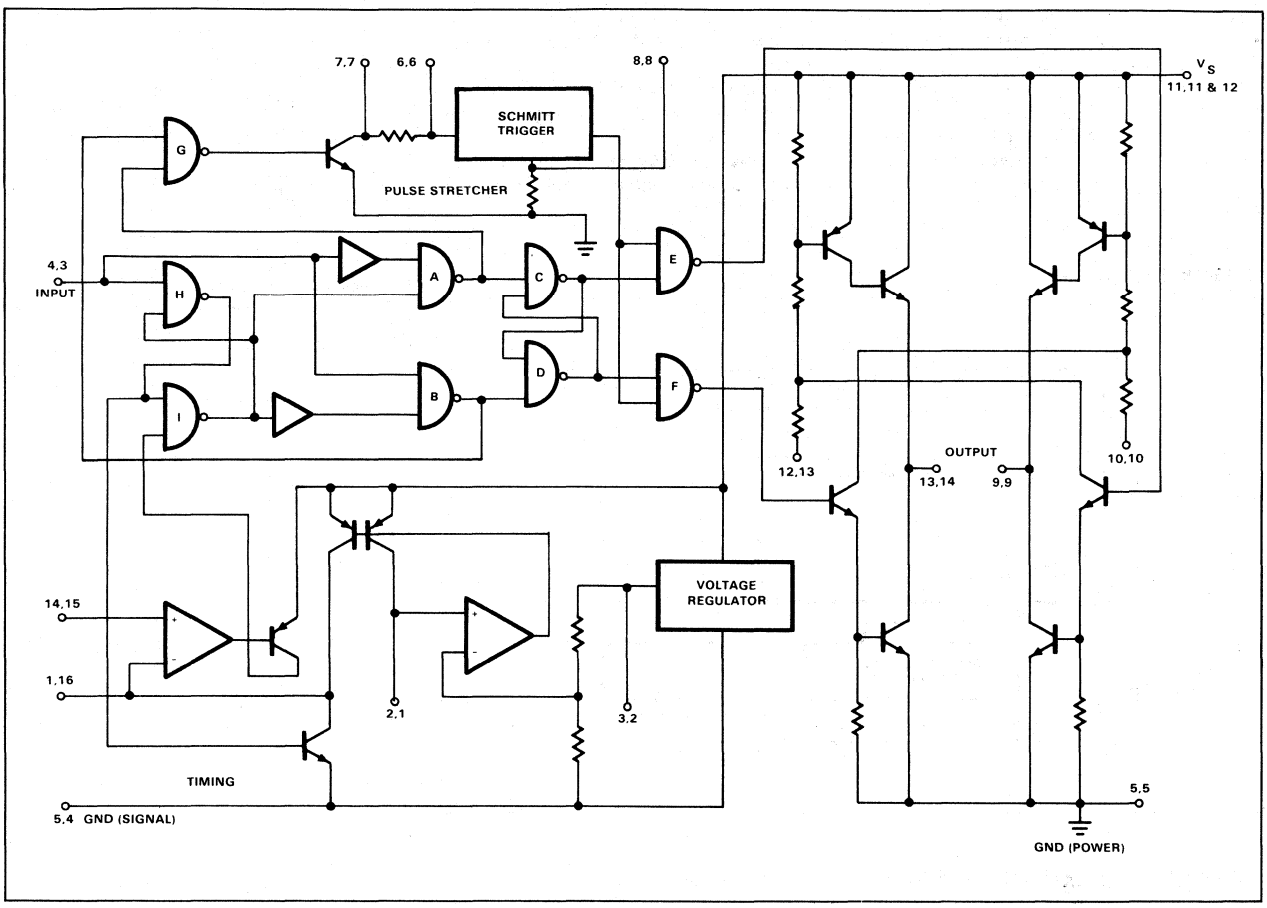
W PACKAGE*



*Pinout same as 644N package
Order part no. NE644W

13

EQUIVALENT CIRCUIT SCHEMATIC



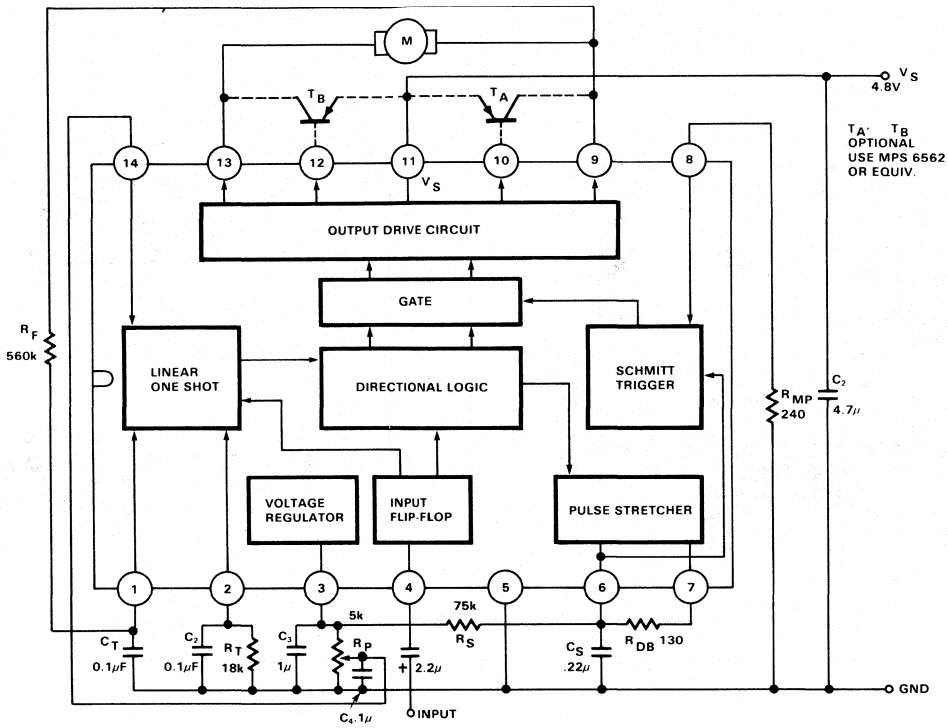
DC ELECTRICAL CHARACTERISTICS

$T_A = 25°C$, $V_S = 4.8V$ unless otherwise specified.

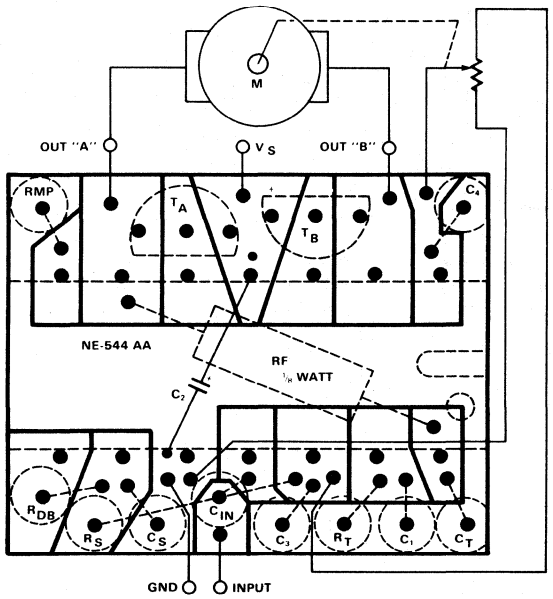
PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
V_{CC}	Supply voltage		3.2	4.8	6	V
I_{CC}	Supply current	Quiescent	4.2	5.5	7.3	mA
V_{TH}	Input threshold					V
	On			1.5		
	Off			1.4		
Z_{IN}	Input resistance			18		kΩ
	Output voltage					V
V_{OL}	Low	Pin 9 or 13, I_L = 400mA		0.3		
V_{OH}	High			3.9		
V_R	Reference voltage		2.4	2.5	2.7	V
PSRR	Power supply rejection	$3.5V \leq V_S \leq 6V$		.01		%/V
	Minimum dead band	RDB = 0		1		μs
	One shot temperature coefficient			.01		%/°C
	Standby power			27		mW
	PNP drive current	Pin 10 and 12		20		mA

NE544/644-N,W

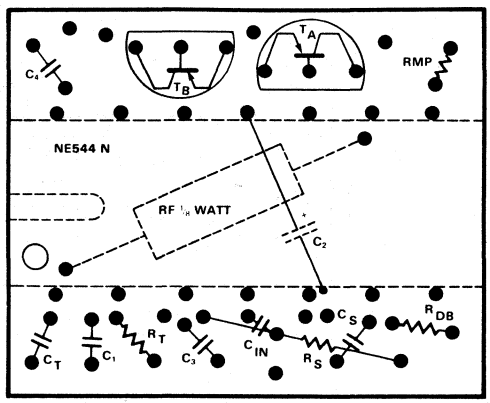
TYPICAL CONNECTION OF NE544N FOR LINEAR ONE SHOT TIMING



PC BOARD—N PACKAGE

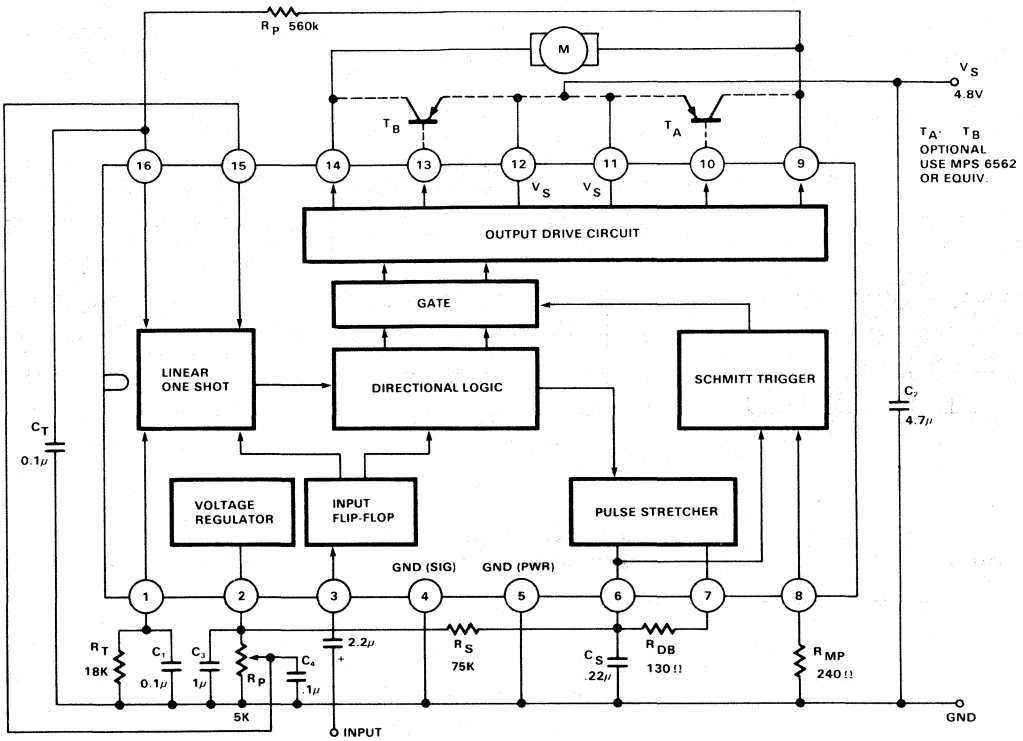


Typical PC Board Layout
Bottom View—4X



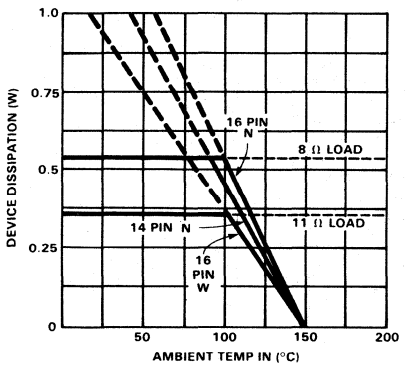
Parts Layout
Top View

TYPICAL CONNECTION OF NE644W AND NE644N FOR LINEAR ONE SHOT TIMING

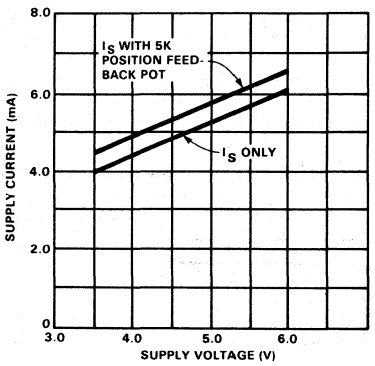


TYPICAL PERFORMANCE CHARACTERISTICS

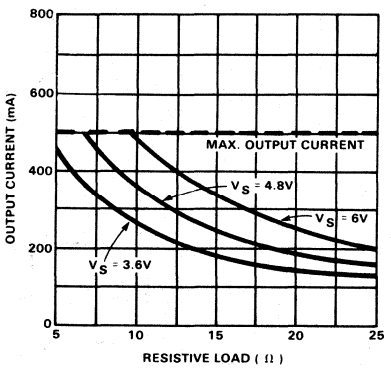
MAXIMUM DISSIPATION vs AMBIENT TEMPERATURE



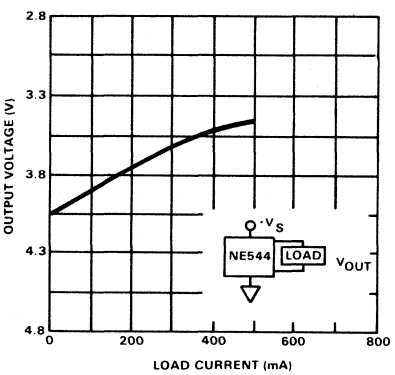
SUPPLY CURRENT vs SUPPLY VOLTAGE



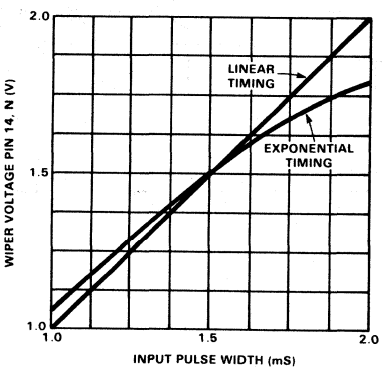
OUTPUT CURRENT vs LOAD RESISTANCE



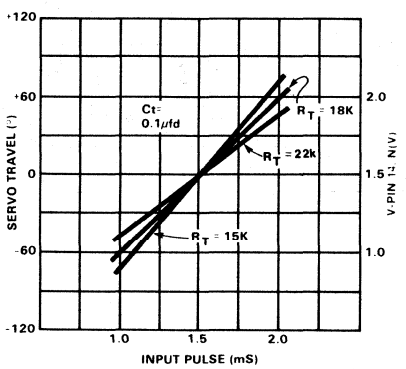
OUTPUT VOLTAGE vs LOAD CURRENT



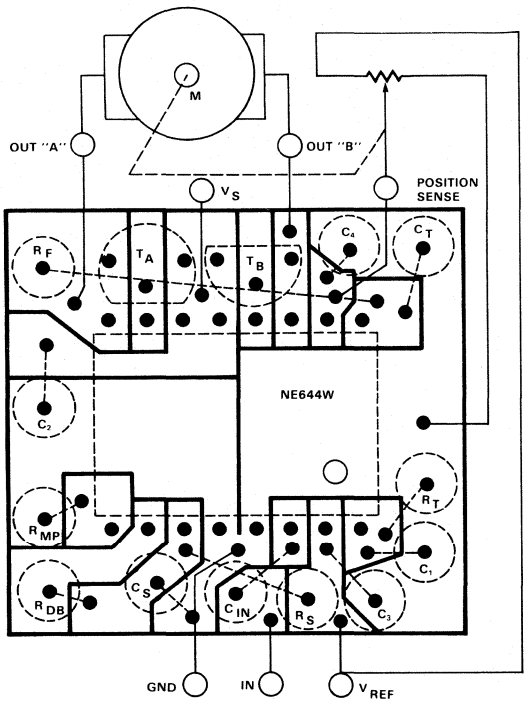
INPUT PULSE WIDTH vs FEEDBACK POT OUTPUT



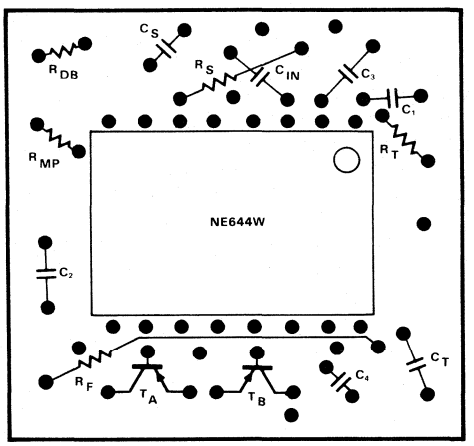
INPUT PULSE vs SERVO TRAVEL



PC BOARD—W PACKAGE



PC Board Layout
Bottom View—4X



Parts Layout
Top View

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SECTION 14
PHASE LOCKED LOOPS

Section 14—PHASE LOCKED LOOPS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

PHASE LOCKED LOOPS DEFINITIONS

T_A
Ambient temperature range. Range of the surrounding environment of the operating device.

T_J
Junction Temperature. The maximum temperature of the device. 150°C is standard for silicon devices.

T_{STG}
Storage temperature range. Temperature range that the device can be stored in a non-operating condition.

T_{SOLD}
Soldering Temperature. The temperature which can be applied to the lead frame of the device for short periods of time (normally specified for a duration of 10 sec).

Truth Tables
0 is logic level low
1 is logic level high
X - don't care condition - has no effect under circuit conditions listed.

Absolute Maximum Rating
Operating safe zones exceeding these limits could cause permanent damage to the device and are not meant to imply that devices can operate at these limits.

Power Dissipation
The power that the device can safely handle at 25°C. The dissipation must be derated as indicated for the individual package type.

Package Type Designation
See full package designations in Appendix.

V_{CC} ($-V_{CC}$)
Supply Voltage. The range of power supply voltage over which the device will operate safely.

FREE-RUNNING FREQUENCY (f_o', ω_o').
Also called the *center frequency*, this is the frequency at which the loop VCO operates when not locked to an input signal. The "prime" superscripts are used to distinguish the free-running frequency from f_o' and ω_o' which are used for the general oscillator frequency. (Many references use f_o' and ω_o' for both the free-running and general oscillator frequency and leave the proper choice for the reader to infer from the context). The appropriate units for f_o' and ω_o' are Hz and radians per second respectively.

LOCK RANGE ($2f_L$, $2\omega_L$).*
The range of frequencies over which the loop will remain in lock. Normally the lock range is centered at the free-running frequency unless there is some nonlinearity in the system which limits the frequency deviation on one side of f_o'. The deviations from f_o' are referred to as the *Tracking Range* or *Hold-in Range*. (See figure 1.6). The tracking range is therefore one-half of the lock range.

CAPTURE RANGE ($2f_C$, $2\omega_C$).**
Although the loop will remain in lock throughout its lock range, it may not be able to acquire lock at the tracking range extremes because of the selectivity afforded by the low-pass filter. The capture range also is centered at f_o' with the equal deviations called the *Lock-in* or *Pull-in Ranges*. The capture range can never exceed the lock range.

LOCK-UP TIME (t_L).***
The transient time required for a free-running loop to lock. This time depends principally upon the bandwidth selectivity designed into the loop with the low-pass filter. The lock-up time is inversely proportional to the selectivity bandwidth. Also, lock-up time exhibits a statistical spreading due to random initial phase relationships between the input and oscillator phases.

PHASE COMPARATOR CONVERSION GAIN (K_d).
The conversion constant relating the phase comparators output voltage to the phase difference between input and VCO signals when the loop is locked. At low input signal levels, K_d is also a function of signal amplitude. K_d has units of volts per radian (V/rad).

VCO CONVERSION GAIN (K_o).
The conversion constant relating the oscillators frequency shift from f_o' to the applied input voltage. K_o has units of radians per second per volt (rad/sec/volt). K_o is a linear function of ω_o' and must be obtained using a formula or graph provided or experimentally measured at the desired ω_o'.

LOOP GAIN (K_v).
The product of K_d, K_o, and the low-pass filters gain at dc. K_d is evaluated at the appropriate input signal level and K_o at the appropriate ω_o'. K_v has units of $(sec)^{-1}$.

CLOSED LOOP GAIN (CLG).
The output signal frequency and phase can be determined from a product of the CLG and the input signal where the CLG is given by

$$CLG = \frac{K_v}{1 + K_v} \qquad \text{(Equation 1.4)}$$

NATURAL FREQUENCY (ω_n).
The characteristic frequency of the loop, determined mathematically by the final pole positions in the complex plane or determined experimentally as the modulation frequency for which an underdamped loop gives the maximum frequency deviation from f_o' and at which the phase error swing is the greatest.

DAMPING FACTOR (ζ).
The standard damping constant of a second order feedback system. For the PLL, ζ refers to the ability of the loop to respond quickly to an input frequency step without excessive overshoot.

LOOP NOISE BANDWIDTH (B_L).
A loop property relating ω_n and τ which describes the effective bandwidth of the received signal. Noise and signal components outside this bandwidth are greatly attenuated.

* Also called Synchronization Range.
** Also called Acquisition Range.
*** Also called Acquisition Time.

NOTE
Refer to Section 10 of the 1979 Analog Applications Manual for an in-depth explanation of Phase Locked Loops and their applications.

SE/NE564-N,I

DESCRIPTION

The NE564 is a versatile, high frequency Phase Locked Loop designed for operation up to 50MHz. As shown in the block diagram, the NE564 consists of a VCO, limiter, phase comparator, and post detection processor.

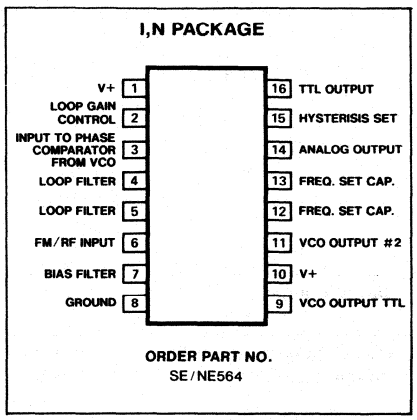
APPLICATIONS

- **High speed modems**
- **FSK receivers and transmitters**
- **Frequency synthesizers**
- **Signal generators**

FEATURES

- **Operation with single 5V supply**
- **TTL compatible inputs and outputs**
- **Operation to 50MHz**
- **External loop gain control**
- **Reduced carrier feedthrough**
- **No elaborate filtering needed in FSK applications**
- **Can be used as a modulator**
- **Variable loop gain (Externally Controlled)**

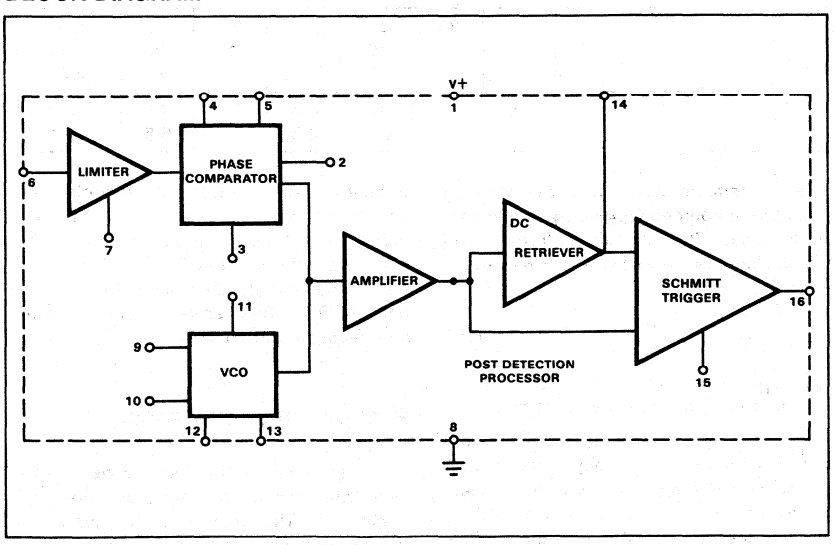
PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS

	PARAMETER		RATING	UNIT
V+	Supply voltage			V
	Pin 1		14	
	Pin 10		6	
P_D	Power dissipation		400	mW
T_A	Operating temperature	NE	0 to 70	°C
	Operating temperature	SE	−55 to +125	
t_{stg}	Storage temperature		−65 to 150	°C

BLOCK DIAGRAM



FUNCTIONAL DESCRIPTION

The NE564 is a monolithic phase locked loop with a post detection processor. The use of Schottky clamped transistors and optimized device geometries extends the frequency of operation to greater than 50MHz. In addition to the classical PLL applications, the NE564 can be used as a modulator with a controllable frequency deviation.

The output voltage of the PLL can be written as shown in the following equation:

$$V_O = \frac{(f_{in} - f_o)}{K_{vco}} \qquad \text{Equation 1}$$

K_{VCO} = conversion gain of the VCO (see figure 7)
f_{in} = frequency of the input signal
f_o = free running frequency of the VCO

The process of recovering FSK signals involves the conversion of the PLL output into logic compatible signals. For high data rates, a considerable amount of carrier will be present at the output of the PLL due to the wideband nature of the loop filter. To avoid the use of complicated filters, a comparator with hysterisis or Schmitt trigger is required. With the conversion gain of the VCO fixed, the output voltage as given by Equation 1 varies according to the frequency deviation of f_{in} from f_o. Since this differs from system to system, it is necessary that the hysterisis of the Schmitt trigger be capable of being changed, so that it can be optimized for a particular system. This is

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ELECTRICAL CHARACTERISTICS

$V+ = 5V$, $T_A = 25°C$, fo = 5MHz, $I_B = -200\mu A$ unless otherwise specified.
Test Circuit: Figure 1

PARAMETER	TEST CONDITIONS	SE564			NE564			UNIT
		Min	Typ	Max	Min	Typ	Max	
Maximum VCO frequency		50	65		45	60		MHz
Lock range	Input ≥ 200mVrms, $T_A = 25°C$	60	90		60	90		% of fo
	$= 125°C$	30	50					
	$= -55°C$	120	150					
	$= 0°C$				100	120		
	$= 70°C$				50	70		
Capture range	Input ≥ 200mVrms, R2 = 27Ω	25	35		25	35		% of fo
	= 100Ω	35	50		35	50		
VCO frequency drift with temperature	fo = 5MHz, $T_A = -55°C$ to $125°C$		400	1000				PPM/°C
	$= 0°C$ to $70°C$					400	1250	
	fo = 500kHz, $T_A = -55°C$ to $125°C$		250	500				
	$= 0°C$ to $70°C$					400	850	
VCO frequency change with supply voltage	V+ = 4.5V to 5.5V		3	6		3	6	% of fo
Demodulated output voltage	Modulation frequency: 1kHz, fo = 5MHz							
	Input deviation: 10%, T = 25°C	120	140		120	140		mVrms
	: 1%, T = 25°C	12	14		12	14		mVrms
	T = 0°C				11	13		mVrms
	$= -55°C$	9	12					mVrms
	$= 70°C$				13	15		mVrms
	$= 125°C$	14	16					mVrms
Linearity	Deviation: 1% to 8%		1	3		1	3	%
Signal to noise ratio			40			40		dB
AM rejection			35			35		dB
Supply current	V+ = 5V		35	50		35	50	mA
Leakage current	Pin 9		1	10		1	10	μA
Output current	Pin 9			6			6	mA
Supply voltage	Pin 1	4.5		12	4.5		12	V
	Pin 10	4.5		5.5	4.5		5.5	V

accomplished in the 564 by varying the voltage at pin 15 which results in a change of the hysterisis of the Schmitt trigger.

For FSK signals, an important factor to be considered is the drift in the free running frequency of the VCO itself. If this changes due to temperature, according to Equation 1 it will lead to a change in the dc levels of the PLL output, and consequently to errors in the digital output signal. This is especially true for narrow band signals where the deviation in f_{in} itself may be less than the change in f_o due to temperature. This effect can be eliminated if the dc or average value of the signal is retrieved and used as the reference to the comparator. In this manner, variations in the dc levels of the PLL output do not affect the FSK output.

VCO Section

Due to its inherent high frequency performance, an emitter coupled oscillator is used in the VCO. In the circuit, shown in the equivalent schematic, transistors Q_{21} and Q_{23} with current sources Q_{25}–Q_{26} form the basic oscillator. The free running frequency of the oscillator is shown in the following equation:

$$f_o = \frac{1}{16R_cC_1} \qquad \text{Equation 2}$$

$R_c = R_{19} = R_{20} = 100\Omega$ (INTERNAL)
C_1 = external frequency setting capacitor

Variation of V_d (phase detector output voltage) changes the frequency of the oscillator. As indicated by Equation 2, the frequency of the oscillator has a negative temperature coefficient due to the positive temperature coefficient of the monolithic resistor. To compensate for this, a current I_R with negative temperature coefficient is introduced to achieve a low frequency drift with temperature.

Phase Comparator Section

The phase comparator consists of a double balanced modulator with a limiter amplifier to improve AM rejection. Schottky clamped vertical PNPs are used to obtain TTL level inputs. The loop gain can be varied by changing the current in Q_4 and Q_{15} which effectively changes the gain of the differential amplifiers. This can be accomplished by introducing a current at pin 2.

Post Detection Processor Section

The post detection processor consists of a unity gain transconductance amplifier and comparator. The amplifier can be used as a dc retriever for demodulation of FSK signals, and as a post detection filter for linear FM demodulation. The comparator has adjustable hysterisis so that phase jitter in the output signal can be eliminated.

As shown in the equivalent schematic, the dc retriever is formed by the transductance amplifier Q_{42}–Q_{43} together with an external capacitor which is connected at the am-

plifier output (pin 14). This forms an integrator whose output voltage is shown in the following equation:

$$V_0 = \frac{g_m}{C_2} \int V_{in} dt \qquad \text{Equation 3}$$

g_m = transconductance of the amplifier
C_2 = capacitor at the output (pin 14)
V_{in} = signal voltage at amplifier input

With proper selection of C_2, the integrator time constant can be varied so that the output voltage is the dc or average value of the input signal for use in FSK, or as a post detection filter in linear demodulation.

The comparator with hysterisis is made up of Q_{49}–Q_{50} with positive feedback being provided by Q_{47}–Q_{48}. The hysterisis is varied by changing the current in Q_{52} with a resulting variation in the loop gain of the comparator. This method of hysterisis control, which is a dc control, provides symmetric variation around the nominal value.

Design Formula

The free running frequency of the VCO is shown by the following equation:

$$f_o = \frac{1}{16 R_c C_1} \text{ in Hz} \qquad \text{Equation 4}$$

R_c = 100Ω
C_1 = external cap in farads

The loop filter diagram shown is explained by the following equation:

$$F(s) = \frac{1}{1 + sRC_3} \qquad \text{Equation 5}$$

$R = R_{12} = R_{13} = 1.3k\Omega$ (INTERNAL)

By adding capacitors to pins 4 and 5, two poles are added to the loop transfer function

at $\omega = \frac{1}{RC_3}$.

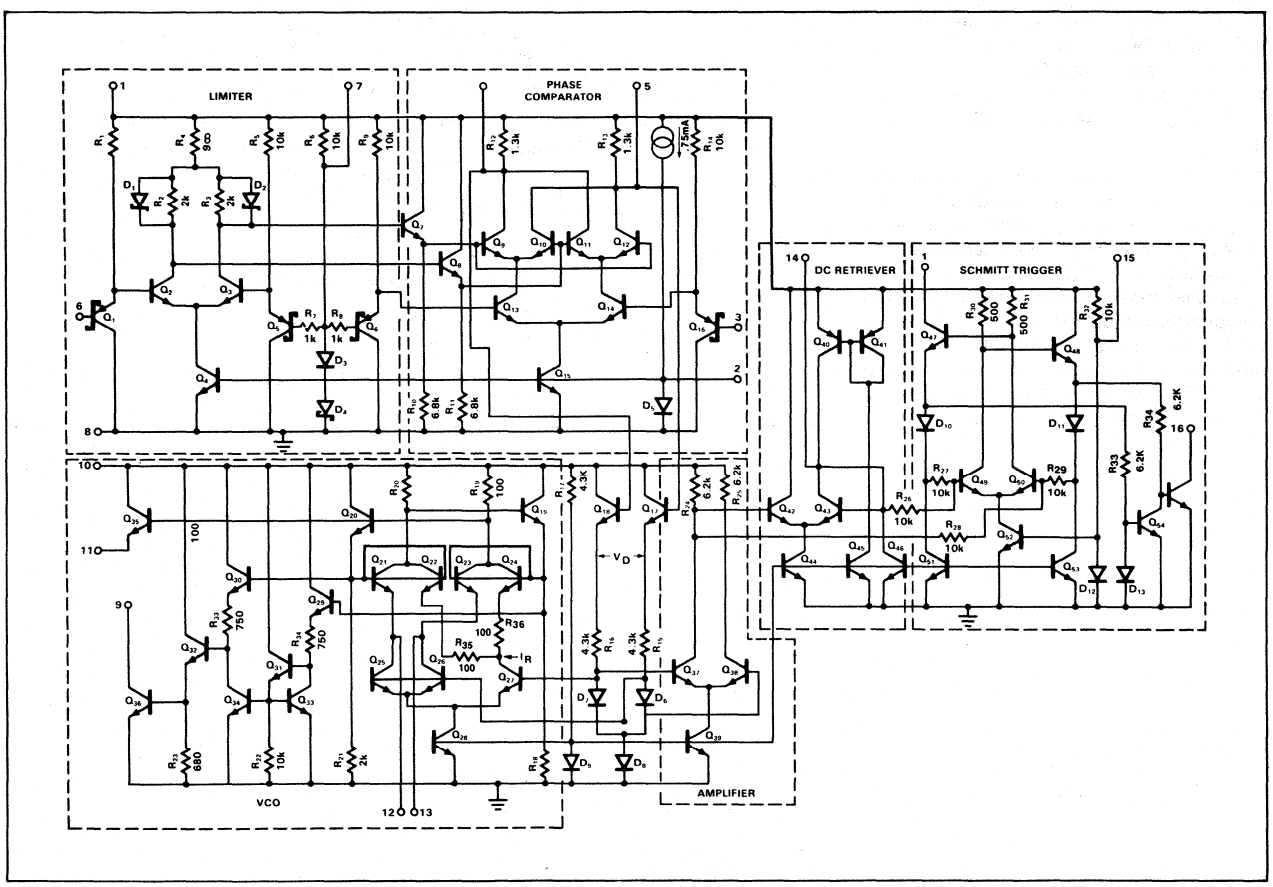
FM DEMODULATOR

The NE564 can be used as an FM demodulator. The connections for operation at 5V and 12V are shown in figures 2 and 3 respectively. The input signal is ac coupled with the output signal being extracted at pin 14. Loop filtering is provided by the capacitors at pins 4 and 5 with additional filtering being provided by the capacitor at pin 14. Since the conversion gain of the VCO is not very high, to obtain sufficient demodulated output signal the frequency deviation in the input signal should be fairly high (1% or higher).

MODULATION TECHNIQUES

The NE564 phase locked loop can be modulated at either the loop filter ports (pins 4 and 5) or the input port (pin 6) as shown in figure 4. The approximate modulation frequency can be determined from the frequency conversion gain curve shown in figure 5. This curve will be appropriate for signals injected into pins 4 and 5 as shown in figure 4.

EQUIVALENT SCHEMATIC



FSK Demodulation

The 564 PLL is particularly attractive for FSK demodulation since it contains an internal voltage comparator and VCO which have TTL compatible inputs and outputs, and it can operate from a single 5 volt power supply. Demodulated dc voltages associated with the mark and space frequencies are recovered with a single external capacitor in a dc retriever without utilizing extensive filtering networks. An internal comparator, acting as a Schmitt trigger with an adjustable hysteresis, shapes the demodulated voltages into compatible TTL output levels. The high frequency design of the 564 enables it to demodulate FSK at high data rates in excess of 1.0M baud.

Figure 6 shows a high-frequency FSK decoder designed for input frequency deviations of ± 1.0MHz centered around a free-running frequency of 10.8MHz. The value of the timing capacitance required was estimated from figure 8 to be approximately 40pF. A trimmer capacitor was added to fine tune f_o' to 10.8MHz.

Figure 9 indicates that the ± 1.0MHz frequency deviations will be within the lock range for input signal levels greater than approximately 50mV with zero pin 2 bias current. While strictly this figure is appropriate only for 5MHz, it can be used as a guide for lock range estimates at other f_o' frequencies.

The hysteresis was adjusted experimentally via the 10kΩ potentiometer and 2kΩ bias arrangement to give the waveshape shown in figure 7 for 20K, 500K, 2M baud rates with square wave FSK modulation. Note the magnitude and phase relationships of the phase comparators output voltages with respect to each other and to the FSK output. The high frequency sum components of the input and VCO frequency also are visible as noise on the phase comparators outputs.

SE/NE 564 TEST CIRCUIT

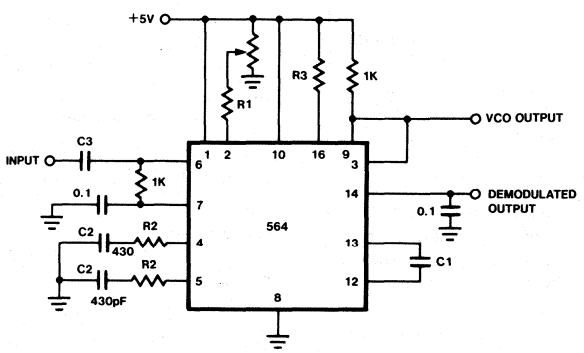


Figure 1

FM DEMODULATOR AT 5V

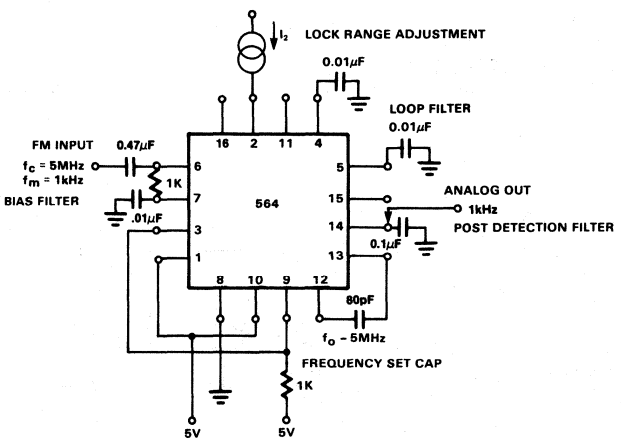


Figure 2

FM DEMODULATOR AT 12V

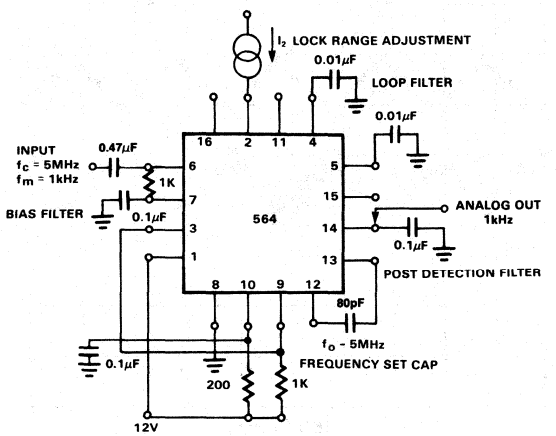


Figure 3

MODULATOR

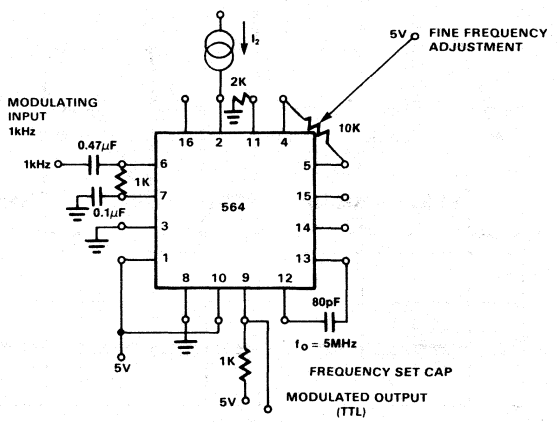
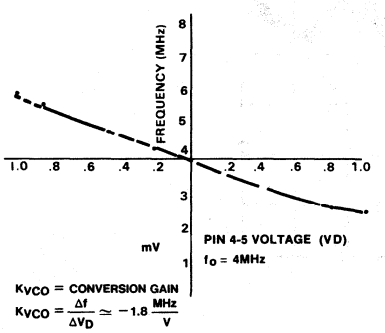


Figure 4

VCO CONVERSION GAIN



K_{VCO} = CONVERSION GAIN

$$K_{VCO} = \frac{\Delta f}{\Delta V_D} \simeq -1.8 \frac{MHz}{V}$$

FOR K_0 OF PLL MODEL

$$K_0 = \frac{(\Delta f / f_o)}{VOLT} = \frac{-(1.8MHz/4MHz)}{1VOLT}$$

$$= \frac{-0.45 \text{ RADIANS}}{VOLT}$$

$$= -4.5 \times 10^{-4} \text{ RADIANS/mV}$$

Figure 5

10.8MHz FSK DECODER USING THE 564

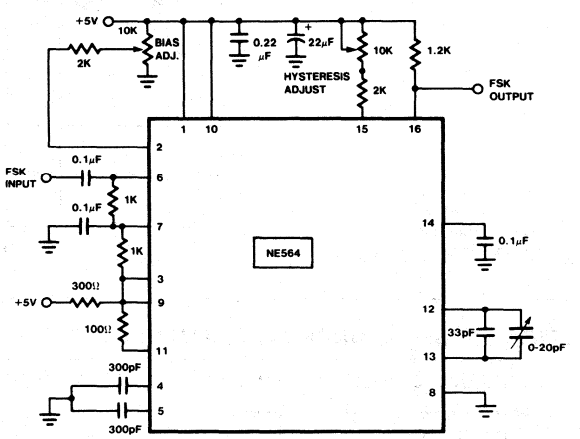
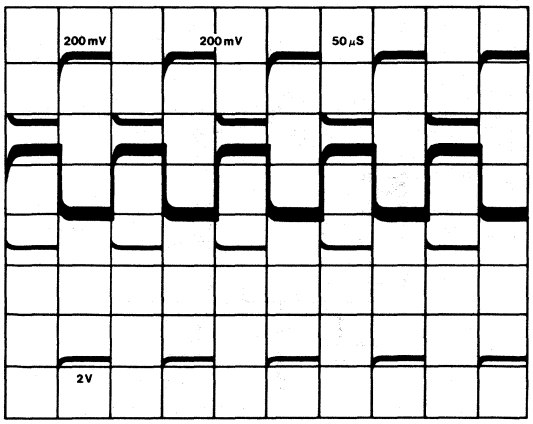
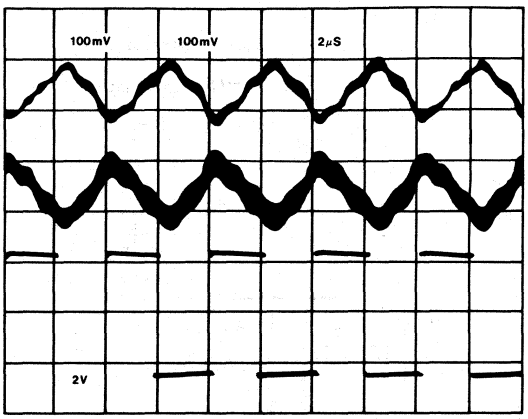


Figure 6

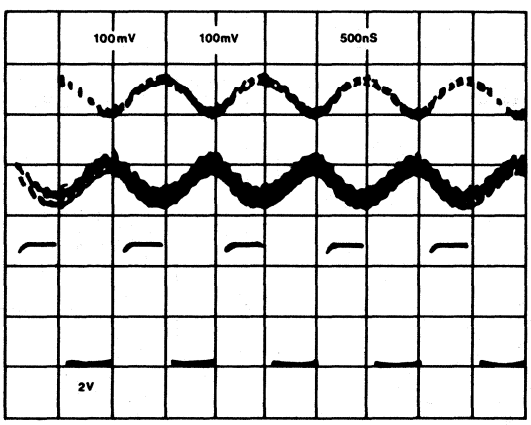
PHASE COMPARATOR (PINS 4 AND 5) AND FSK (PIN 16) OUTPUTS FOR DATA RATES OF



(a) 20K BAUD



(b) 500K BAUD



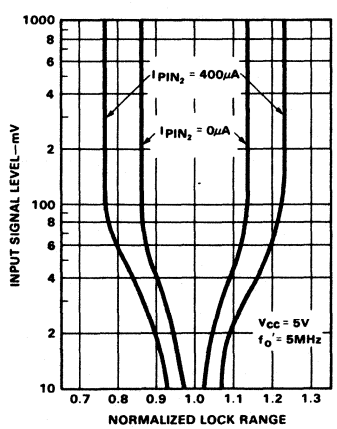
(c) 2.0M BAUD

NOTE
Top trace-pin 4
Center trace-pin 5
Bottom trace-pin 16

Figure 7

TYPICAL PERFORMANCE CHARACTERISTICS

LOCK RANGE vs SIGNAL INPUT



VCO CAPACITOR vs FREQUENCY

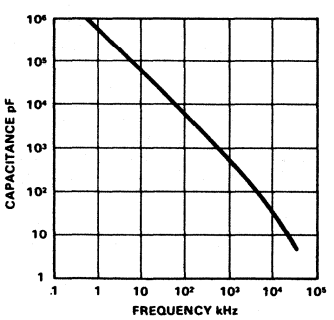
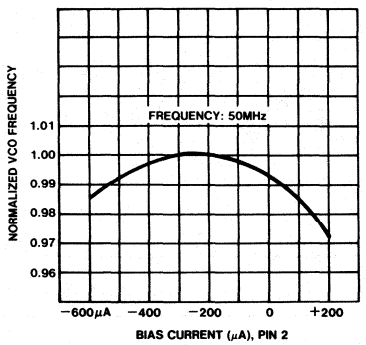
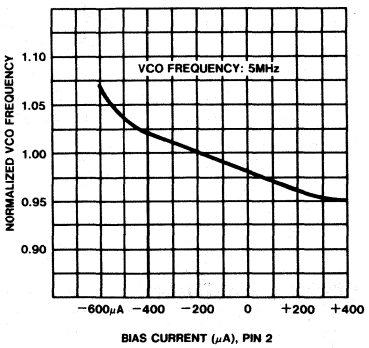


Figure 8

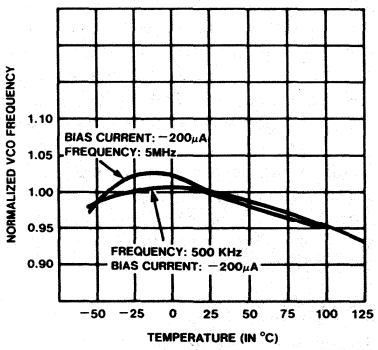
TYPICAL NORMALIZED VCO FREQUENCY AS A FUNCTION OF PIN 2 BIAS CURRENT



TYPICAL NORMALIZED VCO FREQUENCY AS A FUNCTION OF PIN 2 BIAS CURRENT



NORMALIZED VCO FREQUENCY AS A FUNCTION OF TEMPERATURE



NOTE
Refer to section 10 of Signetics Analog Applications Manual for more detailed information.

14

NE/SE565-F,K,N

DESCRIPTION

The SE/NE565 Phase-Locked Loop (PLL) is a self-contained, adaptable filter and demodulator for the frequency range from 0.001Hz to 500kHz. The circuit comprises a voltage-controlled oscillator of exceptional stability and linearity, a phase comparator, an amplifier and a low-pass filter as shown in the block diagram. The center frequency of the PLL is determined by the free-running frequency of the VCO; this frequency can be adjusted externally with a resistor or a capacitor. The low-pass filter, which determines the capture characteristics of the loop, is formed by an internal resistor and an external capacitor.

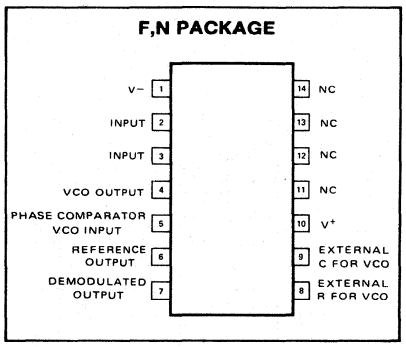
FEATURES

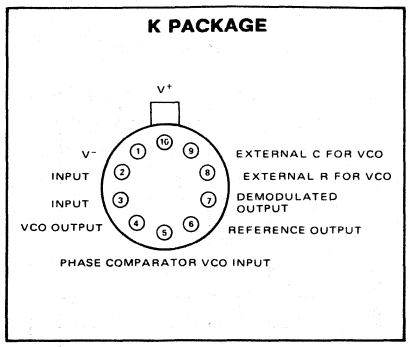
- **Highly stable center frequency (200ppm/°C typ.)**
- **Wide operating voltage range (±6 to ±12 volts)**
- **Highly linear demodulated output (0.2% typ.)**
- **Center frequency programming by means of a resistor or capacitor, voltage or current**
- **TTL and DTL compatible square-wave output; loop can be opened to insert digital frequency divider**
- **Highly linear triangle wave output**
- **Reference output for connection of comparator in frequency discriminator**
- **Bandwidth adjustable from < ±1% to > ±60%**
- **Frequency adjustable over 10 to 1 range with same capacitor**

APPLICATIONS

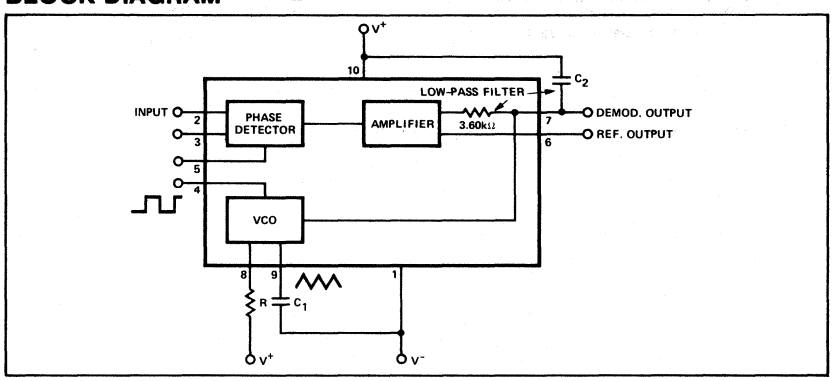
- **Frequency shift keying**
- **Modems**
- **Telemetry receivers**
- **Tone decoders**
- **SCA receivers**
- **Wideband FM discriminators**
- **Data synchronizers**
- **Tracking filters**
- **Signal restoration**
- **Frequency multiplication & division**

PIN CONFIGURATIONS

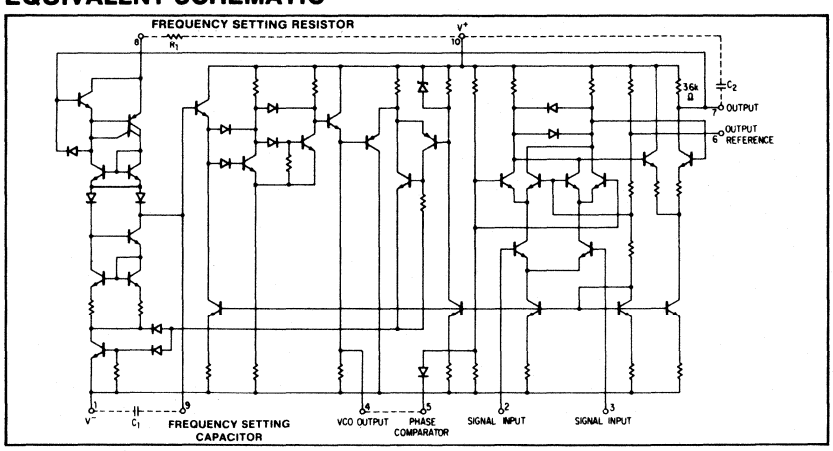




BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise specified.

PARAMETER	RATING	UNIT
Maximum operating voltage	26	V
Input voltage	3	Vp-p
Storage temperature	-65 to +150	°C
Operating temperature range		
NE565	0 to +70	°C
SE565	-55 to +125	°C
Power dissipation	300	mW

ELECTRICAL CHARACTERISTICS $T_A = 25°C$, $V_{CC} = \pm 6V$ unless otherwise specified.

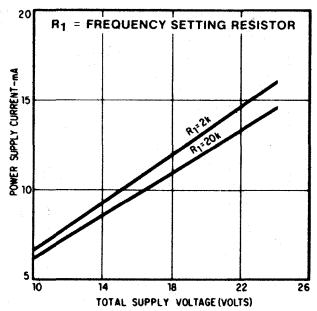
PARAMETER	TEST CONDITIONS	SE565			NE565			UNIT
		Min	Typ	Max	Min	Typ	Max	
SUPPLY REQUIREMENTS								
Supply voltage		12		±12	±6		±12	V
Supply current			8	12.5		8	12.5	mA
INPUT CHARACTERISTICS								
Input impedance[1]		7	10		5	10		kΩ
Input level required for tracking	f_o = 50kHz, ±10% frequency deviation	10	1		10	1		mVrms
VCO CHARACTERISTICS								
Center frequency								
Maximum value	C_1 = 2.7pF	300	500			500		kHz
Distribution[2]	Distribution taken about f_o = 50kHz, R_1 = 5.0kΩ, C_1 = 1200pF	-10	0	+10	-30	0	+30	%
Drift with temperature	f_o = 50kHz		200			300		ppm/°C
Drift with supply voltage	f_o = 50kHz, V_{CC} = ±6 to ±7 volts		0.1	1.0		0.2	1.5	%/V
Triangle wave								
Output voltage level		1.9	0		1.9	0		V
Amplitude			2.4	3		2.4	3	Vp-p
Linearity			0.2			0.5		%
Square wave								
Logical "1" output voltage	f_o = 50kHz	+4.9	+5.2		+4.9	+5.2		V
Logical "0" output voltage	f_o = 50kHz		-0.2	+0.2		-0.2	+0.2	V
Duty cycle	f_o = 50kHz	45	50	55	40	50	60	%
Rise time			20	100		20		ns
Fall time			50	200		50		ns
Output current (sink)		0.6	1		0.6	1		mA
Output current (source)		5	10		5	10		mA
DEMODULATED OUTPUT CHARACTERISTICS								
Output voltage level	Measured at pin 7	4.25	4.5	4.75	4.0	4.5	5.0	V
Maximum voltage swing[3]			2			2		Vp-p
Output voltage swing	±10% frequency deviation	250	300		200	300		mVp-p
Total harmonic distortion			0.2	0.75		0.4	1.5	%
Output impedance[4]			3.6			3.6		kΩ
Offset voltage (V6-V7)			30	100		50	200	mV
Offset voltage vs temperature (drift)			50			100		μV/°C
AM rejection		30	40			40		dB

NOTES

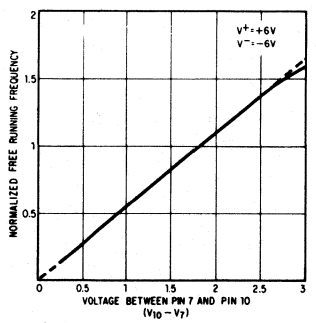
1. Both input terminals (pins 2 and 3) must receive identical dc bias. This bias may range from 0 volts to -4 volts.
2. The external resistance for frequency adjustment (R1) must have a value between 2kΩ and 20kΩ.
3. Output voltage swings negative as input frequency increases.
4. Output not buffered.

TYPICAL PERFORMANCE CHARACTERISTICS

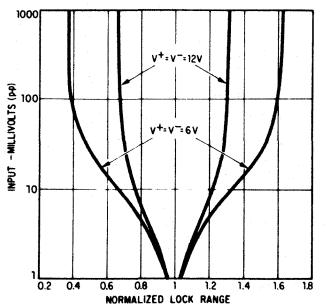
POWER SUPPLY CURRENT AS A FUNCTION OF SUPPLY VOLTAGE



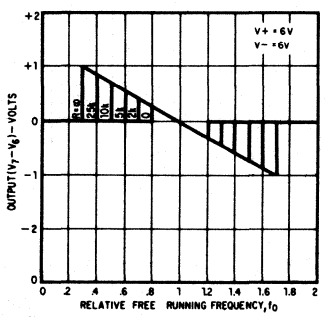
VCO CONVERSION GAIN



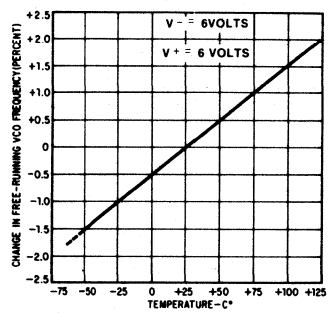
LOCK RANGE AS A FUNCTION OF INPUT VOLTAGE



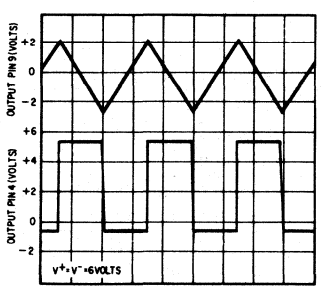
LOCK RANGE AS A FUNCTION OF GAIN SETTING RESISTANCE (PIN 6-7)



CHANGE IN FREE-RNNING VCO FREQUENCY AS A FUNCTION OF TEMPERATURE



VCO OUTPUT WAVEFORM



DESIGN FORMULAS (See Figure 1)

Free-running frequency of VCO: $f_o \simeq \frac{1.2}{4R_1C_1}$ in Hz

Lock-range: $f_L = \pm \frac{8f_o}{V_{CC}}$ in Hz

Capture-range: $f_C \simeq \pm \frac{1}{2\pi} \sqrt{\frac{2\pi f_L}{\tau}}$

where $\tau = (3.6X10^3) \times C_2$

TYPICAL APPLICATIONS

FM Demodulation

The 565 Phase Locked Loop is a general purpose circuit designed for highly linear FM demodulation. During lock, the average dc level of the phase comparator output signal is directly proportional to the frequency of the input signal. As the input frequency shifts, it is this output signal which causes the VCO to shift its frequency to match that of the input. Consequently, the linearity of the phase comparator output with frequency is determined by the voltage-to-frequency transfer function of the VCO.

Because of its unique and highly linear VCO, the 565 PLL can lock to and track an input signal over a very wide bandwidth (typically ±60%) with very high linearity (typically, within 0.5%).

A typical connection diagram is shown in Figure 1. The VCO free-running frequency is given approximately by

$f_o = \frac{1.2}{4R_1C_1}$ and should be adjusted to be at the center of the input signal frequency range. C1 can be any value, but R1 should be within the range of 2000 to 20,000 ohms with an optimum value on the order of 4000 ohms. The source can be direct coupled if the dc resistances seen from pins 2 and 3 are equal and there is no dc voltage difference between the pins. A short between pins 4 and 5 connects the VCO to the phase comparator. Pin 6 provides a dc reference voltage that is close to the dc potential of the demodulated output (pin 7). Thus, if a resistance is connected between pins 6 and 7, the gain of the output stage can be reduced with little change in the dc voltage level at the output. This allows the lock range to be decreased with little change in the free-running frequency. In this manner the lock range can be decreased from ±60% of f_o to approximately ±20% of f_o (at ±6V).

A small capacitor (typically 0.001μF) should be connected between pins 7 and 8 to eliminate possible oscillation in the control current source.

A single-pole loop filter is formed by the capacitor C2, connected between pin 7 and the positive supply, and an internal resistance of approximately 3600 ohms.

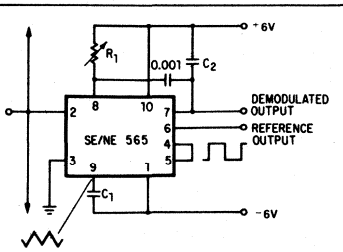


Figure 1

Frequency Shift Keying (FSK)

FSK refers to data transmission by means of a carrier which is shifted between two preset frequencies. This frequency shift is usually accomplished by driving a VCO with the binary data signal so that the two resulting frequencies correspond to the "0" and "1" states (commonly called space and mark) of the binary data signal.

A simple scheme using the 565 to receive FSK signals of 1070Hz and 1270Hz is shown in Figure 2. As the signal appears at the input, the loop locks to the input frequency and tracks it between the two frequencies with a corresponding dc shift at the output.

The loop filter capacitor C2 is chosen smaller than usual to eliminate overshoot on the output pulse, and a three-stage RC ladder filter is used to remove the carrier component from the output. The band edge of the ladder filter is chosen to be approximately half way between the maximum keying rate (in this case 300 baud or 150Hz) and twice the input frequency (approximately 2200Hz). The output signal can now be made logic compatible by connecting a voltage comparator between the output and pin 6 of the loop. The free-running frequency is adjusted with R1 so as to result in a slightly-positive voltage at the output with f_{IN} = 1070Hz.

The input connection is typical for cases where a dc voltage is present at the source and therefore a direct connection is not desirable. Both input terminals are returned to ground with identical resistors (in this case, the values are chosen to effect a 600-ohm input impedance).

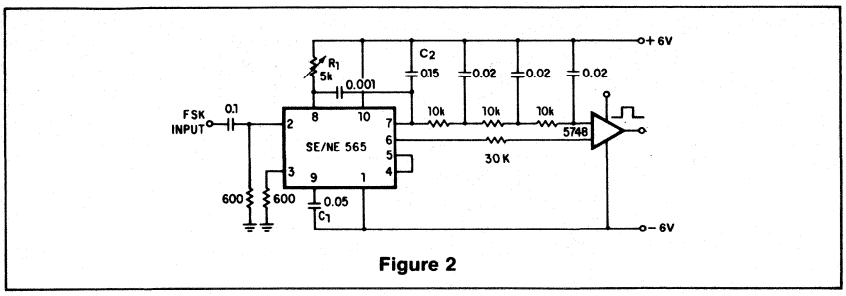


Figure 2

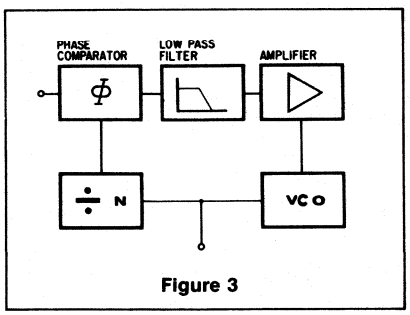


Figure 3

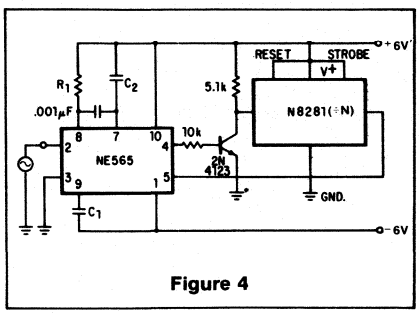


Figure 4

Frequency Multiplication

There are two methods by which frequency multiplication can be achieved using the 565:

1. Locking to a harmonic of the input signal.
2. Inclusion of a digital frequency divider or counter in the loop between the VCO and phase comparator.

The first method is the simplest, and can be achieved by setting the free-running frequency of the VCO to a multiple of the input frequency. A limitation of this scheme is that the lock range decreases as successively higher and weaker harmonics are used for locking. If the input frequency is to be constant with little tracking required, the loop can generally be locked to any one of the first 5 harmonics. For higher orders of multiplication, or for cases where a large lock range is desired, the second scheme is more desirable. An example of this might be a case where the input signal varies over a wide frequency range and a large multiple of the input frequency is required.

A block diagram of the second scheme is shown in Figure 3. Here the loop is broken between the VCO and the phase comparator, and a frequency divider is inserted. The fundamental of the divided VCO frequency is locked to the input frequency in this case, so that the VCO is actually running at a multiple of the input frequency. The amount of multiplication is determined by the frequency divider. A typical connection scheme is shown in Figure 4. To set up the circuit, the frequency limits of the input signal must be determined. The free-running frequency of the VCO is then adjusted by means of R1 and C1 (as discussed under FM demodulation) so that the output frequency of the divider is midway between the input frequency limits. The filter capacitor, C2, should be large enough to eliminate variations in the demodulated output voltage (at pin 7), in order to stabilize the VCO frequency. The output can now be taken as the VCO squarewave output, and its fundamental will be the desired multiple of the input frequency (f_{IN}) as long as the loop is in lock.

SCA (Background Music) Decoder

Some FM stations are authorized by the FCC to broadcast uninterrupted background music for commerical use. To do this a frequency modulated subcarrier of 67kHz is used. The frequency is chosen so as not to interfere with the normal stereo or monaural program; in addition, the level of the subcarrier is only 10% of the amplitude of the combined signal.

The SCA signal can be filtered out and demodulated with the NE565 Phase Locked Loop without the use of any resonant circuits. A connection diagram is shown in Figure 5. This circuit also serves as an example of operation from a single power supply.

A resistive voltage divider is used to establish a bias voltage for the input (pins 2 and 3). The demodulated (multiplex) FM signal is fed to the input through a two-stage high-pass filter, both to effect capacitive coupling and to attenuate the strong signal of the regular channel. A total signal amplitude, between 80mV and 300mV, is required at the input. Its source should have an impedance of less than 10,000 ohms.

The Phase Locked Loop is tuned to 67kHz with a 5000 ohm potentiometer; only approximate tuning is required, since the loop will seek the signal.

The demodulated output (pin 7) passes through a three-stage low-pass filter to provide de-emphasis and attenuate the high-frequency noise which often accompanies SCA transmission. Note that no capacitor is provided directly at pin 7; thus, the circuit is operating as a first-order loop. The demodulated output signal is in the order of 50mV and the frequency response extends to 7kHz.

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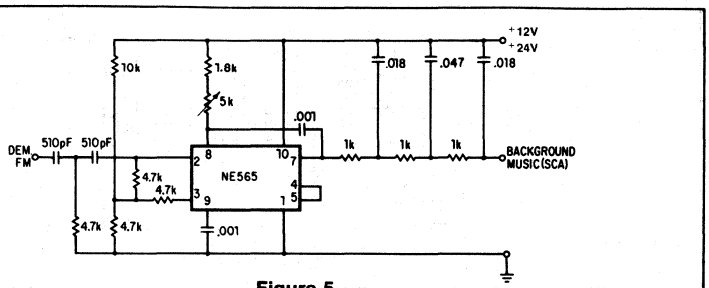

+12V
+24V
10k
1.8k
5k
.018
.047
.018
.001
DEM FM
510pF
510pF
1k
1k
1k
BACKGROUND MUSIC (SCA)
4.7k
4.7k
NE565
4.7k
4.7k
.001

Figure 5

NE/SE566-F,N,T

DESCRIPTION

The SE/NE 566 Function Generator is a voltage controlled oscillator of exceptional linearity with buffered square wave and triangle wave outputs.The frequency of oscillation is determined by an external resistor and capacitor and the voltage applied to the control terminal. The oscillator can be programmed over a ten to one frequency range by proper selection of an external resistance and modulated over a ten to one range by the control voltage, with exceptional linearity.

FEATURES

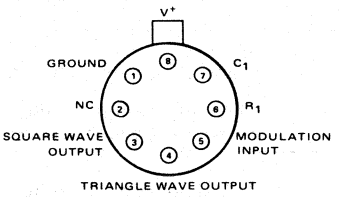
- **Wide range of operating voltage (up to 24 volts)**
- **High linearity of modulation**
- **Highly stable center frequency (200 ppm/°C typical)**
- **Highly linear triangle wave output**
- **Frequency programming by means of a resistor or capacitor, voltage or current**
- **Frequency adjustable over 10 to 1 range with same capacitor**

APPLICATIONS

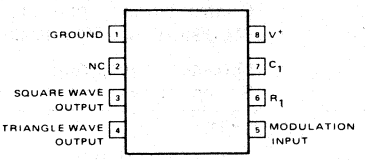
- **Tone generators**
- **Frequency shift keying**
- **FM modulators**
- **Clock generators**
- **Signal generators**
- **Function generators**

PIN CONFIGURATIONS

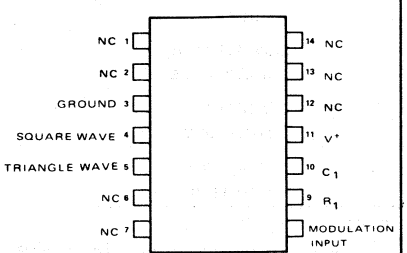
T PACKAGE



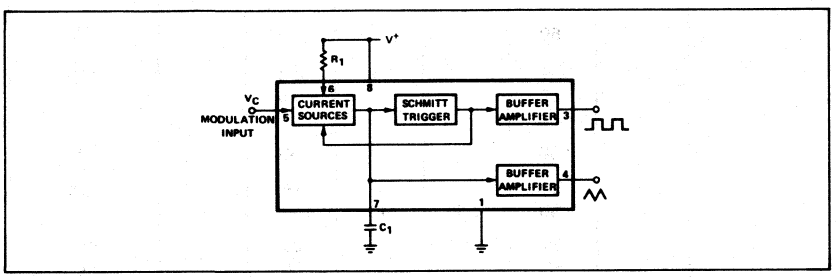
N PACKAGE



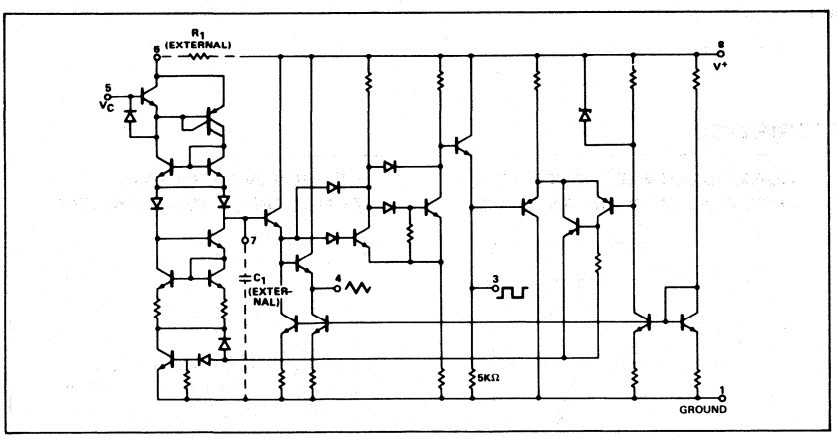
F PACKAGE



BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Maximum operating voltage	26	V
Input voltage	3	V_{P-P}
Storage temperature	-65 to +150	°C
Operating temperature range		
NE566	0 to +70	°C
SE566	-55 to +125	°C
Power dissipation	300	mW

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ELECTRICAL CHARACTERISTICS $T_A = 25°C$; $V_{CC} = 12V$ unless otherwise specified.

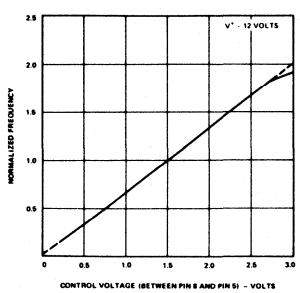
PARAMETER	SE566			NE566			UNIT
	Min	Typ	Max	Min	Typ	Max	
GENERAL							
Operating temperature range	-55		125	0		70	°C
Operating supply voltage			24			24	V
Operating supply current		7	12.5		7	12.5	mA
VCO[1]							
Maximum operating frequency		1			1		MHz
Frequency drift with temperature		200			300		ppm/°C
Frequency drift with supply voltage		1			2		%/V
Control terminal input impedance[2]		1			1		MΩ
FM distortion (±10% deviation)		0.2	0.75		0.4	1.5	%
Maximum sweep rate		1			1		MHz
Sweep range		10:1			10:1		
OUTPUT							
Triangle wave output							
Impedance		50			50		Ω
Voltage	1.9	2.4		1.9	2.4		Vpp
Linearity		0.2			0.5		%
Square wave input							
Impedance		50			50		Ω
Voltage	5	5.4		5	5.4		Vpp
Duty Cycle	45	50	55	40	50	60	%
Rise time		20			20		ns
Fall Time		50			50		ns

NOTES

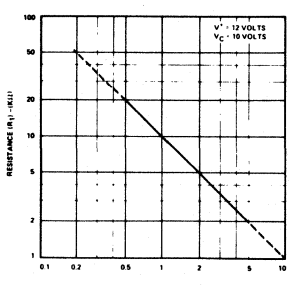
1. The external resistance for frequency adjustment (R_1) must have a value between 2kΩ and 20KΩ.
2. The bias voltage (V_C) applied to the control terminal (pin 5) should be in the range $3/4V^+ \leq V_C \leq V^+$.

TYPICAL PERFORMANCE CHARACTERISTICS

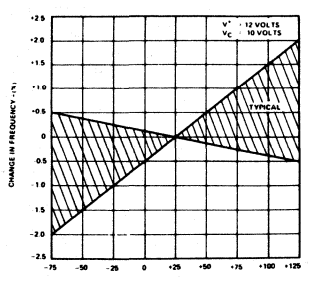
NORMALIZED FREQUENCY AS A FUNCTION OF CONTROL VOLTAGE



NORMALIZED FREQUENCY AS A FUNCTION OF RESISTANCE (R1)

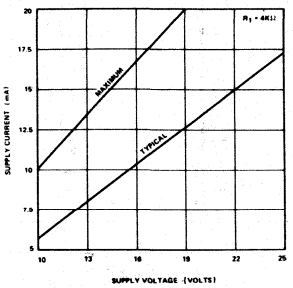


CHANGE IN FREQUENCY AS A FUNCTION OF TEMPERATURE

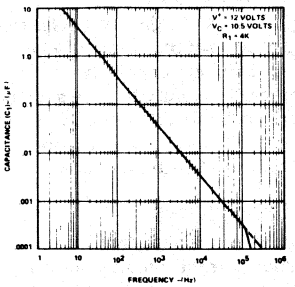


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

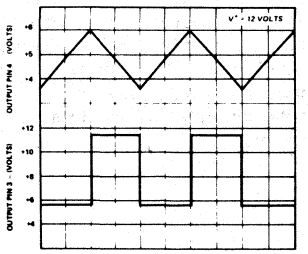
POWER SUPPLY CURRENT AS A FUNCTION OF SUPPLY VOLTAGE



FREQUENCY AS A FUNCTION OF CAPACITANCE (C1)



VCO OUTPUT WAVEFORMS



OPERATING INSTRUCTIONS

The SE/NE 566 Function Generator is a general purpose voltage controlled oscillator designed for highly linear frequency modulation. The circuit provides simultaneous square wave and triangle wave outputs at frequencies up to 1MHz. A typical connection diagram is shown in Figure 1. The control terminal (pin 5) must be biased externally with a voltage (V_C) in the range

$$3/4\ V^+ \leq V_C \leq V^+$$

where V_{CC} is the total supply voltage. In Figure 1, the control voltage is set by the voltage divider formed with R_2 and R_3. The modulating signal is then ac coupled with the capacitor C_2. The modulating signal can be direct coupled as well, if the appropriate dc bias voltage is applied to the control terminal. The frequency is given approximately by

$$f_o \simeq \frac{2[(V^+) - (V_C)]}{R_1 C_1 V^+}$$

and R_1 should be in the range $2k\Omega < R_1 < 20k\Omega$.

A small capacitor (typically $0.001\mu f$) should be connected between pins 5 and 6 to eliminate possible oscillation in the control current source.

If the VCO is to be used to drive standard logic circuitry, it may be desirable to use a dual supply of ±5 volts as shown in Figure 2. In this case the square wave output has the proper dc levels for logic circuitry. RTL can be driven directly from pin 3. For DTL or T²L gates, which require a current sink of more than 1mA, it is usually necessary to connect a 5kΩ resistor between pin 3 and negative supply. This increases the current sinking capability to 2mA. The third type of interface shown uses a saturated transistor between the 566 and the logic circuitry. This scheme is used primarily for T²L circuitry which requires a fast fall time (<50ns) and a large current sinking capability.

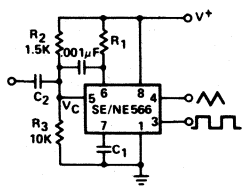


FIGURE 1

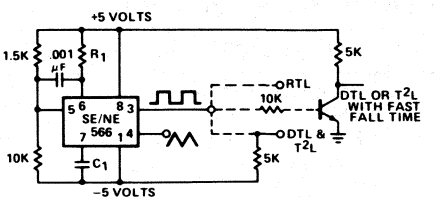


FIGURE 2

14

NE/SE567-F,N,T

DESCRIPTION

The SE/NE567 tone and frequency decoder is a highly stable phase-locked loop with synchronous AM lock detection and power output circuitry. Its primary function is to drive a load whenever a sustained frequency within its detection band is present at the self-biased input. The bandwidth center frequency, and output delay are independently determined by means of four external components.

FEATURES

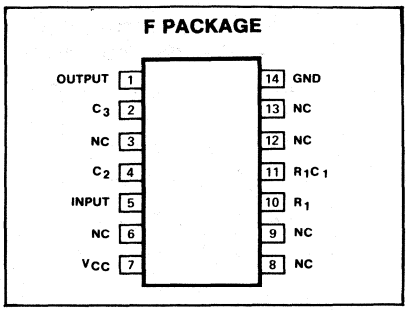
- **Wide frequency range (.01Hz to 500kHz)**
- **High stability of center frequency**
- **Independently controllable bandwidth (up to 14 percent)**
- **High out-band signal and noise rejection**
- **Logic-compatible output with 100mA current sinking capability**
- **Inherent immunity to false signals**
- **Frequency adjustment over a 20 to 1 range with an external resistor**
- **Military processing available**

APPLICATIONS

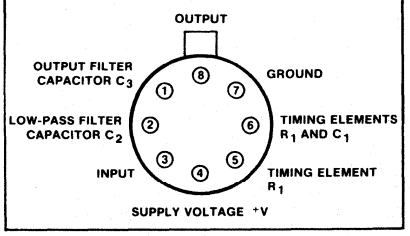
- **Touch Tone® decoding**
- **Carrier current remote controls**
- **Ultrasonic controls (remote TV, etc.)**
- **Communications paging**
- **Frequency monitoring and control**
- **Wireless intercom**
- **Precision oscillator**

PIN CONFIGURATIONS

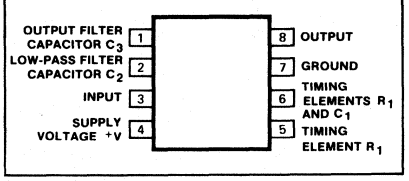
F PACKAGE



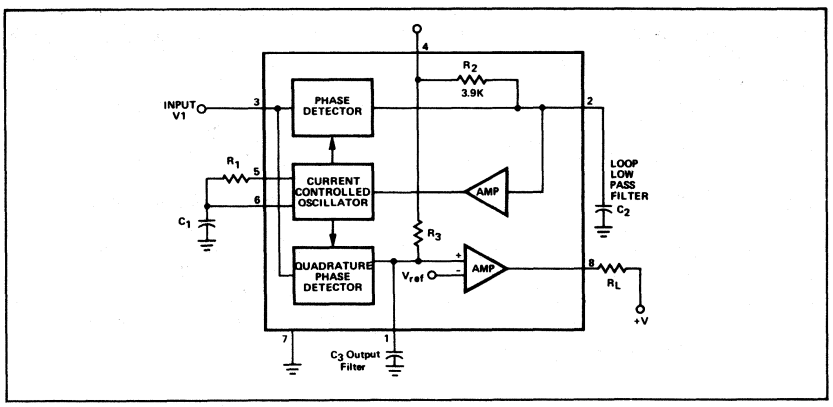
T PACKAGE



N PACKAGE



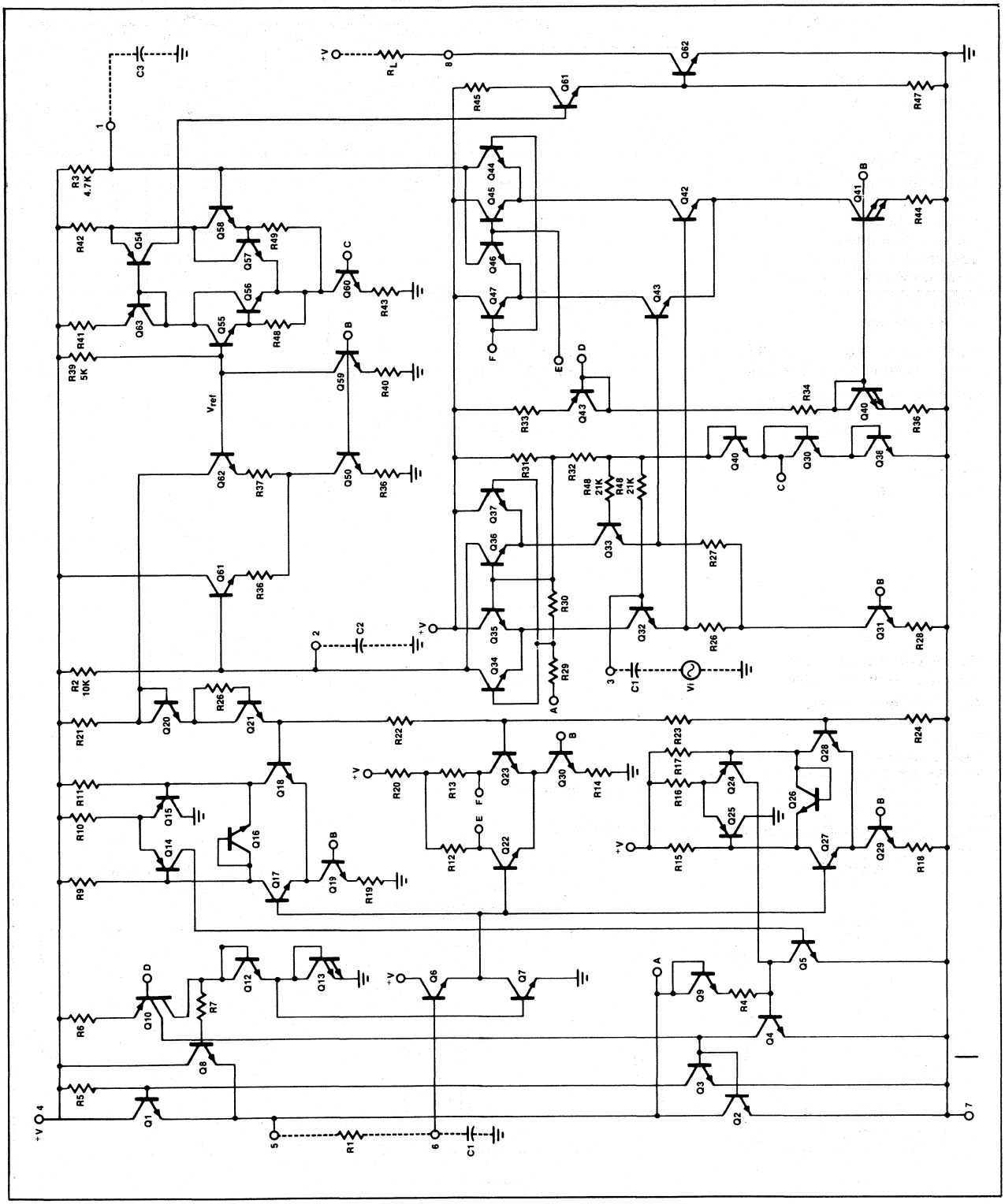
BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Operating temperature		
NE567	0 to +70	°C
SE567	-55 to +125	°C
Operating voltage	10	V
Positive voltage at input	0.5 + Vs	V
Negative voltage at input	-10	Vdc
Output voltage (collector of output transistor)	15	Vdc
Storage temperature	-65 to +150	°C
Power dissipation	300	mW

EQUIVALENT SCHEMATIC



DC ELECTRICAL CHARACTERISTICS (V+ = 5.0V; T_A = 25°C unless otherwise specified.)

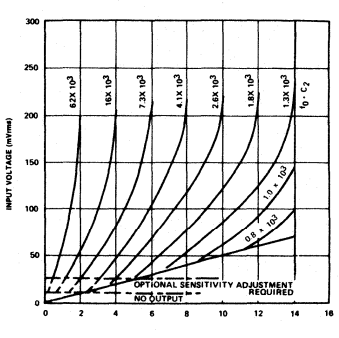
PARAMETER	TEST CONDITIONS	SE567			NE567			UNIT
		Min	Typ	Max	Min	Typ	Max	
CENTER FREQUENCY[1]								
Highest center frequency (f_o)		100	500		100	500		kHz
Center frequency stability[2]	-55 to +125°C		35±140			35±140		ppm/°C
	0 to +70°C		35±60			35±60		ppm/°C
Center frequency shift with supply voltage	f_o = 100kHz		0.5	1		0.7	2	%/V
DETECTION BANDWIDTH								
Largest detection bandwidth	f_o = 100kHz	12	14	16	10	14	18	% of f_o
Largest detection bandwidth skew			1	2		2	3	% of f_o
Largest detection bandwidth—variation with temperature	V_i = 300mVrms		±0.1			±0.1		%/°C
Largest detection bandwidth—variation with supply voltage	V_i = 300mVrms		±2			±2		%/V
INPUT								
Input resistance			20			20		kΩ
Smallest detectable input voltage (V_i)	I_L = 100mA, $f_i = f_o$		20	25		20	25	mVrms
Largest no-output input voltage	I_L = 100mA, $f_i = f_o$	10	15		10	15		mVrms
Greatest simultaneous outband signal to inband signal ratio			+6			+6		dB
Minimum input signal to wideband noise ratio	B_n = 140kHz		-6			-6		dB
OUTPUT								
Fastest on-off cycling rate			f_o/20			f_o/20		
"1" output leakage current			0.01	25		0.01	25	μA
"0" output voltage	I_L = 30mA		0.2	0.4		0.2	0.4	V
	I_L = 100mA		0.6	1.0		0.6	1.0	V
Output fall time[3]	R_L = 50Ω		30			30		ns
Output rise time[3]	R_L = 50Ω		150			150		ns
GENERAL								
Operating voltage range		4.75		9.0	4.75		9.0	V
Supply current quiescent			6	8		7	10	mA
Supply current—activated	R_L = 20kΩ		11	13		12	15	mA
Quiescent power dissipation			30			35		mW

NOTES

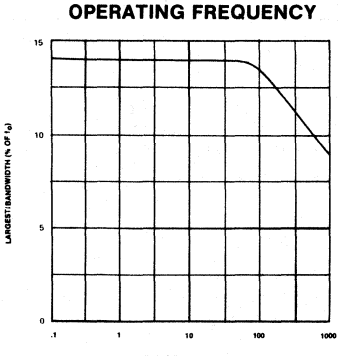
1. Frequency determining resistor R_1 should be between 1 and 20kΩ.
2. Applicable over 4.75 to 5.75 volts. See graphs for more detailed information.
3. Pin 8 to Pin 1 feedback R_L network selected to eliminate pulsing during turn-on and turn-off.

TYPICAL PERFORMANCE CHARACTERISTICS

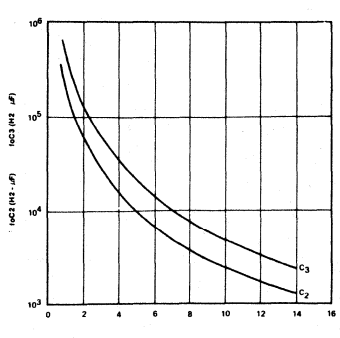
BANDWIDTH vs INPUT SIGNAL AMPLITUDE



LARGEST DETECTION BANDWIDTH vs OPERATING FREQUENCY

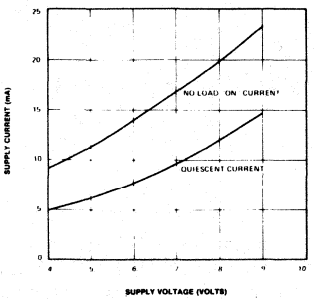


DETECTION BANDWIDTH AS A FUNCTION OF C_2 and C_3

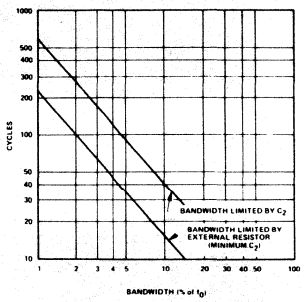


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

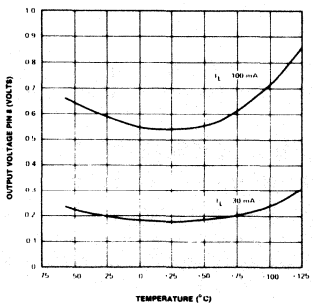
TYPICAL SUPPLY CURRENT vs SUPPLY VOLTAGE



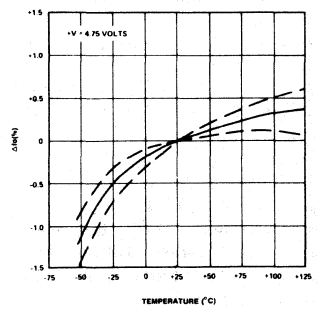
GREATEST NUMBER OF CYCLES BEFORE OUTPUT



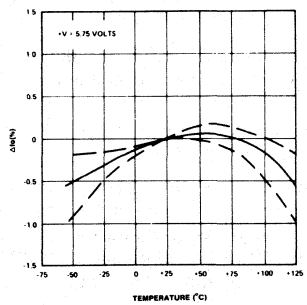
TYPICAL OUTPUT VOLTAGE vs TEMPERATURE



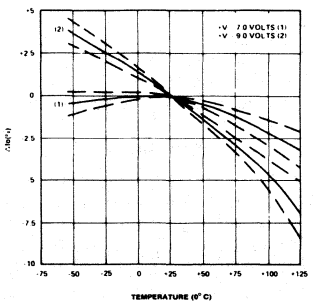
TYPICAL FREQUENCY DRIFT WITH TEMPERATURE (MEAN AND S.D.)



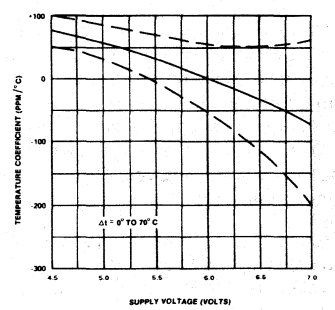
TYPICAL FREQUENCY DRIFT WITH TEMPERATURE (MEAN AND S.D.)



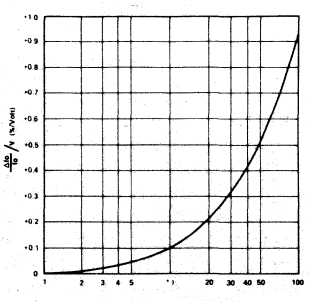
TYPICAL FREQUENCY DRIFT WITH TEMPERATURE (MEAN AND S.D.)



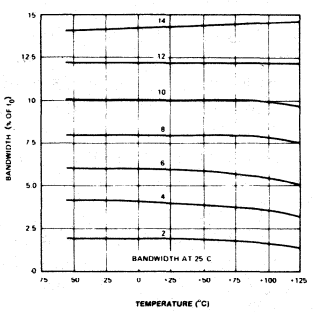
CENTER FREQUENCY TEMPERATURE COEFFICIENT (MEAN AND S.D.)



CENTER FREQUENCY SHIFT WITH SUPPLY VOLTAGE CHANGE vs OPERATING FREQUENCY



TYPICAL BANDWIDTH VARIATION WITH TEMPERATURE



14

DESIGN FORMULAS

$$f_o \approx \frac{1.1}{R_1C_1}$$

$$BW \approx 1070\sqrt{\frac{V_i}{f_oC_2}} \text{ in \% of } f_o,\ V_i \leq 200\text{mVrms}$$

Where

V_i = Input Voltage (Vrms)
C_2 = Low-Pass Filter Capacitor (μF)

PHASE LOCKED LOOP TERMINOLOGY CENTER FREQUENCY (fo)

The free-running frequency of the current controlled oscillator (CCO) in the absence of an input signal.

Detection Bandwidth (BW)

The frequency range, centered about f_o, within which an input signal above the threshold voltage (typically 20mVrms) will cause a logical zero state on the output. The detection bandwidth corresponds to the loop capture range.

Lock Range

The largest frequency range within which an input signal above the threshold voltage will hold a logical zero state on the output.

Detection Band Skew

A measure of how well the detection band is centered about the center frequency, f_0. The skew is defined as $(f_{max} + f_{min} - 2f_o)/2f_o$ where fmax and fmin are the frequencies corresponding to the edges of the detection band. The skew can be reduced to zero if necessary by means of an optional centering adjustment.

OPERATING INSTRUCTIONS

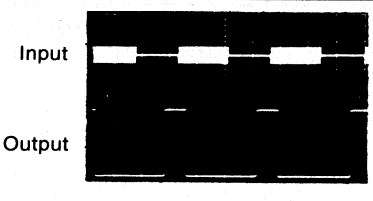
Figure 1 shows a typical connection diagram for the 567. For most applications, the following three-step procedure will be sufficient for choosing the external components R_1, C_1, C_2 and C_3.

1. Select R_1 and C_1 for the desired center frequency. For best temperature stability, R_1 should be between 2K and 20K ohm, and the combined temperature coefficient of the R_1C_1 product should have sufficient stability over the projected temperature range to meet the necessary requirements.

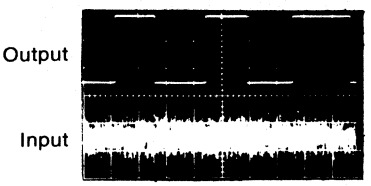
2. Select the low pass capacitor, C_2, by referring to the Bandwidth versus Input Signal Amplitude graph. If the input amplitude variation is known, the appropriate value of f_oC_2 necessary to give the desired bandwidth may be found. Conversely, an area of operation may be selected on this graph and the input level and C_2 may be adjusted accordingly. For example, constant bandwidth operation requires that input amplitude be above 200mVrms. The bandwidth, as noted on the graph, is then controlled solely by the f_oC_2 product (f_o (Hz), C_2 (μ fd)).

3. The value of C_3 is generally non-critical. C_3 sets the band edge of a low pass filter which attenuates frequencies outside the detection band to elminate spurious outputs. If C_3 is too small, frequencies just outside the detection band will switch the output stage on and off at the beat frequency, or the output may pulse on and off during the turn-on transient. If C_3 is too large, turn-on and turn-off of the output stage will be delayed until the voltage on C_3 passes the threshold voltage. (Such delay may be desirable to avoid spurious outputs due to translent frequencies.) A typical minimum value for C_3 is $2C_2$.

TYPICAL RESPONSE



Response to 100mVrms tone burst.
R_L = 100 ohms.



Response to same input tone burst with wideband noise.
$\frac{S}{N}$ = -6db R_L = 100 ohms
Noise Bandwidth = 140Hz

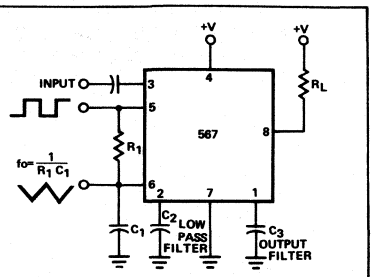


Figure 1

AVAILABLE OUTPUTS (Figure 2)

The primary output is the uncommitted output transistor collector, pin 8. When an in-band input signal is present, this transistor saturates; its collector voltage being less than 1.0 volt (typically 0.6V) at full output current (100mA). The voltage at pin 2 is the phase detector output which is a linear function of frequency over the range of 0.95 to 1.05 f_o with a slope of about 20mV per percent of frequency deviation. The average voltage at pin 1 is, during lock, a function of the inband input amplitude in accordance with the transfer characteristic given. Pin 5 is the controlled oscillator square wave output of magnitude $(+V - 2V_{be}) \approx (+V - 1.4V)$ having a dc average of +V/2. A 1kΩ load may be driven from pin 5. Pin 6 is an exponential triangle of 1 volt peak-to-peak with an average dc level of +V/2. Only high impedance loads may be connected to pin 6 without affecting the CCO duty cycle or temperature stability.

OPERATING PRECAUTIONS

A brief review of the following precautions will help the user achieve the high level of performance of which the 567 is capable.

1. Operation in the high input level mode (above 200mV) will free the user from bandwidth variations due to changes in the in-band signal amplitude. The input stage is now limiting, however, so that out-band signals or high noise levels can cause an apparent bandwidth reduction as the in-band signal is suppressed. Also, the limiting action will create in-band components from sub-harmonic signals, so the 567 becomes sensitive to signals at $f_o/3$, $f_o/5$, etc.

2. The 567 will lock onto signals near $(2n + 1)\ f_o$, and will give an output for signals near $(4n + 1)\ f_o$ where $n = 0, 1, 2$, etc. Thus, signals at $5f_o$ and $9f_o$ can cause an unwanted output. If such signals are anticipated, they should be attenuated before reaching the 567 input.

3. Maximum immunity from noise and out-band signals is afforded in the low input level (below 200mVrms) and reduced bandwidth operating mode. However, decreased loop damping causes the worse-case lock-up time to increase, as shown by the Greatest Number of Cycles Before Output vs Bandwidth graph.

4. Due to the high switching speeds (20ns) associated with 567 operation, care should be taken in lead routing. Lead lengths should be kept to a minimum. The power supply should be adequately bypassed close to the 567 with a 0.01μF or greater capacitor; grounding paths should be carefully chosen to avoid ground loops and

unwanted voltage variations. Another factor which must be considered is the effect of load energization on the power supply. For example, an incandescent lamp typically draws 10 times rated current at turn-on. This can cause supply voltage fluctuations which could, for example, shift the detection band of narrow-band systems sufficiently to cause momentary loss of lock. The result is a low-frequency oscillation into and out of lock. Such effects can be prevented by supplying heavy load currents from a separate supply or increasing the supply filter capacitor.

SPEED OF OPERATION

Minimum lock-up time is related to the natural frequency of the loop. The lower it is, the longer becomes the turn-on transient. Thus, maximum operating speed is obtained when C_2 is at a minimum. When the signal is first applied, the phase may be such as to initially drive the controlled oscillator away form the incoming frequency rather than toward it. Under this condition, which is of course unpredictable, the lock-up transient is at its worst and the theoretical minimum lock-up time is not achievable. We must simply wait for the transient to die out.

The following expressions give the values of C_2 and C_3 which allow highest operating speeds for various band center frequencies. The minimum rate at which digital information may be detected without information loss due to the turn-on transient or output chatter is about 10 cycles per bit, corresponding to an information transfer rate of $f_o/10$ baud.

$$C_2 = \frac{130}{f_o}\ \mu F$$

$$C_3 = \frac{260}{f_o}\ \mu F$$

In cases where turn-off time can be sacrificed to achieve fast turn-on, the optional sensitivity adjustment circuit can be used to move the quiescent C_3 voltage lower (closer to the threshold voltage). However, sensitivity to beat frequencies, noise and extraneous signals will be increased.

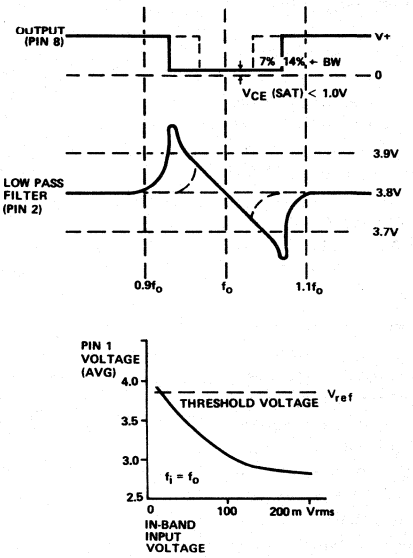


Figure 2

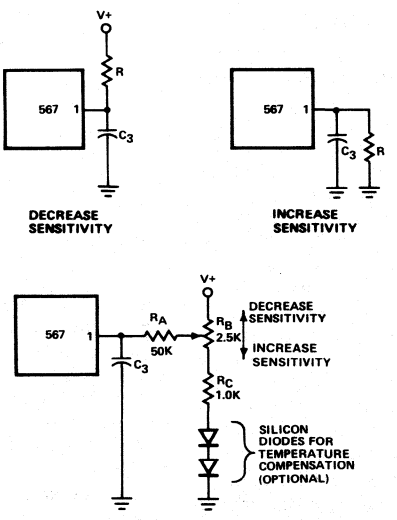


Figure 3

OPTIONAL CONTROLS (Figure 3)

The 567 has been designed so that, for most applications, no external adjustments are required. Certain applications, however, will be greatly facilitated if full advantage is taken of the added control possibilities available through the use of additional external components. In the diagrams given, typical values are suggested where applicable. For best results the resistors used, except where noted, should have the same temperature coefficient. Ideally, silicon diodes would be low-resistivity types, such as forward-biased transistor base-emmiter junctions. However, ordinary low-voltage diodes should be adequate for most applications.

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SENSITIVITY ADJUSTMENT

(Figure 3)

When operated as a very narrow band detector (less than 8 percent), both C_2 and C_3 are made quite large in order to improve noise and outband signal rejection. This will inevitably slow the response time. If, however, the output stage is biased closer to the threshold level, the turn-on time can be improved. This is accomplished by drawing additional current to terminal 1. Under this condition, the 567 will also give an output for lower-level signals (10mV or lower).

By adding current to terminal 1, the output stage is biased further away from the threshold voltage. This is most useful when, to obtain maximum operating speed, C_2 and C_3 are made very small. Normally, frequencies just outside the detection band could cause false outputs under this condition. By desensitizing the output stage, the outband beat notes do not feed through to the output stage. Since the input level must be somewhat greater when the output stage is made less sensitive, rejection of third harmonics or in-band harmonics (of lower frequency signals) is also improved.

CHATTER PREVENTION (Figure 4)

Chatter occurs in the output stage when C_3 is relatively small, so that the lock transient and the AC components at the quadrature phase detector (lock detector) output cause the output stage to move through its threshold more than once. Many loads, for example lamps and relays, will not respond to the chatter. However, logic may recognize the chatter as a series of outputs. By feeding the output stage output back to its input (pin 1) the chatter can be eliminated. Three schemes for doing this are given in Figure 4. All operate by feeding the first output step (either on or off) back to the input, pushing the input past the threshold until the transient conditions are over. It is only necessary to assure that the feedback time constant is not so large as to prevent operation at the highest anticipated speed. Although chatter can always be eliminated by making C_3 large, the feedback circuit will enable faster operation of the 567 by allowing C_3 to be kept small. Note that if the feedback time constant is made quite large, a short burst at the input frequency can be stretched into a long output pulse. This may be useful to drive, for example, stepping relays.

DETECTION BAND CENTERING (OR SKEW) ADJUSTMENT

(Figure 5)

When it is desired to alter the location of the detection band (corresponding to the loop capture range) within the lock range, the

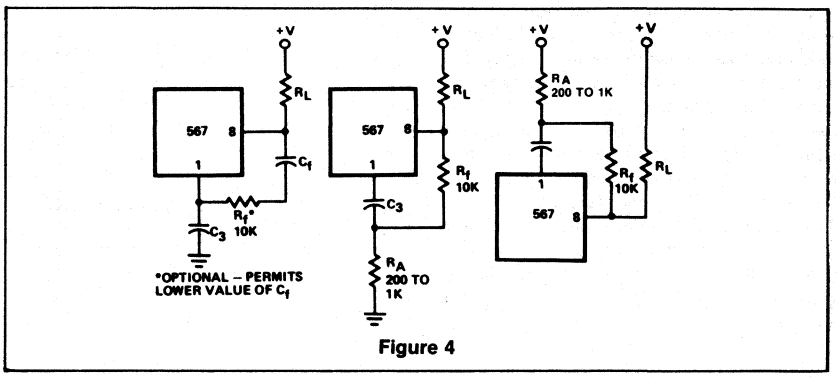


Figure 4

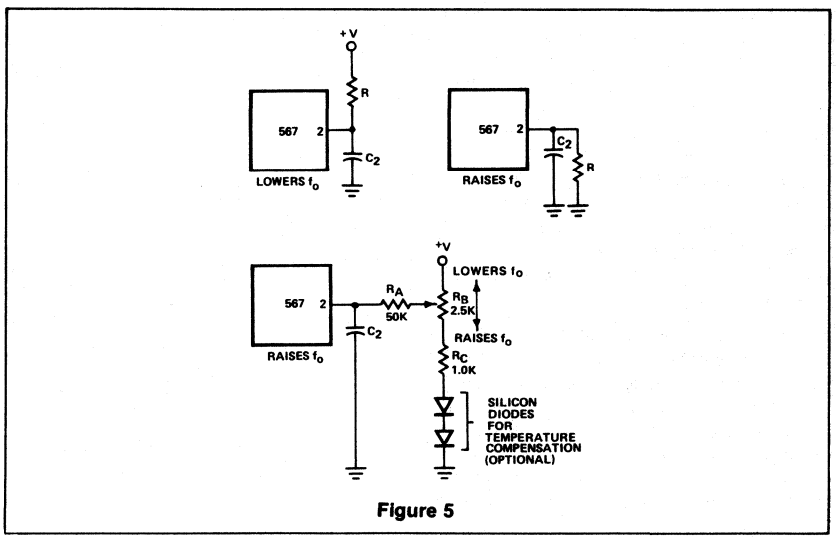


Figure 5

circuits shown above can be used. By moving the detection band to one edge of the range, for example, input signal variations will expand the detection band in only one direction. This may prove useful when a strong but undesirable signal is expected on one side or the other of the center frequency. Since R_B also alters the duty cycle slightly, this method may be used to obtain a precise duty cycle when the 567 is used as an oscillator.

ALTERNATE METHOD OF BANDWIDTH REDUCTION

(Figure 6)

Although a large value of C_2 will reduce the bandwidth, it also reduces the loop damping so as to slow the circuit response time. This may be undesirable. Bandwidth can be reduced by reducing the loop gain. This scheme will improve damping and permit faster operation under narrow-band conditions. Note that the reduced impedance level at terminal 2 will require that a larger value of C_2 be used for a given filter cutoff frequency. If more than three 567s are to be used, the network of R_B and R_C can be eliminated and the R_A resistors connected together. A capacitor between this junction and ground may be required to shunt high frequency components.

OUTPUT LATCHING (Figure 7)

To latch the output on after a signal is received, it is necessary to provide a feedback resistor around the output stage (between pins 8 and 1). Pin 1 is pulled up to unlatch the output stage.

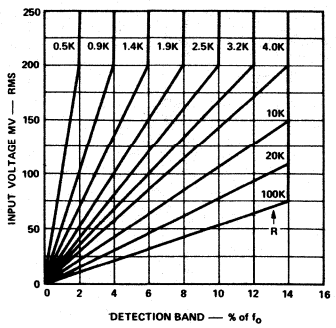
REDUCTION OF C1 VALUE

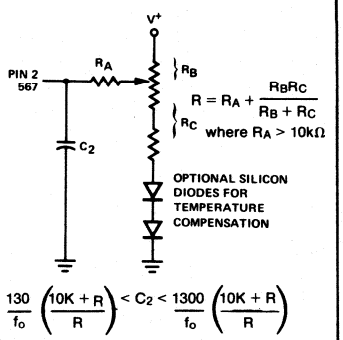
(Figure 8)

For precision very low-frequency applications, where the value of C_1 becomes large, an overall cost savings may be achieved by inserting a voltage follower between the R_1 C_1 junction and pin 6, so as to allow a higher value of R_1 and a lower value of C_1 for a given frequency.

PROGRAMMING

To change the center frequency, the value of R_1 can be changed with a mechanical or solid state switch, or additional C_1 capacitors may be added by grounding them through saturating npn transistors.





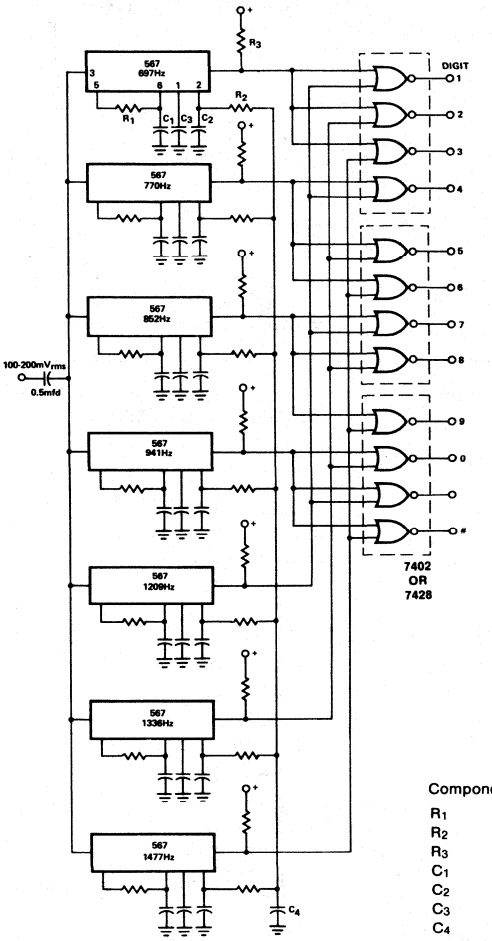
NOTE

Adjust control for symmetry of detection band edges about f_o.

Figure 6

TYPICAL APPLICATIONS

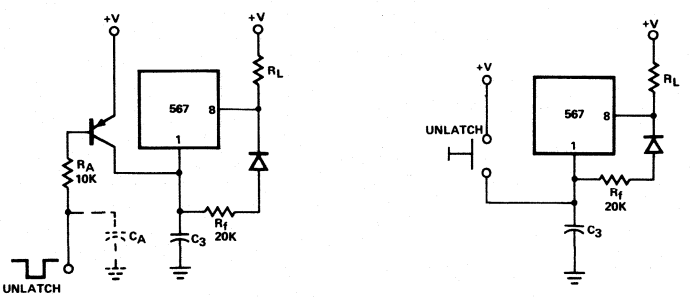
TOUCH-TONE® DECODER



Component values (Typical)

R_1	6.8 to 15K ohm
R_2	4.7K ohm
R_3	20K ohm
C_1	0.10mfd
C_2	1.0mfd 5V
C_3	2.2mfd 6V
C_4	250 μF 6V

OUTPUT LATCHING



C_A prevents latch-up when power supply is turned on.

Figure 7

PRECISION VLF

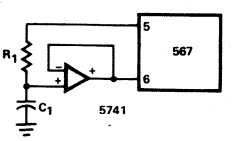
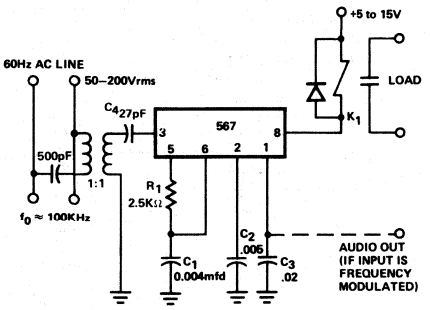


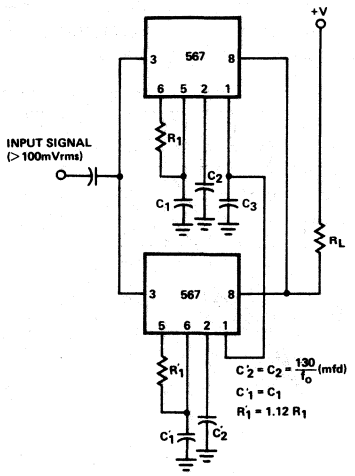
Figure 8

TYPICAL APPLICATIONS (Cont'd)

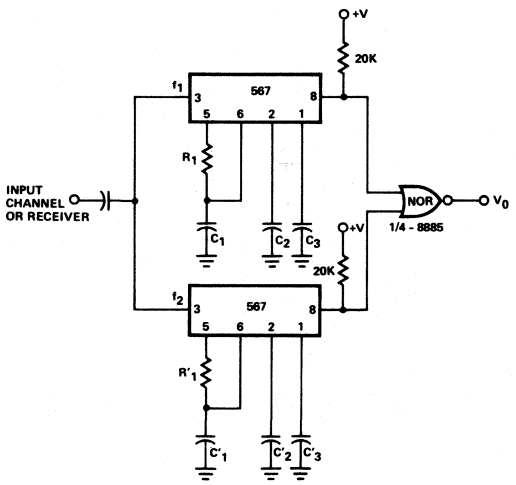
CARRIER-CURRENT REMOTE CONTROL OR INTERCOM



24% BANDWIDTH TONE DECODER

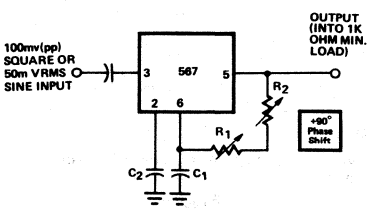


DUAL-TONE DECODER



1. Resistor and capacitor values chosen for desired frequencies and bandwidth.
2. If C_3 is made large so as to delay turn-on of the top 567, decoding of sequential (f_1 f_2) tones is possible.

0° to 180° PHASE SHIFTER

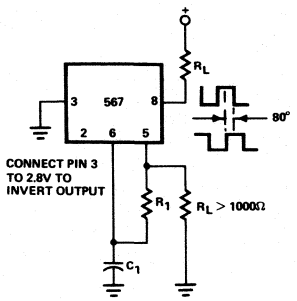


$R_2 \approx R_1/5$

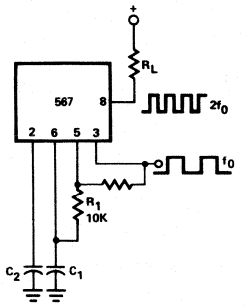
Adjust R_1 so that $\phi = 90°$ with control midway

TYPICAL APPLICATIONS (Cont'd)

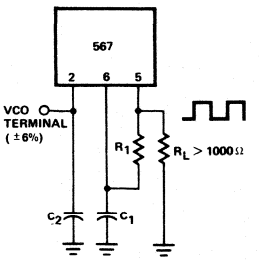
OSCILLATOR WITH QUADRATURE OUTPUT



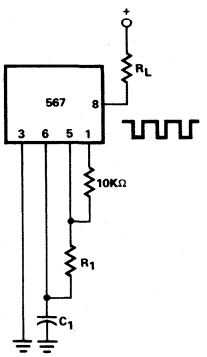
OSCILLATOR WITH DOUBLE FREQUENCY OUTPUT



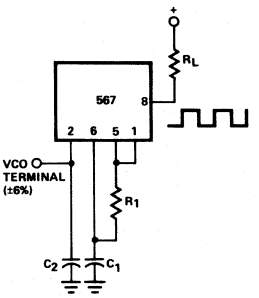
PRECISION OSCILLATOR WITH 20ns SWITCHING



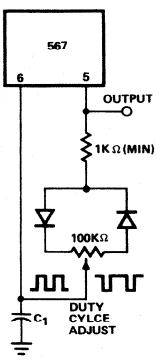
PULSE GENERATOR WITH 25% DUTY CYCLE



PRECISION OSCILLATOR TO SWITCH 100ma LOADS



PULSE GENERATOR



NOTE

Application information available on request.

SECTION 15
D-MOS FETS

Section 15—D-MOS FETS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

SD203-DC

DESCRIPTION

The Signetics D-MOS SD203 is a silicon, insulated gate, field effect transistor of the N-channel enhancement mode type. It is fabricated by the Signetics double-diffused process which gives superior high frequency performance up to 2GHz. A zener diode is connected between the gate and substrate of the SD201 and 203 that bypasses any voltage transient lying outside the range of -0.3V to +25.0V. Thus the gate of the 203 is protected against damage in all normal handling and operating situations.

The device is a general purpose transistor especially suited for amplifier designs in the UHF range (500MHz to 2GHz). It has extremely high transconductance, very low input capacitance and extremely low feedback capacitance. The SD203 combines high gain with low levels of noise, intermodulation distortion, and feedback capacitance. These parameters make it ideally suited for critical amplifier applications. This device is hermetically sealed in a modified 4-lead TO-72 package.

GENERAL FEATURES

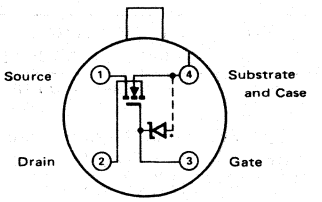
- **Ion-implanted for greater control and reliability**
- **Wide dynamic range**
- **Positive bias only**

SD203 FEATURES

- **High gain through UHF range: 10dB at 1.5GHz**
- **Low noise through UHF range: 3.5dB at 1.0GHz**
- **Low input capacitance: 3.0pF**
- **Low feedback capacitance: 0.20pF**
- **High drain-to-source voltage: +25V**
- **High forward transconductance: 20mmhos**

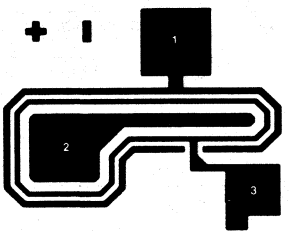
PIN CONFIGURATION

DC PACKAGE
(Top View)



ORDER PART NO.
SD203DC

SD203
SINGLE GATE RF DEVICE



PAD NO.	PAD FUNCTION
1	SOURCE
2	DRAIN
3	GATE/DIODE

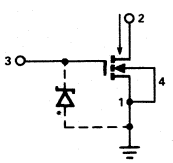
Die Size 19 X 22

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

	PARAMETER	RATING	UNIT
V_{DS}	Drain-to-source voltage SD203	+20	V
V_{DB}	Drain-to-substrate voltage SD203	+20	V
V_{GB}	DC gate-to-substrate voltage SD203	-0.3, +10	V
I_D	Drain current	50	mA
T_{STG}	Temperature range Storage	-65 to +175	°C
T_A	Operating	-55 to +125	°C
P_T	Transistor dissipation At +25°C case temperature (Derate linearly to +125°C case temperature at the rate of 8.0mW/°C.)	1.2	W
	At +25°C free-air temperature (Derate linearly to +125°C free-air temperature at the rate of 2.0mW/°C.)	300	mW

COMMON SOURCE BIAS SCHEME



$+V_{DS}$ = 0 → +20 Volts
$+V_{GS}$ = 0 → +4 Volts
$+I_{DS}$ = 0 → +20mA

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DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD203			UNIT
			Min	Typ	Max	
BV_{DS}	Drain-to-source breakdown voltage	$V_{GS} = 0V$, $I_D < 1\mu A$	20	25		V
I_{GSS}	Gate leakage current	$V_{GS} = \pm 10V$, $V_{DS} = 0V$				nA
		$V_{GS} = +10V$, $V_{DS} = 0V$		0.001	1.0	μA
$I_{D(OFF)}$	Drain-to-source current	$V_{DS} = +15V$, $V_{GS} = 0V$		0.001	1.0	μA
I_{DSS}	Zero bias drain current	$V_{DS} = +15V$, $V_{GS} = 0V$		0.001	1.0	μA
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_D = 1\mu A$	0.1	1.0	2.0	V
$r_{DS(ON)}$	Drain-to-source ON resistance	$V_{GS} = +5V$, $I_D = 1.0mA$		35	50	Ω

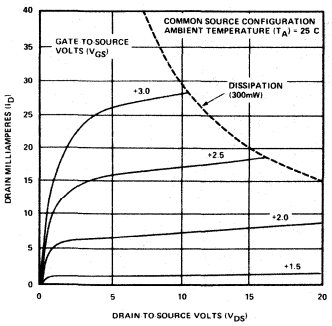
AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD203			UNIT
			Min	Typ	Max	
gfs	Forward transconductance	$V_{DS} = +15V$, $I_D = 20mA$, f = 1kHz $V_{GS} \cong +2.5V$	17	20		mmhos
	Small signal short circuit capacitance	$V_{DS} = +15V$, f = 1MHz				
	C_{ISS} input	$I_D = 20mA$		3.0	3.6	pF
	C_{OSS} output	$I_D = 0A$		1.0	1.2	pF
	C_{RSS} reverse transfer	$I_D = 0A$		0.20	0.30	pF
G_{ps}	Power gain	$V_{DS} = +15V$, $I_D = 20mA$, f = 1GHz $V_{GS} \cong +2.5V$	8	10		dB
NF	Noise figure*	$V_{DS} = +15V$, $I_D = 20mA$, f = 1GHz $V_{GS} \cong +2.5V$		4.0	5.0	dB
P_I	Intercept point	$V_{DS} = 15V$, $I_D = 20mA$, f=1GHz $\Delta f = 2MHz$		29		dBM

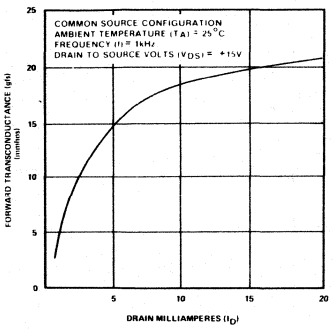
*NOTE
Measured in amplifier test fixture.

TYPICAL PERFORMANCE CHARACTERISTICS—SD203 (Cont'd)

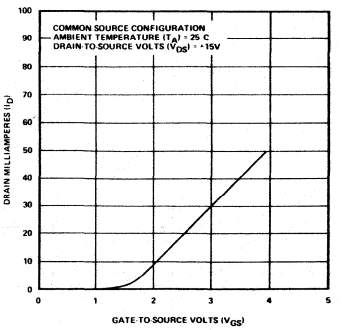
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



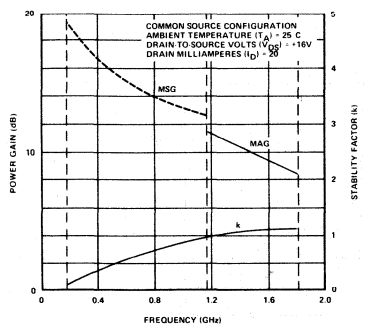
1kHz FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



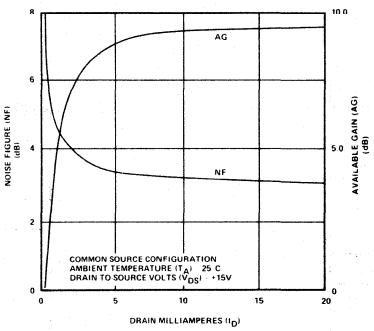
DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



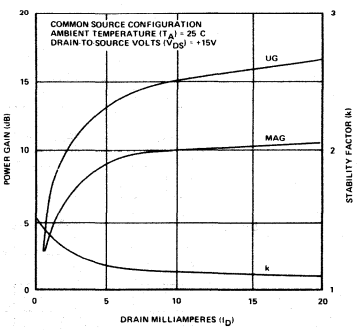
POWER GAIN vs FREQUENCY



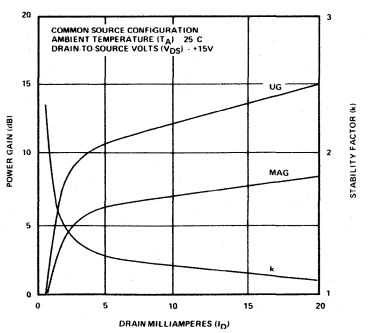
1.0GHz NOISE FIGURE AND AVAILABLE GAIN vs DRAIN CURRENT



1.5GHz POWER GAIN vs DRAIN CURRENT



1.8GHz POWER GAIN vs DRAIN CURRENT



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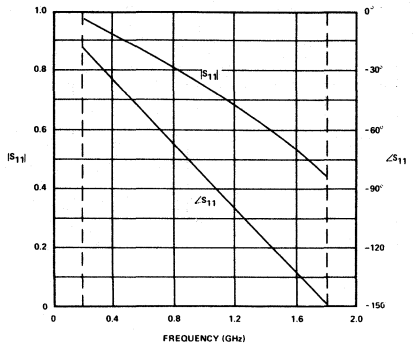
TYPICAL PERFORMANCE CHARACTERISTICS—SD203 (Cont'd)

"S" PARAMETERS—SD203

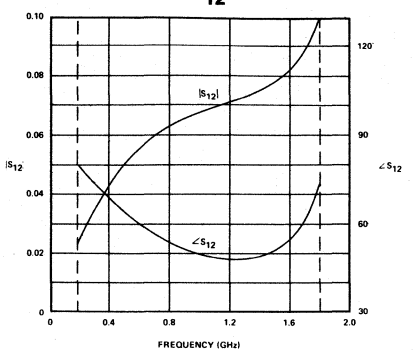
COMMON SOURCE CONFIGURATION
AMBIENT TEMPERATURE (T_A) = 25°C

DRAIN MILLIAMPERES (I_D) = 20
DRAIN-TO-SOURCE VOLTS (V_{DS}) = +15

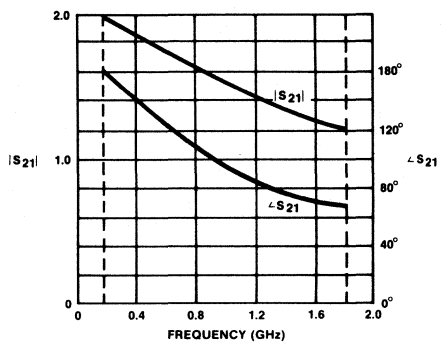
S_{11}



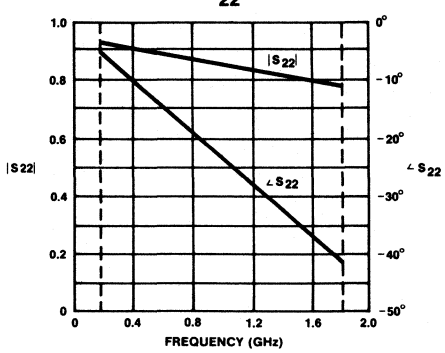
S_{12}



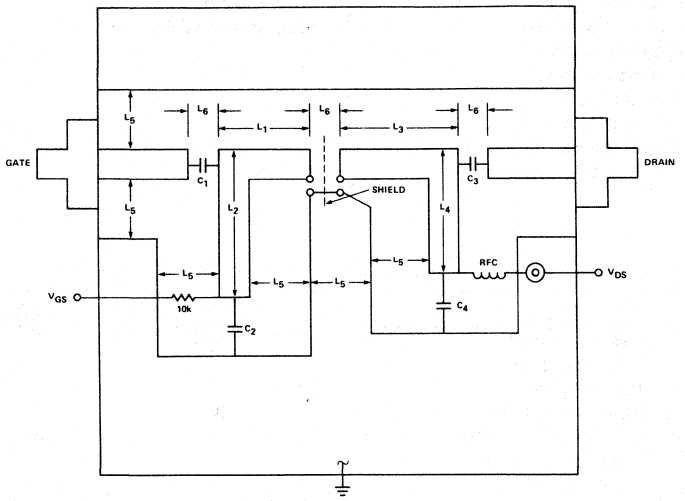
S_{21}



S_{22}



1GHz NOISE FIGURE TEST FIXTURE



Dialectric is 1/16" teflon-fiberglass (3M-K6096-11) all microstrip width = 0.175"

L1 = 0.48"	C1 = C2 = C3 = 0.8-10pF
L2 = 1.52"	Johanson 5201
L3 = 0.64"	C4 =1.20pF
L4 = 1.36"	Johanson 5501
L5 = 5/16"	RFC = 10 turns 26 AWG 1/4" dia.
L6 = 1/8"	1000pF bypass
	CORY FT4-01-2
	Launchers — OSM248.2

NOTE

Shield and 4 tunable capacitors on ground plane side of amplifier.

DESCRIPTION

The Signetics DMP4025 is a power MOSFET of the n-channel enhancement mode type designed for switching and amplifier applications requiring high current, high speed, and excellent linear transfer characteristics. Superior performance is achieved by utilizing the Signetics double-diffused MOS process which provides high gain, low drain to source "ON" resistance, low inter-electrode capacitance, and enhanced high frequency operation.

The device is hermetically sealed in a TO-39 package. The source, substrate, and case are connected to pin 3, which results in the package being at ground potential in the common source configuration.

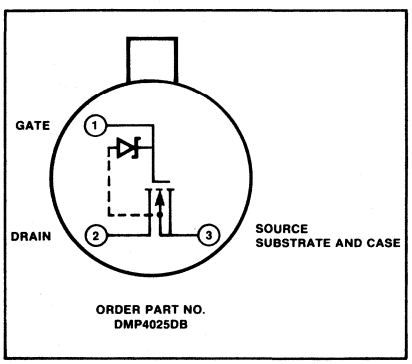
FEATURES

- **10dB gain @ 300MHz**
- **High I_{DS}: 800mA @ V_{GS} = +10V**
- **Withstands high VSWR**
- **No thermal runaway**
- **Low input capacitance**
- **Low feedback capacitance**
- **Switches 500mA in less than 2ns**
- **CMOS logic compatible input**
- **Extremely low drive current**

APPLICATIONS

- **Broadband power amplifier**
- **Power driver**
- **High speed switching**

PIN CONFIGURATION (Top View)



ORDER PART NO.
DMP4025DB

ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified

	PARAMETER	RATING	UNIT
V_{DS}	Drain-to-source	+25	V
V_{GS}	Gate-to-source	+20	V
V_{DG}	Drain-to-gate	+20	V
$I_{D(ON)}$	Continuous drain current	0.8	A
I_Z	Gate (Zener) current	10	mA
P_D	Power dissipation		
	T_A = 25°C[2]	1	W
	T_C = 25°C[3]	4	W
	Power derating factors		
	Free air	10	mW/°C
	Infinite heat sink	40	mW/°C
θ_{JA}	Thermal resistance	100	°C/W
θ_{JC}	Thermal resistance	25	°C/W
T_{OP}	Operating Temperature	−55 to +125	°C
T_{STG}	Storage Temperature	−55 to +150	°C

NOTES
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Free air.
3. Infinite heat sink.

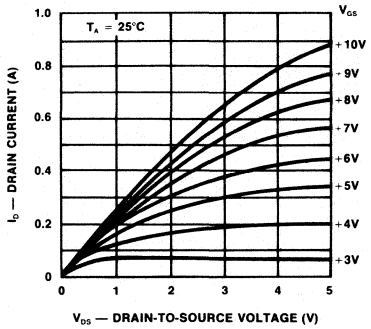
ELECTRICAL CHARACTERISTICS T_A = +25°C unless otherwise specified

	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
BV_{DSS}	Drain-source breakdown	I_D = 10μA, V_{GS} = 0	25	30		V
$V_{GS(th)}$	Gate threshold voltage	I_D = 10μA, V_{GS} = V_{DS} = $V_{GS(th)}$	0.5		2	V
$I_{D(ON)}$	Drain "ON" current [4]	V_{GS} = V_{DS} = +10V	1			A
$I_{D(OFF)}$	Drain "OFF" current	V_{DS} = +25V, V_{GS} = 0			1	μA
$r_{DS(ON)}$	Drain-source	V_{GS} = +5V, I_D = 50mA		6	8	Ω
	"ON" resistance[4]	V_{GS} = +10V, I_D = 50mA		4	6	Ω
		V_{GS} = +10V, I_D = 500mA		4	6	Ω
g_{fs}	Forward Transconductance[4]	V_{DS} = +15V, I_D = 200mA	100	120		mmhos
	Capacitance	V_{DS} = +10V, I_D = 0, f = 1MHz				pF
C_{iss}	Input			11	13	
C_{rss}	Reverse transfer			2	3	
C_{oss}	Common source output			6	8	
N_F	Noise figure[5]	f = 300MHz, V_{DS} = +10V, I_D = 100mA		3.5	4.5	dB
G_{ps}	Common source power gain[5]	f = 300MHz, V_{DS} = +10V, I_D = 100mA	9	12		dB
t_{ON}		See test figure		1		nS
t_{OFF}		See test figure		3		nS
P_I	Intercept point	f = 300MHz, V_{DS} = +12V, I_D = 400mA		29		dBM

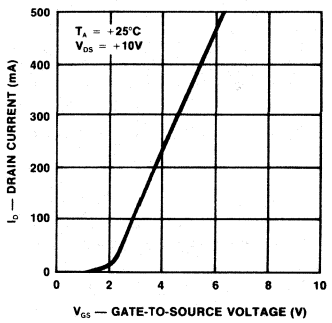
NOTES
4. Pulsed @ 80μs, 1% duty cycle.
5. Measured in amplifier test fixture.

TYPICAL PERFORMANCE CHARACTERISTICS

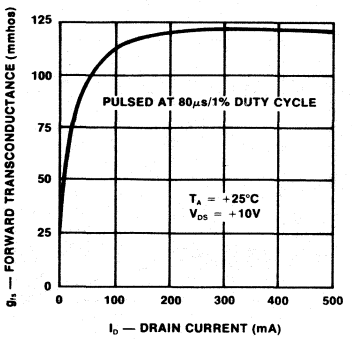
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



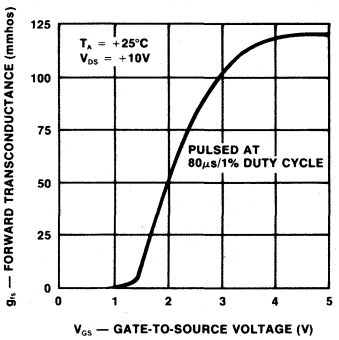
DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



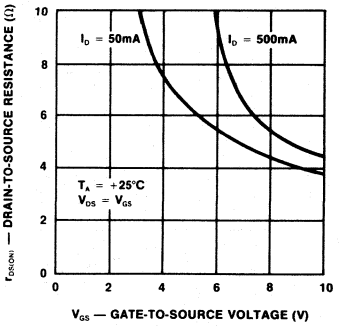
FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



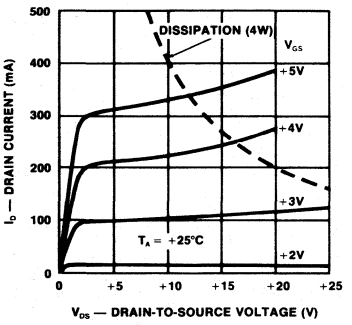
FORWARD TRANSCONDUCTANCE vs GATE-TO-SOURCE VOLTAGE



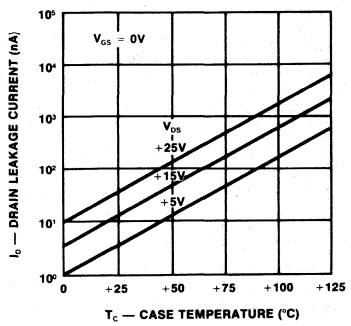
DRAIN-TO-SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



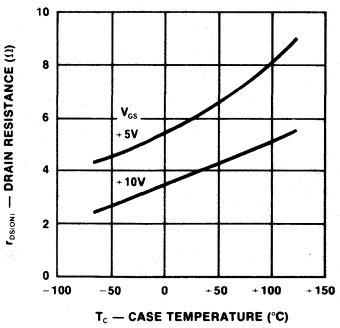
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



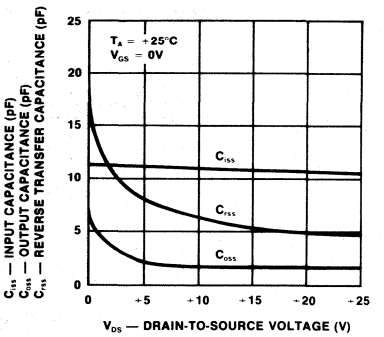
DRAIN LEAKAGE CURRENT vs CASE TEMPERATURE



DRAIN-TO-SOURCE RESISTANCE vs CASE TEMPERATURE



CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE



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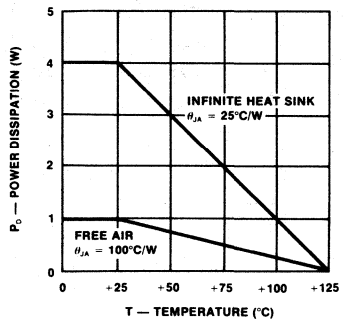
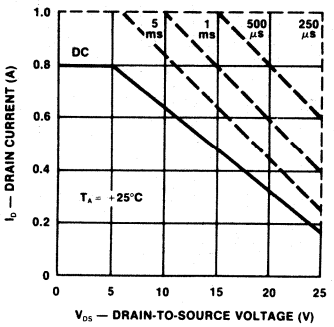
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

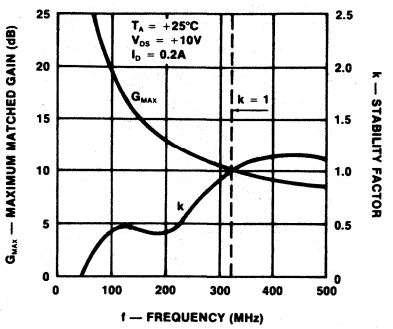
POWER DISSIPATION vs TEMPERATURE



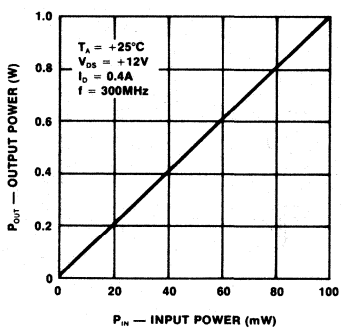
MAXIMUM SAFE OPERATING REGION



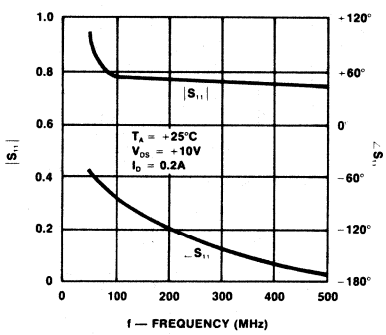
MAXIMUM MATCHED GAIN AND STABILITY FACTOR vs FREQUENCY



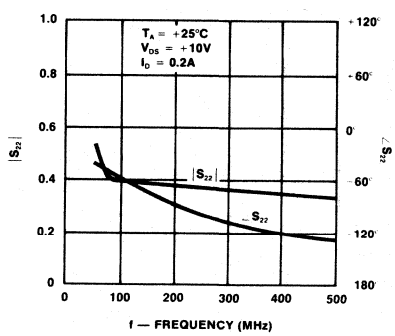
OUTPUT POWER vs INPUT POWER



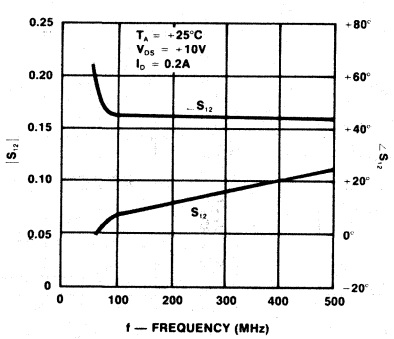
S_{11} vs FREQUENCY



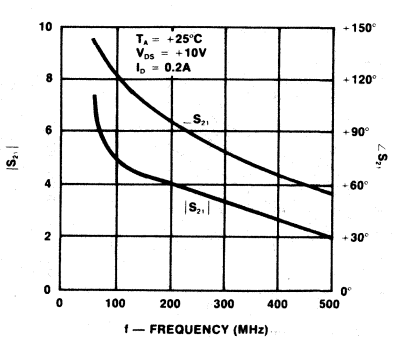
S_{22} vs FREQUENCY



S_{12} vs FREQUENCY



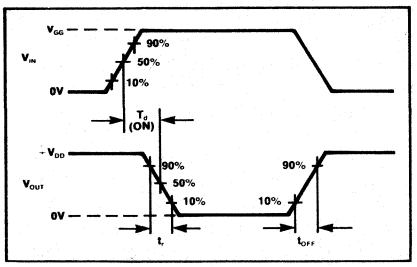
S_{21} vs FREQUENCY



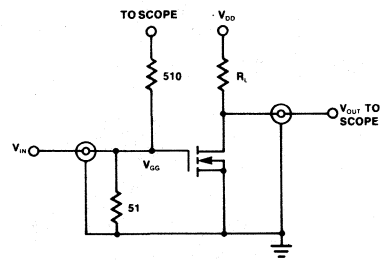
SWITCHING CHARACTERISTICS

V_{GG}(V)	V_{DD}(V)	R_L(Ω)	$t_{d(ON)}$(ns) Typ	t_r(ns) Typ	t_{OFF}(ns) Typ
5	5	100	<1	1	3
	10	200	<1	1	3
	20	390	<1	1	3
10	5	67	<1	1	3
	10	133	<1	1	3
	20	270	<1	1	3

SWITCHING WAVEFORMS



TEST CIRCUIT

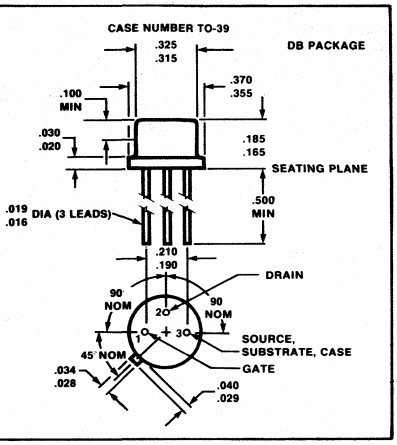


NOTE
All resistors standard and are measured in ohms.

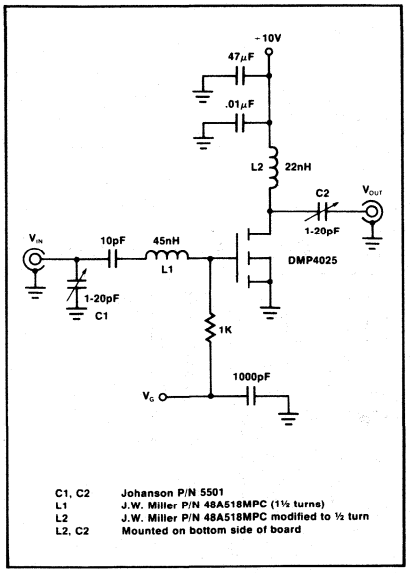
INPUT PULSE
t_d, t_r<1ns
PULSE WIDTH = 10ns
REP RATE = 1MHz

SAMPLING SCOPE
t_r<360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

PACKAGE OUTLINE

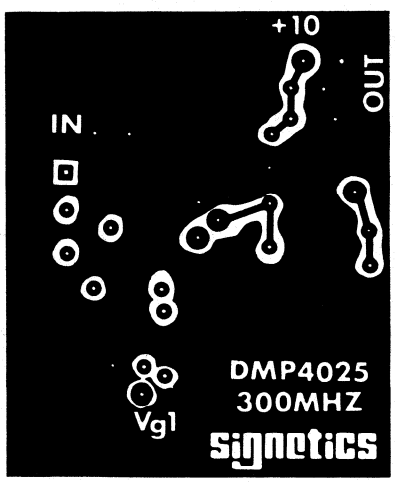


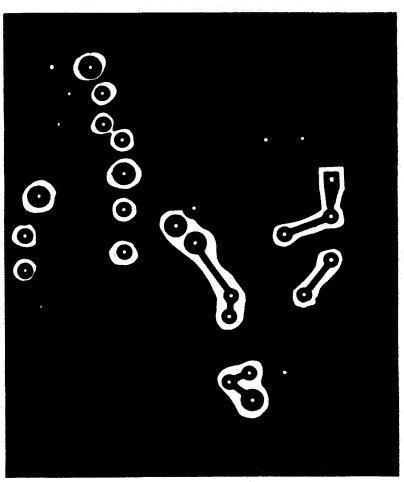
300MHz AMPLIFIER TEST CIRCUIT



C1, C2	Johanson P/N 5501
L1	J.W. Miller P/N 48A518MPC (1½ turns)
L2	J.W. Miller P/N 48A518MPC modified to ½ turn
L2, C2	Mounted on bottom side of board

300MHz AMPLIFIER PC BOARD LAYOUT





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SD210/211/212/213/214/215-DE

DESCRIPTION

The Signetics D-MOS SD210, 211, 212, 213, 214 and 215 are silicon, insulated gate, field effect transistors of the N-channel enhancement mode type. They are fabricated by the Signetics double-diffused process which gives high switching speed and low capacitance. A zener diode is connected between the gate and substrate of the SD211, 213 and 215. The diode bypasses any voltage transients which lie outside the range of -0.3V to +30V. Thus, the gate is protected against damage in all normal handling and operating situations. A drain-to-source breakdown of typically 35V makes the SD210 and 211 ideally suited for ±10V switch driver applications. Other characteristics allow them to be used as ±5V switches. The SD214 and 215 are designed to switch signals up to ±10V and the SD212 and 213 are designed to switch signals up to ±5V.

All the devices feature low gate node capacitance, extremely low drain node capacitance and very low feedback capacitance. Low "ON" resistance and hermetically sealed 4-lead TO-72 packages are also featured.

FEATURES

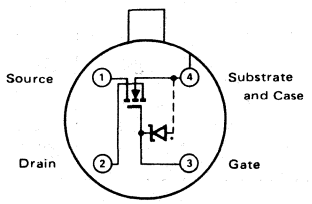
- **Low feedback capacitance: 0.30pF**
- **Low drain node capacitance: 1.3pF**
- **Low gate node capacitance: 2.4pF**
- **Low feedthrough and feedback transients**
- **Ion-implanted for greater reliability**
- **Excellent isolation from input to output: -120dB**
- **35V drain-to-source voltage for SD210/211**
- **Military qualifications pending**

APPLICATIONS

- **Switch driver**
- **Analog switch**
- **Multiplexers**
- **Digital switch**
- **Sample and hold**
- **Choppers**
- **A-TO-D converters**
- **D-TO-A converters**

PIN CONFIGURATION (Top View)

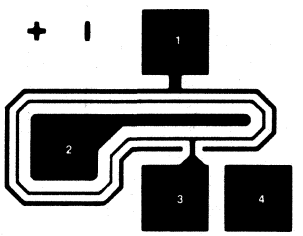
DE PACKAGE



*Diode protection on SD 211/213/215 only.

ORDER PART NO.
SD210DE, SD211DE, SD212DE,
SD213DE, SD214DE, SD215DE

CHIP DIAGRAM



PAD NO.	PAD FUNCTION
1	SOURCE
2	DRAIN
3	GATE
4	DIODE

Die size 19X22

For SD211, 213, 215 bond gate and diode to same point.

ABSOLUTE MAXIMUM RATINGS (all devices)

PARAMETER	RATING	UNIT
Drain current (I_D)	50	mA
Ambient temperature range		
Storage	-65 to +175	°C
Operating	-55 to +125	°C
Transistor dissipation (P_T)		
At 25°C case temperature (Derate linearly to +125 °C case temperature at the rate of 8.0mW/°C.)	1.2	W
At 25° C free-air temperature (Derate linearly to +125 °C free-air temperature at the rate of 2.0mW/°C.)	300	mW

ABSOLUTE MAXIMUM RATINGS T_A = 25° C unless otherwise specified.*

PARAMETER		SD210	SD211	SD212	SD213	SD214	SD215	UNIT
V_{DS}	Drain-to-source	+30	+30	+10	+10	+20	+20	Vdc
V_{SD}	Source-to-drain*	+10	+10	+10	+10	+20	+20	Vdc
V_{DB}	Drain-to-substrate	+30	+30	+15	+15	+25	+25	Vdc
V_{SB}	Source-to-substrate	+15	+15	+15	+15	+25	+25	Vdc
V_{GS}	Gate-to-source	±40	-15 +25	±40	-15 +25	±40	-25 +30	Vdc
V_{GB}	Gate-to-substrate	±40	-0.3 +25	±40	-0.3 +25	±40	-0.3 +30	Vdc
V_{GD}	Gate-to-drain	±40	-30 +25	±40	-15 +25	±40	-25 +30	Vdc

*NOTE

Refer to test conditions specified in Electrical Characteristics Table.

DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER	TEST CONDITIONS	SD210			SD211			SD212			UNIT
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Breakdown voltage											
BV_{DS} Drain-to-source	$V_{GS} = V_{BS} = 0V$, $I_D = 10\mu A$	30	35		30	35					V
	$V_{GS} = V_{BS} = -5V$, $I_S = 10nA$	10	25		10	25		10	25		V
BV_{SD} Source-to-drain	$V_{GD} = V_{BD} = -5V$ $I_D = 10nA$	10			10			10			V
BV_{DB} Drain-to-substrate	$V_{GB} = 0V$, source OPEN $I_D = 10nA$	15			15			15			V
BV_{SB} Source-to-substrate	$V_{GB} = 0V$, drain OPEN $I_S = 10\mu A$	15			15			15			V
Leakage current											
$I_{DS}(OFF)$ Drain-to-source	$V_{GS} = V_{BS} = -5V$ $V_{DS} = +10V$		1	10		1	10		1	10	nA
$I_{SD}(OFF)$ Source-to-drain	$V_{GD} = V_{BD} = -5V$ $V_{SD} = +10V$		1	10		1	10		1	10	nA
I_{GBS} Gate	$V_{DB} = V_{SB} = 0V$ $V_{GB} = \pm 40V$			0.1						0.1	nA
	$V_{GB} = +25V$						10				μA
V_T Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_S = 1\mu A$ $V_{SB} = 0V$	0.5	1.0	2.0	0.5	1.0	2.0	0.1	1.0	2.0	V
$r_{DS}(ON)$ Drain-to-source resistance	$I_D = 1.0mA$, $V_{SB} = 0$										
	$V_{GS} = +5V$		50	70		50	70		50	70	Ω
	$V_{GS} = +10V$		30	45		30	45		30	45	Ω
	$V_{GS} = +15V$		23			23			23		Ω
	$V_{GS} = +20V$		19			19			19		Ω
	$V_{GS} = +25V$		17						17		Ω

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DC ELECTRICAL CHARACTERISTICS (Cont'd) T_A = 25 °C unless otherwise specified.

PARAMETER	TEST CONDITIONS	SD213			SD214			SD215			UNIT
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Breakdown voltage											
BV_{DS} Drain-to-source	$V_{GS} = V_{BS} = -5V$, $I_S = 10nA$	10	25		20	25		20	25		V
BV_{SD} Source-to-drain	$V_{GD} = V_{BD} = -5V$ $I_D = 10nA$	10			20			20			V
BV_{DB} Drain-to-substrate	V_{GB} = 0V, source OPEN $I_D = 10nA$	15			25			25			V
BV_{SB} Source-to-substrate	V_{GB} = 0V, drain OPEN $I_S = 10\mu A$	15			25			25			V
Leakage current											
$I_{DS(OFF)}$ Drain-to-source	$V_{GS} = V_{BS} = -5V$										
	$V_{DS} = +10V$		1	10							nA
	$V_{DS} = +20V$					1	10		1	10	nA
$I_{SD(OFF)}$ Source-to-drain	$V_{GD} = V_{BD} = -5V$										
	$V_{SD} = +10V$		1	10							nA
	$V_{SD} = +20V$					1	10		1	10	nA
I_{GBS} Gate	$V_{DB} = V_{SB} = 0V$										
	$V_{GB} = \pm 40V$						0.1				nA
	$V_{GB} = +25V$			10							μA
	$V_{GB} = +30V$									10	μA
V_T Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_S = 1\mu A$ $V_{SB} = 0V$	0.1	1.0	2.0	0.1	1.0	2.0	0.1	1.0	2.0	V
$r_{DS(ON)}$ Drain-to-source resistance	I_D = 1.0mA, V_{SB} = 0										
	$V_{GS} = +5V$		50	70		50	70		50	70	Ω
	$V_{GS} = +10V$		30	45		30	45		30	45	Ω
	$V_{GS} = +15V$		23			23			23		Ω
	$V_{GS} = +20V$		19			19			19		Ω
	$V_{GS} = +25V$					17			17		Ω

AC ELECTRICAL CHARACTERISTICS T_A = 25 °C unless otherwise specified.

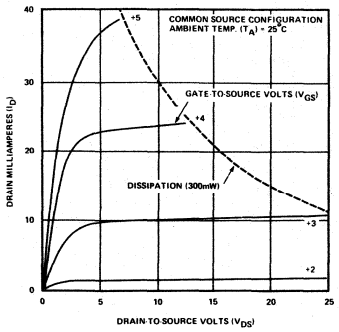
PARAMETER	TEST CONDITIONS	SD210			SD211			SD212			UNIT
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
gfs Forward transconductance	V_{DS} = 10V, V_{SB} = 0V I_D = 20mA, f = 1kHz	10	15		10	15		10	15		mmhos
Small Signal Capacitances (See capacitance model)	V_{DS} = 10V, f = 1MHz $V_{GS} = V_{BS} = -15V$										
$C_{(GS+GD+GB)}$ Gate node			2.4	3.5		2.4	3.5		2.4	3.5	pF
$C_{(GD+DB)}$ Drain node			1.3	1.5		1.3	1.5		1.3	1.5	pF
$C_{(GS+SB)}$ Source node			3.5	4.0		3.5	4.0		3.5	4.0	pF
C_{DG} Reverse transfer			0.3	0.5		0.3	0.5		0.3	0.5	pF

AC ELECTRICAL CHARACTERISTICS (Cont'd) T_A = 25 °C unless otherwise specified.

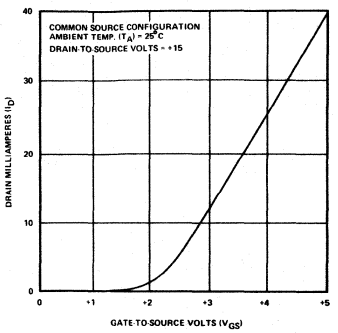
PARAMETER	TEST CONDITIONS	SD213			SD214			SD215			UNIT
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
gfs Forward transconductance	V_{DS} = 10V, V_{SB} = 0V I_D = 20mA, f = 1kHz	10	15		10	15		10	15		mmhos
Small Signal Capacitances (See capacitance model)	V_{DS} = 10V, f = 1MHz $V_{GS} = V_{BS} = -15V$										
$C_{(GS+GD+GB)}$ Gate node			2.4	3.5		2.4	3.5		2.4	3.5	pF
$C_{(GD+DB)}$ Drain node			1.3	1.5		1.3	1.5		1.3	1.5	pF
$C_{(GS+SB)}$ Source node			3.5	4.0		3.5	4.0		3.5	4.0	pF
C_{DG} Reverse transfer			0.3	0.5		0.3	0.5		0.3	0.5	pF

TYPICAL PERFORMANCE CHARACTERISTICS

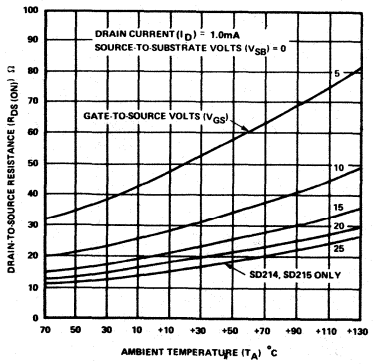
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



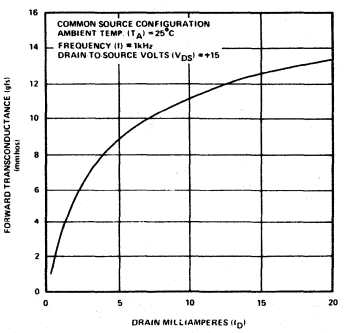
DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



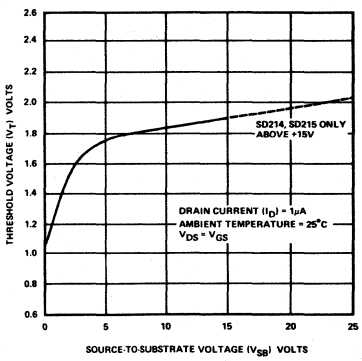
DRAIN-TO-SOURCE RESISTANCE vs TEMPERATURE



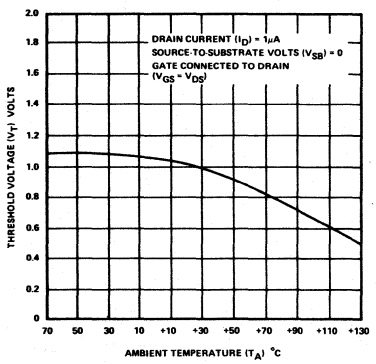
1kHz FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



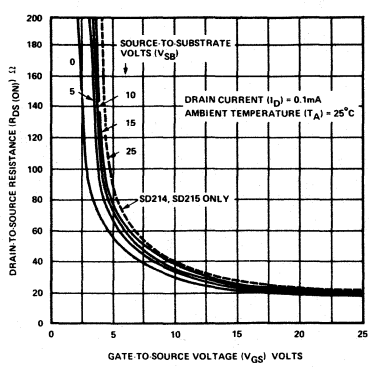
THRESHOLD VOLTAGE vs SOURCE-TO-SUBSTRATE VOLTAGE



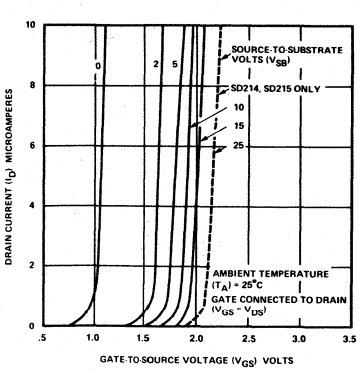
THRESHOLD VOLTAGE vs TEMPERATURE



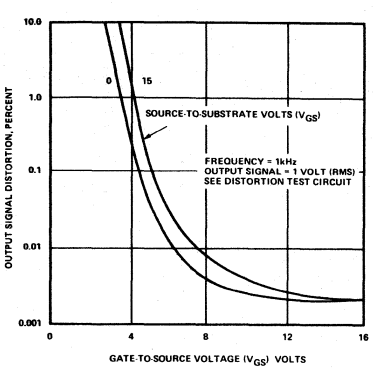
DRAIN-TO-SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



DISTORTION vs GATE-TO-SOURCE VOLTAGE



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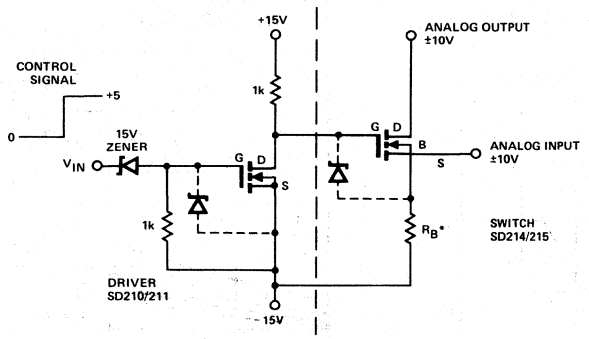
TYPICAL APPLICATION

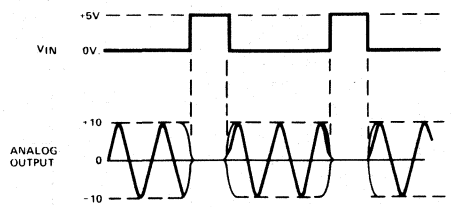
D-MOS DRIVER/SWITCH



R_B*Optional current limiting resistor

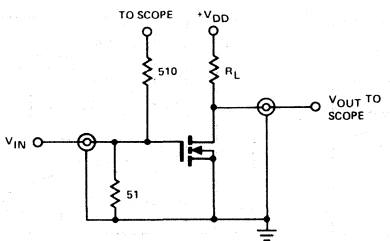
NOTE
*All resistors standard and are measured in ohms.

TYPICAL SWITCHING WAVEFORM



TEST CIRCUITS

SWITCHING

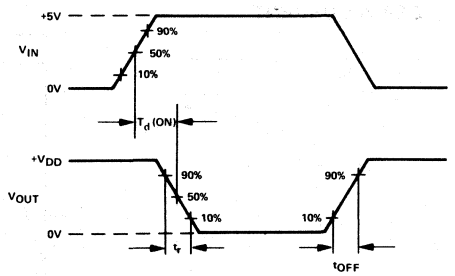


Input pulse: t_d, t_r < 1ns,
Pulse width = 100ns,
Rep rate = 1MHz

SAMPLING SCOPE

t_r < 360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

TYPICAL SWITCHING WAVEFORM

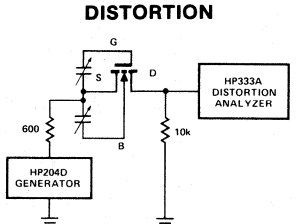


SWITCHING CHARACTERISTICS

		$t_{d(ON)}$ (ns)		t_r(ns)		t_{OFF}(ns)	
V_{DD}	R_L	Typ	Max	Typ	Max	Typ	Max
5	680	0.6	1.0	0.7	1.0	9.0	*
10	680	0.7		0.8		9.0	*
15	1k	0.9		1.0		14.0	*

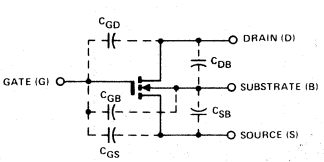
*t_{OFF} is dependent on R_L and C_L and does not depend on the device characteristics.

DISTORTION



NOTE: All resistors standard and are measured in ohms.

CAPACITANCE MODEL



DESCRIPTION

The Signetics DMS4025DE is a power MOSFET of the n-channel enhancement mode type designed for switching applications requiring high current, high speed, low "ON" resistance and excellent node-to-node isolation. Superior performance is achieved by utilizing the Signetics double-diffused MOS process which provides high gain, low drain to source "ON" resistance, low inter-electrode capacitance, and enhanced high frequency operation. The DMS4025DE is designed to switch analog signals up to ±7.5 volts. The device is hermetically sealed in a 4-lead TO-72 package.

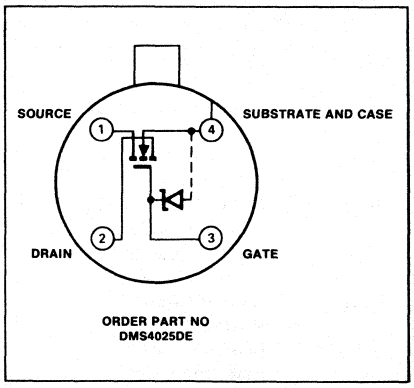
FEATURES

- **Low node capacitances**
- **Low feedthrough and feedback transients**
- **Excellent isolation from input to output**
- **CMOS logic compatible input**
- **Extremely low drive current**
- **Switches 500mA in less than 2ns**

APPLICATIONS

- **Switch driver**
- **Analog switch**
- **Multiplexers**
- **Digital switch**
- **Sample and hold**
- **A-to-D converters**
- **D-to-A converters**

PIN CONFIGURATION (Top View)



ORDER PART NO
DMS4025DE

ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified

PARAMETER		RATING	UNIT
V_{DS}	Drain-to-source	+25	V
V_{SD}	Source-to-drain[2]	+15	V
V_{DB}	Drain-to-body	+22.5	V
V_{SB}	Source-to-body	+22.5	V
V_{GB}	Gate-to-body	+30	V
V_{GS}	Gate-to-source	±22.5	V
V_{GD}	Gate-to-drain	±22.5	V
$I_{D(ON)}$	Continuous drain current	800	mA
P_D	Power dissipation		
	T_A = +25°C[3]	300	mW
	T_C = +25°C[4]	1.2	W
	Power derating factors		
	Free air	3	mW/°C
	Infinite heat sink	12	mW/°C
θ_{JA}	Thermal resistance	330	°C/W
θ_{JC}	Thermal resistance	83.5	°C/W
T_{OP}	Operating temperature	−55 to +125	°C
T_{STG}	Storage temperature	−55 to +150	°C

NOTES

1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. See test conditions in dc electrical characteristics section.
3. Free air.
4. Infinite heat sink.

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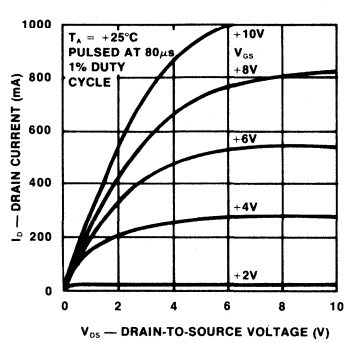
ELECTRICAL CHARACTERISTICS T_A = +25°C

PARAMETER		TEST CONDITIONS	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
BV_{DS}	Breakdown voltage drain-source	$V_{GS} = V_{BS} = 0V$, $I_D = 10\mu A$	25	30		V
		$V_{GS} = V_{BS} = -5V$, $I_D = 100nA$	15			V
BV_{SD}	Breakdown voltage source-drain	$V_{GD} = V_{BD} = -5V$, $I_S = 100nA$	15			V
BV_{DB}	Breakdown voltage drain-body	$V_{GB} = 0V$, $I_D = 100nA$, source open	22.5			V
BV_{SB}	Breakdown voltage source-body	$V_{GB} = 0V$, $I_S = 100nA$, drain open	22.5			V
$I_{D(OFF)}$	Leakage current drain node	$V_{GS} = V_{BS} = -5V$, $V_{DS} = +15V$		10	100	nA
$I_{S(OFF)}$	Leakage current source node	$V_{GD} = V_{BD} = -5V$, $V_{SD} = +15V$		10	100	nA
$I_{G(OFF)}$	Leakage current gate node (OFF)	$V_{GB} = 0V$, $V_{GS} = V_{GD} = -22.5V$		1	100	nA
$I_{G(ON)}$	Leakage current gate node (ON)	$V_{GB} = +30V$, $V_{GS} = V_{GD} = +22.5V$		.05	10	μA
$I_{D(ON)}$	Drain "ON" current [5]	$V_{GS} = V_{DS} = +10V$, $V_{SB} = 0V$,	1			A
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $V_{SB} = 0V$, $I_D = 10\mu A$	0.1	1	2	V
$r_{DS(ON)}$	Drain-source "ON" resistance[5]	$V_{GS} = +5V$, $I_D = 50mA$		6	8	Ω
		$V_{GS} = +10V$, $I_D = 50mA$		4	6	Ω
		$V_{GS} = +10V$, $I_D = 500mA$		4	6	Ω
g_{fs}	Forward Transconductance[5]	$V_{DS} = +15V$, $I_D = 200mA$	100	120		mmhos
	Capacitances	(See capacitance model) $V_{DS} = +10V$, $V_{GS} = V_{BS} = -15V$, $I_D = 0A$, f = 1 MHz				
$C_{(GS+GD+GB)}$	Gate node			25	30	pF
$C_{(GD+DB)}$	Drain node			13	15	pF
$C_{(GS+SB)}$	Source node			35	40	pF
C_{DG}	Reverse transfer			3	5	pF
t_{ON}	Turn ON time	See switching		2	4	ns
t_{OFF}	Turn OFF time	time test circuit		3	5	ns

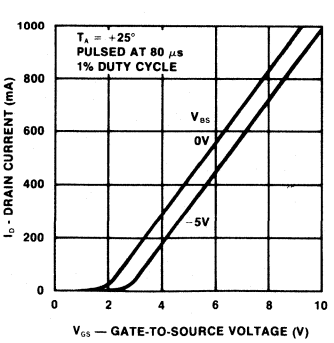
NOTES
5. Pulsed @ 80μs, 1% duty cycle.

TYPICAL PERFORMANCE CHARACTERISTICS

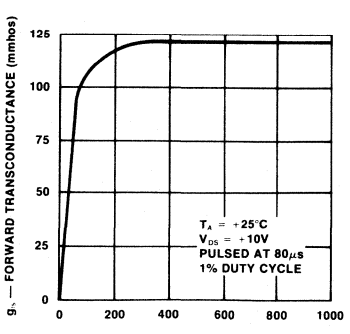
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE

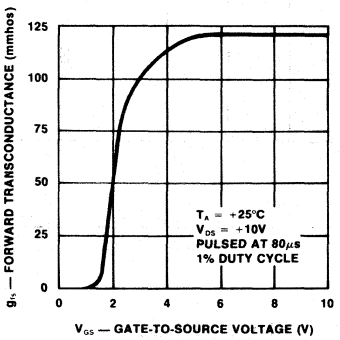


FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT

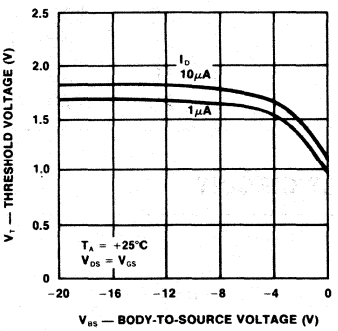


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

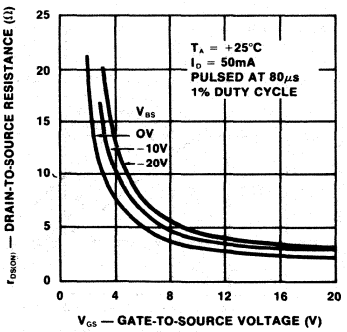
FORWARD TRANSCONDUCTANCE vs GATE-TO-SOURCE VOLTAGE



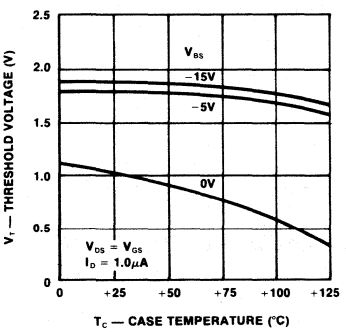
THRESHOLD VOLTAGE vs BODY-TO-SOURCE VOLTAGE



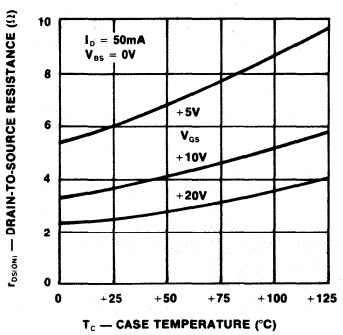
DRAIN-TO-SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



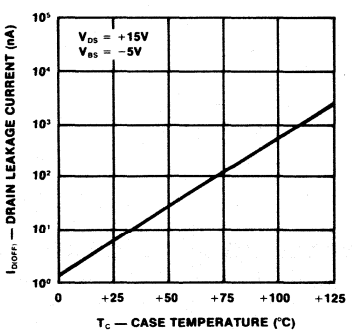
THRESHOLD VOLTAGE vs CASE TEMPERATURE



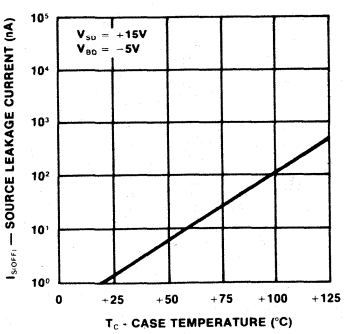
DRAIN-TO-SOURCE RESISTANCE vs CASE TEMPERATURE



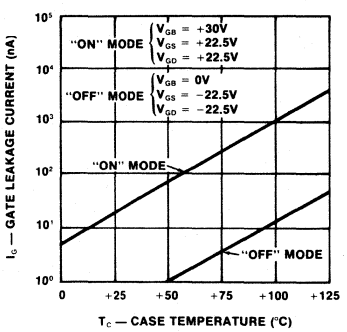
DRAIN LEAKAGE CURRENT vs CASE TEMPERATURE



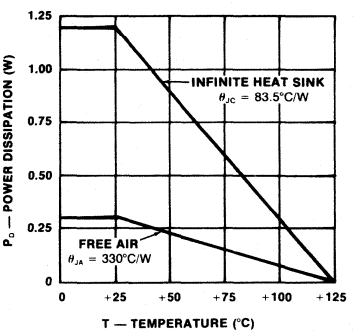
SOURCE LEAKAGE CURRENT vs CASE TEMPERATURE



GATE LEAKAGE CURRENT vs CASE TEMPERATURE



POWER DISSIPATION vs TEMPERATURE



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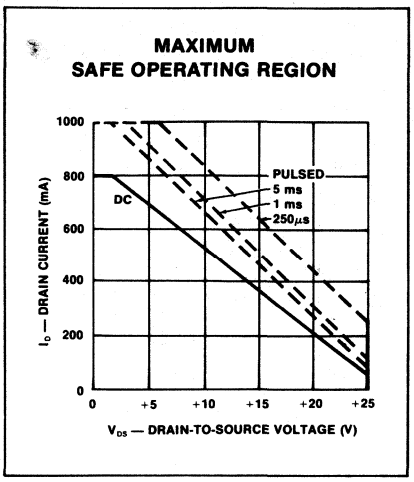
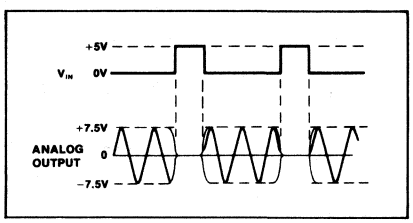
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)



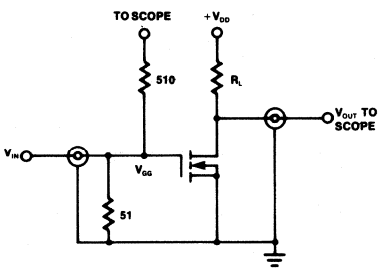
TYPICAL WAVEFORMS



SWITCHING CHARACTERISTICS

V_{GG}(V)	V_{DD}(V)	R_L(Ω)	$t_{d(ON)}$(ns) Typ	t_r(ns) Typ	t_{OFF}(ns) Typ
5	5	100	<1	1	3
	10	200	<1	1	3
	20	390	<1	1	3
10	5	67	<1	1	3
	10	133	<1	1	3
	20	270	<1	1	3

TEST CIRCUIT

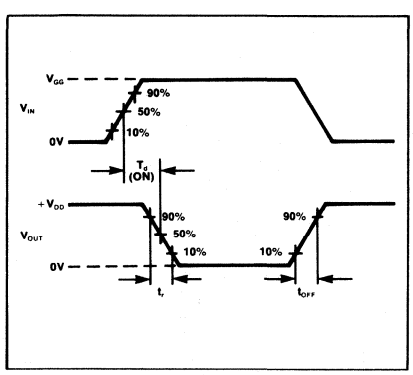


NOTE
All resistors standard and are measured in ohms.

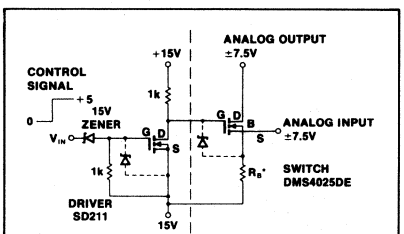
INPUT PULSE
t_d, t_r <1ns
PULSE WIDTH = 10ns
REP RATE = 1MHz

SAMPLING SCOPE
t_r <360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

SWITCHING WAVEFORMS



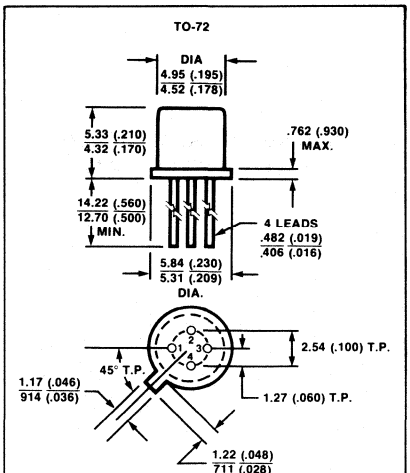
D-MOS DRIVER/SWITCH APPLICATION



R_B* OPTIONAL CURRENT LIMITING RESISTOR

NOTE
All resistors standard and are measured in ohms.

PACKAGE INFORMATION



NOTES
1. Lead Material: Kover or equivalent—gold plated.
2. Body Material: Eyelet, Kover or equivalent—gold plated, glass body
3. Lid Material: Nickel, weld seal
4. All dimensions shown in parenthesis are English (inches)

PRELIMINARY SPECIFICATION

DESCRIPTION

The Signetics SD220 is a POWER MOSFET of the N-channel enhancement mode type designed for switching and amplifier applications requiring high voltage, high current, high speed, and exceptional linear transfer characteristics. Superior performance is achieved by utilizing the Signetics D-MOS process which provides high gain, low inter-electrode capacitances, low drain-to-source "ON" resistance, and enhanced high frequency operation.

The device is hermetically sealed in a TO-39 package. The source, substrate, and case are internally connected.

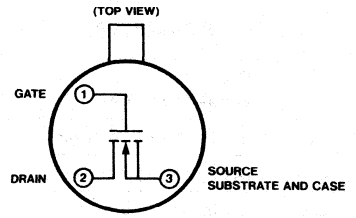
FEATURES

- **Low "ON" resistance: $<10\Omega$ @ 500mA**
- **High current: 500mA dc**
- **High voltage: $V_{DS} > +60V$**
- **Low input drive power**
- **Low inter-electrode capacitances**
- **Linear transfer characteristics**
- **No secondary breakdown**
- **Withstands high VSWR**

APPLICATIONS

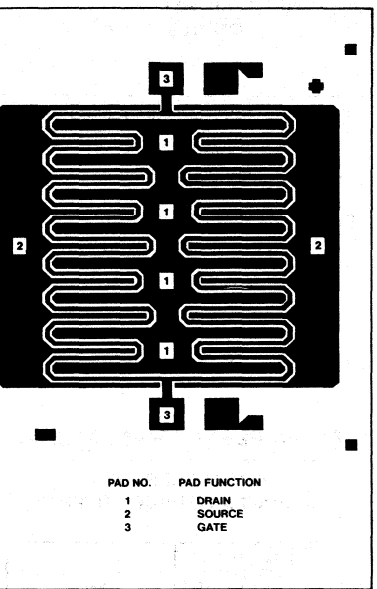
- **Power amplification**
- **Power driver**
- **High speed switching**
- **Switching power supplies**

PIN CONFIGURATION



ORDER PART NO.
SD220H

CHIP DIAGRAM



ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified.

PARAMETER		RATING	UNIT
V_{DS}	Drain-to-source	+60	V
V_{GS}	Gate-to-source	±20	V
V_{DG}	Drain-to-gate	+60 −20	V
$I_D(ON)$	"ON" drain current		
	Continuous	500	mA
	Pulsed (80μs, 1% duty cycle)	800	mA
P_D	Power dissipation		
	T_A = +25°C[2]	1	W
	T_C = +25°C[3]	6.25	W
	Power derating factors		
	Free air	8	mW/°C
	Infinite heat sink	50	mW/°C
Θ_{JA}	Thermal resistance	125	°C/W
Θ_{JC}	Thermal resistance	20	°C/W
T_{op}	Operating temperature	−55 to +125	°C
T_{STG}	Storage temperature	−55 to +150	°C

NOTES
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Free air.
3. Infinite heat sink.

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PRELIMINARY SPECIFICATION

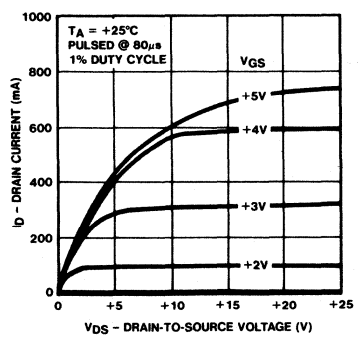
ELECTRICAL CHARACTERISTICS T_A = +25°C

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
BV_{DS}	Drain-source Breakdown voltage	$V_{GS} = V_{SB} = 0$, $I_D = 1\mu A$	60	100		V
I_{GSS}	Gate leakage current	$V_{GSS} = \pm 20V$			1.0	nA
$I_D(OFF)$	Drain leakage current	$V_{DS} = +60V$, $V_{GS} = 0$		0.1	1.0	μA
$I_D(ON)$	Drain "ON" current	$V_{DS} = +6V$, $V_{GS} = +10V$	500			mA
$I_D(ON)$	Drain "ON" current[4]	$V_{DS} = +10V$, $V_{GS} = +10V$	600	700		mA
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_D = 10\mu A$ $V_{DS} = V_{GS} = V_T$, $I_D = 1mA$	0.1 0.5	0.8 1.5	2.3 3.0	V V
$r_{DS}(ON)$	Drain-source "ON" resistance[4]	$V_{GS} = +5V$, $I_D = 50mA$ $V_{GS} = +10V$, $I_D = 50mA$ $V_{GS} = +10V$, $I_D = 500mA$		7.5 6.5 9	10 9 12	Ω Ω Ω
g_{fs}	Forward transconductance[4]	$V_{DS} = +30V$, $I_D = 300mA$	220	250		mmhos
	Capacitances	$V_{DS} = +30V$, $I_D = 0$, f = 1MHz				
C_{iss}	Input			12	15	pF
C_{oss}	Output			2.8	3.5	pF
C_{rss}	Reverse transfer			0.6	1.0	pF
$t_d(ON)$	Turn-ON Delay Time	See switching		1	2	ns
t_r	Rise Time	Time test		1	3	ns
t_f	Fall Time	Circuit		3	5	ns

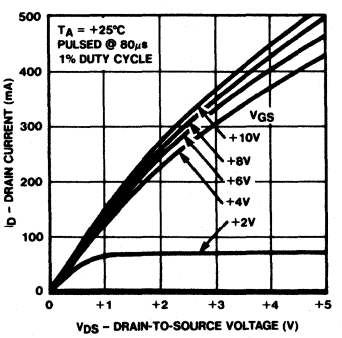
NOTE
4. Pulsed @ 80μs, 1% duty cycle.

TYPICAL PERFORMANCE CHARACTERISTICS

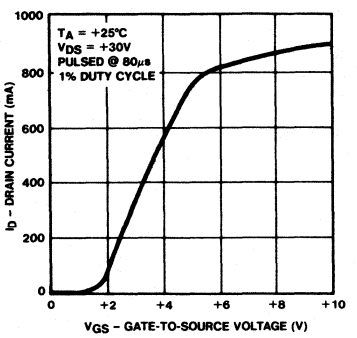
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



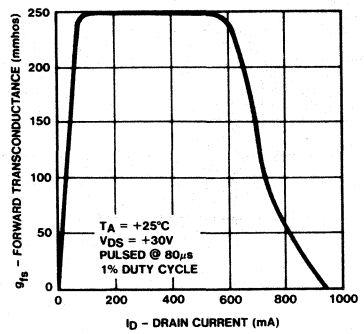
DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



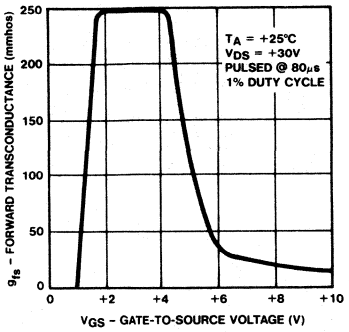
PRELIMINARY SPECIFICATION

TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

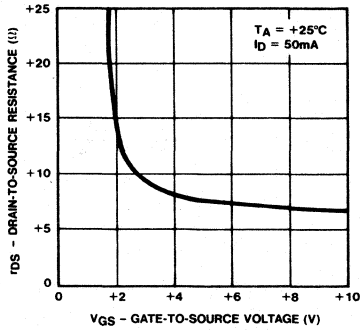
FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



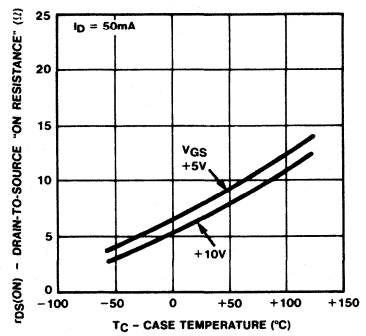
FORWARD TRANSCONDUCTANCE vs GATE-TO-SOURCE VOLTAGE



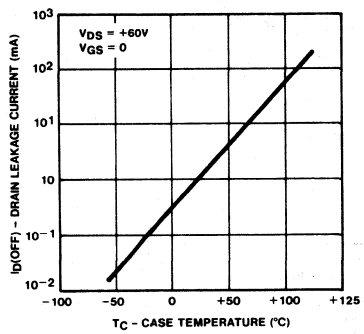
DRAIN-TO-SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



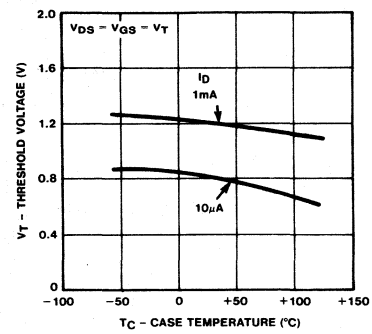
DRAIN-TO-SOURCE "ON RESISTANCE" vs CASE TEMPERATURE



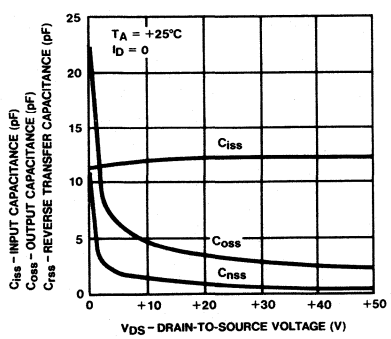
DRAIN LEAKAGE CURRENT vs CASE TEMPERATURE



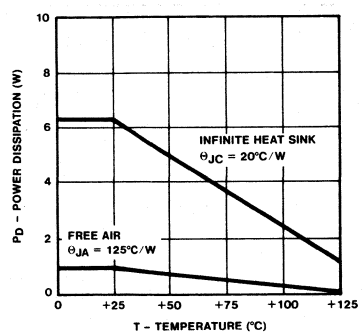
THRESHOLD VOLTAGE vs CASE TEMPERATURE



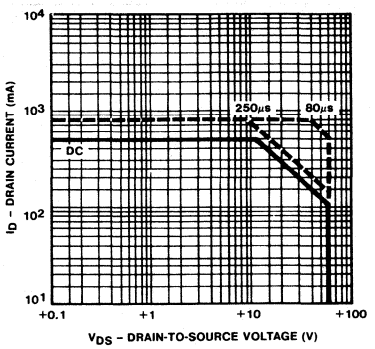
CAPACITANCES vs DRAIN-TO-SOURCE VOLTAGE



POWER DISSIPATION vs TEMPERATURE



MAXIMUM SAFE OPERATING REGION



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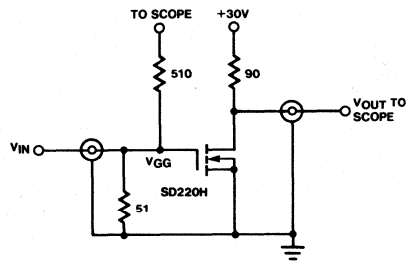
PRELIMINARY SPECIFICATION

SWITCHING SPEED

TEST CIRCUIT

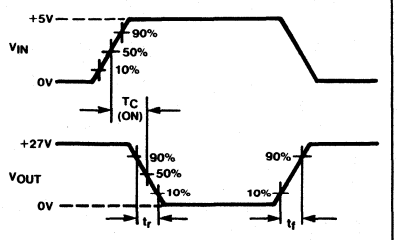


INPUT PULSE
t_d, t_r < 1ns
PULSE WIDTH = 10ns
REP RATE = 1MHz

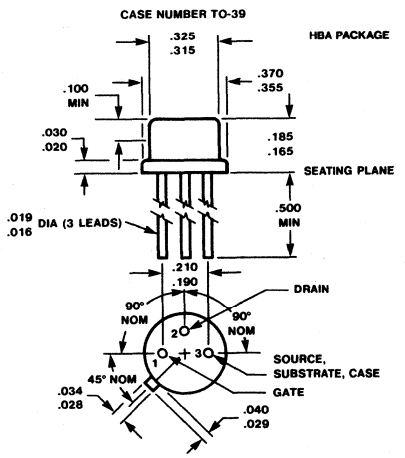
SAMPLING SCOPE
t_r < 360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

NOTE
All resistors standard and are measured in ohms.

WAVEFORM



PACKAGE OUTLINE



PRELIMINARY SPECIFICATION

DESCRIPTION

The Signetics SD222 is a POWER MOSFET of the N-channel enhancement mode type designed for switching applications requiring high voltage, high current, low "ON" resistance and high node-to-node isolation. Superior performance is achieved by utilizing the Signetics D-MOS process which provides high gain, low inter-electrode capacitances, low drain-to-source "ON" resistance and enhanced high frequency operation.

The device is hermetically sealed in a 4-lead TO-72 package.

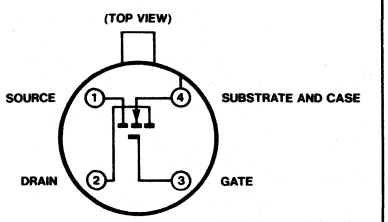
FEATURES

- **Low node capacitances**
- **Low feedthrough and feedback transients**
- **Excellent input and output isolations**
- **Extremely low input drive power**
- **High voltage: $V_{DS} > +60V$**

APPLICATIONS

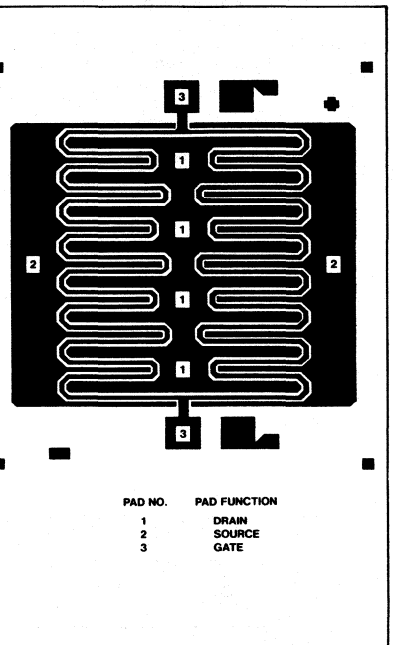
- **Power driver**
- **High speed switching**
- **Analog switching**
- **Multiplexers**
- **Sample and hold**

PIN CONFIGURATION



ORDER PART NO.
SD222DC

CHIP DIAGRAM



ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified.

PARAMETER		RATING	UNIT
V_{DS}	Drain-to-source	+60	V
V_{DB}	Drain-to-body	+60	V
V_{DG}	Drain-to-gate	+60 −20	V
V_{GS}	Gate-to-source	±20	V
V_{GB}	Gate-to-body	±20	V
V_{SB}	Source-to-body	+10	V
$I_{D(ON)}$	"ON" Drain current		
	Continuous	350	mA
	Pulsed (80μs, 1% duty cycle)	800	mA
P_D	Power dissipation		
	T_A = +25°C[2]	300	mW
	T_C = 25°C[3]	1.2	W
	Power derating factors		
	Free air	2.4	mW/°C
	Infinite heat sink	9.6	mW/°C
Θ_{JA}	Thermal resistance	417	°C/W
Θ_{JC}	Thermal resistance	104	°C/W
T_{op}	Operating temperature	−55 to +125	°C
T_{STG}	Storage temperature	−55 to +150	°C

NOTES
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Free air.
3. Infinite heat sink.

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PRELIMINARY SPECIFICATION

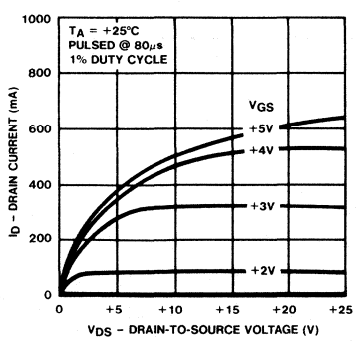
ELECTRICAL CHARACTERISTICS T_A = +25°C

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
BV_{DS}	Drain-source breakdown voltage	V_{GS} = V_{SB} = 0, I_D = 1μA	+60	+100		V
BV_{SB}	Source-Body breakdown voltage	V_{GB} = 0, Drain Open, I_S = 1μA	10			V
I_{GSS}	Gate leakage current	V_{GSS} = ±20V			1.0	nA
I_D (OFF)	Drain leakage current	V_{DS} = +60V, V_{GS} = V_{SB} = 0		0.1	1	μA
I_D (ON)	Drain "ON" current	V_{DS} = +3.5V, V_{SB} = 0, V_{GS} = +10V	275			mA
I_D (ON)	Drain "ON" current[4]	V_{DS} = +6.5V, V_{SB} = 0, V_{GS} = +10V	500	720		mA
V_T	Threshold voltage	V_{DS} = V_{GS} = V_T, V_{SB} = 0, I_D = 10μA V_{DS} = V_{GS} = V_T, V_{SB} = 0, I_D = 1mA	0.1 0.5	0.8 1.5	2.3 3.0	V V
r_{DS} (ON)	Drain-source "ON" resistance[4]	V_{GS} = +5V, V_{SB} = 0, I_D = 50mA V_{GS} = +10V, V_{SB} = 0, I_D = 50mA V_{GS} = +10V, V_{SB} = 0, I_D = 500mA		7.5 6.5 9	10 9 13	Ω Ω Ω
g_{fs}	Forward transconductance[4]	V_{DS} = +30V, V_{SB} = 0, I_D = 300mA	220	250		mmhos
	Capacitances	V_{DSS} = +30V, I_D = 0, f = 1MHz				
C_{iss}	Input			12	15	pF
C_{oss}	Output			2.8	3.5	pF
C_{rss}	Reverse transfer			0.6	1.0	pF
t_d (ON)	Turn-ON delay time	See switching		1	2	ns
t_r	Rise time	Time test		1	3	ns
t_f	Fall time	Circuit		3	5	ns

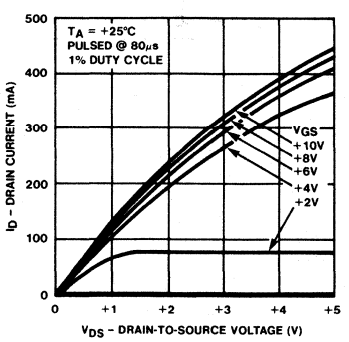
NOTE
4. Pulsed @ 80μs, 1% duty cycle.

TYPICAL PERFORMANCE CHARACTERISTICS

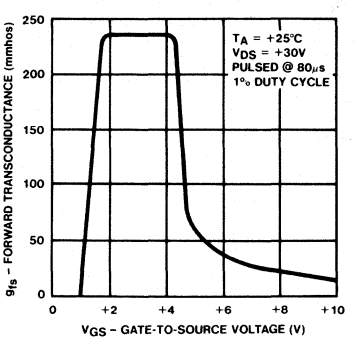
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



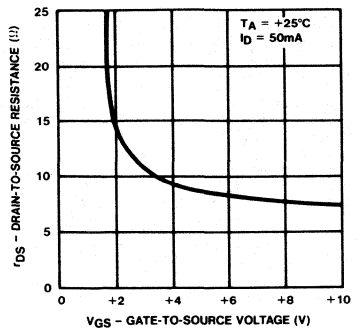
FORWARD TRANSCONDUCTANCE vs GATE-TO-SOURCE VOLTAGE



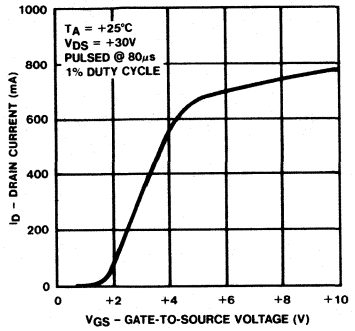
PRELIMINARY SPECIFICATION

TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

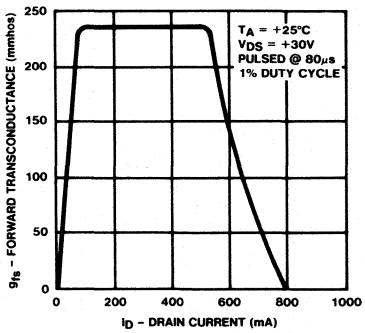
DRAIN TO SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



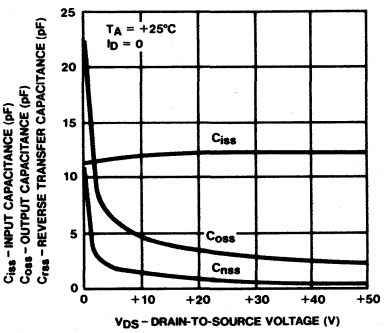
DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE



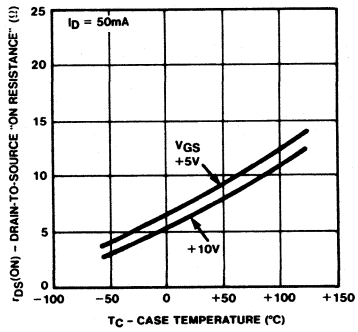
FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



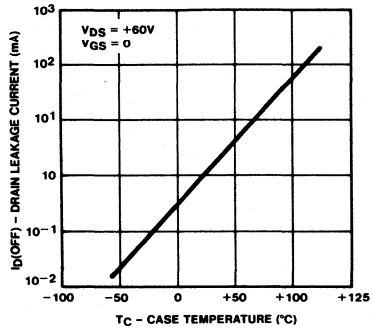
CAPACITANCES vs DRAIN-TO-SOURCE VOLTAGE



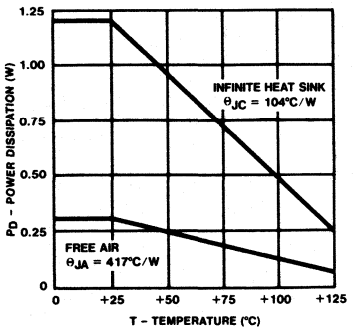
DRAIN-TO-SOURCE "ON" RESISTANCE vs CASE TEMPERATURE



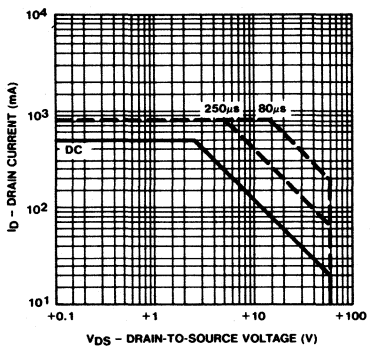
DRAIN LEAKAGE CURRENT vs CASE TEMPERATURE



POWER DISSIPATION vs TEMPERATURE



MAXIMUM SAFE OPERATING REGION



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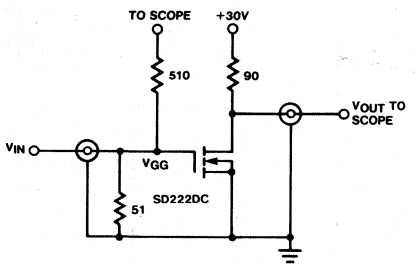
PRELIMINARY SPECIFICATION

SWITCHING SPEED

TEST CIRCUIT

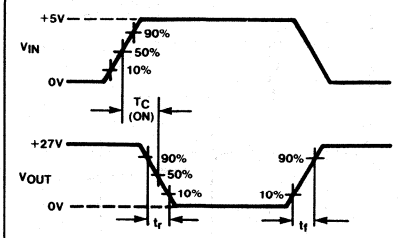


INPUT PULSE
t_d, t_r < 1ns
PULSE WIDTH = 10ns
REP RATE = 1MHz

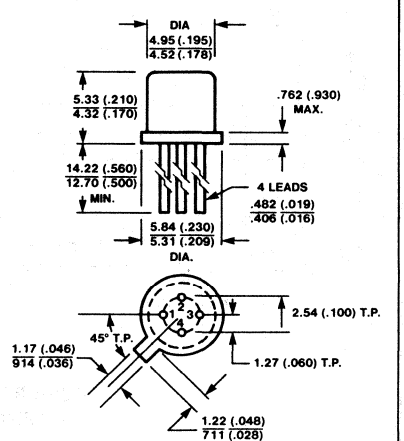
SAMPLING SCOPE
t_r < 360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

NOTE
All resistors standard and are measured in ohms

WAVEFORM



PACKAGE INFORMATION



NOTES
1. Lead Material: Kover or equivalent—gold plated.
2. Body Material: Eyelet, Kover or equivalent—gold plated.
3. Lid Material: Nickel, weld seal.
4. All dimensions shown in parenthesis are English (inches).

PRELIMINARY SPECIFICATION SD226H

DESCRIPTION

The Signetics SD226 is a POWER MOSFET of the N-channel enhancement mode type designed for switching and amplifier applications requiring high current, high speed, and exceptionally linear transfer characteristics. Superior performance is achieved by utilizing the Signetics D-MOS process which provides high gain, low drain-to-source "ON" resistance, low inter-electrode capacitances, and enhanced high frequency operation.

The device is hermetically sealed in a TO-39 package. The source, substrate, and case are internally connected.

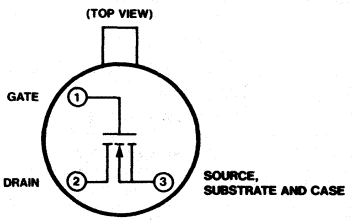
FEATURES

- **Low "ON" resistance: 1Ω @ 1A**
- **High current: 2A dc, 3A pulsed**
- **Withstands high VSWR**
- **No secondary breakdown**
- **Low drive power**
- **Low inter-electrode capacitances**
- **Linear transfer characteristics**

APPLICATIONS

- **Power amplification**
- **Power driver**
- **High speed switching**
- **Motor controls**
- **Switching power supplies**
- **Analog switching**

PIN CONFIGURATION



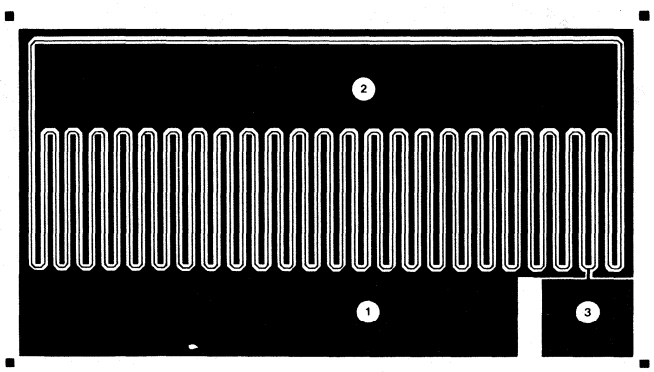
ORDER PART NO.
SD226H

ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified

	PARAMETER	RATING	UNIT
V_{DS}	Drain-to-source	+30	V
V_{GS}	Gate-to-source	±20	V
V_{GD}	Gate-to-drain	+20 −30	V
$I_D(ON)$	Continuous drain current	2	A
$I_D(ON)$	Pulsed drain current	3	A
P_D	Power dissipation		
	T_A = 25°C[2]	1	W
	T_C = 25°C[3]	6.25	W
	Power derating factors		
	Free Air	8	mW/°C
	Infinite Heat Sink	50	mW/°C
Θ_{JA}	Thermal Resistance[2]	125	°C/W
Θ_{JC}	Thermal Resistance[3]	20	°C/W
T_{op}	Operating Temperature	−55 to +125	°C
T_{STG}	Storage Temperature	−55 to +150	°C

NOTES
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. Free air.
3. Infinite heat sink.

CHIP DIAGRAM



PAD NO.	PAD FUNCTION
1	SOURCE
2	DRAIN
3	GATE

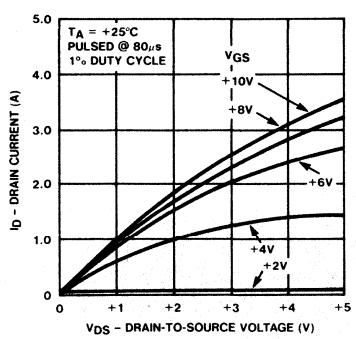
ELECTRICAL CHARACTERISTICS $T_A = +25°C$

PARAMETER		TEST CONDITIONS	LIMITS Min	LIMITS Typ	LIMITS Max	UNIT
BV_{DS}	Drain-source breakdown voltage	$V_{GS} = V_{SB} = 0$, $I_D = 1\mu A$	+30	+35		V
I_{GSS}	Gate leakage current	$V_{GSS} = \pm 20V$			1.0	nA
$I_{D(OFF)}$	Drain leakage current	$V_{DS} = +30V$, $V_{GS} = 0$		0.1	1	μA
$I_{D(ON)}$	Drain "ON" current	$V_{DS} = +2.2V$, $V_{GS} = +10V$	1.4	2.0		A
$I_{D(ON)}$	Drain "ON" current[4]	$V_{DS} = +3.3V$, $V_{GS} = +10V$	2.2	3.0		A
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_D = 10\mu A$	0.1	1.0	2.3	V
		$V_{DS} = V_{GS} = V_T$, $I_D = 1mA$	0.5	1.5	3.0	V
$r_{DS(ON)}$	Drain-source "ON" resistance[4]	$V_{GS} = +5V$, $I_D = 50mA$		1.4	2.0	Ω
		$V_{GS} = +10V$, $I_D = 50mA$		1.1	1.5	Ω
		$V_{GS} = +10V$, $I_D = 3A$		1.1	1.5	Ω
g_{fs}	Forward transconductance[4]	$V_{DS} = +15V$, $I_D = 2A$	700	750		mmhos
	Capacitances	$V_{DS} = +15V$, $I_D = 0$, f = 1MHz				
C_{iss}	Input			35	45	pF
C_{oss}	Output			20	25	pF
C_{rss}	Reverse transfer			5	6	pF
$t_{d(ON)}$	Turn-ON delay time	See Switching		1	2	ns
t_r	Rise time	Time Test		1	3	ns
t_f	Fall time	Circuit		3	5	ns

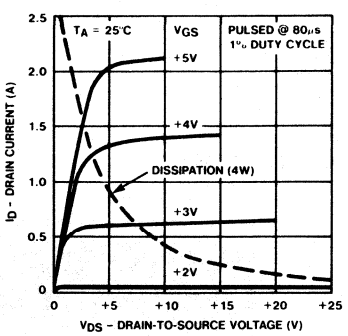
NOTE
4. Pulsed @ 80μs, 1% duty cycle.

TYPICAL PERFORMANCE CHARACTERISTICS

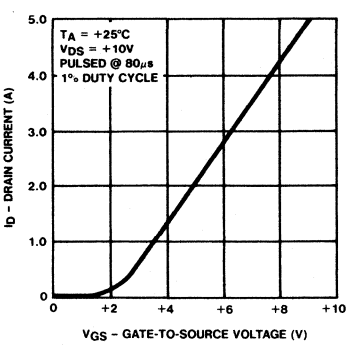
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE

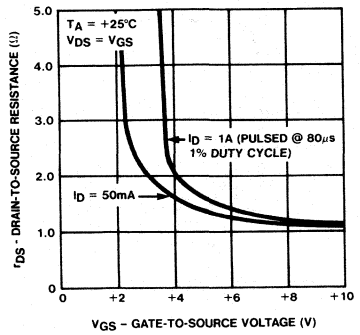


DRAIN CURRENT vs GATE-TO-SOURCE VOLTAGE

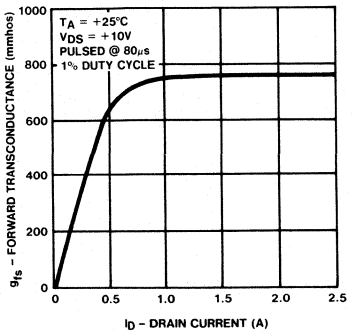


TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

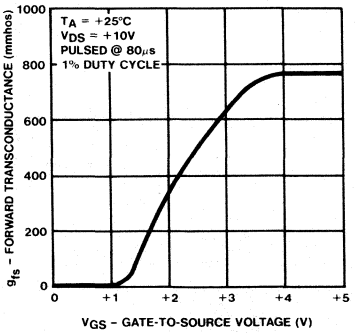
DRAIN-TO-SOURCE RESISTANCE vs GATE-TO-SOURCE VOLTAGE



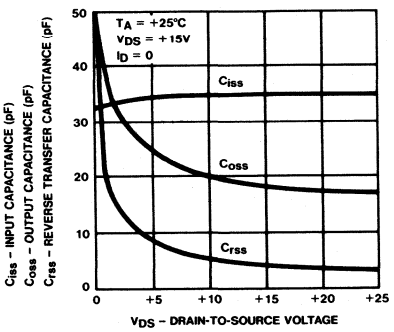
FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



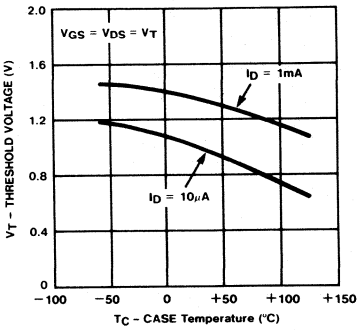
FORWARD TRANSCONDUCTANCE vs GATE-TO-SOURCE VOLTAGE



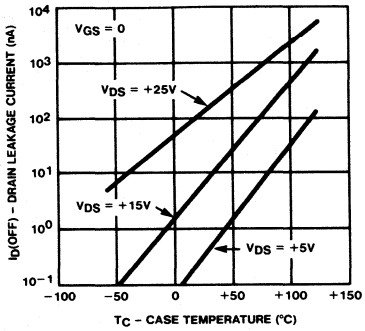
CAPACITANCES vs DRAIN-TO-SOURCE VOLTAGE



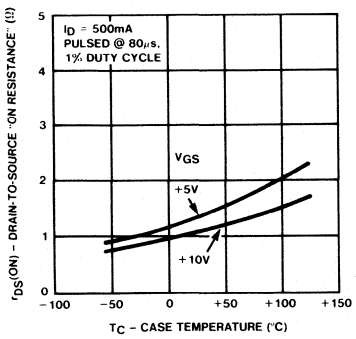
THRESHOLD VOLTAGE vs CASE TEMPERATURE



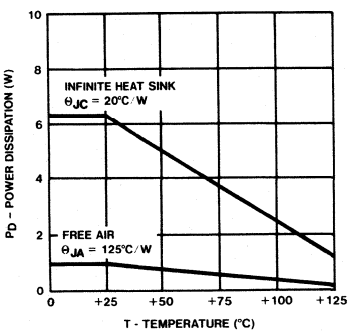
DRAIN LEAKAGE CURRENT vs CASE TEMPERATURE



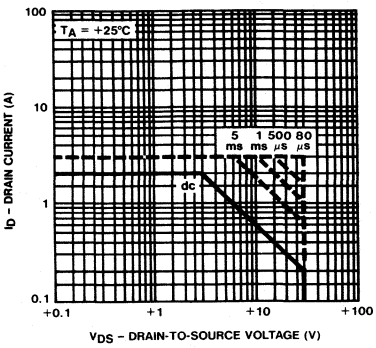
DRAIN-TO-SOURCE "ON RESISTANCE" vs CASE TEMPERATURE



POWER DISSIPATION vs TEMPERATURE



MAXIMUM SAFE OPERATING REGION



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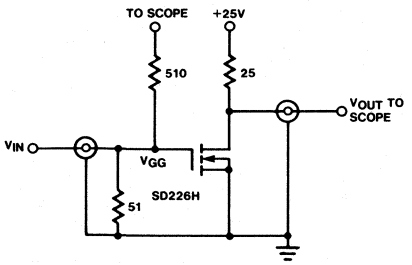
PRELIMINARY SPECIFICATION

SWITCHING SPEED

TEST CIRCUIT

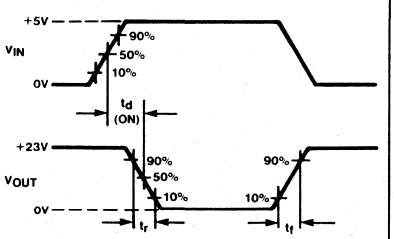


INPUT PULSE
t_d, t_r < 1ns
PULSE WIDTH = 10ns
REP RATE = 1MHz

SAMPLING SCOPE
t_r < 360ps
R_{IN} = 1MΩ
C_{IN} = 2.0pF

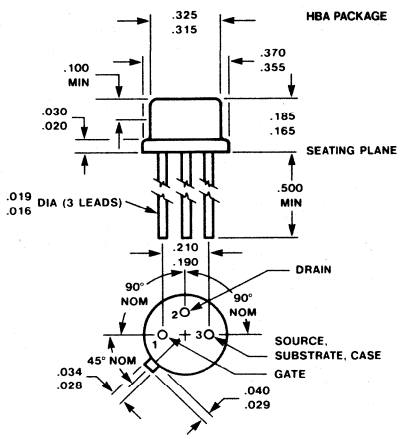
NOTE
All resistors standard and are measured in ohms.

WAVEFORM



PACKAGE OUTLINE

CASE NUMBER TO-39



SD303-DC

DESCRIPTION

The Signetics D-MOS SD303 is a silicon, dual-insulated-gate, field effect transistor of the N-channel enhancement mode type. It is fabricated by the Signetics double-diffused process which gives superior high frequency performance. Zener diodes are connected between the two gates and the substrate. These diodes bypass any voltage transients which lie outside the range of -0.3V to +25.0V. Thus, the gates are protected against damage in all normal handling and operating situations.

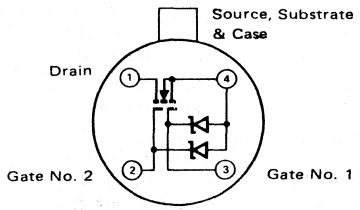
The device characteristics make it ideally suited for a variety of high frequency amplifier and mixer applications. The presence of two gates plus the incorporation of the drift region in the structure has made the feedback capacity (Crss) less than 0.02pF. A wide AGC capability plus a significant reduction in cross-modulation distortion is now available because of the inherent linearity of these devices. The SD303 is hermetically sealed in a modified 4-lead TO-72 package.

GENERAL FEATURES

- **Lower cross-modulation and wider dynamic range than bipolar or single gate FETs**
- **Reverse AGC capability**
- **Linear mixing capability**
- **Diode protected gates**
- **High forward transconductance: 10mmhos**
- **ION-implanted**
- **Positive bias only**

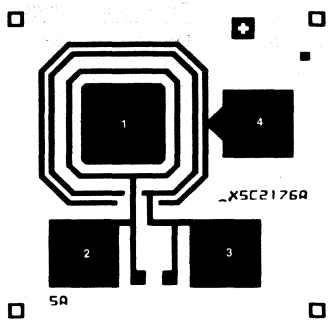
PIN CONFIGURATIONS (Top View)

DC, DE PACKAGE



ORDER PART NO.
SD303DC

CHIP DIAGRAM



PAD NO.	PAD FUNCTION
1	DRAIN
2	GATE NO. 2
3	GATE NO. 1
4	SOURCE

Die Size 20X20

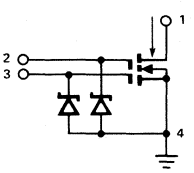
FEATURES

PARAMETER	SD303	UNIT
High gain through UHF range	14	dB at 1GHz
High gain through VHF range		dB at 500MHz
Low noise through UHF range	5.5	dB at 1GHz
Low noise through VHF range		dB at 500MHz
Low input capacitance	3.0	pF
Low feedback capacitance	0.02	pF
Low outut capacitance	0.6	pF

ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise specified.

	PARAMETER	RATING	UNIT
V_{DS}	Drain-to-source		
	SD303	+20	V
V_{G1B}	DC gate no. 1-to-substrate voltage	-0.3, +10	V
V_{G2B}	DC gate no. 2-to-substrate voltage	-0.3, +15	V
I_D	Drain current	50	mA
T_A	Ambient temperature range		
	Storage	-65 to +175	°C
	Operating	-55 to +125	°C
P_T	Transistor dissipation		
	At +25°C case temperature (Derate linearly to +125°C case temperature at the rate of 8.0mW/°C.)	1.2	W
	At +25°C free-air temperature (Derate linearly to +125°C free-air temperature at the rate of 2.0mW/°C.)	300	mW

DUAL GATE CASCODE BIAS SCHEME



$+V_{DS}$ = 0 → +20 volts
$+V_{G1S}$ = 0 → +4 volts
$+V_{G2S}$ = 0 → +10 volts
$+I_{DS}$ = 0 → +20mA

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DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD303			UNIT
			Min	Typ	Max	
BV_{DS}	Drain-to-source Breakdown voltage	$V_{G1S} = V_{G2S} = 0V$, $I_D = 5\mu A$	20	25		V
I_{G1SS}	Gate 1 Leakage current	$V_{G1S} = +5V$, $V_{G2S} = V_{DS} = 0V$		0.001	0.1	μA
I_{G2SS}	Gate 2 Leakage current	$V_{G2S} = +10V$ $V_{G1S} = V_{DS} = 0V$		0.001	0.1	μA
$I_{D(OFF)}$	Drain-to-source Leakage current	$V_{DS} = +15V$, $V_{G1S} = V_{G2S} = 0V$		0.001	0.1	μA
I_{DSS}	Zero bias Drain current	$V_{DS} = +15V$ $V_{G1S} = V_{G2S} = 0V$		0.001	0.1	μA
V_{T1}	Gate 1 Threshold voltage	$V_{DS} = V_{G1S} = V_{T1}$ $V_{G2S} = +10V$, $I_D = 1\mu A$	0.1	0.5	1.5	V
V_{T2}	Gate 2 Threshold voltage	$V_{DS} = V_{G2S} = V_{T2}$, $V_{G1S} = +4V$, $I_D = 1\mu A$	0.1	0.5	1.5	V
$r_{DS}(ON)$	Drain-to-source On resistance	$V_{G1S} = +5V$, $V_{G2S} = +10V$, $I_D = 1.0mA$		65	80	Ω

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

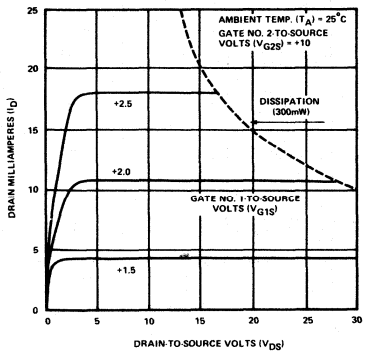
PARAMETER		TEST CONDITIONS	SD303			UNIT
			Min	Typ	Max	
	Small signal short circuit Capacitances	f = 1MHz, Gate 2 AC grounded				
C_{iss}	Input	V_{DS} = +15V, V_{G1S} ≅ 3.5V, V_{G2S} = +10V, I_D = 18mA				pF
		V_{DS} = +15V, V_{G1S} ≅ +2.5V, V_{G2S} = +10V, I_D = 18mA		3.0	3.5	pF
C_{oss}	Output	V_{DS} = +15V, V_{G1S} = 0V V_{G2S} = +10V		0.6		pF
C_{rss}	Reverse transfer	V_{DS} = +15V V_{G1S} = 0V, V_{G2S} = +10V		0.02		pF
gfs	Forward transconductance	V_{DS} = +15V, V_{G1S} ≅ +3.5V V_{G2S} = +10V, I_D = 18mA, f = 1kHz				mmhos
		V_{DS} = +15V, V_{G1S} ≅ +2.5V, V_{G2S} = +10V, I_D = 18mA	13.0	15.0		mmhos
Gps	Power gain	V_{DS} = +15V, V_{G1S} ≅ +3.5V, V_{G2S} = +10V, I_D = 18mA				
		f = 1GHz				dB
		f = 500MHz				dB
		f = 200MHz				dB
		V_{DS} = +15V, V_{G1S} ≅ +2.5V, V_{G2S} = +10V, I_D = 18mA f = 1GHz	10.0	14.0*		dB
E_{int}	Noise figure	V_{DS} = +15V, V_{G1S} ≅ +3.5V, V_{G2S} = +10V, I_D = 18mA				
		f = 1GHz				dB
		f = 500MHz				dB
		f = 200MHz				
		V_{DS} = +15V, V_{G1S} ≅ +2.5V, V_{G2S} = +10V, I_D = 18mA, f = 1GHz		5.5*	7.0	dB
NF	Interfering signal level at gate for 1% cross-modulation distortion. Peak voltage referenced to 300Ω system.	V_{DS} = +15V, V_{G2S} = +10V, I_D = 18mA, Desired signal f = 500MHz, Undersired signal f = 501MHz				mV
		V_{DS} = +15V, V_{G2S} = +10V, I_D = 18mA, Wanted Signal f = 1GHz, Interfering signal f = 0.995GHz		150		mV
AGC (V_{G2S})	Range of automatic Gain control	V_{DS} = +15V, V_{G1S} ≅ +3.5V, f = 500MHz				dB
		V_{DS} = +15V, V_{G1S} ≅ +2.5V, f = 500MHz		40		dB

*NOTE

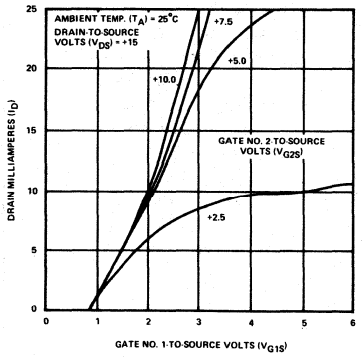
Measured in amplifier test fixture.

SD303 TYPICAL PERFORMANCE CHARACTERISTICS

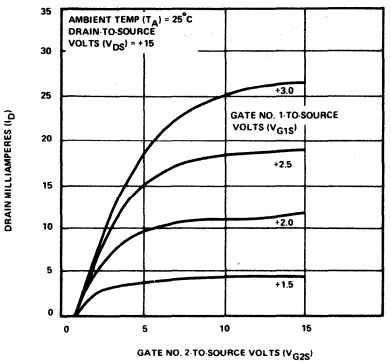
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



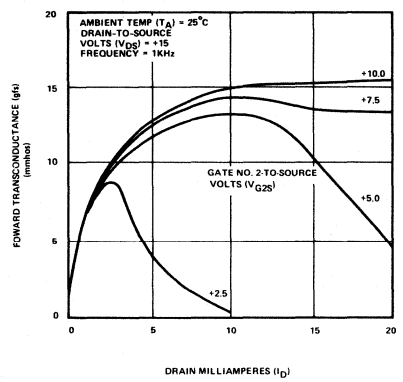
DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



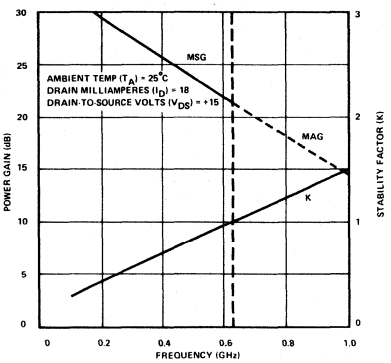
DRAIN CURRENT vs GATE NO. 2-TO-SOURCE VOLTAGE



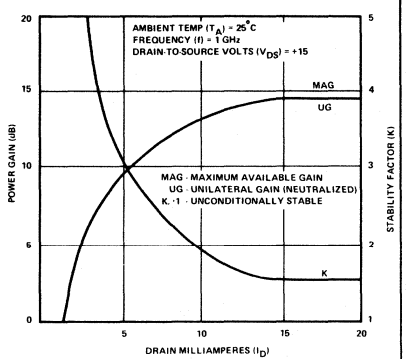
1kHz FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



POWER GAIN vs FREQUENCY

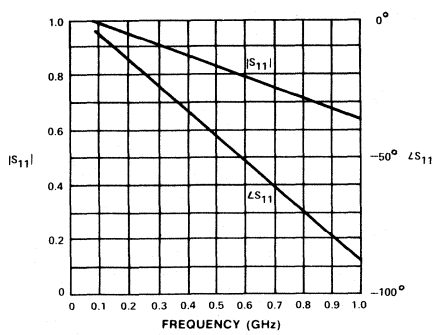


POWER GAIN vs DRAIN CURRENT

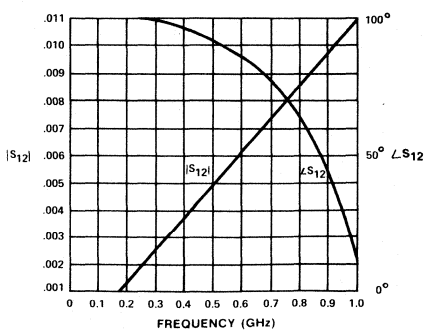


SD303 "S" PARAMETERS

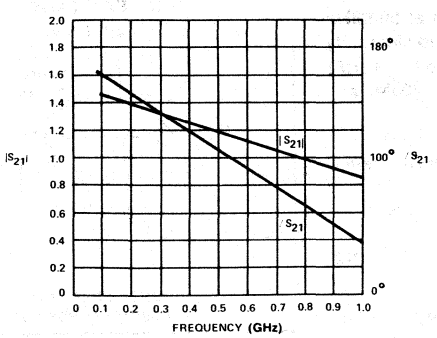
AMBIENT TEMP. (T_A) = +25°C
DRAIN MILLIAMPERES (I_D) = 18

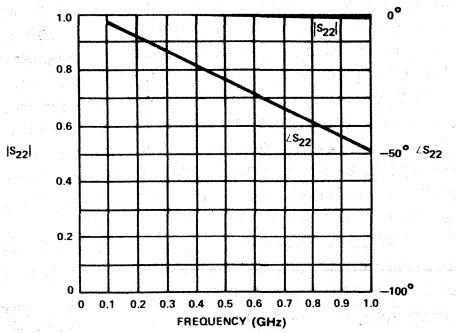


DRAIN-TO-SOURCE VOLTS (V_{DS}) = +15
GATE NO. 1-TO-SOURCE VOLTS (V_{G1S}) ≃ +2.5
GATE NO. 2-TO-SOURCE VOLTS (V_{G2S}) = +10

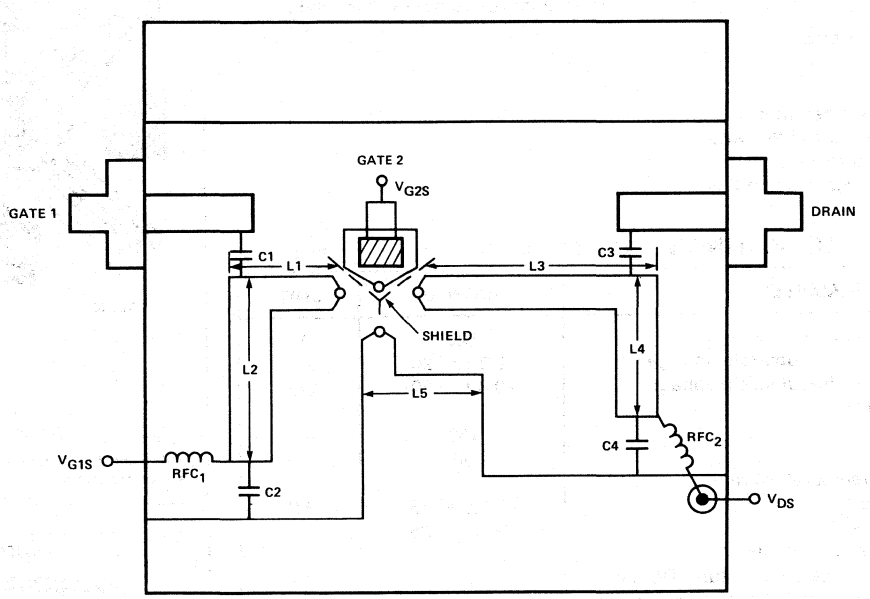


SD303 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)





1GHz TEST FIXTURE



Dielectric is 1/16" Teflon-Fiberglass (3M-K6098-11).
All microstrip width = 0.175 inch.

L_1 = 0.42 inch	C_1 = 0.8-10pF Johanson 5201
L_2 = 1.68 inches	C_2 = C_4 1.20pF Johanson 5501
L_3 = 0.64 inch	C_3 = 0.4-6.0pF Johanson 4642
L_4 = 1.52 inches	RFC_1 = 0.22μH
L_5 = 0.30 inch	RFC_2 = 18μH

NOTE Shield and all passive components on ground plane side of amplifier.
1000pF bypasses are:
Drain: Cory FT4-01-2
Gate 2: American technical Ceramics ATC100B (Chip capacitor)
Launchers are OSM248-2

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DESCRIPTION

The Signetics D-MOS SD305 and 306 are silicon, dual-insulated gate, field-effect transistors of the N-channel enhancement mode type. Zener diodes are connected between the two gates and the substrate. These diodes bypass any voltage transients which lie outside the range of -0.3V to +20.0V. Thus, the gates are protected against damage in all normal handling and operating situations. The characteristics of the devices make them ideally suited for a variety of VHF amplifier and mixer applications. The presence of two gates plus the incorporation of the drift region in the structure has made the feedback capacity (C_{G1D}) typically less than 0.03pF. A wide AGC capability plus significant reduction in cross modulation distortion is now available because of the inherent linearity of the devices. The SD305 and SD306 are hermetically sealed in a 4-lead TO-72 package.

GENERAL FEATURES

- **Positive bias only**
- **Low gate voltages**
- **Enhancement mode operation**
- **Wide AGC range: -50dB at 200MHz**
- **Zener diode gate protection**
- **ION implanted for greater reliability**

FEATURES—SD305 (VHF TV and FM Mixer)

- **High conversion gain: 17dB at 200MHz with $V_{G1S} = V_{G2S}$ for biasing simplicity**
- **Excellent isolation from Gate No. 1 (RF) to Gate No. 2 (LO): -20dB at 200MHz**
- **Low input capacitance: 4.0pF**
- **Low feedback capacitance: 0.03pF**
- **Excellent cross modulation performance and low noise operation**
- **High transconductance: 27mmhos**

FEATURES—SD306 (VHF TV and FM RF Amplifier)

- **High power gain without neutralization: 20dB at 200MHz**
- **Low noise figure: 1.5dB at 200MHz**
- **Low input and output capacitance: 3.3pF and 1.0pF constant with AGC**
- **Low feedback capacitance: 0.03pF**
- **Superior cross modulation performance**
- **High transconductance: 15mmhos**

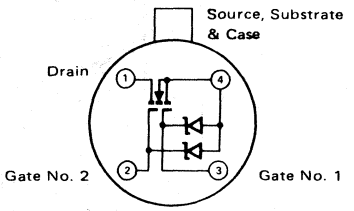
ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

PARAMETER		RATING	UNIT
V_{DS}	Drain-to-source voltage	+20	V
V_{G1B}	Gate no. 1—to-substrate voltage	-0.3 to +20	Vdc
V_{G2B}	Gate no. 1—to-substrate voltage	-0.3 to +20	Vdc
I_D	Drain current		
	SD305	150	mA
	SD306	50	mA
T_A	Ambient temperature range		
	Storage	-65 to +175	°C
	Operating	-55 to +125	°C
P_T	Transistor dissipation		
	At 25°C case temperature (Derate linearly to 125°C case temperature at the rate of 8.0mW/°C)	1.2	W
	At 25°C free-air temperature (Derate linearly to 125°C free-air temperature at the rate of 2.0mW/°C)	300	mW

PIN CONFIGURATION

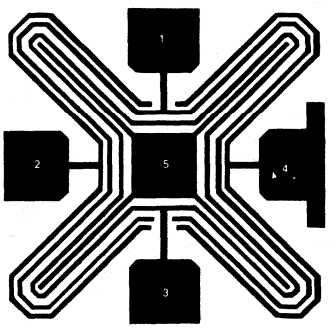
DE PACKAGE
(Top View)



ORDER PART NO.
SD305DE and SD306DE

CHIP DIAGRAMS

SD305

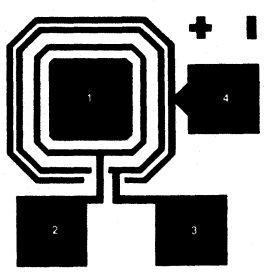


PAD NO.	PAD FUNCTION
1	GATE NO. 1
2	SOURCE
3	GATE NO. 2
4	SOURCE
5	DRAIN

Die Size 24 X 24

NOTE
Pads 2 and 4 must both be utilized for source connection

SD306



PAD NO.	PAD FUNCTION
1	DRAIN
2	GATE NO. 2
3	GATE NO. 1
4	SOURCE

Die Size 20 X 20

DC ELECTRICAL CHARACTERISTICS T_A = 25°C unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD305			SD306			UNIT
			Min	Typ	Max	Min	Typ	Max	
OFF Characteristics									
BV_{DS}	Drain-to-source Breakdown voltage	$V_{G1S} = V_{G2S} = 0V$, $I_D = 5\mu A$	20	30		20	25		V
I_D (OFF)	Drain-to-source Leakage current	$V_{DS} = +15V$ $V_{G1S} = V_{G2S} = 0V$		0.001	1.0		0.001	1.0	μA
I_{DSS}	Zero bias drain current	$V_{DS} = +15V$ $V_{G1S} = V_{G2S} = 0V$		0.001	1.0		0.001	1.0	μA
I_{G1SS}	Gate no. 1 leakage current	$V_{G1S} = +5V$ $V_{G2S} = V_{DS} = 0V$		0.001	0.1		0.001	0.1	μA
I_{G2SS}	Gate no. 2 leakage current	$V_{G2S} = +10V$ $V_{G1S} = V_{DS} = 0V$		0.001	0.1		0.001	0.1	μA
ON Characteristics									
V_{T1}	Gate 1 threshold voltage	$V_{DS} = V_{G1S} = V_{T1}$, $V_{G2S} = +10V$, $I_D = 1\mu A$	0.1	1.0	2.0	0.1	0.5	1.5	V
V_{T2}	Gate 2 threshold voltage	$V_{DS} = V_{G2S} = V_{T2}$, $V_{G1S} = +5V$, $I_D = 1\mu A$	0.1	1.0	2.0	0.1	0.5	1.5	V
$r_{DS(ON)}$	Drain-to-source on resistance	$V_{G1S} = +5V$, $V_{G2S} = +10V$, $I_D = 1.0mA$		30	60		65	100	Ω

AC ELECTRICAL CHARACTERISTICS T_A = 25°C unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD305			SD306			UNIT
			Min	Typ	Max	Min	Typ	Max	
Small signal characteristics									
gfs	Forward transconductance	$V_{DS} = +15V$, $V_{G2S} = +10V$, f = 1kHz							
		I_D = 50mA	24	27					mmhos
		I_D = 18mA				13	15		mmhos
gfs (CONV)	Conversion transconductance	$V_{DS} = +15V$, $V_{G1S} = V_{G2S}$, I_D = 8mA, f = 1kHz, $E_{LO(RMS)}$ = 750mV		10					mmhos
Capacitances		f = 1MHz, gate 2 AC grounded							
C_{G1S}	Input	$V_{DS} = +15V$, $V_{G2S} = +10V$							
		I_D = 50mA		4.0	5.0				pF
		I_D = 18mA					3.3	3.6	pF
		$V_{DS} = +15V$, $V_{G1S} = V_{G2S}$, I_D = 8mA		4.0	5.0				pF
C_{DS}	Output	$V_{DS} = +15V$, $V_{G1S} = 0V$, $V_{G2S} = +10V$		1.3	1.7		1.0	1.3	pF
C_{G1D}	Reverse transfer	$V_{DS} = +15V$ $V_{G1S} = 0V$, $V_{G2S} = +10V$		0.03			0.03		pF
	Input admittance	f = 200MHz, $V_{DS} = +15V$	$V_{G1S} = V_{G2S}$, I_D = 8mA			$V_{G2S} = +10V$, I_D = 18mA			
	$Re(Y_{11})$			1.05			1.11		mmhos
	$Im(Y_{11})$			6.66			4.76		mmhos
	Output admittance	f = 200MHz, $V_{DS} = +15V$							
	$Re(Y_{22})$			0.73			1.05		mmhos
	$Im(Y_{22})$			2.09			1.54		mmhos
	Forward transmittance	f = 200MHz, $V_{DS} = +15V$							
	$Re(Y_{21})$			4.69			13.23		mmhos
	$Im(Y_{21})$			-3.01			-5.62		mmhos
	Reverse transmittance	f = 200MHz, $V_{DS} = +15V$							
	$Re(Y_{12})$			0.04			0.01		mmhos
	$Im(Y_{12})$			-0.03			-0.04		mmhos
G_{ps}	Power gain[2]	$V_{DS} = +15V$, $V_{G2S} = +10V$ I_D = 18mA, f = 200MHz				17	20		dB

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AC ELECTRICAL CHARACTERISTICS (Cont'd) $T_A = 25°C$ unless otherwise specified.

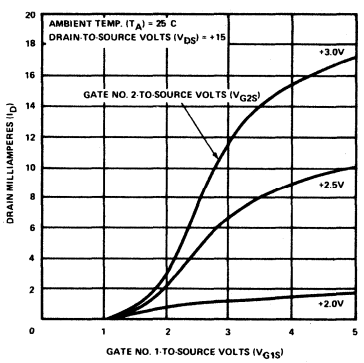
PARAMETER		TEST CONDITIONS	SD305			SD306			UNIT
			Min	Typ	Max	Min	Typ	Max	
G_{ps}(CONV)	Conversion power gain[1]	V_{DS} = +15V, V_{G1S} = V_{G2S}, I_D = 8mA, f_{rf} = 200MHz, f_{LO} = 245MHz	14	17					dB
NF	Noise figure	V_{DS} = +15V, V_{G2S} = +10V, I_D = 18mA, f = 200MHz					1.5	2.5	dB
AGC_{VG2S}	Range of automatic gain control	V_{DS} = +15V, V_{G1S} ≅ +2.5V, V_{G2S} = +10V→0V, f = 200MHz					50		dB
E_{INT}	Interfering signal level at gate 1 for 1% cross modulation distortion, peak voltage referenced to 50Ω system[3]	V_{DS} = 15V, V_{G2S} = +8V, I_D = 15mA Wanted signal f = 200MHz interfering signal f = 196MHz					480		mV

NOTES

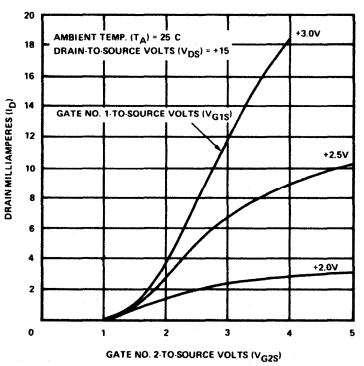
1. Measured in mixer test fixture.
2. Measured in amplifier test fixture.
3. Measured as shown in block diagram.

SD305 TYPICAL PERFORMANCE CHARACTERISTICS

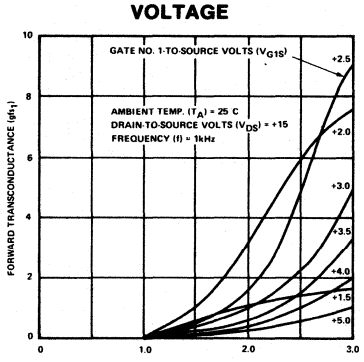
DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



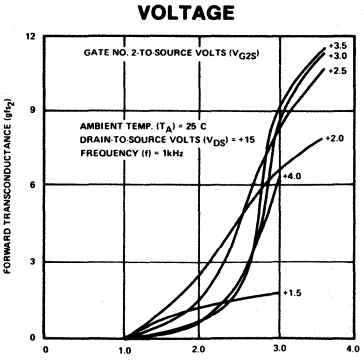
DRAIN CURRENT vs GATE NO. 2-TO-SOURCE VOLTAGE



GATE NO. 1 FORWARD TRANSCONDUCTANCE vs GATE NO. 2-TO-SOURCE VOLTAGE



GATE NO. 2 FORWARD TRANSCONDUCTANCE vs GATE NO. 1-TO-SOURCE VOLTAGE

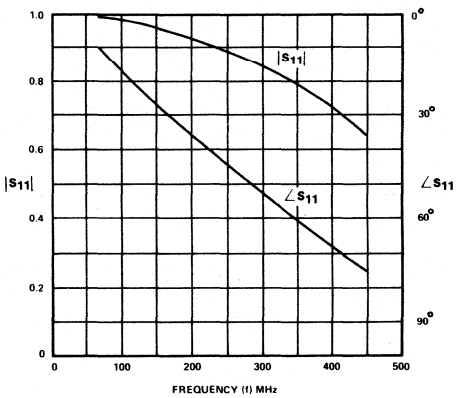


SD305 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

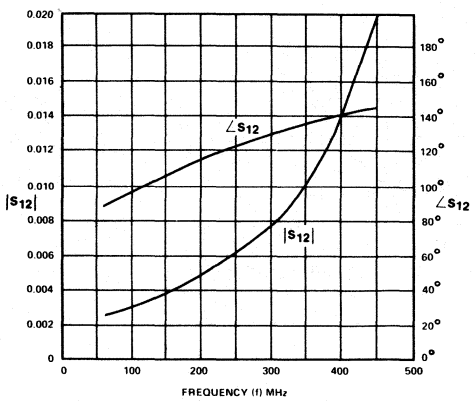
"S" PARAMETERS

AMBIENT TEMP. (T_A) = +25°C
DRAIN-TO-SOURCE VOLTS (V_{DS}) = +15
DRAIN MILLIAMPERES (I_D) = 8
GATE NO. 1-TO-SOURCE VOLTS (V_{G1S}) =
GATE NO. 2-TO-SOURCE VOLTS (V_{G2S})

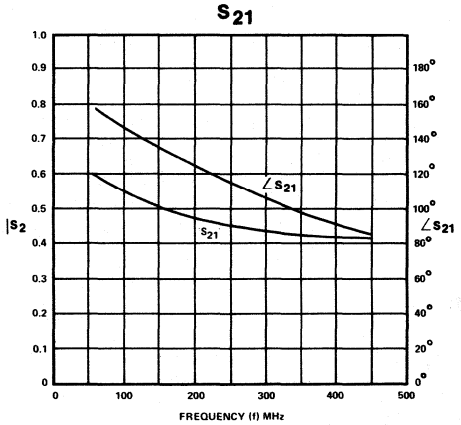
S_{11}



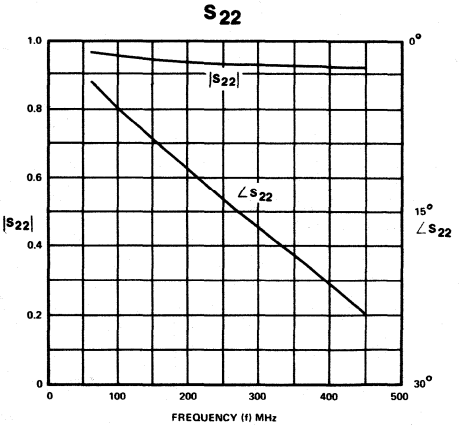
S_{12}



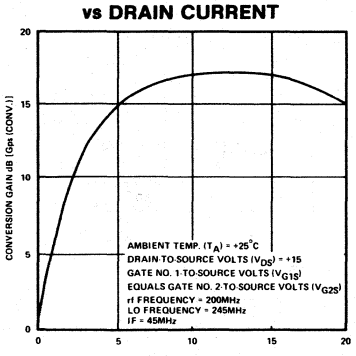
S_{21}



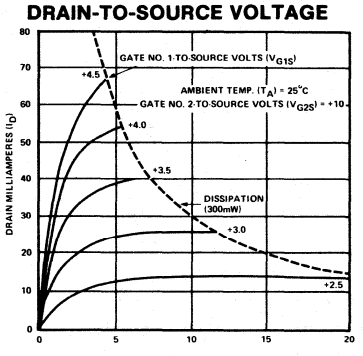
S_{22}



CONVERSION GAIN vs DRAIN CURRENT



DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



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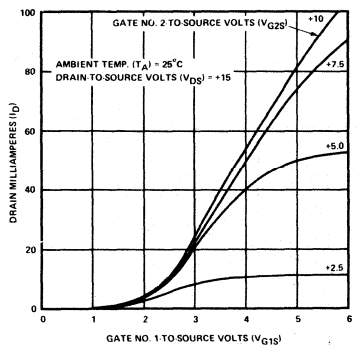
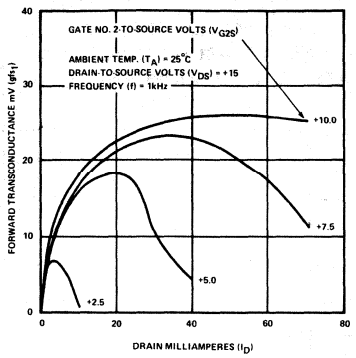
SD305 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

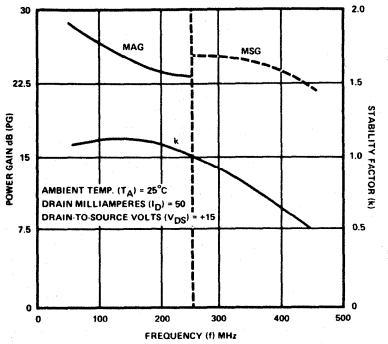
DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



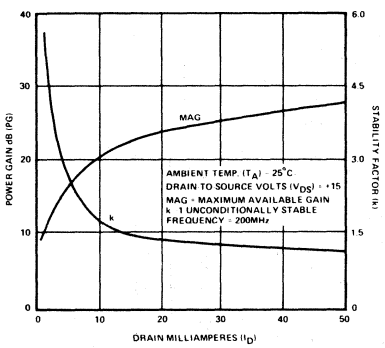
GATE NO. 1 FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



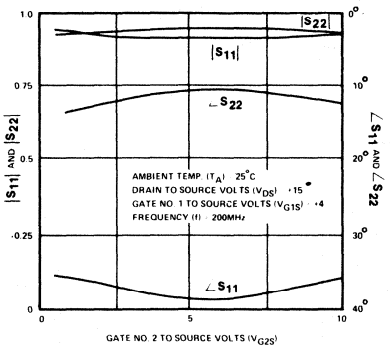
POWER GAIN vs FREQUENCY



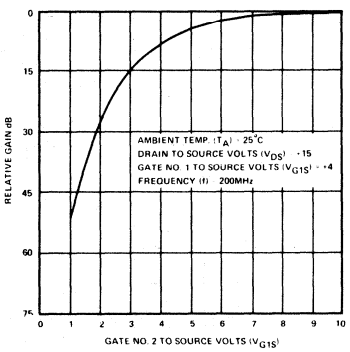
POWER GAIN vs DRAIN CURRENT



AUTOMATIC GAIN CONTROL vs S_{11} AND S_{22}



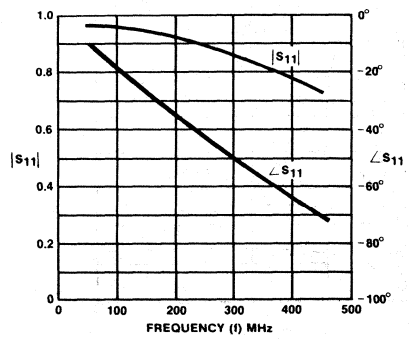
AUTOMATIC GAIN CONTROL RANGE



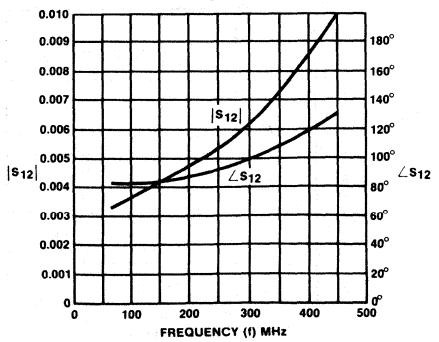
"S" PARAMETERS

AMBIENT TEMP. (T_A) = +25° C
DRAIN-TO-SOURCE VOLTS (V_{DS}) = +15
DRAIN MILLIAMPERES (I_D) = 50
GATE NO. 1-TO-SOURCE VOLTS (V_{G1S}) ≃ +3.5
GATE NO. 2-TO-SOURCE VOLTS (V_{G2S}) = +10

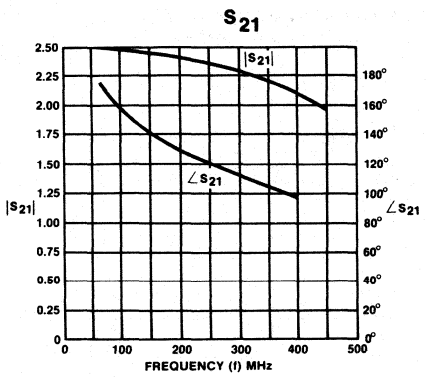
S_{11}

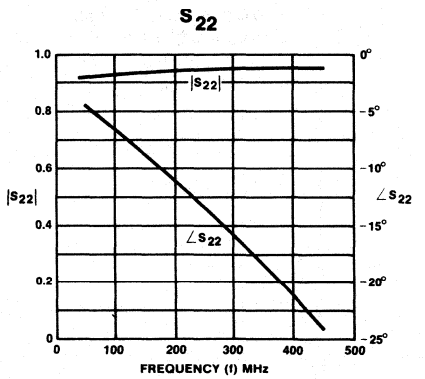


S_{12}



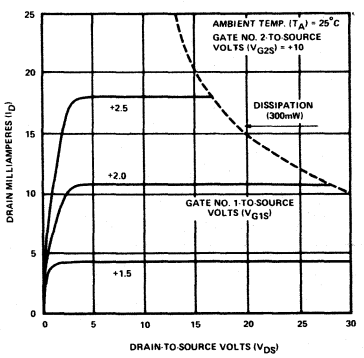
SD305 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)



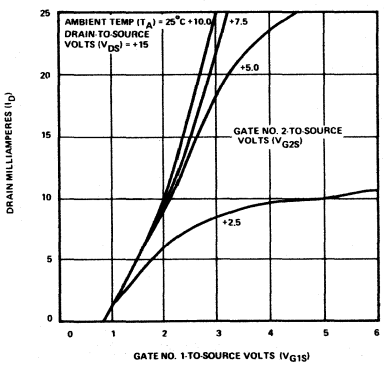


SD306 TYPICAL PERFORMANCE CHARACTERISTICS

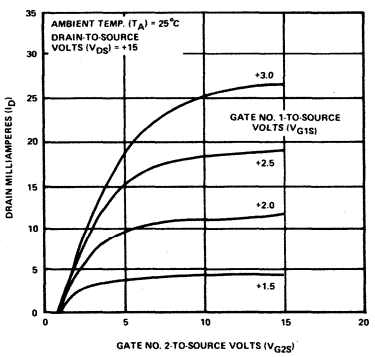
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



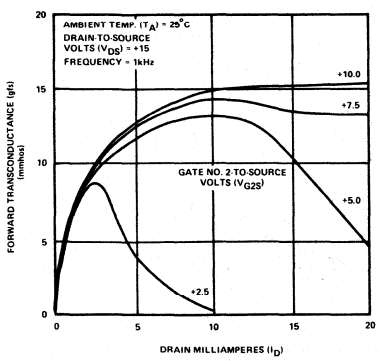
DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



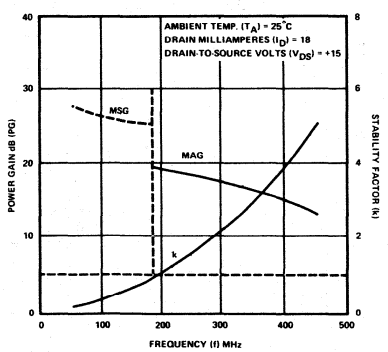
DRAIN CURRENT vs GATE NO. 2-TO-SOURCE VOLTAGE



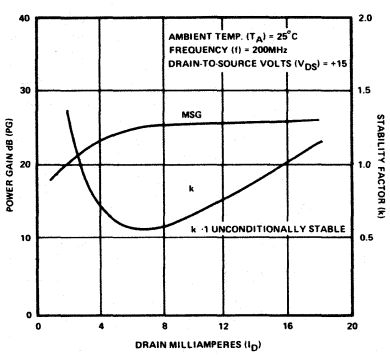
1kHz FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



POWER GAIN vs FREQUENCY



POWER GAIN vs DRAIN CURRENT



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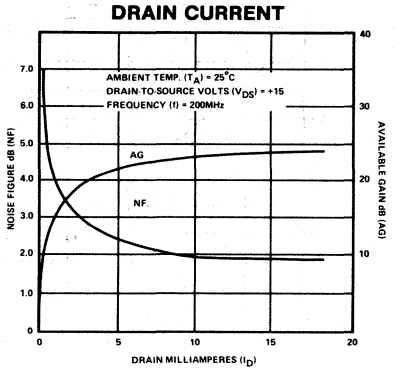
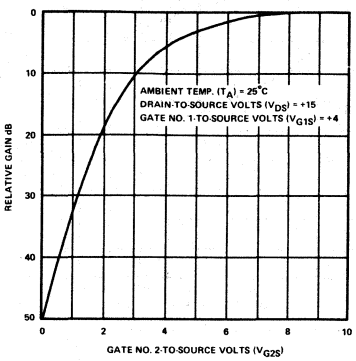
SD306 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

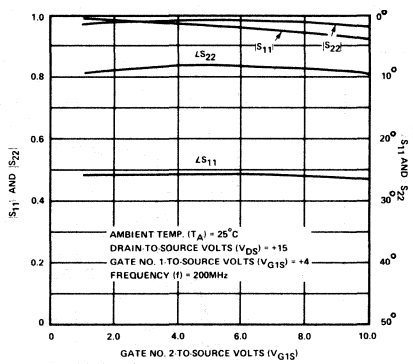
NOISE FIGURE AND AVAILABLE GAIN vs DRAIN CURRENT



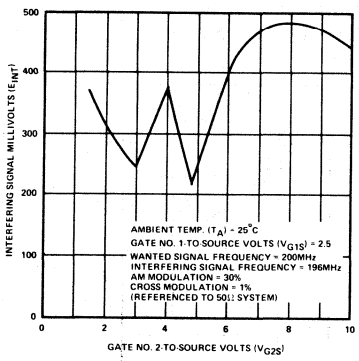
AUTOMATIC GAIN CONTROL RANGE AT 200MHz



S_{11} AND S_{22} vs AUTOMATIC GAIN CONTROL



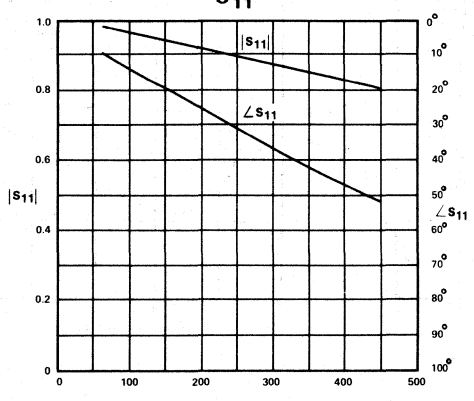
INTERFERING SIGNAL LEVEL vs GATE NO. 2-TO-SOURCE VOLTS



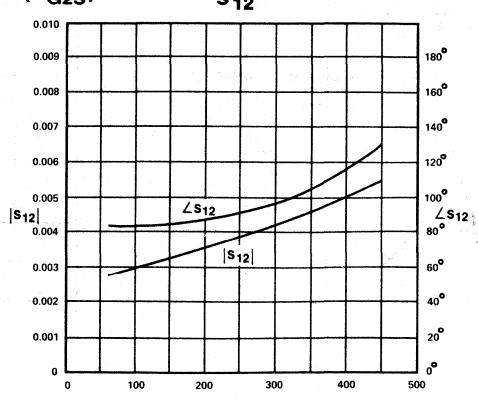
"S" PARAMETERS

AMBIENT TEMP. (T_A) = +25°C
DRAIN-TO-SOURCE VOLTS (V_{DS}) = 15
DRAIN MILLIAMPERES (I_D) = 8
GATE NO. 1-TO-SOURCE VOLTS (V_{G1S}) ≃ +2.5
GATE NO. 2-TO-SOURCE VOLTS (V_{G2S}) = +10

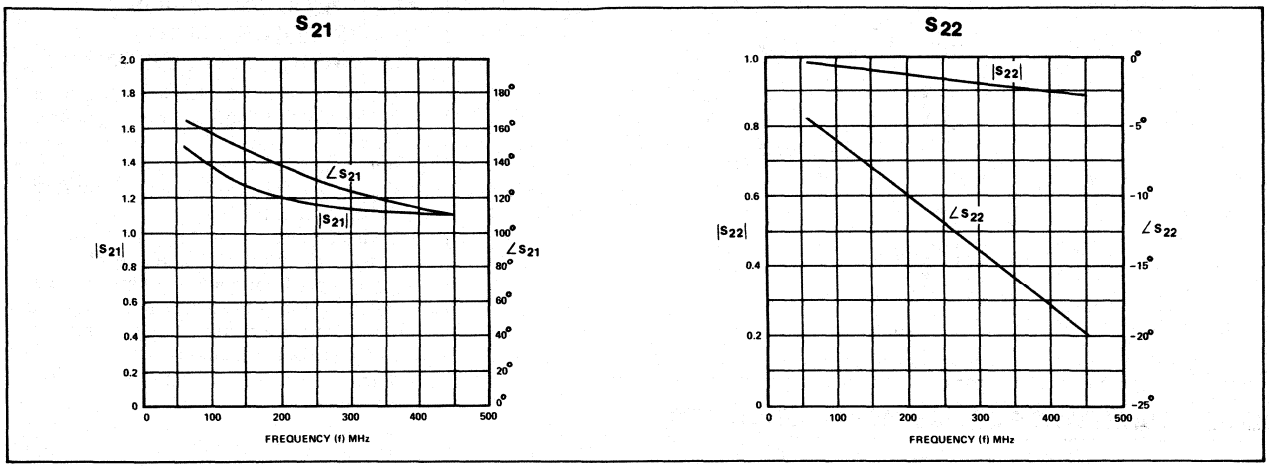
S_{11}



S_{12}

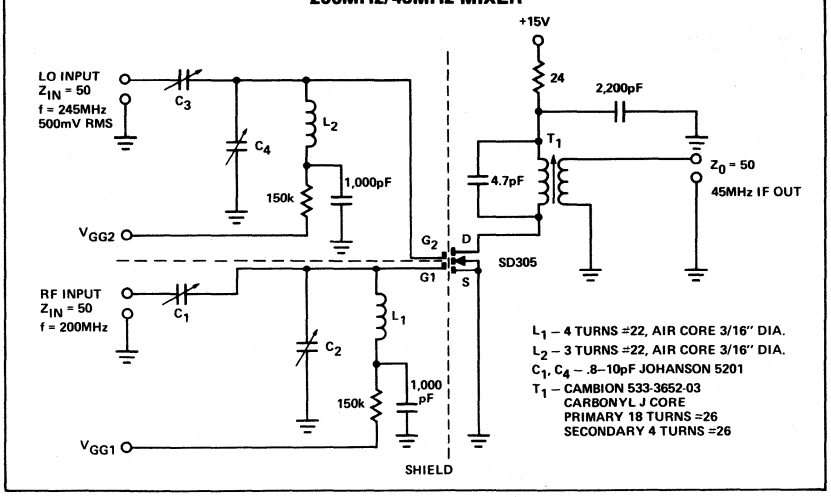


SD306 TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

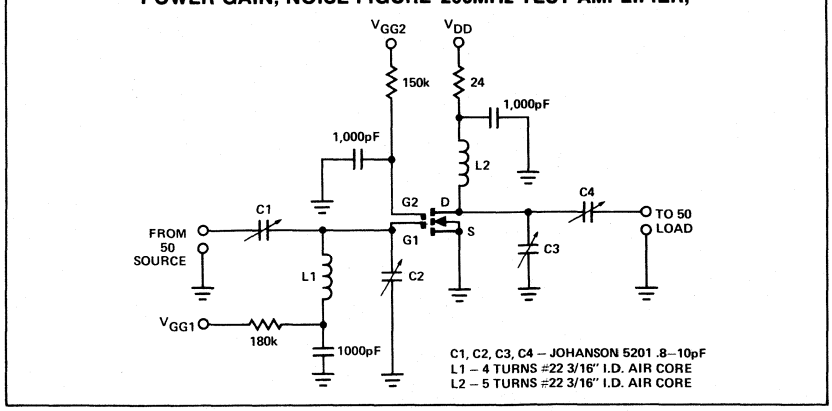


TEST CIRCUITS

SD305
200MHz/45MHz MIXER



SD306
POWER GAIN, NOISE FIGURE 200MHz TEST AMPLIFIER;



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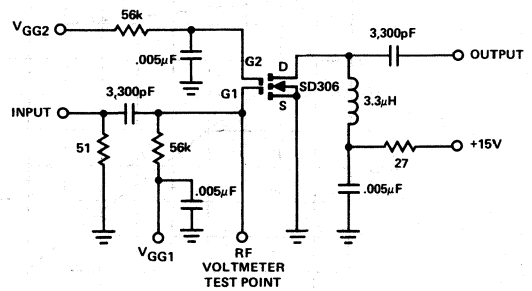
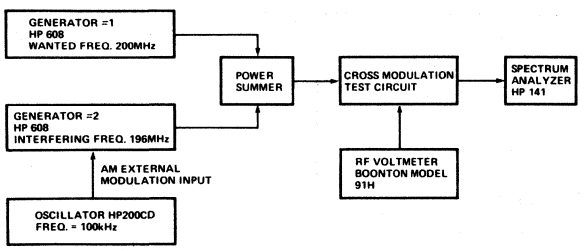
TEST CIRCUITS (Cont'd)

SD306
CROSS MODULATION



BLOCK DIAGRAM OF CROSS MODULATION TEST



SD306
TEST PROCEDURE FOR CROSS MODULATION DISTORTION MEASUREMENTS

1. Modulation on Generator #2 is set at 100kHz, 30% AM modulation (sidebands down 15.6dB) with an output signal frequency equal to 196MHz.
2. Generator #2 is set at approximately -15dbm, 200MHz.
3. While observing the test circuit output spectrum, adjust the signal level of the interfering frequency so that the sidebands on the desired frequency are 46dB down from the carrier. This corresponds to 1% cross modulation.
4. Turn off Generator #1 and turn off the modulation on Generator #2.
5. Using the RF voltmeter, measure the amplitude of the interfering signal at the test point.

DESCRIPTION

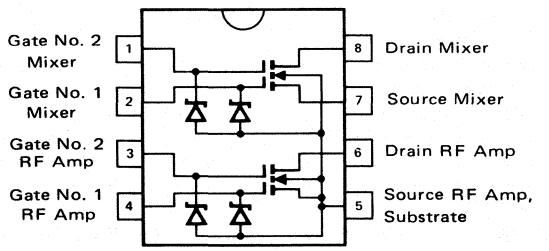
The Signetics D-MOS SD6000 is an integrated circuit fabricated by the double-diffused process and employing silicon N-channel enhancement mode MOSFETs with dual gates. Zener diodes are connected between all gates and the substrate. These diodes bypass any voltage transients which lie outside the range of -0.3V to +20.0V. Thus, the gates are protected against damage in all normal handling and operating situations. The use of the dual gate structure plus the incorporation of the drift region has made the feedback capacity (C_{G1D}) typically less than 0.03pF. The attributes of the IC make it ideally suited for FM/VHF RF amplifier and mixer applications. The IC is specifically characterized for incorporation into varactor or conventional FM tuners but the performance guaranteed makes it useful in a wide variety of VHF tuner applications. The power gain at 100MHz is 30dB minimum with a guaranteed noise figure of 3.0dB. A wide AGC capability plus significant reduction in cross modulation is now available because of the inherent linearity of the D-MOS FETs. The SD6000 is packaged in the Signetics 8-pin plastic N package.

GENERAL FEATURES

- **Positive bias only**
- **Low gate voltages**
- **Enhancement mode operation**
- **Zener diode gate protection**
- **Ion implanted for greater reliability**

PIN CONFIGURATION

N PACKAGE
(Top View)



ORDER PART NO.
SD6000N

FEATURES (RF AMP Section)

- **High power gain without neutralization: 25dB at 100MHz**
- **Low noise figure: 2.5dB at 100MHz**
- **Low input and output capacitances constant with AGC: 3.0pF and 1.0pF**
- **Low feedback capacitance: 0.025pF**
- **Superior cross modulation performance**
- **High transconductance: 15mmhos**
- **Wide AGC range: 50dB at 100MHz**

FEATURES (Mixer Section)

- **High conversion gain: 17dB at 100MHz with $V_{G1S} = V_{G2S}$ for biasing simplicity**
- **Excellent isolation from gate no. 1 (RF) to gate no. 2 (LO)**
- **Low input capacitance: 4.0pF**
- **Low feedback capacitance: 0.03pF**
- **Excellent cross modulation performance and low noise operation**
- **High conversion transconductance at low drain currents: 10mmhos**

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C unless otherwise specified.

	PARAMETER	RATING	UNIT
V_{DS}	Drain-to-source voltage	+20	V
V_{G1B}	Gate no. 1-to-substrate voltage	-0.3 to +20	Vdc
V_{G2B}	Gate no. 2-to-substrate voltage	-0.3 to +20	Vdc
	Drain current	50	mA
T_A	Ambient temperature range		
	Storage	-65 to +150	°C
	Operating	-55 to +85	°C
P_T	Power dissipation		
	At 25°C case temperature	625	mW
	Temperature above 25°C	Derate at 5.0	mW/°C

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DC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	RFAMP			MIXER			UNIT
			Min	Typ	Max	Min	Typ	Max	
OFF CHARACTERISTICS									
BV_{DS}	Drain-to-source breakdown voltage	$V_{G1S} = V_{G2S} = 0V$, $I_D = 5\mu A$	20	30		20	30		V
$I_{D(OFF)}$	Drain-to-source leakage current	$V_{DS} = +15V, V_{G1S} = V_{G2S} = 0V$		0.001	1.0		0.001	1.0	μA
I_{DSS}	Zero bias drain current	$V_{DS} = +15V, V_{G1S} = V_{G2S} = 0V$		0.001	1.0		0.001	1.0	μA
I_{G1SS}	Gate no. 1 leakage current	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0V$		0.001	0.1		0.001	0.1	μA
I_{G2SS}	Gate no. 2 leakage current	$V_{G2SS} = +10V, V_{G1S} = V_{DS} = 0V$		0.001	0.1		0.001	0.1	μA
ON CHARACTERISTICS									
V_{T1}	Gate 1 threshold voltage	$V_{DS} = V_{G1S} = V_{T1}$, $V_{G2S} = +10V$, $I_D = 1\mu A$	0.1	0.5	1.5	0.1	1.0	2.0	V
V_{T2}	Gate 2 threshold voltage	$V_{DS} = V_{G2S} = V_{T2}$, $V_{G1S} = +5V$, $I_D = 1\mu A$	0.1	0.5	1.5	0.1	1.0	2.0	V
$r_{DS(ON)}$	Drain-to-source on resistance	$V_{G1S} = +5V$, $V_{G2S} = +10V$, $I_D = 1.0mA$		65	100		30	60	Ω

AC ELECTRICAL CHARACTERISTICS $T_A = 25°C$ unless otherwise specified.[1,2]

PARAMETER		TEST CONDITIONS	SD6000			UNIT
			Min	Typ	Max	
SMALL SIGNAL CHARACTERISTICS-RF Amp						
gfs	Forward transconductance	$V_{DS} = +15V$, $V_{G2S} = +10V$, $I_D = 18mA$, $f = 1kHz$	12	15		mmhos
	Capacitances	$f = 1MHz$, gate no. 2 AC grounded				
C_{G1S}	Input	$V_{DS} = +15V$, $V_{G2S} = +10V$ $I_D = 18mA$		3.0	3.5	pF
C_{DS}	Output	$V_{DS} = +15V$, $V_{G1S} = 0V$, $V_{G2S} = 10V$		1.0	1.3	pF
C_{G1D}	Reverse transfer	$V_{DS} = +15V$, $V_{G1S} = 0V$, $V_{G2S} = 10V$		0.025		pF
	Input admittance					
	Re (Y_{11})			0.21		mmhos
	Im (Y_{11})			2.26		mmhos
	Output admittance					
	Re (Y_{22})			0.20		mmhos
	Im(Y_{22})	$f = 100MHz$, $V_{DS} = +15V$		0.68		mmhos
	Forward transmittance	$V_{G2S} = +10V$, $I_D = 18mA$				
	Re (Y_{21})			12.85		mmhos
	Im (Y_{21})			-1.50		mmhos
	Reverse transmittance					
	Re (Y_{12})			0.01		mmhos
	Im (Y_{12})			-0.03		mmhos
Gps	Power gain[1]	$V_{DS} = +15V$, $V_{G2S} = +10V$ $I_D = 18mA$, $f = 100MHz$	20	25		dB
NF	Noise figure[1]	$V_{DS} = +15V$, $V_{G2S} = +10V$ $I_D = 18mA$, $f = 100MHz$		2.5	3.0	dB
AGC(V_{G2S})	Range of automatic gain control	$V_{DS} = +15V$, $V_{G1S} \cong +2.5V$, $f = 100MHz$		50		dB

AC ELECTRICAL CHARACTERISTICS (Cont'd) T_A = 25°C unless otherwise specified.[1,2]

	SMALL SIGNAL CHARACTERISTICS—MIXER					
$gfs_{(CONV)}$	conversion transconductance	V_{DS} = +15V, V_{G1S} = V_{G2S} I_D = 8mA, f = 1kHz $E_{LO(RMS)}$ = 750mV		10		mmhos
	Capacitances	f = 1MHz, gate no. 2 AC grounded				
C_{G1S}	Input	V_{DS} = +15V, V_{G1S} = V_{G2S}, I_D = 8mA		4.0	4.75	pF
C_{DS}	Output	V_{DS} = +15V, V_{G1S} = V_{G2S} = 0V		1.1	1.5	pF
C_{G1D}	Reverse transfer	V_{DS} = +15V, V_{G1S} = V_{G2S} = 0V		0.030		pF
	Input admittance					
	Re (Y_{11})			0.21		mmhos
	Im (Y_{11})			2.28		mmhos
	Output admittance					
	Re (Y_{22})			0.41		mmhos
	Im (Y_{22})	f = 100MHz, V_{DS} = +15V		1.04		mmhos
	Forward transmittance	V_{G1S} = V_{G2S}, I_D = 8mA				
	Re (Y_{21})			3.18		mmhos
	Im (Y_{21})			-0.83		mmhos
	Reverse transmittance					
	Re (Y_{12})			0.03		mmhos
	Im (Y_{12})			-0.01		mmhos
$Gps_{(CONV)}$	Conversion power gain[2]	V_{DS} = +15V, V_{G1S} = V_{G2S}, I_D = 8mA, f_{RF} = 100MHz, f_{LO} = 89.3MHz	14	19		dB

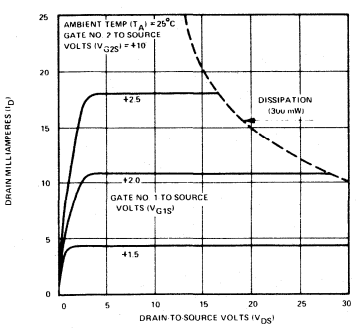
NOTES

1. Measured in amplifier test fixture.
2. Measured in MIXER test fixture.

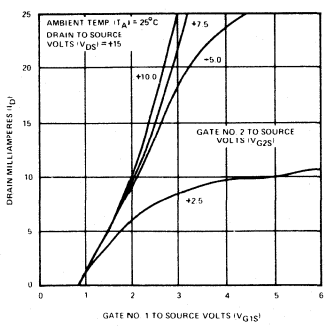
TYPICAL PERFORMANCE CHARACTERISTICS

RF AMP SECTION

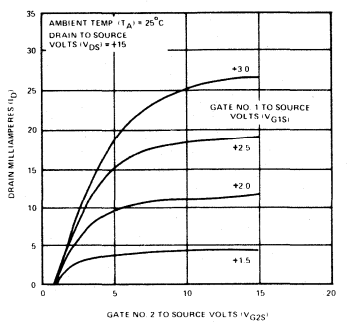
DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE



DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



DRAIN CURRENT vs GATE NO. 2-TO-SOURCE VOLTAGE



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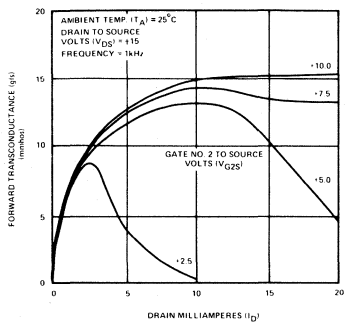
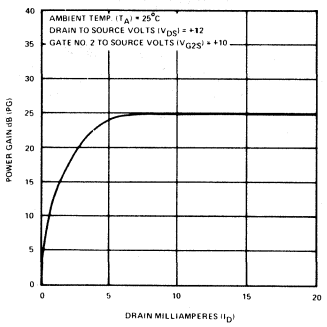
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

RF AMP SECTION

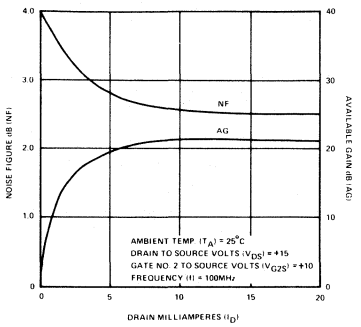
1kHz FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



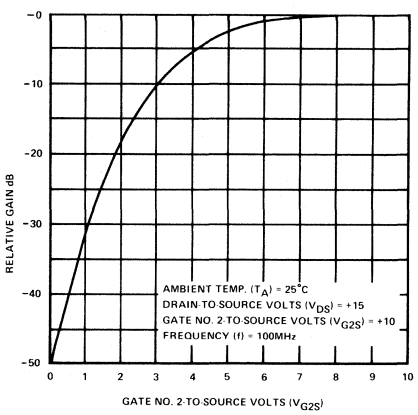
POWER GAIN vs DRAIN CURRENT



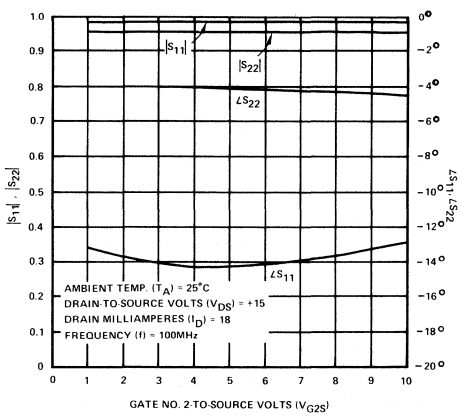
NOISE FIGURE AND AVAILABLE GAIN vs DRAIN CURRENT



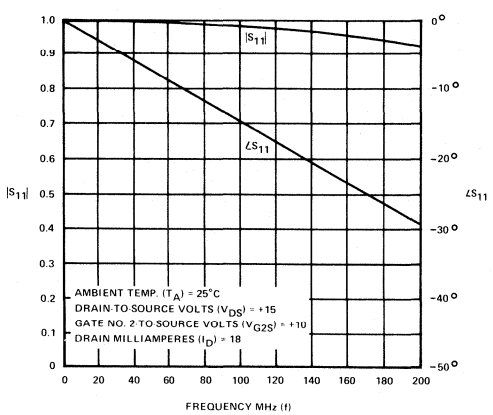
AUTOMATIC GAIN CONTROL RANGE



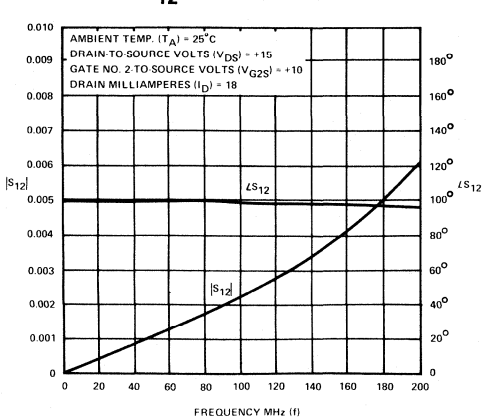
S_{11} AND S_{22} vs GATE NO. 2-TO-SOURCE VOLTAGE



S_{11} vs FREQUENCY



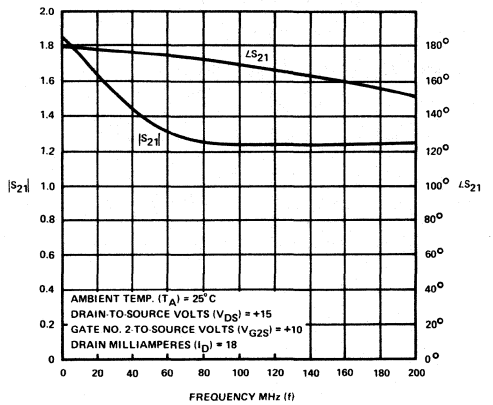
S_{12} vs FREQUENCY



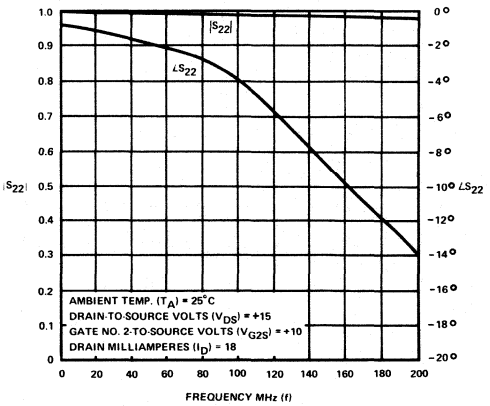
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

RF AMP SECTION

S_{21} vs FREQUENCY

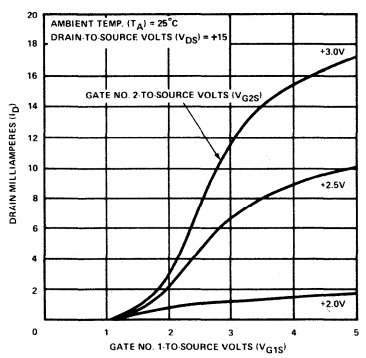


S_{22} vs FREQUENCY

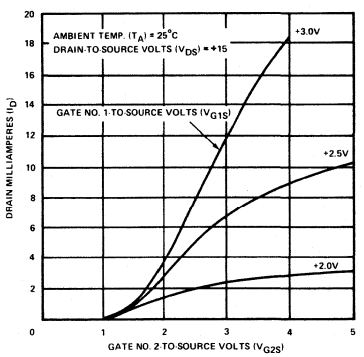


MIXER SECTION

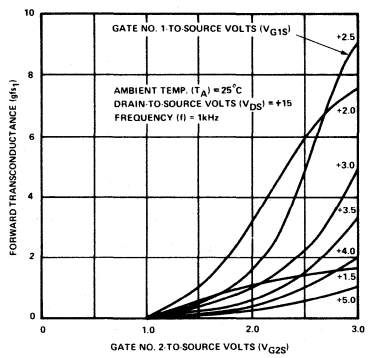
DRAIN CURRENT vs GATE NO. 1-TO-SOURCE VOLTAGE



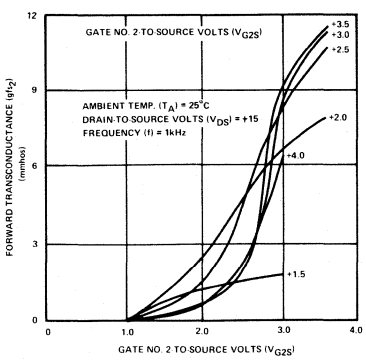
DRAIN CURRENT vs GATE NO. 2-TO-SOURCE VOLTAGE



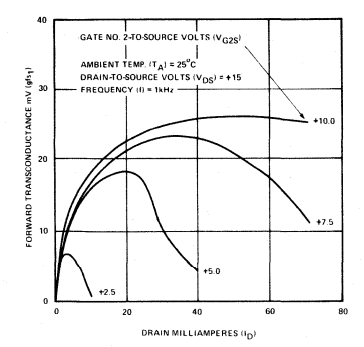
GATE NO. 1 FORWARD TRANSCONDUCTANCE vs GATE NO. 2-TO-SOURCE VOLTAGE



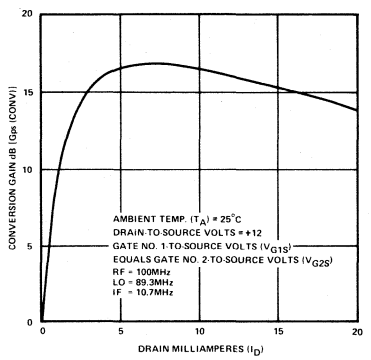
GATE NO. 2 FORWARD TRANSCONDUCTANCE vs GATE NO. 1-TO-SOURCE VOLTAGE



GATE NO. 1 FORWARD TRANSCONDUCTANCE vs DRAIN CURRENT



CONVERSION GAIN vs DRAIN CURRENT



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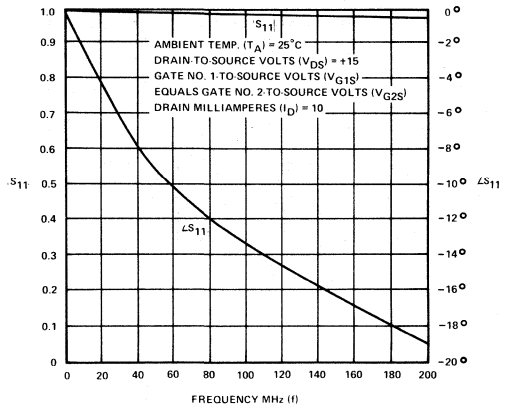
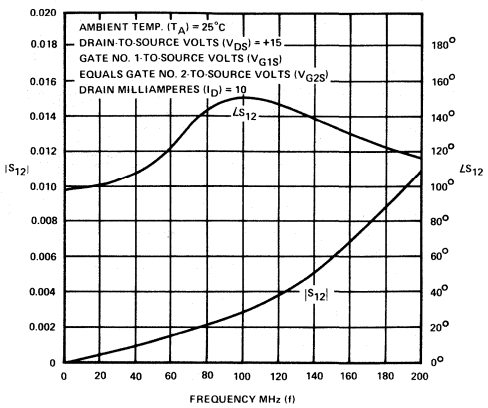
TYPICAL PERFORMANCE CHARACTERISTICS (Cont'd)

MIXER SECTION

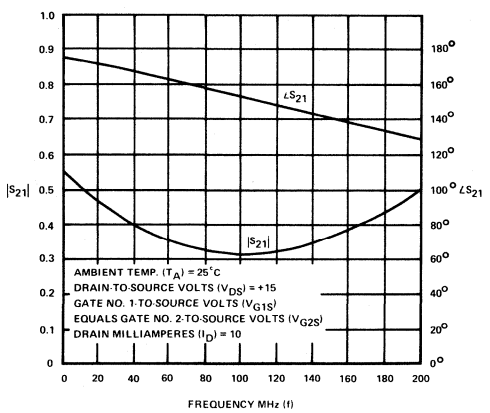
S_{11} vs FREQUENCY



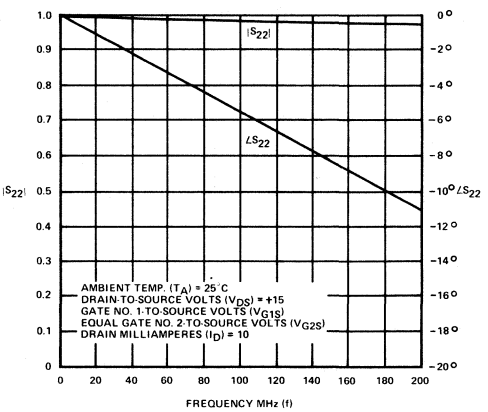
S_{12} vs FREQUENCY



S21 vs FREQUENCY

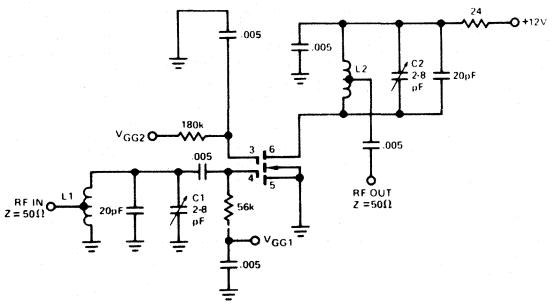


S22 vs FREQUENCY



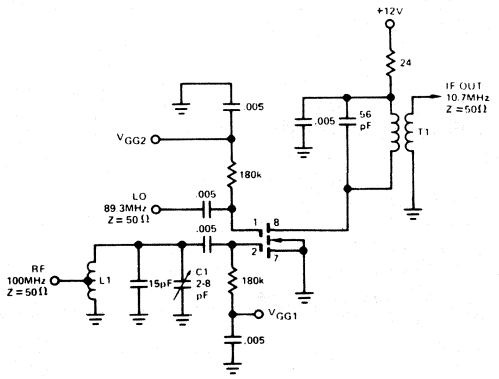
TEST CIRCUITS

RF AMP SECTION



L1-L2 5 turn #18 wire 3/16" dia. air core tapped at 1 turn
C1-C2 NPO, ERIE no. 538-011A-2-8

MIXER SECTION



T1	Cambion core = 533-3652-003 Carbonyl J core, Primary coil 30 turns = 26 wire Secondary coil 2 turns = 26 wire
L1	5 turns = 18 wire, 3/16" dia. air core Tap 1 turn from ground side
C1	NPO, ERIE no. 538-011A-2-8

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SD5000/5001/5002/5200-N,I

DESCRIPTION

The Signetics D-MOS SD5000 and 5200 series are monolithic arrays of silicon, insulated-gate, field-effect transistors using the N-channel enhancement mode technology.

This family of devices is designed to handle a wide variety of analog switching and driver applications. They are capable of high speed operation where excellent transient response, and wide voltage range are required. The SD5000 quad switch array quad multiplexer can handle high voltage analog signals (±10V). The SD5002 is designed for ±7.5V analog signals using ±15V power supplies. The SD5001 is designed for lower voltage applications. The SD5200 is intended for use as a 30V driver to complement the other switch products.

FEATURES

- **Low input capacitance: 2.4pF**
- **Low feedback capacitance: 0.3pF**
- **Low output capacitance: 1.3pF**
- **±10V analog signal range**
- **Low propagation delay time: 600ps**
- **Low on resistance: 30Ω**
- **Low feedthrough and feedback transients**
- **Ion implanted for greater reliability**
- **High channel-to-channel isolation: 107dB**
- **Transient protection for gates**
- **Military qualifications pending**

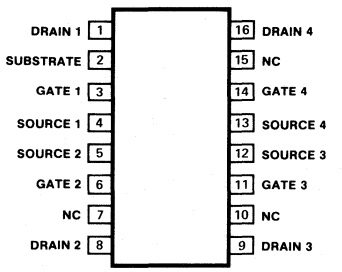
APPLICATIONS

- **SD5000 applications**
  - **Analog switching (up to very high frequencies)**
  - **Audio routing**
  - **Choppers**
  - **Crosspoint switches**
  - **Sample and hold**
- **SD5200 applications**
  - **Switch drivers**

PIN CONFIGURATIONS

I, N PACKAGE

(Top View)

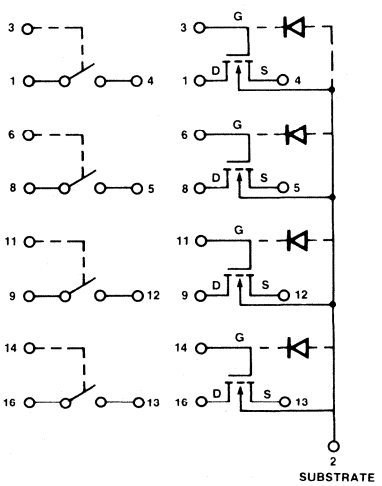


ORDER PART NO.

SD5000N,I SD5001N,I SD5002N,I SD5200N,I

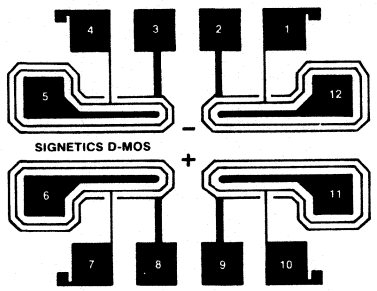
FUNCTIONAL AND SCHEMATIC DIAGRAM

SD5000, 5001, 5002, 5200



CHIP DIAGRAM

SD5000, 5001, 5002, 5200 SWITCH ARRAYS



PAD NO.	PAD FUNCTION
1	Gate No. 1
2	Source No. 1
3	Source No. 2
4	Gate No. 2
5	Drain No. 2
6	Drain No. 3
7	Gate No. 3
8	Source No. 3
9	Source No. 4
10	Gate No. 4
11	Drain No. 4
12	Drain No. 1

Die Size 40X32

ABSOLUTE MAXIMUM RATINGS T_A = 25°C unless otherwise specified.

PARAMETER		SD5000	SD5001	SD5002	SD5200	UNIT
V_{DS}	Drain-to-source	+20	+10	+15	+30	Vdc
V_{SD}	Source-to-drain[1]	+20	+10	+15	+.5	Vdc
V_{DB}	Drain-to-substrate	+25	+15	+22.5	+30	Vdc
V_{SB}	Source-to-substrate	+25	+15	+22.5	+15	Vdc
V_{GS}	Gate-to-source	+30 -25	+25 -15	+30 -22.5	+25	Vdc
V_{GB}	Gate-to-substrate	+30 -0.3	+25 -0.3	+30 -0.3	+25 -0.3	Vdc
V_{GD}	Gate-to-drain	+30 -25	+25 -15	+30 -22.5	+25	Vdc
I_D	Drain current	50	50	50	50	mA
Ambient temperature range						
	Storage			-55 to +150		°C
	Operating			0 to +85		°C
Power Dissipation						
	Total package dissipation[2]			640		mW
	Individual transistor dissipation			300		mW

NOTES

1. Refer to test conditions specified in Electrical Characteristics Table.
2. Derated 5mW per degree centigrade.

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DC ELECTRICAL CHARACTERISTICS

T_A = +25°C unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD5000			SD5001			UNIT
			Min	Typ	Max	Min	Typ	Max	
BREAKDOWN VOLTAGE									
BV_{DS}	Drain-to-source	V_{GS} = V_{BS} = -5V, I_S = 10nA	20	25		10	25		V
BV_{SD}	Source-to-drain	V_{GD} = V_{BD} = -5V, I_D = 10nA	20			10			V
BV_{DB}	Drain-to-substrate	V_{GB} = 0V, source Open							
		I_D = 10nA	25			15			V
BV_{SB}	Source-to-substrate	V_{GB} = 0V, drain Open							
		I_S = 10μA	25			15			V
LEAKAGE CURRENT									
$I_{DS(OFF)}$	Drain-to-source	V_{GS} = V_{BS} = -5V							
		V_{DS} = +20V		1	10				nA
		V_{DS} = +10V					1	10	nA
$I_{SD(OFF)}$	Source-to-drain	V_{GD} = V_{BD} = -5V							
		V_{SD} = +20V		1	10				nA
		V_{SD} = +10V					1	10	nA
I_{GBS}	Gate	V_{DB} = V_{SB} = 0V							
		V_{GB} = 30V			1				μA
		V_{GB} = 25V						1	μA
V_T	Threshold voltage	V_{DS} = V_{GS} = V_T, I_S = 1μA V_{SB} = 0V	0.1	1.0	2.0	0.1	1.0	2.0	V
$r_{DS(ON)}$	Drain-to-source-resistance	I_D = 1.0mA, V_{SB} = 0							
		V_{GS} = +5V		50	70		50	70	Ω
		V_{GS} = +10V		30			30		Ω
		V_{GS} = +15V		23			23		Ω
		V_{GS} = +20V		19			19		Ω
$r_{DS(ON)}$	Resistance match	I_D = 1.0mA, V_{SB} = 0							
		V_{GS} = +5V		1	5		1	5	Ω

DC ELECTRICAL CHARACTERISTICS (Cont'd) $T_A = +25°C$ unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD5002 Min	SD5002 Typ	SD5002 Max	UNIT
BREAKDOWN VOLTAGE						
BV_{DS}	Drain-to-source	$V_{GS} = V_{BS} = -5V$, $I_S = 10nA$	15	25		V
		$V_{GS} = V_{BS} = 0V$, $I_S = 1\mu A$				V
BV_{SD}	Source-to-drain	$V_{GD} = V_{BD} = -5V$, $I_D = 10nA$	15			V
BV_{DB}	Drain-to-substrate	$V_{GB} = 0V$, source Open				
		$I_D = 10nA$	22.5			V
		$I_D = 1\mu A$				V
BV_{SB}	Source-to-substrate	$V_{GB} = 0V$, drain Open				
		$I_S = 10\mu A$	22.5			V
LEAKAGE CURRENT						
$I_{DS(OFF)}$	Drain-to-source	$V_{GS} = V_{BS} = -5V$				
		$V_{DS} = +15V$		1	10	nA
		$V_{GS} = V_{BS} = 0V$, $V_{DS} = +10V$				nA
$I_{SD(OFF)}$	Source-to-drain	$V_{GD} = V_{BD} = -5V$				
		$V_{SD} = +15V$		1	10	nA
I_{GBS}	Gate	$V_{DB} = V_{SB} = 0V$				
		$V_{GB} = 30V$			1	μA
		$V_{GB} = 25V$				μA
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_S = 1\mu A$ $V_{SB} = 0V$	0.1	1.0	2.0	V
$r_{DS(ON)}$	Drain-to-source-resistance	$I_D = 1.0mA$, $V_{SB} = 0$				
		$V_{GS} = +5V$		50	70	Ω
		$V_{GS} = +10V$		30		Ω
		$V_{GS} = +15V$		23		Ω
		$V_{GS} = +20V$		19		Ω
$r_{DS(ON)}$	Resistance match	$I_D = 1.0mA$, $V_{SB} = 0$				
		$V_{GS} = +5V$		1	5	Ω

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DC ELECTRICAL CHARACTERISTICS (Cont'd) T_A = +25°C unless otherwise specified.

PARAMETER		TEST CONDITIONS	SD5200 Min	SD5200 Typ	SD5200 Max	UNIT
BREAKDOWN VOLTAGE						
BV_{DS}	Drain-to-source	$V_{GS} = V_{BS} = 0V$, $I_S = 1\mu A$				
		$V_{GS} = V_{BS} = 0V$, $I_D = 10\mu A$	30	35		V
BV_{SD}	Source-to-drain	$V_{GD} = V_{BD} = -5V$, $I_D = 10nA$				V
BV_{DB}	Drain-to-substrate	$V_{GB} = 0V$, source Open				
		$I_D = 1\mu A$				V
BV_{SD}	Source-to-substrate	$V_{GB} = 0V$, drain Open				
		$I_S = 10\mu A$				V
LEAKAGE CURRENT						
$I_{DS(OFF)}$	Drain-to-source	$V_{GS} = V_{BS} = 0V$, $V_{DS} = +10V$				nA
I_{GBS}	Gate	$V_{DB} = V_{SB} = 0V$				
		$V_{GB} = 25V$			1	μA
V_T	Threshold voltage	$V_{DS} = V_{GS} = V_T$, $I_S = 1\mu A$, $V_{SB} = 0V$	0.5	1.0	2.0	V
$r_{DS(ON)}$	Drain-to-source-resistance	I_D = 1.0mA, V_{SB} = 0				
		V_{GS} = +5V		50	80	Ω
		V_{GS} = +10V		30		Ω
		V_{GS} = +15V		23		Ω
		V_{GS} = +20V		19		Ω
$r_{DS(ON)}$	Resistance match	I_D = 1.0mA, V_{SB} = 0, V_{GS} = +5V				Ω

AC ELECTRICAL CHARACTERISTICS

PARAMETER		TEST CONDITIONS	SD5000 Min	SD5000 Typ	SD5000 Max	SD5001 Min	SD5001 Typ	SD5001 Max	UNIT
gfs	Forward transconductance	V_{DS} = 10V, V_{SB} = 0V, I_D = 20mA, f = 1kHz	10	15		10	15		mmhos
	Small signal capacitances	V_{DS} = 10V, f = 1MHz, $V_{GS} = V_{BS}$ = -15V							
$C_{(GS+GD+GB)}$	Gate node	See capacitance model in Figure 1		2.4	3.5		2.4	3.5	pF
$C_{(GD+DB)}$	Drain node			1.3	1.5		1.3	1.5	pF
$C_{(GS+SB)}$	Source node			3.5	4.0		3.5	4.0	pF
C_{DG}	Reverse transfer			0.3	0.5		0.3	0.5	pF
C_T	Cross talk	See test circuits no. 1 and 2, f = 3kHz		-107			-107		dB

AC ELECTRICAL CHARACTERISTICS (Cont'd)

	PARAMETER	TEST CONDITIONS	SD5002			UNIT
			Min	Typ	Max	
gfs	Forward transconductance	V_{DS} = 10V, V_{SB} = 0V I_D = 20mA, f = 1kHz	10	15		mmhos
	Small signal capacitances	V_{DS} = 10V, f = 1MHz V_{GS} = V_{BS} = -15V				
$C_{(GS+GD+GB)}$	Gate node	See capacitance model in Figure 1		2.4	3.5	pF
$C_{(GD+DB)}$	Drain node			1.3	1.5	pF
$C_{(GS+SB)}$	Source node			3.5	4.0	pF
C_{DG}	Reverse transfer			0.3	0.5	pF
C_T	Cross talk	See test circuits no. 1 and 2, f = 3kHz		-107		dB

AC ELECTRICAL CHARACTERISTICS (Cont'd)

	PARAMETER	TEST CONDITIONS	SD5200			UNIT
			Min	Typ	Max	
gfs	Forward transconductance	V_{DS} = 10V, V_{SB} = 0V I_D = 20mA, f = 1kHz	10	15		mmhos
	Small signal capacitances	V_{DS} = 10V, f = 1MHz V_{GS} = V_{BS} = -15V				
$C_{(GS+GD+GB)}$	Gate node	See capacitance model in Figure 1		2.4	3.5	pF
$C_{(GD+DB)}$	Drain node			1.3	1.5	pF
C_{DG}	Reverse transfer			0.3	0.5	pF
C_T	Cross talk	See test circuits no. 1 and 2, f = 3kHz		-107		dB

THEORY OF OPERATION

The SD5000 series consists of four SPST switches with analog signal capability of up to ±10 volts for the SD5000 and ±7.5 volts for the SD5002. Each switch of the array is a D-MOS N-channel field-effect transistor of the enhancement-mode type; that is, the device is normally off when gate-to-source voltage (V_{GS}) is zero volts. When V_{GS} exceeds the threshold voltage, V_T, the FET switch starts to turn ON with V_{GS} in excess of +10 volts, a low resistance path (typically 30Ω) exists between input and output of the switch. Figure 1 shows the normal mode of operation of a single switch of the array for ±5 volt analog signal processing. Note that the source is recommended for the input since feedback or reverse transfer capacitance is lower when drain is used as the output. In this case, the switch is driven by ±10 volts for which the SD5200 could be used as discussed later. When analog signals are routed from one point to another the important factors are **isolation, crosstalk between switches, feedthrough and feedback transients, insertion loss and speed of operation**. The SD5000 series offers superior performance in all these areas (Figure 1).

Isolation. ON resistance is typically 30Ω and OFF resistance is typically 10^{10}Ω, which results in an OFF to ON resistance ratio in excess of 10^9. Isolation from output to input from 3kHz analog signals is typically -107dB.

Feedback and feedthrough transients. These are kept to a minimum because of the very low feedback and feedthrough capacitances. This means that "glitchless" or "clean" signals appear at the output.

Insertion loss. This depends upon the source and load impedances involved. As an example, for 600Ω source impedance the insertion loss for voice signals (1V RMS at 3kHz) is less than 0.3dB. This indicates that the SD5000 series would make good telephone cross-point switches.

Speed. Because of the low ON resistance and low input capacitance, the SD5000 switches turn ON at sub-nanosecond speeds. They are also capable of handling very high frequency analog signals and still maintain excellent isolation (20-30dB at 1GHz).

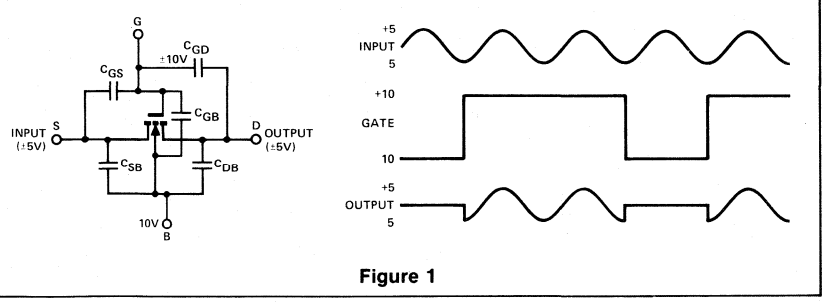

Figure 1

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The SD5200 is intended as a driver for the SD5000/5001/5002 but is capable of driving any system which requires ±15 volts. Four drivers are in each package and Figure 2 shows how a single driver is biased for ±15 volts. Two external resistors, R_1 and R_2, and a zener diode, D_1, are required per driver. The input is 5V open collector TTL (Figure 2).

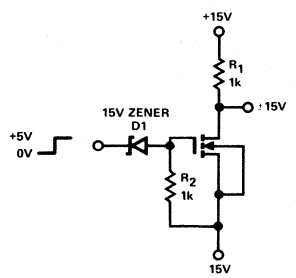


Figure 2

ANALOG SWITCH/DRIVER APPLICATION

The SD5200 operates as an inverting switch capable of driving 30 volts maximum. This wide range capability with high speed fulfills most analog switching applications. Figure 3 demonstrates how the SD5200 drives the SD5000 in a typical analog switching application (Figure 3).

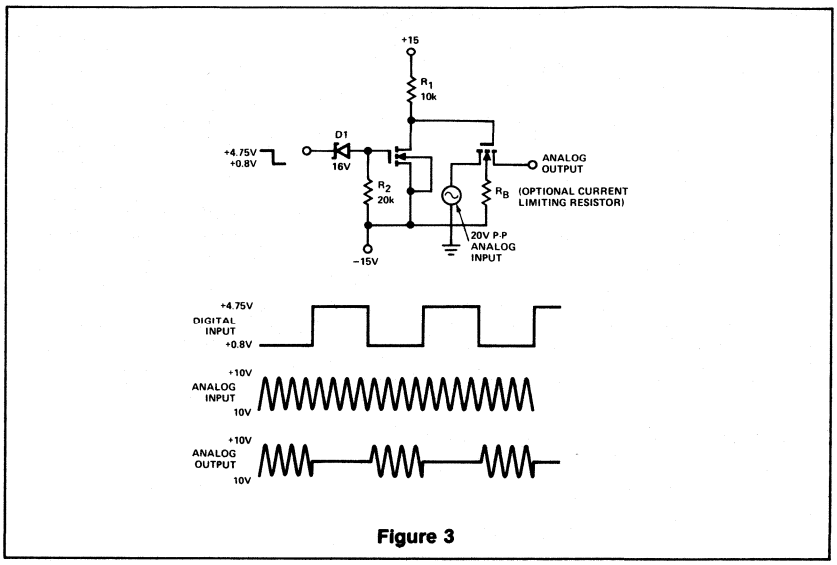
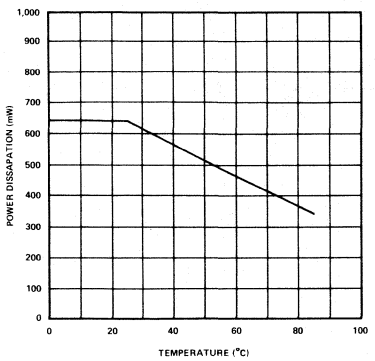


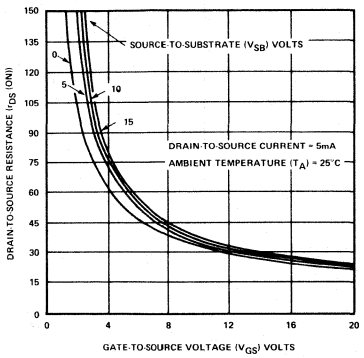
Figure 3

TYPICAL PERFORMANCE CHARACTERISTICS

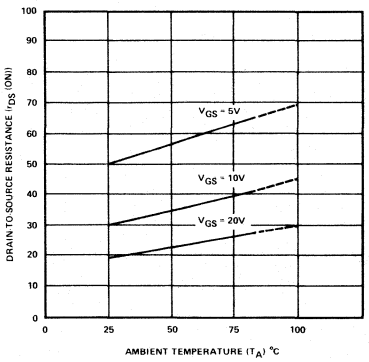
MAXIMUM POWER DISSIPATION vs TEMPERATURE



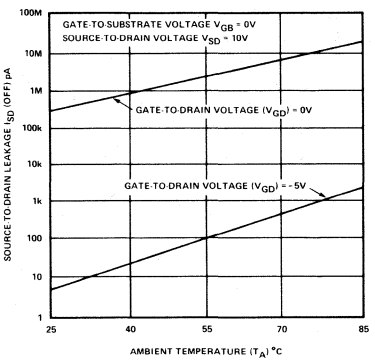
DRAIN-TO-SOURCE RESISTANCE vs SOURCE-TO-SUBSTRATE AND GATE-TO-SOURCE VOLTAGE



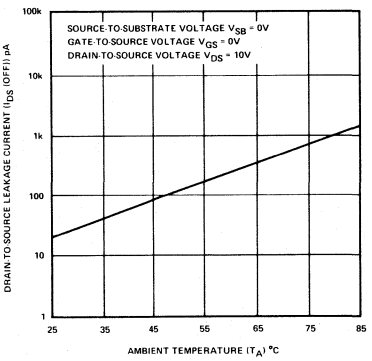
DRAIN-TO-SOURCE RESISTANCE vs TEMPERATURE



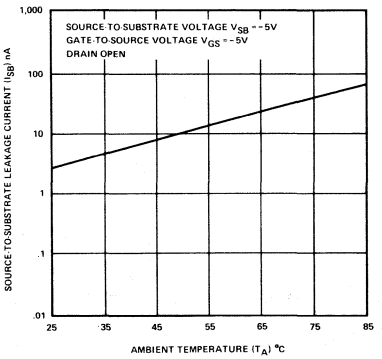
SOURCE-TO-DRAIN LEAKAGE CURRENT vs TEMPERATURE



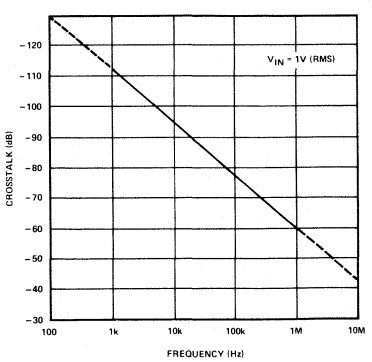
DRAIN-TO-SOURCE LEAKAGE CURRENT vs TEMPERATURE



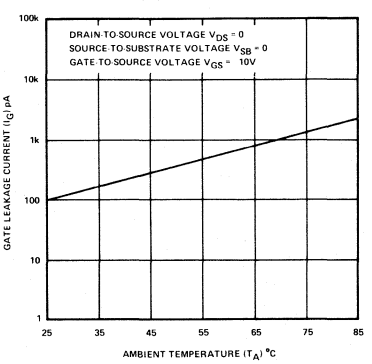
SOURCE-TO-SUBSTRATE LEAKAGE CURRENT vs TEMPERATURE



CROSSTALK vs FREQUENCY



GATE LEAKAGE CURRENT vs TEMPERATURE



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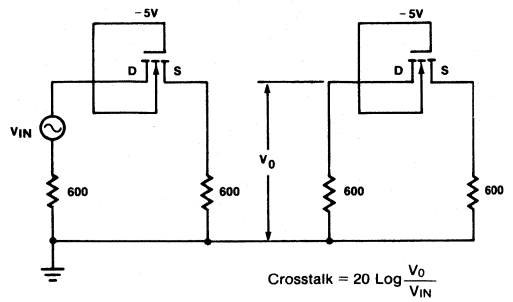
TEST CIRCUIT

CROSSTALK MEASUREMENT

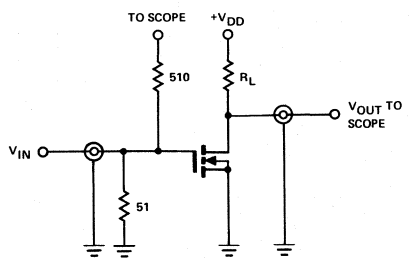
Quad Switch
SD5000/SD5001/SD5002



$$\text{Crosstalk} = 20 \text{ Log} \frac{V_0}{V_{IN}}$$

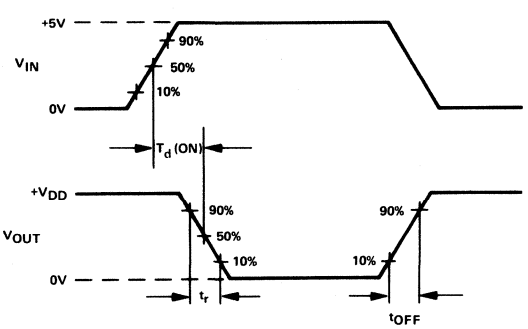
Where V_{IN} = 1V RMS at 3kHz

SWITCHING TEST CIRCUIT



Input Pulse	Sampling Scope
t_r, t_F < 1ns	t_r < 350ps
Pulse Width = 100ns	R_{IN} = 1MΩ
Rep Rate = 1MHz	C_{IN} = 2.0pF

SWITCHING WAVEFORMS



SWITCHING CHARACTERISTICS

		t_d (ON) (ns)		t_r (ns)		t_{OFF} (ns)*	
V_{DD}	R_L	TYP	MAX	TYP	MAX	TYP	MAX
5	680	0.6	1.0	0.7	1.0	9.0	
10	680	0.7		0.8		9.0	
15	1k	0.9		1.0		14.0	

*t_{OFF} is dependent on R_L and C_L and does not depend on the device characteristics.

DESCRIPTION

The SD5301/SD5302 D-MOS 8X2 Switching Arrays are monolithic chips consisting of 16 D-MOS enhancement mode transistors arranged in an 8X2 switching matrix. Control is included on the chip to provide a complete switching subsystem which has minimum pinout and is easily expandable to larger arrays.

FEATURES

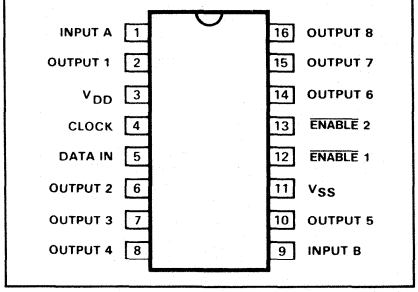
- **Excellent bilateral transmission specifications**
- **Useful in unbalanced or balanced networks**
- **On chip control and decoding**
- **Easy adaptation to microcomputer control**
- **Serial control input, independent of signal paths**
- **No latch-up from spurious signals on signal paths**
- **Easy system design for cost reduction as switch array density increases**
- **Easy expansion to larger systems with minimum external components**
- **Single supply operation**
- **Open collector TTL and C-MOS compatible inputs**
- **Encoded chip select**

APPLICATIONS

- **PABX/Key switching networks**
- **Video switching**
- **Analog signal routing/multiplexing**
- **Digital routing**

PIN CONFIGURATION

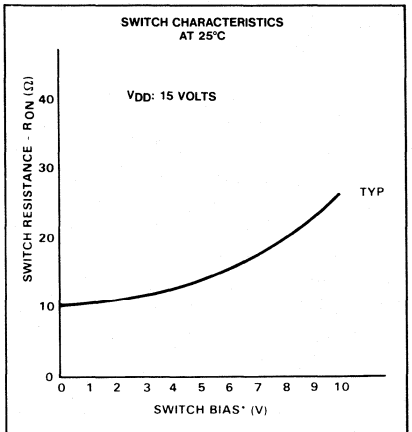
PACKAGE



ABSOLUTE MAXIMUM RATINGS

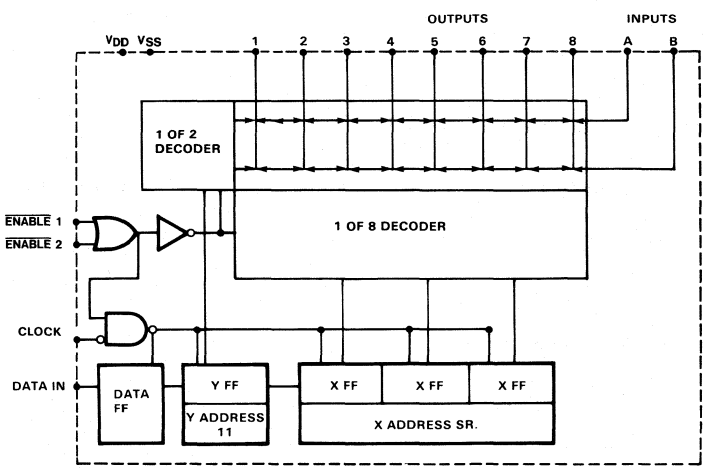
	PARAMETER	RATING	UNIT
T_A	Operating ambient temperature	0 to +70	°C
t_{stg}	Storage temperature	−65 to +150	°C
P_D	Package dissipation		
	At T_A = 25°C	640 max	mW
	Above 25°C	Derate at 5.1	mW/°C
T_J	Junction temperature	150	°C
	V_{DD}, data, clock and enable voltages with respect to V_{SS}	−0.3 to +16.0	V

TYPICAL PERFORMANCE CHARACTERISTICS



*Switch bias determines the On resistance (R_{ON}) of a particular switch, i.e. if switch A• 4 was On and input A & Output 4 = 5V, then R_{ON} = 14Ω typ

BLOCK DIAGRAM



15

DC ELECTRICAL CHARACTERISTICS[1]

TA = 25°C, V_{DD} = 15Vdc ±5%, V_{SS} = 0Vdc unless otherwise specified

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
R_{ON}	Switch on resistance[2]	V_{DD} = 15V, V_{AB} = V_{1-8} = 1.8 Vdc, I_D = 1mA				Ω
		T_A = 25°C	7	11	15	
	SD5301	T_A = 0°C to 70°C	5		20	
		V_{DD} = 10V, T_A = 25°C		18		
R_{ON}	Switch on resistance	V_{DD} = 15V, V_{AB} = V_{1-8} = 1.8 Vdc, I_D = 1mA				Ω
		T_A = 25°C	7		30	
	SD5302	T_A = 0°C to 70°C	5		40	
		V_{DD} = 10V, T_A = 25°C				
I_{DD}	Supply current			4	7	mA
	Input leakage	V_{IN} = 5V				μA
I_Φ	Clock			.001	1	
I_D	Data			.001	1	
I_E	$\overline{\text{Enable}}$ 1 and $\overline{\text{Enable}}$ 2			.001	1	
	Switch leakage					μA
I_{1-8}	1-8 outputs	V_{1-8} = 4.5Vdc, V_{AB} = 1.5Vdc		.01	1	
I_{AB}	A,B inputs	V_{AB} = 4.5Vdc, V_{1-8} = 1.5Vdc		.1	1	
	Capacitance					pF
C_Φ	Clock			3.5		
C_D	Data	Inputs = 0Vdc, f = 1MHz		4.5		
C_E	$\overline{\text{Enable}}$ 1 and $\overline{\text{Enable}}$ 2			3.0		
C_A,C_B	A,B inputs	V_{DD} = V_{SS} = 0Vdc, V_A = V_B = 2.5Vdc		150		
C_1-C_8	1-8 outputs	V_{1-8} = 2.5Vdc, f = 1MHz		8		
	Input voltage	All digital inputs				V
V_{IL}	Low		−0.3		0.8	
V_{IH}	High		5.0		15.0	

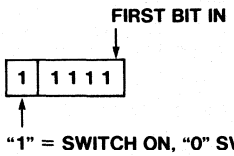
AC ELECTRICAL CHARACTERISTICS[1]

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
CT	Crosstalk	See Figure 1		−105	−90	dB
I_O	Off isolation	See Figure 2		−105	−90	dB
f	Clock frequency	Clock voltage = 0Vdc when f = 0Hz	0	2.0	1.0	MHz
T_{LG}	Lag time	See Figure 3				ns
	Data and enable (5)		100			
	Lead time	See Figure 3				ns
T_{LD1}	Data and enable (5)		400			
T_{LD2}			150			
T_W	Write time	See Figure 3		2.0	3.0	μs
Φ_{PW}	Clock pulse width	Measured at 3.0Vdc level	0.4		100	μs
		t_{rise} = t_{fall} ≤ 500 ns				

NOTES
1. These specs apply to both the SD5301 and SD5302 except where separately specified.
2. ΔR_{ON} for the crosspoints of a single SD5301 is typically ±2Ω.

	1	2	3	4	5	6	7	8
INPUT A	1 1 1 1	1 0 1 1	1 1 0 1	1 0 0 1	1 1 1 0	1 0 1 0	1 1 0 0	1 0 0 0
INPUT B	0 1 1 1	0 0 1 1	0 1 0 1	0 0 0 1	0 1 1 0	0 0 1 0	0 1 0 0	0 0 0 0

EXAMPLE:



"1" = SWITCH ON, "0" SWITCH OFF

Table 1 SD5301/SD5302 SWITCHING CODES

CROSSTALK MEASUREMENTS

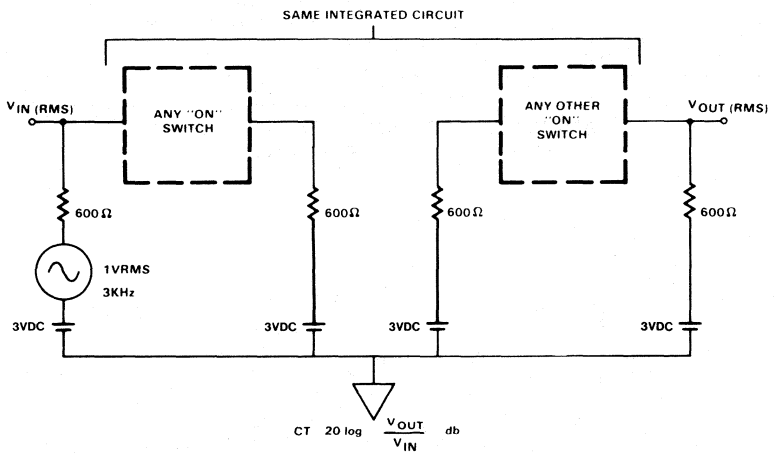


Figure 1

OFF ISOLATION MEASUREMENT

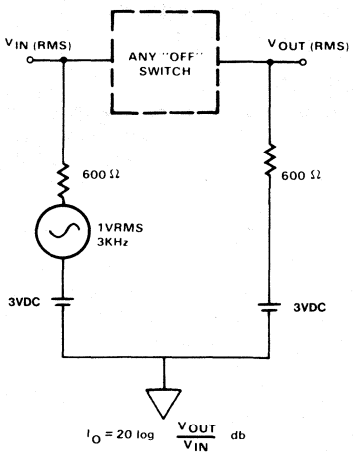


Figure 2

TIMING DIAGRAM

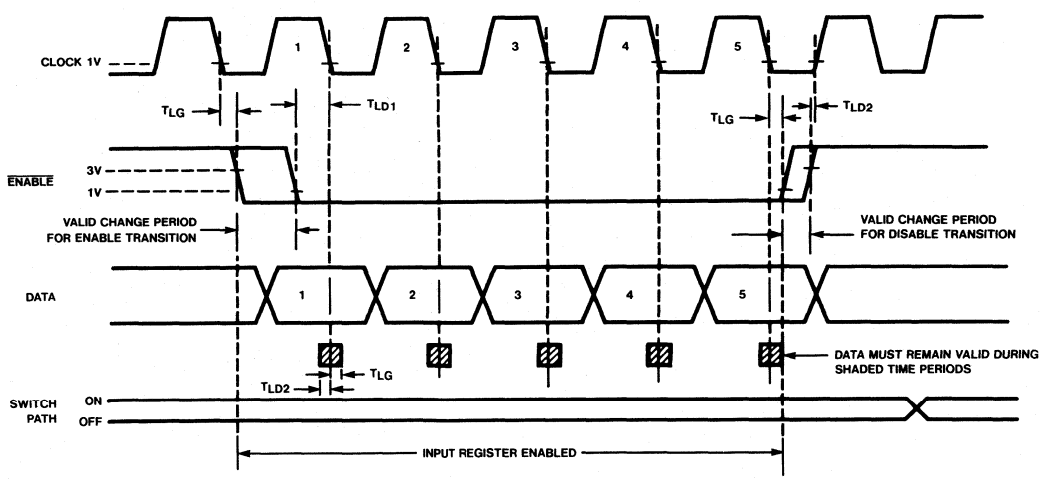


Figure 3

THEORY OF OPERATION

The 8x2 array consists of 16 switches. Each switch consists of one low impedance D-MOS transistor and a gated flip-flop to maintain the required On or Off state.

To establish the status of any switch, the enable inputs for the 8x2 array must be selected as shown in Figure 3. This disables the decoder preventing accidental changing of voice paths and simultaneously enables the clock input for this array. With the circuit enabled, 5 bits of serial data are fed into the data/address pin. The first 4 bits are decoded to select one of the 16 switches. The selected switch will be turned on or off by the fifth bit. At this point, the circuit is disabled and the decoders are enabled. The switch will be updated within 3.0μs after the enable line has been disabled. The device is now ready to accept new data

APPLICATIONS

A typical PABX interface network is shown in Figure 4. This configuration is unbalanced. A balanced configuration can be made by tying the control lines of two SD5301s in parallel which allows a simple control of the balanced switch.

The SD5301 may be used in a variety of digital/analog routing and multiplexing applications. Application examples are shown in Figure 5 and Figure 6.

NOTE
All references to SD5301 in the text also apply to the SD5302.

PABX APPLICATION

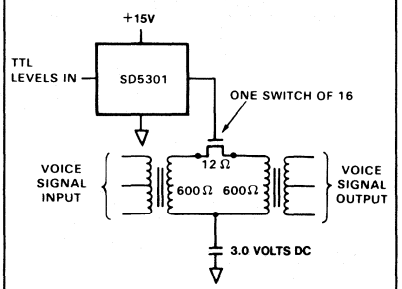
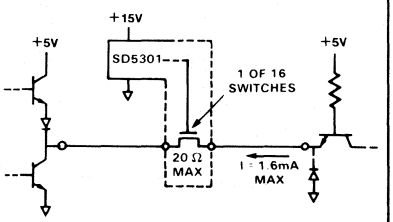


Figure 4

DIGITAL ROUTING/
MULTIPLEXING APPLICATION



Maximum voltage drop across
SD5301 switch is 20 Ω x 1.6mA = 32mV

Figure 5

VARIABLE GAIN CONTROL CIRCUIT EMPLOYING
ONE SD5301 AND ONE MC1458

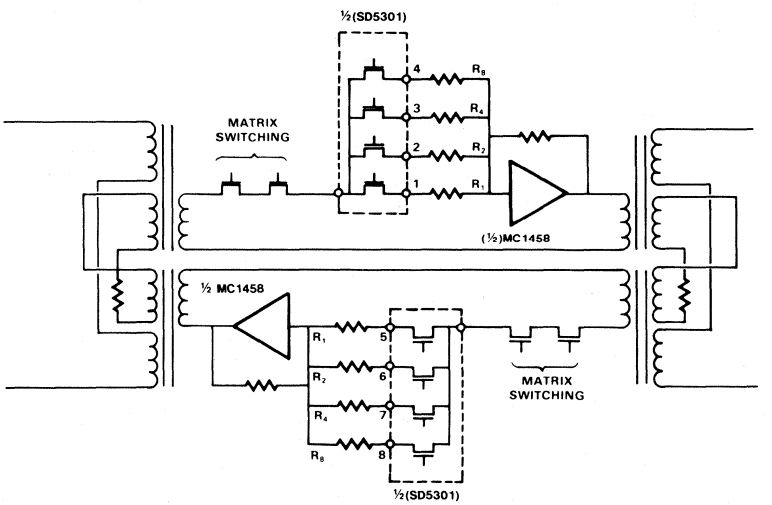


Figure 6

SECTION 16
NEW PRODUCTS

Section 16—NEW PRODUCTS

NOTE

*Any product listed in this section but not incorporated within the text may be obtained by writing Information Services at Signetics, 811 E. Arques, M/S 027, Sunnyvale, California 94086, or by calling (408) 746-1682.

DESCRIPTION

The 5034 is an 8-bit resolution analog-to-digital converter. The 5034 contains all of the elements comprising a true 8-bit accuracy analog-to-digital converter on one monolithic chip. These elements include the logic, voltage reference, comparator, clock, and output buffers. The output buffers are microprocessor addressable for three-state bus compatibility.

The 5034 achieves fast conversion time (17 microseconds, Typ) using a single external capacitor to set the internal clock frequency. Faster conversion times are possible using an external clock.

FEATURES

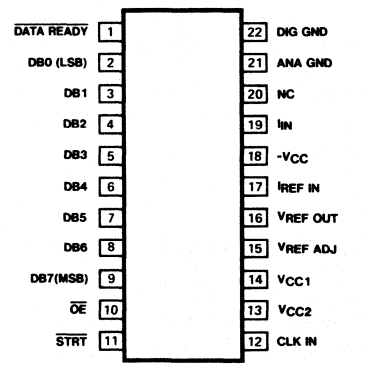
- **8-bit resolution and accuracy**
- **Microprocessor compatible logic**
- **Internal clock with external override for higher speed**
- **No missing codes over full operating temperature range**

APPLICATIONS

- **A/D converters in microprocessor based systems**
- **High speed A/D systems**
- **Ratiometric A/D conversion**
- **Automated process controls**
- **Low cost A/D systems**

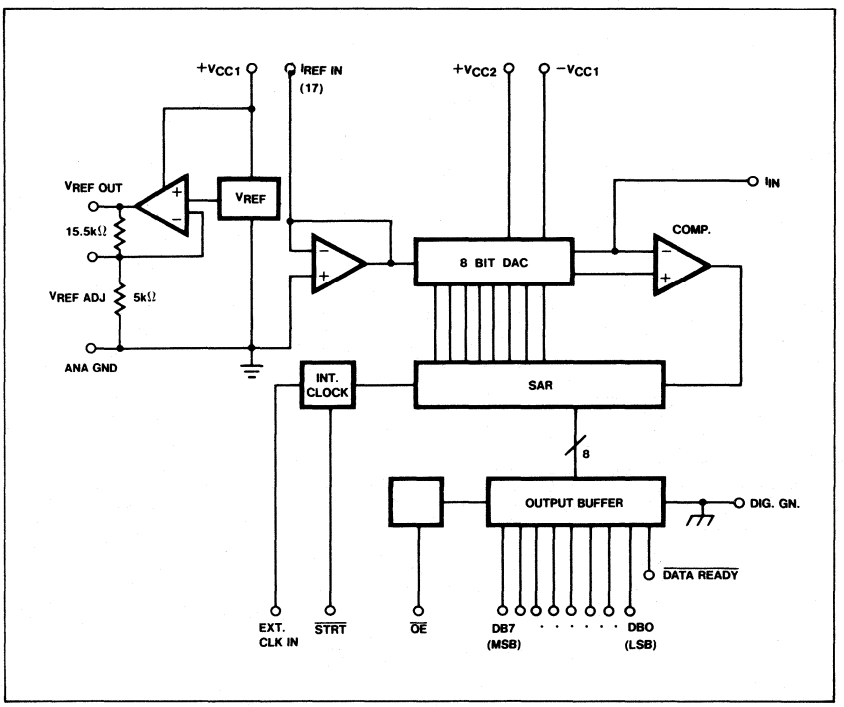
PIN CONFIGURATION

F,N PACKAGE



NE 5034 N Plastic DIP Package
NE 5034 F Ceramic DIP Package

BLOCK DIAGRAM



OBJECTIVE SPECIFICATION
March 1979

DESCRIPTION

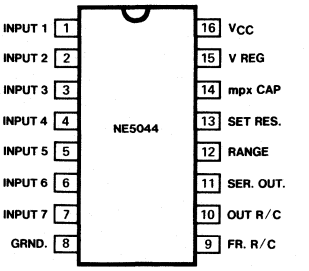
The NE5044 is a programmable parallel input, serial output pulsewidth encoder. A multiplexed dual linear ramp technique is used to allow up to 7 inputs to be converted to a serial pulsewidth modulated signal with excellent linearity and minimal crosstalk. Fixed or variable frame rate can be used, externally controlled, for ease of demodulation.

Features

- **3 to 7 channels, externally selectable**
- **Constant current dual linear ramp for linearity better than .5%**
- **Internal voltage regulator for low drift**
- **Wide supply range 6 – 16V**
- **Fixed or variable frame rate set by external R-C**
- **External control for channel gain or range**
- **Versatile applications; exponential rates, mixing, dual rate, reversing etc.**
- **Minimum external components**

PIN CONFIGURATION

N PACKAGE

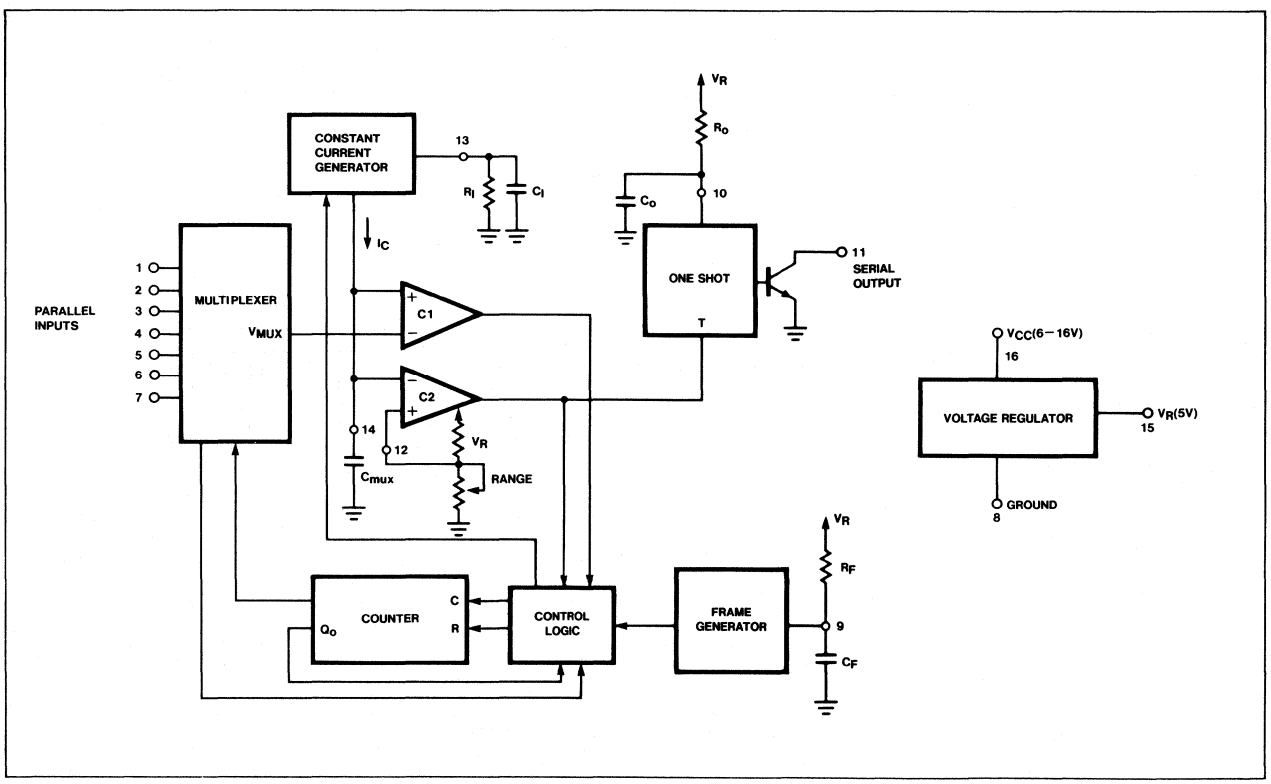


ORDER NE5044N
7 CHANNEL ENCODER

ELECTRICAL CHARACTERISTICS

PARAMETERS	LIMITS
Supply voltage range	6 -16V
Supply current	15mA
Input bias current	<200nA
Power supply rejection	0.01%/V
Pulsewidth tempco	0.01%/°C
Crosstalk	<2μS
Linearity error	<2μS
Output drive current	25mA
Regulator output voltage	5V
Regulator output current	25mA
Regulator voltage drop	1.2V
Operating temperature	−20 to +75°C
Storage temperature	−65 to +150°C

BLOCK DIAGRAM



OBJECTIVE SPECIFICATION
March 1979

DESCRIPTION

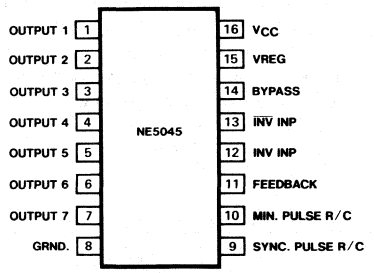
The NE5045 is a serial input, parallel output, decoder intended for applications in pulse width or pulse position modulation systems. The serial input is amplified and shaped before being fed to the counter/decoder. An integrating type sync. separator detects pulses greater than $T_W = R_S C_S$ to reset the counter. An internal voltage regulator supplies power for the radio receiver providing excellent isolation from the power supply as well as the decoder logic.

FEATURES

- **Up to 7 channels**
- **High gain op amp input**
- **Sync separator time constant set externally, $T = R_S C_S$**
- **Voltage regulator for receiver**
- **Wide supply voltage range 3.6V to 8V**
- **Low power dissipation**
- **Minimum external components**
- **Positive or negative inputs**
- **Noise spike flutter rejection**
- **Outputs reset to zero without input**

PIN CONFIGURATION

N PACKAGE

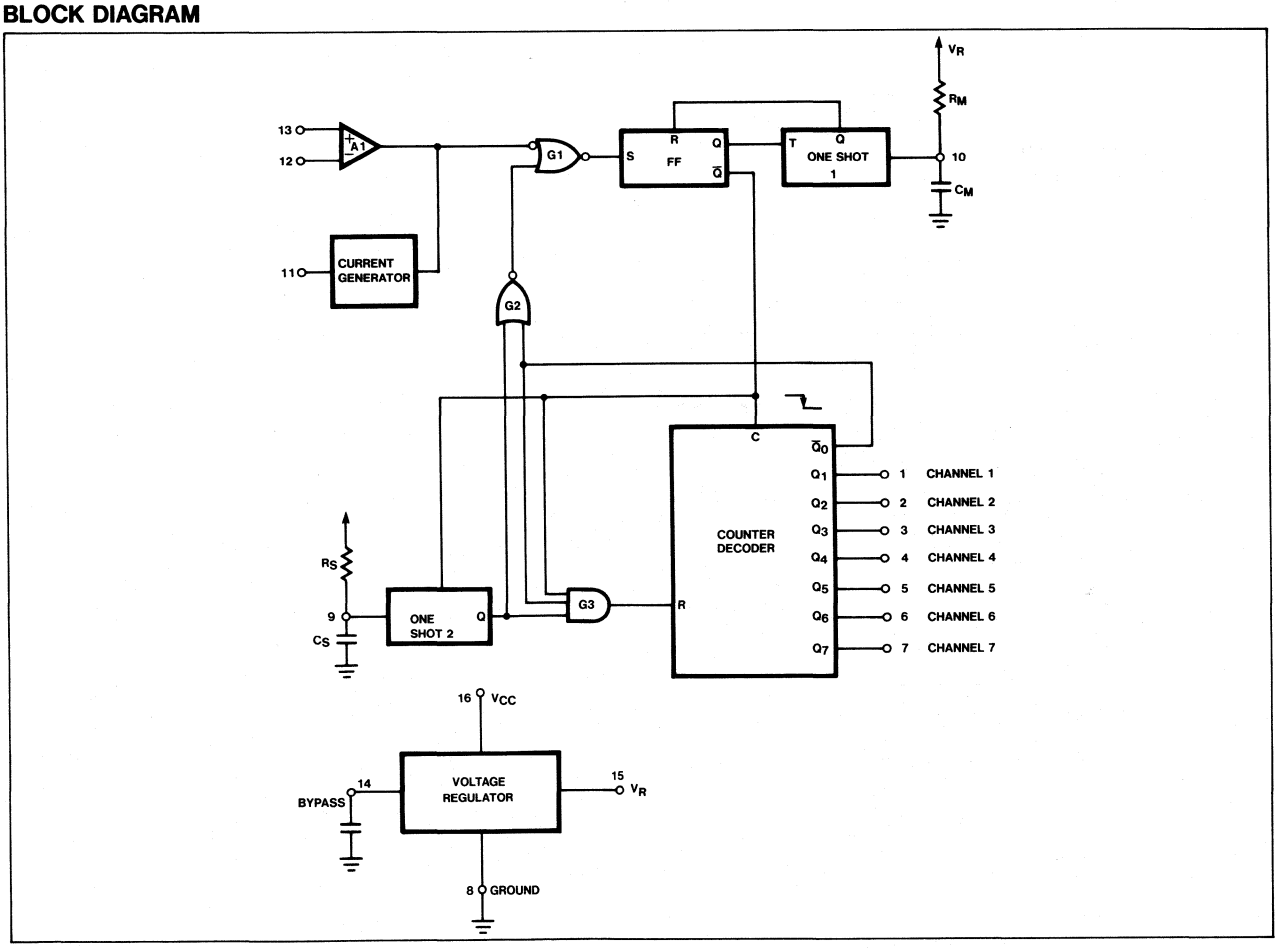


ORDER NE5045N
7 CHANNEL DECODER

ELECTRICAL CHARACTERISTICS

PARAMETERS	LIMITS
Supply voltage range	3.6 −8V
Supply current	10mA
Regulator output voltage	4.1V ($V_{CC} > 5V$), V_{CC} −0.9V ($V_{CC} < 5V$)
Regulator output current	25mA
Output drive current	2mA

BLOCK DIAGRAM



OBJECTIVE SPECIFICATION
March 1979

DESCRIPTION

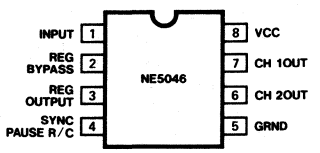
The NE5046 is a serial input parallel output decoder designed for 2 channel digital proportional pulse width or pulse position modulation systems. In a typical application, the serial input from the receiver is processed through an amplifier and pulse shaper and then converted to parallel output with a shift register. An internal sync separator detects the sync pause and clears the shift register.

FEATURES

- **High Gain input amplifier**
- **Minimum external components, low cost applications**
- **Space saving 8 pin mini dip package**
- **Low power consumption**
- **Adjustable sync separator timing**
- **Pulse shaper with hysteresis for high noise immunity**
- **Outputs reset to zero without input**

PIN CONFIGURATION

N PACKAGE

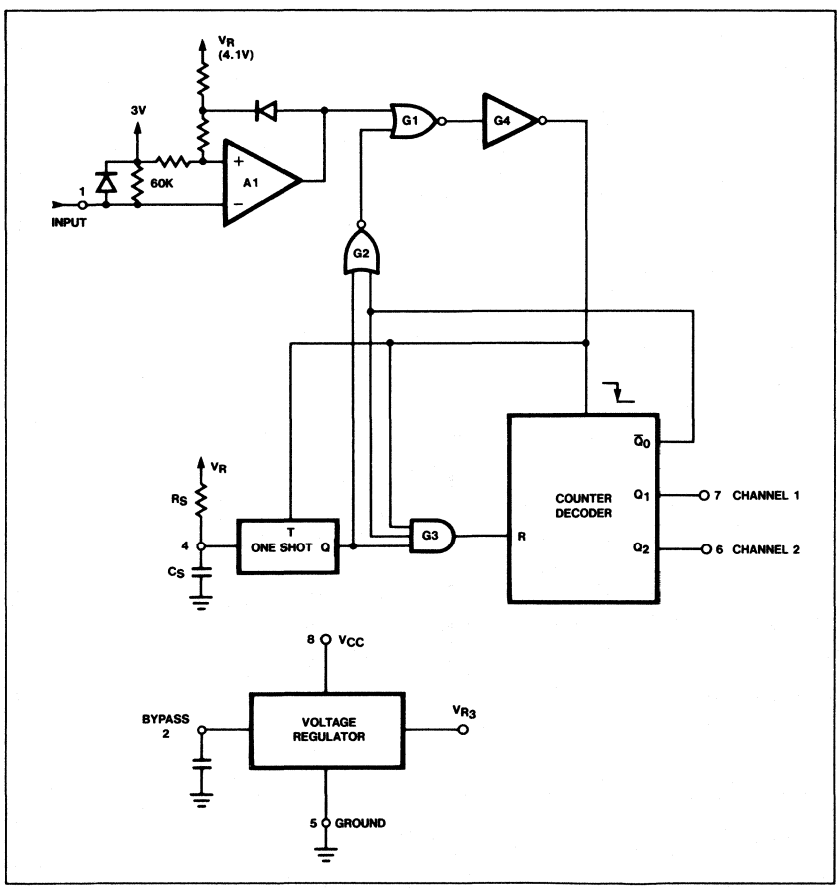


ORDER NE5046N
2 CHANNEL DECODER

ELECTRICAL CHARACTERISTICS

PARAMETERS	LIMITS
Supply voltage range	3.6 to 8 volt
Supply current	6mA
Input Impedance	>50kΩ
Output drive current	2mA
Regulator output voltage	4.1V (V_{CC} > 5V), V_{CC} −0.9V (V_{CC} < 5V)
Regulator output current	20mA

BLOCK DIAGRAM



PRELIMINARY SPECIFICATION N,FE,F,H

DESCRIPTION

The 5512/5514 series of high performance operational amplifier provides very good input characteristics coupled with single power supply operation. These amplifiers feature low input bias and voltage characteristics such as a 108 op amp with improved CMRR and a high differential input voltage limit achieved through the use of a bias cancellation and PNP input circuits with collector to emitter clamping. The output characteristics are like those of a 741 op amp with improved slew rate and drive capability yet have low supply quiescent current.

	5512	5514
Pin out	MC1458 TL072	LM324 TL074
Configuration	Dual	Quad

FEATURES

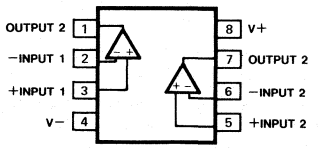
- Low input bias $< \pm 1$nA
- Low input offset current $< \pm .5$nA
- Low input offset voltage $<$ 1mV
- Low V_{OS} temperature drift 3μV/°C
- Low input bias temperature drift 10pA/°C
- Low input current noise 0.1pA$\sqrt{Hz}$
- Low input voltage noise 10nV/$\sqrt{Hz}$
- Low supply current 1mA/amp
- High slew rate 1.2V/μs
- High CMRR 110dB
- High input impedance 100MΩ
- High common mode impedance 10GΩ
- High PSRR 110dB
- High differential input voltage limit
- No cross-over distortion
- Indefinite output short circuit protection
- Single supply operation

APPLICATIONS

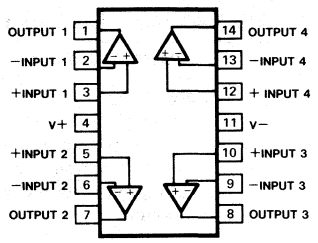
- AC amplifiers
- RC active filters
- Transducer amplifiers
- DC gain block
- 5V dc power supply operation
- Battery operation
- Instrumentation application
- Low noise, low power audio PRE amps

PIN CONFIGURATIONS

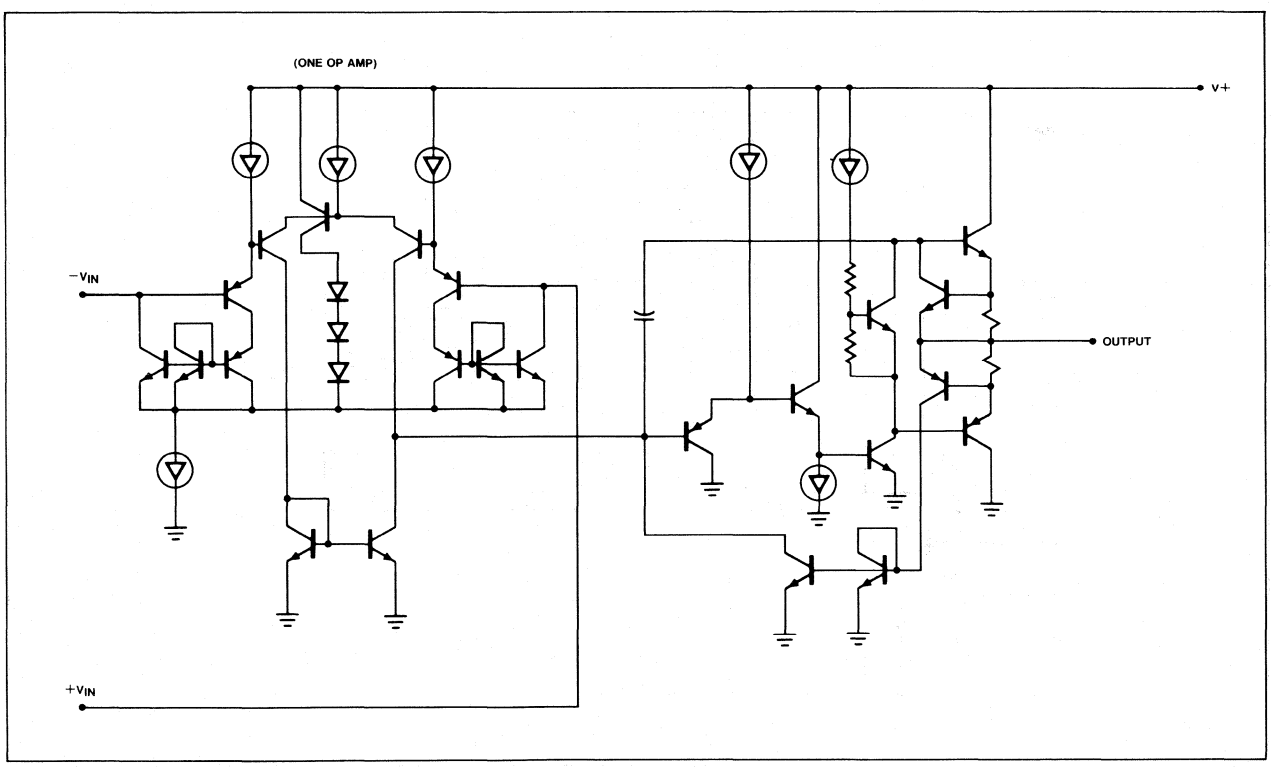
N,FE,H PACKAGE



N,F PACKAGE



EQUIVALENT SCHEMATIC



DESCRIPTION

The Signetics NE5539 is a very wide bandwidth, high slew rate, monolithic operational amplifier for use in video amplifiers, RF amplifiers, and extremely high slew rate amplifiers.

Emitter follower inputs provide a true differential high input impedance device. Proper external compensation will allow the designation to operate over a wide range of closed loop gains, both inverting and non-inverting, to meet specific design requirements.

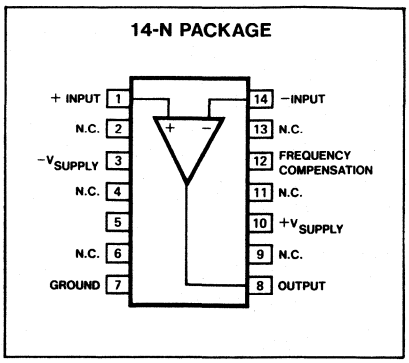
FEATURES

- **Gain bandwidth product: 1.2GHz**
- **Slew rate: 600V/μsec**
- **Full power response: 48MHz**
- **A_{VOL}: 50dB**

APPLICATIONS

- **Fast pulse amplifiers**
- **RF oscillators**
- **Fast sample and hold**
- **High gain video amplifiers (BW > 20MHz)**

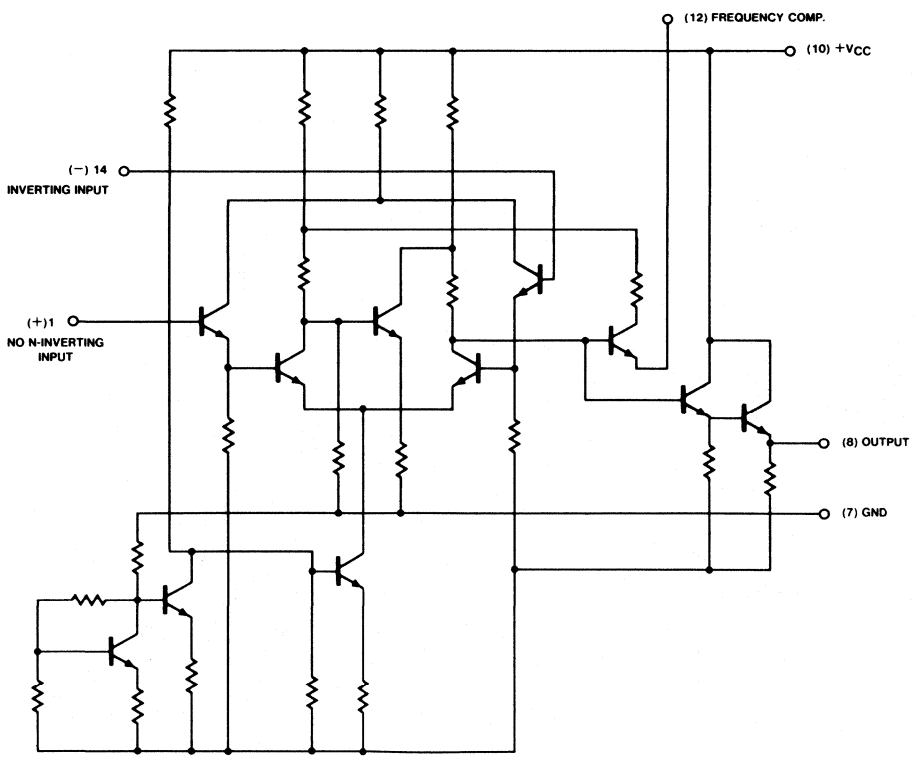
PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS

	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	±12	V
P_D	Internal power dissipation	550	mW
T_{STG}	Storage temperature range	−65 to +150	°C
T_J	Max junction temperature	150	°C
T_A	Operating temperature range	0 to +70	°C
	Lead temperature	300	°C

EQUIVALENT CIRCUIT



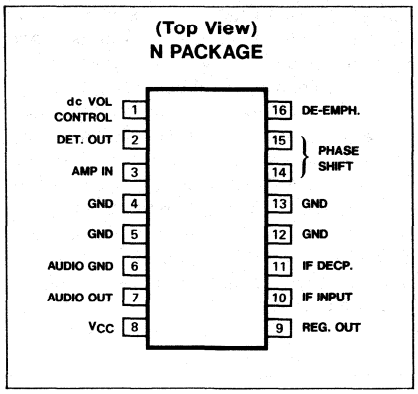
DESCRIPTION

Ideally suited for use in small-screen TV or mobile F-M radios, the ULN-2212B is a complete 1-watt sound channel. It operates from a single 14V supply and provides $V_{CC}/2$ output tracking as well as greater than 20dB of ripple rejection. This I.C. will directly drive an 8 or 16 ohm speaker. It has a true 1 watt output into the 8 ohm load.

FEATURES

- **Low limiting threshold**
- **Low external parts count**
- **High A-M rejection**
- **Single-adjustment tuning**
- **70dB limiter gain**
- **70dB DC volume control range**
- **Automatic thermal shutdown**
- **Output current limiting**
- **10V to 18V operating range**
- **>20dB ripple rejection**

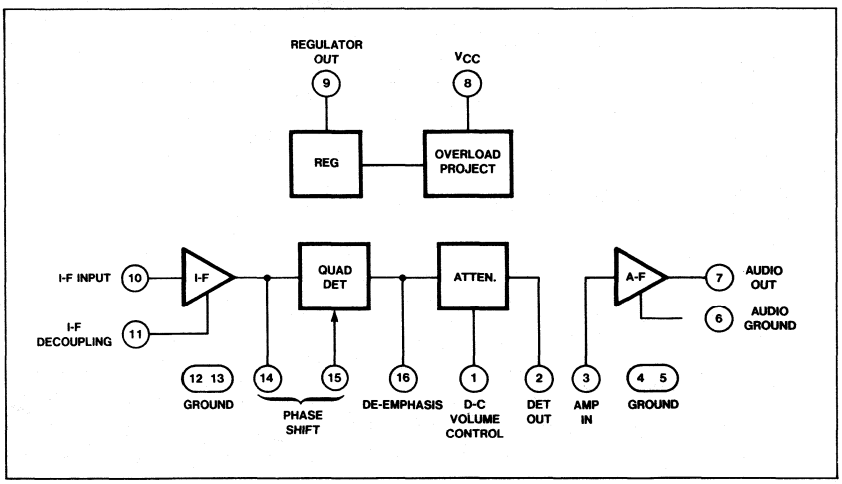
PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
Supply voltage, V_{CC}	+18	V
Regulator output current, I_{REG}	10	mA
Input voltage (pin 10), V_{IN}	+4.0	V
Operating temperature range, T_A	40°C to +85	°C
Storage temperature range, T_S	65° to +150	°C

BLOCK DIAGRAM



DESCRIPTION

The Signetics ST100 is a monolithic μ255 law companded PCM Codec. This is a per channel device fabricated in I^2L technology. The ST100 has all the circuitry necessary to convert an analog signal into an 8 bit PCM digital data stream and vice versa. Asynchronous operation of transmit and receive is possible. A & B signaling and zero code suppression are also provided. Very few external components are required for its operation. The digital inputs are TTL compatible while the digital outputs are open collector, TTL compatible.

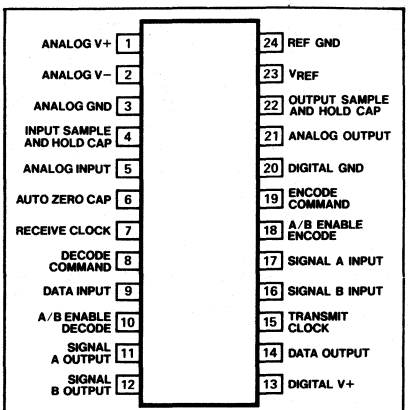
FEATURES

- **μ255 law companding**
- **Serial data rates up to 2.048MHz**
- **Sampling rates up to 16kHz**
- **Asynchronous operation of transmit and receive**
- **A & B dual channel signaling**
- **Zero code suppression**
- **Low noise**
- **Fabricated with proven, reliable bipolar process**
- **100% burned in**

APPLICATIONS

- **PCM channel banks**
- **EPABX's**
- **Subscriber loop carrier systems**
- **Central office switches**

PIN CONFIGURATION



NOTE
Available in plastic, cer-dip and ceramic packages.

ORDERING CODE

PACKAGES	COMMERCIAL RANGES T_A=0°C to 70°C
Plastic	ST100CN
Cer-dip	ST100CF
Ceramic	ST100CI

NOTE
For more information, contact your nearest Signetics sales office, representative, or franchised distributor.

BLOCK DIAGRAM

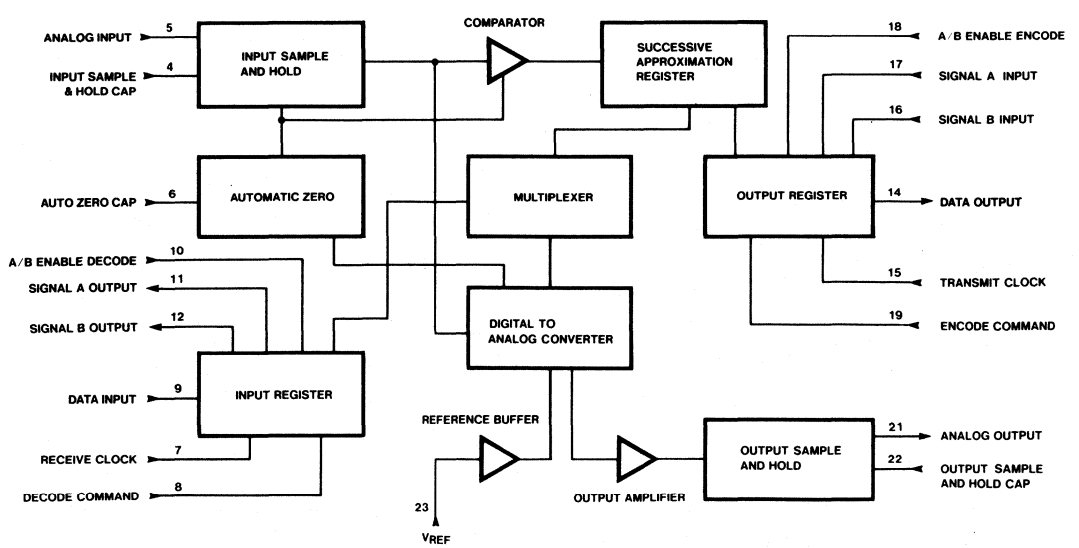


Figure 1

DESCRIPTION

The Signetics SD224 is a POWER MOSFET of the N-channel enhancement mode type designed for switching applications requiring high current, high speed, low "ON" resistance and excellent node-to-node isolation. Superior performance is achieved by utilizing the Signetics D-MOS process which provides high gain, low drain-to-source "ON" resistance, low inter-electrode capacitance and enhanced high frequency operation.

The SD224 is designed to switch analog signals up to ±7.5 volts. The device is hermetically sealed in a TO-12 package allowing each of the four electrodes to be biased independently.

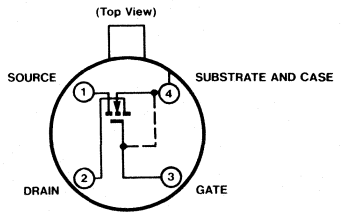
FEATURES

- **Low node capacitances**
- **Low feedthrough and feedback transients**
- **Excellent isolation input to output**
- **CMOS logic compatible input**
- **Extremely low drive power**
- **Switches 1A in less than 5ns**

APPLICATIONS

- **Switch driver**
- **Analog switch**
- **Digital switch**
- **Sample and hold**
- **Multiplexers**
- **A/D converters**
- **D/A converters**

PIN CONFIGURATION



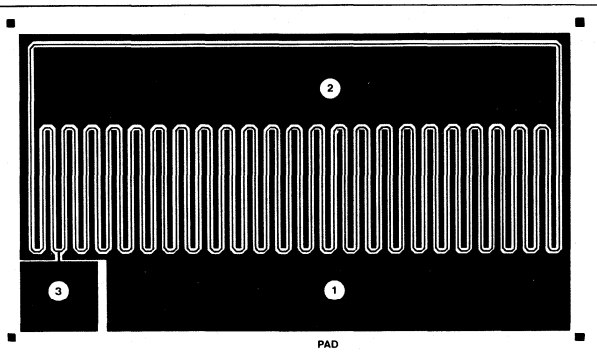
ORDER PART NO
SD224H

ABSOLUTE MAXIMUM RATINGS[1] T_A = +25°C unless otherwise specified

PARAMETER		RATING	UNIT
V_{DS}	Drain-to-source	+25	V
V_{SD}	Source-to-drain[2]	+15	V
V_{DB}	Drain-to-body	−0.3, +20	V
V_{SB}	Source-to-body	−0.3, +20	V
V_{GS}	Gate-to-source	±30	V
V_{GD}	Gate-to-drain	±30	V
V_{GB}	Gate-to-body	±30	V
I_D (ON)	Continuous drain current	2	A
I_D(ON)	Pulsed drain current	3	A
P_D	Power dissipation		
	T_A = +25°C[3]	1	W
	T_C = +25°C[4]	5	W
	Power derating factors		
	Free air	8	mW/°C
	Infinite heat sink	40	mW/°C
Θ_{JA}	Thermal resistance	125	°C/W
Θ_{JC}	Thermal resistance	25	°C/W
T_{op}	Operating temperature	−55 to +125	°C
T_{stg}	Storage temperature	−55 to +150	°C

NOTES
1. Absolute maximum ratings are limiting values above which serviceability may be impaired.
2. See test conditions in dc electrical characteristics section.
3. Free air.
4. Infinite heat sink.

CHIP DIAGRAM



PAD NO.	PAD FUNCTION
1	SOURCE
2	DRAIN
3	GATE

SECTION 17
APPENDICES

MILITARY

MILITARY PRODUCTS/ PROCESS LEVELS

The Signetics MIL 38510/883 Program is organized to provide a broad selection of processing options, structured around the most commonly requested customer flows. The program is designed to provide our customers:

- Fully compliant 883 flows on all products.
- Standard processing flows to help minimize the need for custom specs.
- Cost savings realized by using standard processing flows in lieu of custom flows.
- Better delivery lead times by minimizing spec negotiation time, plus allows customer to buy product off-the-shelf or in various stages of production rather than waiting for devices started specifically to custom specs.

The following explains the different processing options available to you. Special device marking clearly distinguishes the type of screening performed. Refer to Tables 2, 3, 4 and 5.

JAN CASE OUTLINE AND LEAD FINISH	SIGNETICS MILITARY PACKAGE TYPES				
			DUAL-IN-LINE		
	8-PIN	10-PIN	14-PIN	16-PIN	24-PIN
CB	—	—	F	—	—
EB	—	—	—	F	—
JB	—	—	—	—	F
DB	—	—	W	—	—
FB	—	—	—	W	—
ZC	—	—	—	—	Q
GC	T	—	—	—	—
IC	—	K	—	—	—

All products listed are also available in Die form.

Table 1 MILITARY PACKAGE AVAILABILITY

	JB	RB	RC
	Jan Qualified	883B	883C
54/54H	X	X	X
54LS	X	X	X
54S	X	X	X
82/8T	X	X	X
93XX	X	X	X
96XX	—	X	X
Linear	X	X	X
Bipolar Memory	X	X	X
Microprocessor	—	X	X

Table 2 MILITARY SUMMARY

JAN QUALIFIED (JB)

JAN Qualified product is designed to give you the optimum in quality and reliability. The JAN processing level is offered as the result of the government's product standardization programs, and is monitored by the Defense Electronic Supply Center (DESC), through the use of industry-wide procedures and specifications.

JAN Qualified products are manufactured, processed and tested in a government certified facility to Mil-M 38510, and appropriate device slash sheet specifications. Design documentation, lot sampling plans, electrical test data and qualification data for each specific part type has been approved by the Defense Electronic Supply Center (DESC) and products appear on the DESC Qualified Products List (QPL-38510).

Group B testing, per Mil-Std-883 Method 5005, is performed on each six weeks of production on each slash sheet for each package type. Group C, per Mil-Std-883 Method 5005, is performed every ninety days for each microcircuit group. Group D testing, per Mil-Std-883 Method 5005, is performed every six months for each package type.

In addition to the common specs used throughout the industry for processing and testing, JAN Qualified products also possess a requirement for a standard marking used throughout the IC industry.

MIL-STD-883, LEVEL B

Processing to this option is ideal when no JAN slash sheets are released on devices required. Product is processed to Mil-Std-883 Method 5004, and is 100% electrically tested to industry data sheets. Devices are selectively available as custom processed parts with electricals screened to the JAN Slash Sheets.

MIL-STD-883, LEVEL C

If you need a Military temp, range device, but do not require burn in screening performed, our 883C product is ideal. 883C parts are the standard full Mil-Temperature range product to the Signetics data sheet parameters and screened to MIL-STD-883, Class C.

MILITARY GENERIC DATA

Signetics has a new program for those customers who require quality conformance data on their products. This program allows our customers to obtain reliability information without the necessity or running Groups B, C and D inspections for their particular purchase order. It provides for the customer something that has not been readily available before in the semiconductor industry in that all Military Generic Data is controlled and audited by both Government Inspection in the case of JAN data and Signetics Quality Assurance.

Signetics Military Generic Data is compiled by the Military Products Division based on data from 1) JAN quality conformance lots, and 2) Data generated by quality conformance lots run for other reliability programs. Refer to Table 4.

A Military Generic family is defined as consisting of die function and package type families.

Military Generic Data

- Allows our customers to qualify Signetics products based on existing quality conformance data performed at Signetics.
- Allows our customers to reduce costs and improve deliveries.
- Provides assurance that all Signetics die function families and packages meet Mil-M-38510 and customer reliability requirements.
- Provides an attributes summary to the customer backed by lot identity and traceability.

PROCESS LEVEL AND MARKETING	PRE-CAP VISUAL	BURN IN	FUNCTIONAL TEST	DC/AC @25°C	DC/AC @TEMP	QPL	OFFSHORE
JB JM38510XXXXX	2010, Cond. B	Yes	100%	100%	100%	Yes	No
RB SXXXX883B	2010, Cond.B	Yes	100%	100%	100%	No	Yes
RC SXXXX883C	2010, Cond. B	No	100%	100% dc Sample ac	Sample dc only	No	Yes

Table 3 MILITARY PRODUCTS PROCESSING MATRIX

QUALIFIED SUB-GROUPS	QUALIFIES	OPTION 1	OPTION 2
A*	Electrical Test		
B	Package—Same package construction and lead finish.	Data selected from devices manufactured within 6 weeks of the manufacturing period on the same production line through final seal.	Data selected from devices manufactured within 24 weeks of manufacturing period.
C	Die/Process—Devices representing the same process families.	Data selected from representative devices from the same microcircuit group and sealed within 12 weeks of the manufacturing period.	Data selected from the representative devices from the same microcircuit group and sealed within 48 weeks of the manufacturing period.
D	Package—Same package construction and lead finish.	Data selected from the devices representing the same package construction and lead finish manufactured within the 24 weeks of manufacturing period. If specific data not available, Option 2 will be supplied	Data selected from the devices representing the same package construction and lead finish manufactured within the 52 weeks of manufacturing period.

NOTE*
Group A is performed on each lot or sublot of Signetics devices.

Table 4 DEFINITION AND QUALIFYING MANUFACTURING PERIODS FOR GENERIC DATA

DESCRIPTION OF REQUIREMENTS AND SCREENS	MIL-M-38510 AND MIL-STD-883 REQUIREMENTS, METHDS AND TEST CONDITIONS	REQUIREMENT	PROCESSING LEVELS			
			CLASS S	JAN QUALIFIED (JB)	883B (RB)	883C (RC)
General Mil-M-38510 1. Pre-Certification A. Product Assurance Program Plan B. Manufacturer's Certification	The Manufacturer shall establish and implement a Products Assurance Program Plan and provide for a manufacturer survey by the qualifying activity, Para. 3.4.1.1	—	X	X	N/A	N/A
2. Certification	Received after manufacturer has completed a successful survey, Para. 3.4.1.2	—	X	X	N/A	N/A
3. Device Qualification	Device qualification shall consist of subjecting the desired device to groups A, B, C & D of method 5005 to tightened LTPD, Para. 3.4.1.2	—	X	X	N/A	N/A
4. Traceability	Traceability maintained back to a production lot Para. 3.4.6	—	X	X	X	X
5. Country of Origin	Devices must be manufactured, assembled, and tested within the U.S. or its territories, Para. 3.2.1	—	X	X	N/A	N/A
Screening Per Method 5004 of Mil-Std-883						
6. Internal Visual (Precap)	2010, Cond. A or B	100%	XA	XB	XB	XB
7. Stabilization Bake	1008, Cond. C Min; (24 Hrs @ 150°C)	100%	X	X	X	X
8. Temperature Cycling* *For Class B and C devices thermal shock may be substituted, 1011, Cond. A; (15 cycles, 0° to +100°C)	1010, Cond. C; (10 cycles, −65°C to +150°C)	100%	X	X	X	X
9. Constant Acceleration	2001, Cond. E; (30kg in Yl Plane)	100%	X	X	X	X
10. Visual Inspection	There is no test method for this screen; it is intended only for the removal of "Catastrophic Failures" defined as "Missing Leads, Broken Packages or Lids Off."	100%	X	X	X	X
11. Seal (Hermeticity)	1014					
A. Fine	Cond. A or B (5.0 X 10^{-8}CC/Sec)	100%	X	X	X	X
B. Gross	Cond. C2 Min.	100%	X	X	X	X
12. Interim Electricals (Pre Burn-In)	Per applicable device specification	100% Optional	100% Read & Record	Slash Sheet	Data Sheet	N/A
13. Burn-In	1015, Cond. as specified (160 hrs. Min. at 125°C)	100%	100% 240 hrs.	X	X	N/A
14. Final Electricals	Per applicable Device Specification	100%	100% Read & Record	Slash Sheet	Data Sheet	Data Sheet
A. Static Tests @ 25°C	Sub Group 1		X	X	X	X
B. Static Tests @ +125°C	Sub Group 2		X	X	X	N/A
C. Static Tests @ −55°C	Sub Group 3		X	X	X	N/A

Table 5 REQUIREMENTS AND SCREENING FLOWS FOR STANDARD PRODUCTS

DESCRIPTION OF REQUIREMENTS AND SCREENS	MIL-M-38510 AND MIL-STD-883 REQUIREMENTS, METHODS AND TEST CONDITIONS	REQUIREMENT	PROCESSING LEVELS			
			CLASS S	JAN QUALIFIED (JB)	883B (RB)	883C (RC)
D. Dynamic Test @25°C	Sub Group 4 (for Linear Product Mainly)		X	X	X	X
E. Functional Test @25°C	Sub Group 7		X	X	X	X
F. Switching Test @25°C	Sub Group 9		X	X	X	N/A
15. Percent Defective allowable (PDA)	A PDA of 10% is a normal requirement applied against the static tests @25°C (A-1). This is controlled by the slash sheets for JB products. For RB 10% is standard	10%	10% 3% Funct"l	X	X	N/A
16. Marking	Fungus Inhibiting Paint	100%	As Req'd	JM38510/ XXXX Slash Sheet #	S X X X X 883B	SXXXX 883C
17. X-Ray	2012		100%	N/A	N/A	N/A
18. External Visual	2009	100%	X	X	X	X
Quality Conformance Inspection per Method 5005 of Mil-Std 883						
19. Group A	Electrical Tests-Final Electricals (#14 above) repeated on a sample basis. (Sub Groups 1 thru 12 as specified.)	Each Lot	X	X	X	X
20. Group B	Package functional and constructional related test I.E. package dimensions, resistance to solvents, internal visual & mechanical, bond strength & solderability.	Every 6 week per pkg. group	X	X	Generic Data Available	
21. Group C	Die related tests I.E. 1,000 hr. operating life, temperature cycling, & constand acceleration.	Every 3 months per μcircuit type	X	X	Generic Data Available	
22. Group D	Package related tests I.E. physical dimensions, lead fatigue, thermal shock, temperature cycle, moisture resistance, mechanical shock, vibration variable frequency constant acceleration, & salt atmosphere.	Every 6 months per package type	X	X	Generic Data Available	

Table 5 REQUIREMENTS AND SCREENING FLOWS FOR STANDARD PRODUCTS (Cont'd)

LINEAR DEVICES

DEVICE	DESCRIPTION	PACKAGE*	
		DIP	CAN
	OPERATIONAL AMPLIFIERS		
LF155/A	JFET Op Amp		H
LF156/A	JFET Op Amp		H
LF157/A	JFET Op Amp		H
LH2101A	Dual Op Amp	F	
LM101/A	Hi Perf Op Amp	F	H
LM107	Gen Purp Op Amp	F	H
LM108/A	Precision Op Amp	F	H
LM124	Quad Op Amp	F	
LM158	Dual Op Amp		H
MC1556	Hi Perf Op Amp	F	H
MC1558	Dual Op Amp	F	H
SE530	Hi Slew Op Amp	F	H
SE532	Dual Op Amp		H
SE535	Hi Slew Op Amp	F	H
SE538	Hi Slew Op Amp	F	H
SE5530	Dual Op Amp	F	H
SE5534	Lo Noise Op Amp	F	H
SE5535	Dual Op Amp	F	H
SE5538	Dual Op Amp	F	H
μA709/A	Gen Purp Op Amp	F	H
μA741	Gen Purp Op Amp	F	H
μA747	Dual Op Amp	F	H
μA748	Gen Purp Op Amp	F	H
	COMPARATORS		
SE521	Dual Differential Comparator	F	
SE522	Dual Differential Comparator	F	
SE527	Voltage Comparator	F	H
SE529	Voltage Comparator	F	H
LH2111	Dual Voltage Comparator	F	
LM111	Voltage Comparator	F	H
LM139/A	Quad Voltage Comparator	F	
LM193/A	Dual Voltage Comparator		H
μA710	Voltage Comparator	F	H
μA711	Dual Voltage Comparator	F	H
	DIFFERENTIAL AMPLIFIERS		
SE510	Dual Differential Amplifier	F	
SE511	Dual Differential Amplifier	F	
SE515	Differential Amplifier	F	H
SE592	Video Amplifier	F	H
μA733	Video Amplifier	F	H
	PHASE LOCKED LOOPS		
SE567	Tone Decoder PLL	F	H
SE564*	Phase Locked Loop	F	H
	TIMERS		
SE555	Timer	F,FE	H
SE556	Dual Timer	F	
SE558	Quad Timer	F	
SE559	Quad Timer	F	

DEVICE	DESCRIPTION	PACKAGE*	
		DIP/ CAN	CAN
	VOLTAGE REGULATORS		
SE5551	Dual Track Reg	F	H
SE5552	Dual Track Reg	F	H
SE5553	Dual Track Reg	F	H
SE5554	Dual Track Reg	F	H
SE5555	Dual Track Reg	F	H
78HV(8)	3 Term Pos Reg	K	—
78MHV(8)	3 Term Pos Reg	—	H
790X(8)	3 Term Neg Reg	K	—
79MOX(8)	3 Term Neg Reg	—	H
μA723	Adj Volt Reg	F	H

DEVICE	DESCRIPTION	PACKAGE	
		DIP	CAN
	D to A CONVERTERS		
SE5008	8-Bit Mult DAC	F	—
SE5009	8-Bit Mult DAC	F	—
SE5018	8-Bit μP-Comp DAC	F	—
SE5019	8-Bit μP-Comp DAC	F	—

JAN – 38510		
DEVICE	**QPL I**	**QPL II**
SE555F	1979	10901BCB
SE555FE	1979	10901BPB
SE555H	1979	10901BGC
SE556F	1979	10902BCB
LH2101AF	1979	10105BEB
LM101AF	10103BCB	—
LM101AFE	1979	10103BPB
LM101AH	1979	—
μA741H	1979	—
μA747H	1979	—
LM111F	—	1979
LM111H	1979	—
LM124F	—	1979
LM139F	—	1979

NOTES
F = Cerdip, K = TO-3
H = TO-5

PACKAGES

INTRODUCTION

The following information applies to all packages unless otherwise specified on individual package outline drawings.

General

1. Dimensions shown are metric units (millimeters), except those in parentheses which are English units (inches).
2. Lead spacing shall be measured within this zone.
   a. Shoulder and lead tip dimensions are to centerline of leads.
3. Tolerances non-cumulative
4. Thermal resistance values are determined by utilizing the linear temperature dependence of the forward voltage drop across the substrate diode in a digital device to monitor the junction temperature rise during known power application across V_{CC} and ground. The values are based upon 120 mils square die for plastic packages and a 90 mils square die in the smallest available cavity for hermetic packages. All units were solder mounted to P.C. boards, with standard stand-off, for measurement.

Plastic Only

5. Lead material: Alloy 42 or equivalent, solder dipped.
6. Body material: Plastic
7. Round hole in top corner denotes lead No. 1.
8. Body dimensions do not include molding flash.

Hermetic Only

9. Lead material
   a. Alloy 52—gold plated, or solder dipped.
   b. ASTM alloy F-15 (KOVAR) or equivalent—gold plated, tin plated, or solder dipped.
   c. ASTM alloy F-30 (Alloy 42) or equivalent—tin plated.
   d. ASTM alloy F-15 (KOVAR) or equivalent—gold plated.
   e. ASTM alloy F-15 (KOVAR) or equivalent—tin plated.
10. Body Material
    a. 1010 Steel—nickel plated or tin plate over nickel.
    b. Eyelet, ASTM alloy F-15 or equivalent—gold or tin plated.
    c. Eyelet, ASTM alloy F-15 or equivalent—gold or tin plated, glass body.
    d. Ceramic with glass seal at leads.
    e. BeO ceramic with glass seal at leads.
    f. Ceramic with ASTM alloy F-15 or equivalent.
11. Lid Material
    a. 1010 steel, nickel plated, or tin-plate over nickel, weld seal.
    b. Nickel or tin plated nickel, weld seal.
    c. Ceramic, glass seal.
    d. ASTM alloy F-15 or equivalent, gold plated.
    e. BeO Ceramic with glass seal.
    f. Translucent $A1_2O_3$, glass seal.
12. Signetics symbol, angle cut, or lead tab denotes Lead No. 1.
13. Recommended minimum offset before lead bend.
14. Maximum glass climb .010 inches.
15. Maximum glass climb or lid skew is .010 inches.
16. Typical four places.
17. Dimension also applies to seating plane.

PLASTIC PACKAGES

NO. OF LEADS	PACKAGE CODE	Θ_{ja}/Θ_{jc}(°C/W)	DESCRIPTION[1]
Standard Dual-In-Line			
8	NE	162/65	
14	NH	150/65	TO-116/MO-001
16	NJ	137/53	MO-001
18	NK	135/53	
20	NL	135/53	
22	NM	120/53	
24	NN	116/53	MO-015
24	NNE	TBD	
28	NQ	116/53	MO-015
40	NW	110/50	MO-015
Power Dual-In-Line			
8	NEA[2]	180/80	Heatsink
14	NHA[2]	95/33	Heatsink
16	NJA[2]	95/33	Heatsink
18	NKA[2]	90/26	Heatsink
20	NLA[2]	90/26	Heatsink
22	NMA[2]	80/40	Heatsink
24	NNA[2]	60/23	Heatsink
28	NQA[2]	56/21	Heatsink
40	NWA[2]	45/18	Heatsink
Power			
3	S	200/70	TO-92
3	UCA	75/3	TO-220
3 + GND	UC	95/15	Single-in-Line (SIL)
4 + GND	UD	95/15	Single-in-Line (SIL)
5 + GND	UEA	TBD	TO-220
7 + GND	UGA	TBD	TO-220
12 + GND	PH/PHA	95/15	Batwing

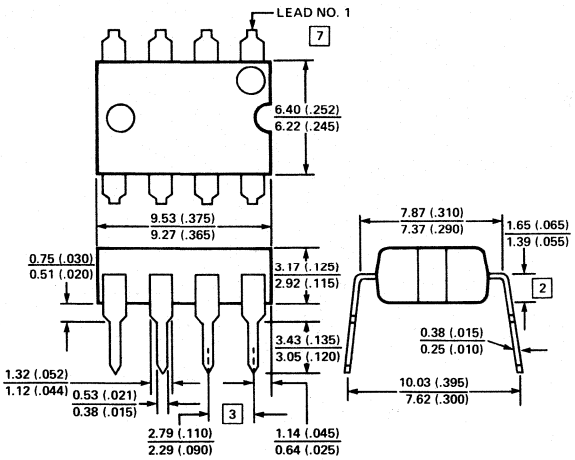
HERMETIC PACKAGES

NO. OF LEADS	PACKAGE CODE	Θ_{ja}/Θ_{jc}(°C/W)	DESCRIPTION[1]
Metal Headers			
2	K	TBD	TO-3 Solid Header
3	HBA	TBD	TO-39 Solid Header, Short Can
4	DC	TBD	TO-72 Solid Header
4	DE	TBD	TO-72 Glass Filled Header
4	HCA	TBD	TO-12 Glass Filled Header, Short Can
8	HEA	150/45	TO-99 Header (.200 Dia.)
10	HFA	150/45	TO-100 Header, Short Can
10	HFC	150/45	TO-100 Header, Tall Can
Flat Packs			
10	WF	240/50	Flat Ceramic
14	WH	205/50	Flat Ceramic
16	WJ	200/50	Flat Ceramic
24	WN	155/40	Flat Ceramic
16	RJA	145/26	Flat Ceramic, BeO
18	RKA	107/22	Flat Ceramic, BeO
24	RNA	96/22	Flat Ceramic, BeO
28	RQA	92/22	Flat Ceramic, BeO
40	RWA	77/20	Flat Ceramic, BeO
10	QFA	230/55	Flat Ceramic Laminate
14	QHA	185/45	Flat Ceramic Laminate
16	QJA	170/45	Flat Ceramic Laminate
24	QNA	155/44	Flat Ceramic Laminate
Cerdip Family			
8	FE	140/32	Dual-in-Line Ceramic
14	FH	110/30	Dual-in-Line Ceramic
16	FJ	100/30	Dual-in-Line Ceramic
18	FK	93/27	Dual-in-Line Ceramic
20	FL	88/27	Dual-in-Line Ceramic
22	FM	75/27	Dual-in-Line Ceramic
24	FN	60/26	Dual-in-Line Ceramic
28	FQ	55/26	Dual-in-Line Ceramic
Laminated Ceramic, Side Brazed Lead			
8	IEA	100/30	Dip Laminate
14	IHA	95/25	Dip Laminate
16	IJA	90/25	Dip Laminate
18	IKA	88/25	Dip Laminate
22	IMA	80/25	Dip Laminate
24	INC	65/25	Dip Laminate
28	IQA	60/25	Dip Laminate
40	IWA	55/25	Dip Laminate
48	JY	TBD	Leadless Dip Laminate
50	IZA	42/20	Dip Laminate

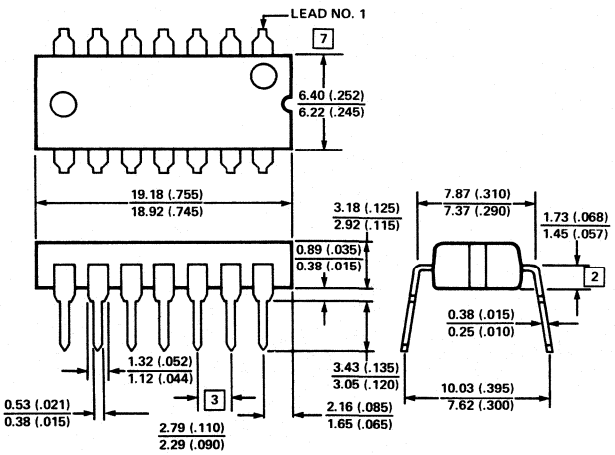
NOTES
1. Dual-in-Line packages unless otherwise described.
2. Package outline is the same as corresponding standard Dual-in-Line package with identical number of leads.

PLASTIC: Standard and Power Dual-In-Line

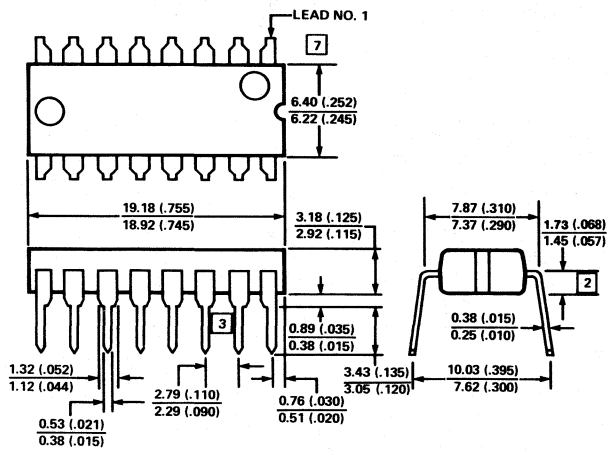
NE Package and NEA Package



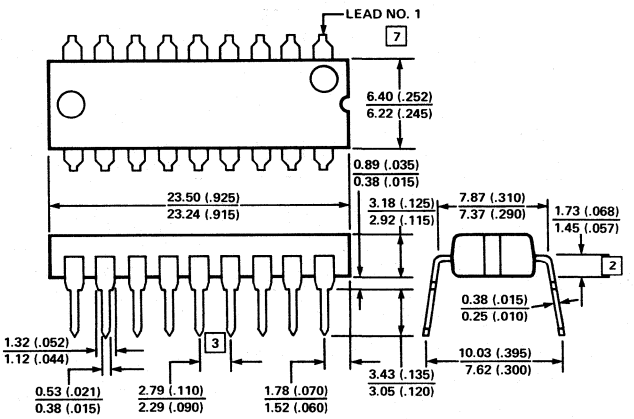
NH Package and NHA Package



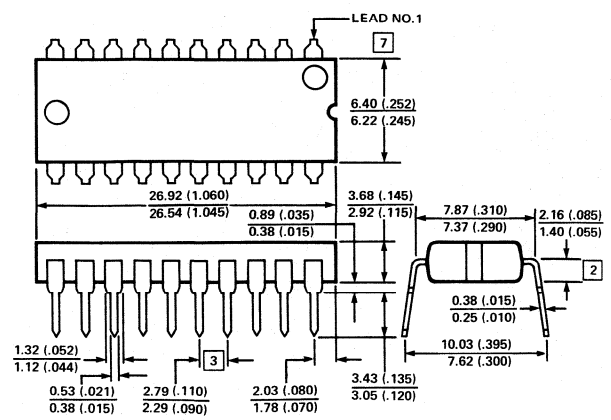
NJ Package and NJA Package



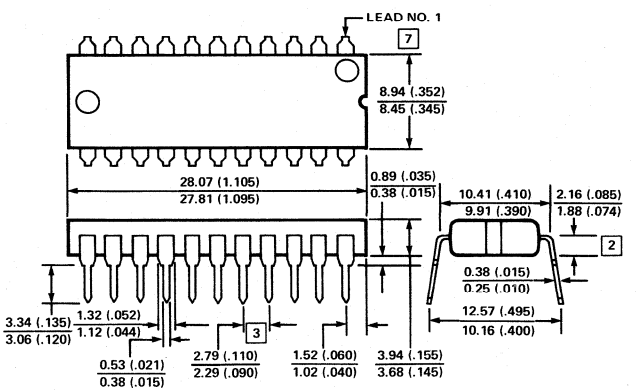
NK Package and NKA Package



NL Package and NLA Package

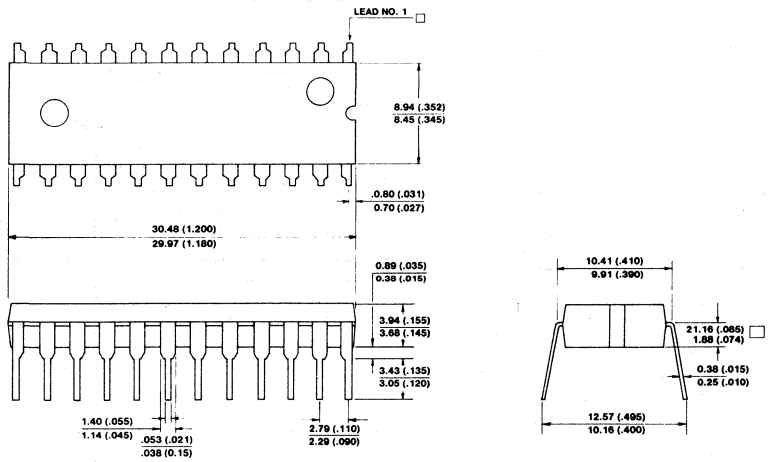


NM Package and NMA Package

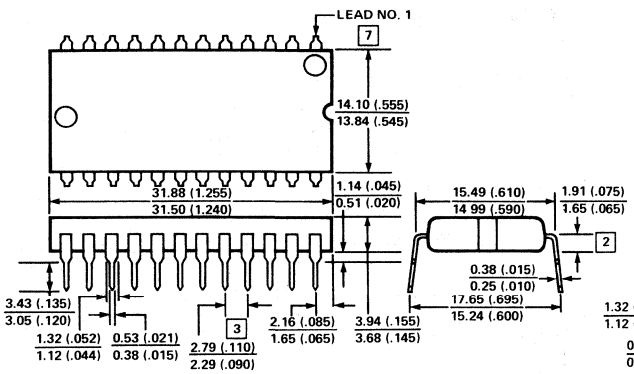


PLASTIC: Standard and Power Dual-In-Line (cont'd.)

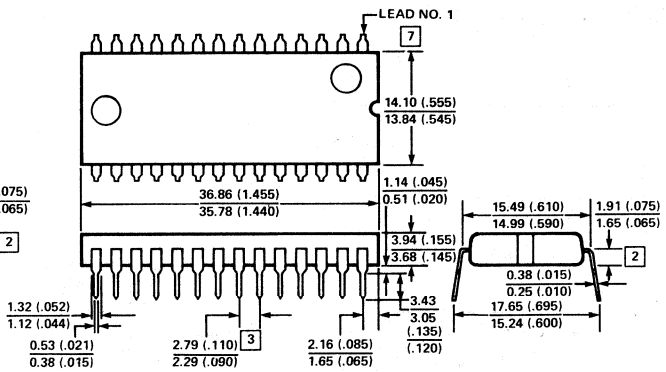
NNE/NNF Package



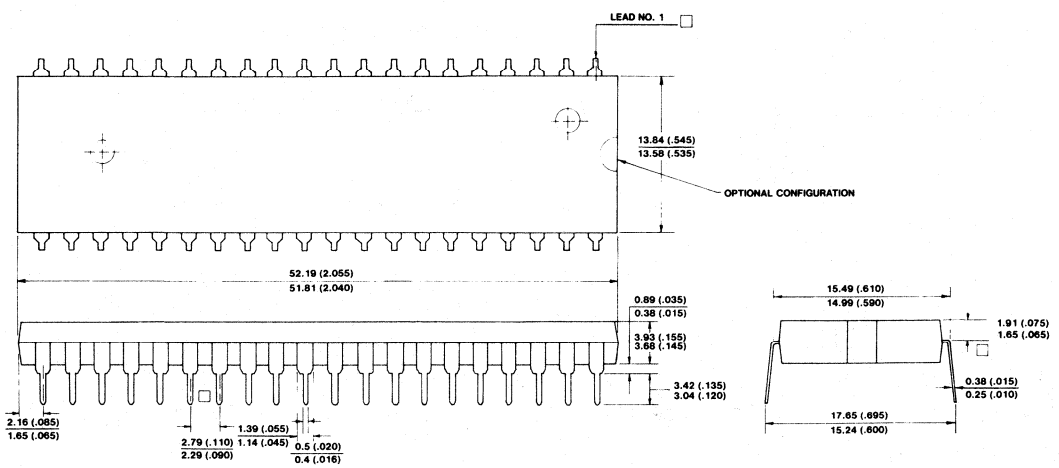
NN Package and NNA Package



NQ Package and NQA Package

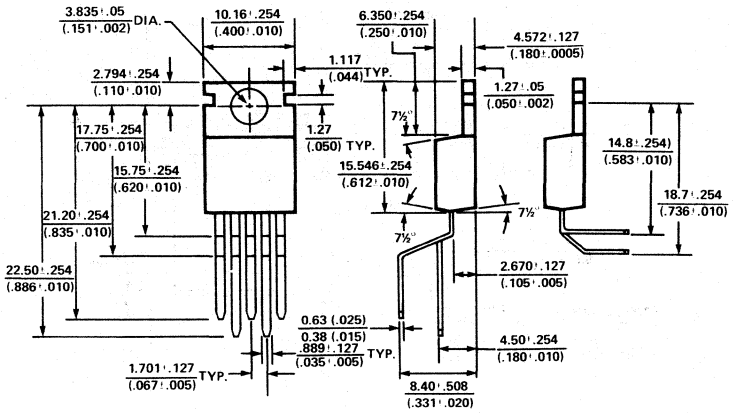


NW Package and NWA Package



PLASTIC: Power (Not Dual-In-Line) (cont'd.)

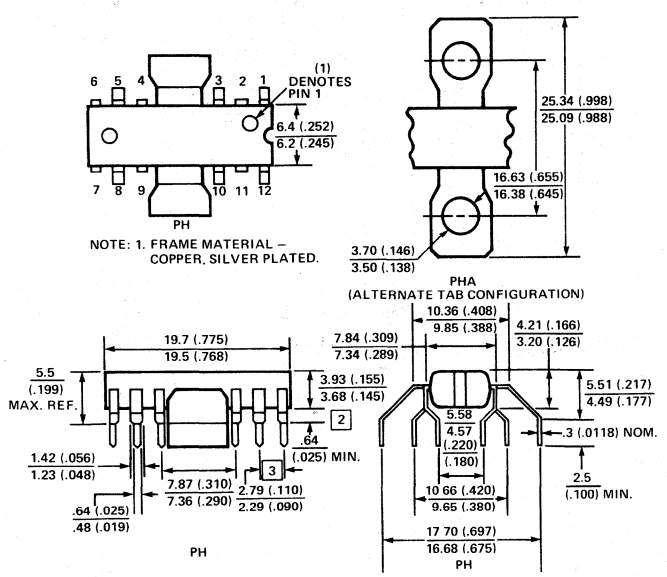
UEA Package



UGA Package

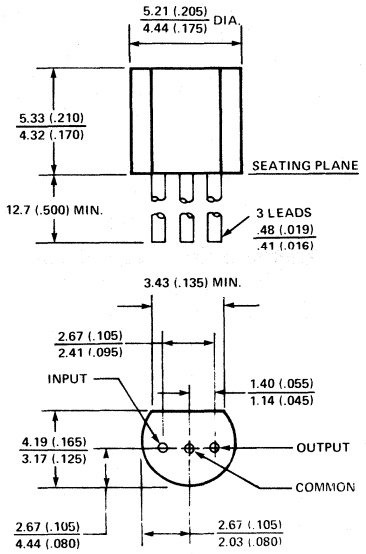
Package drawing not yet available.

PH/PHA Package

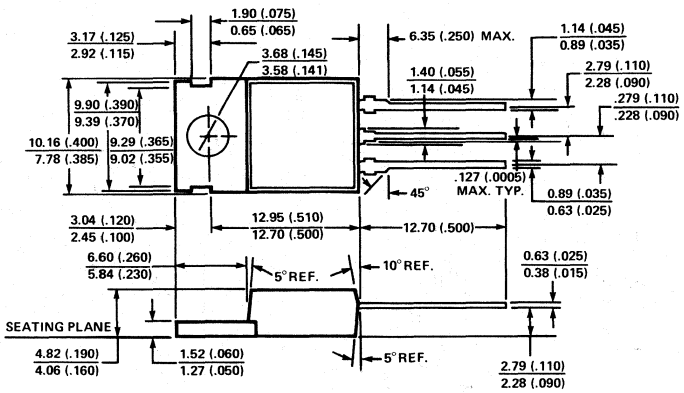


PLASTIC: Power (Not Dual-In-Line)

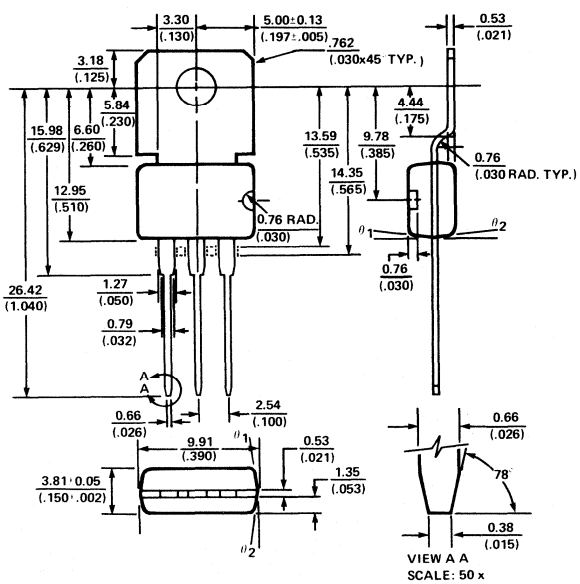
S Package



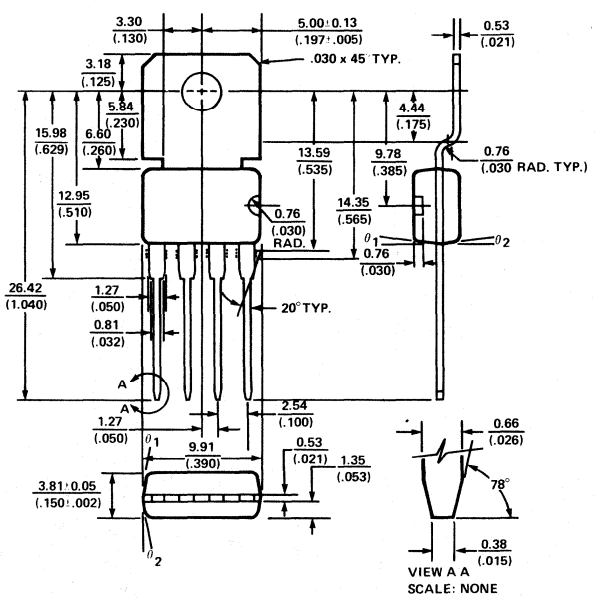
UCA Package



UC Package

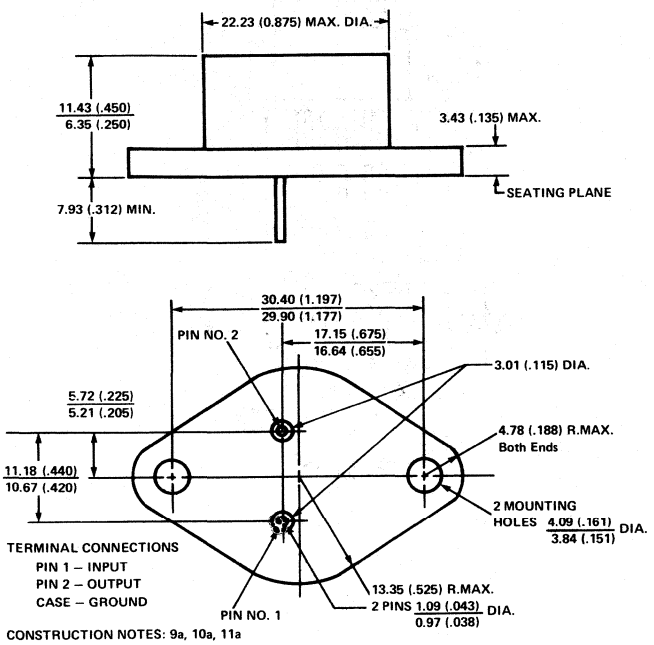


UD Package



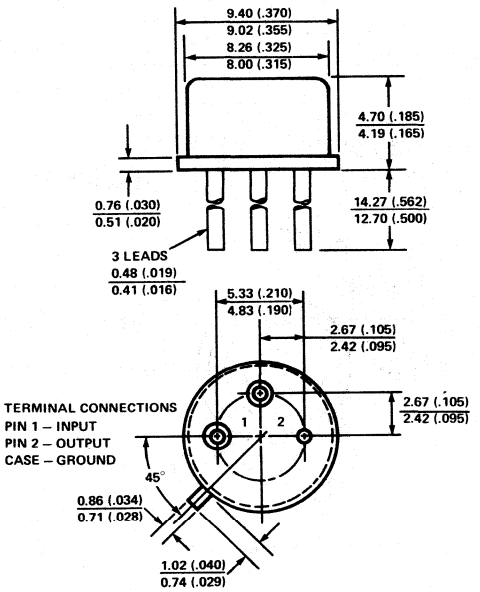
HERMETIC: Metal Headers

K Package (formerly DA)



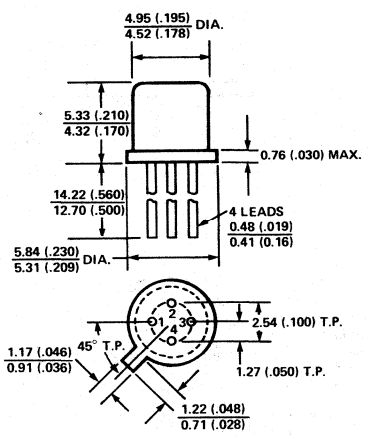
CONSTRUCTION NOTES: 9a, 10a, 11a

HBA Package (formerly DB)



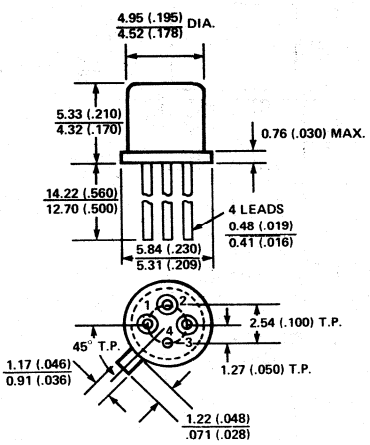
CONSTRUCTION NOTES: 9b, 10b, 11b

DC Package



CONSTRUCTION NOTES: 9b, 10b, 11b

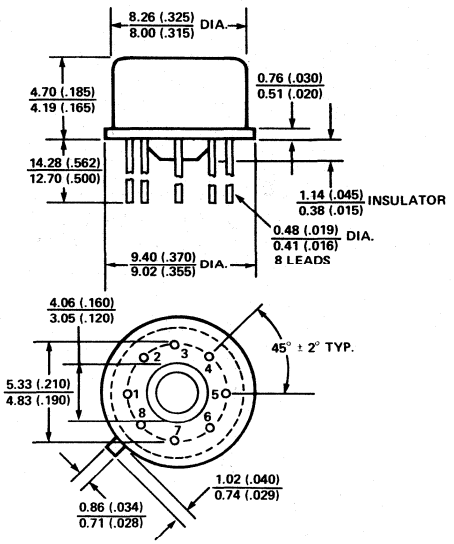
DE Package



CONSTRUCTION NOTES: 9b, 10c, 11b

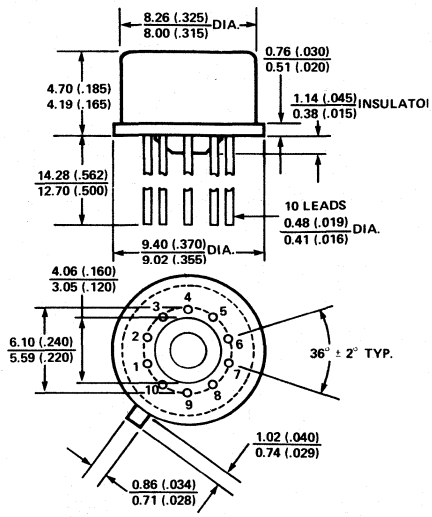
HERMETIC: Metal Headers (cont'd.)

HEA Package (formerly T)



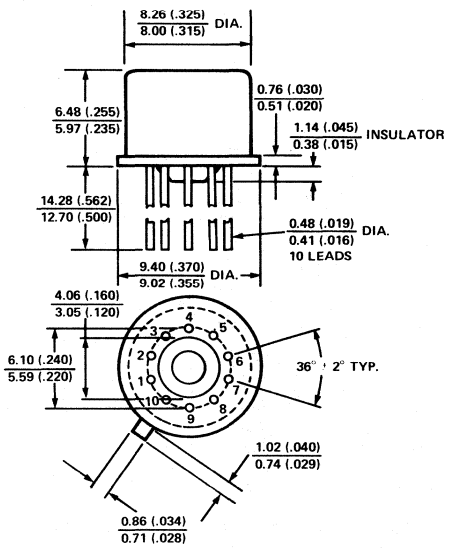
CONSTRUCTION NOTES: 9b, 10c, 11b

HFA Package (formerly K)



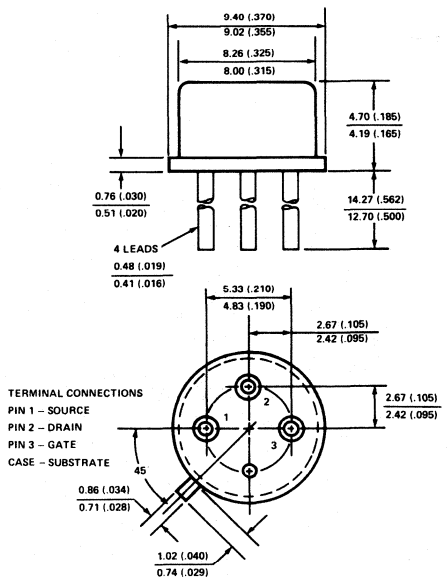
CONSTRUCTION NOTES: 9b, 10c, 11b

HFC Package (formerly L)



CONSTRUCTION NOTES: 9b, 10c, 11b

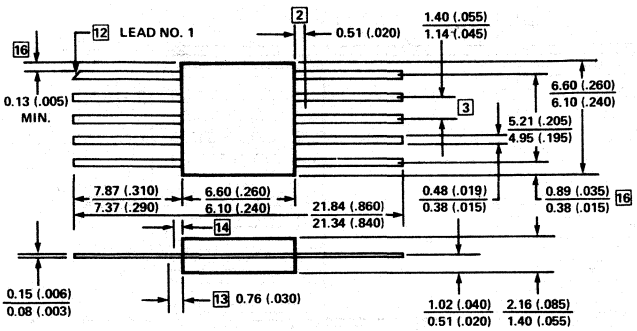
HCA Package



CONSTRUCTION NOTES: 9b, 10b, 11b

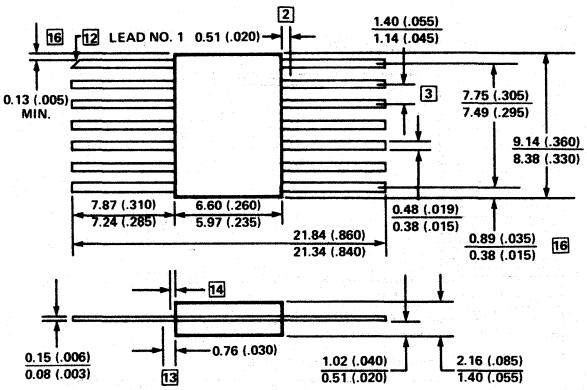
HERMETIC: Flat Packs

WF Package



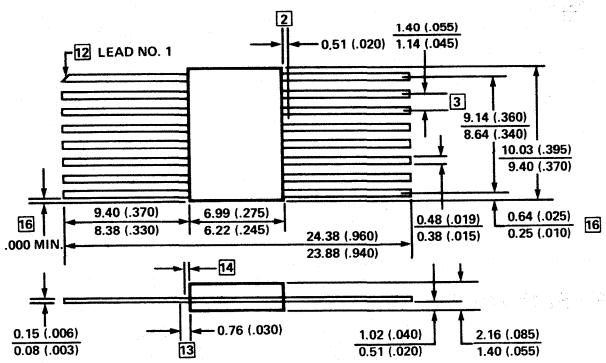
CONSTRCUTION NOTES: 9c, 10d, 11c

WH Package



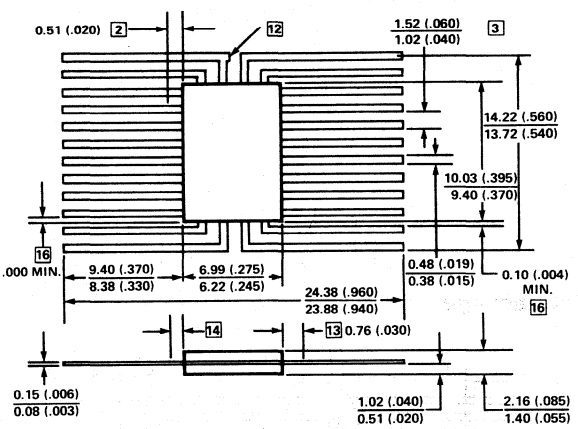
CONSTRUCTION NOTES: 9c, 10d, 11c

WJ Package



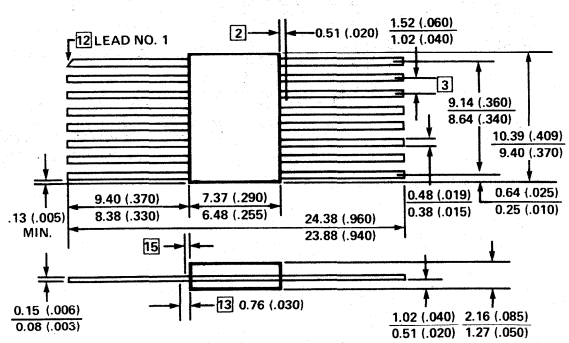
CONSTRUCTION NOTES: 9c, 10d, 11c

WN Package



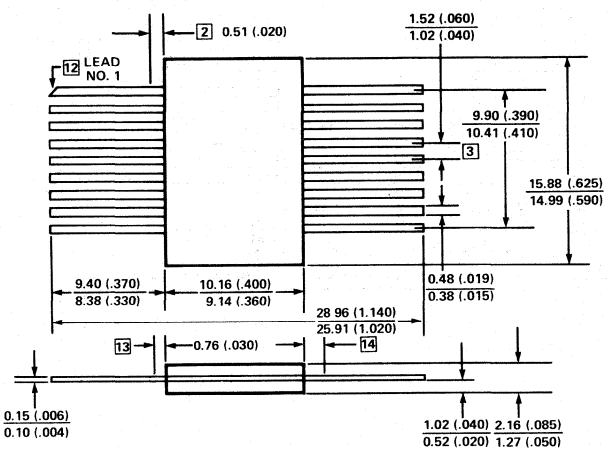
CONSTRUCTION NOTES: 9c, 10d, 11c

RJA Package



RJA CONSTRUCTION NOTES: 9c, 10e, 11e

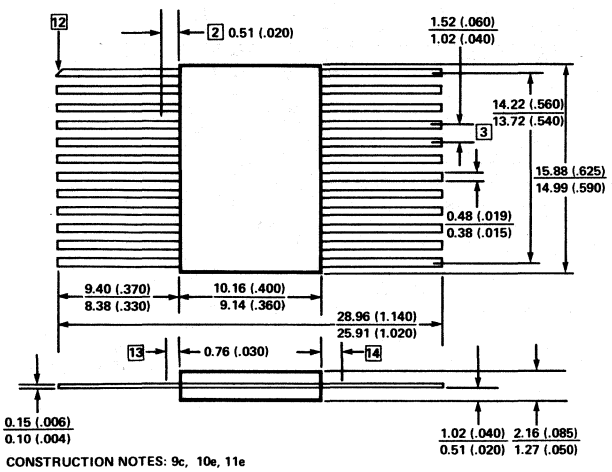
RKA Package



CONSTRUCTION NOTES: 9c, 10e, 11e

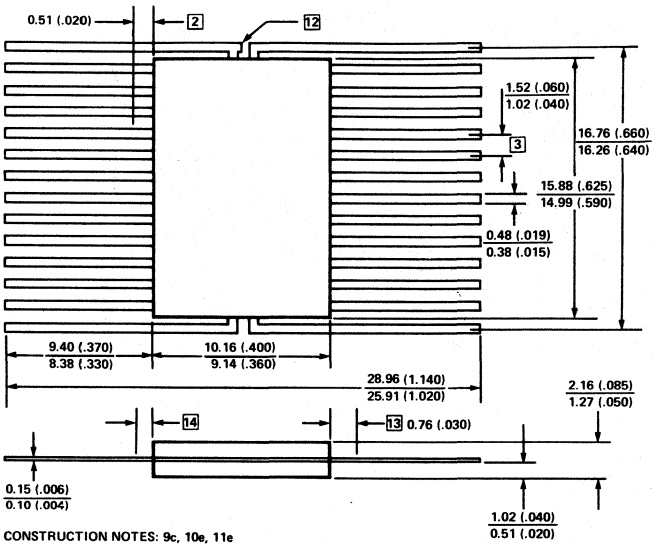
HERMETIC: Flat Packs (cont'd.)

RNA Package



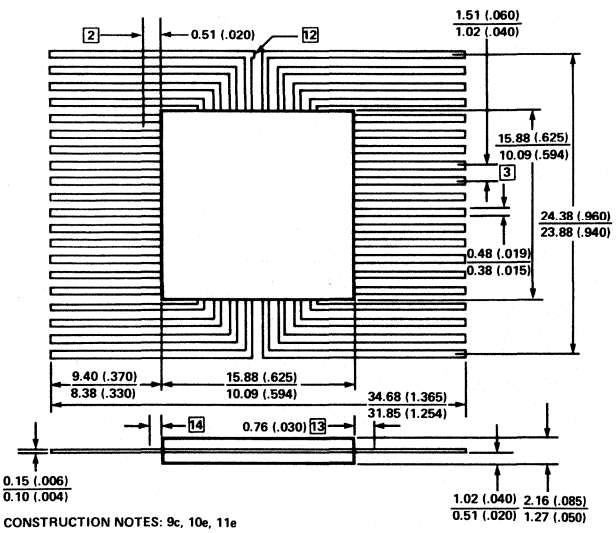
CONSTRUCTION NOTES: 9c, 10e, 11e

RQA Package



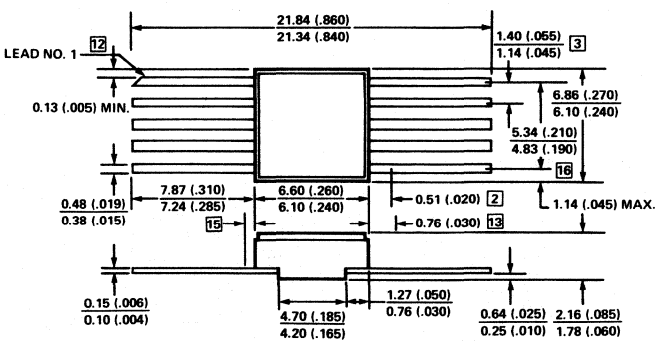
CONSTRUCTION NOTES: 9c, 10e, 11e

RWA Package



CONSTRUCTION NOTES: 9c, 10e, 11e

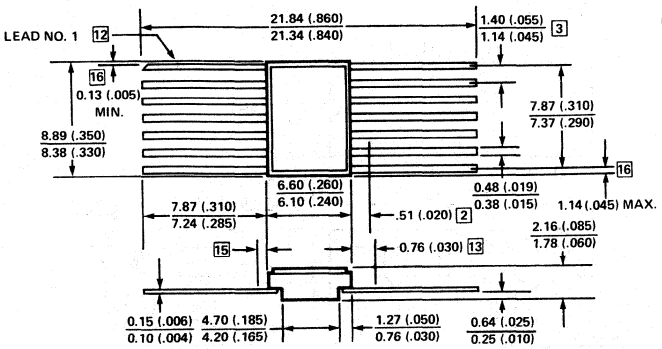
QFA Package



CONSTRUCTION NOTES: 9d, 10f, 11c

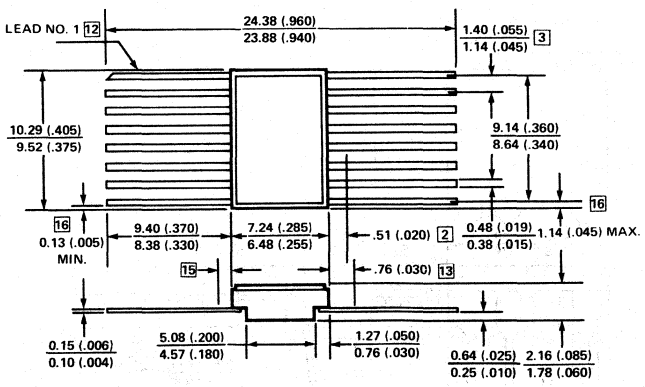
HERMETIC: Flat Packs (cont'd.)

QHA Package



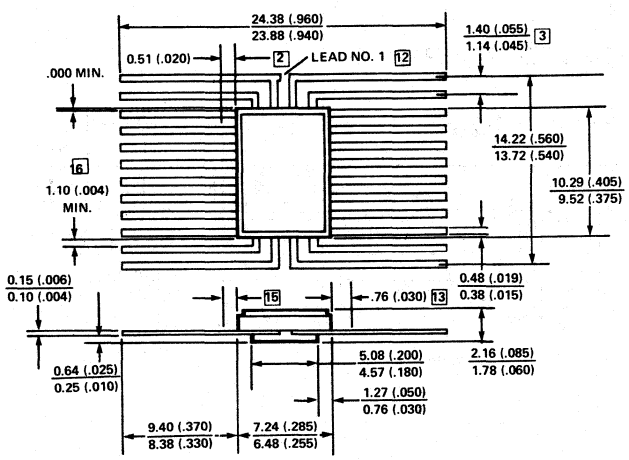
CONSTRUCTION NOTES: 9d, 10f, 11c

QJA Package



CONSTRUCTION NOTES: 9d, 10f, 11c

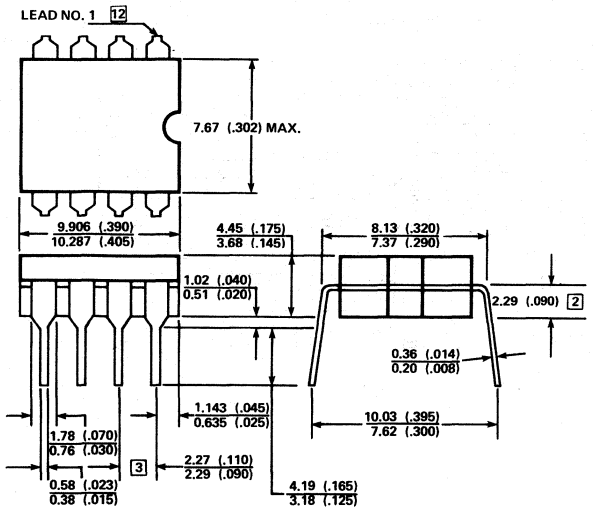
QNA Package



CONSTRUCTION NOTES: 9d, 10f, 11c

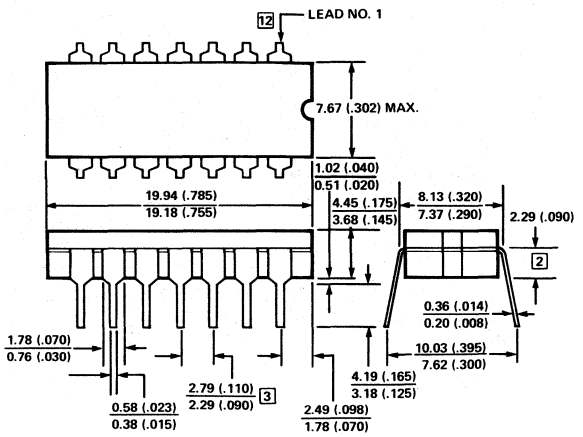
HERMETIC: Cerdip

FE Package



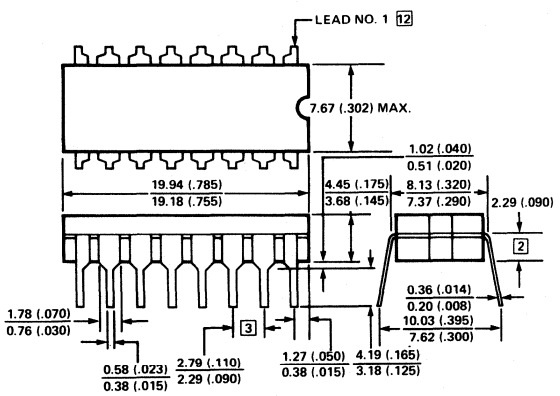
CONSTRUCTION NOTES: 9C, 10D, 11C

FH Package



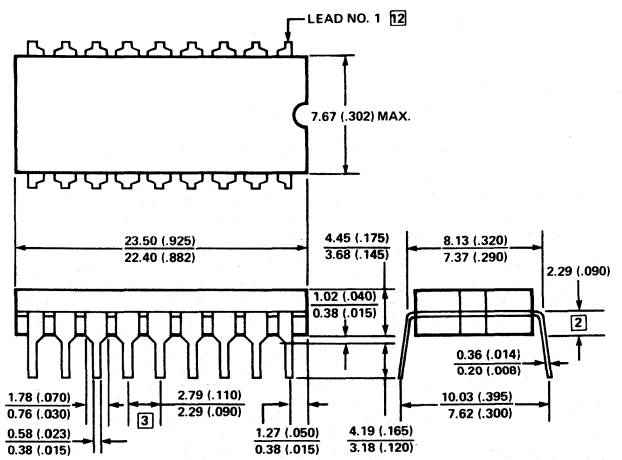
CONSTRUCTION NOTES: 9c, 10d, 11c

FJ Package



CONSTRUCTION NOTES: 9c, 10d, 11c

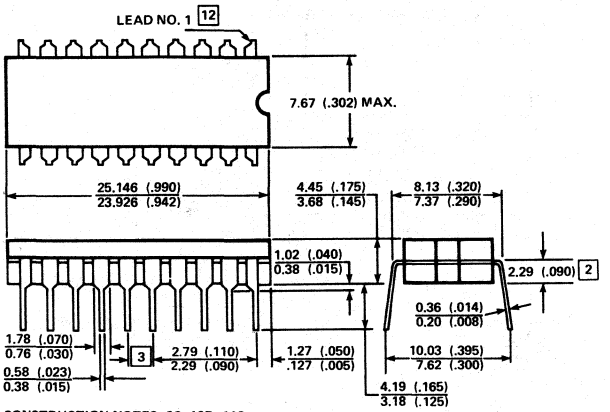
FK Package



CONSTRUCTION NOTES: 9c, 10d, 11c

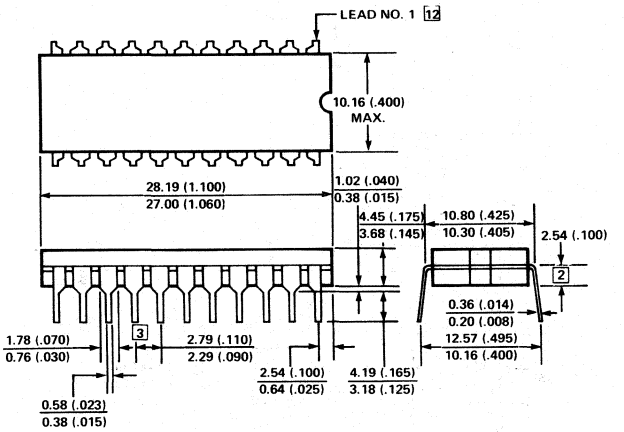
HERMETIC: Cerdip (cont'd.)

FL Package



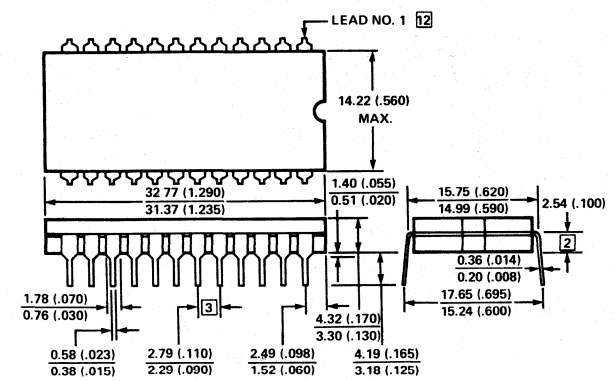
CONSTRUCTION NOTES: 9C, 10D, 11C

FM Package



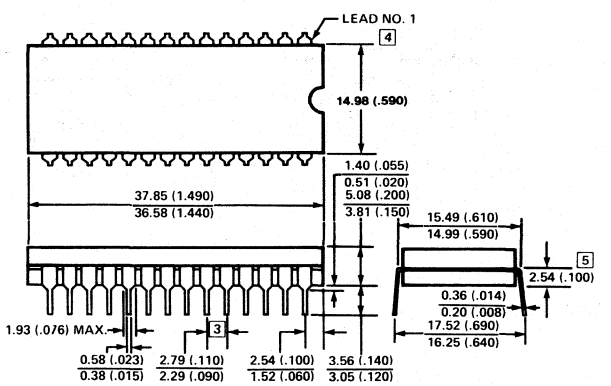
CONSTRUCTION NOTES: 9c, 10d, 11c

FN Package



CONSTRUCTION NOTES: 9c. 10d, 11c

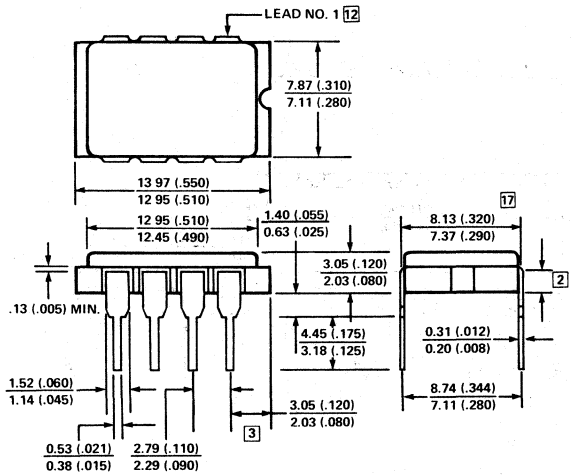
FQ Package



CONSTRUCTIONS NOTES: 9c, 10d, 11c

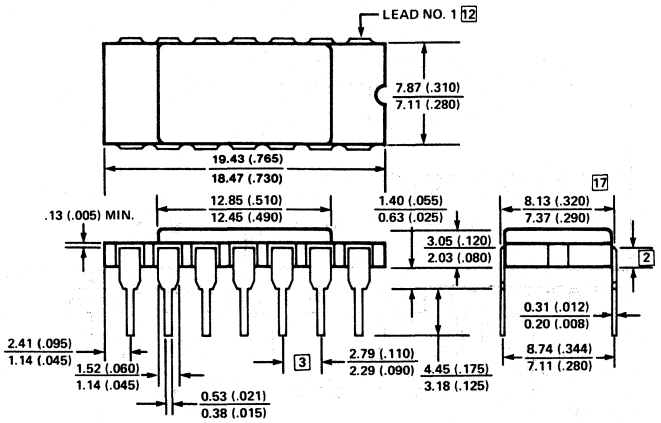
HERMETIC: Laminated Ceramic, Side Brazed Lead

IEA Package



CONSTRUCTION NOTES: 9e, 10f, 11c

IHA Package



CONSTRUCTION NOTES: 9e, 10f, 11c

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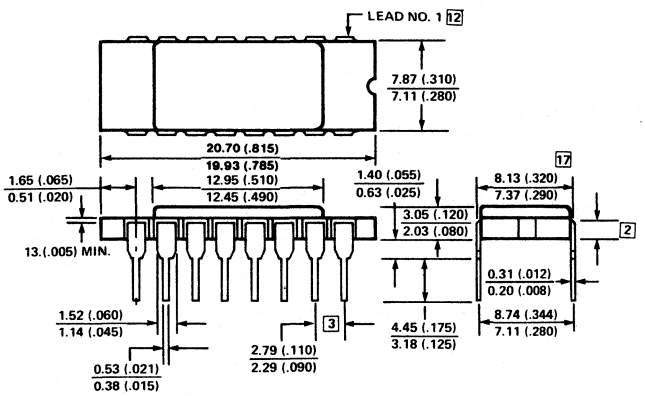

CONSTRUCTION NOTES: 9e, 10d,11c

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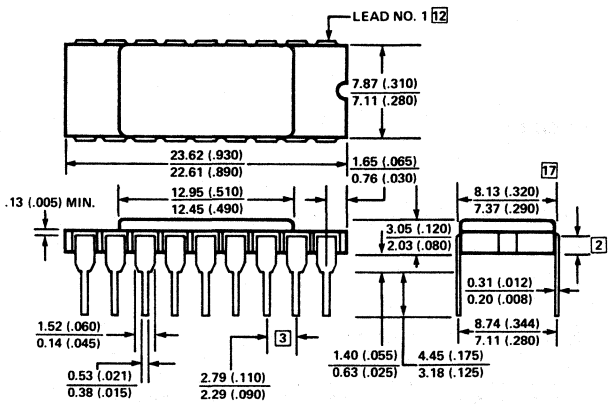

CONSTRUCTION NOTES: 9e, 10f, 11c

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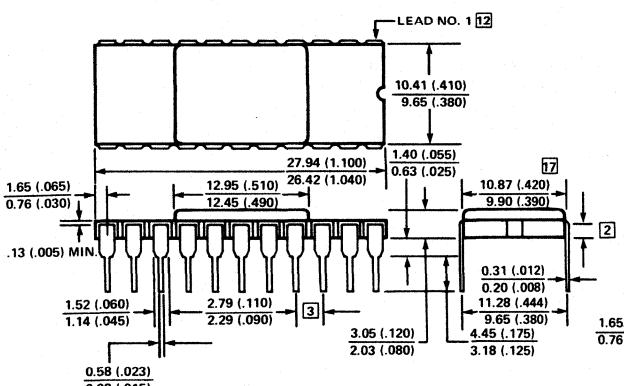

CONSTRUCTION NOTES: 9e, 10f, 11c

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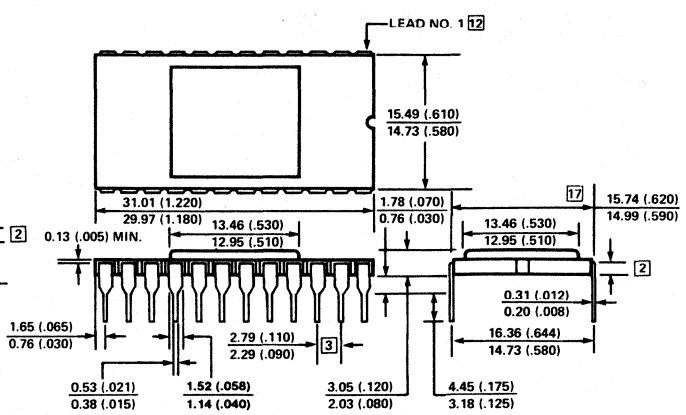
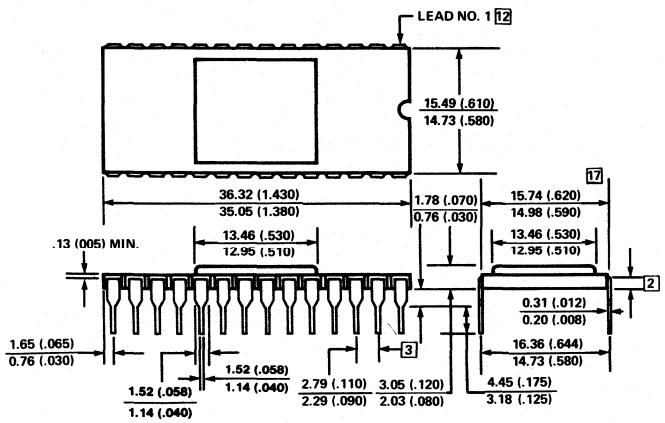


CONSTRUCTION NOTES: 9e, 10f, 11f (IND)

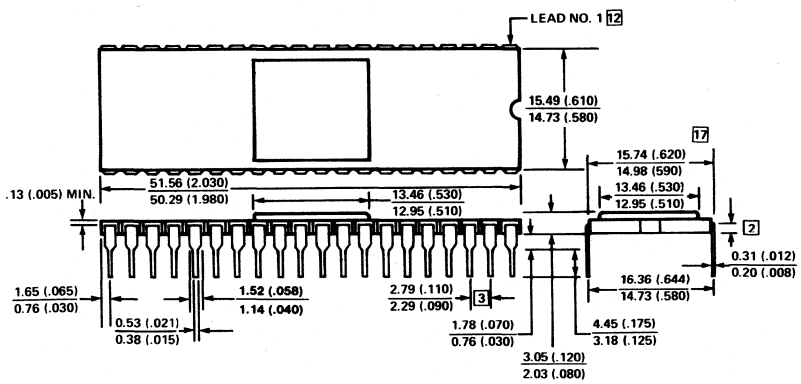
HERMETIC: Laminated Cermaic, Side Brazed Lead (cont'd.)

IQA Package



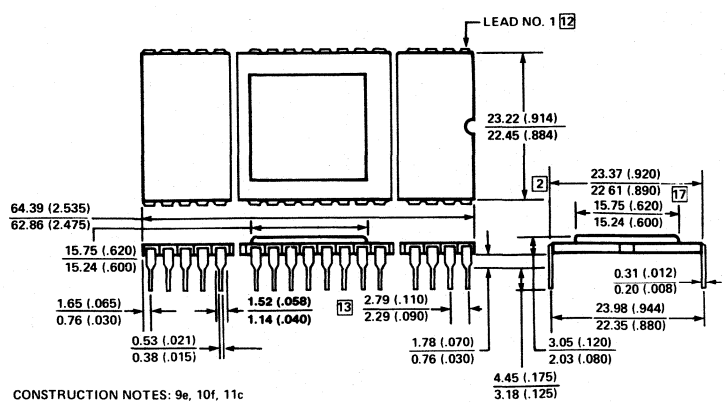
CONSTRUCTION NOTES: 9e, 10f, 11c

IWA Package



CONSTRUCTION NOTES: 9e, 10f, 11c

IZA Package



CONSTRUCTION NOTES: 9e, 10f, 11c

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